AN2606
Application note

Introduction to system memory boot mode on STM32 MCUs

Introduction

This document applies to the products listed in *Table 1*, referred to as STM32 throughout the document.

It describes the supported peripherals and hardware requirements to consider when using the bootloader, stored in the internal boot ROM (system memory) of STM32 devices, and programmed during production.

Its main task is to download the application program to the internal flash memory through one of the available serial peripherals (such as USART, CAN, USB, I^2C, I^3C, SPI, FDCAN). A communication protocol is defined for each interface, with a compatible command set and sequence.

Table 1. Applicable products

Type	Part number or product series	
Microcontrollers	STM32C0 series	STM32C011xx, STM32C031xx, STM32C051xx, STM32C071xx, STM32C091xx, STM32C092xx
	STM32C5 series	STM32C5A3xx, STM32C531xx, STM32C532xx, STM32C542xx, STM32C551xx, STM32C552xx, STM32C562xx, STM32C591xx, STM32C593xx
	STM32F0 series	STM32F03xxx, STM32F04xxx, STM32F05xxx, STM32F07xxx, STM32F09xxx
	STM32F1 series	All products
	STM32F2 series	All products
	STM32F3 series	STM32F301xx, STM32F302xx, STM32F303xx, STM32F318xx, STM32F328xx, STM32F334xx, STM32F358xx, STM32F373xx, STM32F378xx, STM32F398xx
	STM32F4 series	STM32F401xx, STM32F405xx, STM32F407xx, STM32F410xx, STM32F411xx, STM32F412xx, STM32F413xx, STM32F415xx, STM32F417xx, STM32F423xx, STM32F427xx, STM32F429xx, STM32F437xx, STM32F439xx, STM32F446xx, STM32F469xx, STM32F479xx
	STM32F7 series	STM32F722xx, STM32F723xx, STM32F732xx, STM32F733xx, STM32F745xx, STM32F746xx, STM32F756xx, STM32F765xx, STM32F767xx, STM32F769xx, STM32F777xx, STM32F779xx
	STM32G0 series	STM32G030xx, STM32G031xx, STM32G041xx, STM32G07xxx, STM32G08xxx, STM32G0B0xx, STM32G0B1xx, STM32G0C1xx, STM32G050xx, STM32G051xx, STM32G061xx
	STM32G4 series	STM32G431xx, STM32G441xx, STM32G47xxx, STM32G48xxx, STM32G491xx, STM32G4A1xx
	STM32G5 series	All
	STM32H5 series	STM32H503xx, STM32H523xx, STM32H533xx, STM32H543xx, STM32H553xx, STM32H562xx, STM32H563xx, STM32H573xx, STM32H5E4xx, STM32H5E5xx, STM32H5F4xx, STM32H5F5xx

Table 1. Applicable products (continued)

Type	Part number or product series	
Microcontrollers	STM32H7 series	STM32H72xxx, STM32H73xxx, STM32H74xxx, STM32H75xxx, STM32H7A3xx, STM32H7B0xx, STM32H7B3xx, STM32H7R3xx, STM32H7R7xx, STM32H7S3xx, STM32H7S7xx, STM32H7P4xx, STM32H7P5xx
	STM32L0 series	All products
	STM32L1 series	STM32L100xx, STM32L151xx, STM32L152xx, STM32L162xx
	STM32L4 series	STM32L431xx, STM32L432xx, STM32L433xx, STM32L442xx, STM32L443xx, STM32L451xx, STM32L452xx, STM32L462xx, STM32L471xx, STM32L475xx, STM32L476xx, STM32L486xx, STM32L496xx, STM32L4A6xx, STM32L4R5xx, STM32L4R7xx, STM32L4R9xx, STM32L4S5xx, STM32L4S7xx, STM32L4S9xx, STM32L412xx, STM32L422xx, STM32L4P5xx, STM32L4Q5xx, STM32L431xx, STM32L432xx, STM32L433xx, STM32L442xx, STM32L443xx, STM32L451xx, STM32L452xx, STM32L462xx, STM32L471xx, STM32L475xx, STM32L476xx, STM32L486xx, STM32L496xx, STM32L4A6xx, STM32L4R5xx, STM32L4R7xx, STM32L4R9xx, STM32L4S5xx, STM32L4S7xx, STM32L4S9xx, STM32L412xx, STM32L422xx, STM32L4P5xx, STM32L4Q5xx
	STM32L5 series	STM32L552xx, STM32L562xx
	STM32U0 series	STM32U031xx, STM32U073xx, STM32U083xx
	STM32U3 series	STM32U375xx, STM32U385xx, STM32U3B5xx, STM32U3C5xx
	STM32U5 series	STM32U535xx, STM32U545xx, STM32U575xx, STM32U585xx, STM32U595xx, STM32U599xx, STM32U5A5xx,STM32U5A9xx, STM32U5F7xx, STM32U5F9xx, STM32U5G7xx, STM32U5G9xx
	STM32WB series	STM32WB10xx, STM32WB15xx, STM32WB30xx, STM32WB35xx, STM32WB50xx, STM32WB55xx
	STM32WBA series	STM32WBA23xx, STM32WBA25xx, STM32WBA50xx, STM32WBA52xx, STM32WBA54xx, STM32WBA55xx, STM32WBA62xx, STM32WBA63xx, STM32WBA64xx, STM32WBA65xx
	STM32WB0 series	STM32WB05xx, STM32WB06xx, STM32WB07xx, STM32WB09xx
	STM32WL series	STM32WL30xx, STM32WL31xx, STM32WL33xx, STM32WL3Rxx, STM32WLE5xx, STM32WL55xx

Contents

1 General information 28

2 Related documents 28

3 Glossary 29

4 General bootloader description 35

4.1 Bootloader activation 35

4.2 Bootloader identification 38

4.3 Hardware connection requirements 48

4.4 Bootloader memory management 50

4.5 Bootloader UART baudrate detection 52

4.6 Programming constraints 54

4.7 ExitSecureMemory feature 55

4.7.1 ExitSecureMemory v1.0 55

4.7.2 ExitSecureMemory v1.1 57

4.7.3 ExitSecureMemory v2.0 58

4.8 IWDG usage 59

4.9 Bootloader models 59

4.10 Boot constraints on BL 60

4.11 Possibility to disable bootloader instances 62

5 STM32C011xx devices 63

5.1 Bootloader configuration 63

5.2 Bootloader selection 64

5.3 Bootloader version 64

6 STM32C031xx devices 65

6.1 Bootloader configuration 65

6.2 Bootloader selection 66

6.3 Bootloader version 66

7 STM32C051xx devices 67

7.1 Bootloader configuration 67
7.2 Boot model 69
7.3 Bootloader selection 70
7.4 Bootloader version 71

8 STM32C071xx devices 72
8.1 Bootloader configuration 72
8.2 Bootloader selection 74
8.3 Bootloader version 75

9 STM32C091xx/92xx devices 76
9.1 Bootloader configuration 76
9.2 Boot model 78
9.3 Bootloader selection 79
9.4 Bootloader version 80

10 STM32C531xx/532xx/542xx devices 81
10.1 Bootloader configuration 81
10.2 BL_COM_CFG mapping 84
10.3 Bootloader selection 84
10.4 Bootloader version 85

11 STM32C55xxx/562xx devices 86
11.1 Bootloader configuration 86
11.2 BL_COM_CFG mapping 89
11.3 Bootloader selection 89
11.4 Bootloader version 90

12 STM32C5A3xx/59xxx devices 91
12.1 Bootloader configuration 91
12.2 BL_COM_CFG mapping 94
12.3 Bootloader selection 94
12.4 Bootloader version 95

13 STM32F03xx4/6 devices 96

13.1 Bootloader configuration 96
13.2 Bootloader selection 97
13.3 Bootloader version 97

14 STM32F030xC devices 98
14.1 Bootloader configuration 98
14.2 Bootloader selection 99
14.3 Bootloader version 99

15 STM32F05xxx and STM32F030x8 devices 100
15.1 Bootloader configuration 100
15.2 Bootloader selection 101
15.3 Bootloader version 101

16 STM32F04xxx devices 102
16.1 Bootloader configuration 102
16.2 Bootloader selection 104
16.3 Bootloader version 105

17 STM32F070x6 devices 106
17.1 Bootloader configuration 106
17.2 Bootloader selection 108
17.3 Bootloader version 109

18 STM32F070xB devices 110
18.1 Bootloader configuration 110
18.2 Bootloader selection 112
18.3 Bootloader version 113

19 STM32F071xx/072xx devices 114
19.1 Bootloader configuration 114
19.2 Bootloader selection 116
19.3 Bootloader version 116

20 STM32F09xxx devices 118

20.1 Bootloader configuration 118
20.2 Bootloader selection 119
20.3 Bootloader version 119

21 STM32F10xxx devices 120
21.1 Bootloader configuration 120
21.2 Bootloader selection 121
21.3 Bootloader version 121

22 STM32F105xx/107xx devices 123
22.1 Bootloader configuration 123
22.2 Bootloader selection 125
22.3 Bootloader version 126
22.3.1 How to identify STM32F105xx/107xx bootloader versions 126
22.3.2 Bootloader unavailability on STM32F105xx/STM32F107xx devices with date code lower than 937 127
22.3.3 USART bootloader Get-Version command returns 0x20 instead of 0x22 127
22.3.4 PA9 excessive power consumption when USB cable is plugged in bootloader V2.0 128

23 STM32F10xxx XL-density devices 129
23.1 Bootloader configuration 129
23.2 Bootloader selection 130
23.3 Bootloader version 130

24 STM32F2xxxx devices 131
24.1 Bootloader V2.x 131
24.1.1 Bootloader configuration 131
24.1.2 Bootloader selection 132
24.1.3 Bootloader version 133
24.2 Bootloader V3.x 134
24.2.1 Bootloader configuration 134
24.2.2 Bootloader selection 136
24.2.3 Bootloader version 137

25 STM32F301xx/302x4(6/8) devices 138

25.1 Bootloader configuration 138
25.2 Bootloader selection 140
25.3 Bootloader version 141

26 STM32F302xB(C)/303xB(C) devices 142
26.1 Bootloader configuration 142
26.2 Bootloader selection 144
26.3 Bootloader version 145

27 STM32F302xD(E)/303xD(E) devices 146
27.1 Bootloader configuration 146
27.2 Bootloader selection 148
27.3 Bootloader version 149

28 STM32F303x4(6/8)/334xx/328xx devices 150
28.1 Bootloader configuration 150
28.2 Bootloader selection 151
28.3 Bootloader version 151

29 STM32F318xx devices 152
29.1 Bootloader configuration 152
29.2 Bootloader selection 153
29.3 Bootloader version 154

30 STM32F358xx devices 155
30.1 Bootloader configuration 155
30.2 Bootloader selection 156
30.3 Bootloader version 156

31 STM32F373xx devices 157
31.1 Bootloader configuration 157
31.2 Bootloader selection 159
31.3 Bootloader version 159

32 STM32F378xx devices 161

32.1 Bootloader configuration 161
32.2 Bootloader selection 162
32.3 Bootloader version 162

33 STM32F398xx devices 163
33.1 Bootloader configuration 163
33.2 Bootloader selection 164
33.3 Bootloader version 165

34 STM32F40xxx/41xxx devices 166
34.1 Bootloader V3.x 166
34.1.1 Bootloader configuration 166
34.1.2 Bootloader selection 168
34.1.3 Bootloader version 169
34.2 Bootloader V9.x 169
34.2.1 Bootloader configuration 169
34.2.2 Bootloader selection 173
34.2.3 Bootloader version 174

35 STM32F401xB(C) devices 175
35.1 Bootloader configuration 175
35.2 Bootloader selection 178
35.3 Bootloader version 179

36 STM32F401xD(E) devices 180
36.1 Bootloader configuration 180
36.2 Bootloader selection 183
36.3 Bootloader version 184

37 STM32F410xx devices 185
37.1 Bootloader configuration 185
37.2 Bootloader selection 188
37.3 Bootloader version 189

38 STM32F411xx devices 190
38.1 Bootloader configuration 190

38.2 Bootloader selection 193
38.3 Bootloader version 194

39 STM32F412xx devices 195
39.1 Bootloader configuration 195
39.2 Bootloader selection 199
39.3 Bootloader version 200

40 STM32F413xx/423xx devices 201
40.1 Bootloader configuration 201
40.2 Bootloader selection 205
40.3 Bootloader version 206

41 STM32F42xxx/43xxx devices 207
41.1 Bootloader V7.x 207
41.1.1 Bootloader configuration 207
41.1.2 Bootloader selection 210
41.1.3 Bootloader version 212
41.2 Bootloader V9.x 213
41.2.1 Bootloader configuration 213
41.2.2 Bootloader selection 217
41.2.3 Bootloader version 219

42 STM32F446xx devices 220
42.1 Bootloader configuration 220
42.2 Bootloader selection 224
42.3 Bootloader version 225

43 STM32F469xx/479xx devices 226
43.1 Bootloader configuration 226
43.2 Bootloader selection 230
43.3 Bootloader version 232

44 STM32F72xxx/73xxx devices 233
44.1 Bootloader configuration 233
44.2 Bootloader selection 237

44.3 Bootloader version 238

45 STM32F74xxx/75xxx devices 239

45.1 Bootloader V7.x 239

45.1.1 Bootloader configuration 239

45.1.2 Bootloader selection 242

45.1.3 Bootloader version 242

45.2 Bootloader V9.x 243

45.2.1 Bootloader configuration 243

45.2.2 Bootloader selection 247

45.2.3 Bootloader version 248

46 STM32F76xxx/77xxx devices 249

46.1 Bootloader configuration 249

46.2 Bootloader selection 253

46.3 Bootloader version 255

47 STM32G03xxx/STM32G04xxx devices 256

47.1 Bootloader configuration 256

47.2 Bootloader selection 257

47.3 Bootloader version 258

48 STM32G07xxx/08xxx device bootloader 259

48.1 Bootloader configuration 259

48.2 Bootloader selection 262

48.3 Bootloader version 262

48.3.1 Compatibility break on boot sequence 264

49 STM32G0B0xx device bootloader 265

49.1 Bootloader configuration 265

49.2 Bootloader selection 268

49.3 Bootloader version 269

50 STM32G0B1xx/0C1xx device bootloader 270

50.1 Bootloader configuration 270

50.2 Bootloader selection 273

50.3 Bootloader version 274

51 STM32G05xxx/061xx devices 275

51.1 Bootloader configuration 275

51.2 Bootloader selection 277

51.3 Bootloader version 277

52 STM32G431xx/441xx devices 279

52.1 Bootloader configuration 279

52.2 Bootloader selection 282

52.3 Bootloader version 283

53 STM32G47xxx/48xxx devices 284

53.1 Bootloader configuration 284

53.2 Bootloader selection 287

53.3 Bootloader version 288

54 STM32G491xx/4A1xx devices 290

54.1 Bootloader configuration 290

54.2 Bootloader selection 293

54.3 Bootloader version 294

55 STM32G53xxx/54xxx devices 295

55.1 Bootloader configuration 295

55.2 BL_COM_CFG mapping 297

55.3 Bootloader selection 298

55.4 Bootloader version 299

56 STM32G554xx/564xx devices 300

56.1 Bootloader configuration 300

56.2 BL_COM_CFG mapping 302

56.3 Bootloader selection 304

56.4 Bootloader version 305

57 STM32H503xx devices 306

57.1 Bootloader configuration 306
57.2 Bootloader selection 310
57.3 Bootloader version 311

58 STM32H523xx/533xx devices 312
58.1 Bootloader configuration 312
58.2 Bootloader selection 317
58.3 Bootloader version 318

59 STM32H543xx/553xx devices 319
59.1 Bootloader configuration 319
59.2 Bootloader selection 323
59.3 Bootloader version 324

60 STM32H562xx/563xx/573xx devices 325
60.1 Bootloader configuration 325
60.2 Bootloader selection 329
60.3 Bootloader version 330

61 STM32H5Ex/5Fx devices 331
61.1 Bootloader configuration 331
61.2 Bootloader selection 334
61.3 Bootloader version 335

62 STM32H72xxx/73xxx devices 336
62.1 Bootloader configuration 336
62.2 Bootloader selection 340
62.3 Bootloader version 341

63 STM32H74xxx/75xxx devices 342
63.1 Bootloader configuration 342
63.2 Bootloader selection 346
63.3 Bootloader version 347

64 STM32H7A3xx/7B3xx/7B0xx devices 350

64.1 Bootloader configuration 350
64.2 Bootloader selection 355
64.3 Bootloader version 356

65 STM32H7Rxxx/7Sxxx devices 357
65.1 Bootloader configuration 357
65.2 Bootloader selection 362
65.3 Bootloader version 363
65.4 Jump to bootloader 363

66 STM32H7P4xx/P5xx devices 364
66.1 Bootloader configuration 364
66.2 Bootloader selection 368
66.3 Bootloader version 369

67 STM32L01xxx/02xxx devices 370
67.1 Bootloader configuration 370
67.2 Bootloader selection 372
67.3 Bootloader version 373

68 STM32L031xx/041xx devices 374
68.1 Bootloader configuration 374
68.2 Bootloader selection 376
68.3 Bootloader version 376

69 STM32L05xxx/06xxx devices 377
69.1 Bootloader configuration 377
69.2 Bootloader selection 379
69.3 Bootloader version 379

70 STM32L07xxx/08xxx devices 380
70.1 Bootloader V4.x 380
70.1.1 Bootloader configuration 380
70.1.2 Bootloader selection 382
70.1.3 Bootloader version 383

70.2 Bootloader V11.x 385
70.2.1 Bootloader configuration 385
70.2.2 Bootloader selection 387
70.2.3 Bootloader version 388

71 STM32L1xxx6(8/B)A devices 389
71.1 Bootloader configuration 389
71.2 Bootloader selection 390
71.3 Bootloader version 390

72 STM32L1xxx6(8/B) devices 391
72.1 Bootloader configuration 391
72.2 Bootloader selection 392
72.3 Bootloader version 392

73 STM32L1xxxC devices 393
73.1 Bootloader configuration 393
73.2 Bootloader selection 395
73.3 Bootloader version 396

74 STM32L1xxxD devices 397
74.1 Bootloader configuration 397
74.2 Bootloader selection 399
74.3 Bootloader version 400

75 STM32L1xxxE devices 401
75.1 Bootloader configuration 401
75.2 Bootloader selection 403
75.3 Bootloader version 404

76 STM32L412xx/422xx devices 405
76.1 Bootloader configuration 405
76.2 Bootloader selection 408
76.3 Bootloader version 410

77 STM32L43xxx/44xxx devices 411

77.1 Bootloader configuration 411
77.2 Bootloader selection 415
77.3 Bootloader version 417

78 STM32L45xxx/46xxx devices 419
78.1 Bootloader configuration 419
78.2 Bootloader selection 423
78.3 Bootloader version 425

79 STM32L47xxx/48xxx devices 426
79.1 Bootloader V10.x 426
79.1.1 Bootloader configuration 426
79.1.2 Bootloader selection 429
79.1.3 Bootloader version 431
79.2 Bootloader V9.x 432
79.2.1 Bootloader configuration 432
79.2.2 Bootloader selection 435
79.2.3 Bootloader version 437

80 STM32L496xx/4A6xx devices 438
80.1 Bootloader configuration 438
80.2 Bootloader selection 442
80.3 Bootloader version 444

81 STM32L4P5xx/4Q5xx devices 445
81.1 Bootloader configuration 445
81.2 Bootloader selection 449
81.3 Bootloader version 451

82 STM32L4Rxxx/4Sxxx devices 452
82.1 Bootloader configuration 452
82.2 Bootloader selection 456
82.3 Bootloader version 458

83 STM32L552xx/62xx devices 459
83.1 Bootloader configuration 459

83.2 Bootloader selection 463
83.3 Bootloader version 464

84 STM32WB10xx/15xx devices 465
84.1 Bootloader configuration 465
84.2 Bootloader selection 467
84.3 Bootloader version 468

85 STM32WB30xx/35xx/50xx/55xx devices 469
85.1 Bootloader configuration 469
85.2 Bootloader selection 472
85.3 Bootloader version 473

86 STM32WBA5xxx devices 474
86.1 Bootloader configuration 474
86.2 Bootloader selection 476
86.3 Bootloader version 477

87 STM32WBA2xxx devices 478
87.1 Bootloader configuration 478
87.2 Bootloader selection 482
87.3 Bootloader version 483

88 STM32WBA62xx/63xx/64xx/65xx devices 484
88.1 Bootloader configuration 484
88.2 Bootloader selection 487
88.3 Bootloader version 487

89 STM32WB05xx devices 488
89.1 Bootloader configuration 488
89.2 Bootloader selection 489
89.3 Bootloader version 489

90 STM32WB06xx/07xx devices 490
90.1 Bootloader configuration 490

90.2 Bootloader selection 491
90.3 Bootloader version 491

91 STM32WB09xx devices 492
91.1 Bootloader configuration 492
91.2 Bootloader selection 493
91.3 Bootloader version 493

92 STM32WL3xxx devices 494
92.1 Bootloader configuration 494
92.2 Bootloader selection 495
92.3 Bootloader version 495

93 STM32WLE5xx/55xx devices 496
93.1 Bootloader configuration 496
93.2 Bootloader selection 498
93.3 Bootloader version 498

94 STM32U031xx devices 499
94.1 Bootloader configuration 499
94.2 Bootloader selection 502
94.3 Bootloader version 503

95 STM32U073xx/83xx devices 504
95.1 Bootloader configuration 504
95.2 Bootloader selection 507
95.3 Bootloader version 508

96 STM32U375xx/85xx devices 509
96.1 Bootloader configuration 509
96.2 SPI1 pinout on WLCSP68-G 512
96.3 Boot model 512
96.4 Bootloader selection 514
96.5 Bootloader version 515

97 STM32U3B5xx/3C5xx devices 516
97.1 Bootloader configuration 516
97.2 Bootloader selection 521
97.3 Bootloader version 522

98 STM32U535xx/545xx devices 523
98.1 Bootloader configuration 523
98.2 Bootloader selection 527
98.3 Bootloader version 528

99 STM32U575xx/85xx devices 529
99.1 Bootloader configuration 529
99.2 Bootloader selection 533
99.3 Bootloader version 534

100 STM32U595xx/99xx/A5xx/A9xx devices 535
100.1 Bootloader configuration 535
100.2 Bootloader selection 539
100.3 Bootloader version 540

101 STM32U5F7xx/F9xx/G7xx/G9xx devices 541
101.1 Bootloader configuration 541
101.2 Bootloader selection 545
101.3 Bootloader version 546

102 Device-dependent bootloader parameters 547

103 Bootloader timings 554
103.1 Bootloader startup timing 554
103.2 USART connection timing 557
103.3 USB connection timing 561
103.4 I2C connection timing 563
103.5 SPI connection timing 567

Appendix A Example of ExitSecureMemory v1.0 function 568

Appendix B Example of ExitSecureMemory v1.1 function 570

Appendix C ExitSecureMemory v2.0 function 573

104 Revision history 574

List of tables

Table 1. Applicable products . . . 1
Table 2. Bootloader activation patterns . . . 35
Table 3. Embedded bootloaders . . . 40
Table 4. STM32 F2, F4, and F7 voltage range configuration using bootloader . . . 51
Table 5. Supported memory area by Write, Read, Erase, and Go commands . . . 52
Table 6. Jitter software calculation on bootloader USART detection . . . 53
Table 7. Flash memory alignment constraints . . . 54
Table 8. ExitSecureMemory entry address . . . 58
Table 9. EXITHDP APIs . . . 58
Table 10. BL and boot by product series . . . 61
Table 11. STM32C011xx configuration in system memory boot mode . . . 63
Table 12. STM32C011xx bootloader versions . . . 64
Table 13. STM32C031xx configuration in system memory boot mode . . . 65
Table 14. STM32C031xx bootloader versions . . . 66
Table 15. STM32C051xx configuration in system memory boot mode . . . 67
Table 16. STM32C051xx bootloader versions . . . 71
Table 17. STM32C071xx configuration in system memory boot mode . . . 72
Table 18. STM32C071xx bootloader versions . . . 75
Table 19. STM32C091xx/92xx configuration in system memory boot mode . . . 76
Table 20. STM32C091xx/92xx bootloader versions . . . 80
Table 21. STM32C531xx/532xx/542xx configuration in system memory boot mode . . . 81
Table 22. STM32C531xx/532xx/542xx special commands . . . 84
Table 23. STM32C531xx/532xx/542xx bootloader versions . . . 85
Table 24. STM32C55xxx/562xx configuration in system memory boot mode . . . 86
Table 25. STM32C55xxx/562xx special commands . . . 88
Table 26. STM32C55xxx/562xx bootloader versions . . . 90
Table 27. STM32C5A3xx/59xxx configuration in system memory boot mode . . . 91
Table 28. STM32C5A3xx/59xxx special commands . . . 93
Table 29. STM32C55xxx/562xx bootloader versions . . . 95
Table 30. STM32F03xx4/6 configuration in system memory boot mode . . . 96
Table 31. STM32F03xx4/6 bootloader versions . . . 97
Table 32. STM32F030xC configuration in system memory boot mode . . . 98
Table 33. STM32F030xC bootloader versions . . . 99
Table 34. STM32F05xxx and STM32F030x8 devices configuration in system memory boot mode 100
Table 35. STM32F05xxx and STM32F030x8 devices bootloader versions . . . 101
Table 36. STM32F04xxx configuration in system memory boot mode . . . 102
Table 37. STM32F04xxx bootloader versions . . . 105
Table 38. STM32F070x6 configuration in system memory boot mode . . . 106
Table 39. STM32F070x6 bootloader versions . . . 109
Table 40. STM32F070xB configuration in system memory boot mode . . . 110
Table 41. STM32F070xB bootloader versions . . . 113
Table 42. STM32F071xx/072xx configuration in system memory boot mode . . . 114
Table 43. STM32F071xx/072xx bootloader versions . . . 117
Table 44. STM32F09xxx configuration in system memory boot mode . . . 118
Table 45. STM32F09xxx bootloader versions . . . 119
Table 46. STM32F10xxx configuration in system memory boot mode . . . 120
Table 47. STM32F10xxx bootloader versions . . . 121
Table 48. STM32F105xx/107xx configuration in system memory boot mode . . . 123

Table 49. STM32F105xx/107xx bootloader versions . . . 126
Table 50. STM32F10xxx XL-density configuration in system memory boot mode . . . 129
Table 51. STM32F10xxx XL-density bootloader versions . . . 130
Table 52. STM32F2xxxx configuration in system memory boot mode . . . 131
Table 53. STM32F2xxxx bootloader V2.x versions . . . 133
Table 54. STM32F2xxxx configuration in system memory boot mode . . . 134
Table 55. STM32F2xxxx bootloader V3.x versions . . . 137
Table 56. STM32F301xx/302x4(6/8) configuration in system memory boot mode . . . 138
Table 57. STM32F301xx/302x4(6/8) bootloader versions . . . 141
Table 58. STM32F302xB(C)/303xB(C) configuration in system memory boot mode . . . 142
Table 59. STM32F302xB(C)/303xB(C) bootloader versions . . . 145
Table 60. STM32F302xD(E)/303xD(E) configuration in system memory boot mode . . . 146
Table 61. STM32F302xD(E)/303xD(E) bootloader versions . . . 149
Table 62. STM32F303x4(6/8)/334xx/328xx configuration in system memory boot mode . . . 150
Table 63. STM32F303x4(6/8)/334xx/328xx bootloader versions . . . 151
Table 64. STM32F318xx configuration in system memory boot mode . . . 152
Table 65. STM32F318xx bootloader versions . . . 154
Table 66. STM32F358xx configuration in system memory boot mode . . . 155
Table 67. STM32F358xx bootloader versions . . . 156
Table 68. STM32F373xx configuration in system memory boot mode . . . 157
Table 69. STM32F373xx bootloader versions . . . 160
Table 70. STM32F378xx configuration in system memory boot mode . . . 161
Table 71. STM32F378xx bootloader versions . . . 162
Table 72. STM32F398xx configuration in system memory boot mode . . . 163
Table 73. STM32F398xx bootloader versions . . . 165
Table 74. STM32F40xxx/41xxx configuration in system memory boot mode . . . 166
Table 75. STM32F40xxx/41xxx bootloader V3.x versions . . . 169
Table 76. STM32F40xxx/41xxx configuration in system memory boot mode . . . 170
Table 77. STM32F40xxx/41xxx bootloader V9.x versions . . . 174
Table 78. STM32F401xB(C) configuration in system memory boot mode . . . 175
Table 79. STM32F401xB(C) bootloader versions . . . 179
Table 80. STM32F401xD(E) configuration in system memory boot mode . . . 180
Table 81. STM32F401xD(E) bootloader versions . . . 184
Table 82. STM32F410xx configuration in system memory boot mode . . . 185
Table 83. STM32F410xx bootloader V11.x versions . . . 189
Table 84. STM32F411xx configuration in system memory boot mode . . . 190
Table 85. STM32F411xx bootloader versions . . . 194
Table 86. STM32F412xx configuration in system memory boot mode . . . 195
Table 87. STM32F412xx bootloader V9.x versions . . . 200
Table 88. STM32F413xx/423xx configuration in system memory boot mode . . . 201
Table 89. STM32F413xx/423xx bootloader V9.x versions . . . 206
Table 90. STM32F42xxx/43xxx configuration in system memory boot mode . . . 207
Table 91. STM32F42xxx/43xxx bootloader V7.x versions . . . 212
Table 92. STM32F42xxx/43xxx configuration in system memory boot mode . . . 213
Table 93. STM32F42xxx/43xxx bootloader V9.x versions . . . 219
Table 94. STM32F446xx configuration in system memory boot mode . . . 220
Table 95. STM32F446xx bootloader V9.x versions . . . 225
Table 96. STM32F469xx/479xx configuration in system memory boot mode . . . 226
Table 97. STM32F469xx/479xx bootloader V9.x versions . . . 232
Table 98. STM32F72xxx/73xxx configuration in system memory boot mode . . . 233
Table 99. STM32F72xxx/73xxx bootloader V9.x versions . . . 238
Table 100. STM32F74xxx/75xxx configuration in system memory boot mode . . . 239

Table 101. STM32F74xxx/75xxx bootloader V7.x versions . . . 242
Table 102. STM32F74xxx/75xxx configuration in system memory boot mode. . . . 243
Table 103. STM32F74xxx/75xxx bootloader V9.x versions . . . 248
Table 104. STM32F76xxx/77xxx configuration in system memory boot mode. . . . 249
Table 105. STM32F76xxx/77xxx bootloader V9.x versions . . . 255
Table 106. STM32G03xxx/G04xxx configuration in system memory boot mode . . . 256
Table 107. STM32G03xxx/04xxx bootloader versions . . . 258
Table 108. STM32G07xxx/8xxx configuration in system memory boot mode . . . 259
Table 109. STM32G07xxx/08xxx bootloader versions . . . 262
Table 110. STM32G0B0xx configuration in system memory boot mode . . . 265
Table 111. STM32G0B0xx bootloader versions . . . 269
Table 112. STM32G0B1xx/0C1xx configuration in system memory boot mode. . . . 270
Table 113. STM32G0B1xx/0C1xx bootloader versions . . . 274
Table 114. STM32G05xxx/061xx configuration in system memory boot mode . . . 275
Table 115. STM32G05xxx/061xx bootloader versions . . . 278
Table 116. STM32G431xx/441xx configuration in system memory boot mode . . . 279
Table 117. STM32G431xx/441xx bootloader version. . . . 283
Table 118. STM32G47xxx/48xxx configuration in system memory boot mode . . . 284
Table 119. STM32G47xxx/48xxx bootloader version . . . 288
Table 120. STM32G491xx/4A1xx configuration in system memory boot mode . . . 290
Table 121. STM32G491xx/4A1xx bootloader version . . . 294
Table 122. STM32G53xxx/54xxx configuration in system memory boot mode . . . 295
Table 123. STM32G53xxx/54xxx special commands . . . 297
Table 124. STM32G53xxx/54xxx bootloader version . . . 299
Table 125. STM32G554xx/564xxconfiguration in system memory boot mode. . . . 300
Table 126. STM32G554xx/564xx special commands . . . 303
Table 127. STM32G554xx/564xx bootloader version. . . . 305
Table 128. STM32H503xx configuration in system memory boot mode . . . 306
Table 129. STM32H503xx special commands . . . 309
Table 130. STM32H503xx bootloader version . . . 311
Table 131. STM32H523xx/533xx configuration in system memory boot mode . . . 312
Table 132. STM32H523xx/533xx special commands. . . . 316
Table 133. STM32H523xx/533xx bootloader version. . . . 318
Table 134. STM32H543xx/553xx configuration in system memory boot mode . . . 319
Table 135. STM32H543xx/553xx special commands. . . . 322
Table 136. STM32H543xx/553xx bootloader version. . . . 324
Table 137. STM32H562xx/563xx/573xx configuration in system memory boot mode . . . 325
Table 138. STM32H562xx/563xx/573xx special commands . . . 328
Table 139. STM32H562xx/563xx/573xx bootloader version . . . 330
Table 140. STM32H5Ex/5Fx configuration in system memory boot mode. . . . 331
Table 141. STM32H5Ex/5Fx special commands . . . 334
Table 142. STM32H5Ex/5Fx bootloader versions . . . 335
Table 143. STM32H72xxx/73xxx configuration in system memory boot mode . . . 336
Table 144. STM32H72xxx/73xxx bootloader version . . . 341
Table 145. STM32H74xxx/75xxx configuration in system memory boot mode . . . 342
Table 146. STM32H74xxx/75xxx bootloader version . . . 347
Table 147. STM32H7A3xx/7B3xx/7B0xx configuration in system memory boot mode . . . 350
Table 148. STM32H7A3xx/7B3xx/7B0xx bootloader version . . . 356
Table 149. STM32H7Rxxx/7Sxxx configuration in system memory boot mode . . . 357
Table 150. STM32H7Rxxx/7Sxxx special commands . . . 361
Table 151. STM32H7Rxxx/7Sxxx bootloader version . . . 363
Table 152. STM32H7P4xx/P5xx configuration in system memory boot mode . . . 364

Table 153. STM32H7P4xx/P5xx special commands . . . 367
Table 154. STM32H7P4xx/P5xx bootloader version . . . 369
Table 155. STM32L01xxx/02xxx configuration in system memory boot mode . . . 370
Table 156. STM32L01xxx/02xxx bootloader versions . . . 373
Table 157. STM32L031xx/041xx configuration in system memory boot mode . . . 374
Table 158. STM32L031xx/041xx bootloader versions . . . 376
Table 159. STM32L05xxx/06xxx configuration in system memory boot mode . . . 377
Table 160. STM32L05xxx/06xxx bootloader versions . . . 379
Table 161. STM32L07xxx/08xxx configuration in system memory boot mode . . . 380
Table 162. STM32L07xxx/08xxx bootloader versions . . . 384
Table 163. STM32L07xxx/08xxx configuration in system memory boot mode . . . 385
Table 164. STM32L07xxx/08xxx bootloader V11.x versions . . . 388
Table 165. STM32L1xxx6(8/B)A configuration in system memory boot mode . . . 389
Table 166. STM32L1xxx6(8/B)A bootloader versions . . . 390
Table 167. STM32L1xxx6(8/B) configuration in system memory boot mode . . . 391
Table 168. STM32L1xxx6(8/B) bootloader versions . . . 392
Table 169. STM32L1xxxC configuration in system memory boot mode . . . 393
Table 170. STM32L1xxxC bootloader versions . . . 396
Table 171. STM32L1xxxD configuration in system memory boot mode . . . 397
Table 172. STM32L1xxxD bootloader versions . . . 400
Table 173. STM32L1xxxE configuration in system memory boot mode . . . 401
Table 174. STM32L1xxxE bootloader versions . . . 404
Table 175. STM32L412xx/422xx configuration in system memory boot mode . . . 405
Table 176. STM32L412xx/422xx bootloader versions . . . 410
Table 177. STM32L43xxx/44xxx configuration in system memory boot mode . . . 411
Table 178. STM32L43xxx/44xxx bootloader versions . . . 417
Table 179. STM32L45xxx/46xxx configuration in system memory boot mode . . . 419
Table 180. STM32L45xxx/46xxx bootloader versions . . . 425
Table 181. STM32L47xxx/48xxx configuration in system memory boot mode . . . 426
Table 182. STM32L47xxx/48xxx bootloader V10.x versions . . . 431
Table 183. STM32L47xxx/48xxx configuration in system memory boot mode . . . 432
Table 184. STM32L47xxx/48xxx bootloader V9.x versions . . . 437
Table 185. STM32L496xx/4A6xx configuration in system memory boot mode . . . 438
Table 186. STM32L496xx/4A6xx bootloader version . . . 444
Table 187. STM32L4P5xx/4Q5xx configuration in system memory boot mode . . . 445
Table 188. STM32L4P5xx/4Q5xx bootloader versions . . . 451
Table 189. STM32L4Rxxx/4Sxxx configuration in system memory boot mode . . . 452
Table 190. STM32L4Rxx/4Sxx bootloader versions . . . 458
Table 191. STM32L552xx/62xx configuration in system memory boot mode . . . 459
Table 192. STM32L552xx/62xx special commands . . . 462
Table 193. STM32L552xx/62xx bootloader versions . . . 464
Table 194. STM32WB10xx/15xx configuration in system memory boot mode . . . 465
Table 195. STM32WB10xx/15xx bootloader versions . . . 468
Table 196. STM32WB30xx/35xx/50xx/55xx configuration in system memory boot mode . . . 469
Table 197. STM32WB30xx/35xx/50xx/55xx bootloader versions . . . 473
Table 198. STM32WBA5xxx configuration in system memory boot mode . . . 474
Table 199. STM32WBA5xxx special commands . . . 475
Table 200. STM32WBA5xxx bootloader versions . . . 477
Table 201. STM32WBA2xxx configuration in system memory boot mode . . . 478
Table 202. STM32WBA2xxx special commands . . . 481
Table 203. STM32WBA2xxx bootloader versions . . . 483
Table 204. STM32WBA62xx/63xx/64xx/65xx configuration in system memory boot mode . . . 484

Table 205. STM32WBA62xx/63xx/64xx/65xx special commands . . . 486
Table 206. STM32WBA62xx/63xx/64xx/65xx bootloader versions . . . 487
Table 207. STM32WB05xx configuration in system memory boot mode . . . 488
Table 208. STM32WB05xx bootloader versions . . . 489
Table 209. STM32WB06xx/07xx configuration in system memory boot mode . . . 490
Table 210. STM32WB06xx/07xx bootloader versions . . . 491
Table 211. STM32WB09xx configuration in system memory boot mode . . . 492
Table 212. STM32WB09xx bootloader versions . . . 493
Table 213. STM32WL3xxx configuration in system memory boot mode . . . 494
Table 214. STM32WL3xxx bootloader versions . . . 495
Table 215. STM32WLE5xx/55xx configuration in system memory boot mode . . . 496
Table 216. STM32WLE5xx/55xx bootloader versions . . . 498
Table 217. STM32U031xx configuration in system memory boot mode . . . 499
Table 218. STM32U031xx bootloader versions . . . 503
Table 219. STM32U073xx/83xx configuration in system memory boot mode . . . 504
Table 220. STM32U073xx/83xx bootloader versions . . . 508
Table 221. STM32U375xx/85xx configuration in system memory boot mode . . . 509
Table 222. STM32U375xx/385xx special commands . . . 513
Table 223. STM32U375xx/85xx bootloader versions . . . 515
Table 224. STM32U3B5xx/3C5xx configuration in system memory boot mode . . . 516
Table 225. STM32U3B5xx/3C5xx special commands . . . 520
Table 226. STM32U3B5xx/3C5xx bootloader versions . . . 522
Table 227. STM32U535xx/545xx configuration in system memory boot mode . . . 523
Table 228. STM32U535xx/545xx special commands . . . 526
Table 229. STM32U535xx/545xx bootloader versions . . . 528
Table 230. STM32U575xx/85xx configuration in system memory boot mode . . . 529
Table 231. STM32U575xx/585xx special commands . . . 532
Table 232. STM32U575xx/85xx bootloader versions . . . 534
Table 233. STM32U595xx/99xx/A5xx/A9xx configuration in system memory boot mode . . . 535
Table 234. STM32U595xx/99xx/A5xx/A9xx special commands . . . 538
Table 235. STM32U595xx/99xx/A5xx/A9xx bootloader versions . . . 540
Table 236. STM32U5F7xx/F9xx/G7xx/G9xx configuration in system memory boot mode . . . 541
Table 237. STM32U5F7xx/F9xx/G7xx/G9xx special commands . . . 544
Table 238. STM32U5F7xx/F9xx/G7xx/G9xx bootloader versions . . . 546
Table 239. Bootloader device-dependent parameters . . . 547
Table 240. Bootloader startup timings (ms) . . . 554
Table 241. USART bootloader minimum timings (ms) . . . 558
Table 242. USB bootloader minimum timings (ms) . . . 562
Table 243. I2C bootloader minimum timings (ms) . . . 564
Table 244. SPI bootloader minimum timings (ms) for STM32 devices . . . 567
Table 245. Document revision history . . . 574

List of figures

Figure 1. USART connection . . . 48
Figure 2. USB connection . . . 49
Figure 3. I2C connection . . . 49
Figure 4. SPI connection . . . 50
Figure 5. CAN connection . . . 50
Figure 6. ExitSecureMemory (v1.0 or v1.1) function usage . . . 56
Figure 7. Access to securable memory (v1.0 or V1.1) area from the bootloader . . . 57
Figure 8. Defining an MPU region . . . 57
Figure 9. BL_V1 (left) and BL_V2 (right) models . . . 60
Figure 10. Boot_V1 (left) and Boot_V2 (right) . . . 61
Figure 11. Boot_V3_1 . . . 61
Figure 12. Boot_V3_2 . . . 62
Figure 13. Bootloader V5.x selection for STM32C011xx devices . . . 64
Figure 14. Bootloader V5.x selection for STM32C031xx devices . . . 66
Figure 15. Bootloader V11.0 selection for STM32C051xx devices . . . 70
Figure 16. Bootloader V13.1 selection for STM32C071xx devices . . . 74
Figure 17. Bootloader V18.1 selection for STM32C091xx/92xx devices . . . 79
Figure 18. Bootloader V16.x selection for STM32C531xx/532xx/542xx devices . . . 85
Figure 19. Bootloader V16.x selection for STM32C55xxx/562xx devices . . . 89
Figure 20. Bootloader V16.x selection for STM32C55xxx/562xx devices . . . 94
Figure 21. Bootloader selection for STM32F03xx4/6 devices . . . 97
Figure 22. Bootloader selection for STM32F030xC . . . 99
Figure 23. Bootloader selection for STM32F05xxx and STM32F030x8 devices . . . 101
Figure 24. Bootloader selection for STM32F04xxx . . . 104
Figure 25. Bootloader selection for STM32F070x6 . . . 108
Figure 26. Bootloader selection for STM32F070xB . . . 112
Figure 27. Bootloader selection for STM32F071xx/072xx . . . 116
Figure 28. Bootloader selection for STM32F09xxx . . . 119
Figure 29. Bootloader selection for STM32F10xxx . . . 121
Figure 30. Bootloader selection for STM32F105xx/107xx devices . . . 125
Figure 31. Bootloader selection for STM32F10xxx XL-density devices . . . 130
Figure 32. Bootloader V2.x selection for STM32F2xxxx devices . . . 132
Figure 33. Bootloader V3.x selection for STM32F2xxxx devices . . . 136
Figure 34. Bootloader selection for STM32F301xx/302x4(6/8) . . . 140
Figure 35. Bootloader selection for STM32F302xB(C)/303xB(C) devices . . . 144
Figure 36. Bootloader selection for STM32F302xD(E)/303xD(E) . . . 148
Figure 37. Bootloader selection for STM32F303x4(6/8)/334xx/328xx . . . 151
Figure 38. Bootloader selection for STM32F318xx . . . 153
Figure 39. Bootloader selection for STM32F358xx devices . . . 156
Figure 40. Bootloader selection for STM32F373xx devices . . . 159
Figure 41. Bootloader selection for STM32F378xx devices . . . 162
Figure 42. Bootloader selection for STM32F398xx . . . 164
Figure 43. Bootloader V3.x selection for STM32F40xxx/41xxx devices . . . 168
Figure 44. Bootloader V9.x selection for STM32F40xxx/41xxx . . . 173
Figure 45. Bootloader selection for STM32F401xB(C) . . . 178
Figure 46. Bootloader selection for STM32F401xD(E) . . . 183
Figure 47. Bootloader V11.x selection for STM32F410xx . . . 188
Figure 48. Bootloader selection for STM32F411xx . . . 193

Figure 49. Bootloader V9.x selection for STM32F412xx . . . 199
Figure 50. Bootloader V9.x selection for STM32F413xx/423xx . . . 205
Figure 51. Dual bank boot implementation for STM32F42xxx/43xxx Bootloader V7.x . . . 210
Figure 52. Bootloader V7.x selection for STM32F42xxx/43xxx . . . 211
Figure 53. Dual bank boot implementation for STM32F42xxx/43xxx bootloader V9.x . . . 217
Figure 54. Bootloader V9.x selection for STM32F42xxx/43xxx . . . 218
Figure 55. Bootloader V9.x selection for STM32F446xx . . . 224
Figure 56. Dual bank boot implementation for STM32F469xx/479xx Bootloader V9.x . . . 230
Figure 57. Bootloader V9.x selection for STM32F469xx/479xx . . . 231
Figure 58. Bootloader V9.x selection for STM32F72xxx/73xxx . . . 237
Figure 59. Bootloader V7.x selection for STM32F74xxx/75xxx . . . 242
Figure 60. Bootloader V9.x selection for STM32F74xxx/75xxx . . . 247
Figure 61. Dual bank boot implementation for STM32F76xxx/77xxx Bootloader V9.x . . . 253
Figure 62. Bootloader V9.x selection for STM32F76xxx/77xxx . . . 254
Figure 63. Bootloader V5.x selection for STM32G03xxx/G04xxx . . . 257
Figure 64. Bootloader V11.0 selection for STM32G07xxx/G08xxx . . . 262
Figure 65. Bootloader selection for STM32G0B0xx . . . 268
Figure 66. Bootloader selection for STM32G0B1xx/0C1xx . . . 273
Figure 67. Bootloader selection for STM32G05xxx/061xx . . . 277
Figure 68. Bootloader selection for STM32G431xx/441xx . . . 282
Figure 69. Bootloader selection for STM32G47xxx/48xxx . . . 287
Figure 70. Dual bank boot implementation for STM32G47xxx/48xxx bootloader V13.x . . . 288
Figure 71. Bootloader selection for STM32G491xx/4A1xx . . . 293
Figure 72. Bootloader V18.x selection for STM32G53xxx/54xxx . . . 298
Figure 73. Bootloader V9.x selection for STM32G554xx/564xx . . . 304
Figure 74. Bootloader V14 selection for STM32H503xx . . . 310
Figure 75. Bootloader V14 selection for STM32H523xx/533xx . . . 317
Figure 76. Bootloader V14 selection for STM32H543xx/553xx . . . 323
Figure 77. Bootloader V14 selection for STM32H562xx/563xx/573xx . . . 329
Figure 78. Bootloader V15.x selection for STM32H5Ex/5Fx devices . . . 335
Figure 79. Bootloader V9.0 selection for STM32H72xxx/73xxx . . . 340
Figure 80. Bootloader V9.x selection for STM32H74xxx/75xxx . . . 346
Figure 81. Bootloader V9.x selection for STM32H7A3xx/7B3xx/7B0xx . . . 355
Figure 82. Bootloader V14.x selection for STM32H7Rxxx/7Sxxx . . . 362
Figure 83. Bootloader V20.x selection for STM32H7P4xx/P5xx . . . 368
Figure 84. Bootloader selection for STM32L01xxx/02xxx . . . 372
Figure 85. Bootloader selection for STM32L031xx/041xx . . . 376
Figure 86. Bootloader selection for STM32L05xxx/06xxx . . . 379
Figure 87. Dual bank boot implementation for STM32L07xxx/08xxx bootloader V4.x . . . 382
Figure 88. Bootloader V4.x selection for STM32L07xxx/08xxx . . . 383
Figure 89. Dual bank boot implementation for STM32L07xxx/08xxx bootloader V11.x . . . 387
Figure 90. Bootloader V11.x selection for STM32L07xxx/08xxx . . . 388
Figure 91. Bootloader selection for STM32L1xxx6(8/B)A devices . . . 390
Figure 92. Bootloader selection for STM32L1xxx6(8/B) devices . . . 392
Figure 93. Bootloader selection for STM32L1xxxC devices . . . 395
Figure 94. Bootloader selection for STM32L1xxxD devices . . . 399
Figure 95. Bootloader selection for STM32L1xxxE devices . . . 403
Figure 96. Dual bank boot Implementation for STM32L412xx/422xx bootloader V9.x . . . 408
Figure 97. Bootloader V13.x selection for STM32L412xx/422xx . . . 409
Figure 98. Dual bank boot Implementation for STM32L3x2xx/44xxx bootloader V9.x . . . 415
Figure 99. Bootloader V9.x selection for STM32L43xxx/44xxx . . . 416
Figure 100. Dual bank boot implementation for STM32L45xxx/46xxx bootloader V9.x . . . 423

Figure 101. Bootloader V9.x selection for STM32L45xxx/46xxx . . . 424
Figure 102. Dual bank boot implementation for STM32L47xxx/48xxx bootloader V10.x. . . . 429
Figure 103. Bootloader V10.x selection for STM32L47xxx/48xxx . . . 430
Figure 104. Dual bank boot implementation for STM32L47xxx/48xxx bootloader V9.x. . . . 435
Figure 105. Bootloader V9.x selection for STM32L47xxx/48xxx . . . 436
Figure 106. Dual bank boot Implementation for STM32L496xx/4A6xx bootloader V9.x . . . 442
Figure 107. Bootloader V9.x selection for STM32L496xx/4A6xx. . . . 443
Figure 108. Dual bank boot implementation for STM32L4P5xx/4Q5xx bootloader V9.x. . . . 449
Figure 109. Bootloader V9.x selection for STM32L4P5xx/4Q5xx . . . 450
Figure 110. Dual bank boot implementation for STM32L4Rxxx/STM32L4Sxxx bootloader V9.x . . . 456
Figure 111. Bootloader V9.x selection for STM32L4Rxx/4Sxx . . . 457
Figure 112. Bootloader V9.x selection for STM32L552xx/62xx . . . 463
Figure 113. Bootloader V11.x selection for STM32WB10xx/15xx . . . 467
Figure 114. Bootloader V13.0 selection for STM32WB30xx/35xx/50xx/55xx . . . 472
Figure 115. Bootloader V11.x selection for STM32WBA5xxx . . . 476
Figure 116. Bootloader V13.x selection for STM32WBA2xxx . . . 482
Figure 117. Bootloader V13.2 selection for STM32WBA62xx/63xx/64xx/65xx . . . 487
Figure 118. Bootloader V2.x selection for STM32WB05xx . . . 489
Figure 119. Bootloader V4.x selection for STM32WB06xx/07xx . . . 491
Figure 120. Bootloader V1.x selection for STM32WB09xx . . . 493
Figure 121. Bootloader V12.x selection for STM32WL3xxx . . . 495
Figure 122. Bootloader V12.x selection for STM32WLE5xx/55xx . . . 498
Figure 123. Bootloader V11.x selection for STM32U031xx . . . 502
Figure 124. Bootloader V13.x selection for STM32U073xx/83xx . . . 507
Figure 125. Bootloader V14.2 selection for STM32U375xx/85xx . . . 514
Figure 126. Bootloader V14.0 selection for STM32U3B5xx/3C5xx . . . 521
Figure 127. Bootloader V9.x selection for STM32U535xx/545xx . . . 527
Figure 128. Bootloader V9.x selection for STM32U575xx/85xx . . . 533
Figure 129. Bootloader V9.x selection for STM32U595xx/99xx/A5xx/A9xx. . . . 539
Figure 130. Bootloader V9.x selection for STM32U5F7xx/F9xx/G7xx/G9xx . . . 545
Figure 131. Bootloader startup timing description . . . 554
Figure 132. USART connection timing description . . . 558
Figure 133. USB connection timing description . . . 561
Figure 134. I2C connection timing description . . . 564
Figure 135. SPI connection timing description . . . 567

1 General information

This document applies to Arm®(a)-based devices.

2 Related documents

For each supported product refer to the following documents, available on *www.st.com*:

- Datasheet or databrief
- Reference manual
- Application notes
  - AN3154: How to use CAN protocol in bootloader on STM32 MCUs
  - AN3155: How to use USART protocol in bootloader on STM32 MCUs
  - AN3156: How to use USB DFU protocol in bootloader on STM32 MCUs
  - AN4221: How to use I2C protocol in bootloader on STM32 MCUs
  - AN4286: How to use SPI protocol in bootloader on STM32 MCUs
  - AN5405: How to use FDCAN protocol in bootloader on STM32 MCUs
  - AN5927: How to use I3C protocol in bootloader on STM32 MCUs

a. Arm is a registered trademark of Arm Limited (or its subsidiaries or affiliates) in the US and/or elsewhere. The Arm word and logo are trademarks of Arm Limited (or its subsidiaries) in the US and/or elsewhere. All rights reserved

3 Glossary

C0 series:

STM32C011xx indicates STM32C011xx devices

STM32C031xx indicates STM32C031xx devices

STM32C051xx indicates STM32C051xx devices

STM32C071xx indicates STM32C071xx devices

STM32C091xx/92xx indicates STM32C091xx and STM32C092xx devices

C5 series:

STM32C5A3xx indicates STM32C5A3xx devices.

STM32C591xx/593xx indicates STM32C591xx and STM32C593xx devices.

STM32C55xxx indicates STM32C551xx and STM32C552xx devices.

STM32C562xx indicates STM32C562xx devices.

STM32C531xx/532xx indicates STM32C531xx and STM32C532xx devices.

STM32C542xx indicates STM32C542xx devices.

F0 series:

STM32F03xxx indicates STM32F030x4, STM32F030x6, STM32F038x6, STM32F030xC, STM32F031x4, and STM32F031x6 devices

STM32F04xxx indicates STM32F042x4 and STM32F042x6 devices

STM32F05xxx and STM32F030x8 devices indicates STM32F051x4, STM32F051x6, STM32F051x8, STM32F058x8, and STM32F030x8 devices

STM32F07xxx indicates STM32F070x6, STM32F070xB, STM32F071xB, STM32F072x8, and STM32F072xB devices

STM32F09xxx indicates STM32F091xx and STM32F098xx devices

F1 series:

STM32F10xxx indicates Low-density, Medium-density, High-density, Low-density value line, Medium-density value line, and High-density value line devices:

Low-density devices are STM32F101xx, STM32F102xx, and STM32F103xx microcontrollers, where the flash memory density ranges between 16 and 32 Kbytes.

Medium-density devices are STM32F101xx, STM32F102xx, and STM32F103xx microcontrollers, where the flash memory density ranges between 64 and 128 Kbytes.

High-density devices are STM32F101xx and STM32F103xx microcontrollers, where the flash memory density ranges between 256 and 512 Kbytes.

Low-density value line devices are STM32F100xx microcontrollers, where the flash memory density ranges between 16 and 32 Kbytes.

Medium-density value line devices are STM32F100xx microcontrollers, where the flash memory density ranges between 64 and 128 Kbytes.

High-density value line devices are STM32F100xx microcontrollers, where the flash memory density ranges between 256 and 512 Kbytes.

STM32F105xx/107xx indicates STM32F105xx and STM32F107xx devices

STM32F10xxx XL-density indicates STM32F101xx and STM32F103xx devices, where the flash memory density ranges between 768 Kbytes and 1 Mbyte.

F2 series:

STM32F2xxxx indicates STM32F215xx, STM32F205xx, STM32F207xx, and SMT32F217xx devices

F3 series:

STM32F301xx/302x4(6/8) indicates STM32F301x4, STM32F301x6, STM32F301x8, STM32F302x4, STM32F302x6, and STM32F302x8 devices

STM32F302xB(C)/303xB(C) indicates STM32F302xB, STM32F302xC, STM32F303xB and STM32F303xC devices

STM32F302xD(E)/303xD(E) indicates STM32F302xD, STM32F302xE, STM32F303xD, and STM32F303xE devices

STM32F303x4(6/8)/334xx/328xx indicates STM32F303x4, STM32F303x6, STM32F303x8, STM32F334x4, STM32F334x6, STM32F334x8, and STM32F328x8 devices

STM32F318xx indicates STM32F318x8 devices

STM32F358xx indicates STM32F358xC devices

STM32F373xx indicates STM32F373x8, STM32F373xB and STM32F373xC devices

STM32F378xx indicates STM32F378xC devices

STM32F398xx indicates STM32F398xE devices

F4 series:

STM32F40xxx/41xxx indicates STM32F405xx, STM32F407xx, STM32F415xx, and SMT32F417xx devices

STM32F401xB(C) indicates STM32F401xB and STM32F401xC devices

STM32F401xD(E) indicates STM32F401xD and STM32F401xE devices

STM32F410xx indicates STM32F410x8 and STM32F410xB devices

STM32F411xx indicates STM32F411xD and STM32F411xE devices

STM32F412xx indicates STM32F412Cx, STM32F412Rx, STM32F412Vx and STM32F412Zx devices

STM32F413xx/423xx indicates STM32F413xG, STM32F413xH and STM32F423xH devices

STM32F42xxx/43xxx indicates STM32F427xx, STM32F429xx, STM32F437xx, and STM32F439xx devices

STM32F446xx indicates STM32F446xE and STM32F446xC devices

STM32F469xx/479xx indicates STM32F469xE, STM32F469xG, STM32F469xI, STM32F479xG, and STM32F479xI devices

F7 series:

STM32F72xxx/73xxx indicates STM32F722xx, STM32F723xx, STM32F732xx, and STM32F733xx devices

STM32F74xxx/75xxx indicates STM32F745xx, STM32F746xx, and STM32F756xx devices

STM32F76xxx/77xxx indicates STM32F765xx, STM32F767xx, STM32F769xx, STM32F777xx, and STM32F779xx devices

G0 series:

STM32G03xxx/04xxx indicates STM32G03xxx, and STM32G04xxx devices

STM32G07xxx/08xxx indicates STM32G07xxx, and STM32G08xxx devices

STM32G0B0xx indicates STM32G0B0xx devices

STM32G0B1xx/C1xx indicates STM32G0B1xx, and STM32G0C1xxx devices

STM32G05xxx/061xx indicates STM32G050xx, STM32G051xx, and STM32G061xx devices

G4 series:

STM32G431xx/441xx indicates STM32G431xx and STM32G441xx devices

STM32G47xxx/48xxx indicates STM32G471xx, STM32G473xx, STM32G474xx, STM32G483xx, and STM32G484xx devices

STM32G491xx/A1xx indicates STM32G491xx and STM32G4A1xx devices

G5 series:

STM32G53xxx/54xxx indicates STM32G53xxx and STM32G54xxx devices

STM32G553xx/554xx/564xx indicates STM32G553xx, STM32G554xx, and STM32G564xx devices

H5 series:

STM32H503xx indicates STM32H503xx devices

STM32H562/63xx/73xx indicates STM32H562xx, STM32H563xx, and STM32H573xx devices

STM32H523xx/533xx indicates STM32H523xx and STM32H533xx devices

STM32H543xx/553xx indicates STM32H543xx and STM32H553xx devices

STM32H5E4xx/5E5xx indicates STM32H5E4xx and STM32H5E5xx devices.

STM32H5F4xx/5F5xx indicates STM32H5F4xx and STM32H5F5xx devices.

H7 series:

STM32H72xxx/73xxx indicates STM32H72xxx and STM32H73xxx devices

STM32H74xxx/75xxx indicates STM32H74xxx and STM32H75xxx devices

STM32H7A3xx/7B3xx/7B0xx indicates STM32H7A3xx, STM32H7B3xx, and STM32H7B0xx devices

STM32H7Rxxx/7Sxxx indicates STM32H7R3xx, STM32H7R7xx, STM32H7S3xx and STM32H7S7xx devices

STM32H7P4xx/P5xx indicates STM32H7P4xx and STM32H7P5xx devices

L0 series:

STM32L01xxx/02xxx indicates STM32L011xx and STM32L021xx devices

STM32L031xx/041xx indicates STM32L031xx and STM32L041xx devices

STM32L05xxx/06xxx indicates STM32L051xx, STM32L052xx, STM32L053xx, STM32L062xx, and STM32L063xx ultra-low power devices

STM32L07xxx/08xxx indicates STM32L071xx, STM32L072xx, STM32L073xx, STM32L081xx, STM32L082xx, and STM32L083xx devices

L1 series:

STM32L1xxx6(8/B) indicates STM32L1xxV6T6, STM32L1xxV6H6, STM32L1xxR6T6, STM32L1xxR6H6, STM32L1xxC6T6, STM32L1xxC6H6, STM32L1xxV8T6, STM32L1xxV8H6, STM32L1xxR8T6, STM32L1xxR8H6, STM32L1xxC8T6, STM32L1xxC8H6, STM32L1xxVBT6, STM32L1xxVBH6, STM32L1xxRBT6, STM32L1xxRBH6, STM32L1xxCBT6, and STM32L1xxCBH6 ultra-low power devices

STM32L1xxx6(8/B)A indicates STM32L1xxV6T6-A, STM32L1xxV6H6-A, STM32L1xxR6T6-A, STM32L1xxR6H6-A, STM32L1xxC6T6-A, STM32L1xxC6H6-A, STM32L1xxV8T6-A, STM32L1xxV8H6-A, STM32L1xxR8T6-A, STM32L1xxR8H6-A, STM32L1xxC8T6-A, STM32L1xxC8H6-A, STM32L1xxVBT6-A, STM32L1xxVBH6-A, STM32L1xxRBT6-A, STM32L1xxRBH6-A, STM32L1xxCBT6-A, and STM32L1xxCBH6-A ultra-low power devices

STM32L1xxxC indicates STM32L1xxVCT6, STM32L1xxVCH6, STM32L1xxRCT6, STM32L1xxUCY6, STM32L1xxCCT6, and STM32L1xxCCU6 ultra-low power devices

STM32L1xxxD indicates STM32L1xxZDT6, STM32L1xxQDH6, STM32L1xxVDT6, STM32L1xxRDY6, STM32L1xxRDT6, STM32L1xxZCT6, STM32L1xxQCH6, STM32L1xxRCY6, STM32L1xxVCT6-A, and STM32L1xxRCT6-A ultra-low power devices

STM32L1xxxE indicates STM32L1xxZET6, STM32L1xxQEH6, STM32L1xxVET6, STM32L1xxVEY6, and STM32L1xxRET6 ultra-low power devices

L4 series:

STM32L412xx/422xx indicates STM32L412xB, STM32L412x8, and STM32L422xB devices

STM32L43xxx/44xxx indicates STM32L431xx, STM32L432xx, STM32L433xx and STM32L442xx, and STM32L443xx devices

STM32L45xxx/46xxx indicates STM32L451xx, STM32L452xx, and STM32L462xx devices

STM32L47xxx/48xxx indicates STM32L471xx, STM32L475xx, STM32L476xx, and STM32L486xx devices

STM32L496xx/4A6xx indicates STM32L496xE, STM32L496xG, and STM32L4A6xG devices

STM32L4Rxxx/4Sxxx indicates STM32L4R5xx, STM32L4R7xx, STM32L4R9xx, STM32L4S5xx, STM32L4S7xx, and STM32L4S9xx devices

STM32L4P5xx/4Q5xx indicates STM32L4P5xx/STM32L4Q5xx devices

L5 series:

STM32L552xx/62xx indicates STM32L552xx and STM32L562xx devices

U0 series:

STM32U031xx indicates STM32U031xx devices

STM32U073xx/83xx indicates STM32U073xx and STM32U083xx devices

U3 series:

STM32U375xx/385xx indicates STM32U375xx and STM32U385xx devices

STM32U3B5xx/3C5xx indicates STM32U3B5xx and STM32U3C5xx devices

U5 series:

STM32U535xx/345xx indicates STM32U535xx and STM32U545xx devices

STM32U575xx/385xx indicates STM32U575xx and STM32U585xxdevices

STM32U595xx/599xx/5A5xx/5A9xx indicates STM32U595xx, STM32U599xx, STM32U5A5xx, and STM32U5A9xx devices

STM32U5F7xx/5F9xx/5G7xx/5G9xx indicates STM32U5F7xx, STM32U5F9xx, STM32U5G7xx, and STM32U5G9xx devices

WB series:

STM32WB10xx/15xx indicates STM32WB10xx and STM32WB15xx devices

STM32WB30xx/35xx/50xx/55xx indicates STM32WB30xx, STM32WB35xx, STM32WB50xx, and STM32WB55xx devices

WBA series:

STM32WBA2xxx indicates STM32WBA23xx and STM32WBA25xx devices

STM32WBA5xxx indicates STM32WBA50xx, STM32WBA52xx, STM32WBA54xx, and STM32WBA55xx devices

STM32WBA62xx/63xx/64xx/65xx indicates STM32WBA54xx, STM32WBA55xx, STM32WBA64xx, and STM32WBA65xx devices

WB0 series:

STM32WB0xx indicates STM32WB05xx, STM32WB06xx, STM32WB07xx, and STM32WB09xx devices

WL series:

STM32WL3xxx indicates STM32WL30xx, STM32WL31xx, STM32WL33xx, and STM32WL3Rxx devices

STM32WLE5xx/55xx indicates STM32WLE5xx and STM32WL55xx devices

Note: BL_USART_Loop refers to the USART bootloader execution loop.
BL_CAN_Loop refers to the CAN bootloader execution loop.
BL_FDCAN_Loop refers to the FDCAN execution loop.
BL_I2C_Loop refers to the I2C bootloader execution loop.
BL_I3C_Loop refers to the I3C bootloader execution loop.
BL_SPI_Loop refers to the SPI bootloader execution loop.

4 General bootloader description

4.1 Bootloader activation

The bootloader is activated by applying one of the patterns described in *Table 2*.

If boot from Bank2 option is activated (for products supporting this feature), the bootloader executes Dual Boot mechanism as described in figures “Dual bank boot implementation for STM32xxxx” (example: *Figure 51*), otherwise bootloader selection protocol is executed as described in figures “Bootloader VY.x selection for STM32xxxx” (example: *Figure 32*), where STM32xxxx is the relative STM32 product.

When readout protection Level2 is activated, the MCU does not boot on system memory, and bootloader cannot be executed (unless jumping to it from flash user code, all commands are not accessible except Get, GetID, and GetVersion).

Table 2. Bootloader activation patterns

Pattern	Condition
Pattern 1	Boot0(pin) = 1 and Boot1(pin) = 0
Pattern 2	Boot0(pin) = 1 and nBoot1(bit) = 1
Pattern 3	Boot0(pin) = 1, Boot1(pin) = 0 and BFB2(bit) = 1
	Boot0(pin) = 0, BFB2(bit) = 0 and both banks do not contain valid code
	Boot0(pin) = 1, Boot1(pin) = 0, BFB2(bit) = 0 and both banks do not contain valid code
Pattern 4	Boot0(pin) = 1, Boot1(pin) = 0 and BFB2(bit) = 1
	Boot0(pin) = 0, BFB2(bit) = 0 and both banks do not contain valid code
	Boot0(pin) = 1, Boot1(pin) = 0 and BFB2(bit) = 0
Pattern 5	Boot0(pin) = 1, Boot1(pin) = 0 and BFB2(bit) = 0
	Boot0(pin) = 0, BFB2(bit) = 1 and both banks do not contain valid code
	Boot0(pin) = 1, Boot1(pin) = 0 and BFB2 (bit) = 1
Pattern 6	Boot0(pin) = 1, nBoot1(bit) = 1 and nBoot0_SW(bit) = 1
	nBoot0(bit) = 0, nBoot1(bit) = 1 and nBoot0_SW(bit) = 0
	Boot0(pin) = 0, nBoot0_SW(bit) = 1 and main flash memory empty
	nBoot0(bit) = 1, nBoot0_SW(bit)=0 and main flash memory empty
Pattern 7	Boot0(pin) = 1, nBoot1(bit) = 1 and BFB2(bit) = 0
	Boot0(pin) = 0, BFB2(bit) = 1 and both banks do not contain valid code
	Boot0(pin) = 1, nBoot1(bit) = 1 and BFB2(bit) = 1
Pattern 8	Boot(pin) = 0 and BOOT_ADD0(optionbyte) = 0x0040
	Boot(pin) = 1 and BOOT_ADD1(optionbyte) = 0x0040

Table 2. Bootloader activation patterns (continued)

Pattern	Condition
Pattern 9	nDBANK(bit) = 1, Boot(pin) = 0 and BOOT_ADD0(optionbyte) = 0x0040
	nDBANK(bit) = 1, Boot(pin) = 1 and BOOT_ADD1(optionbyte) = 0x0040
	nDBANK(bit) = 0, nDBOOT(bit) = 1, Boot(pin) = 0 and BOOT_ADD0(optionbyte) = 0x0040
	nDBANK(bit) = 0, nDBOOT(bit) = 1, Boot(pin) = 1 and BOOT_ADD1(optionbyte) = 0x0040
	nDBANK(bit) = 0, nDBOOT(bit) = 0, BOOT_ADDx(optionbyte) out of memory range or in ICP memory range
	nDBANK(bit) = 0, nDBOOT(bit) = 0, BOOT_ADDx(optionbyte) in flash memory range and both banks do not contain valid code
Pattern 10	Boot(pin) = 0 and BOOT_ADD0(optionbyte) = 0x1FF0
	Boot(pin) = 1 and BOOT_ADD1(optionbyte) = 0x1FF0
Pattern 11	BOOT_LOCK(bit) = 0, nBoot1(bit) = 1, nBOOT0_SEL(bit) = 1 and nBoot0(bit) = 0
	BOOT_LOCK(bit) = 0, nBoot1(bit) = 1, Boot0(pin) = 1 and nBOOT0_SEL(bit) = 0
	BOOT_LOCK(bit) = 0, nBOOT0_SEL(bit) = 1, nBoot0(bit) = 1 and main flash empty
	BOOT_LOCK(bit) = 0, Boot0(pin) = 0, nBOOT0_SEL(bit) = 0 and main flash empty
Pattern 12	TZEN = 1 = 0, Boot0(pin) = 0, nSWBoot0(bit) = 1 and NSBOOTADD0 [24:0] = Address(1)
	TZEN = 1 = 0, Boot0(pin) = 1, nSWBoot0(bit) = 1 and NSBOOTADD1 [24:0] = Address(1)
	TZEN = 1 = 0, nBoot0(bit) = 0, nSWBoot0(bit) = 0 and NSBOOTADD1 [24:0] = Address(1)
	TZEN = 0, nBoot0(bit) = 1, nSWBoot0(bit) = 0 and NSBOOTADD0 [24:0] = Address(1)
	TZEN = 1, Boot0(pin) = 0, nSWBoot0(bit) = 1 and SECBOOTADD0 [24:0] = Address(1) and RSSCMD = 0
	TZEN = 1, Boot0(pin) = 1, nSWBoot0(bit) = 1 and RSSCMD = 0, BOOT_LOCK = 0 or (BOOT_LOCK = 1 and SECBOOTADD0 [24:0] = Address(1))
	TZEN = 1, nBoot0(bit) = 1, nSWBoot0(bit) = 0 and SECBOOTADD0 [24:0] = Address(1) and RSSCMD = 0, BOOT_LOCK = 0 or (BOOT_LOCK = 1 and SECBOOTADD0 [24:0] = Address(1))
	TZEN = 1, nBoot0(bit) = 0, nSWBoot0(bit) = 0 and RSSCMD = 0, BOOT_LOCK = 0 or BOOT_LOCK = 1 and SECBOOTADD1 [24:0] = Address(1)
	TZEN = 1, RSSCMD = 0x1C0, BOOT_LOCK=0 or (BOOT_LOCK = 1 and SECBOOTADD0 [24:0] = Address(1))
Pattern 13	nBoot0(bit) = 0, nBoot1(bit) = 1 and nSWBoot0(bit) = 0
	nBoot0(bit) = 1, nBoot1(bit) = 1, nSWBoot0(bit) = 0 and user flash empty
	nBoot1(bit) = 1, nSWBoot0(bit) = 1 and Boot0(pin) = 1
	nBoot1(bit) = 1, nSWBoot0(bit) = 1, Boot0(pin) = 0 and user flash empty
Pattern 14	BOOT_LOCK(bit) = 0, nBoot1(bit) = 1, Boot0(pin) = 1 and nSWBoot0(bit) = 1
	BOOT_LOCK(bit) = 0, nBoot1(bit) = 1, nBoot0(bit) = 0 and nSWBoot0(bit) = 0
	BOOT_LOCK(bit) = 0, Boot0(pin) = 0, nSWBoot0(bit) = 1, BFB2(bit) = 1 and both banks do not contain valid code
	BOOT_LOCK(bit) = 0, nBoot0(bit) = 1, nSWBoot0(bit) = 0, BFB2(bit) = 1 and both banks do not contain valid code

Table 2. Bootloader activation patterns (continued)

Pattern	Condition
Pattern 15	BOOT_LOCK(bit)=0, Boot0(pin) = 1, nBoot1(bit) = 1 and nBoot0_SW(bit) = 1
	BOOT_LOCK(bit)=0, nBoot0(bit) = 0, nBoot1(bit) = 1 and nBoot0_SW(bit) = 0
Pattern 16	Boot0(pin) = 1, nBoot1(bit) = 1 and nBoot0_SW(bit) = 1
	nBoot0(bit) = 0, nBoot1(bit) = 1 and nBoot0_SW(bit) = 0
	Boot0(pin) = 0, nBoot0_SW(bit) = 1 and main flash memory empty
Pattern 17	PRODUCT_STATE = Open and Boot0(pin) = 1
	PRODUCT_STATE = Provisioning
Pattern 18	Force PA10 high during HW reset
Pattern 19	Boot0(bit) = 1 and BootSel(bit) = 0 Boot0(bit) = 0, BootSel(bit) = 0, and user flash empty BootSel(bit) = 1 and Boot pin = 1

1. Device dependent: 0x17F200 for STM32L5, STM32U5, and STM32WBA6, 0x17F1E00 for STM32U3, 0x17F1000 for STM32WBA5, 0x17F0A0 for STM32WBA2.

Note: nBoot0_SW means either nSWBoot0 or nBOOT0_SEL, depending upon the product.

Note: BOOT_LOCK implementation is product dependent. See the reference manual for more details.

In addition to the patterns described above, the user can execute bootloader by performing a jump to system memory from user code. Before jumping to bootloader:

- Disable all peripheral clocks
- Disable used PLL
- Disable interrupts
- Clear pending interrupts

In some products using interrupts (integrating USB, SPI, non auto baud rate USART), interrupts must be re-enabled before jumping to the Bootloader, as this is not done by the bootloader SW.

System memory boot mode can be exited by getting out from bootloader activation condition and generating hardware reset or using Go command to execute user code.

Note: When executing the Go command, the peripheral registers used by the bootloader are not initialized to their default reset values before jumping to the user application. They must be reconfigured in the user application if they are used. So, if the application uses the IWDG, the IWDG prescaler value must be adapted to meet requirements (since the prescaler was set to its maximum value). For new products, the software resets all resources used by the bootloader (RCC, buses, PWR, PIO ports, and interrupts). Occasionally, not all reset values are set due to errors. For more information, see the known limitations for each product bootloader version.

Note: On devices with dual bank boot, to jump to system memory from user code the user must first remap the system memory bootloader at address 0x00000000 using SYSCFG register (except for STM32F7 series), then jump to bootloader. For the STM32F7 series, the user must disable nDBOOT and/or nDBANK features (in option bytes), then jump to bootloader. For STM32L0 series, the jump to system memory from user code is not possible.

Note: For STM32 devices embedding bootloader using the DFU/CAN interface in which the external clock source (HSE) is required for DFU/CAN operations, the detection of the HSE value is done dynamically by the bootloader firmware and is based on the internal oscillator clock (HSI, MSI). When (because of temperature variations or other conditions) the internal oscillator precision is altered above the tolerance band (1% around the theoretical value), the bootloader can calculate a wrong HSE frequency value. In this case, the bootloader DFU/CAN interfaces can malfunction, or not work at all.

4.2 Bootloader identification

Depending upon the device, the bootloader can support one or more embedded serial peripherals used to download the code to the internal flash memory. The bootloader identifier (ID) provides information about the supported serial peripherals.

For a given STM32 device, the bootloader is identified by means of the:

1. **Bootloader (protocol) version**: version of the serial peripheral (e.g. USART, CAN, USB) communication protocol used in the bootloader. This version can be retrieved using the bootloader Get Version command.
2. **Bootloader identifier (ID)**: version of the STM32 device bootloader, coded on one byte in the **0xXY** format**,** where:
   - **X** specifies the embedded serial peripheral(s) used by the device bootloader:
     X = 1: one USART is used
     X = 2: two USARTs are used
     X = 3: USART, CAN, and DFU are used
     X = 4: USART and DFU are used
     X = 5: USART and I^2C are used
     X = 6: I^2C is used
     X = 7: USART, CAN, DFU, and I^2C are used
     X = 8: I2C and SPI are used
     X = 9: USART, CAN (or FDCAN), DFU, I^2C, and SPI are used
     X = 10: USART, I2C, and DFU are used
     X = 11: USART, I2C, and SPI are used
     X = 12: USART and SPI are used
     X = 13: USART, DFU, I2C, and SPI are used
     X = 14: USART, DFU, I2C, I3C, FDCAN, and SPI are used
     X = 15: USART, USB-DFU, I2C, and I3C are used
     Bootloader interface combinations have reached the maximum supported value. The solution is to extend the format to 0xXXY.
     XX now specifies the serial peripheral or peripherals used by the device bootloader:
     X = 16: USART, USB DFU, FDCAN, and SPI are used
     X = 17: USART, SPI, and FDCAN are used
     X = 18: USART, SPI, FDCAN, and I2C are used
     X = 19: USART, SPI, I3C, USB-DFU, and I2C
     X = 20: USART, SPI, I3C, USB-DFU, I2C, and FDCAN
     Example: If the bootloader identification read on STM32C0 is 0x121, this means that the bootloader version is 18.1.
   - **Y** specifies the device bootloader version
     For example, if the bootloader ID is 0x10, this is the first version, which uses only one USART.
     The bootloader ID is programmed in the last byte address - 1 of the device system

memory and can be read by using the “Read memory” command or by direct access to the system memory via JTAG/SWD.

Note: The bootloader ID format is applied to all STM32 products, except the STM32F1xx devices. The bootloader version for the STM32F1xx applies only to the embedded device bootloader version and not to its supported protocols.

Table 3 provides identification information of the bootloaders embedded in STM32 devices.

Table 3. Embedded bootloaders

Series	Device	Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
			ID	Memory location	
C0	STM32C011xx	USART1 I2C1	0x51	0x1FFF17FE	USART (V3.1) I2C1(V1.1)
	STM32C031xx	USART1 I2C1	0x52	0x1FFF17FE	USART (V3.1) I2C1(V1.1)
	STM32C051xx	USART1/USART2 I2C1/I2C2 SPI1/SPI2	0xB0	0x1FFF2FFE	USART (V4.0) I2C (V2.0) SPI (V2.0)
	STM32C071xx	USART1/USART2 I2C1/I2C2 SPI1/SPI2 USB DFU	0xD1	0x1FFF67FE	USART (V3.1) I2C1(V1.2) SPI (V1.1) USB (V2.2)
	STM32C091xx/92xx	USART1/USART2/USART3 I2C1/I2C2 SPI1/SPI2 FDCAN1	0x121	0x1FFF3FFE	USART (V4.0) I2C (V2.0) SPI (V2.0) FDCAN (V2.2)
C5	STM32C5A3xx/59xxx	USART1/2/3 and UART4 SPI1/2/3 FDCAN2 USB DFU	0x100	0x0BF885FE	USART (V4.0) SPI (V2.0) FDCAN (V2.3) USB DFU (V3.0)
	STM32C55xxx/562xx	USART1/2/3 and UART4 SPI1/2/3 FDCAN1 USB DFU	0x101	0x0BF885FE	USART (V4.0) SPI (V2.0) FDCAN (V2.3) USB DFU (V3.0)
	STM32C53xxx/542xx	USART1/2 and UART4 SPI1/2 FDCAN2 USB DFU	0x100	0x0BF885FE	USART (V4.0) SPI (V2.0) FDCAN (V2.3) USB DFU (V3.0)
F0	STM32F05xxx/STM32F030x8	USART1/USART2	0x21	0x1FFFF7A6	USART (V3.1)
	STM32F03xx4/6	USART1	0x10	0x1FFFF7A6	USART (V3.1)
	STM32F030xC	USART1 I2C1	0x52	0x1FFFF796	USART (V3.1) I2C1(V1.0)
	STM32F04xxx	USART1/USART2 DFU (USB device FS) I2C1	0xA1	0x1FFFF6A6	USART (V3.1) DFU (V2.2) I2C (V1.0)
	STM32F071xx/072xx	USART1/USART2 DFU (USB device FS) I2C1	0xA1	0x1FFFF6A6	USART (V3.1) DFU (V2.2) I2C (V1.0)
	STM32F070x6	USART1/USART2 DFU (USB device FS) I2C1	0xA2	0x1FFFF6A6	USART (V3.1) DFU (V2.2) I2C (V1.0)
	STM32F070xB	USART1/USART2 DFU (USB device FS) I2C1	0xA3	0x1FFFF6A6	USART (V3.1) DFU (V2.2) I2C (V1.0)
	STM32F09xxx	USART1/USART2 I2C1	0x50	0x1FFFF796	USART (V3.1) I2C (V1.0)

Table 3. Embedded bootloaders (continued)

Series	Device		Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
				ID	Memory location	
F1	STM32F10xxx	Low-density	USART1	NA	NA	USART (V2.2)
		Medium-density	USART1	NA	NA	USART (V2.2)
		High-density	USART1	NA	NA	USART (V2.2)
		Medium-density value line	USART1	0x10	0x1FFFF7D6	USART (V2.2)
		High-density value line	USART1	0x10	0x1FFFF7D6	USART (V2.2)
	STM32F105xx/107xx		USART1/USART2 (remapped) CAN2 (remapped) DFU (USB device)	NA	NA	USART (V2.2[1]) CAN (V2.0) DFU(V2.2)
	STM32F10xxx XL-density		USART1/USART2 (remapped)	0x21	0x1FFFF7D6	USART (V3.0)
F2	STM32F2xxxx		USART1/USART3	0x20	0x1FFF77DE	USART (V3.0)
			USART1/USART3 CAN2 DFU (USB device FS)	0x33	0x1FFF77DE	USART (V3.1) CAN (V2.0) DFU (V2.2)
F3	STM32F373xx		USART1/USART2 DFU (USB device FS)	0x41	0x1FFFF7A6	USART (V3.1) DFU (V2.2)
	STM32F378xx		USART1/USART2 I2C1	0x50	0x1FFFF7A6	USART (V3.1) I2C (V1.0)
	STM32F302xB(C)/303xB(C)		USART1/USART2 DFU (USB device FS)	0x41	0x1FFFF796	USART (V3.1) DFU (V2.2)
	STM32F358xx		USART1/USART2 I2C1	0x50	0x1FFFF796	USART (V3.1) I2C (V1.0)
	STM32F301xx/302x4(6/8)		USART1/USART2 DFU (USB device FS)	0x40	0x1FFFF796	USART (V3.1) DFU (V2.2)
	STM32F318xx		USART1/USART2 I2C1/ I2C3	0x50	0x1FFFF796	USART (V3.1) I2C (V1.0)
	STM32F302xD(E)/303xD(E)		USART1/USART2 DFU (USB device FS)	0x40	0x1FFFF796	USART (V3.1) DFU (V2.2)
	STM32F303x4(6/8)/334xx/328xx		USART1/USART2 I2C1	0x50	0x1FFFF796	USART (V3.1) I2C (V1.0)
	STM32F398xx		USART1/USART2 I2C1/I2C3	0x50	0x1FFFF796	USART (V3.1) I2C (V1.0)

Table 3. Embedded bootloaders (continued)

Series	Device	Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
			ID	Memory location	
F4	STM32F40xxx/41xxx	USART1/USART3 CAN2 DFU (USB device FS)	0x31	0x1FFF77DE	USART (V3.1) CAN (V2.0) DFU (V2.2)
		USART1/USART3 CAN2 DFU (USB device FS) I2C1/I2C2/I2C3 SPI1/SPI2	0x91	0x1FFF77DE	USART (V3.1) CAN (V2.0) DFU (V2.2) SPI(V1.1) I2C (V1.0)
	STM32F42xxx/43xxx	USART1/USART3 CAN2 DFU (USB device FS) I2C1	0x70	0x1FFF76DE	USART (V3.1) CAN (V2.0) DFU (V2.2) I2C (V1.0)
		USART1/USART3 CAN2 DFU (USB device FS) SPI1/ SPI2/ SPI4 I2C1/I2C2/I2C3	0x91	0x1FFF76DE	USART (V3.1) CAN (V2.0) DFU (V2.2) SPI(V1.1) I2C (V1.0)
	STM32F401xB(C)	USART1/USART2 DFU (USB device FS) SPI1/SPI2/ SPI3 I2C1/I2C2/I2C3	0xD1	0x1FFF76DE	USART (V3.1) DFU (V2.2) SPI(V1.1) I2C (V1.0)
	STM32F401xD(E)	USART1/USART2 DFU (USB device FS) SPI1/SPI2/SPI3 I2C1/I2C2/I2C3	0xD1	0x1FFF76DE	USART (V3.1) DFU (V2.2) SPI(V1.1) I2C (V1.1)
	STM32F410xx	USART1/USART2 I2C1/I2C2/I2C4 SPI1/SPI2	0xB1	0x1FFF76DE	USART (V3.1) I2C (V1.2) SPI (V1.1)
	STM32F411xx	USART1/USART2 DFU (USB device FS) SPI1/SPI2/ SPI3 I2C1/I2C2/I2C3	0xD0	0x1FFF76DE	USART (V3.1) DFU (V2.2) SPI(V1.1) I2C (V1.1)
	STM32F412xx	USART1/USART2 USART3/CAN2 DFU (USB device FS) SPI1/SPI3/SPI4 I2C1/I2C2/I2C3/I2C4	0x91	0x1FFF76DE	USART (V3.1) CAN (V2.0) DFU (V2.2) SPI (V1.1) I2C (V1.2)
	STM32F413xx/423xx	USART1/USART2 USART3/CAN2 DFU (USB device FS) I2C1/I2C2/I2C3/I2C4 SPI1/SPI3/SPI4	0x90	0x1FFF76DE	USART (V3.1) CAN (V2.0) DFU (V2.2) I2C (V1.2) SPI (V1.1)
	STM32F446xx	USART1/USART3 CAN2 DFU (USB device FS) SPI1/ SPI2/SPI4 I2C1/I2C2/I2C3	0x90	0x1FFF76DE	USART (V3.1) CAN (V2.0) DFU (V2.2) SPI(V1.1) I2C (V1.2)
	STM32F469xx/479xx	USART1/USART3 I2C1/I2C2/I2C3 CAN2 DFU (USB device FS) SPI1/SPI2/ SPI4	0x90	0x1FFF76DE	USART (V3.1) I2C (V1.2) CAN (V2.0) DFU (V2.2) SPI (V1.1)

Table 3. Embedded bootloaders (continued)

Series	Device	Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
			ID	Memory location	
F7	STM32F72xxx/73xxx	USART1/USART3 CAN1 DFU (USB device FS) I2C1/I2C2/I2C3 SPI1/SPI2/SPI4	0x90	0x1FF0EDBE	USART (V3.1) CAN (V2.0) DFU (V2.2) I2C (V1.2) SPI (V1.2)
	STM32F74xxx/75xxx	USART1/USART3 I2C1/I2C2/I2C3 CAN2 DFU (USB device FS)	0x70	0x1FF0EDBE	USART (V3.1) I2C (V1.2) CAN (V2.0) DFU (V2.2)
		USART1/USART3 I2C1/I2C2/I2C3 CAN2 DFU (USB device FS) SPI1/SPI2/SPI4	0x90	0x1FF0EDBE	USART (V3.1) I2C (V1.2) CAN (V2.0) DFU (V2.2) SPI (V1.2)
	STM32F76xxx/77xxx	USART1/USART3 CAN2 DFU (USB device FS) I2C1/I2C2/I2C3 SPI1/SPI2/SPI4	0x93	0x1FF0EDBE	USART (V3.1) CAN (V2.0) DFU (V2.2) I2C (V1.2) SPI (V1.2)
G0	STM32G07xxx/08xxx	USART1/USART2/USART3 I2C1/I2C2 SPI1/SPI2	0xB4	0x1FFF6FFE	USART (V3.1) I2C (V1.2) SPI (V1.1)
	STM32G03xxx/04xxx	USART1/USART2 I2C1\I2C2	0x54	0x1FFF1FFE	USART (V3.1) I2C (V1.2)
	STM32G0B0xx	USART1/USART2/USART3 I2C1/I2C2 SPI1/SPI2 DFU (USB device FS)	0xD0	0x1FFF9FFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2)
	STM32G0B1xx/0C1xx	USART1/USART2/USART3 I2C1/I2C2 SPI1/SPI2 DFU (USB device FS) FDCAN	0x92	0x1FFF9FFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2) FDCAN (V1.0)
	STM32G05xxx/061xx	USART1/USART2 I2C1/I2C2	0x51	0x1FFF1FFE	USART (V3.1) I2C (V1.2)
G4	STM32G431xx/441xx	USART1/USART2/USART3 I2C2/I2C3 SPI1/SPI2 DFU (USB device FS)	0xD4	0x1FFF6FFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2)
	STM32G47xxx/48xxx	USART1/USART2/USART3 I2C2/I2C3/I2C4 SPI1/SPI2 DFU (USB device FS)	0xD5	0x1FFF6FFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2)
	STM32G491xx/4A1xx	USART1/USART2/USART3 I2C2/I2C3 SPI1/SPI2 DFU (USB device FS)	0xD2	0x1FFF6FFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2)

Table 3. Embedded bootloaders (continued)

Series	Device	Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
			ID	Memory location	
G5	STM32G53xxx/54xxx	USART2/UART4/USART5 SPI1/SPI2 I2C2 FDCAN1	0x120	0x0BFADAE0	USART (V4.0) SPI (V2.0) I2C (V2.0) FDCAN (V2.3)
	STM32G554xx/564xx	USART2/UART4/USART5 SPI1/SPI2 I2C2/3 FDCAN1 USB DFU	0x90	0x0BFADAE0	USART (V4.0) SPI (V2.0) I2C (V2.0) FDCAN (V2.3) USB DFU (V3.0)
H5	STM32H503xx	USART1/USART2/USART3 I2C2 I3C1 SPI1/SPI2/SPI3 USB DFU FDCAN1	0xE2	0x0BF8FFFE	USART (V4.0) I2C (V2.0) I3C (V1.0) SPI (V2.0) USB (V3.0) FDCAN (V2.0)
	STM32H562xx/563xx/573xx	USART1/USART2/USART3 I2C3/I2C4 I3C1 SPI1/SPI2/SPI3 USB DFU FDCAN2	0xE5	0x0BF9FAFE	USART (V4.0) I2C (V2.0) I3C (V1.0) SPI (V2.0) USB (V3.0) FDCAN (V2.0)
	STM32H523xx/533xx	USART1/USART2/USART3 I2C1/I2C3 I3C1 SPI1/SPI2/SPI3 USB DFU FDCAN2	0xE2	0x0BF8FFFE	USART (V4.0) I2C (V2.0) I3C (V1.0) SPI (V2.0) USB (V3.0) FDCAN (V2.0)
	STM32H543xx/553xx	USART1/USART2/USART3 I2C1/ I2C3 SPI1/SPI2/SPI3 I3C1 FDCAN2 USBFS	0xE0	0x0BFADFFE	USART (V4.0) I2C (V2.0) SPI (V2.0) I3C (V1.0) FDCAN (V2.3) USB DFU (V3.0)
	STM32H5Ex/5Fx	USART1/USART2/USART3 I2C3/ I2C4 I3C1 USBHS/USBFS	0xF0	0x0BFB5FFE	USART (V4.0) I2C (V2.0) I3C (V1.0) USB DFU (V3.0)

Table 3. Embedded bootloaders (continued)

Series	Device	Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
			ID	Memory location	
H7	STM32H72xxx/73xxx	USART1/USART2/USART3 I2C1/I2C2/I2C3 DFU (USB device FS) SPI1/SPI2/SPI3/SPI4 FDCAN1	0x93	0x1FF1E7FE	USART (V3.1) I2C (V1.2) DFU (V2.2) SPI (V1.1) FDCAN (V1.1)
	STM32H74xxx/75xxx	USART1/USART2/USART3 I2C1/I2C2/I2C3 DFU (USB device FS) SPI1/SPI2/SPI3/SPI4 FDCAN1	0x92	0x1FF1E7FE	USART (V3.1) I2C (V1.1) DFU (V2.2) SPI (V1.1) FDCAN (V1.1)
	STM32H7A3xx/7B3xx/7B0xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 DFU (USB device FS) SPI1/SPI2/SPI3 FDCAN1	0x92	0x1FF13FFE	USART (V3.1) I2C (V1.2) DFU (V2.2) SPI (V1.2) FDCAN (V1.1)
	STM32H7Rxxx/7Sxxx	USART1/USART2/USART3 UART4 I2C1/I2C2/I2C3 DFU (USB device FS) SPI1/SPI2/SPI3 FDCAN2 I3C1	0xE3 (RevY) 0xE5 (Rev B)	0x1FF1FCFE	USART (V4.0) I2C (V2.0) DFU (V2.2) SPI (V2.0) FDCAN (V2.1) I3C (V1.0)
	STM32H7P4xx/P5xx	USART2/USART4/USART5 I2C1/I2C2/I2C3 FDCAN1 I3C1 USB	0x141	0x1FF19FFE	USART (V4.0) I2C (V2.0) FDCAN (V2.3) I3C (V1.0) USB (V3.0)
L0	STM32L01xxx/02xxx	USART2 SPI1	0xC3	0x1FF00FFE	USART (V3.1) SPI (V1.1)
	STM32L031xx/041xx	USART2 SPI1	0xC0	0x1FF00FFE	USART (V3.1) SPI (V1.1)
	STM32L05xxx/06xxx	USART1/USART2 SPI1/ SPI2	0xC0	0x1FF00FFE	USART (V3.1) SPI (V1.1)
	STM32L07xxx/08xxx	USART1/USART2 DFU (USB device FS)	0x41	0x1FF01FFE	USART (V3.1) DFU (V2.2)
		USART1/USART2 SPI1/SPI2 I2C1/I2C2	0xB2	0x1FF01FFE	USART (V3.1) SPI (V1.1) I2C (V1.2)
L1	STM32L1xxx6(8/B)	USART1/USART2	0x20	0x1FF00FFE	USART (V3.0)
	STM32L1xxx6(8/B)A	USART1/USART2	0x20	0x1FF00FFE	USART (V3.1)
	STM32L1xxxC	USART1/USART2 DFU (USB device FS)	0x40	0x1FF01FFE	USART (V3.1) DFU (V2.2)
	STM32L1xxxD	USART1/USART2 DFU (USB device FS)	0x45	0x1FF01FFE	USART (V3.1) DFU (V2.2)
	STM32L1xxxE	USART1/USART2 DFU (USB device FS)	0x40	0x1FF01FFE	USART (V3.1) DFU (V2.2)

Table 3. Embedded bootloaders (continued)

Series	Device	Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
			ID	Memory location	
L4	STM32L412xx/422xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 DFU (USB device FS) SPI1/SPI2	0xD1	0x1FFF6FFE	USART (V3.1) I2C (V1.2) DFU (V2.2) SPI (V1.1)
	STM32L43xxx/44xxx	USART1/USART2/USART3 I2C1/I2C2/I2C3 CAN1 DFU (USB device FS) SPI1/SPI2	0x91	0x1FFF6FFE	USART (V3.1) I2C (V1.2) CAN (V2.0) DFU (V2.2) SPI (V1.1)
	STM32L45xxx/46xxx	USART1/USART2/USART3 I2C1/I2C2/I2C3 CAN1 DFU (USB device FS) SPI1/SPI2	0x92	0x1FFF6FFE	USART (V3.1) I2C (V1.2) CAN (V2.0) DFU (V2.2) SPI (V1.1)
	STM32L47xxx/48xxx	USART1/USART2/ USART3 I2C1/I2C2/I2C3 DFU (USB device FS)	0xA3	0x1FFF6FFE	USART (V3.1) I2C (V1.2) DFU (V2.2)
		USART1/USART2/ USART3 I2C/I2C2/I2C3 SPI1/SPI2 CAN1 DFU (USB device FS)	0x92	0x1FFF6FFE	USART (V3.1) I2C (V1.2) SPI (V1.1) CAN(V2.0) DFU(V2.2)
	STM32L496xx/4A6xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 CAN1 DFU (USB device FS) SPI1/SPI2	0x93	0x1FFF6FFE	USART (V3.1) I2C (V1.2) CAN (V2.0) DFU (V2.2) SPI (V1.1)
	STM32L4Rxxx/STM32L4Sxxx	USART1/USART2/USART3 I2C1/I2C2/I2C3 CAN1 DFU (USB device FS) SPI1/SPI2	0x95	0x1FFF6FFE	USART (V3.1) I2C (V1.2) CAN (V2.0) DFU (V2.2) SPI (V1.1)
	STM32L4P5xx/Q5xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 CAN1 DFU (USB device FS) SPI1/SPI2	0x90	0x1FFF6FFE	USART (V3.1) I2C (V1.2) CAN (V2.0) DFU (V2.2) SPI (V1.1)
L5	STM32L552xx/562xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 SPI1/SPI2/SPI3 DFU (USB device FS) FDCAN1	0x92	0x0BF97FFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2) FDCAN (V1.0)

Table 3. Embedded bootloaders (continued)

Series	Device	Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
			ID	Memory location	
U0	STM32U031xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 SPI1/SPI2	0xB0	0x1FFF37FE	USART (V3.1) I2C (V1.2) SPI (V1.1)
	STM32U073xx/83xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 SPI1/SPI2 DFU (USB device FS)	0xD0	0x1FFF67FE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2)
U3	STM32U375xx/385xx	USART1/USART3 I2C1/I2C2/I2C3 I3C1 SPI1/SPI2/SPI3 DFU (USB device FS) FDCAN1	0xE2	0x0BF98FFE	USART(V4.0) I2C (V2.0) I3C(V1.0) SPI (V2.0) DFU (V3.0) FDCAN (V2.2)
	STM32U3B5xx/3C5xx	USART1/USART3 I2C1/I2C2/I2C3 SPI1/SPI2/SPI3 I3C1 FDCAN1 USB DFU	0xE0	0x0BF98FFE	USART (V4.0) I2C (V2.0) SPI (V2.0) I3C (V1.0) FDCAN (V2.2) USB DFU (V3.0)
U5	STM32U535xx/545xx	USART1/USART3 I2C1/I2C2/I2C3 SPI1/SPI2/SPI3 DFU (USB device FS) FDCAN1	0x91	0x0BF99EFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2) FDCAN (V1.1)
	STM32U575xx/585xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 SPI1/SPI2/SPI3 DFU (USB device FS) FDCAN1	0x93	0x0BF99EFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2) FDCAN (V1.1)
	STM32U595xx/599xx/ STM32U5A5xx/5A9xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 SPI1/SPI2/SPI3 DFU (USB device HS) FDCAN1	0x92	0x0BF99EFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2) FDCAN (V1.1)
	STM32U5F7xx/5F9xx/ STM32U5G7xx/5G9xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 SPI1/SPI2/SPI3 DFU (USB device HS) FDCAN1	0x90	0x0BF99EFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2) FDCAN (V1.1)
WB	STM32WB10xx/15xx	USART1 I2C1 SPI1	0xB1	0x1FFF6FFE	USART (V3.1) I2C (V1.2) SPI (V1.1)
	STM32WB30xx/35xx/50xx/55xx	USART1 I2C1/I2C3 SPI1/SPI2 DFU (USB device FS)	0xD5	0x1FFF6FFE	USART (V3.2) I2C (V1.2) SPI (V1.1) DFU (V2.2)

Table 3. Embedded bootloaders (continued)

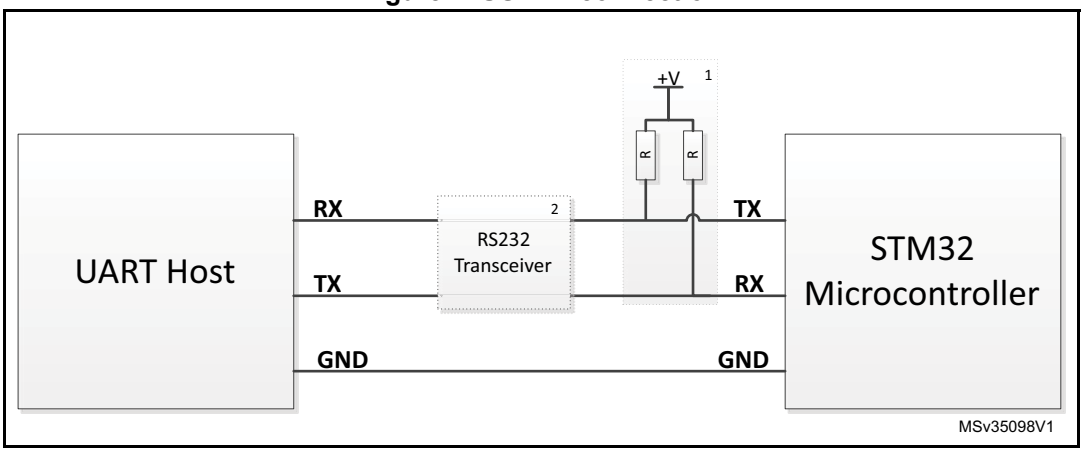
Series	Device	Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
			ID	Memory location	
WBA	STM32WBA2xxx	USART1 SPI3 I2C1/3 USB DFU	0xD0	0x0BF8CCFE	USART (V4.0) SPI (V2.0) I2C (V2.0) USB DFU (V3.0)
	STM32WBA5xxx	USART1/USART2 I2C1/I2C3 SPI3	0xB0 (revA), 0xB1 (revB)	0x0BF8FEFE	USART (V3.1) I2C (V1.2) SPI (V1.1)
	STM32WBA62xx/63xx/64xx/65xx	USART1/USART2 I2C1/I2C3 SPI2/SPI3 DFU (USB device FS)	0xD2	0x0BF97EFE	USART (V4.0) I2C (V2.0) SPI (V2.0) DFU (V3.0)
WB0	STM32WB05xx	USART1	NA	NA	USART (V2.0)
	STM32WB06xx/7xx				USART (V4.0)
	STM32WB09xx				USART (V1.0)
WL	STM32WL3xxx	USART	NA	NA	USART (V4.0)
	STM32WLE5xx/55xx	USART1/USART2 SPI1/SPI2	0xC4	0x1FFF3EFE	USART (V3.1) SPI (V1.1)

1. For connectivity line devices, the USART bootloader returns V2.0 instead of V2.2 for the protocol version. For more details refer to the “STM32F105xx and STM32F107xx revision Z” errata sheet available from www.st.com.

4.3 Hardware connection requirements

To use the USART bootloader, the host must be connected to the RX and TX pins of the desired USARTx interface via a serial cable.

Figure 1. USART connection

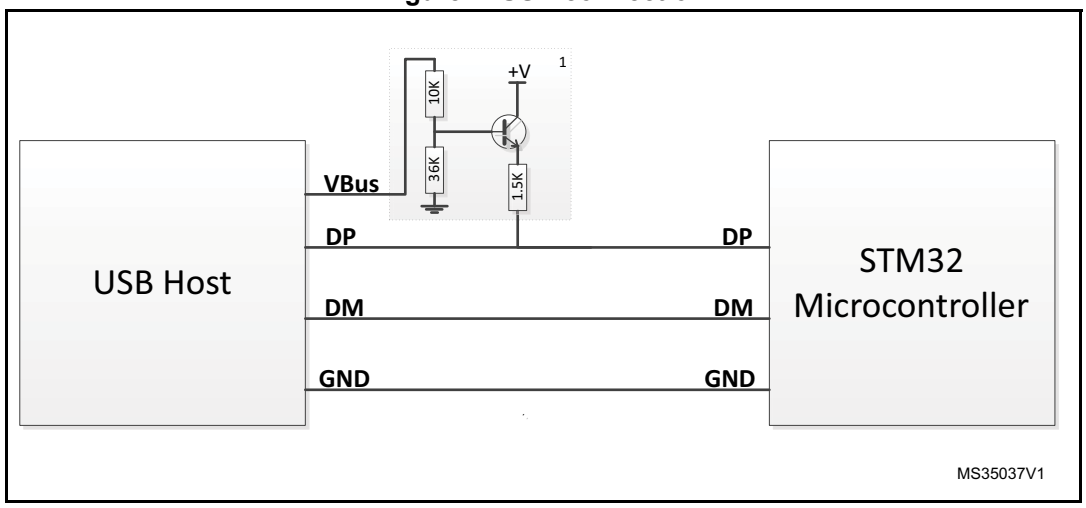


1. A pull-up resistor must be added, if they are not connected on host side.
2. An RS232 transceiver must be connected to adapt the voltage level (3.3 to 12 V) between the STM32 device and the host.

Note: Typically V is 3.3 V, and R is 100 KΩ. These values depend upon the application and the used hardware.

To use the DFU, connect the microcontroller USB interface to a USB host (such as a PC).

Figure 2. USB connection

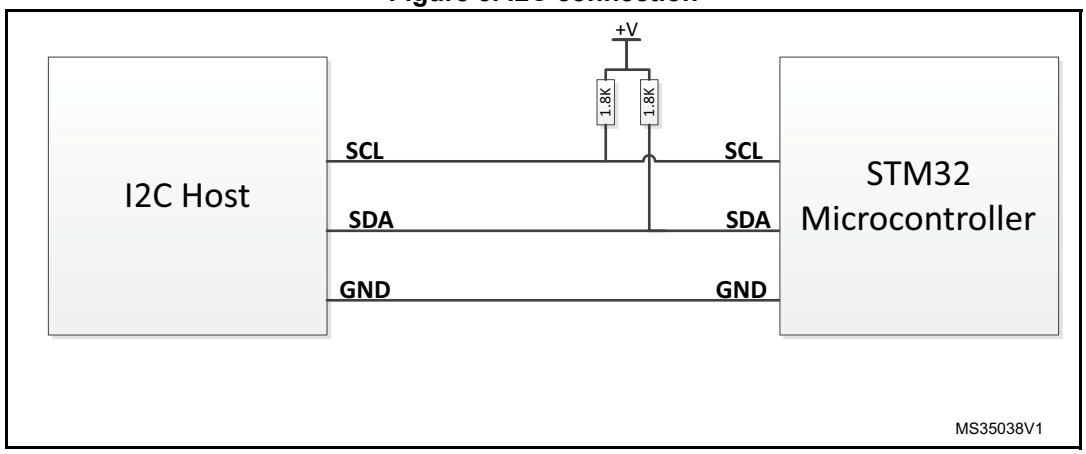


1. This additional circuit permits to connect a pull-up resistor to DP pin using VBus when needed. Refer to product section (table describing STM32 configuration in system memory boot mode) to know if an external pull-up resistor must be connected to DP pin.

Note: V typically is 3.3 V. This value depends upon the application and the used hardware.

To use the I2C bootloader, connect the host (controller) and the desired I2Cx interface (target) together via the data (SDA) and clock (SCL) pins. A 1.8 KΩ pull-up resistor must be connected to both SDA and SCL lines.

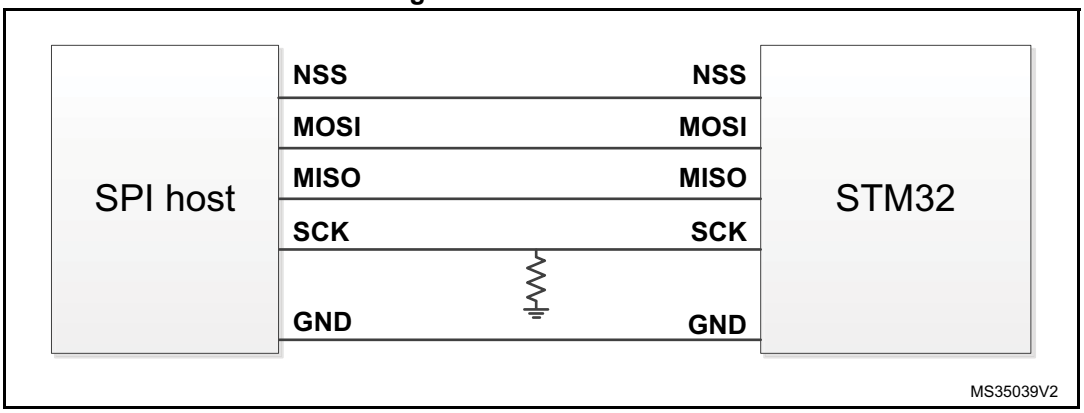
Figure 3. I2C connection



Note: V is typically 3.3 V. This value depends upon the application and the used hardware.

To use the SPI bootloader, connect the host (master) and the desired SPIx interface (slave) together via the MOSI, MISO, SCK, and NSS pins. A pull-down resistor must be connected to the SCK line.

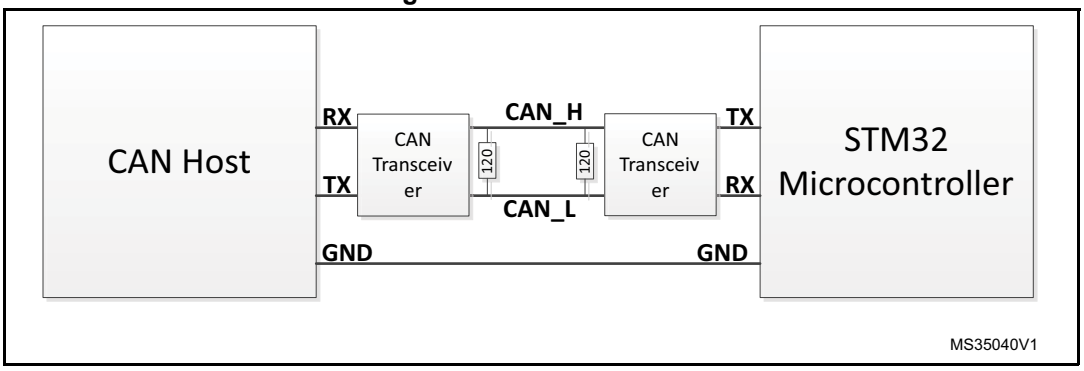
Figure 4. SPI connection



Note: The resistor is typically 10 KΩ, its value depends upon the application and the used hardware.

To use the CAN interface, the host must be connected to the RX and TX pins of the desired CANx interface via CAN transceiver and a serial cable. A 120 Ω resistor must be added as terminating resistor.

Figure 5. CAN connection



Note: When a bootloader firmware supports DFU, it is mandatory that no USB host is connected to the USB peripheral during the selection phase of the other interfaces. After selection phase, the user can plug a USB cable without impacting the selected bootloader execution, except for commands generating a system reset.

It is recommended to keep the RX pins of unused bootloader interfaces (USART_RX, SPI_MOSI, and CAN_RX, if present) at a known (low or high) level and keep the USB D+/D- lines, if present, on the same level (low/high) at the startup of the bootloader (detection phase). Leaving these pins floating during the detection phase can result in activation of unused interfaces.

4.4 Bootloader memory management

All write operations using bootloader commands must be word-aligned (the address must be a multiple of 4). The number of data to write must be a multiple of 4 as well (non-aligned half page write addresses are accepted).

Some products embed a bootloader with specific features:

- On products that do not support mass erase operation, to perform this operation using the bootloader, two options are available:
  - Erase all sectors one by one using the Erase command
  - Set protection level to Level 1. Then, set it to Level 0 (using the Read protect and then the Read unprotect command). This operation results in a mass erase of the internal flash memory.
- Bootloader firmware of STM32 L1 and L0 series supports Data memory in addition to standard memories (internal flash, internal SRAM, option bytes and System memory). The start address and the size of this area depends on product, refer to the reference manual for more information. Data memory can be read and written but cannot be erased using the Erase command. When writing in a Data memory location, the bootloader firmware manages the erase operation of this location before any write. A write to Data memory must be word-aligned (address to be written must be a multiple of 4) and the number of data must also be a multiple of 4. To erase a Data memory location, write 0s at this location.
- Bootloader firmware of the F2, F4, F7, and L4 series supports OTP memory in addition to standard memories (internal flash, internal SRAM, option bytes and System memory). The start address and the size of this area depends on product, refer to the reference manual for more information. OTP memory can be read and written but cannot be erased using Erase command. When writing in an OTP memory location, make sure that the relative protection bit is not reset.
- For STM32 F2, F4, and F7 series the internal flash memory write operation format depends on voltage range. By default write operations are allowed by one byte format (half-word, word, and double-word operations are not allowed). To increase the speed of write operation, the user must apply the adequate voltage range that allows write operation by half-word, word or double-word and update this configuration on the fly by the bootloader software through a virtual memory location. This memory location is not physical but can be read and written using usual bootloader read/write operations according to the protocol in use. This memory location contains four bytes, described in *Table 4*. It can be accessed by 1, 2, 3, or 4 bytes. However, reserved bytes must remain at their default values (0xFF), otherwise the request is NACK-ed.

Table 4. STM32 F2, F4, and F7 voltage range configuration using bootloader

Address	Size	Description
0xFFFF0000	1 byte	This byte controls the current value of the voltage range. – 0x00: voltage range [1.8 V, 2.1 V] – 0x01: voltage range [2.1 V, 2.4 V] – 0x02: voltage range [2.4 V, 2.7 V] – 0x03: voltage range [2.7 V, 3.6 V] – 0x04: voltage range [2.7 V, 3.6 V] and double word write/erase operation is used. In this case it is mandatory to supply 9 V through the VPP pin (refer to the product reference manual for more details about the double-word write procedure). – Others: all other values are not supported and are NACK-ed.

Address	Size	Description
0xFFFF0001	1 byte	Reserved. 0xFF is the default value, all other values are not supported and are NACK-ed.
0xFFFF0002	1 byte	
0xFFFF0003	1 byte	

Table 5 lists the valid memory areas, depending upon the bootloader commands.

Table 5. Supported memory area by Write, Read, Erase, and Go commands

Memory area	Write command	Read command	Erase command	Go command
Flash	Supported	Supported	Supported	Supported
RAM	Supported	Supported	Not supported	Supported
System memory	Not supported	Supported	Not supported	Not supported
Data memory	Supported	Supported	Supported(1)	Not supported
OTP memory	Supported	Supported	Not supported	Not supported

1. Depending on the STM32 device, the erase method varies:

   - Write 0 to the data memory address on STM32L0 and STM32L1 devices.

   - Use flash erase when the data memory corresponds to flash sectors, for example, STM32H57xx/8xx devices.

   - Use a special command to erase, as described in the STM32 paragraph.

4.5 Bootloader UART baudrate detection

For the UART interface baudrate detection, there are two implemented mechanisms:

- Software baudrate detection using internal HSI and timer (use GPIO as input, detect falling edge and rising edge as explained in AN3155).
  The devices using this mechanism are subject to software jitter (variable error of baudrate calculation) that can reach up to ±5%. In this case, the host connecting to the STM32 bootloader UART interface must support a ±5% deviation in baudrate.
  The software jitter value is variable and different at each retry, so it is possible to use multiple retry connections to overcome it. Connect and check for correct bootloader answer, if the answer is not correct, reset the device and retry connection until the correct answer is received. At this point, the rest of the communication is not impacted.
  It is also possible to reduce the software jitter by reducing the baudrate (as an example, use 56000 instead of 115200 bps).
  Table 6 provides the maximum software jitter value for the 115200 bps baudrate. The lower the baudrate, the lower the software jitter.
- Baudrate detection using UART auto-baudrate feature. Devices using this mechanism do not present any software jitter.

Table 6. Jitter software calculation on bootloader USART detection

Series or product	Detection method	Maximum software jitter
STM32C011xx	Auto-baudrate	Not applicable
STM32C031xx		
STM32C051xx USART1		
STM32C051xx USART2	Software baudrate detection	-2%
STM32C071xx USART1	Auto-baudrate	Not applicable
STM32C071xx USART2	Software baudrate detection	-2%
STM32C091xx/92xx USART1	Auto-baudrate	Not applicable
STM32C091xx/92xx USART2/3	Software baudrate detection	-2%
STM32C5	Auto-baudrate	Not applicable
STM32F0	Software baudrate detection	-1%
STM32F1		-3%
STM32F2		-5%
STM32F3		-2%
STM32F4		-6%
STM32F7		-6%
STM32G05xxx/061xx USART1	Auto-baudrate	Not applicable
STM32G05xxx/061xx USART2	Software baudrate detection	-2%
STM32G07/8x USART3 STM32G03/4x USART2		-4%
STM32G07/8x USART1/USART2 STM32G03/4x USART1	Auto-baudrate	Not applicable
STM32G0B/Cxxx		
STM32G4		
STM32G5		
STM32H5		
STM32H7		
STM32L0	Software baudrate detection	-2%
STM32L1		-3%
STM32L4		-5%
STM32L5	Auto-baudrate	Not applicable
STM32U031xx USART1/2		
STM32U073/83xx USART1/2		
STM32U073/83xx USART3	Software baudrate detection	-2%

Table 6. Jitter software calculation on bootloader USART detection (continued)

Series or product	Detection method	Maximum software jitter
STM32U3	Auto-baudrate	Not applicable
STM32U5		
STM32WB		
STM32WBA		
STM32WB0		
STM32WL		

4.6 Programming constraints

When using the bootloader interface to write in the flash memory, respect the alignment on the programmed address detailed in *Table 7*. If the address is not aligned, the operation fails, and all following program operations fail as well.

Table 7. Flash memory alignment constraints

Series	Alignment
STM32C0	8 bytes
STM32C5	16 bytes
STM32F0	4 bytes
STM32F1	4 bytes
STM32F2	4 bytes
STM32F3	4 bytes
STM32F4	4 bytes
STM32F7	8 bytes
STM32G0	4 bytes
STM32G4	8 bytes
STM32G5	16 bytes
STM32H5	16 bytes
STM32H7	16 bytes (7Rx/7Sx devices)
	8 bytes (all other devices)
STM32L0	8 bytes
STM32L1	8 bytes
STM32L4	8 bytes
STM32L5	16 bytes
STM32U0	8 bytes
STM32U3	8 bytes
STM32U5	16 bytes

Table 7. Flash memory alignment constraints (continued)

Series	Alignment
STM32WB	8 bytes
STM32WBA	16 bytes
STM32WB0	4 bytes
STM32WL	4 bytes (STM32WL3xxx)
	8 bytes (STM32WLE5xx/55xx)

Examples of alignment:

- 4 bytes: 0x0800 0014 is aligned and passes, 0x0800 0012 is not aligned and fails
- 8 bytes: 0x0800 0010 is aligned and passes, 0x0800 0014 is not aligned and fails

Note: On STM32F4 and STM32F7 it is possible to change the alignment constraint by writing in the device feature space.

4.7 ExitSecureMemory feature

The securable memory area is used to isolate secure boot code/data, which handles sensitive information (secrets), from application code. The secure boot code access is controlled by HW (FLASH registers and option bytes, depending on the product). The code is executed once at boot, then locked by HW until the next reset.

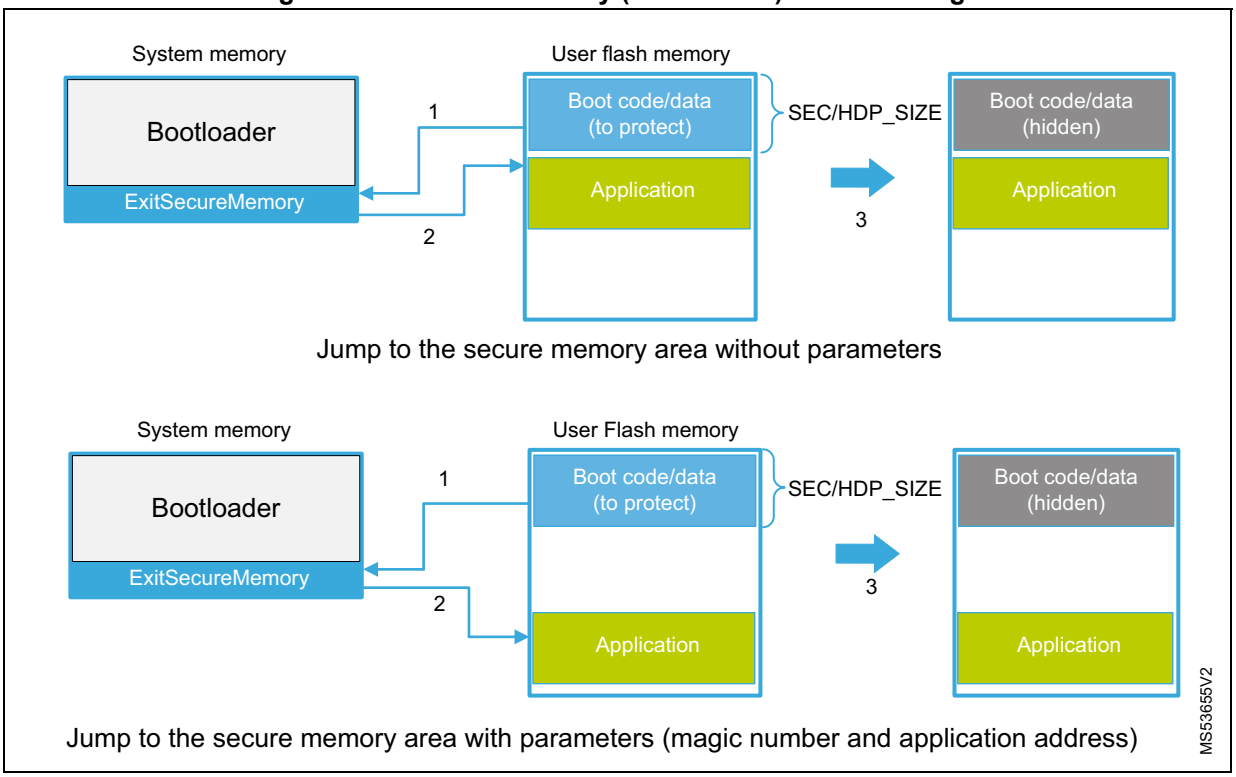
The ExitSecureMemory is a software hosted on the system memory. When the user boot code jumps to it, it is possible to enable the hide protection area, and then jump to the application code. The size of the hide protection area (HDP) must be set by the user to the needed value before jumping to the ExitSecureMemory function.

4.7.1 ExitSecureMemory v1.0

As shown in *Figure 6*, two methods can be used.

1. Jump to the secure memory function without parameters: the application must be loaded just after the defined secure memory area (HDP and size).
2. Jump to the secure memory function using two parameters:
   a) Magic number: 0x08192A3C is used to secure boot code/data in flash/Bank1 and jump in case of a single/dual bank product, 0x08192A3D is used to secure boot code/data and jump to application in Bank2 in case of a dual bank product
   b) User address = Application address: the application can be loaded to any desired address

Figure 6. ExitSecureMemory (v1.0 or v1.1) function usage

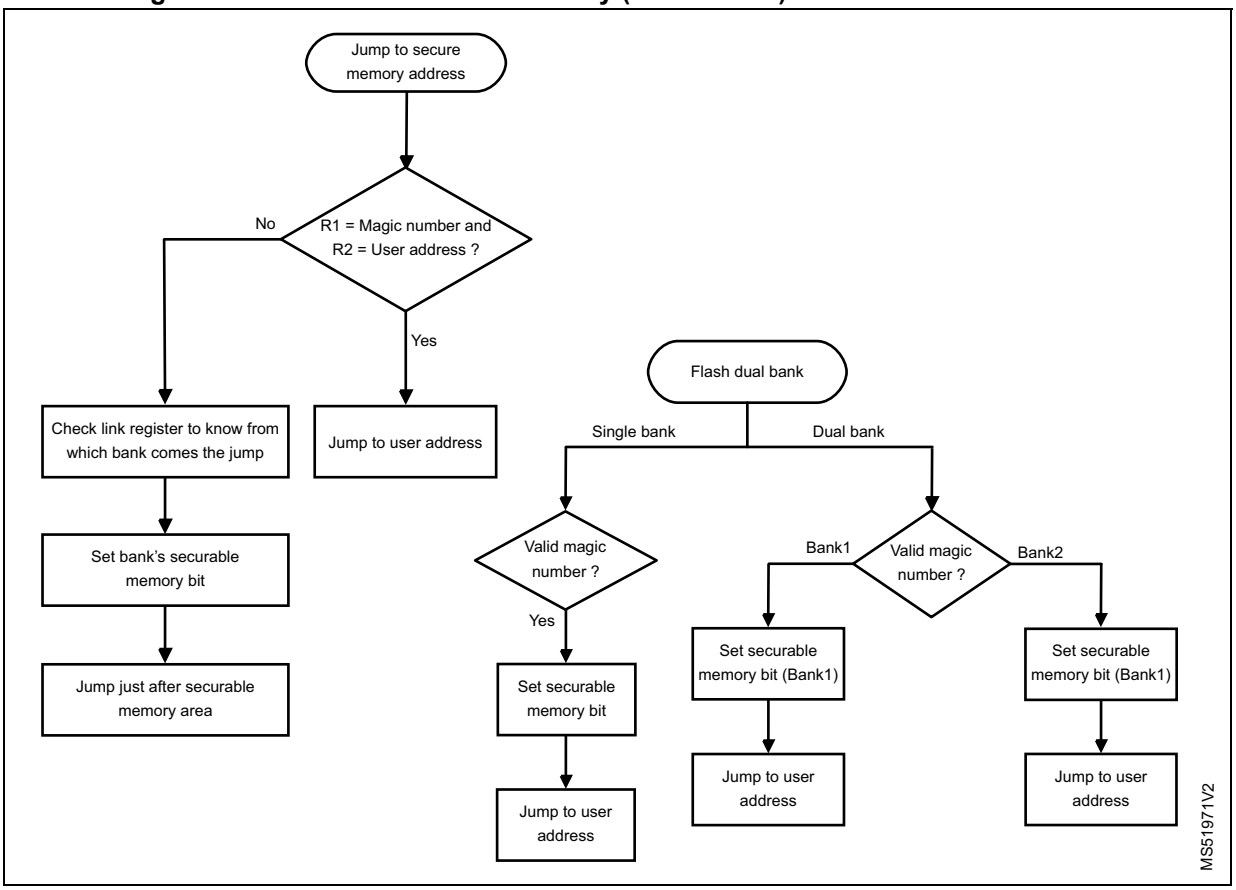


For more information regarding the option bytes configuration, see the reference manual.

For examples of functions that can be used to call ExitSecureMemory, see *Appendix A*.

For more details refer to *Figure 7*.

Figure 7. Access to securable memory (v1.0 or V1.1) area from the bootloader



1. The bootloader does not check the integrity of the user address, it is up to the user to ensure the validity of the address to jump to.

4.7.2 ExitSecureMemory v1.1

Compared to the ExitSecureMemory v1.0, the user can define an MPU region. This is done using the CPU R3 register, before jumping to the software, that runs as shown in *Figure 8*.

Figure 8. Defining an MPU region

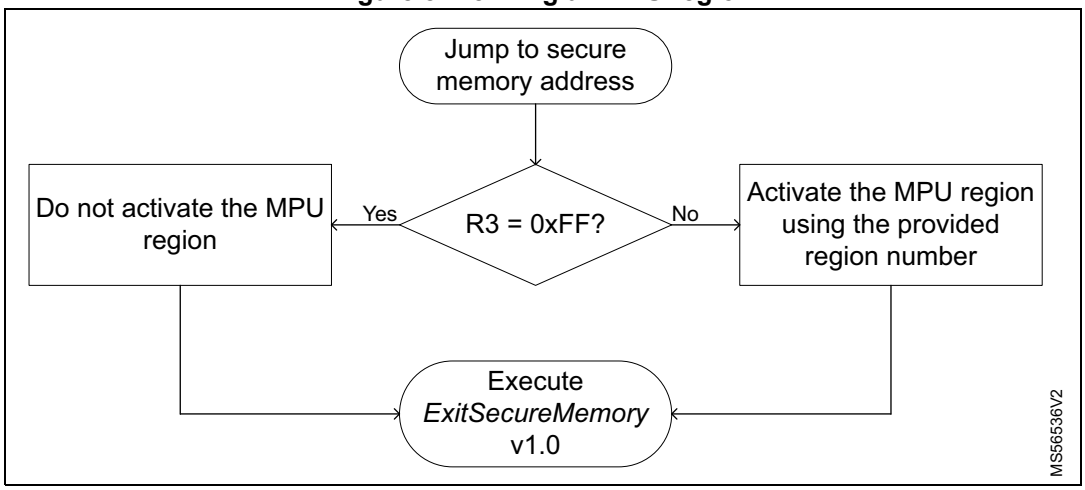


Table 8. ExitSecureMemory entry address

MCU		ExitSecureMemory address	Version address	Version
STM32G0	STM32G07xxx/08xxx	0x1FFF6800	Not available	V1.0
	STM32G03xxx/04xxx	0x1FFF1E00		
	STM32G0Bxxx/0Cxxx	0x1FFF6800		
	STM32G05xxx/061xx	0x1FFF6800		
STM32G4	STM32G47xxx/48xxx	0x1FFF6800		
	STM32G431xx/441xx	0x1FFF6800		
	STM32G491xx/4A1xx	0x1FFF6800		
STM32C0	STM32C011xx	0x1FFF1600		
	STM32C031xx	0x1FFF1600		
	STM32C051xx	0x1FFF2E00	0x1FFF2F8C	V1.1 (0x11)
	STM32C071xx	0x1FFF1600	0x1FFF618C	
	STM32C091xx/92xx	0x1FFF3E00	0x1FFF3F8C	
STM32C5	STM32C5xxx	0x0BF88400	0x0BF883E8	V2.0 (0x20)
STM32U0	STM32U031xx	0x1FFF3500	0x1FFF368C	V1.1 (0x11)
	STM32U073xx/83xx	0x1FFF6000	0x1FFF618C	

4.7.3 ExitSecureMemory v2.0

The implementation of ExitSecureMemory, also called the ExitHDP feature, changes in this major version 2.0. ExitHDP is no longer a standalone software component to which the firmware jumps. It is now a library that the firmware can use by calling runtime services through EXITHDP-prefixed functions.

These functions are available to users in the CMSIS device header file that the STM32Cube firmware package provides for this version.

The user firmware can call one of the EXITHDPLIB functions, depending on the HDP level, by using the “EXITHDPLIB_PFUNC C” macro, which points to a location in system memory.

Table 9. EXITHDP APIs

Library	Function
EXITHDP_PFUNC	JumpHDPLvl2
	JumpHDPLvl3

Function prototypes:

```
uint32_t JumpHDPLvl2(uint32_t VectorTableAddr, uint32_t MPUIndex)
uint32_t JumpHDPLvl3(uint32_t VectorTableAddr, uint32_t MPUIndex)
```

Arguments:

VectorTableAddr: Input parameter. Address of the next vector table to apply. The vector table format is the format that the Arm® Cortex®-Mxx core uses.

MPUIndex: Input parameter. Microprocessor unit (MPU) region index. The caller function must define the corresponding MPU region but keep it disabled before calling JumpHDPLvlx. The function enables the MPU region before it jumps to the reset handler of the vector table. The reset handler function of the vector table must belong to the MPU region.

Descriptions:

JumpHDPLvl2: The user calls JumpHDPLvl2 to close the user flash HDPL1 area by incrementing HDPL to 2. After HDPL1 closes, the function enables the microprocessor unit (MPU) region provided as an input parameter and then jumps to the reset handler in the vector table provided as an input parameter. On successful execution, the function does not return and does not push LR onto the stack.

JumpHDPLvl3: The user calls JumpHDPLvl3 to close the user flash HDPL1 and HDPL2 areas by incrementing HDPL to 3. After HDPL1 and HDPL2 close, the function enables the microprocessor unit (MPU) region provided as an input parameter and then jumps to the reset handler in the vector table provided as an input parameter. On successful execution, the function does not return and does not push LR onto the stack.

Errors:

If the input parameter value is invalid, both APIs return 0xF5F5F5F5.

4.8 IWDG usage

The bootloader does not enable IWDG. It tries to update the prescaler value if the IWDG was enabled by HW (through option bytes) or by SW in case of an application that jumps to bootloader.

If the IWDG was not enabled before the boot on bootloader (using HW boot or by a jump from an application), the watchdog prescaler value update bit (PVU) is set to 1 when the bootloader tries to change the prescaler value.

This value does not change, it remains at 0x1 as the prescaler update never happens (IWDG is not enabled), even after the jump. When using the bootloader to jump to the application, and when there is the need to enable the IWDG, consider that the PVU bit in the IWDG_SR register is set to 1.

4.9 Bootloader models

To address the evolution of STM32 devices on security, the bootloader (BL) is now available on different models.

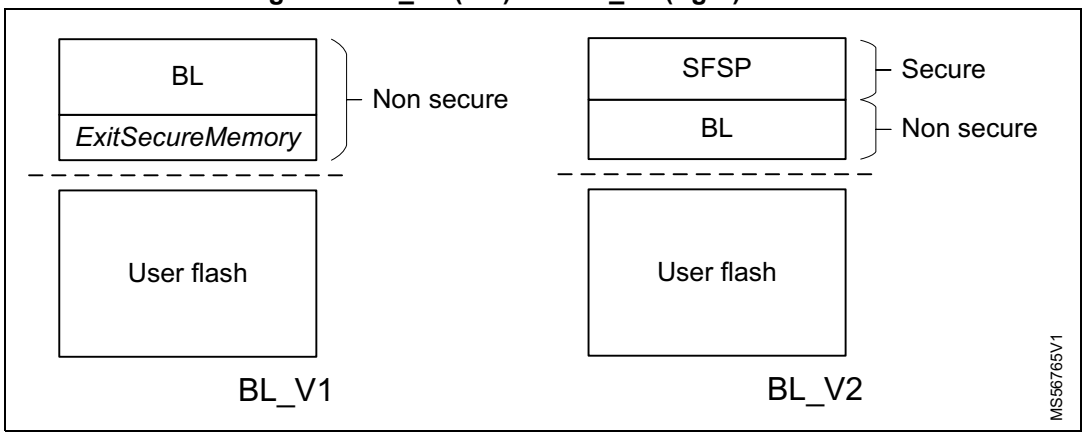
1. Legacy model - BL_V1 (see left side of *Figure 9*):

   The system memory is non secure and allocated to the bootloader. In some projects a SW (functionally independent from the bootloader) called ExitSecureMemory is implemented on the same zone as the BL.

2. New BL model - BL_V2 (see right side of *Figure 9*)

   The system memory is split between secure and nonsecure areas. The secure area contains the System Flash Secure Package (SFSP), the nonsecure contains the BL.

Figure 9. BL_V1 (left) and BL_V2 (right) models



4.10 Boot constraints on BL

Boot depends upon the MCU (see *Table 10*), and adds new constraints to the BL.

- Legacy products - Boot_V1
  When correctly set, the boot is directly on the BL (left side of *Figure 10*)
- Products with security but no TrustZone isolation - Boot_V2 (right side of *Figure 10*)
  When correctly set and boot on the BL is possible, the boot starts on the SFSP, then it jumps to the bootloader. This adds a constraint to the boot timing.
- Products with security using TrustZone isolation - Boot_V3
  On this category there are two possibilities:
  a) Boot depending on TrustZone value - Boot_V3_1 (see *Figure 11*)
  When TZEN is enabled, some constraints are added to the BL functionalities:
  > Boot timing is different from the TZEN disabled use case
  > Before jumping to the BL, the SFSP maps all the needed resources by the BL to the nonsecure domain. A jump from the BL (“Go” command) to an application using other resources does not work.
  > Some secure option bytes are not be accessible as the bootloader is nonsecure. Some APIs are added on the SFSP to guarantee that the BL can modify them on open products states (Open, RDP L0).
  > Some parts of the SRAM are used by the SFSP and remain on Secure domain when jumping to the BL, so are not accessible by the customer through BL
  b) Boot not depending on TrustZone value - Boot_V3_2 (see *Figure 12*)
  Boot goes through SFSP first, then jumps to the BL. In this model, some constraints are added to the BL functionalities on both TZEN states:
  > Boot timing includes SFSP timing.
  > Before jumping to the BL, the SFSP map all the needed resources by the BL to the nonsecure domain. A jump from the BL (“Go” command) to an application using other resources does not work.
  > Some secure option bytes are not be accessible by the Bootloader as it is nonsecure. Some APIs are added on the SFSP to guarantee that the BL can modify them on open products states (Open).

> Some parts of the SRAM are used by the SFSP and remain on Secure domain when jumping to the BL, consequently they are not accessible by the customer through BL.

Table 10. BL and boot by product series

Series	BL model	Boot
STM32H7	BL_V2	Boot_V2 (see *Figure 10*)
STM32L5, STM32U3, STM32U5, STM32WBA		Boot_V3_1 (see *Figure 11*)
STM32H5		Boot_V3_2 (see *Figure 12*)
Others	BL_V1	Boot_V1 (see *Figure 10*)

Figure 10. Boot_V1 (left) and Boot_V2 (right)

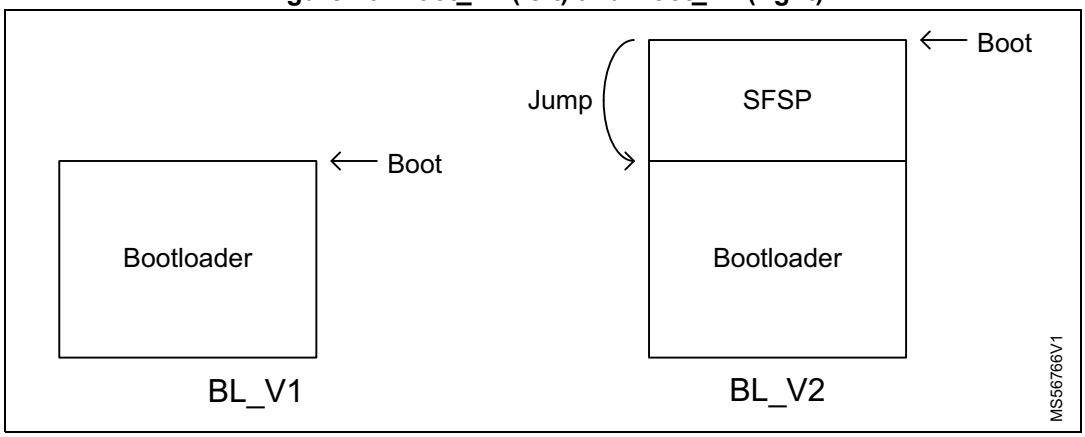


Figure 11. Boot_V3_1

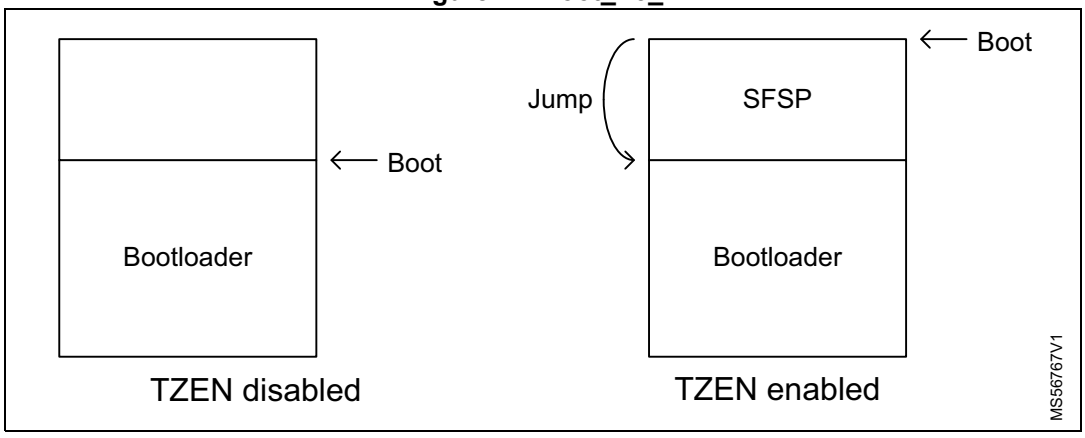
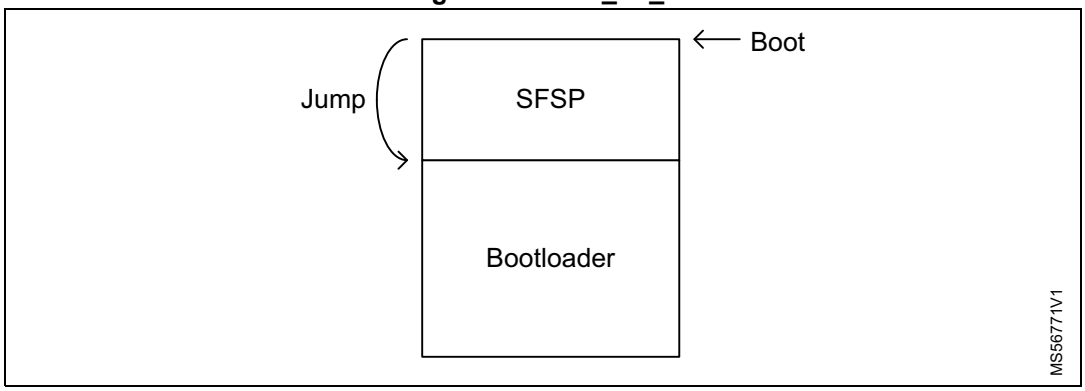


Figure 12. Boot_V3_2



4.11 Possibility to disable bootloader instances

When boot is configured to use the bootloader, the bootloader performs the following actions:

- De-initializes all resources (AHB/APB configurations, interrupts, clocks, power, flash)
- Reinitializes the IWDG and the clocks
- Configures all required interfaces and their pin assignments one by one (for example: USART1, USART2, I2C1, I2C2, USB DFU)
- Enters an infinite loop, waiting for a connection request from one of the supported interfaces

This may result in some GPIOs being configured with different settings, such as pull-up, pull-down, open-drain, or input mode.

The customer must be careful during board design and must avoid using the I/O pins required by the bootloader, or ensure that the actual pin state is compatible with their use.

To help customers and avoid related issues, a new option byte has been added to STM32 devices to enable or disable bootloader-supported interfaces, called **BL_COM_CFG**.

For each new bootloader, a new section is added describing how the bootloader interfaces are mapped within this option byte. This allows customers to choose which interfaces are enabled and which are disabled.

Example:

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved				Reserved				USB				FDCAN			
Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
I3C				SPI				I2C				USART			
Res.	Res.	Res.	Res.	Res.	Res.	Res.	SPI1	Res.	Res.	I2C2	I2C1	Res.	UART7	UART4	USART 1

If no description is found in the bootloader section, this means that this option byte does not exist on this STM32 device.

The default value of this option byte is 0xFFFFFFFF, so all bootloader interfaces are enabled.

5 STM32C011xx devices

5.1 Bootloader configuration

The STM32C011xx bootloader is activated by applying Pattern 11 (see *Table 2*). *Table 11* shows the hardware resources used by this bootloader.

Table 11. STM32C011xx configuration in system memory boot mode

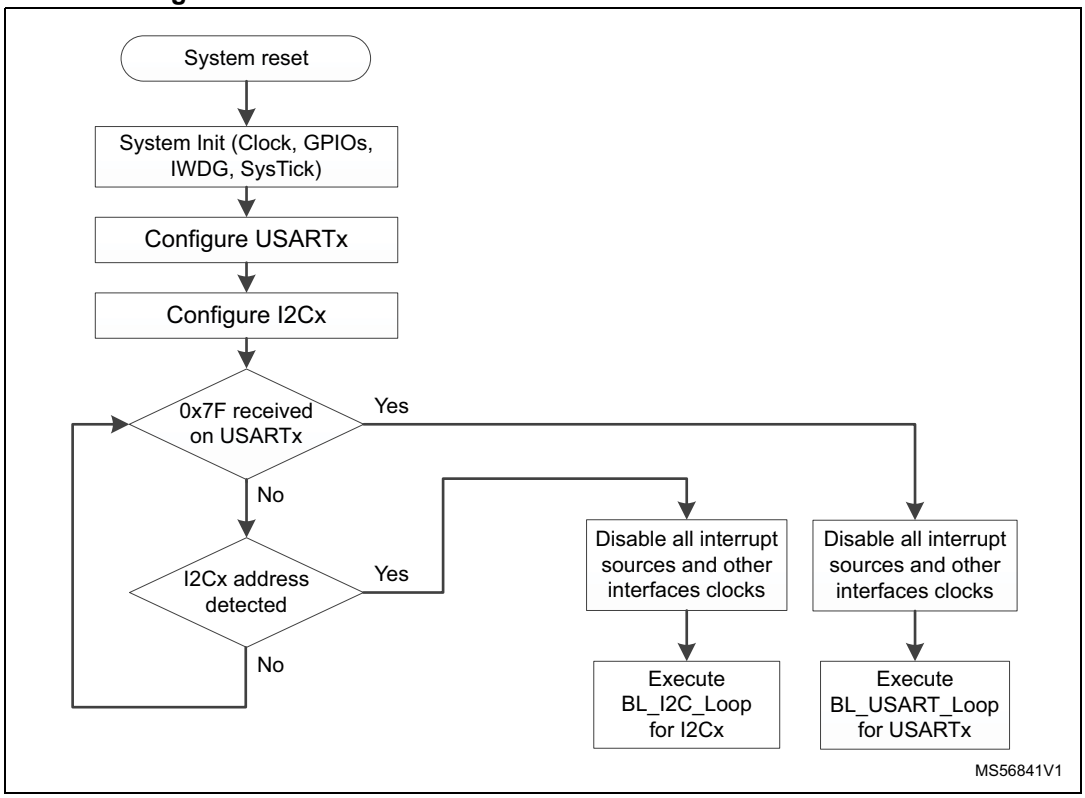
Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz (no PLL)
	RAM	-	3.5 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	6 Kbytes, starting from address 0x1FFF0000 contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset if the hardware IWDG option was previously enabled by the user.
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF1600
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1100100x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode
	I2C1_SDA pin		PB7 pin: data line is used in open-drain pull-up mode

Note: On WLCSP12, SO8N, TSSOP20, and UFQFN20 packages USART1 PA9/PA10 IOs are remapped on PA11/PA12.

5.2 Bootloader selection

Figure 13 shows the bootloader selection mechanism.

Figure 13. Bootloader V5.x selection for STM32C011xx devices



5.3 Bootloader version

Table 12 lists the STM32C011xx devices bootloader versions.

Table 12. STM32C011xx bootloader versions

Version number	Description	Known limitations
V5.1	Initial bootloader version	None

6 STM32C031xx devices

6.1 Bootloader configuration

The STM32C031xx bootloader is activated by applying Pattern 11 (see *Table 2*). *Table 13* shows the hardware resources used by this bootloader.

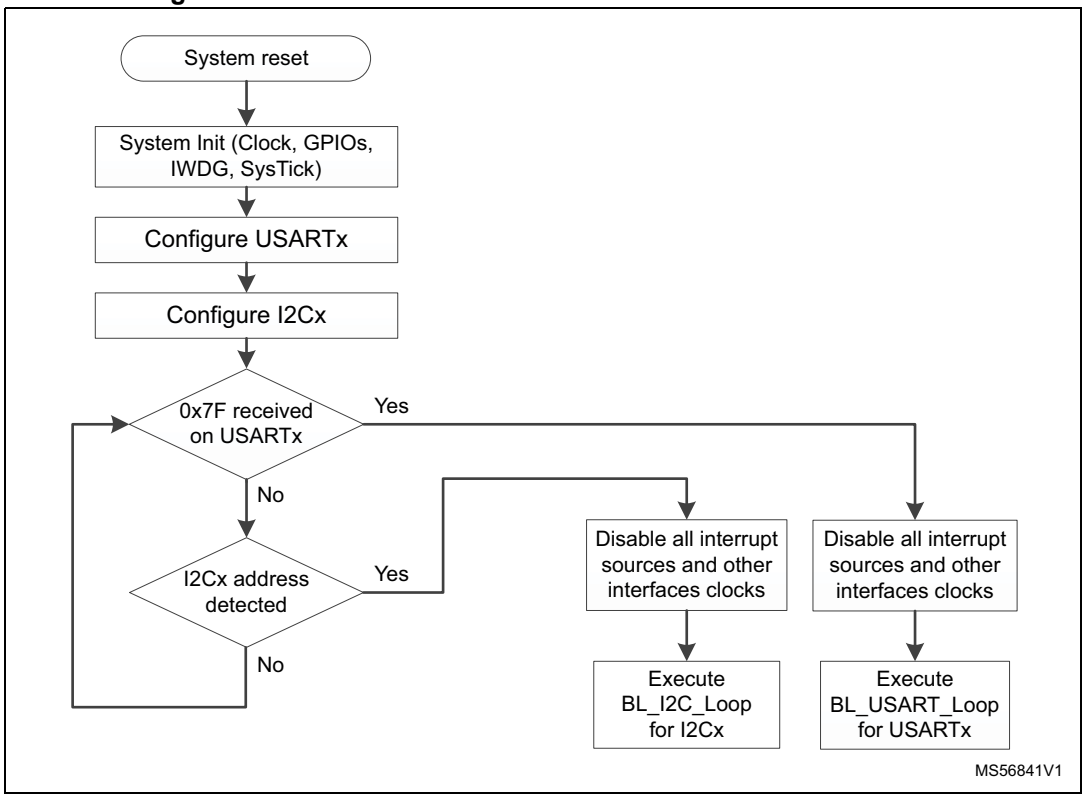
Table 13. STM32C031xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz (no PLL)
	RAM	-	3.5 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	6 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset if the hardware IWDG option was previously enabled by the user.
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF1600
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input pull-up mode. PA12 pin: remapped to PA10, as this pin does is not available on TSOPP20 and UFQFPN28 packages.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode. PA11 pin: remapped to PA9, as this pin does is not available on TSOPP20 and UFQFPN28 packages.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1100011x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain pull-up mode.

6.2 Bootloader selection

Figure 14 shows the bootloader selection mechanism.

Figure 14. Bootloader V5.x selection for STM32C031xx devices



6.3 Bootloader version

Table 14 lists the STM32C031xx devices bootloader versions.

Table 14. STM32C031xx bootloader versions

Version number	Description	Known limitations
V5.2	Initial bootloader version	None

7 STM32C051xx devices

7.1 Bootloader configuration

The STM32C051xx bootloader is activated by applying Pattern 11 (see *Table 2*). *Table 15* shows the hardware resources used by this bootloader.

Table 15. STM32C051xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz, derived directly from the HSI
	RAM	-	5 Kbytes, starting from address 0x2000 0000, are used by the bootloader firmware.
	System memory	-	12 Kbytes, starting from address 0x1FFF 0000, contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset if the hardware IWDG option was previously enabled by the user.
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF 2E00
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART in reception mode. PA12 pin: as PA10 pin does not exist on WLCSP15, TSSOP20, and UFQFN28, PA12 is remapped to PA10. Used in alternate function with pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART in transmission mode. PA11 pin: as PA9 pin does not exist on WLCSP15, TSSOP20, and UFQFN28, PA11 is to PA9. Kept in reset configuration until 0x7F detected on USART_RX.
USART2	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit.
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate function, pull-up mode
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX
	EXTI line 11	Input	Used for USART detection. Baudrate calculation is based on this line interrupt.

Table 15. STM32C051xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1110110x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain pull-up mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1110110x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin		PB11 pin: data line is used in open-drain pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Target mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: target data Input line, used in alternate function, pull-down mode.
	SPI1_MISO pin(1)	Output	PA6 pin: target data output line, used in alternate function, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: target clock line, used in alternate function, pull-down mode.
	SPI1_NSS pin		PA4 pin: slave chip select pin used in alternate function, pull-down mode.

Table 15. STM32C051xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: Slave data Input line, used in alternate function, pull-down mode.
	SPI2_MISO pin(1)	Output	PB14 pin: Slave data output line, used in alternate function, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: Slave clock line, used in alternate function, pull-down mode.
	SPI2_NSS pin		PB12 pin: slave chip select pin used in alternate function, pull-down mode.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

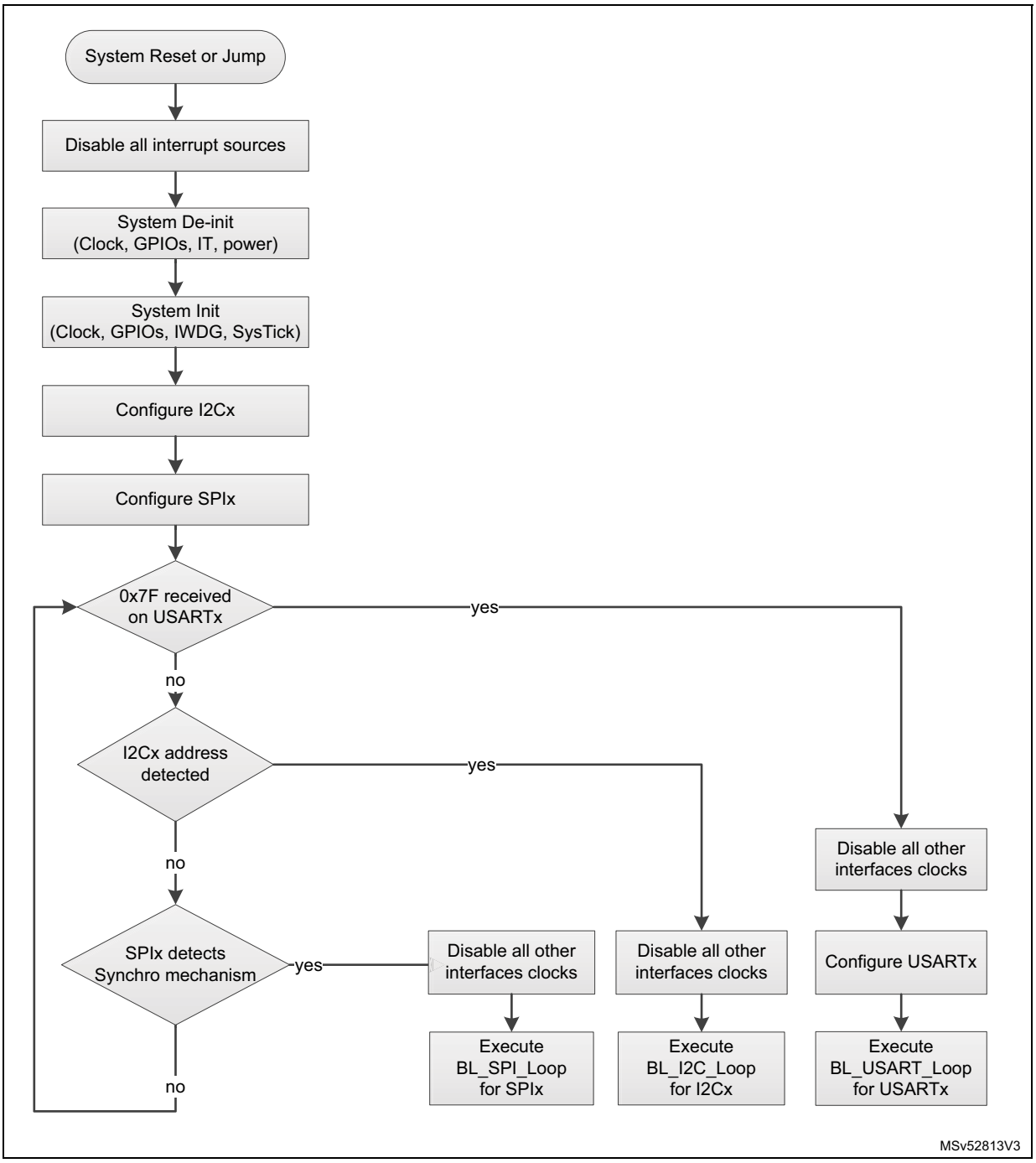
7.2 Boot model

The bootloader follows boot model V2 (see *Section 4.10*), there are no specific constraints.

7.3 Bootloader selection

Figure 15 shows the bootloader selection mechanism.

Figure 15. Bootloader V11.0 selection for STM32C051xx devices



7.4 Bootloader version

Table 16 lists the STM32C051xx devices bootloader versions.

Table 16. STM32C051xx bootloader versions

Version number	Description	Known limitations
V11.0	Initial bootloader version	Empty check flag cleared by error on the bootloader startup phase – Root cause: on the startup phase the bootloader SW performs a system deinitialization, leading to write the default value on the FLASH_ACR register, which overrides the Empty check bit with 0 – Behavior: when Empty check boot mode is used and the flash memory is empty, the MCU boots on the bootloader but the flag is cleared by the SW. If a reset is triggered, the system tries to boot on the empty flash memory, and crashes. – **Caution**: Avoid using reset on this case. if the system crashes, an option byte change or POR is needed to reboot.

8 STM32C071xx devices

8.1 Bootloader configuration

The STM32C071xx bootloader is activated by applying Pattern 11 (see *Table 2*). *Table 15* shows the hardware resources used by this bootloader.

Table 17. STM32C071xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz (no PLL)
		HSI48 enabled	The clock recovery system (CRS) is enabled for the DFU bootloader so that USB can be clocked by HSI48 48 MHz
	RAM	-	8.75 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset if the hardware IWDG option was previously enabled by the user.
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF1600
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin(1): USART1 in reception mode. Used in input pull-up mode.
	USART1_TX pin	Output	PA9 pin(1): USART1 in transmission mode. Set as input until USART1 is detected.
USART2	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit.
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Set as input until USART2 is detected.
	EXTI line 3	Input	Used for USART detection. Baudrate calculation is based on this line interrupt.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1110001x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain pull-up mode.

Table 17. STM32C071xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1110001x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin		PB11 pin: data line is used in open-drain pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Target mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: target data Input line, used in push-pull, pull-down mode.
	SPI1_MISO pin(2)	Output	PA6 pin: target data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: target clock line, used in push-pull, pull-down mode.
	SPI1_NSS pin		PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: Slave data Input line, used in push-pull, pull-down mode.
	SPI2_MISO pin(2)	Output	PB14 pin: Slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: Slave clock line, used in push-pull, pull-down mode.
	SPI2_NSS pin		PB12 pin: slave chip select pin used in push-pull, pull-down mode.

Table 17. STM32C071xx configuration in system memory boot mode (continued)

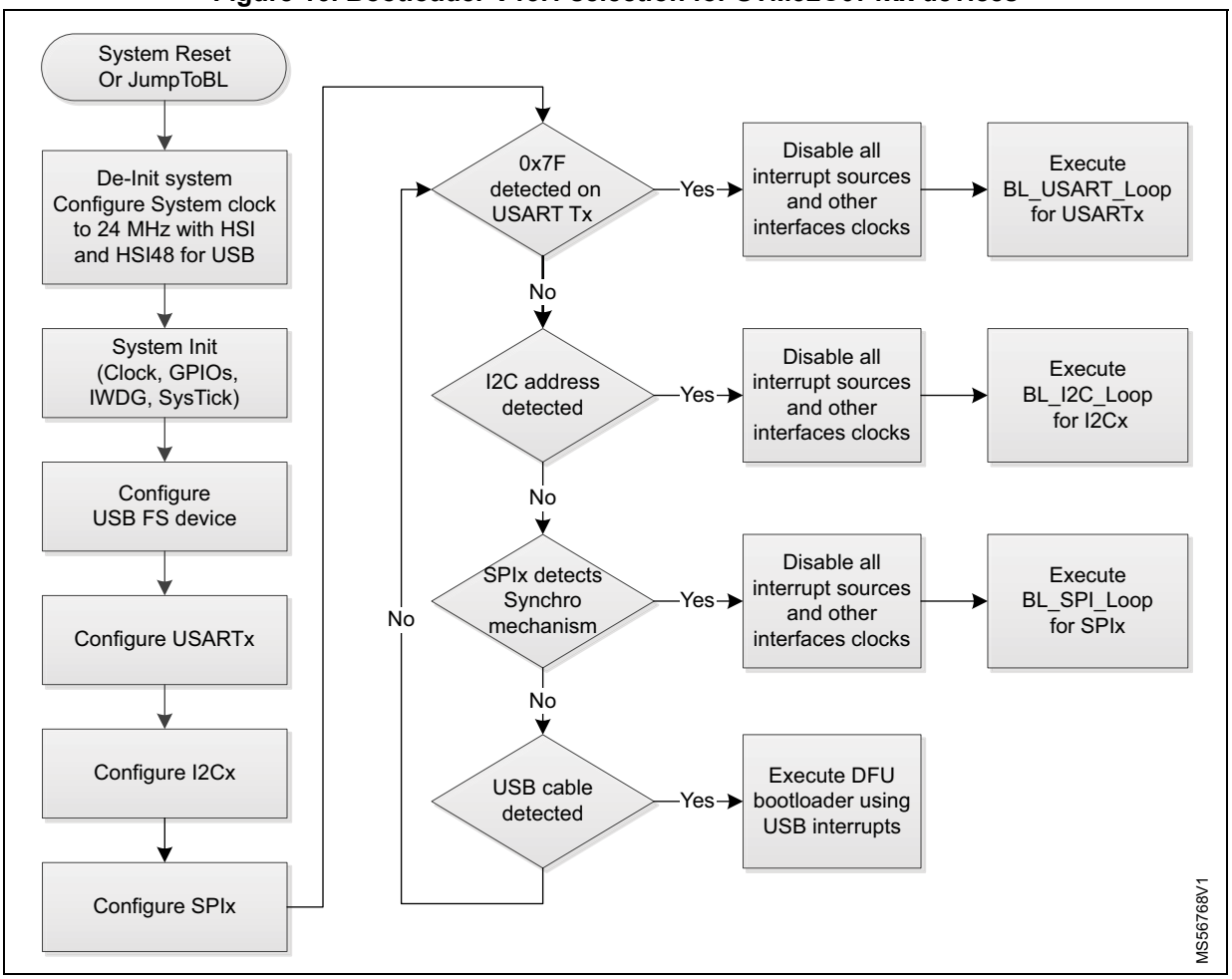
Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.

1. Differently from other STM32C0 products, USART1 is not remapped to PA11/PA12 on small packages, as these pins are used for the USB.
2. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

8.2 Bootloader selection

Figure 15 shows the bootloader selection mechanism.

Figure 16. Bootloader V13.1 selection for STM32C071xx devices



8.3 Bootloader version

Table 16 lists the STM32C071xx devices bootloader versions.

Table 18. STM32C071xx bootloader versions

Version number	Description	Known limitations
V13.1	Initial bootloader version	Empty check flag cleared by error on the startup phase – Root cause: during startup the bootloader SW performs a system deinitialization, leading to write the default value on the FLASH_ACR register, which overrides the Empty check bit with 0 – Behavior: when Empty check boot mode is used and the flash memory is empty, the MCU boots on the bootloader but the flag is cleared by the SW. If a reset is triggered, the system tries to boot on the empty flash memory, and crashes. Avoid using reset on this case. if the system crashes, an option byte change or POR is needed to reboot.

9 STM32C091xx/92xx devices

9.1 Bootloader configuration

The STM32C091xx/92xx bootloader is activated by applying Pattern 11 (see *Table 2*). *Table 15* shows the hardware resources used by this bootloader.

Table 19. STM32C091xx/92xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz, derived directly from the HSI
	RAM	-	5 Kbytes, starting from address 0x2000 0000, are used by the bootloader firmware.
	System memory	-	12 Kbytes, starting from address 0x1FFF 0000, contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset if the hardware IWDG option was previously enabled by the user.
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF 3E00
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART in reception mode. PA12 pin: as PA10 pin does not exist on TSSOP20, WLCSP24, and UFQFN28, PA12 is remapped to PA10. Used in alternate function with pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART in transmission mode. PA11 pin: as PA9 pin does not exist on TSSOP20, WLCSP24, and UFQFN28, PA11 is remapped to PA9. Kept in reset configuration until 0x7F detected on USART_RX.
USART2	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit.
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate function, pull-up mode
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX
	EXTI line 3	Input	Used for USART detection. Baudrate calculation is based on this line interrupt.

Table 19. STM32C091xx/92xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3	USART3	Enabled	Once initialized the USART3 configuration is: 8- bits, even parity and 1 Stop bit
	USART3_RX pin	Input	PC11 pin: USART in reception mode. Used in alternate function with pull-up mode
	USART3_TX pin	Output	PC10 pin: USART in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX
	EXTI line 11	Input	Used for USART detection. Baudrate calculation is based on this line interrupt
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1110111x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain pull-up mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1110111x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin		PB11 pin: data line is used in open-drain pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Target mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: target data Input line, used in alternate function, pull-down mode.
	SPI1_MISO pin(1)	Output	PA6 pin: target data output line, used in alternate function, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: target clock line, used in alternate function, pull-down mode.
	SPI1_NSS pin		PA4 pin: slave chip select pin used in alternate function, pull-down mode.

Table 19. STM32C091xx/92xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: Slave data Input line, used in alternate function, pull-down mode.
	SPI2_MISO pin(1)	Output	PB14 pin: Slave data output line, used in alternate function, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: Slave clock line, used in alternate function, pull-down mode.
	SPI2_NSS pin		PB12 pin: slave chip select pin used in alternate function, pull-down mode.
FDCAN1	FDCAN	Enabled(2)	Once initialized the FDCAN configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN_Rx pin	Input	FDCAN in reception mode. Used in alternate function with pull-up mode. – PB0 for WLCSP24, UFQFN28, UFQFN32, and LQFP32 – PD0 for UFQFN48, LQFP48, UFBGA64, and LQFP644
	FDCAN_Tx pin	Output	FDCAN in transmission mode. Used in alternate function with pull-up mode – PB1 for WLCSP24, UFQFN28, UFQFN32, and LQFP32 – PD1 for UFQFN48, LQFP48, UFBGA64, and LQFP64

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization, as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.
2. Only when enabled by engineering bytes. Not supported on TSSOP20 package, even if enabled by engineering bytes.

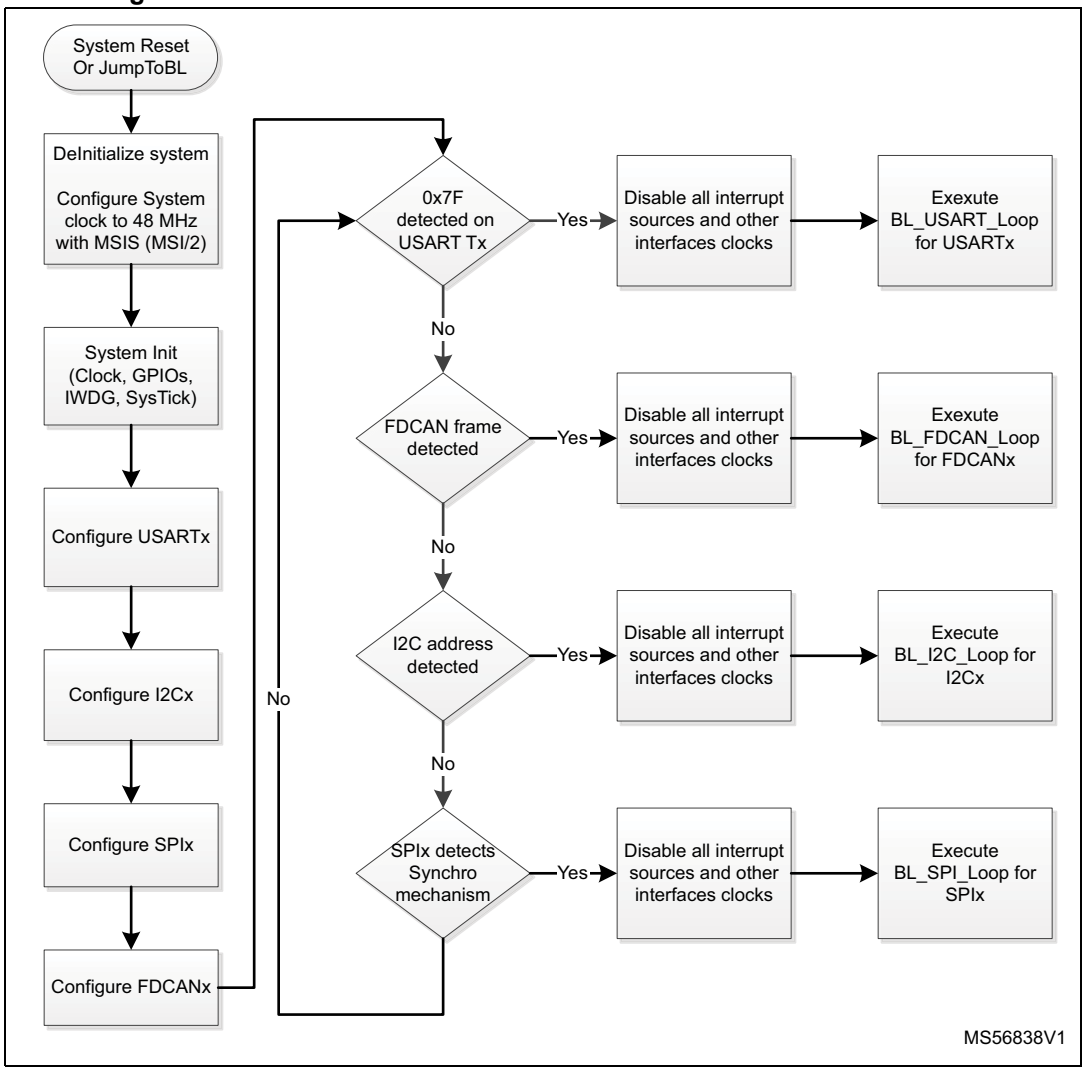
9.2 Boot model

The bootloader follows boot model V2 (see *Section 4.10*), there are no specific constraints.

9.3 Bootloader selection

Figure 15 shows the bootloader selection mechanism.

Figure 17. Bootloader V18.1 selection for STM32C091xx/92xx devices



9.4 Bootloader version

Table 16 lists the STM32C091xx/92xx devices bootloader versions.

Table 20. STM32C091xx/92xx bootloader versions

Version number	Description	Known limitations
V18.1	Initial bootloader version	Empty check flag cleared by error on the bootloader startup phase – Root cause: on the startup phase the bootloader SW performs a system deinitialization, leading to write the default value on the FLASH_ACR register, which overrides the Empty check bit with 0 – Behavior: when Empty check boot mode is used and the flash memory is empty, the MCU boots on the bootloader but the flag is cleared by the SW. If a reset is triggered, the system tries to boot on the empty flash memory, and crashes. – **Caution**: Avoid using reset on this case. if the system crashes, an option byte change or POR is needed to reboot.

10 STM32C531xx/532xx/542xx devices

10.1 Bootloader configuration

The STM32C531xx/532xx/542xx bootloader is activated by applying Pattern19 (see *Table 2*). *Table 21* shows the hardware resources used by this bootloader.

The bootloader follows boot model V1 (see *Section 4.10*), so it inherits all its constraints.

Table 21. STM32C531xx/532xx/542xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is derived from HSI which is 144 MHz divided by 3. So, 48 MHz (no PLL).
			Clock derived from HSI divided by 3 to have 48 MHz. The clock recovery system (CRS) is enabled for the DFU bootloader.
		HSE enabled	Enabled only when FDCAN is enabled on the ENGI and option bytes. Quartz value is detected using TIM17. Only values 12, 24, and 48 MHz are supported as source clock of the FDCAN. If no HSE detected or value do match the supported values, HSE is disabled and FDCAN clock is HSI/3.
	RAM	-	15 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	33 Kbytes, starting from address 0x0BF80080 contain the bootloader firmware.
	IWDG	-	The independent watchdog (IWDG) prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (in case the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to for the securable memory area is 0x0BF88400.
USART1	USART1	Enabled	Once initialized, the USART1 configuration is: 8 bits, even parity and 1 Stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.

Table 21. STM32C531xx/532xx/542xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART2	USART2	Enabled	Once initialized, the USART2 configuration is: 8 bits, even parity and 1 Stop bit.
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: in all packages except TSSOP20, QFN20, and QFN24. PB0 pin: in TSSOP20, QFN20, and QFN24 packages USART2 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.
UART4	UART4	Enabled	Once initialized, the UART4 configuration is: 8 bits, even parity and 1 Stop bit.
	UART4_RX pin	Input	PA1 pin: UART4 in reception mode. Used in alternate push-pull, pull-up mode.
	UART4_TX pin	Output	PA0 pin: UART4 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.
FDCAN2	FDCAN2	Enabled	Once initialized, the FDCAN2 configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN2_RX pin	Input	PB5 pin: FDCAN2 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN2_TX pin	Output	PB6 pin: FDCAN2 in transmission mode. Used in alternate push-pull, no pull mode.

Table 21. STM32C531xx/532xx/542xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1_MOSI pin	Input	PA7 pin: Slave data Input line, used in push-pull, pull-down mode.
	SPI1_MISO pin(1)	Output	PA6 pin: used in all packages except TSSOP20, QFN20, and QFN24. PB4 pin used for packages TSSOP20, QFN20, and QFN24. Slave data output line, used in push-pull, pull-down mode.
	SPI1_SCK pin	Input	PA5 pin: used in all packages except TSSOP20, QFN20, and QFN24. PB3 pin: used in packages TSSOP20, QFN20, and QFN24. Slave clock line, used in push-pull, pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: used in all packages except TSSOP20, QFN20, and QFN24. PA15 pin: used in packages TSSOP20, QFN20, and QFN24. Slave chip select pin used in push-pull, pull-down mode.
SPI2	SPI2_MOSI pin	Input	PB15 pin: Slave data Input line, used in push-pull, pull-down mode.
	SPI2_MISO pin(1)	Output	PB14 pin: Slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: Slave clock line, used in push-pull, pull-down mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/Output	PA11 pin: Not configured by bootloader SW.
	USB_DP pin		PA12 pin: Not configured by bootloader SW.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

Table 22. STM32C531xx/532xx/542xx special commands

Special commands supported (USART/SPI/FDCAN) Opcode – 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent**	**Number of data received**	**Data received (2 bytes)**	**Number of status data received (2 bytes)**	**Status data received**
Reset	0x02	0x4	0x0	0x0	NA	0x1	0x0
Erase EEPROM	0xA4	0x4	Page number to erase	0x0	NA	0x1	0x0

Note: USB special commands differ from other protocols due to USB protocol specificities:
- No opcode is used; the sub-opcode is used directly.
- The sub-opcode is treated as a single byte, not two bytes.
- Data is sent on the USB frame byte by byte; there is no need to specify the number of data bytes to be transmitted.
- Returned data and status are formatted according to the native USB protocol.

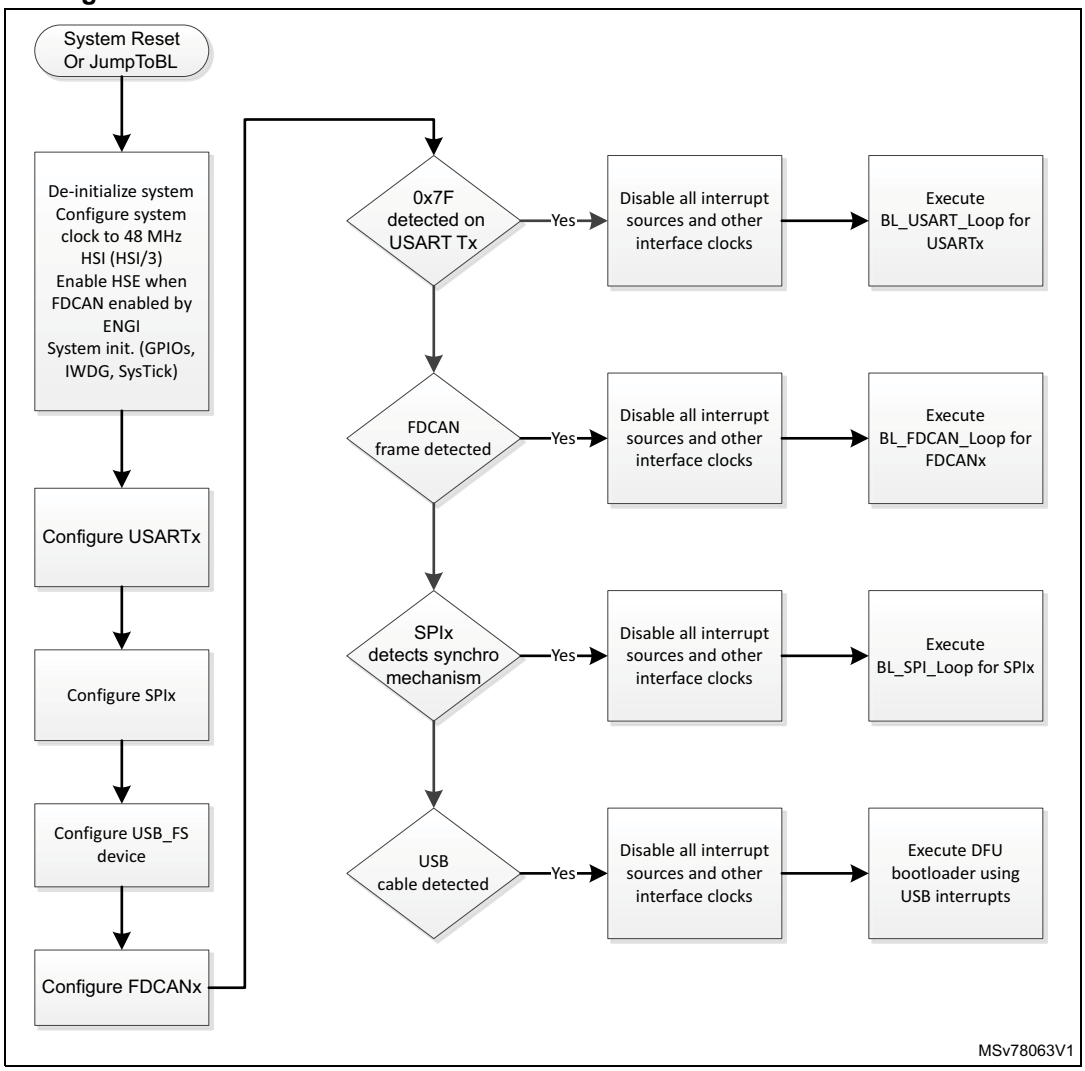
10.2 BL_COM_CFG mapping

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved				Reserved				USB				FDCAN			
Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	USB	Res.	Res.	Res.	FDCAN 2
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
I3C				SPI				I2C				USART			
Res.	Res.	Res.	Res.	Res.	Res.	SPI2	SPI1	Res.	Res.	Res.	Res.	Res.	USART 4	USART 2	USART 1

10.3 Bootloader selection

Figure 18 shows the bootloader selection mechanism.

Figure 18. Bootloader V16.x selection for STM32C531xx/532xx/542xx devices



10.4 Bootloader version

Table 23 lists the STM32C531xx/532xx/542xx devices bootloader versions.

Table 23. STM32C531xx/532xx/542xx bootloader versions

Bootloader version number	Description	Known limitations
V16.0	Initial bootloader version	None

11 STM32C55xxx/562xx devices

11.1 Bootloader configuration

The STM32C55xxx/562xx bootloader is activated by applying Pattern19 (see *Table 2*). *Table 24* shows the hardware resources used by this bootloader.

The bootloader follows boot model V1 (see *Section 4.10*), so it inherits all its constraints.

Table 24. STM32C55xxx/562xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is derived from HSI which is 144 MHz divided by 3. So, 48 MHz (no PLL).
			Clock derived from HSI divided by 3 to have 48 MHz. The clock recovery system (CRS) is enabled for the DFU bootloader.
		HSE enabled	Enabled only when FDCAN is enabled on the ENGI and option bytes. Quartz value is detected using TIM17. Only values 12, 24, and 48 MHz are supported as source clock of the FDCAN. If no HSE detected or value do match the supported values, HSE is disabled and FDCAN clock is HSI/3.
	RAM	-	15 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	33 Kbytes, starting from address 0x0BF80080 contain the bootloader firmware.
	IWDG	-	The independent watchdog (IWDG) prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (in case the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to for the securable memory area is 0x0BF88400.
USART1	USART1	Enabled	Once initialized, the USART1 configuration is: 8 bits, even parity and 1 Stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.

Table 24. STM32C55xxx/562xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART2	USART2	Enabled	Once initialized, the USART2 configuration is: 8 bits, even parity and 1 Stop bit.
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.
USART3	USART3	Enabled	Once initialized, the USART3 configuration is: 8 bits, even parity and 1 Stop bit.
	USART3_RX pin	Input	PD9 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PD8 pin:USART3 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.
UART4	UART4	Enabled	Once initialized, the UART4 configuration is: 8 bits, even parity and 1 Stop bit.
	UART4_RX pin	Input	PA1 pin: UART4 in reception mode. Used in alternate push-pull, pull-up mode.
	UART4_TX pin	Output	PA0 pin: UART4 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.
FDCAN1	FDCAN1	Enabled	Once initialized, the FDCAN1 configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_RX pin	Input	PB5 pin: FDCAN1 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN1_TX pin	Output	PB6 pin: FDCAN1 in transmission mode. Used in alternate push-pull, no pull mode.
SPI1	SPI1_MOSI pin	Input	PA7 pin: Slave data Input line, used in push-pull, pull-down mode.
	SPI1_MISO pin(1)	Output	PA6 pin: Slave data output line, used in push-pull, pull-down mode.
	SPI1_SCK pin	Input	PA5 pin: Slave clock line, used in push-pull, pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: Slave chip select pin used in push-pull, pull-down mode.

Table 24. STM32C55xxx/562xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2_MOSI pin	Input	PB15 pin: Slave data Input line, used in push-pull, pull-down mode.
	SPI2_MISO pin(1)	Output	PB14 pin: Slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: Slave clock line, used in push-pull, pull-down mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.
SPI3	SPI3_MOSI pin	Input	PB2 pin: Slave data Input line, used in push-pull, pull-down mode.
	SPI3_MISO pin(1)	Output	PB0 pin: Slave data output line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PB1 pin: Slave clock line, used in push-pull, pull-down mode.
	SPI3_NSS pin	Input	PB8 pin: slave chip select pin used in push-pull, pull-down mode.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/Output	PA11 pin: Not configured by bootloader SW.
	USB_DP pin		PA12 pin: Not configured by bootloader SW.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

Table 25. STM32C55xxx/562xx special commands

Special commands supported (USART/SPI/FDCAN) Opcode – 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent**	**Number of data received**	**Data received (2 bytes)**	**Number of status data received (2 bytes)**	**Status data received**
Reset	0x02	0x4	0x0	0x0	NA	0x1	0x0
Erase EEPROM	0xA4	0x4	Page number to erase	0x0	NA	0x1	0x0

Note: USB special commands differ from other protocols due to USB protocol specificities:
- No opcode is used; the sub-opcode is used directly.
- The sub-opcode is treated as a single byte, not two bytes.
- Data is sent on the USB frame byte by byte; there is no need to specify the number of data bytes to be transmitted.
- Returned data and status are formatted according to the native USB protocol.

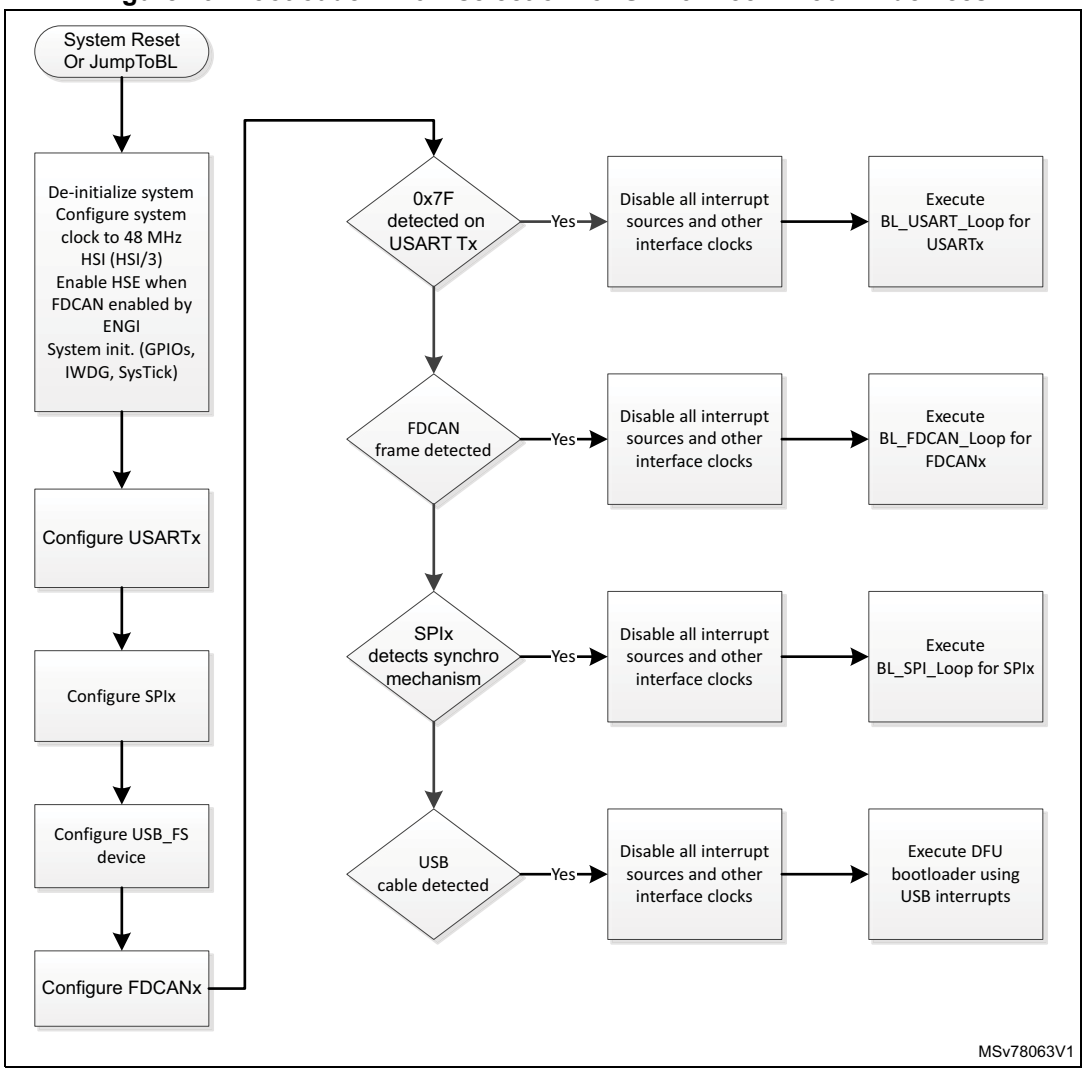
11.2 BL_COM_CFG mapping

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved				Reserved				USB				FDCAN			
Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	USB	Res.	Res.	Res.	FDCAN 1
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
I3C				SPI				I2C				USART			
Res.	Res.	Res.	Res.	Res.	SPI3	SPI2	SPI1	Res.	Res.	Res.	Res.	UART4	USART 3	USART 2	USART 1

11.3 Bootloader selection

Figure 19 shows the bootloader selection mechanism.

Figure 19. Bootloader V16.x selection for STM32C55xxx/562xx devices



11.4 Bootloader version

Table 23 lists the STM32C55xxx/562xx devices bootloader versions.

Table 26. STM32C55xxx/562xx bootloader versions

Bootloader version number	Description	Known limitations
V16.1	Initial bootloader version	None

12 STM32C5A3xx/59xxx devices

12.1 Bootloader configuration

The STM32C5A3xx/59xxx bootloader is activated by applying Pattern19 (see *Table 2*). *Table 27* shows the hardware resources used by this bootloader.

The bootloader follows boot model V1 (see *Section 4.10*), so it inherits all its constraints.

Table 27. STM32C5A3xx/59xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is derived from HSI which is 144 MHz divided by 3. So, 48 MHz (no PLL).
			Clock derived from HSI divided by 3 to have 48 MHz. The clock recovery system (CRS) is enabled for the DFU bootloader.
		HSE enabled	Enabled only when FDCAN is enabled on the ENGI and option bytes. Quartz value is detected using TIM17. Only values 12, 24, and 48 MHz are supported as source clock of the FDCAN. If no HSE detected or value do match the supported values, HSE is disabled and FDCAN clock is HSI/3.
	RAM	-	15 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	33 Kbytes, starting from address 0x0BF80080 contain the bootloader firmware.
	IWDG	-	The independent watchdog (IWDG) prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (in case the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to for the securable memory area is 0x0BF88400.
USART1	USART1	Enabled	Once initialized, the USART1 configuration is: 8 bits, even parity and 1 Stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.

Table 27. STM32C5A3xx/59xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART2	USART2	Enabled	Once initialized, the USART2 configuration is: 8 bits, even parity and 1 Stop bit.
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.
USART3	USART3	Enabled	Once initialized, the USART3 configuration is: 8 bits, even parity and 1 Stop bit.
	USART3_RX pin	Input	PD9 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PD8 pin:USART3 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.
UART4	UART4	Enabled	Once initialized, the UART4 configuration is: 8 bits, even parity and 1 Stop bit.
	UART4_RX pin	Input	PA1 pin: UART4 in reception mode. Used in alternate push-pull, pull-up mode.
	UART4_TX pin	Output	PA0 pin: UART4 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.
FDCAN2	FDCAN2	Enabled	Once initialized, the FDCAN2 configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN2_RX pin	Input	PB5 pin: FDCAN2 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN2_TX pin	Output	PB6 pin: FDCAN2 in transmission mode. Used in alternate push-pull, no pull mode.
SPI1	SPI1_MOSI pin	Input	PA7 pin: Slave data Input line, used in push-pull, pull-down mode.
	SPI1_MISO pin(1)	Output	PA6 pin: Slave data output line, used in push-pull, pull-down mode.
	SPI1_SCK pin	Input	PA5 pin: Slave clock line, used in push-pull, pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: Slave chip select pin used in push-pull, pull-down mode.

Table 27. STM32C5A3xx/59xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2_MOSI pin	Input	PB15 pin: Slave data Input line, used in push-pull, pull-down mode.
	SPI2_MISO pin(1)	Output	PB14 pin: Slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: Slave clock line, used in push-pull, pull-down mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.
SPI3	SPI3_MOSI pin	Input	PB2 pin: Slave data Input line, used in push-pull, pull-down mode.
	SPI3_MISO pin(1)	Output	PB0 pin: Slave data output line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PB1 pin: Slave clock line, used in push-pull, pull-down mode.
	SPI3_NSS pin	Input	PB8 pin: slave chip select pin used in push-pull, pull-down mode.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/Output	PA11 pin: Not configured by bootloader SW.
	USB_DP pin		PA12 pin: Not configured by bootloader SW.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

Table 28. STM32C5A3xx/59xxx special commands

Special commands supported (USART/SPI/FDCAN) Opcode – 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent**	**Number of data received**	**Data received (2 bytes)**	**Number of status data received (2 bytes)**	**Status data received**
Reset	0x02	0x4	0x0	0x0	NA	0x1	0x0
Erase EEPROM	0xA4	0x4	Page number to erase	0x0	NA	0x1	0x0

Note: USB special commands differ from other protocols due to USB protocol specificities:
- No opcode is used; the sub-opcode is used directly.
- The sub-opcode is treated as a single byte, not two bytes.
- Data is sent on the USB frame byte by byte; there is no need to specify the number of data bytes to be transmitted.
- Returned data and status are formatted according to the native USB protocol.

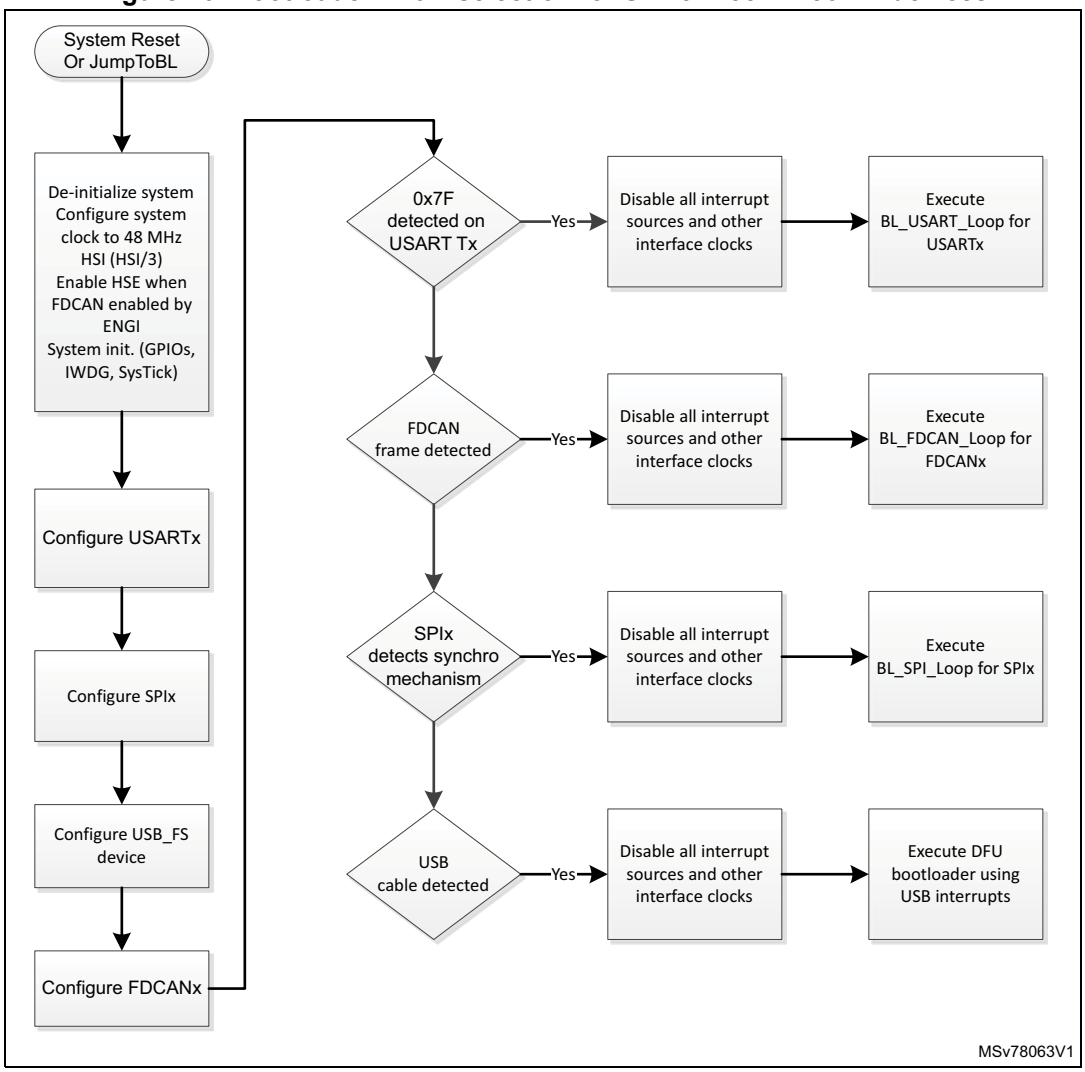
12.2 BL_COM_CFG mapping

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved				Reserved				USB				FDCAN			
Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	USB	Res.	Res.	FDCAN 2	Res.
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
I3C				SPI				I2C				USART			
Res.	Res.	Res.	Res.	Res.	SPI3	SPI2	SPI1	Res.	Res.	Res.	Res.	UART4	USART 3	USART 2	USART 1

12.3 Bootloader selection

Figure 19 shows the bootloader selection mechanism.

Figure 20. Bootloader V16.x selection for STM32C55xxx/562xx devices



12.4 Bootloader version

Table 23 lists the STM32C55xxx/562xx devices bootloader versions.

Table 29. STM32C55xxx/562xx bootloader versions

Bootloader version number	Description	Known limitations
V16.0	Initial bootloader version	None

13 STM32F03xx4/6 devices

13.1 Bootloader configuration

The STM32F03xx4/6 bootloader is activated by applying Pattern 2 (see *Table 2*). *Table 30* shows the hardware resources used by this bootloader.

Table 30. STM32F03xx4/6 configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz (using PLL clocked by HSI). 1 flash Wait State.
	RAM	-	2 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	3 Kbytes, starting from address 0x1FFFEC00 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset if the hardware IWDG option was previously enabled by the user.
USART1 (on PA10/PA9)	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART1 (on PA14/PA15)	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA15 pin: USART1 in reception mode. Used in input pull-up mode.
	USART1_TX pin	Output	PA14 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART1s	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.

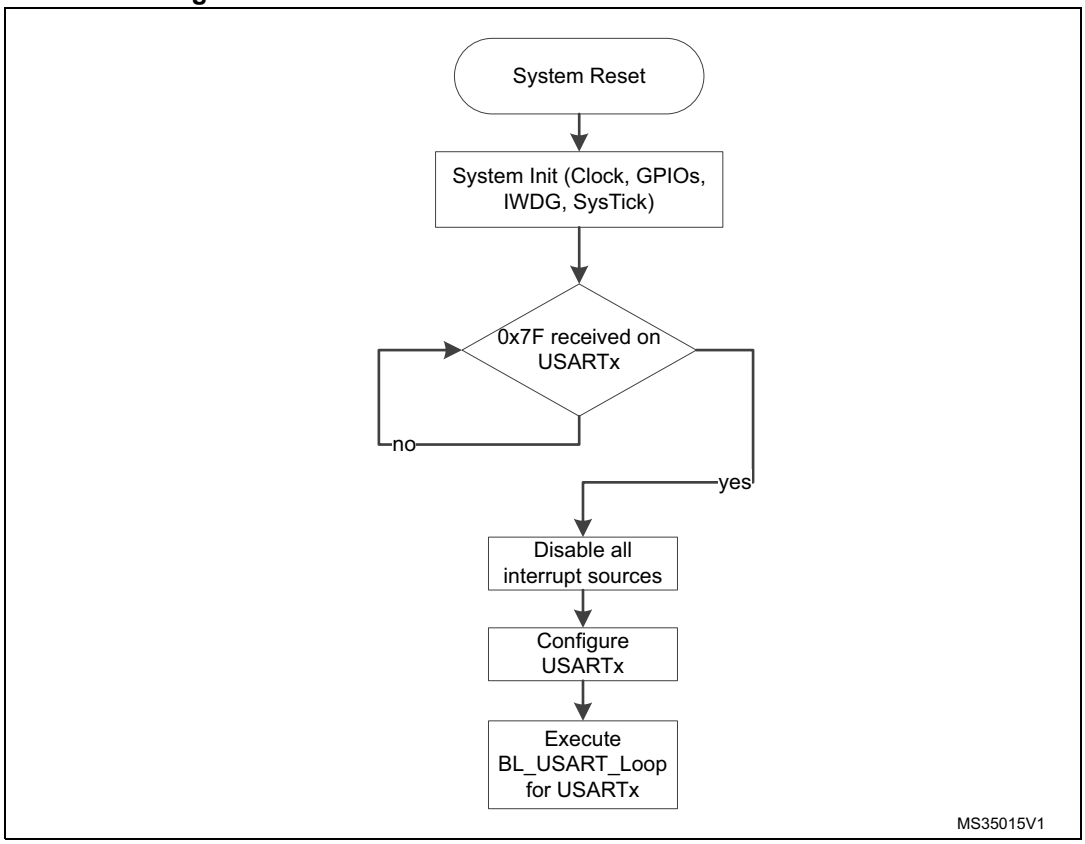
The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

Note: After the STM32F03xx4/6 device has booted in bootloader mode, serial wire debug (SWD) communication is no longer possible until the system is reset. This is because the SWD uses the PA14 pin (SWCLK), already used by the bootloader (USART1_TX).

13.2 Bootloader selection

Figure 21 shows the bootloader selection mechanism.

Figure 21. Bootloader selection for STM32F03xx4/6 devices



13.3 Bootloader version

Table 31 lists the STM32F03xx4/6 devices bootloader versions.

Table 31. STM32F03xx4/6 bootloader versions

Version number	Description	Known limitations
V1.0	Initial bootloader version	For the USART interface, two consecutive NACKs instead of one are sent when a Read Memory or Write Memory command is sent and the RDP level is active.

14 STM32F030xC devices

14.1 Bootloader configuration

The STM32F030xC bootloader is activated by applying Pattern 2 (see *Table 2*). *Table 32* shows the hardware resources used by this bootloader.

Table 32. STM32F030xC configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 48 MHz with HSI 8 MHz as clock source.
	RAM	-	6 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contain the bootloader firmware.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 (on PA2/PA3)	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input pull-up mode.
USART2 (on PA14/PA15)	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA15 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA14 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON Target 7-bit address: 0b1000001x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.

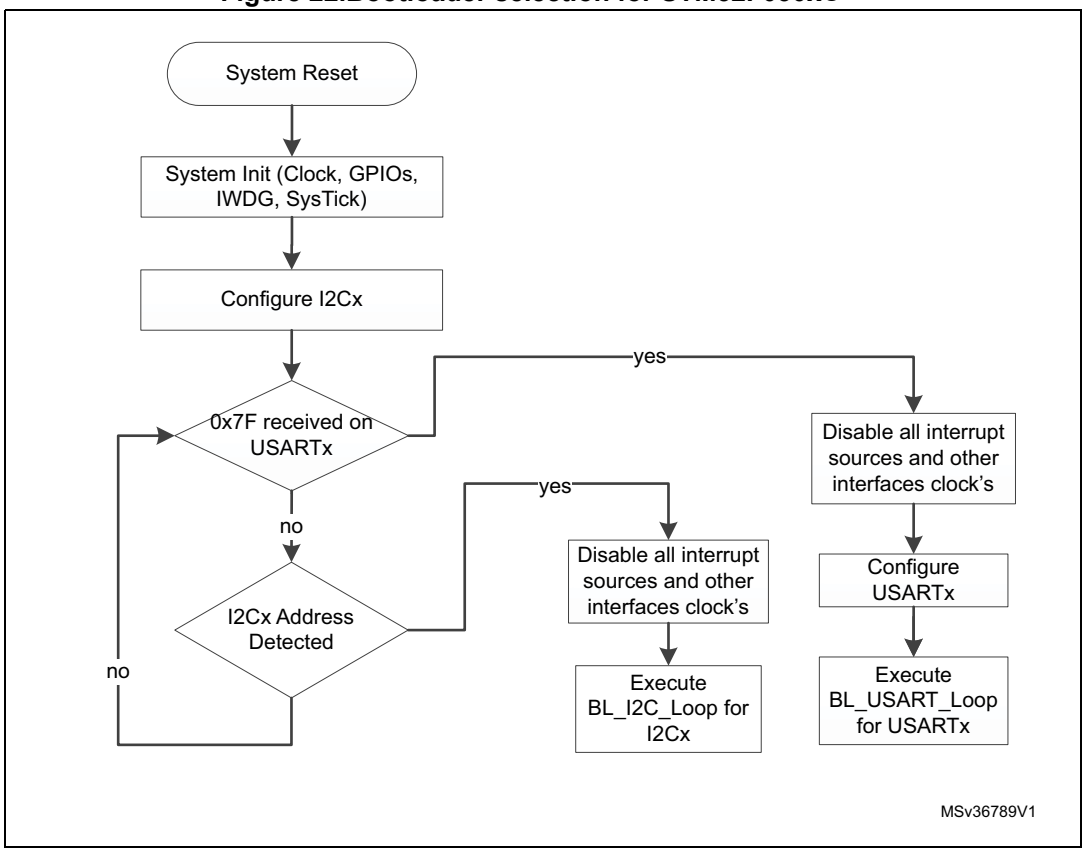
Note: After the devices have booted in bootloader mode using USART2, the serial wire debug (SWD) communication is no more possible until the system is reset, because SWD uses PA14 pin (SWCLK), already used by the bootloader (USART2_RX).

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

14.2 Bootloader selection

Figure 22 shows the bootloader selection mechanism.

Figure 22.Bootloader selection for STM32F030xC



14.3 Bootloader version

Table 33 lists the STM32F030xC devices bootloader versions.

Table 33. STM32F030xC bootloader versions

Version number	Description	Known limitations
V5.2	Initial bootloader version	PA13 is set in input pull-up mode even if not used by the bootloader

15 STM32F05xxx and STM32F030x8 devices

15.1 Bootloader configuration

The STM32F05xxx and STM32F030x8 devices bootloader is activated by applying Pattern 2 (described in *Table 2*). *Table 34* shows the hardware resources used by this bootloader.

Table 34. STM32F05xxx and STM32F030x8 devices configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz (using PLL clocked by HSI). 1 flash Wait State.
	RAM	-	2 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	3 Kbytes, starting from address 0x1FFFEC00, contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset if the hardware IWDG option was previously enabled by the user.
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit.
	USART2_RX pin	Input	PA15 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA14 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.

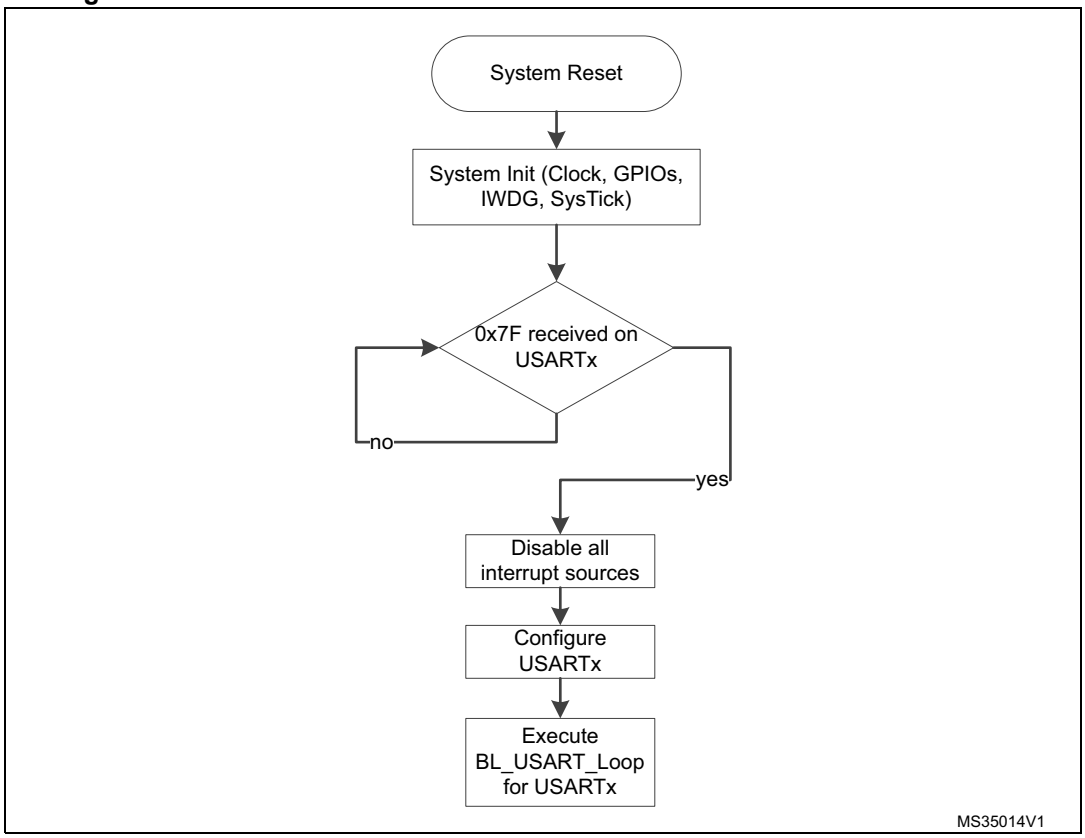
The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

Note: After the STM32F05xxx and STM32F030x8 devices have booted in bootloader mode, the serial wire debug (SWD) communication is no more possible until the system is reset, because SWD uses PA14 pin (SWCLK), already used by the bootloader (USART2_TX).

15.2 Bootloader selection

Figure 23 shows the bootloader selection mechanism.

Figure 23. Bootloader selection for STM32F05xxx and STM32F030x8 devices



15.3 Bootloader version

Table 35 lists the STM32F05xxx and STM32F030x8 devices bootloader versions.

Table 35. STM32F05xxx and STM32F030x8 devices bootloader versions

Version number	Description	Known limitations
V2.1	Initial bootloader version	– At bootloader startup, the HSITRIM value is set to 0 (in HSITRIM bits on RCC_CR register) instead of default value (16), as a consequence a deviation is generated in crystal measurement. For better results, use the smallest supported crystal value (i.e. 4 MHz). – For the USART interface, two consecutive NACKs instead of 1 NACK are sent when a Read Memory or Write Memory command is sent and the RDP level is active. – PA13 is set in input pull-up mode even if not used by the Bootloader.

16 STM32F04xxx devices

16.1 Bootloader configuration

The STM32F04xxx bootloader is activated by applying Pattern 6 (described in *Table 2*). *Table 36* shows the hardware resources used by this bootloader.

Table 36. STM32F04xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 48 MHz with HSI48 48 MHz as clock source.
		-	The clock recovery system (CRS) is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz.
	RAM	-	6 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	13 Kbytes, starting from address 0x1FFFC400, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA15 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA14 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111110x (x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.

Table 36. STM32F04xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB used in FS mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line No external pull-up resistor is required. Used in alternate push-pull, no pull mode.

Note: After the devices have booted in bootloader mode using USART2, the serial wire debug (SWD) communication is no more possible until the system is reset, because SWD uses PA14 pin (SWCLK), already used by the bootloader (USART2_RX).

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

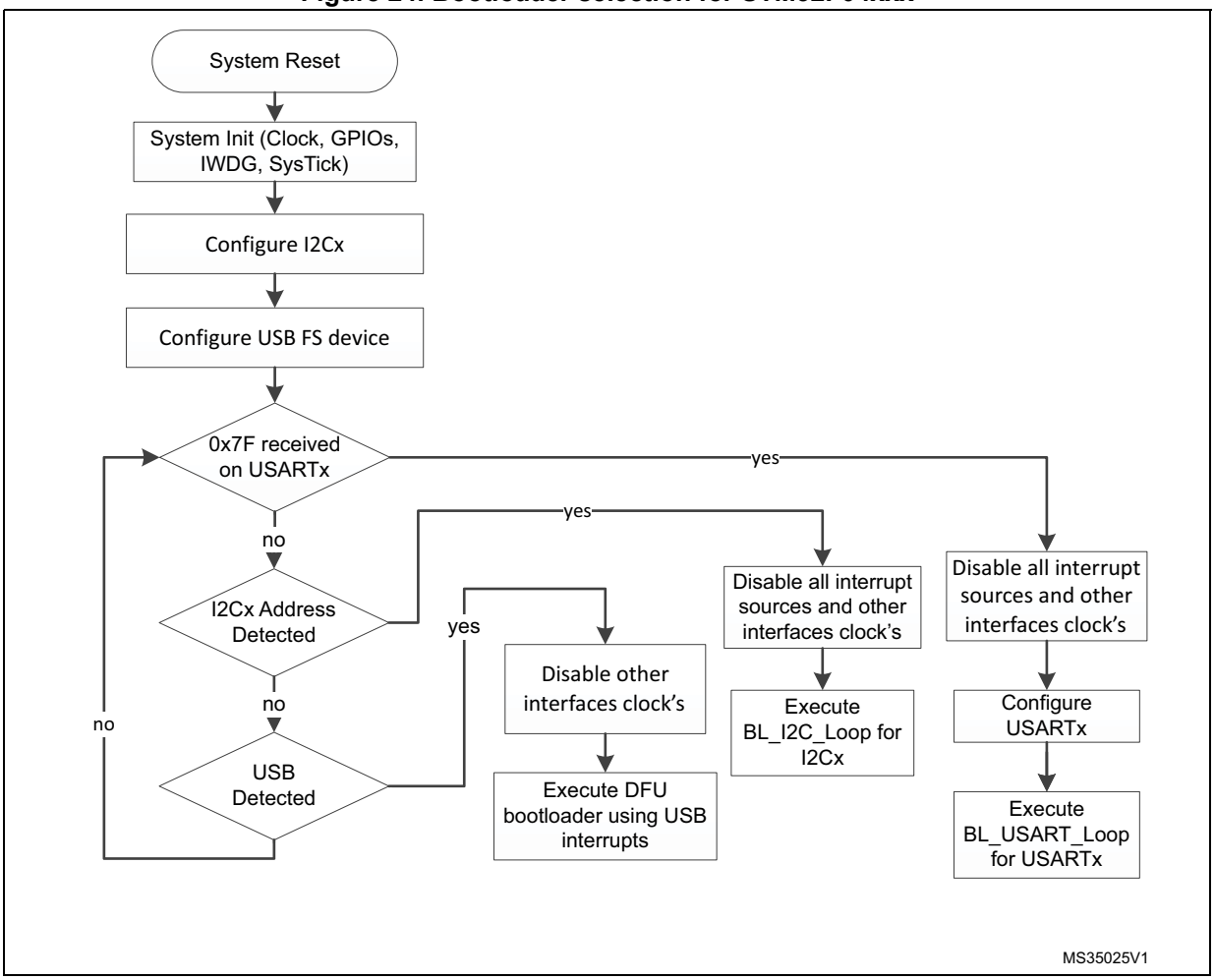
Note: Due to empty check mechanism present on these products, it is not possible to jump from user code to system bootloader. Such jump goes back to user flash memory space. If the first four bytes of user flash (at 0x0800 0000) are empty at the moment of jump (that is, erase first sector before jump or execute code from SRAM while flash is empty), the system bootloader is executed when jumped to. To jump to the bootloader one of the following three conditions must be fulfilled

- First four bytes of UserFlash = 0xFFFFFFFF
- Boot_SW = 0
- PB8 or PF11 State = 1
PB8 for packages LQFP32 and lower (except QFN32)
PF11 for packages QFN32 and higher (except LQFP32)

16.2 Bootloader selection

Figure 24 shows the bootloader selection mechanism.

Figure 24. Bootloader selection for STM32F04xxx



16.3 Bootloader version

Table 37. STM32F04xxx bootloader versions

Version number	Description	Known limitations
V10.0	Initial bootloader version	– At bootloader startup, the HSITRIM value is set to 0 (in HSITRIM bits on RCC_CR register) instead of default value (16), as a consequence a deviation is generated in crystal measurement. For better results, use the smallest supported crystal value (4 MHz). PA13 is set in input pull-up mode even if not used by the bootloader. – USB bootloader fails on some machines using a high speed controller. The bootloader is detected. but then data transaction fails. Root causes: De-synchronization between USB controller and bootloader SW due to the controller high speed transactions. Controller high speed inter-packet delay seems not sufficient for the bootloader SW (based on interrupt routines) to serve all needed transactions (the delay needed by the BL is nearly 25 µs). Some servicing IT are missed. This results in a communication fail, causing Write command to fail. Workarounds: Add USB HUB between host and the MCU. This relaxes transactions inter-packet delay, and allows the BL SW to perform correctly the task. Use USB controller/host that increase inter-packet delay. On new designs, use DFU SW that fix the issue in user flash memory.
V10.1	Add dynamic support of USART/USB interfaces on PA11/12 IOs for small packages	

17 STM32F070x6 devices

17.1 Bootloader configuration

The STM32F070x6 bootloader is activated by applying Pattern 6 (described in *Table 2*). *Table 38* shows the hardware resources used by this bootloader.

Table 38. STM32F070x6 configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	At startup, the system clock frequency is configured to 48 MHz using the HSI. If an external clock (HSE) is not present, the system is kept clocked from the HSI.
		HSE enabled	The external clock can be used for all bootloader interfaces and must have one of the following values: 24, 18, 16, 12, 8, 6, 4 MHz. The PLL is used to generate 48 MHz for USB and system clock.
		-	The CSS interrupt is enabled for HSE. Any failure (or removal) of the external clock generates system reset.
	RAM	-	6 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	13 Kbytes, starting from address 0x1FFFC400, contain the bootloader firmware.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA15 pin: USART2 in reception mode
	USART2_TX pin	Output	PA14 pin: USART2 in transmission mode
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address, Target mode – Analog filter ON – Target 7-bit address: 0b0111110x x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain mode.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11 pin: USB FS DM line
	USB_DP pin		PA12 pin: USB FS DP line. No external pull-up resistor is required.

Note: If HSI deviation exceeds 1% the bootloader might not function correctly.

Note: After the STM32F070x6 *devices have booted in bootloader mode using USART2, the serial wire debug (SWD) communication is no more possible until the system is reset, because SWD uses PA14 pin (SWCLK), already used by the bootloader (USART2_RX).*

The bootloader has two cases of operation depending on the presence of the external clock (HSE) at bootloader startup:

- If HSE is present and has a value of 24, 18, 16, 12, 8, 6, or 4 MHz, the system clock is configured to 48 MHz with HSE as clock source. The DFU interface, USART1, USART2, and I2C1 are functional and can be used to communicate with the bootloader device.
- If HSE is not present, the HSI is kept as default clock source and only USART1, USART2, and I2C1 are functional.

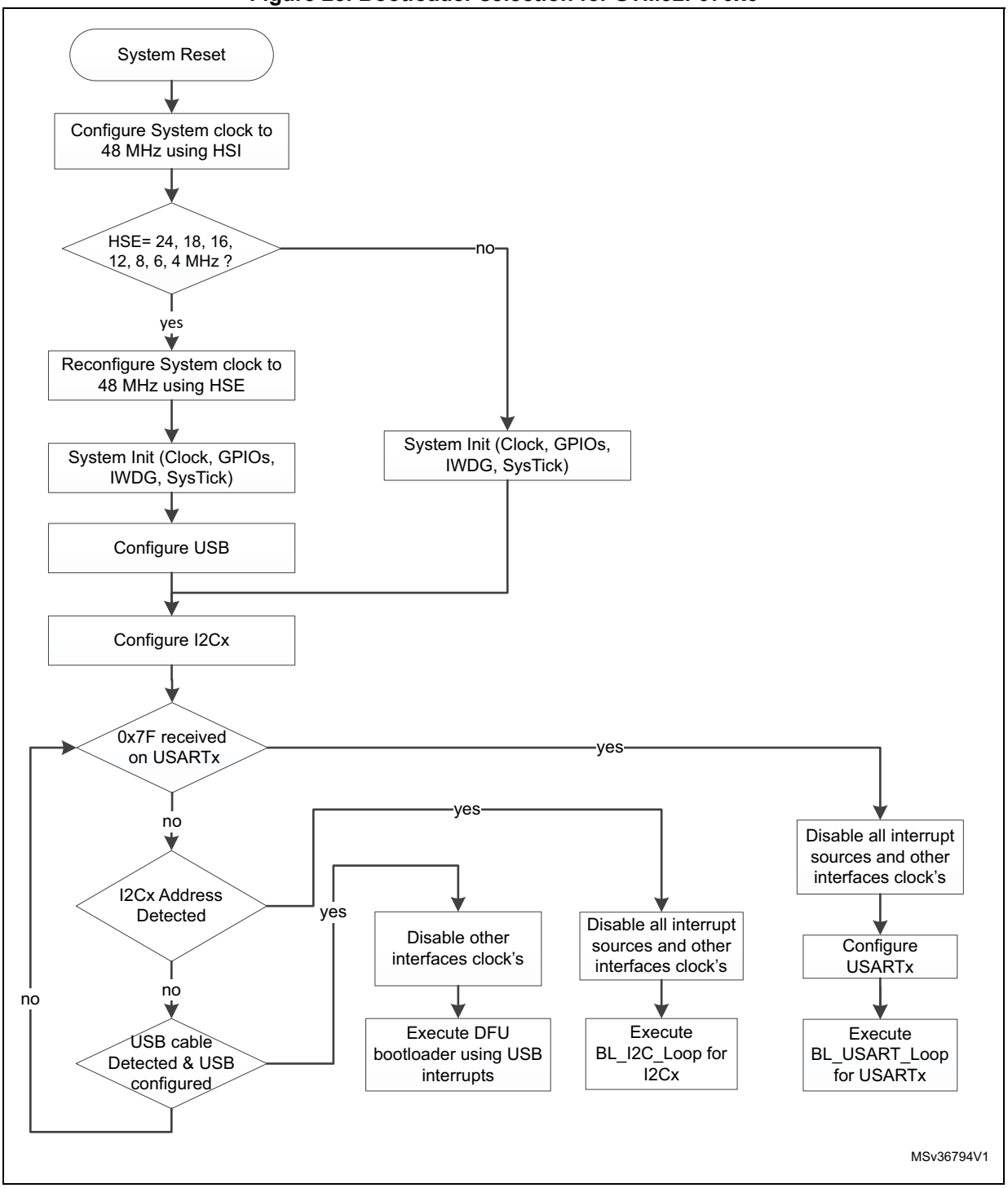
The external clock (HSE) must be kept if it is connected at bootloader startup, because it is used as system clock source.

Note: Due to empty check mechanism present on this product, it is not possible to jump from user code to system bootloader. Such jump results in a jump back to user flash space, but if the first four bytes of user flash (at 0x0800 0000) are empty at the moment of jump (i.e. erase first sector before jump or execute code from SRAM while flash is empty), then system bootloader is executed when jumped to.

17.2 Bootloader selection

Figure 25 shows the bootloader selection mechanism.

Figure 25. Bootloader selection for STM32F070x6



17.3 Bootloader version

Table 39 lists the STM32F070x6 devices bootloader versions.

Table 39. STM32F070x6 bootloader versions

Version number	Description	Known limitations
V10.2	Initial bootloader version	– At bootloader startup, the HSITRIM value is set to 0 (in HSITRIM bits on RCC_CR register) instead of default value (16), as a consequence a deviation is generated in crystal measurement. For better results, use the smallest supported crystal value (4 MHz). – USB bootloader fails on some machines using a high speed controller. The bootloader is detected. but then data transaction fails. Root causes: De-synchronization between USB controller and bootloader SW due to the controller high speed transactions. Controller high speed inter-packet delay seems not sufficient for the bootloader SW (based on interrupt routines) to serve all needed transactions (the delay needed by the BL is nearly 25 µs). Some servicing IT are missed. This results in a communication fail, causing Write command to fail. Workarounds: Add USB HUB between host and the MCU. This relaxes transactions inter-packet delay, and allows the BL SW to perform correctly the task. Use USB controller/host that increase inter-packet delay. On new designs, use DFU SW that fix the issue in user flash memory.
V10.3	Clock configuration fixed to HSI 8 MHz	

18 STM32F070xB devices

18.1 Bootloader configuration

The STM32F070xB bootloader is activated by applying Pattern 2 (described in *Table 2*). *Table 40* shows the hardware resources used by this bootloader.

Table 40. STM32F070xB configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	At startup, the system clock frequency is configured to 48 MHz using the HSI. If an external clock (HSE) is not present, the system is kept clocked from the HSI.
		HSE enabled	The external clock can be used for all bootloader interfaces and must have one of the following values: 24, 18, 16, 12, 8, 6, 4 MHz. The PLL is used to generate 48 MHz for USB and system clock.
		-	The clock security system (CSS) interrupt is enabled for HSE. Any failure (or removal) of the external clock generates a system reset.
	RAM	-	6 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	12 Kbytes, starting from address 0x1FFFC800, contain the bootloader firmware.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input pull-up mode
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA15 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA14 pin: USART2 in transmission mode. Used in input pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111011x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.

Table 40. STM32F070xB configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11 pin: USB FS DM line used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB FS DP line used in alternate push-pull, no pull mode. No external pull-up resistor is required.

Note: If HSI deviation exceeds 1% the bootloader might not function correctly.

Note: After the devices have booted in bootloader mode using USART2, the serial wire debug (SWD) communication is no more possible until the system is reset, because SWD uses PA14 pin (SWCLK), already used by the bootloader (USART2_RX).

The bootloader has two cases of operation depending on the presence of the external clock (HSE) at bootloader startup:

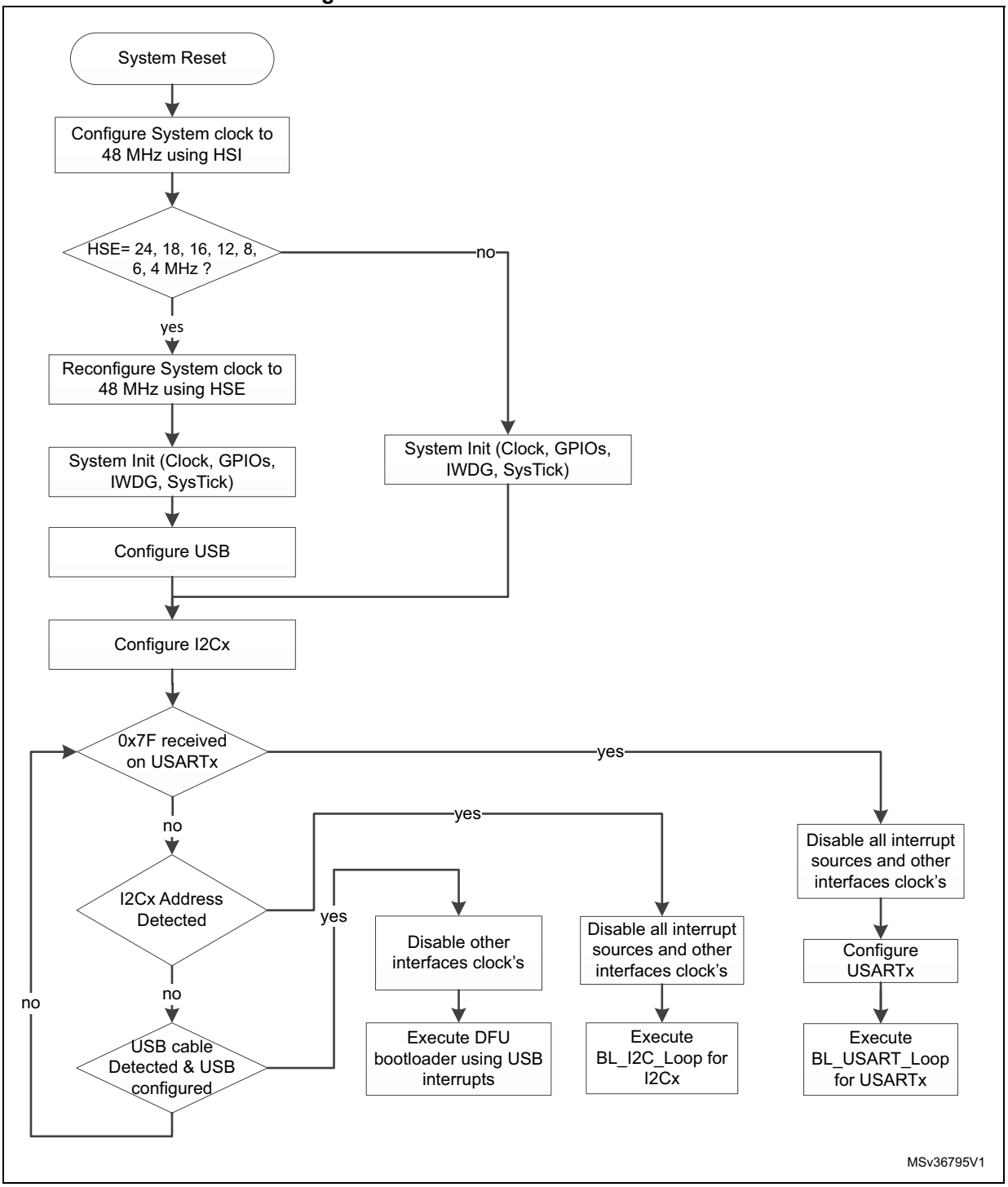
- If HSE is present and has a value of 24, 18, 16, 12, 8, 6, or 4 MHz, the system clock is configured to 48 MHz with HSE as clock source. The DFU interface, USART1, USART2, and I2C1 are functional and can be used to communicate with the bootloader device.
- If HSE is not present, the HSI is kept as default clock source and only USART1, USART2, and I2C1 are functional.

The external clock (HSE) must be kept if it is connected at bootloader startup, because it is used as system clock source.

18.2 Bootloader selection

Figure 26 shows the bootloader selection mechanism.

Figure 26.Bootloader selection for STM32F070xB



18.3 Bootloader version

Table 41 lists the STM32F070xB devices bootloader versions.

Table 41. STM32F070xB bootloader versions

Version number	Description	Known limitations
V10.2	Initial bootloader version	– At bootloader startup, the HSITRIM value is set to 0 (in HSITRIM bits on RCC_CR register) instead of default value (16), as a consequence a deviation is generated in crystal measurement. For better results, use the smallest supported crystal value (4 MHz). PA13 is set in alternate push-pull mode even if not used by the bootloader. – USB bootloader fails on some machines using a high speed controller. The bootloader is detected. but then data transaction fails. Root causes: De-synchronization between USB controller and bootloader SW due to the controller high speed transactions. Controller high speed inter-packet delay seems not sufficient for the bootloader SW (based on interrupt routines) to serve all needed transactions (the delay needed by the BL is nearly 25 µs). Some servicing IT are missed. This results in a communication fail, causing Write command to fail. Workarounds: Add USB HUB between host and the MCU. This relaxes transactions inter-packet delay, and allows the BL SW to perform correctly the task. Use USB controller/host that increase inter-packet delay. On new designs, use DFU SW that fix the issue in user flash memory.
V10.3	Clock configuration fixed to HSI 8 MHz	

19 STM32F071xx/072xx devices

19.1 Bootloader configuration

The STM32F071xx/072xx bootloader is activated by applying Pattern 2 (described in *Table 2*). *Table 42* shows the hardware resources used by this bootloader.

Table 42. STM32F071xx/072xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 48 MHz with HSI48 48 MHz as clock source.
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz.
	RAM	-	6 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	12 Kbytes, starting from address 0x1FFFC800, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA15 pin: USART2 in reception mode. Used in input pull-up mode
	USART2_TX pin	Output	PA14 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address, Target mode – Analog filter ON – Target 7-bit address: 0b0111011x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain pull-up mode.

Table 42. STM32F071xx/072xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB used in FS mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line No external pull-up resistor is required. Used in alternate push-pull, no pull mode.

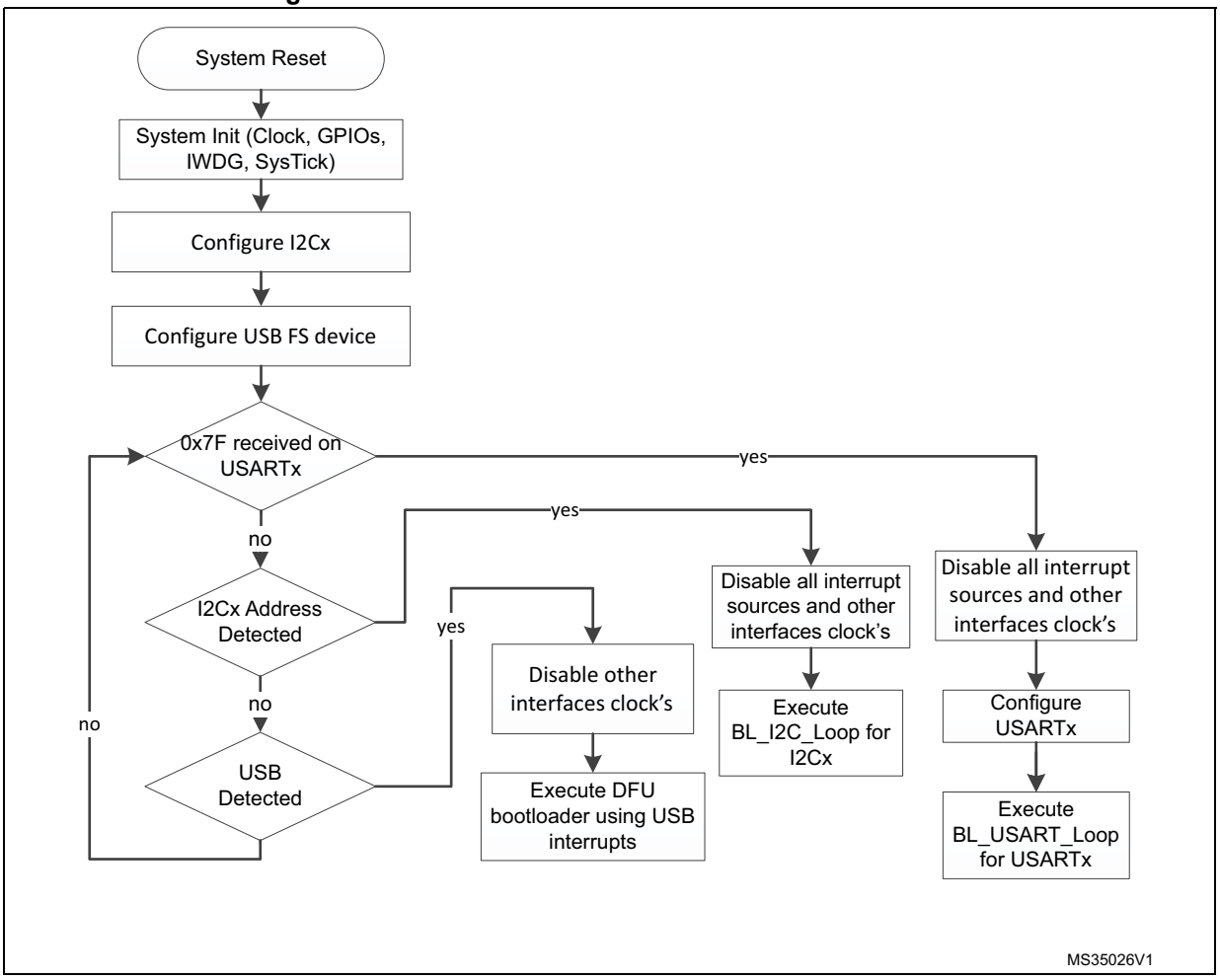
Note: After the devices have booted in bootloader mode using USART2, the serial wire debug (SWD) communication is no more possible until the system is reset, because SWD uses PA14 pin (SWCLK), already used by the bootloader (USART2_RX).

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

19.2 Bootloader selection

Figure 27 shows the bootloader selection mechanism.

Figure 27. Bootloader selection for STM32F071xx/072xx



19.3 Bootloader version

Table 43 lists the STM32F071xx/072xx devices bootloader versions.

Table 43. STM32F071xx/072xx bootloader versions

Version number	Description	Known limitations
V10.1	Initial bootloader version	– At bootloader startup, the HSITRIM value is set to (0) (in HSITRIM bits on RCC_CR register) instead of default value (16), as a consequence a deviation is generated in crystal measurement. For better results, use the smallest supported crystal value (4 MHz). PA13 set in alternate push-pull, pull-up mode even if not used by bootloader. – USB bootloader fails on some machines using a high speed controller. The bootloader is detected. but then data transaction fails. Root causes: De-synchronization between USB controller and bootloader SW due to the controller high speed transactions. Controller high speed inter-packet delay seems not sufficient for the bootloader SW (based on interrupt routines) to serve all needed transactions (the delay needed by the BL is nearly 25 µs). Some servicing IT are missed. This results in a communication fail, causing Write command to fail. Workarounds: Add USB HUB between host and the MCU. This relaxes transactions inter-packet delay, and allows the BL SW to perform correctly the task. Use USB controller/host that increase inter-packet delay. On new designs, use DFU SW that fix the issue in user flash memory.

20 STM32F09xxx devices

20.1 Bootloader configuration

The STM32F09xxx bootloader is activated by applying Pattern 6 (described in *Table 2*).*Table 44* shows the hardware resources used by this bootloader.

Table 44. STM32F09xxx configuration in system memory boot mode

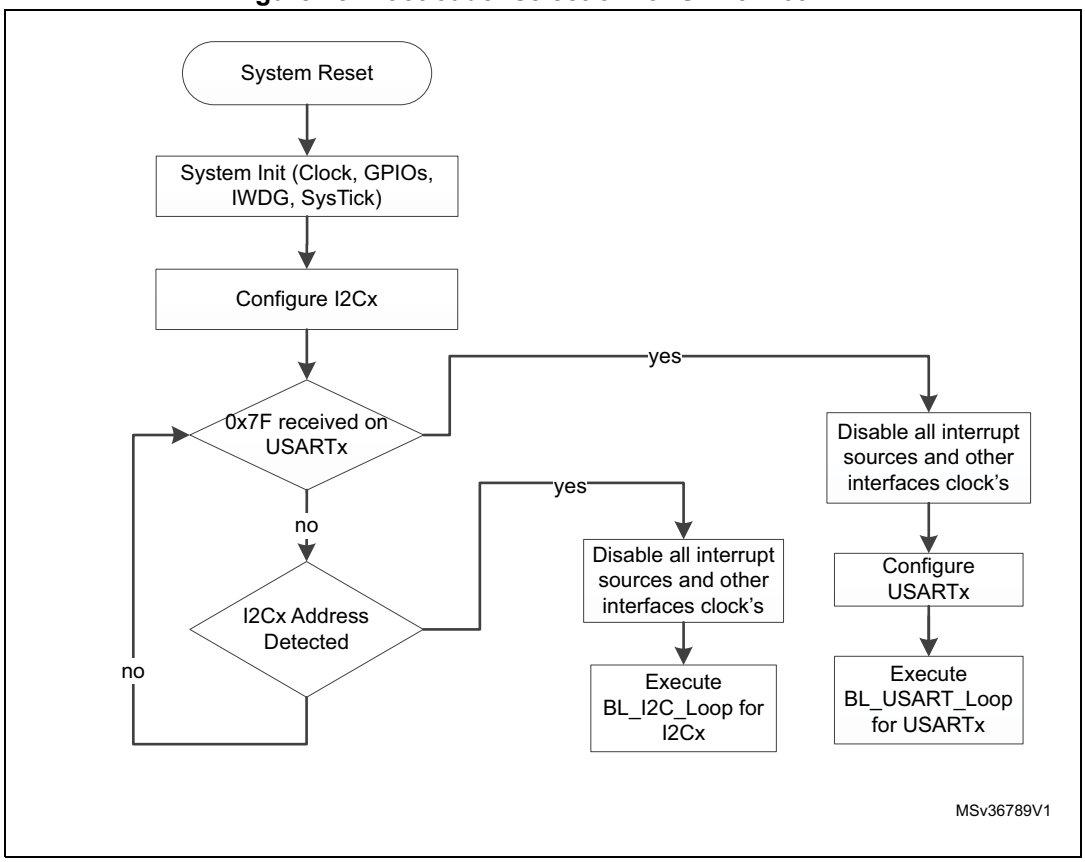
Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 48 MHz with HSI48 48 MHz as clock source.
	RAM	-	6 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contain the bootloader firmware.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input pull-up mode
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
			PA15 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
			PA14 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON Target 7-bit address: 0b1000001x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.

Note: After the devices have booted in bootloader mode using USART2, the serial wire debug (SWD) communication is no longer possible until the system is reset, because SWD uses PA14 pin (SWCLK), already used by the bootloader (USART2_RX).

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

20.2 Bootloader selection

Figure 28. Bootloader selection for STM32F09xxx



20.3 Bootloader version

Table 45 lists the STM32F09xxx devices bootloader versions.

Table 45. STM32F09xxx bootloader versions

Version number	Description	Known limitations
V5.0	Initial bootloader version	At bootloader startup, the HSITRIM value is set to 0 in HSITRIM bits on RCC_CR register instead of default value (16). As a consequence, a deviation is generated in crystal measurement. For better results, use the smallest supported crystal value (4 MHz). PA13 set in input pull-up mode even if not used by the bootloader.

21 STM32F10xxx devices

21.1 Bootloader configuration

The STM32F10xxx bootloader is activated by applying Pattern 1 (described in *Table 2*). *Table 46* shows the hardware resources used by this bootloader.

Table 46. STM32F10xxx configuration in system memory boot mode

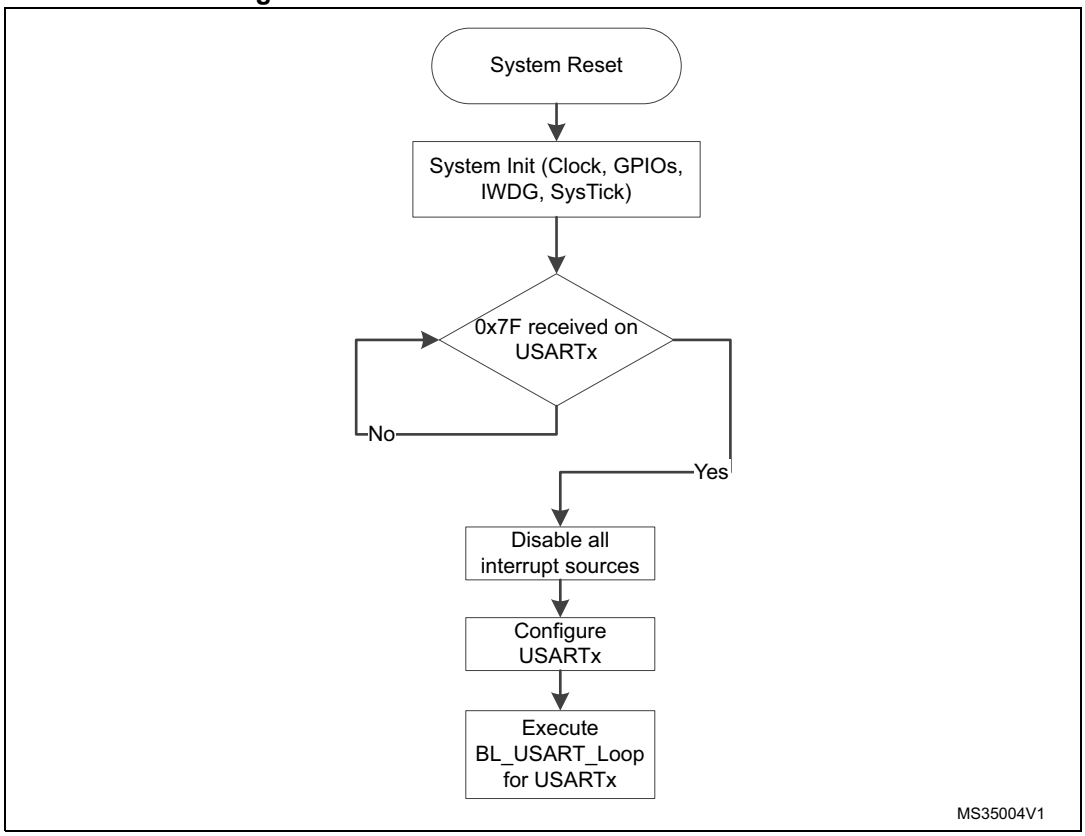
Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz using the PLL.
	RAM	-	512 byte starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	2 Kbytes, starting from address 0x1FFFF000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output push-pull	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

21.2 Bootloader selection

Figure 29 shows the bootloader selection mechanism.

Figure 29. Bootloader selection for STM32F10xxx



21.3 Bootloader version

Table 47 lists the STM32F10xxx devices bootloader versions:

Table 47. STM32F10xxx bootloader versions

Version number	Description
V2.0	Initial bootloader version
V2.1	– Updated Go Command to initialize the main stack pointer – Updated Go command to return NACK when jump address is in the Option byte area or System memory area – Updated Get ID command to return the device ID on two bytes – Update the bootloader version to V2.1
V2.2	– Updated Read Memory, Write Memory and Go commands to deny access with a NACK response to the first 0x200 bytes of RAM used by the bootloader – Updated Readout Unprotect command to initialize the whole RAM content to 0x0 before ROP disable operation

Note: The bootloader ID format is applied to all STM32 devices except the STM32F1xx devices. The bootloader version for the STM32F1xx applies only to the embedded device's bootloader version and not to its supported protocols.

22 STM32F105xx/107xx devices

22.1 Bootloader configuration

The STM32F105xx/107xx bootloader is activated by applying Pattern 1 (described in *Table 2*). *Table 48* shows the hardware resources used by this bootloader.

Table 48. STM32F105xx/107xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz using the PLL. This is used only for USARTx and during CAN2, USB detection for CAN and DFUs (once CAN or DFU is selected, the clock source is derived from the external crystal).
		HSE enabled	The external clock is mandatory only for DFU and CAN bootloaders and it must provide one of the following frequencies: 8 MHz, 14.7456 MHz or 25 MHz. For CAN bootloader, the PLL is used only to generate 48 MHz when 14.7456 MHz is used as HSE. For DFU, the PLL is used to generate a 48 MHz system clock from all supported external clock frequencies.
		-	The CSS interrupt is enabled for the CAN and DFUs. Any failure (or removal) of the external clock will generate system reset.
	RAM	-	4 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	18 Kbytes, starting from address 0x1FFFB000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output push-pull	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 receive (remapped pin)
	USART2_TX pin	Output push-pull	PD5 pin: USART2 transmit (remapped pin)
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloader.

Table 48. STM32F105xx/107xx configuration in system memory boot mode (continued)

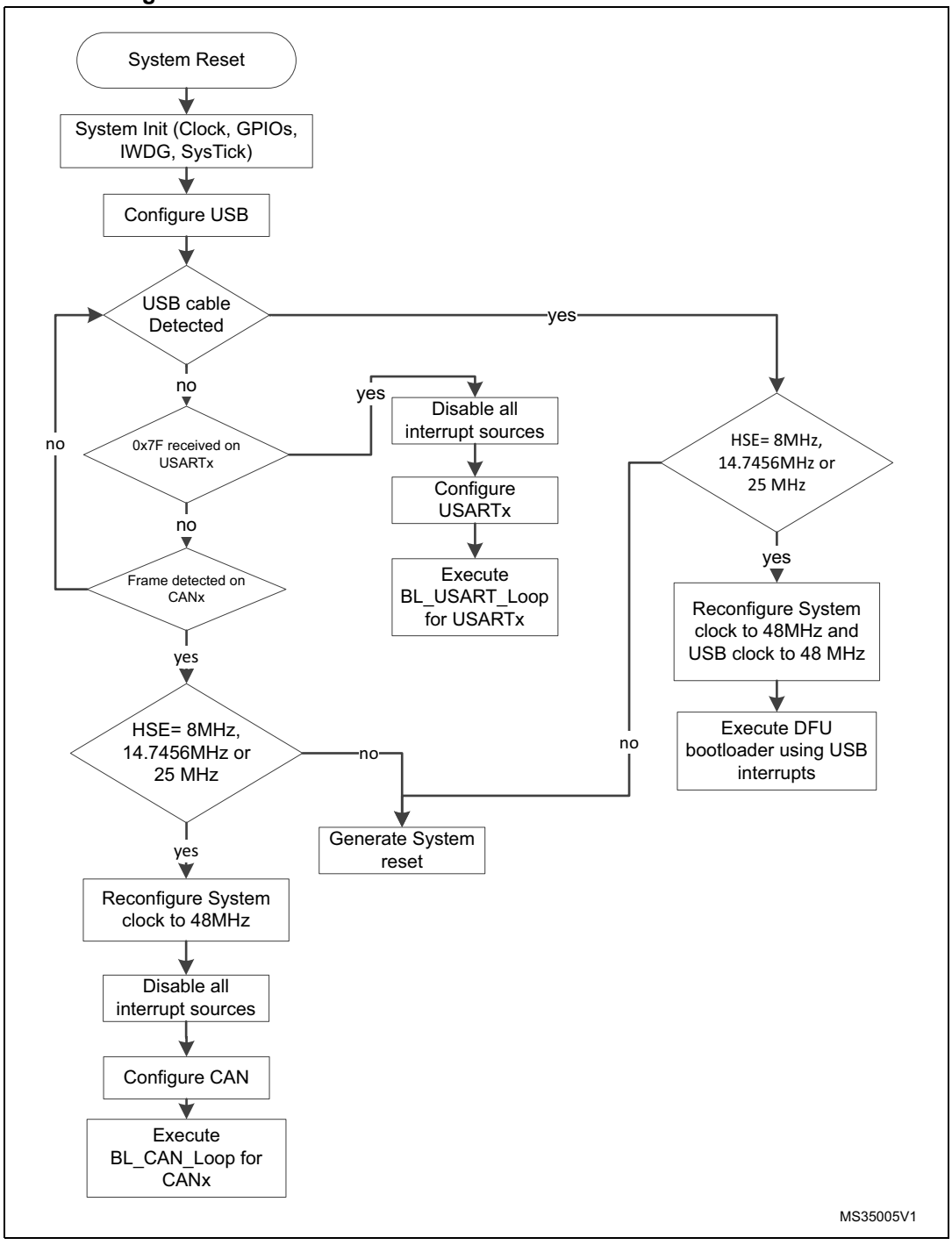
Bootloader	Feature/Peripheral	State	Comment
CAN2	CAN2	Enabled	Once initialized, the CAN2 configuration is baudrate 125 kbps, 11-bit identifier. **Note:** CAN1 is clocked during the CAN bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 receives (remapped pin). Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output push-pull	PB6 pin: CAN2 transmits (remapped pin). Used in input no pull mode.
DFU	USB	Enabled	USB OTG FS configured in forced device mode
	USB_VBUS pin	Input	PA9: Power supply voltage line
	USB_DM pin	Input/output	PA11 pin: USB_DM line
	USB_DP pin		PA12 pin: USB_DP line. No external pull-up resistor is required

The system clock is derived from the embedded internal high-speed RC for USARTx bootloader. This internal clock is used also for DFU and CAN bootloaders, but only for the selection phase. An external clock (8, 14.7456, or 25 MHz) is required for DFU and CAN bootloader execution after the selection phase.

22.2 Bootloader selection

Figure 30 shows the bootloader selection mechanism.

Figure 30. Bootloader selection for STM32F105xx/107xx devices



22.3 Bootloader version

Table 49 lists the STM32F105xx/107xx devices bootloader versions:

Table 49. STM32F105xx/107xx bootloader versions

Version number	Description
V1.0	Initial bootloader version
V2.0	– Bootloader detection mechanism updated to fix the issue when GPIOs of unused peripherals in this bootloader are connected to low level or left floating during the detection phase. For more details refer to *Section 22.3.2*. – Vector table set to 0x1FFFB000 instead of 0x00000000 – Go command updated (for all bootloaders): USART1, USART2, CAN2, GPIOA, GPIOB, GPIOD and SysTick peripheral registers are set to their default reset values – DFU: USB pending interrupt cleared before executing the Leave DFU command – DFU subprotocol version changed from V1.0 to V1.2 – Bootloader version updated to V2.0
V2.1	– Fixed PA9 excessive consumption described in *Section 22.3.4*. – Get-Version command (defined in AN3155) corrected. It returns 0x22 instead of 0x20 in bootloader V2.0. Refer to *Section 22.3.3* for more details. – Bootloader version updated to V2.1
V2.2	– Fixed DFU option bytes descriptor (set to ‘e’ instead of ‘g’ because it is read/write and not erasable). – Fixed DFU polling timings for flash Read/Write/Erase operations. – Robustness enhancements for DFU interface. – Updated bootloader version to V2.2.

Note: The bootloader ID format is applied to all STM32 devices except the STM32F1xx products. The version for STM32F1xx applies only to the embedded device’s bootloader version and not to its supported protocols.

22.3.1 How to identify STM32F105xx/107xx bootloader versions

Bootloader V1.0 is implemented on devices whose date code is lower than 937. Bootloader V2.0 and V2.1 are implemented on devices with a date code higher than or equal to 937. Bootloader V2.2 is implemented on devices with a date code higher than or equal to 227.

Refer to the datasheets to find the date code on the device marking)

There are two ways to distinguish between bootloader versions:

- When using the USART bootloader, the Get-Version command defined in AN3155 has been corrected in V2.1 version. It returns 0x22 instead of 0x20 as in bootloader V2.0.
- The values of the vector table at the beginning of the bootloader code are different. The user software (or via JTAG/SWD) reads 0x1FFFE945 at address 0x1FFFB004 for bootloader V2.0 0x1FFFE9A1 for bootloader V2.1, and 0x1FFFE9C1 for bootloader V2.2.

The DFU version can be read through the bcdDevice field of the DFU Device Descriptor:

- V2.1 in bootloader V2.1
- V2.2 in bootloader V2.2.

22.3.2 Bootloader unavailability on STM32F105xx/STM32F107xx devices with date code lower than 937

Description

The bootloader cannot be used if the USART1_RX (PA10), USART2_RX (PD6, remapped), CAN2_Rx (PB5, remapped), OTG_FS_DM (PA11), and/or OTG_FS_DP (PA12) pin(s) are held low or left floating during the bootloader activation phase.

The bootloader cannot be connected through CAN2 (remapped), DFU (OTG FS in Device mode), USART1 or USART2 (remapped).

On 64-pin packages, the USART2_RX signal remapped PD6 pin is not available and it is internally grounded. In this case, the bootloader cannot be used at all.

Workaround

- For 64-pin packages

  None. The bootloader cannot be used.
- For 100-pin packages

  Depending on the used peripheral, the pins for the unused peripherals must be kept at a high level during the bootloader activation phase as described below:
  - If USART1 is used to connect to the bootloader, PD6 and PB5 must be kept at a high level.
  - If USART2 is used to connect to the bootloader, PA10, PB5, PA11, and PA12 must be kept at a high level.
  - If CAN2 is used to connect to the bootloader, PA10, PD6, PA11, and PA12 must be kept at a high level.
  - If DFU is used to connect to the bootloader, PA10, PB5, and PD6 must be kept at a high level.

Note: This limitation applies only to STM32F105xx and STM32F107xx devices with a date code lower than 937. STM32F105xx and STM32F107xx devices with a date code higher or equal to 937 are not impacted. See STM32F105xx and STM32F107xx datasheets for where to find the date code on the device marking.

22.3.3 USART bootloader Get-Version command returns 0x20 instead of 0x22

Description

In USART mode, the Get-Version command (defined in AN3155) returns 0x20 instead of 0x22. This limitation is present on bootloader versions V1.0 and V2.0, while it is fixed in bootloader version 2.1.

Workaround

None.

22.3.4 PA9 excessive power consumption when USB cable is plugged in bootloader V2.0

Description

When connecting a USB cable after booting from System-Memory mode, PA9 pin (connected to V_{BUS} = 5 V) is also shared with USART TX pin, configured as alternate push-pull and forced to 0 since the USART peripheral is not yet clocked. As a consequence, a current higher than 25 mA is drained by PA9 I/O and may affect the I/O pad reliability.

This limitation is fixed in bootloader version 2.1 by configuring PA9 as alternate function push-pull when a correct 0x7F is received on RX pin and the USART is clocked. Otherwise, PA9 is configured as alternate input floating.

Workaround

None.

23 STM32F10xxx XL-density devices

23.1 Bootloader configuration

The STM32F10xxx XL-density bootloader is activated by applying Pattern 3 (described in *Table 2*). *Table 50* shows the hardware resources used by this bootloader.

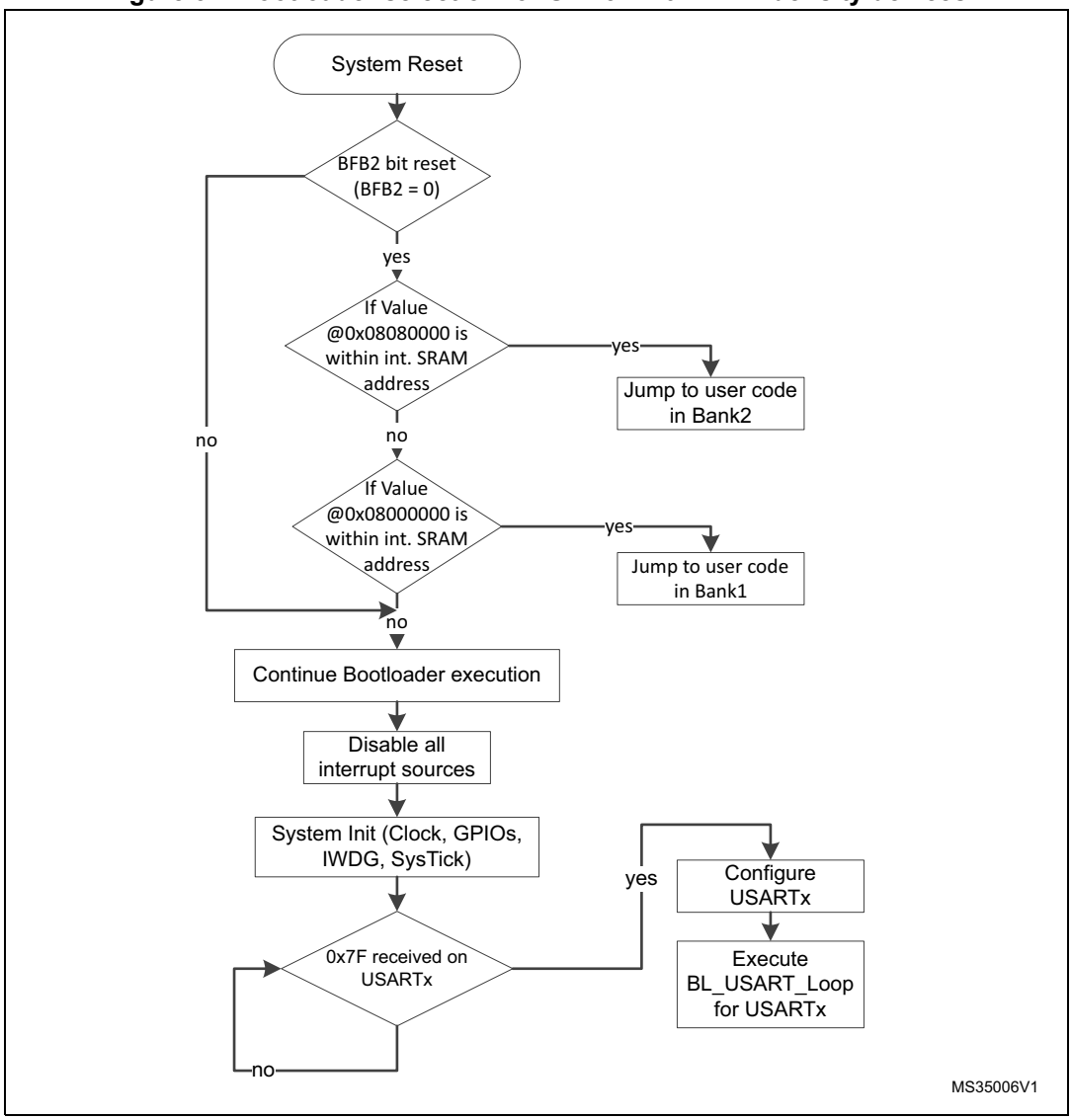
Table 50. STM32F10xxx XL-density configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz using the PLL.
	RAM	-	2 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	6 Kbytes, starting from address 0x1FFFE000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input pull-up mode.
	USART1_TX pin	Output push-pull	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit.
	USART2_RX pin	Input	PD6 pin: USART2 receives (remapped pins). Used in input pull-up mode.
	USART2_TX pin	Output push-pull	PD5 pin: USART2 transmits (remapped pins). Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

23.2 Bootloader selection

Figure 31. Bootloader selection for STM32F10xxx XL-density devices



23.3 Bootloader version

Table 51. STM32F10xxx XL-density bootloader versions

Version number	Description
V2.1	Initial bootloader version

Note: The bootloader ID format is applied to all STM32 devices families except the STM32F1xx family. The bootloader version for the STM32F1xx applies only to the embedded device bootloader version and not to its supported protocols.

24 STM32F2xxxx devices

Two bootloader versions are available on STM32F2xxxx devices:

- V2.x supporting USART1 and USART3
  This version is embedded in revisions A, Z, and B
- V3.x supporting USART1, USART3, CAN2, and DFU (USB FS device)
  This version is embedded in all other revisions (Y, X, W, 1, V, 2, 3, and 4)

24.1 Bootloader V2.x

24.1.1 Bootloader configuration

The STM32F2xxxx bootloader is activated by applying Pattern 1 (described in *Table 2*). *Table 52* shows the hardware resources used by this bootloader.

Table 52. STM32F2xxxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz.
	RAM	-	8 Kbytes, starting from address 0x20000000.
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62 V, 2.1 V]. In this range internal flash write operations are allowed only in byte format (half-word, word, and double-word operations are not allowed). The voltage range can be configured in run time using bootloader commands.
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode
USART3 (on PC10/PC11)	USART3	Enabled	Once initialized, the USART3 configuration is 8 bits, even parity, and one stop bit.
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode

Table 52. STM32F2xxxx configuration in system memory boot mode (continued)

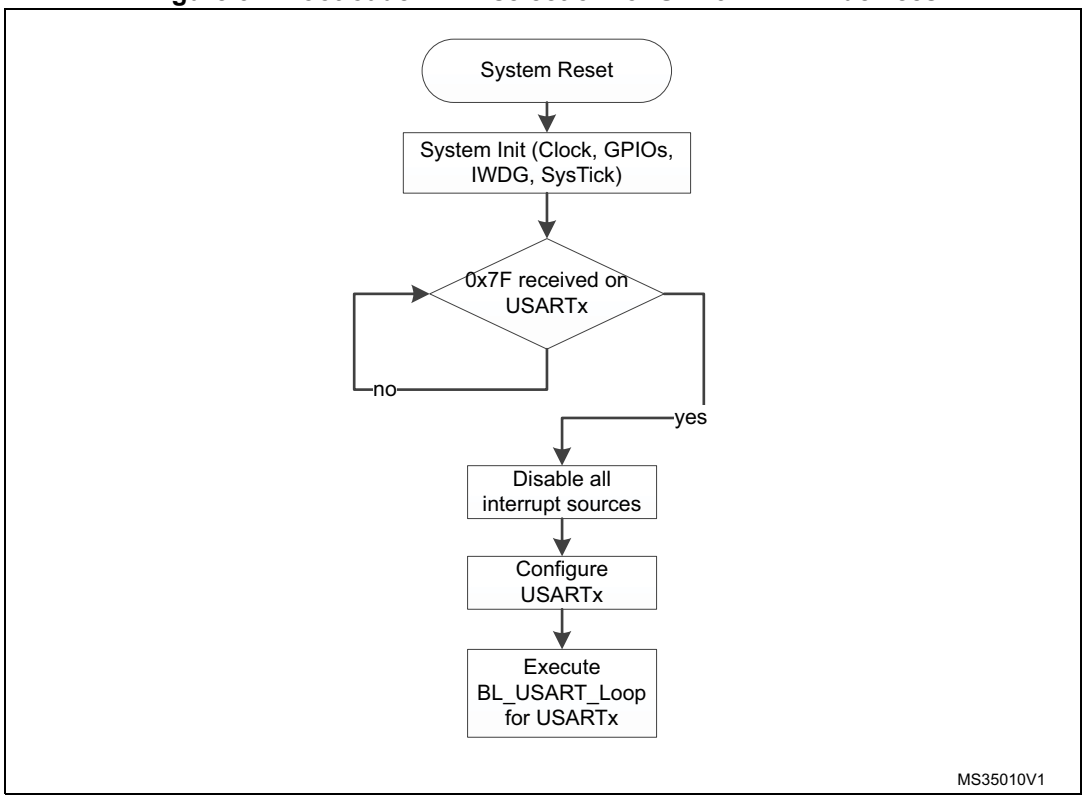
Bootloader	Feature/Peripheral	State	Comment
USART3 (on PB10/PB11)	USART3	Enabled	Once initialized, the USART3 configuration is 8 bits, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader code.

24.1.2 Bootloader selection

Figure 32 shows the bootloader selection mechanism.

Figure 32. Bootloader V2.x selection for STM32F2xxxx devices



24.1.3 Bootloader version

Table 53 lists the STM32F2xxxx devices V2.x bootloader versions:

Table 53. STM32F2xxxx bootloader V2.x versions

Version number	Description	Known limitations
V2.0	Initial bootloader version	When a Read Memory command or Write Memory command is issued with an unsupported memory address and a correct address checksum (i.e. address 0x6000 0000), the command is aborted by the bootloader device, but the NACK (0x1F) is not sent to the host. As a result, the next two bytes (the number of bytes to be read/written and its checksum) are considered as a new command and its checksum. For the CAN interface, the Write Unprotect command is not functional. Use Write Memory command and write directly to the option bytes in order to disable the write protection.(1)

1. If the “number of data - 1” (N-1) to be read/written is not equal to a valid command code (0x00, 0x01, 0x02, 0x11, 0x21, 0x31, 0x43, 0x44, 0x63, 0x73, 0x82 or 0x92), the limitation is not perceived from the host, as the command is NACK-ed anyway (as an unsupported new command).

24.2 Bootloader V3.x

24.2.1 Bootloader configuration

The STM32F2xxxx bootloader is activated by applying Pattern 1 (described in *Table 2*). *Table 54* shows the hardware resources used by this bootloader.

Table 54. STM32F2xxxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USARTx interfaces are selected (once CAN or DFU is selected, the clock source is derived from the external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the CAN or the DFU (USB FS device) interfaces are selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFUs. Any failure (or removal) of the external clock generates system reset.
	RAM	-	8 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	29 Kbytes, starting from address 0x1FF00000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to 1.62 V, 2.1 V. In this range internal flash write operations are allowed only in byte format (half-word, word, and double-word operations are not allowed). The voltage range can be configured in run time using bootloader commands.
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in no pull mode.
USART3 (on PB10/PB11)	USART3	Enabled	Once initialized, the USART3 configuration is 8 bits, even parity, and one stop bit.
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in pull-up mode
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in pull-up mode

Table 54. STM32F2xxxx configuration in system memory boot mode (continued)

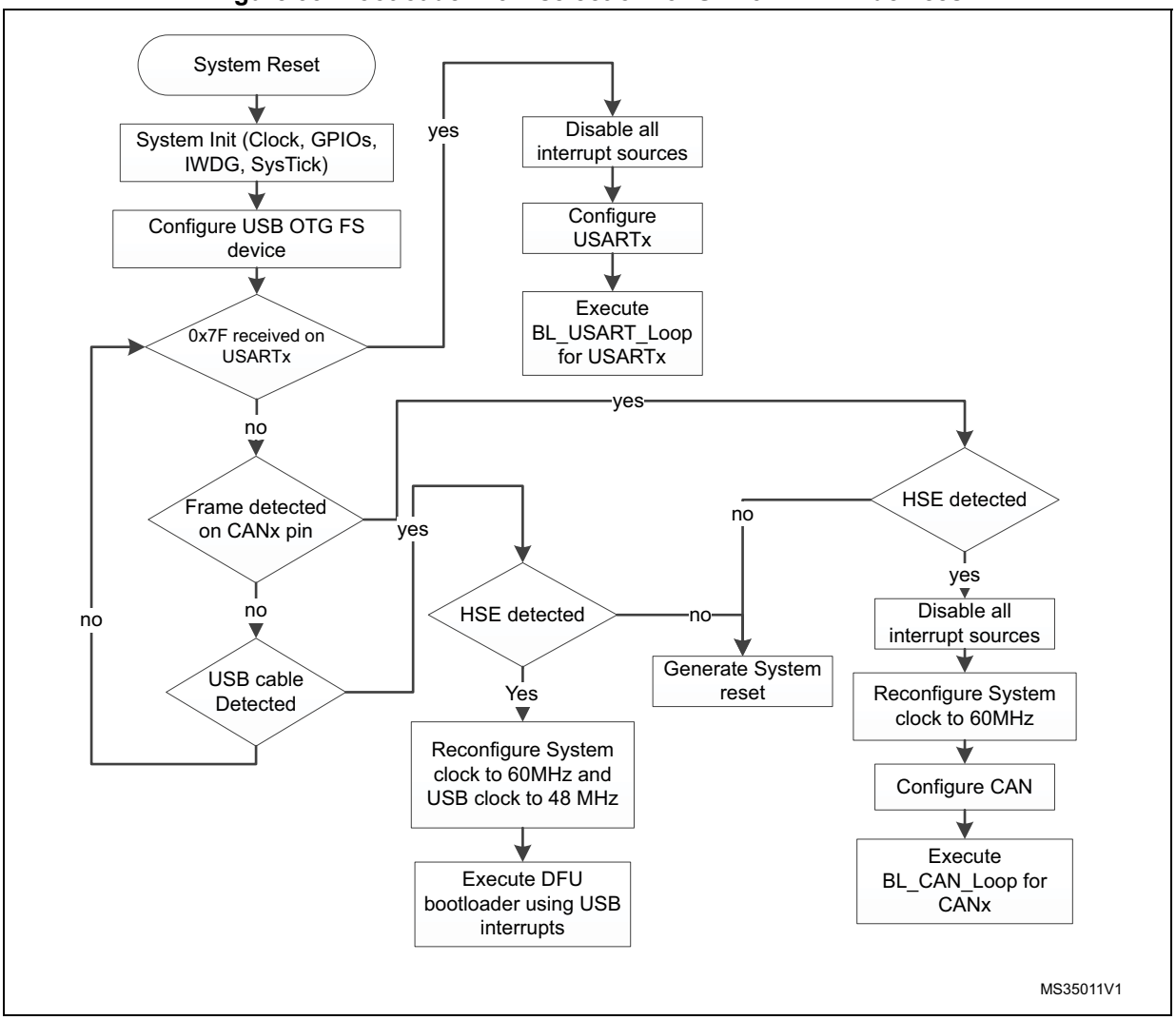
Bootloader	Feature/Peripheral	State	Comment
USART3 (on PC10/PC11)	USART3	Enabled	Once initialized, the USART3 configuration is 8 bits, even parity, and one stop bit.
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
CAN2	CAN2	Enabled	Once initialized, the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. **Note:** CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
DFU	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in inpt no pull mode. No external pull-up resistor is required
CAN2 and DFUs	TIM11	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

The system clock is derived from the embedded internal high-speed RC for USARTx. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU execution after the selection phase.

24.2.2 Bootloader selection

Figure 33 shows the bootloader selection mechanism.

Figure 33. Bootloader V3.x selection for STM32F2xxxx devices



24.2.3 Bootloader version

Table 55 lists the STM32F2xxxx devices V3.x bootloader versions:

Table 55. STM32F2xxxx bootloader V3.x versions

Version number	Description	Known limitations
V3.2	Initial bootloader version	– When a Read Memory command or Write Memory command is issued with an unsupported memory address and a correct address checksum (i.e. address 0x6000 0000), the command is aborted by the bootloader device, but the NACK (0x1F) is not sent to the host. As a result, the next two bytes (which are the number of bytes to be read/written and its checksum) are considered as a new command and its checksum(1). – Option bytes, OTP and Device Feature descriptors (in DFU interface) are set to “g” instead of “e” (not erasable memory areas).
V3.3	Fix V3.2 limitations. DFU interface robustness enhancement	– For the USART interface, two consecutive NACKs (instead of 1 NACK) are sent when a Read Memory or Write Memory command is sent and the RDP level is active. – For the CAN interface, the Write Unprotect command is not functional. Use Write Memory command and write directly to the option bytes in order to disable the write protection.

1. If the “number of data - 1” (N-1) to be read/written is not equal to a valid command code (0x00, 0x01, 0x02, 0x11, 0x21, 0x31, 0x43, 0x44, 0x63, 0x73, 0x82 or 0x92), the limitation is not perceived from the host, as the command is NACK-ed anyway (as an unsupported new command).

25 STM32F301xx/302x4(6/8) devices

25.1 Bootloader configuration

The STM32F301xx/302x4(6/8) bootloader is activated by applying Pattern 2 (described in *Table 2*). *Table 56* shows the hardware resources used by this bootloader.

Table 56. STM32F301xx/302x4(6/8) configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 48 MHz with HSI48 48 MHz as clock source.
		HSE enabled	The external clock can be used for all bootloader interfaces and must have one the following values: 24,18,16,12,9,8,6,4,3 MHz. The PLL is used to generate the USB48 MHz clock and the 48 MHz clock for the system clock.
		-	The CSS interrupt is enabled for the DFU. Any failure (or removal) of the external clock generates system reset.
	RAM	-	6 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.

Table 56. STM32F301xx/302x4(6/8) configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB used in FS mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. An external pull-up resistor 1.5 KΩ must be connected to USB_DP pin.

The bootloader has two cases of operation, depending upon the presence of the external clock (HSE) at bootloader startup:

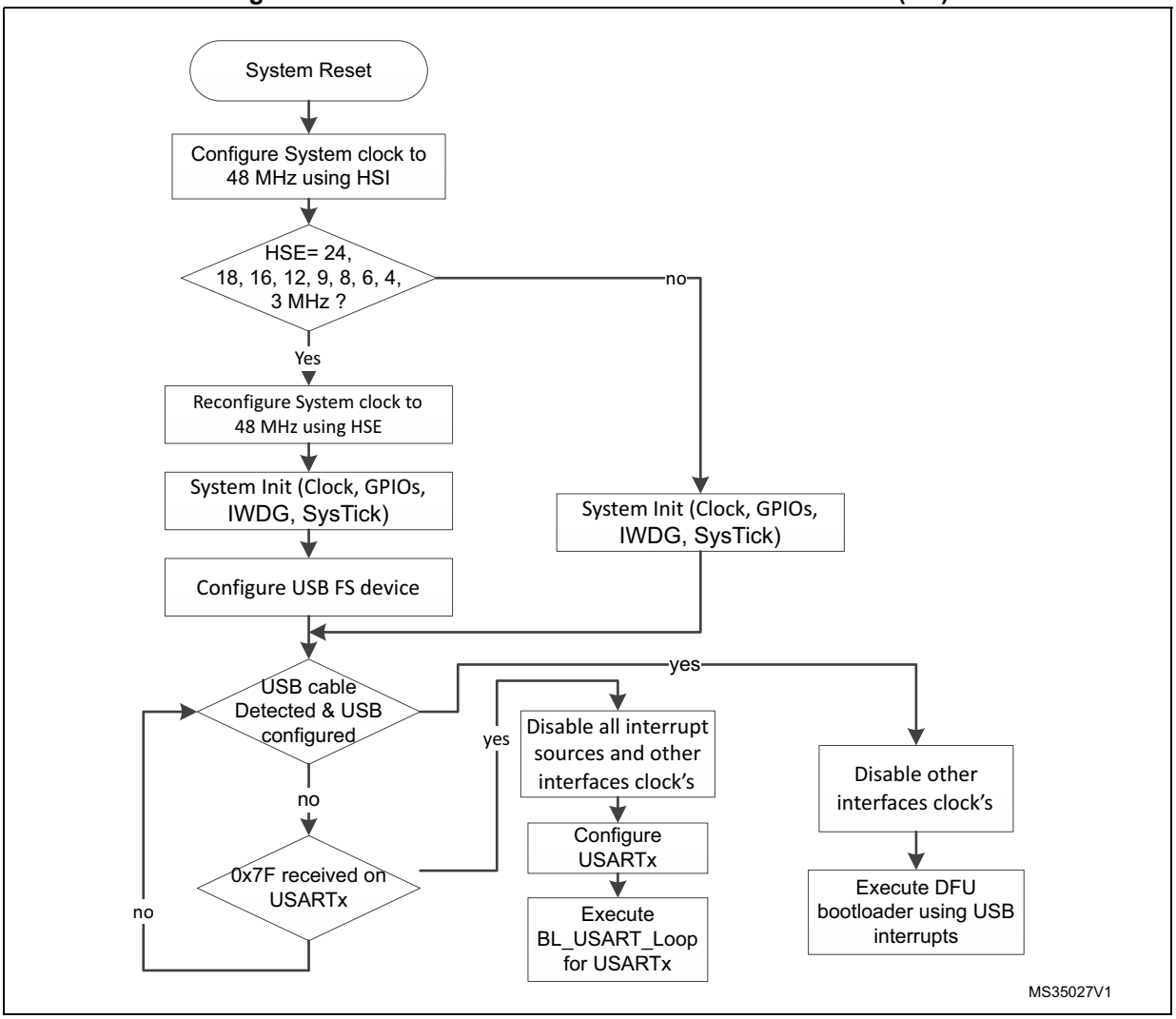
- If HSE is present and has a value of 24, 18, 16, 12, 9, 8, 6, 4, or 3 MHz, the system clock is configured to 48 MHz with HSE as clock source. The DFU interface, USART1 and USART2 are functional and can be used to communicate with the bootloader device.
- If HSE is not present, the HSI is kept as default clock source, and only USART1 and USART2 are functional.

The external clock (HSE) must be kept if it is connected at bootloader startup, because it is used as system clock source.

25.2 Bootloader selection

Figure 34 shows the bootloader selection mechanism.

Figure 34. Bootloader selection for STM32F301xx/302x4(6/8)



25.3 Bootloader version

Table 57 lists the STM32F301xx/302x4(6/8) devices bootloader versions:

Table 57. STM32F301xx/302x4(6/8) bootloader versions

Version number	Description	Known limitations
V4.0	Initial bootloader version	– USB bootloader fails on some machines using a high speed controller. The bootloader is detected. but then data transaction fails. Root causes: De-synchronization between USB controller and bootloader SW due to the controller high speed transactions. Controller high speed inter-packet delay seems not sufficient for the bootloader SW (based on interrupt routines) to serve all needed transactions (the delay needed by the BL is nearly 25 µs). Some servicing IT are missed. This results in a communication fail, causing Write command to fail. Workarounds: Add USB HUB between host and the MCU. This relaxes transactions inter-packet delay, and allows the BL SW to perform correctly the task. Use USB controller/host that increase inter-packet delay. On new designs, use DFU SW that fix the issue in user flash memory.

26 STM32F302xB(C)/303xB(C) devices

26.1 Bootloader configuration

The STM32F302xB(C)/303xB(C) bootloader is activated by applying Pattern 2 (described in *Table 2*). *Table 58* shows the hardware resources used by this bootloader.

Table 58. STM32F302xB(C)/303xB(C) configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	At startup, the system clock frequency is configured to 48 MHz using the HSI. If an external clock (HSE) is not present, the system is kept clocked from the HSI.
		HSE enabled	The external clock can be used for all bootloader interfaces and must have one the following values: 24, 18,16, 12, 9, 8, 6, 4, 3 MHz. The PLL is used to generate the USB 48 MHz clock and the 48 MHz clock for the system clock.
		-	The CSS interrupt is enabled for the DFU. Any failure (or removal) of the external clock generates system reset.
	RAM	-	5 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contains the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloader.

Table 58. STM32F302xB(C)/303xB(C) configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB used in FS mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. An external pull-up resistor 1.5 KΩ must be connected to USB_DP pin.

The bootloader has two cases of operation depending on the presence of the external clock (HSE) at bootloader startup:

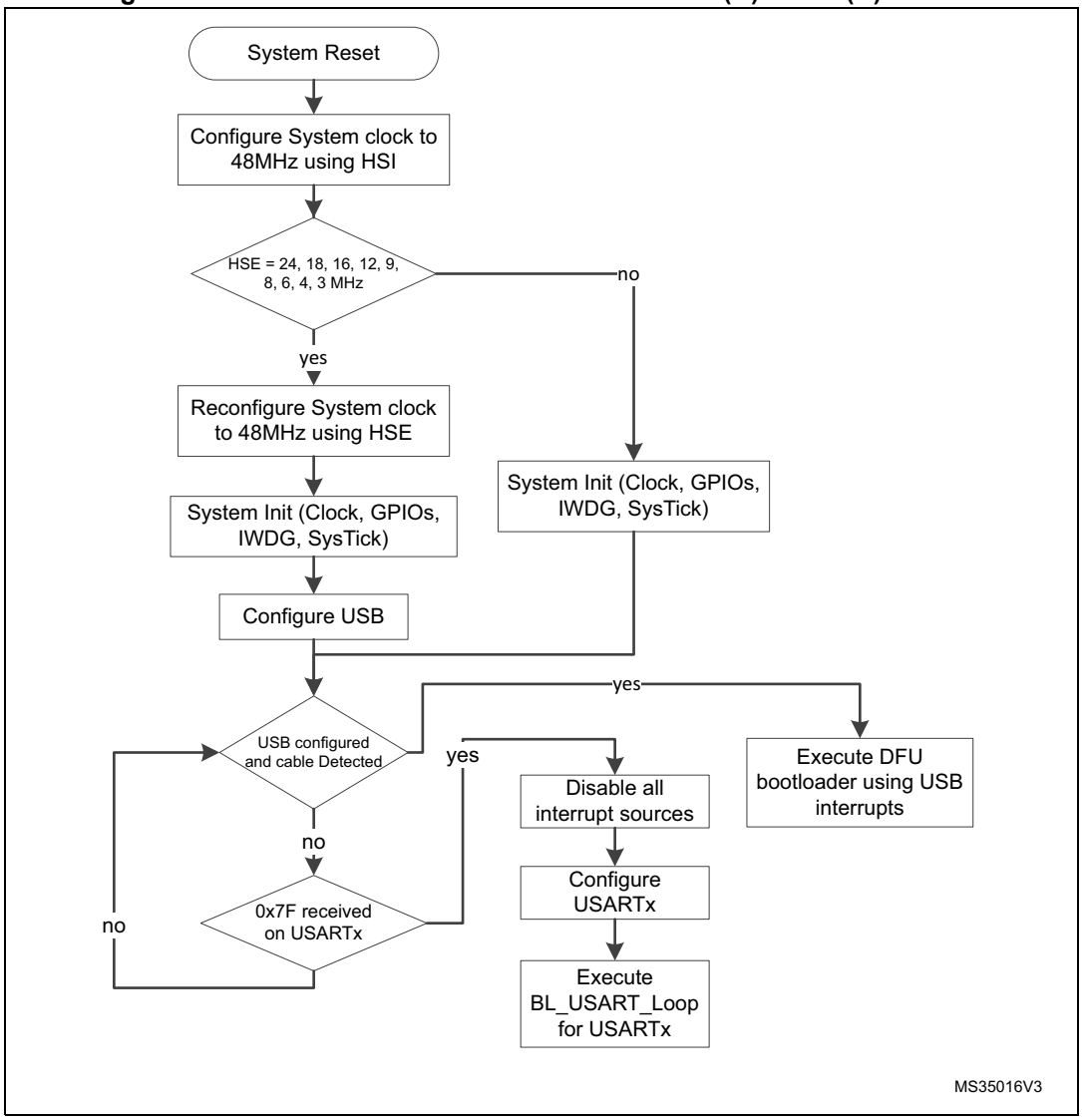
- If HSE is present and has a value of 24, 18, 16, 12, 9, 8, 6, 4 or 3 MHz, the system clock is configured to 48 MHz with HSE as clock source. The DFU interface, USART1 and USART2 are functional and can be used to communicate with the bootloader device.
- If HSE is not present, the HSI is kept as default clock source, and only USART1 and USART2 are functional.

The external clock (HSE) must be kept if it is connected at bootloader startup, because it is used as system clock source.

26.2 Bootloader selection

Figure 35 shows the bootloader selection mechanism.

Figure 35. Bootloader selection for STM32F302xB(C)/303xB(C) devices



26.3 Bootloader version

Table 59 lists the STM32F302xB(C)/303xB(C) devices bootloader versions.

Table 59. STM32F302xB(C)/303xB(C) bootloader versions

Version number	Description	Known limitations
V4.1	Initial bootloader version	RAM parity checks can cause a bootloader crash if RAM is not initialized. The bootloader does not initialize RAM before execution. Workaround: Initialize the SRAM before entering the bootloader when parity check is enabled.

27 STM32F302xD(E)/303xD(E) devices

27.1 Bootloader configuration

The STM32F302xD(E)/303xD(E) bootloader is activated by applying Pattern 2 (described in *Table 2*). *Table 60* shows the hardware resources used by this bootloader.

Table 60.STM32F302xD(E)/303xD(E) configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 48 MHz with HSI48 48 MHz as clock source.
		HSE enabled	The external clock can be used for all bootloader interfaces and must have one the following values: 24, 18, 16, 12, 9, 8, 6, 4, 3 MHz. The PLL is used to generate the USB 48 MHz clock and the 48 MHz clock for the system clock.
		-	The CSS interrupt is enabled for the DFU. Any failure (or removal) of the external clock generates system reset.
	RAM	-	6 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11 pin: USB FS DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB FS DP line. Used in alternate push-pull, no pull mode. An external pull-up resistor 1.5 KΩ must be connected to USB_DP pin.

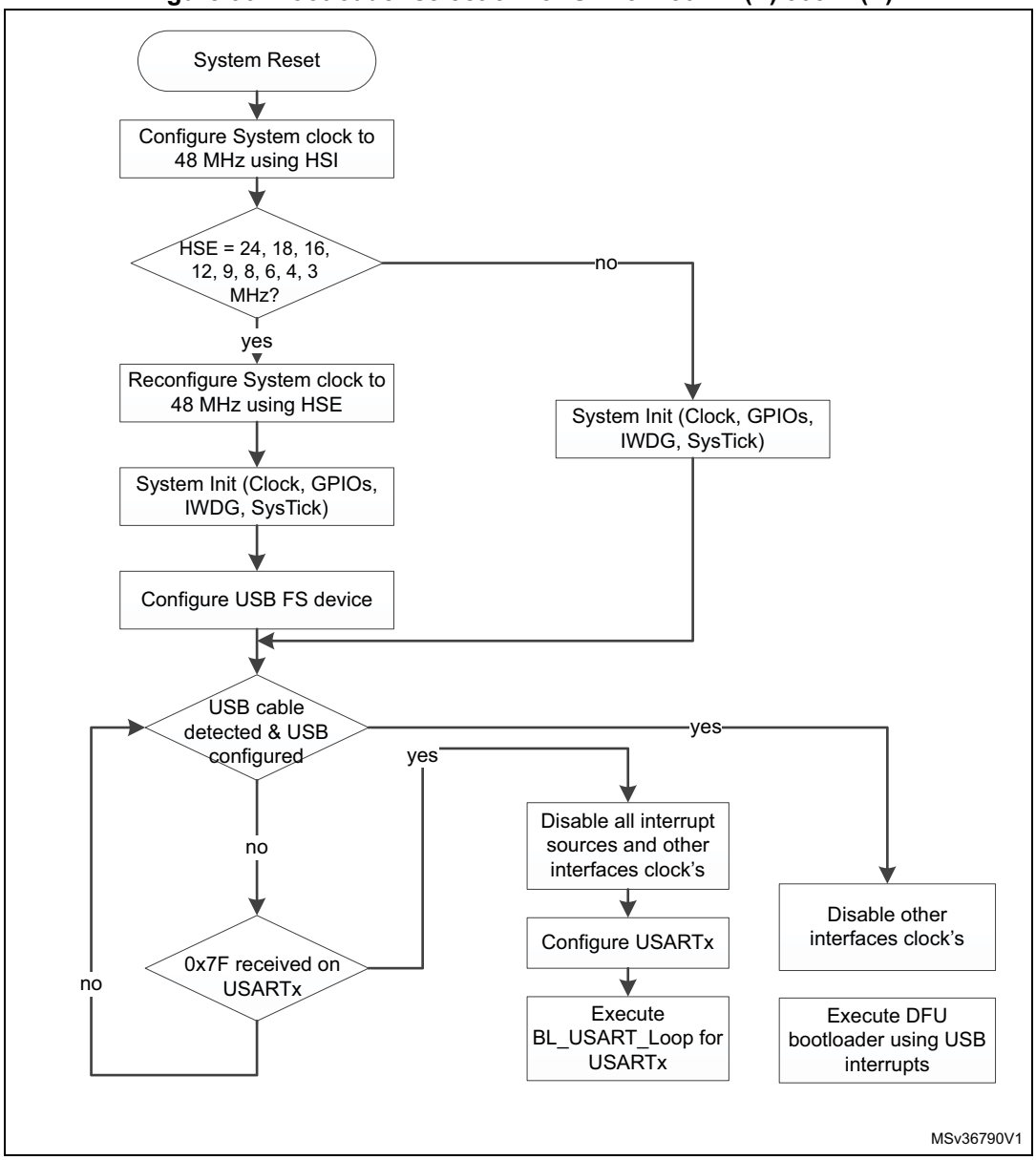
The bootloader has two cases of operation depending on the presence of the external clock (HSE) at bootloader startup:

- If HSE is present and has a value of 24, 18, 16, 12, 9, 8, 6, 4 or 3 MHz, the system clock is configured to 48 MHz with HSE as clock source. The DFU interface, USART1 and USART2 are functional and can be used to communicate with the bootloader device.
- If HSE is not present, the HSI is kept as default clock source, and only USART1 and USART2 are functional.

The external clock (HSE) must be kept if it is connected at bootloader startup, because it is used as system clock source.

27.2 Bootloader selection

Figure 36. Bootloader selection for STM32F302xD(E)/303xD(E)



27.3 Bootloader version

Table 61. STM32F302xD(E)/303xD(E) bootloader versions

Version number	Description	Known limitations
V4.0	Initial bootloader version	– The USB bootloader fails on some machines using a high speed controller. The bootloader is detected. but then data transaction fails. Root causes: De-synchronization between USB controller and bootloader SW due to the controller high speed transactions. Controller high speed inter-packet delay seems not sufficient for the bootloader SW (based on interrupt routines) to serve all needed transactions (the delay needed by the BL is nearly 25 µs). Some servicing IT are missed. This results in a communication fail, causing Write command to fail. Workarounds: Add an USB HUB between the host and the MCU. This relaxes transactions inter-packet delay, and allows the BL SW to perform correctly the task. Use USB controller/host that increase inter-packet delay. On new designs, use DFU SW that fix the issue in user flash memory.

28 STM32F303x4(6/8)/334xx/328xx devices

28.1 Bootloader configuration

The STM32F303x4(6/8)/334xx/328xx bootloader is activated by applying Pattern 2 (described in *Table 2*). *Table 62* shows the hardware resources used by this bootloader.

Table 62. STM32F303x4(6/8)/334xx/328xx configuration in system memory boot mode

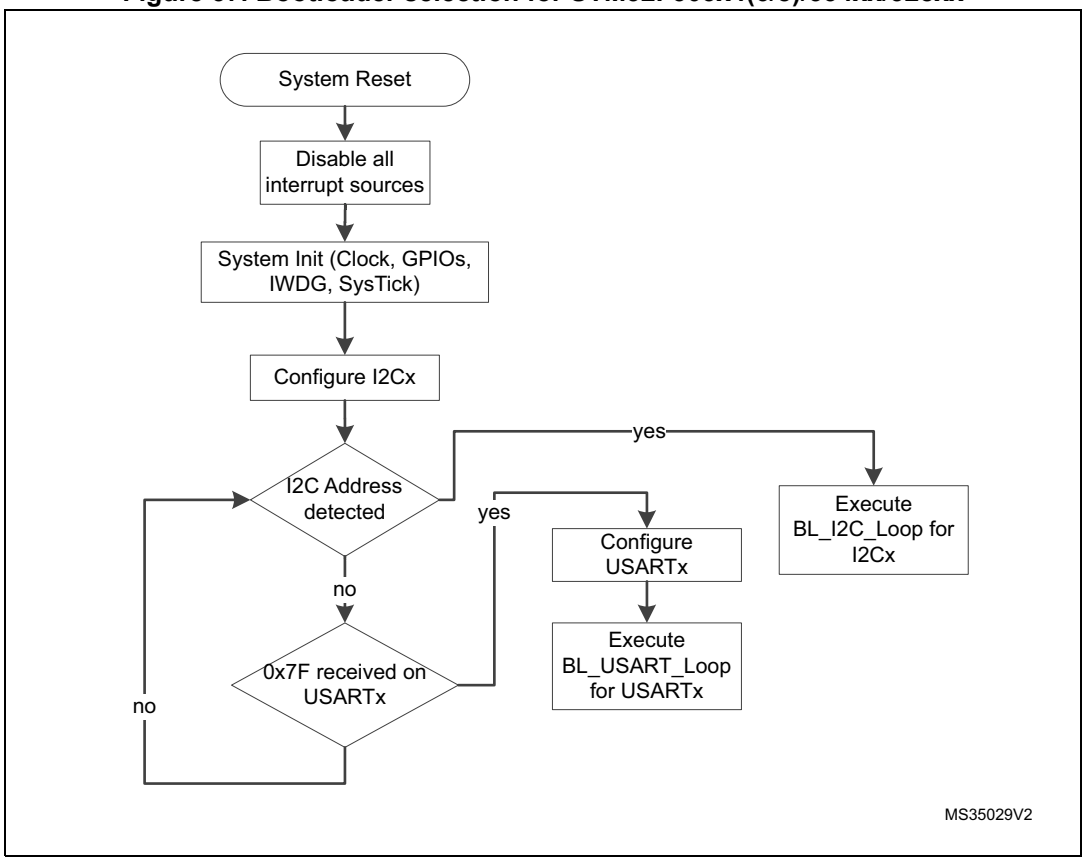
Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz with HSI 8 MHz as clock source.
	RAM	-	6 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b0111111x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

28.2 Bootloader selection

Figure 37 shows the bootloader selection mechanism.

Figure 37. Bootloader selection for STM32F303x4(6/8)/334xx/328xx



28.3 Bootloader version

Table 63 lists the STM32F303x4(6/8)/334xx/328xx devices bootloader versions:

Table 63. STM32F303x4(6/8)/334xx/328xx bootloader versions

Version number	Description	Known limitations
V5.0	Initial bootloader version	RAM parity checks can cause a bootloader crash if RAM is not initialized. The bootloader does not initialize RAM before execution. Workaround: Initialize the SRAM before entering the bootloader when parity check is enabled.

29 STM32F318xx devices

29.1 Bootloader configuration

The STM32F318xx bootloader is activated by applying Pattern 2 (described in *Table 2*). *Table 64* shows the hardware resources used by this bootloader.

Table 64. STM32F318xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz with HSI 8 MHz as clock source.
	RAM	-	6 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value, and periodically refreshed to prevent a reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111101x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.

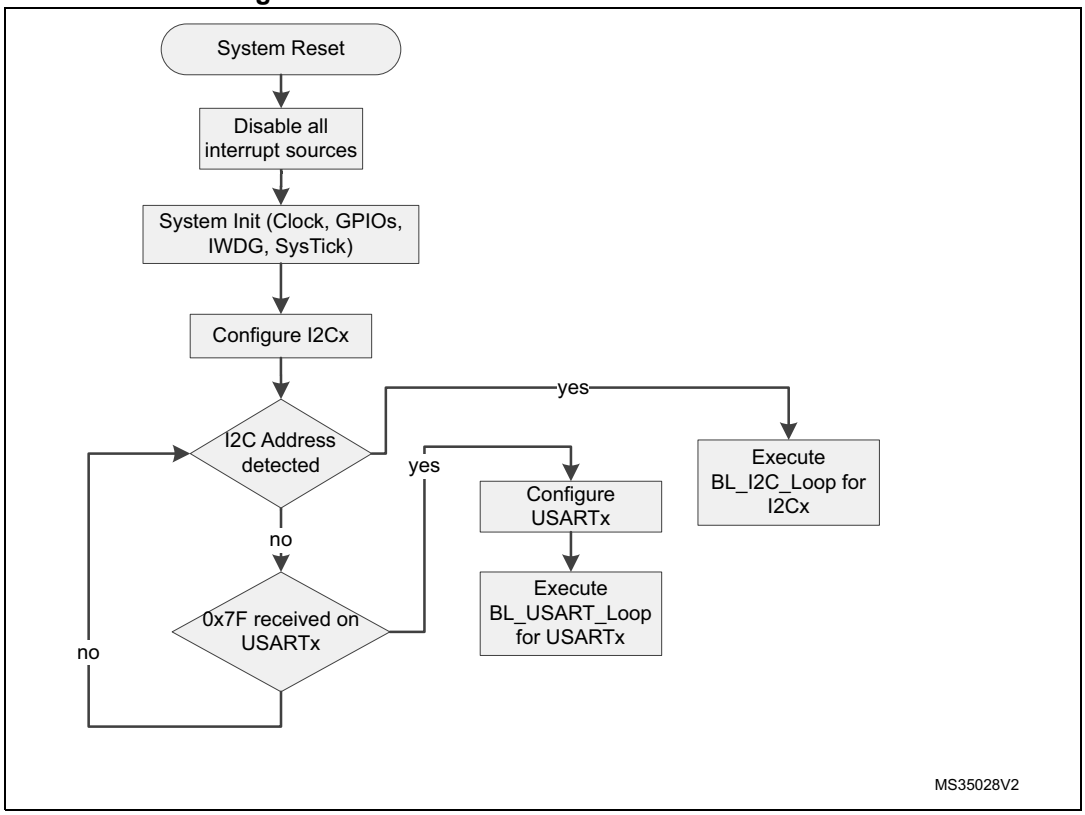
Table 64. STM32F318xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111101x (x = 0 for write and x = 1 for read) and digital filter disabled.
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin		PB5 pin: data line is used in open-drain no pull mode.

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

29.2 Bootloader selection

Figure 38. Bootloader selection for STM32F318xx



29.3 Bootloader version

Table 65. STM32F318xx bootloader versions

Version number	Description	Known limitations
V5.0	Initial bootloader version	RAM parity checks can cause a bootloader crash if RAM is not initialized. The bootloader does not initialize RAM before execution. Workaround: Initialize the SRAM before entering the bootloader when parity check is enabled.

30 STM32F358xx devices

30.1 Bootloader configuration

The STM32F358xx bootloader is activated by applying Pattern 2 (described in *Table 2*). *Table 66* shows the hardware resources used by this bootloader.

Table 66. STM32F358xx configuration in system memory boot mode

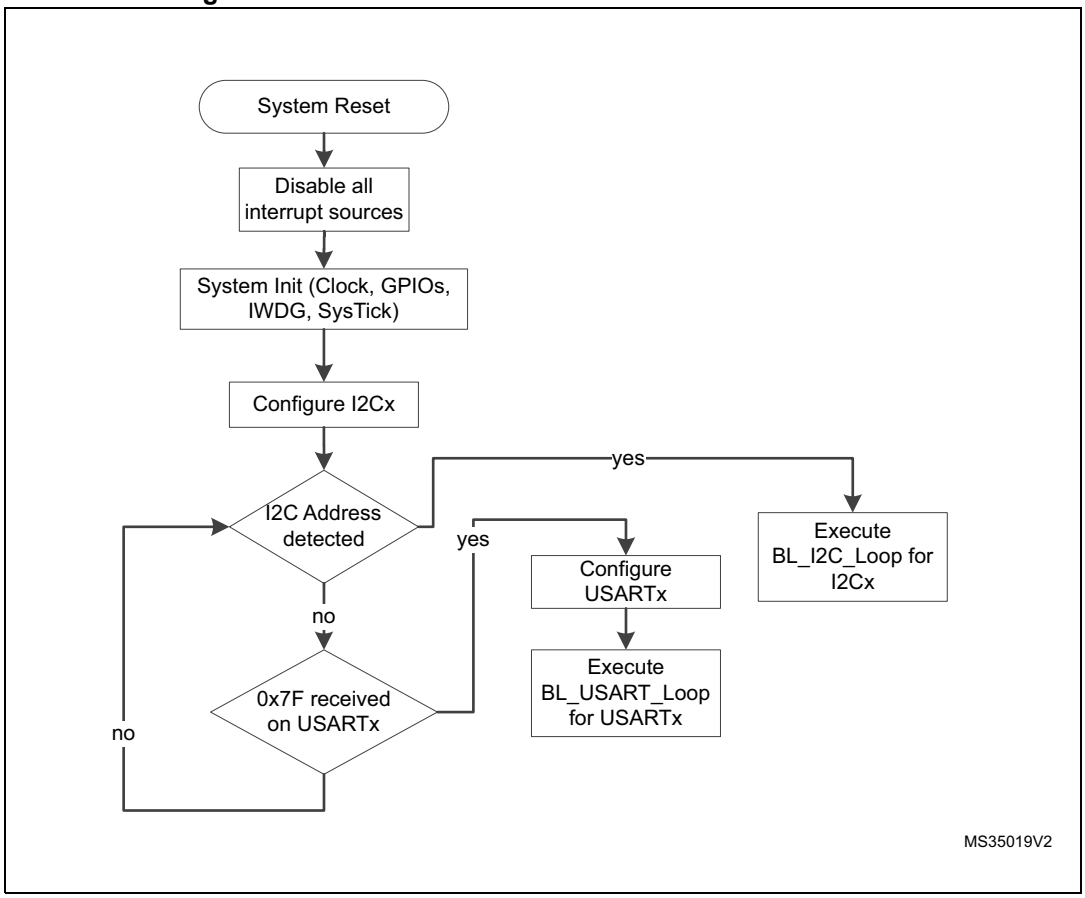
Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 8 MHz using the HSI.
	RAM	-	5 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contains the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user). Window feature is disabled.
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloader.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0110111x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

30.2 Bootloader selection

Figure 39 shows the bootloader selection mechanism.

Figure 39. Bootloader selection for STM32F358xx devices



30.3 Bootloader version

Table 67 lists the STM32F358xx devices bootloader versions.

Table 67. STM32F358xx bootloader versions

Version number	Description	Known limitations
V5.0	Initial bootloader version	For USART1 and USART2 interfaces, the maximum baudrate supported by the bootloader is 57600 baud.

31 STM32F373xx devices

31.1 Bootloader configuration

The STM32F373xx bootloader is activated by applying Pattern 2 (described in *Table 2*). *Table 68* shows the hardware resources used by this bootloader.

Table 68. STM32F373xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	At startup, the system clock frequency is configured to 48 MHz using the HSI. If an external clock (HSE) is not present, the system is kept clocked from the HSI.
		HSE enabled	The external clock can be used for all bootloader interfaces and must have one the following values: 24, 18, 16, 12, 9, 8, 6, 4, 3 MHz. The PLL is used to generate the USB 48 MHz clock and the 48 MHz clock for the system clock.
		-	The CSS interrupt is enabled for the DFU. Any failure (or removal) of the external clock generates system reset.
	RAM	-	5 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contains the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloader.

Table 68. STM32F373xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB used in FS mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. An external pull-up resistor 1.5 KΩ must be connected to USB_DP pin.

There are two operation modes, depending upon the presence of the external clock (HSE) at bootloader startup:

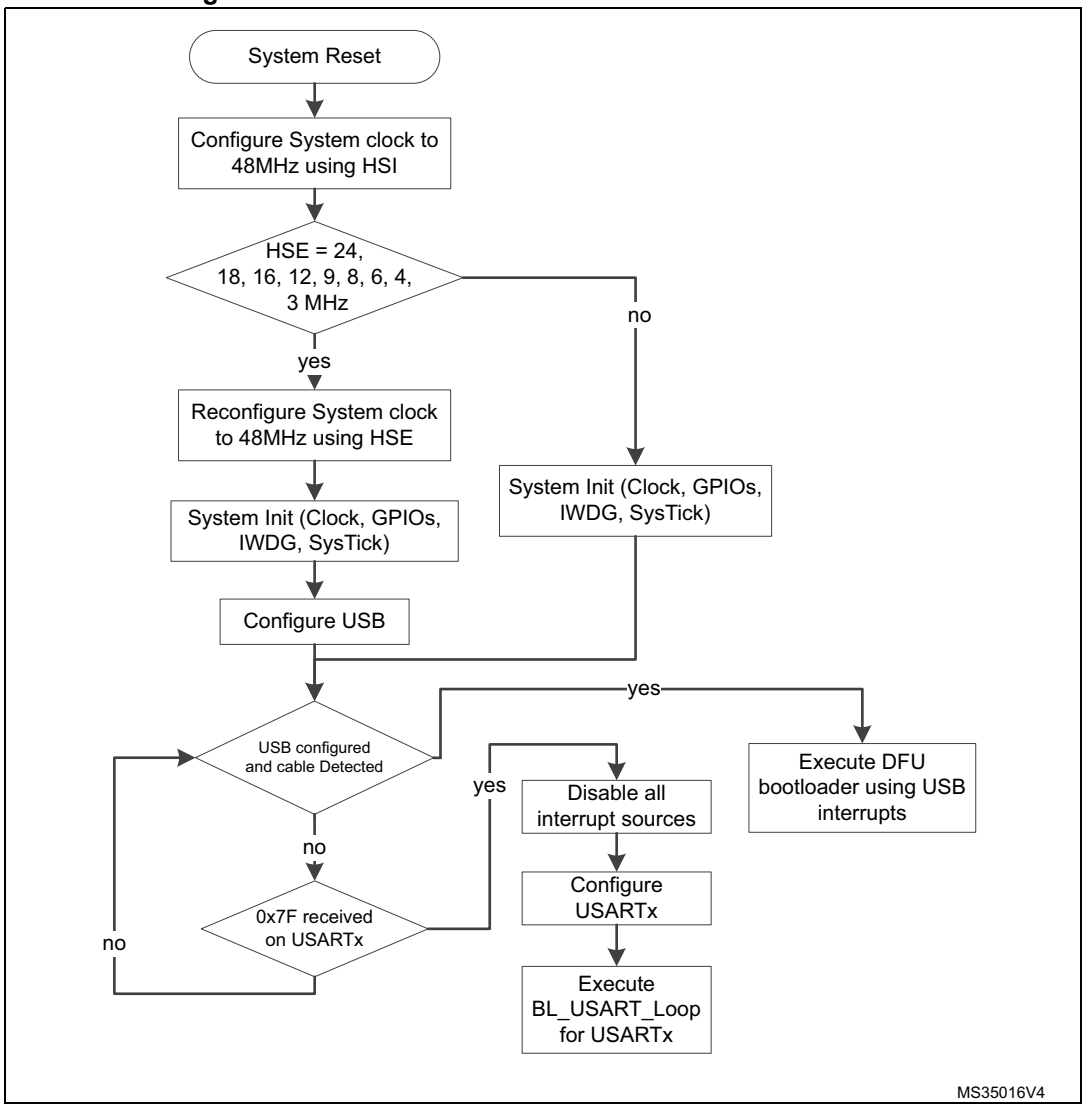
- If HSE is present and has a value of 24, 18, 16, 12, 9, 8, 6, 4, or 3 MHz, the system clock is configured to 48 MHz with HSE as clock source. The DFU interface, USART1 and USART2 are functional and can be used to communicate with the bootloader.
- If HSE is not present, the HSI is kept as default clock source, and only USART1 and USART2 are functional.

Note: The external clock (HSE) must be kept if it is connected at bootloader startup, because it is used as system clock source.

31.2 Bootloader selection

Figure 40 shows the bootloader selection mechanism.

Figure 40. Bootloader selection for STM32F373xx devices



31.3 Bootloader version

Table 69 lists the STM32F373xx devices bootloader versions.

Table 69. STM32F373xx bootloader versions

Version number	Description	Known limitations
V4.1	Initial bootloader version	– The USB bootloader fails on some machines using a high speed controller. The bootloader is detected. but then data transaction fails. Root causes: De-synchronization between USB controller and bootloader SW due to the controller high speed transactions. Controller high speed inter-packet delay seems not sufficient for the bootloader SW (based on interrupt routines) to serve all needed transactions (the delay needed by the BL is nearly 25 µs). Some servicing IT are missed. This results in a communication fail, causing Write command to fail. Workarounds: Add an USB HUB between the host and the MCU. This relaxes transactions inter-packet delay, and allows the BL SW to perform correctly the task. Use USB controller/host that increase inter-packet delay. On new designs, use DFU SW that fix the issue in user flash memory.

32 STM32F378xx devices

32.1 Bootloader configuration

The STM32F378xx bootloader is activated by applying Pattern 2 (described in *Table 2*). *Table 70* shows the hardware resources used by this bootloader.

Table 70. STM32F378xx configuration in system memory boot mode

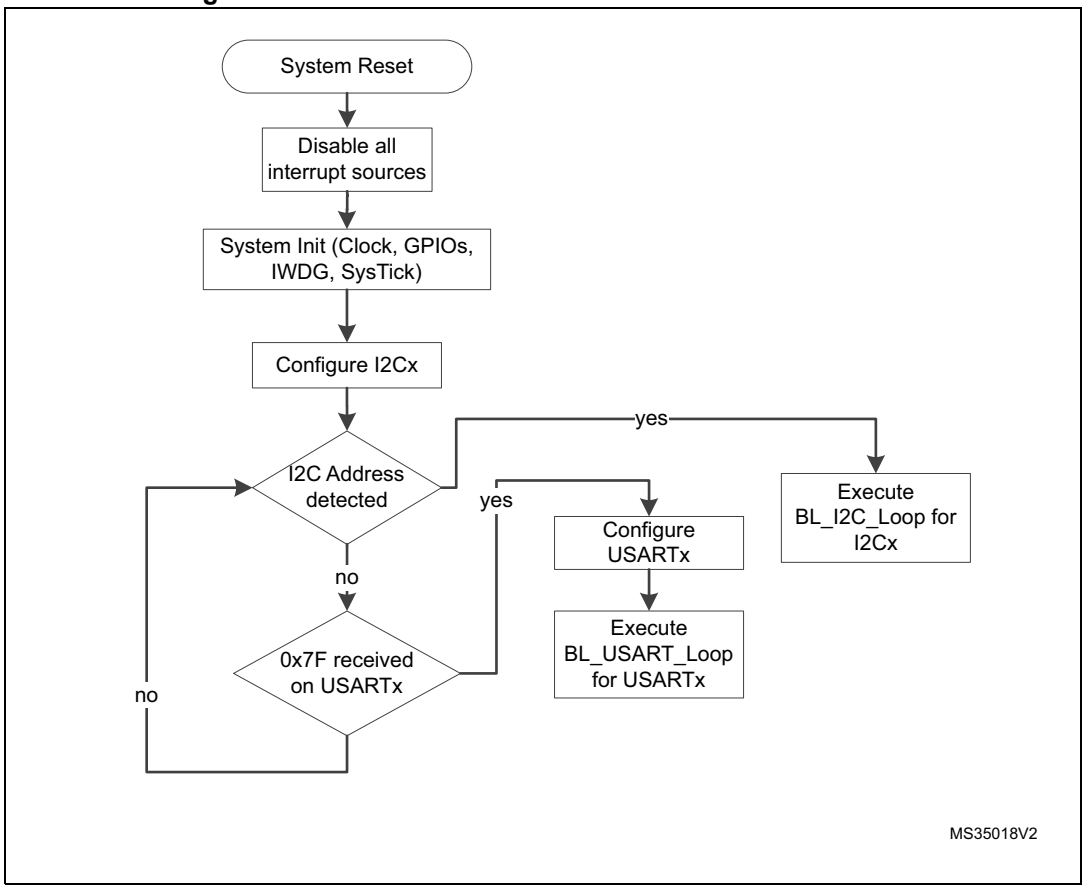
Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 8 MHz using the HSI.
	RAM	-	4 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contains the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user). Window feature is disabled.
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloader.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0110111x (x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

32.2 Bootloader selection

Figure 41 shows the bootloader selection mechanism.

Figure 41. Bootloader selection for STM32F378xx devices



32.3 Bootloader version

Table 71 lists the STM32F378xx devices bootloader versions.

Table 71. STM32F378xx bootloader versions

Version number	Description	Known limitations
V5.0	Initial bootloader version	For USART1 and USART2 interfaces, the maximum baudrate supported by the bootloader is 57600 baud.

33 STM32F398xx devices

33.1 Bootloader configuration

The STM32F398xx bootloader is activated by applying Pattern 2 (described in *Table 2*). *Table 72* shows the hardware resources used by this bootloader.

Table 72.STM32F398xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz with HSI 8 MHz as clock source.
	RAM	-	6 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	7 Kbytes, starting from address 0x1FFFD800, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000000x (x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.

Table 72.STM32F398xx configuration in system memory boot mode (continued)

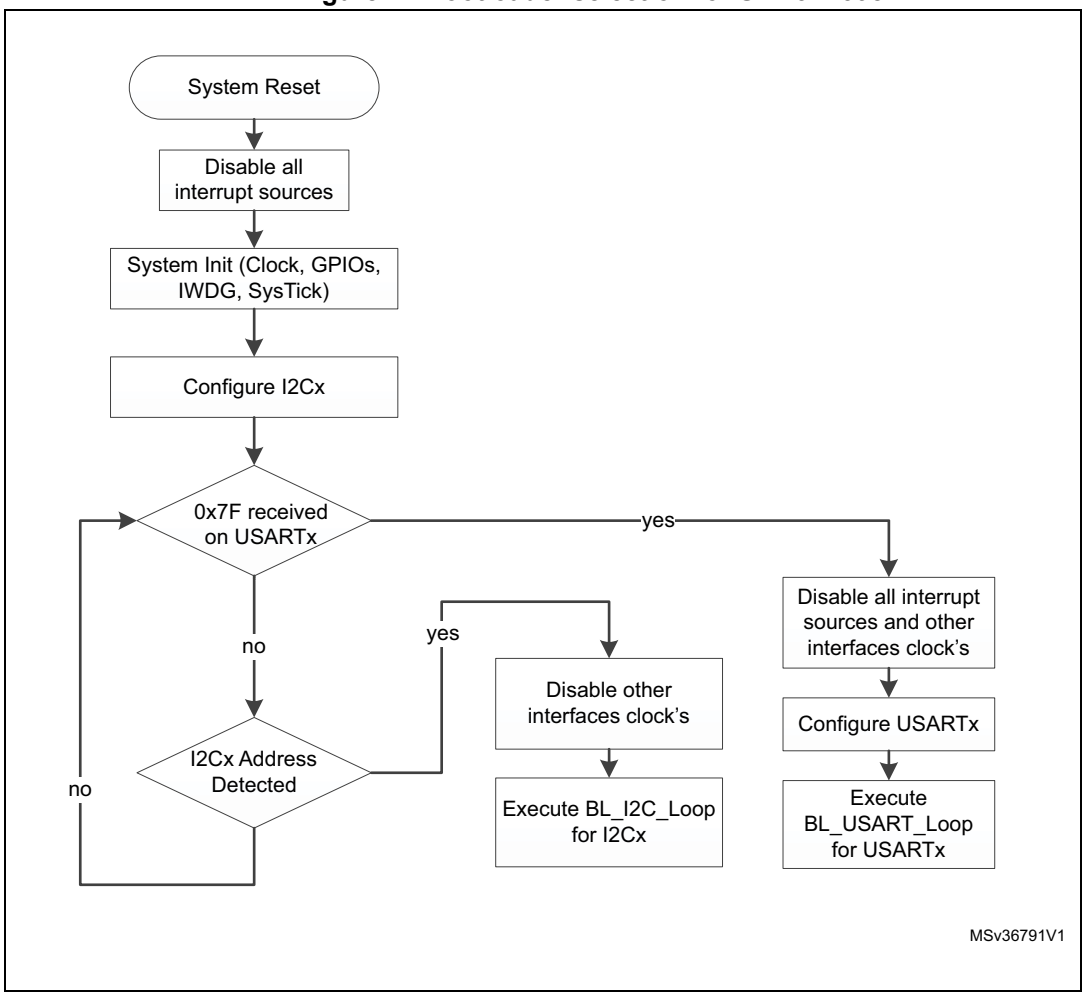
Bootloader	Feature/Peripheral	State	Comment
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address, Target mode – Analog filter ON – Target 7-bit address: 0b1000000x (x = 0 for write and x = 1 for read).
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin		PB5 pin: data line is used in open-drain no pull mode.

The system clock is derived from the embedded internal high-speed RC for all bootloader interfaces. No external quartz is required for bootloader operations.

33.2 Bootloader selection

Figure 42 shows the bootloader selection mechanism.

Figure 42.Bootloader selection for STM32F398xx



33.3 Bootloader version

Table 73 lists the STM32F398xx devices bootloader versions.

Table 73. STM32F398xx bootloader versions

Version number	Description	Known limitations
V5.0	Initial bootloader version	RAM parity checks can cause a bootloader crash if RAM is not initialized. The bootloader does not initialize RAM before execution. Workaround: Initialize the SRAM before entering the bootloader when parity check is enabled.

34 STM32F40xxx/41xxx devices

34.1 Bootloader V3.x

34.1.1 Bootloader configuration

The STM32F40xxx/41xxx bootloader is activated by applying Pattern 1 (described in *Table 2*). *Table 74* shows the hardware resources used by this bootloader.

Table 74. STM32F40xxx/41xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USARTx interfaces are selected (once CAN or DFU is selected, the clock source is derived from the external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the CAN or the DFU (USB FS device) interfaces are selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFUs. Any failure (or removal) of the external clock generates system reset.
	RAM	-	8 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	29 Kbytes, starting from address 0x1FFF 0000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62 V, 2.1 V]. In this range internal flash write operations are allowed only in byte format (half-word, word, and double-word operations are not allowed). The voltage range can be configured in run time using bootloader commands.
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode

Table 74. STM32F40xxx/41xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3 (on PB10/PB11)	USART3	Enabled	Once initialized, the USART3 configuration is 8 bits, even parity, and one stop bit.
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 (on PC10/PC11)	USART3	Enabled	Once initialized, the USART3 configuration is 8 bits, even parity, and one stop bit.
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. used in input pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
CAN2	CAN2	Enabled	Once initialized, the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. **Note:** CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
DFU	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
CAN2 and DFUs	TIM11	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

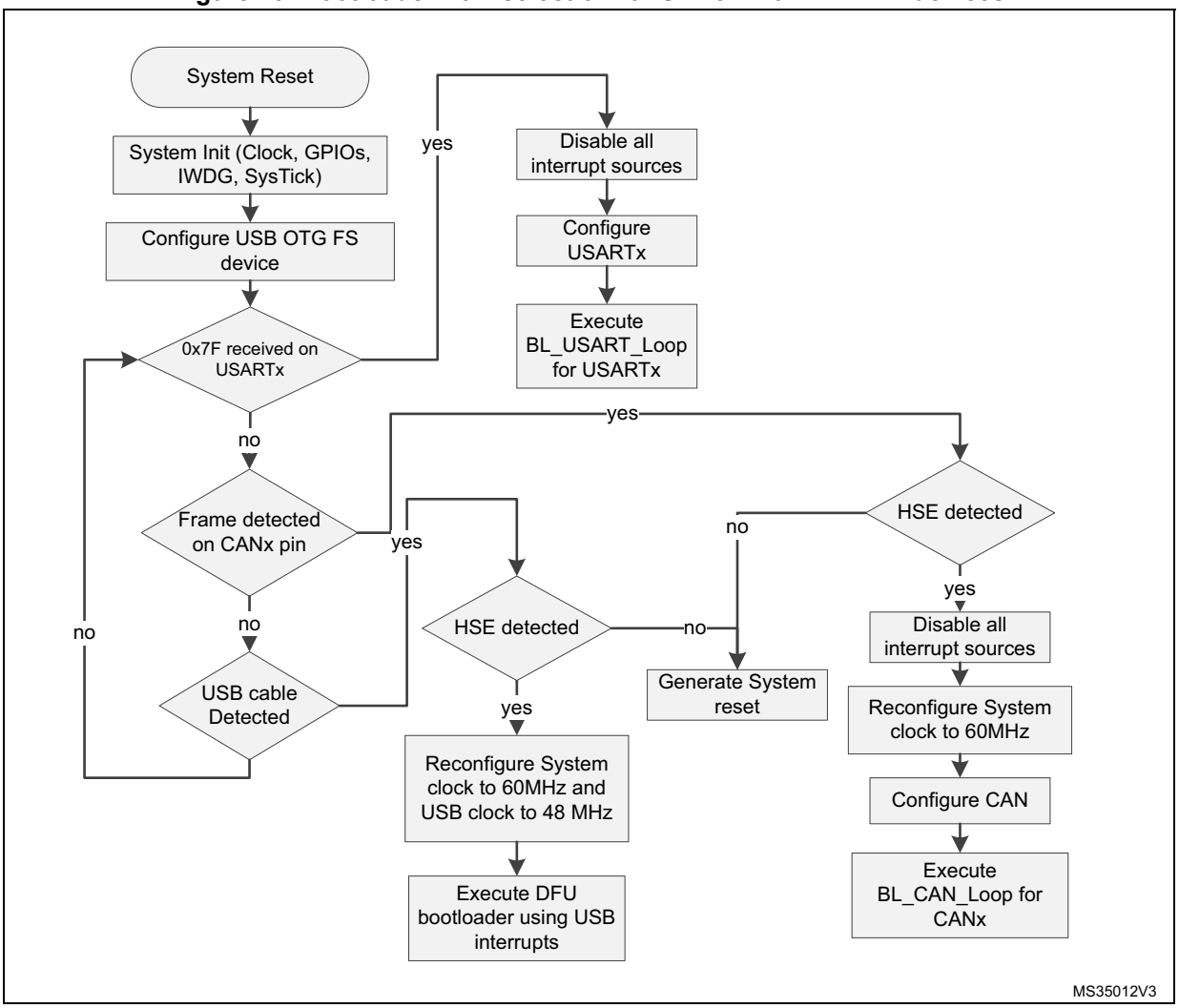
The system clock is derived from the embedded internal high-speed RC for USARTx. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, use low rather than high frequency HSE crystals (low frequency values are better detected due to larger error margin). For example, 8 MHz must be used instead of 25 MHz.

34.1.2 Bootloader selection

Figure 43 shows the bootloader selection mechanism.

Figure 43. Bootloader V3.x selection for STM32F40xxx/41xxx devices



34.1.3 Bootloader version

Table 75 lists the STM32F40xxx/41xxx devices V3.x bootloader versions:

Table 75. STM32F40xxx/41xxx bootloader V3.x versions

Version number	Description	Known limitations
V3.0	Initial bootloader version	– When a Read Memory command or Write Memory command is issued with an unsupported memory address and a correct address checksum (i.e. address 0x6000 0000), the command is aborted by the bootloader device, but the NACK (0x1F) is not sent to the host. As a result, the next two bytes (which are the number of bytes to be read/written and its checksum) are considered as a new command and its checksum(1). – Option bytes, OTP and Device Feature descriptors (in DFU interface) are set to “g” instead of “e” (not erasable memory areas). After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)
V3.1	– Fix V3.0 limitations – DFU interface robustness enhancement	– For the USART interface, two consecutive NACKs (instead of 1 NACK) are sent when a Read Memory or Write Memory command is sent and the RDP level is active. – For the CAN interface, the Write Unprotect command is not functional. Use Write Memory command and write directly to the option bytes in order to disable the write protection. After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)

1. If the “number of data - 1” (N-1) to be read/written is not equal to a valid command code (0x00, 0x01, 0x02, 0x11, 0x21, 0x31, 0x43, 0x44, 0x63, 0x73, 0x82 or 0x92), the limitation is not perceived from the host, as the command is NACK-ed anyway (as an unsupported new command).

34.2 Bootloader V9.x

34.2.1 Bootloader configuration

The STM32F40xxx/41xxx bootloader is activated by applying Pattern 1 (described in *Table 2*). *Table 76* shows the hardware resources used by this bootloader.

Note: The bootloader version V9.0 is embedded only in STM32F405xx/415xx devices in WLCSP90 package.

Version V9.1 is populated in all packages of the product.

Table 76. STM32F40xxx/41xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USART or SPI or I2C interfaces are selected (once CAN or DFU is selected, the clock source is derived from the external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the CAN or the DFU (USB FS device) interfaces are selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFUs. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62 V, 2.1 V]. In this range internal flash write operations are allowed only in byte format (half-word, word, and double-word operations are not allowed). The voltage range can be configured in run time using bootloader commands.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART3 (on PB10/PB11)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode
USART3 (on PC10/PC11)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.

Table 76. STM32F40xxx/41xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
CAN2	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. **Note:** CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111010x (x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111010x (x = 0 for write and x = 1 for read).
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin		PF0 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111010x (x = 0 for write and x = 1 for read).
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin		PC9 pin: data line is used in open-drain no pull mode.

Table 76. STM32F40xxx/41xxx configuration in system memory boot mode (continued)

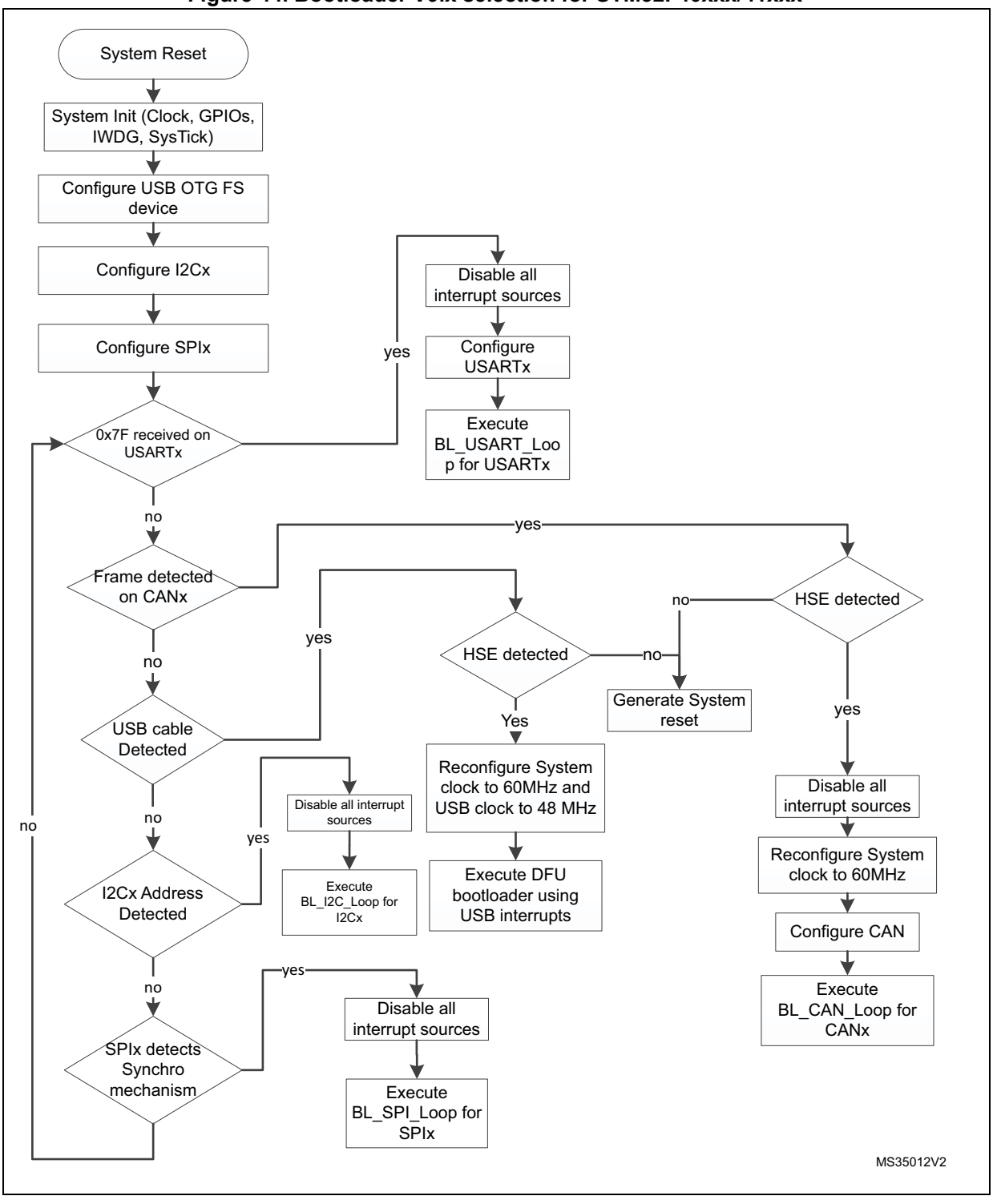
Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz, Polarity: CPOL low, CPHA low, – NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin		PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz, Polarity: CPOL low, CPHA low, – NSS hardware.
	SPI2_MOSI pin	Input	PI3 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PI2 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PI1 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PI0 pin: slave chip select pin used in push-pull, pull-down mode.
DFU	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
CAN2 and DFUs	TIM11	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

The system clock is derived from the embedded internal high-speed RC for USARTx, I2Cx, and SPIx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

34.2.2 Bootloader selection

Figure 44. Bootloader V9.x selection for STM32F40xxx/41xxx



34.2.3 Bootloader version

Table 77 lists the STM32F40xxx/41xxx devices V9.x bootloader versions.

Table 77. STM32F40xxx/41xxx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	This bootloader is an updated version of bootloader v3.1. This new version of bootloader supports I2C1, I2C2, I2C3, SPI1 and SPI2 interfaces. The RAM used by this bootloader is increased from 8 to 12 Kb. The ID of this bootloader is 0x90. The connection time is increased.	– For the USART interface, two consecutive NACKs (instead of 1 NACK) are sent when a Read Memory or Write Memory command is sent and the RDP level is active. – For the CAN interface, the Write Unprotect command is not functional. Use Write Memory command and write directly to the option bytes in order to disable the write protection. After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)
V9.1	This bootloader is an updated version of bootloader v9.0 that will be populated in all packages even the one embedding the V3.1 bootloader version. It contains fixes of the known limitations of the V9.0	None

35 STM32F401xB(C) devices

35.1 Bootloader configuration

The STM32F401xB(C) bootloader is activated by applying Pattern 1 (described in *Table 2*). *Table 78* shows the hardware resources used by this bootloader.

Table 78. STM32F401xB(C) configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USART or SPI or I2C interface is selected (once DFU is selected, the clock source is derived from the external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the DFU (USB FS device) interface is selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFUs. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62 V, 2.1 V]. In this range internal flash write operations are allowed only in byte format (half-word, word, and double-word operations are not allowed). The voltage range can be configured in run time using bootloader commands.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in input pull-up mode.

Table 78. STM32F401xB(C) configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111010x (x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111010x (x = 0 for write and x = 1 for read).
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin		PB3 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111010x (x = 0 for write and x = 1 for read).
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin		PB4 pin: data line is used in open-drain no pull mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin		PA4 pin: slave chip select pin used in push-pull, pull-down mode.

Table 78. STM32F401xB(C) configuration in system memory boot mode (continued)

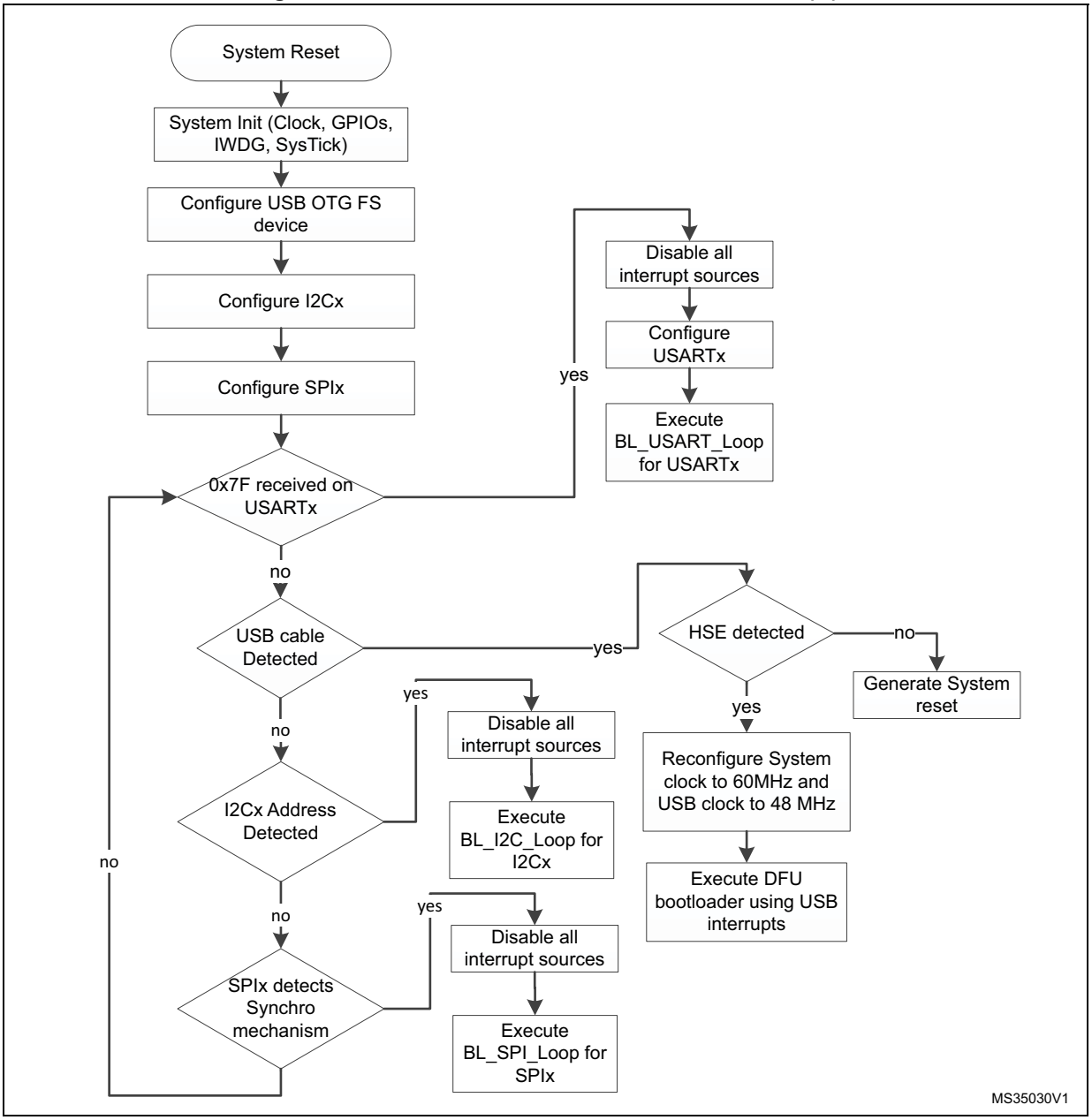
Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin		PB12 pin: slave chip select pin used in push-pull, pull-down mode.
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data input line, used in push-pull, pull-down mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, pull-down mode
	SPI3_NSS pin		PA15 pin: slave chip select pin used in push-pull, pull-down mode.
DFU	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
	TIM11	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

The system clock is derived from the embedded internal high-speed RC for USARTx, I2Cx, and SPIx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock, multiple of 1 MHz (between 4 and 26 MHz), is required for CAN and DFU execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

35.2 Bootloader selection

Figure 45. Bootloader selection for STM32F401xB(C)



35.3 Bootloader version

Table 79. STM32F401xB(C) bootloader versions

Version number	Description	Known limitations
V13.0	Initial bootloader version	– After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup) – The bootloader does not support the reset of SPRMOD bit during RDP regression

36 STM32F401xD(E) devices

36.1 Bootloader configuration

The STM32F401xD(E) bootloader is activated by applying Pattern 1 (described in *Table 2*). *Table 80* shows the hardware resources used by this bootloader.

Table 80. STM32F401xD(E) configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USART or SPI or I2C interface is selected (once DFU is selected, the clock source is derived from the external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the DFU (USB FS device) interface is selected. The external clock must provide a frequency multiple of 1 MHz, ranging from 4 to 26 MHz.
		-	The CSS interrupt is enabled for the DFU. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to 1.62 V, 2.1 V. In this range internal flash write operations are allowed only in byte format (half-word, word, and double-word operations are not allowed). The voltage range can be configured in run time using bootloader commands.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in no pull mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.

Table 80. STM32F401xD(E) configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111001x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111001x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin		PB3 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111001x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin		PB4 pin: data line is used in open-drain no pull mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.

Table 80. STM32F401xD(E) configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data input line, used in push-pull, pull-down mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, pull-down mode
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, pull-down mode.
DFU	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
	TIM11	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

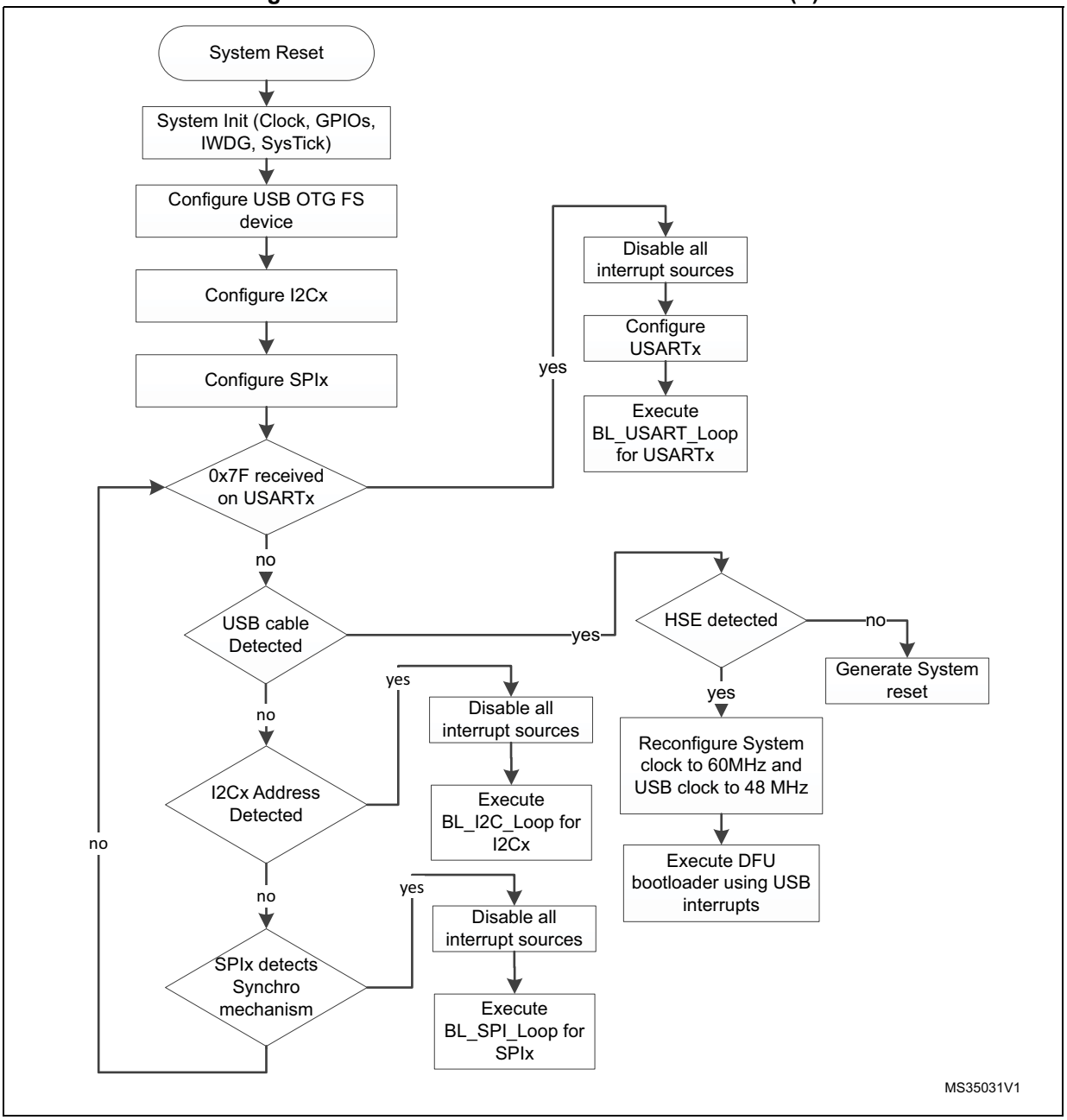
The system clock is derived from the embedded internal high-speed RC for USARTx, I2Cx, and SPIx bootloaders. This internal clock is also used for DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for DFU execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

36.2 Bootloader selection

Figure 46 shows the bootloader selection mechanism.

Figure 46. Bootloader selection for STM32F401xD(E)



36.3 Bootloader version

Table 81 lists the STM32F401xD(E) devices bootloader version.

Table 81. STM32F401xD(E) bootloader versions

Version number	Description	Known limitations
V13.1	Initial bootloader version	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)

37 STM32F410xx devices

37.1 Bootloader configuration

The STM32F410xx bootloader is activated by applying Pattern 1 (described in *Table 2*). *Table 82* shows the hardware resources used by this bootloader.

Table 82. STM32F410xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART and I2C bootloader operation.
	RAM	-	5 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The voltage range is [1.8V, 3.6V]. In this range: – Flash wait states: 3. – System clock frequency 60 MHz. – ART Accelerator enabled. – Flash write operation by byte (refer to bootloader memory management section for more information).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.

Table 82. STM32F410xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000111x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000111x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin		PB11 pin: data line is used in open-drain no pull mode.
I2C4	I2C4	Enabled	The I2C4 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000111x (x = 0 for write and x = 1 for read)
	I2C4_SCL pin	Input/output	PB15 pin: clock line is used in open-drain no pull mode for STM32F410Cx/Rx devices. PB10 pin: clock line is used in open-drain no pull mode for STM32F410Tx devices.
	I2C4_SDA pin	Input/output	PB14 pin: data line is used in open-drain no pull mode for STM32F410Cx/Rx devices. PB3 pin: data line is used in open-drain no pull mode for STM32F410Tx devices.

Table 82. STM32F410xx configuration in system memory boot mode (continued)

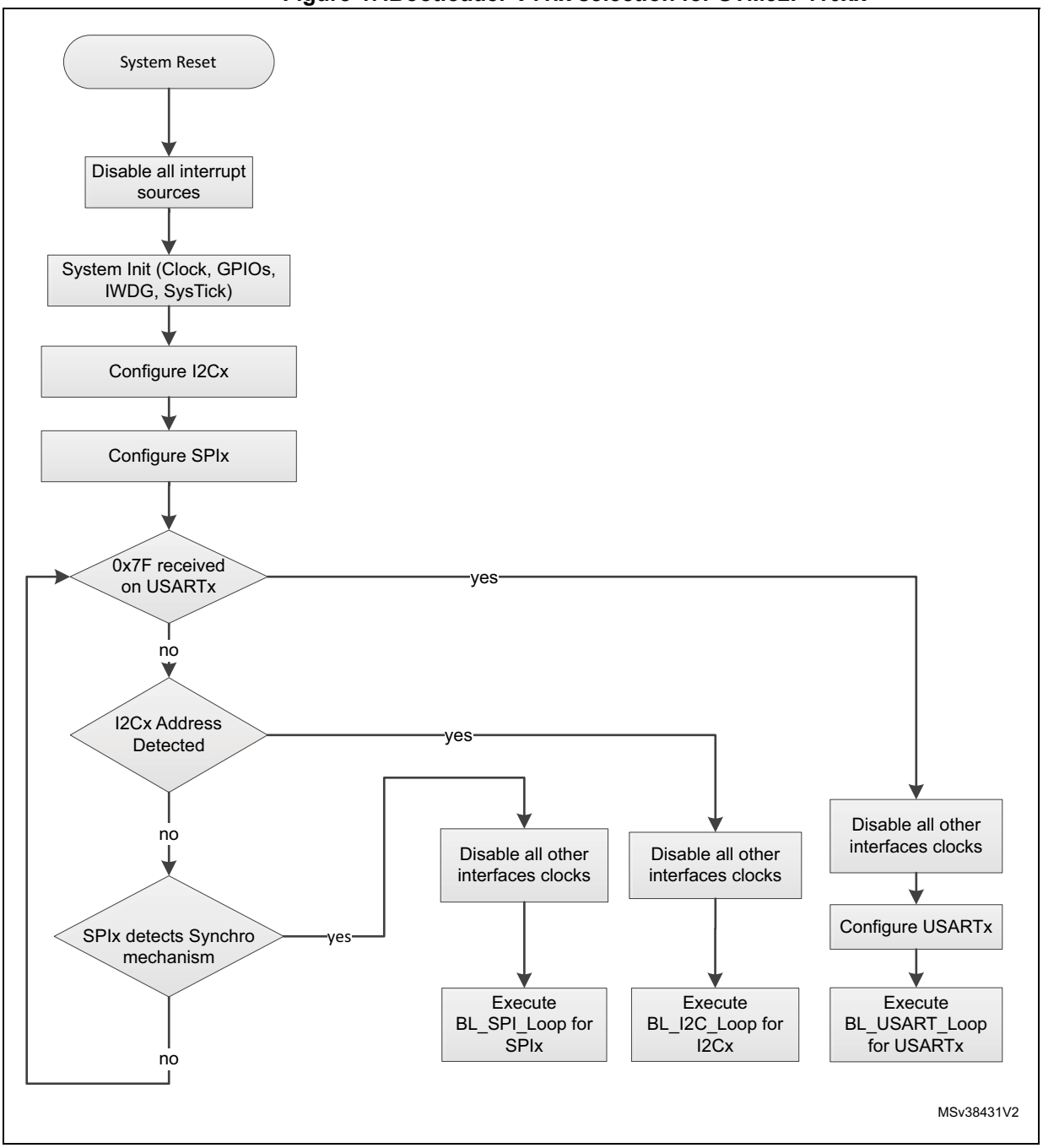
Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode for STM32F410Cx/Rx devices. PB5 pin: slave data input line, used in push-pull, pull-down mode for STM32F410Tx devices.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode for STM32F410Cx/Rx devices. PB4 pin: slave data output line, used in push-pull, pull-down mode for STM32F410Tx devices.
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode.
	SPI1_NSS pin		PA4 pin: slave chip select pin used in push-pull, pull-up mode for STM32F410Cx/Rx devices. PA15 pin: slave chip select pin used in push-pull, pull-down mode for STM32F410Tx devices.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PC3 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PC2 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.

The system clock is derived from the embedded internal high-speed RC for all bootloader interfaces. No external quartz is required for bootloader operations.

37.2 Bootloader selection

Figure 47 shows the bootloader selection mechanism.

Figure 47.Bootloader V11.x selection for STM32F410xx



37.3 Bootloader version

Table 83 lists the STM32F410xx devices bootloader V11.x versions.

Table 83. STM32F410xx bootloader V11.x versions

Version number	Description	Known limitations
V11.0	Initial bootloader version	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)
V11.1	Support I2C4 and SPI1 for STM32F410Tx devices	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)

38 STM32F411xx devices

38.1 Bootloader configuration

The STM32F411xx bootloader is activated by applying Pattern 1 (described in *Table 2*). *Table 84* shows the hardware resources used by this bootloader.

Table 84. STM32F411xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USART or SPI or I2C interface is selected (once DFU is selected, the clock source is derived from the external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the DFU (USB FS device) interface is selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the DFU. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62 V, 2.1 V]. In this range internal flash write operations are allowed only in byte format (half-word, word, and double-word operations are not allowed). The voltage range can be configured in run time using bootloader commands.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in input pull-up mode.

Table 84. STM32F411xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111001x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111001x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin		PB3 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111001x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin		PB4 pin: data line is used in open-drain no pull mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.

Table 84. STM32F411xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware
	SPI3_MOSI pin	Input	PC12 pin: slave data input line, used in push-pull, pull-down mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, pull-down mode
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, pull-down mode.
DFU	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
	TIM11	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

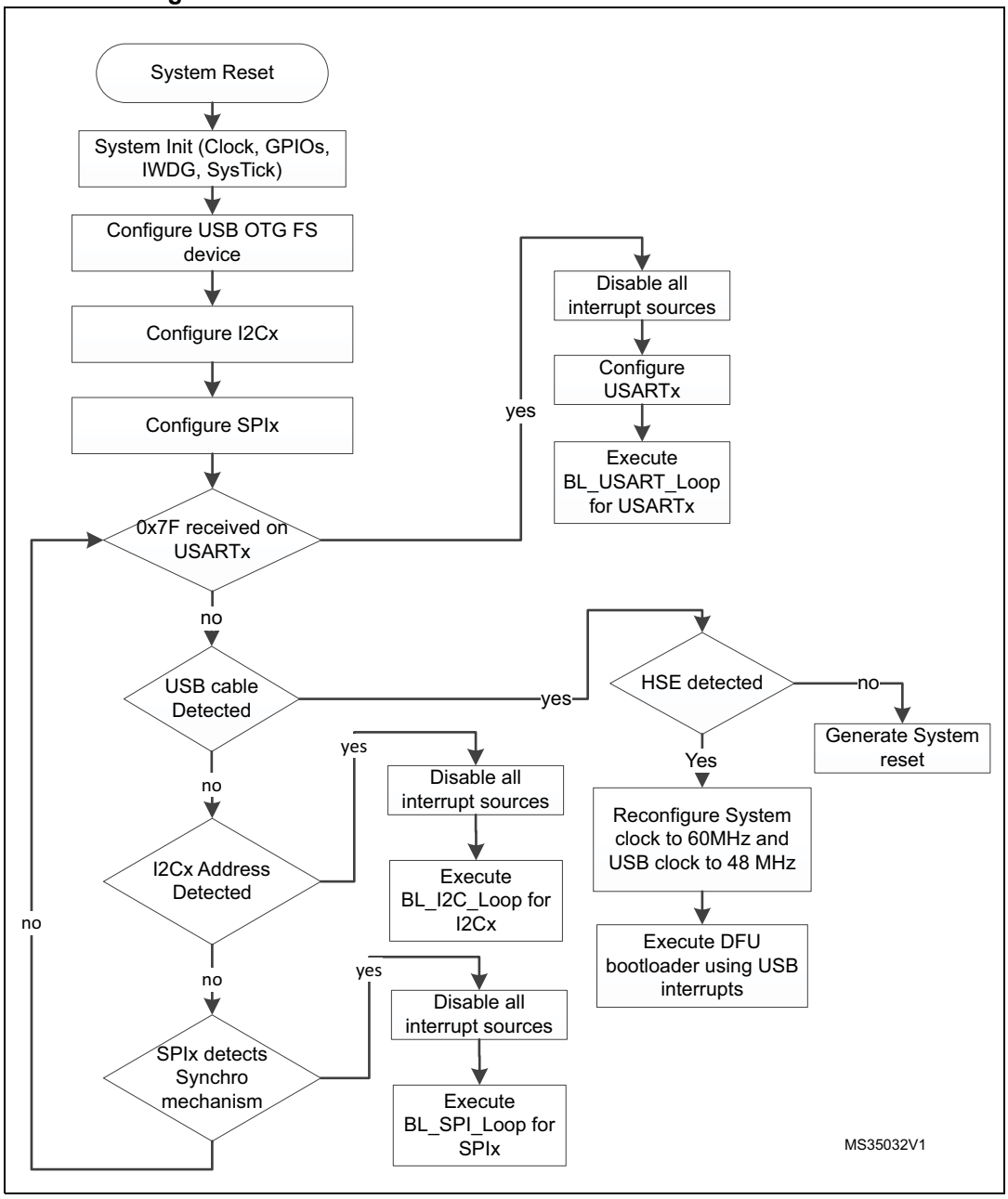
The system clock is derived from the embedded internal high-speed RC for USARTx, I2Cx I2Cx, and SPIx bootloaders. This internal clock is also used for DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for DFU execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

38.2 Bootloader selection

Figure 48 shows the bootloader selection mechanism.

Figure 48. Bootloader selection for STM32F411xx



38.3 Bootloader version

The following table lists the STM32F411xx devices bootloader version.

Table 85. STM32F411xx bootloader versions

Version number	Description	Known limitations
V13.0	Initial bootloader version	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)

39 STM32F412xx devices

39.1 Bootloader configuration

The STM32F412xx bootloader is activated by applying Pattern 1 (described in *Table 2*). *Table 86* shows the hardware resources used by this bootloader.

Table 86.STM32F412xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART and I2C bootloader operation.
		HSE enabled	The HSE is used only when the CAN or the DFU (USB FS device) interfaces are selected. In this case the system clock is configured to 60 MHz with HSE as clock source. The HSE frequency must be a multiple of 1 MHz, ranging from 4 to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFUs. Any failure (or removal) of the external clock generates a system reset.
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The voltage range is [1.8V, 3.6V]. In this range: – Flash wait states: 3. – System clock frequency 60 MHz. – ART Accelerator enabled. – Flash write operation by byte (refer to bootloader memory management section for more information).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in input pull-up mode.

Table 86.STM32F412xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
CAN2	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. **Note:** CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000110x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000110x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin		PF0 pin: data line is used in open-drain no pull mode.

Table 86.STM32F412xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000110x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin		PB4 pin: data line is used in open-drain no pull mode.
I2C4	I2C4	Enabled	The I2C4 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000110x (x = 0 for write and x = 1 for read)
	I2C4_SCL pin	Input/output	PB15 pin: clock line is used in open-drain no pull mode.
	I2C4_SDA pin		PB14 pin: data line is used in open-drain no pull mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin		PA4 pin: slave chip select pin used in push-pull, pull-up mode.

Table 86.STM32F412xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data input line, used in push-pull, pull-down mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, pull-down mode
	SPI3_NSS pin		PA15 pin: slave chip select pin used in push-pull, pull-up mode.
SPI4	SPI4	Enabled	The SPI4 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode
	SP4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-down mode
	SPI4_NSS pin		PE11 pin: slave chip select pin used in push-pull, pull-up mode.
DFU	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11 pin: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.
CAN2 and DFUs	TIM11	Enabled	This timer is used to determine the value of the HSE. Once HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

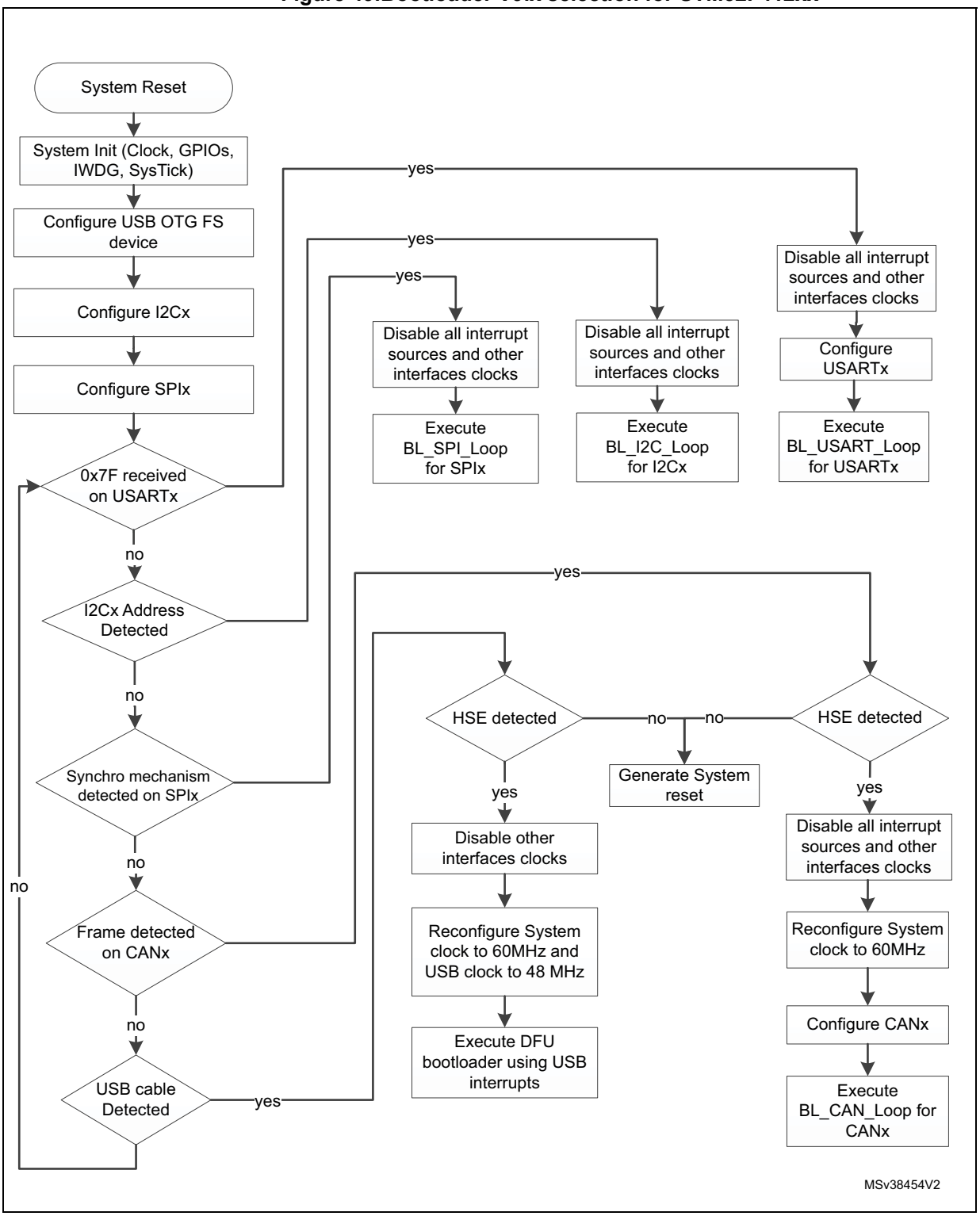
The system clock is derived from the embedded internal high-speed RC for USARTx and I2Cx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

39.2 Bootloader selection

Figure 49 shows the bootloader selection mechanism.

Figure 49.Bootloader V9.x selection for STM32F412xx



39.3 Bootloader version

The following table lists the STM32F412xx devices bootloader V9.x versions.

Table 87. STM32F412xx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	Initial bootloader version	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)
V9.1	Fix USART3 interface pinout	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)

40 STM32F413xx/423xx devices

40.1 Bootloader configuration

The STM32F413xx/423xx bootloader is activated by applying Pattern 1 (described in *Table 2*h). The following table shows the hardware resources used by this bootloader.

Table 88. STM32F413xx/423xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART and I2C bootloader operation.
		HSE enabled	The HSE is used only when the CAN or the DFU (USB FS device) interfaces are selected. In this case the system clock configured to 60 MHz with HSE as clock source. The HSE frequency must be multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFUs. Any failure (or removal) of the external clock generates system reset.
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	60 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The voltage range is [1.8V, 3.6V] In this range: – Flash wait states 4. – System clock frequency 60 MHz. – ART Accelerator enabled. – Flash write operation by byte (refer to *Bootloader memory management* for more information).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in input pull-up mode.

Table 88. STM32F413xx/423xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
CAN2	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. **Note**: CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1001011x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1001011x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1001011x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PB4 pin: data line is used in open-drain no pull mode.

Table 88. STM32F413xx/423xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C4	I2C4	Enabled	The I2C4 configuration is: I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1001011x (x = 0 for write and x = 1 for read)
	I2C4_SCL pin	Input/output	PB15 pin: clock line is used in open-drain no pull mode.
	I2C4_SDA pin	Input/output	PB14 pin: data line is used in open-drain no pull mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB, speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB, speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data input line, used in push-pull, pull-down mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, pull-down mode
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, pull-down mode.

Table 88. STM32F413xx/423xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI4	SPI4	Enabled	The SPI4 configuration is: – Slave mode – Full Duplex – 8-bit MSB, speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode
	SP4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-down mode
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-down mode.
DFU	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11 pin: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.
CAN2 and DFUs	TIM11	Enabled	This timer is used to determine the value of the HSE. Once HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

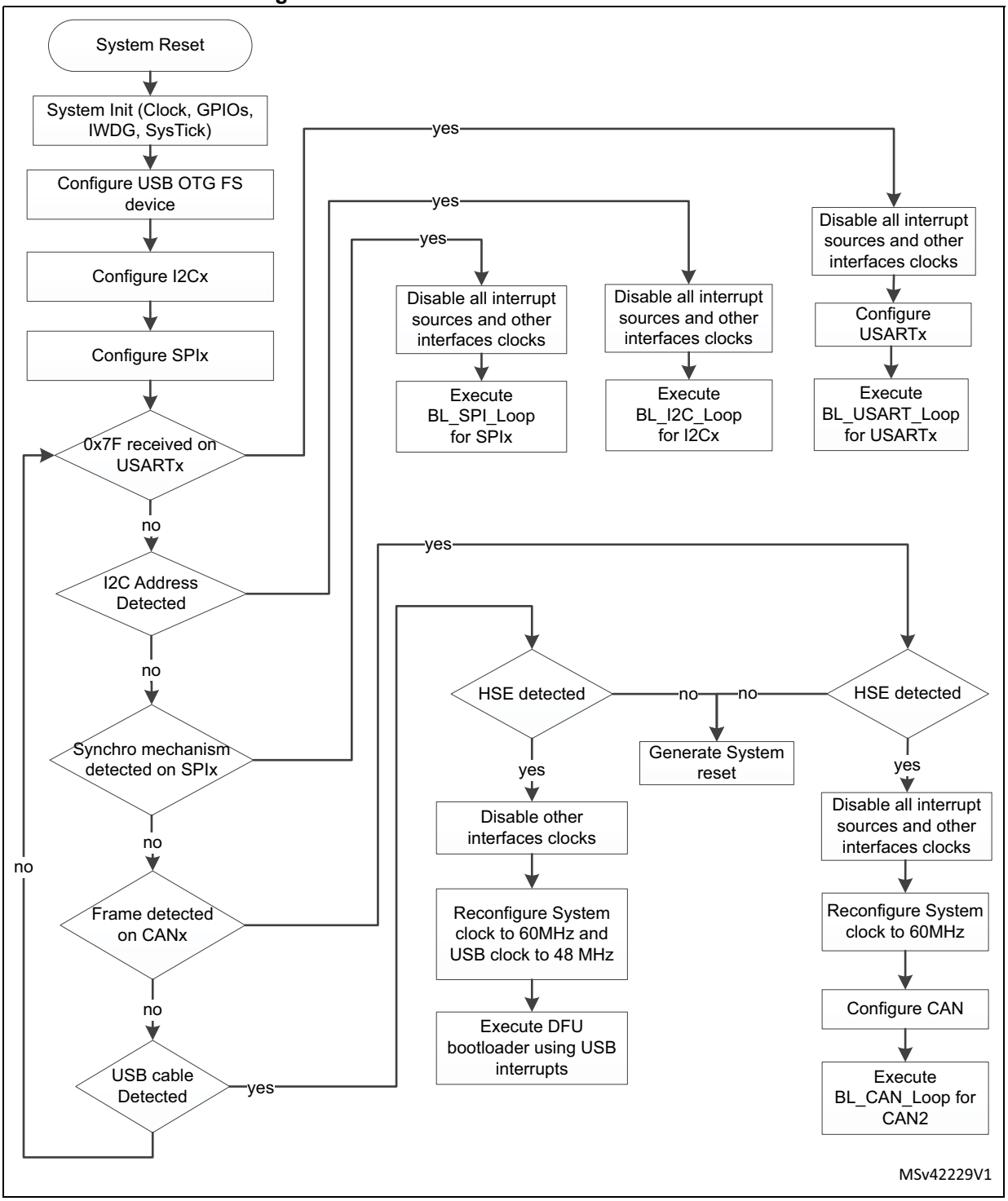
The system clock is derived from the embedded internal high-speed RC for USARTx and I2Cx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

40.2 Bootloader selection

Figure 50 shows the bootloader selection mechanism.

Figure 50.Bootloader V9.x selection for STM32F413xx/423xx



40.3 Bootloader version

The following table lists the STM32F413xx/423xx devices bootloader V9.x versions.

Table 89. STM32F413xx/423xx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	Initial bootloader version	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)

41 STM32F42xxx/43xxx devices

41.1 Bootloader V7.x

41.1.1 Bootloader configuration

The STM32F42xxx/43xxx bootloader is activated by applying Pattern 5 (described in *Table 2*). The following table shows the hardware resources used by this bootloader.

Table 90. STM32F42xxx/43xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USART or I2C interfaces are selected (once CAN or DFU is selected, the clock source is derived from the external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the CAN or the DFU (USB FS device) interfaces are selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFUs. Any failure (or removal) of the external clock /generates system reset.
	RAM	-	8 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62 V, 2.1 V]. In this range internal flash write operations are allowed only in byte format (half-word, word, and double-word operations are not allowed). The voltage range can be configured in run time using bootloader commands.

Table 90. STM32F42xxx/43xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1	USART1	Enabled	Once initialized, the configuration is 8 bits, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART3 (on PB10/PB11)	USART3	Enabled	Once initialized, the configuration is 8 bits, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 (on PC10/PC11)	USART3	Enabled	Once initialized, the configuration is 8 bits, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
CAN2	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. **Note**: CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push pull, pull-up mode.
I2C1	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, Slave mode, Analog filter ON Target 7-bit address: 0b0111000x (x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.

Table 90. STM32F42xxx/43xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push pull no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push pull no pull mode. No external pull-up resistor is required
CAN2 and DFUs	TIM11	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

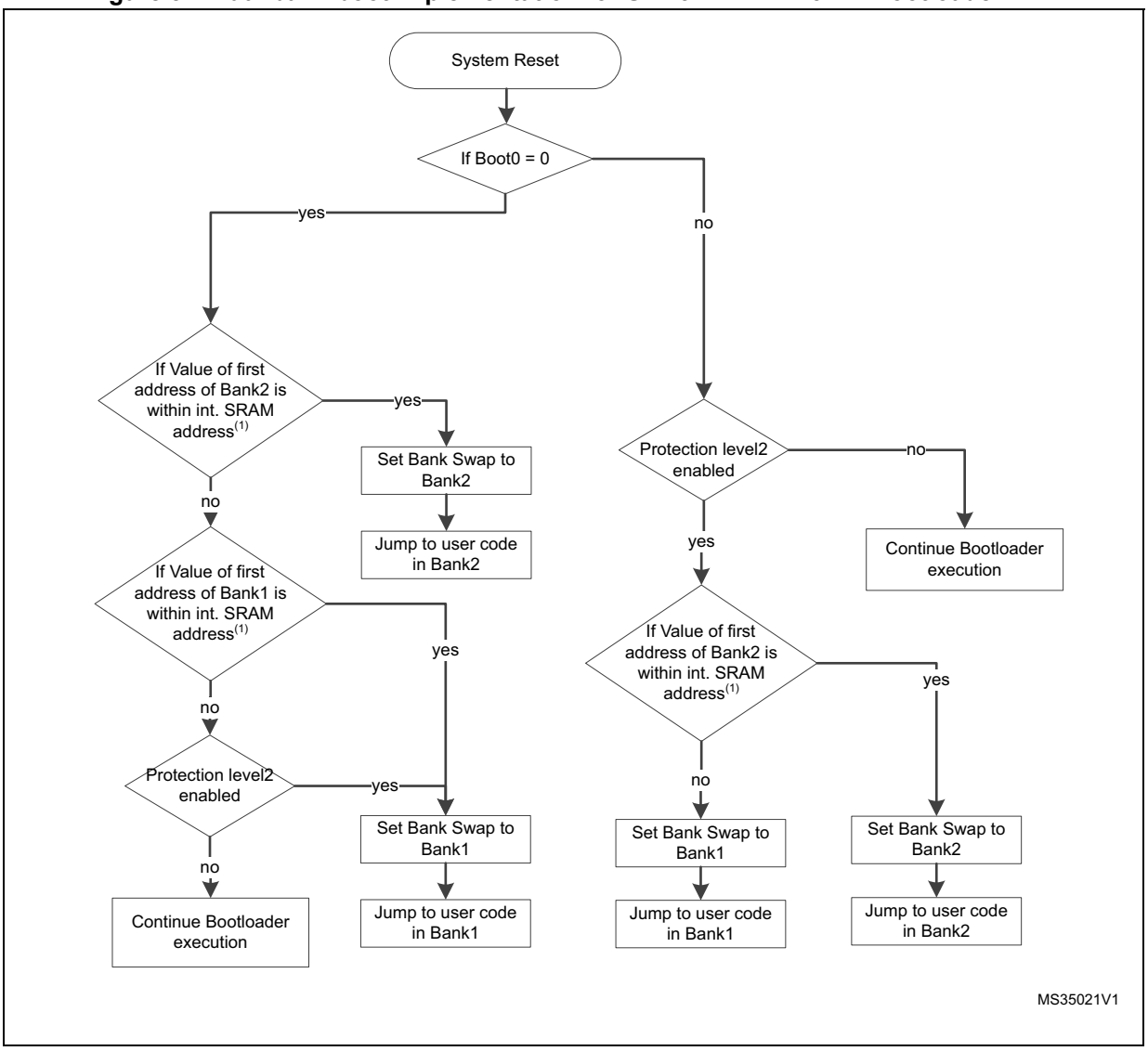
The system clock is derived from the embedded internal high-speed RC for USARTx and I2Cx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

41.1.2 Bootloader selection

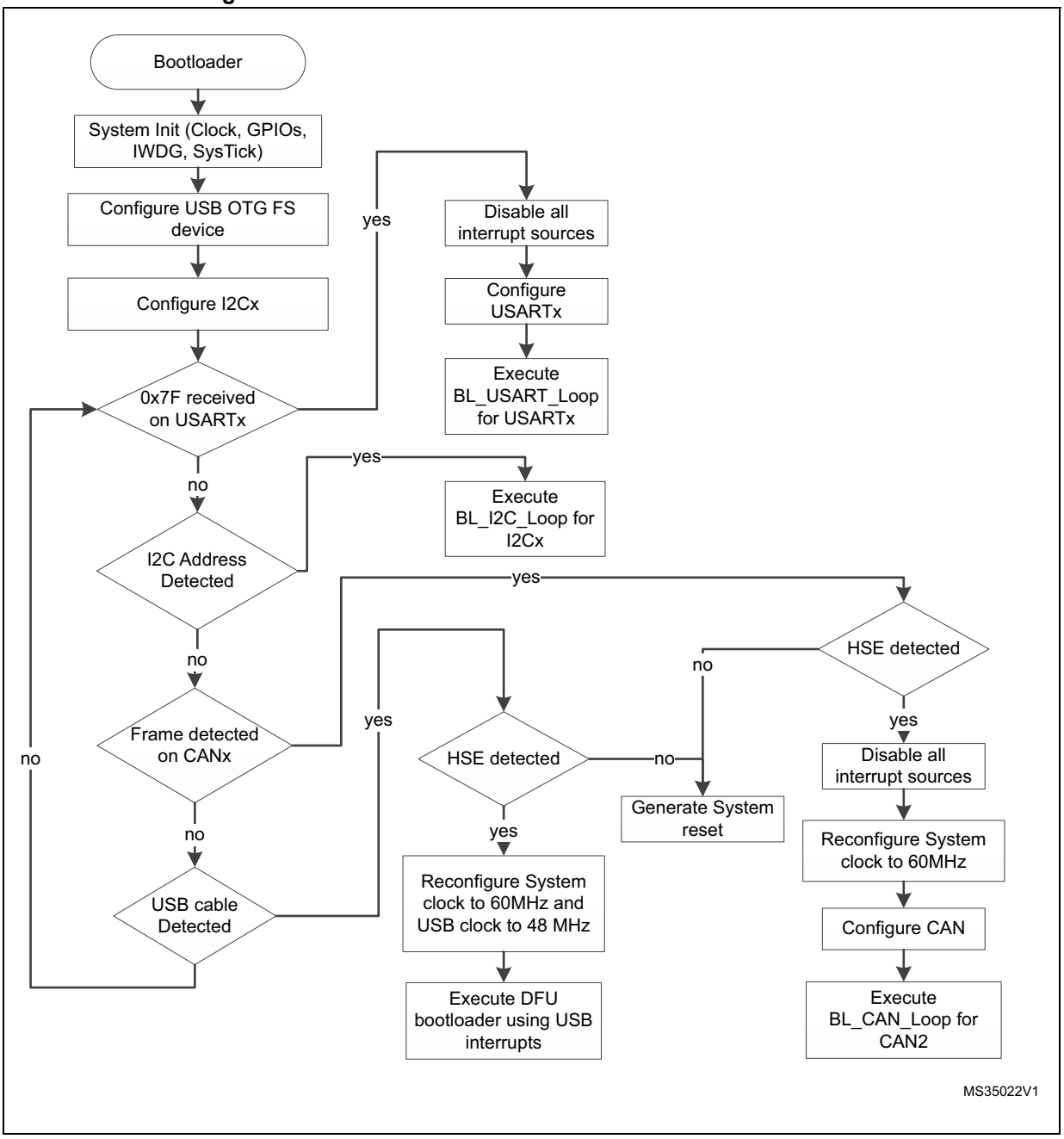
Figure 51 and *Figure 52* show the bootloader selection mechanism.

Figure 51. Dual bank boot implementation for STM32F42xxx/43xxx Bootloader V7.x



1. CCM RAM is not considered valid as stack pointer address for the dual bank boot mechanism.

Figure 52. Bootloader V7.x selection for STM32F42xxx/43xxx



41.1.3 Bootloader version

The following table lists the STM32F42xxx/43xxx devices bootloader V7.x versions.

Table 91. STM32F42xxx/43xxx bootloader V7.x versions

Version number	Description	Known limitations
V7.0	Initial bootloader version	For the CAN interface, the Write Unprotect command is not functional. Use Write Memory command and write directly to the option bytes to disable the write protection. For the USB DFU interface, in Dual Bank mode, the Erase operation is not functional for the second bank. Return to Single Bank mode, erase desired sector(s) and then reactivate the Dual Bank mode. After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup).

41.2 Bootloader V9.x

41.2.1 Bootloader configuration

The STM32F42xxx/43xxx bootloader is activated by applying Pattern 5 (described in *Table 2*). The following table shows the hardware resources used by this bootloader.

Table 92. STM32F42xxx/43xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USART or SPI or I2C interfaces are selected (once CAN or DFU is selected, the clock source is derived from the external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the CAN or the DFU (USB FS device) interfaces are selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFUs. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62 V, 2.1 V]. In this range internal flash write operations are allowed only in byte format (half-word, word, and double-word operations are not allowed). The voltage range can be configured in run time using bootloader commands.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.

Table 92. STM32F42xxx/43xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3 (on PB10/PB11)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 (on PC10/PC11)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit.
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
CAN2	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note**:** CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b0111000x (x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b0111000x (x = 0 for write and x = 1 for read).
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b0111000x (x = 0 for write and x = 1 for read).
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain mode.

Table 92. STM32F42xxx/43xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, -bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PI3 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PI2 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PI1 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PI0 pin: slave chip select pin used in push-pull, pull-down mode.
SPI4	SPI4	Enabled	The SPI4 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode
	SP4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-down mode
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-down mode.
DFU	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull no pull mode. No external pull-up resistor is required
CAN2 and DFUs	TIM11	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

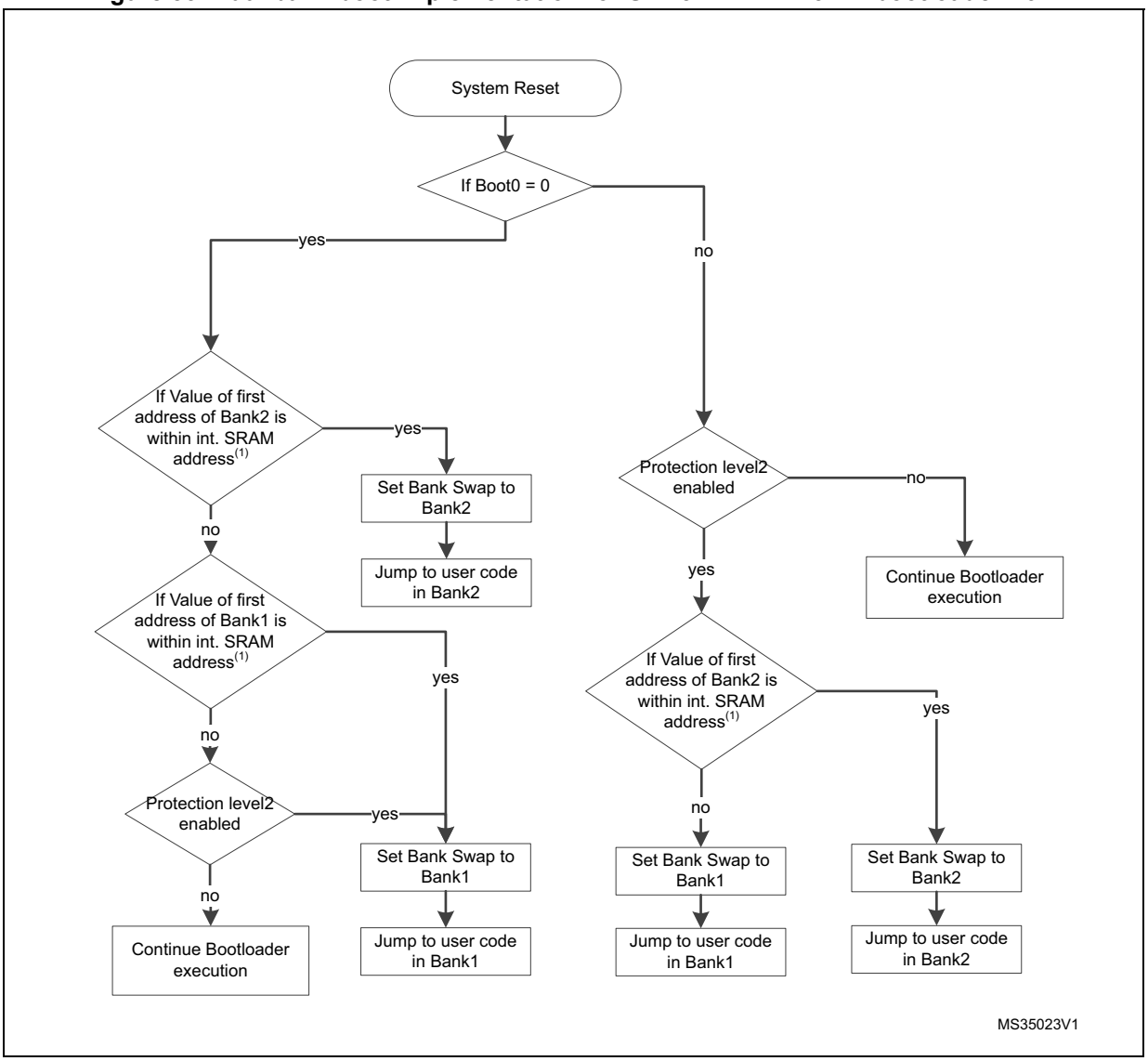
The system clock is derived from the embedded internal high-speed RC for USARTx, I2Cx I2Cx, and SPIx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

41.2.2 Bootloader selection

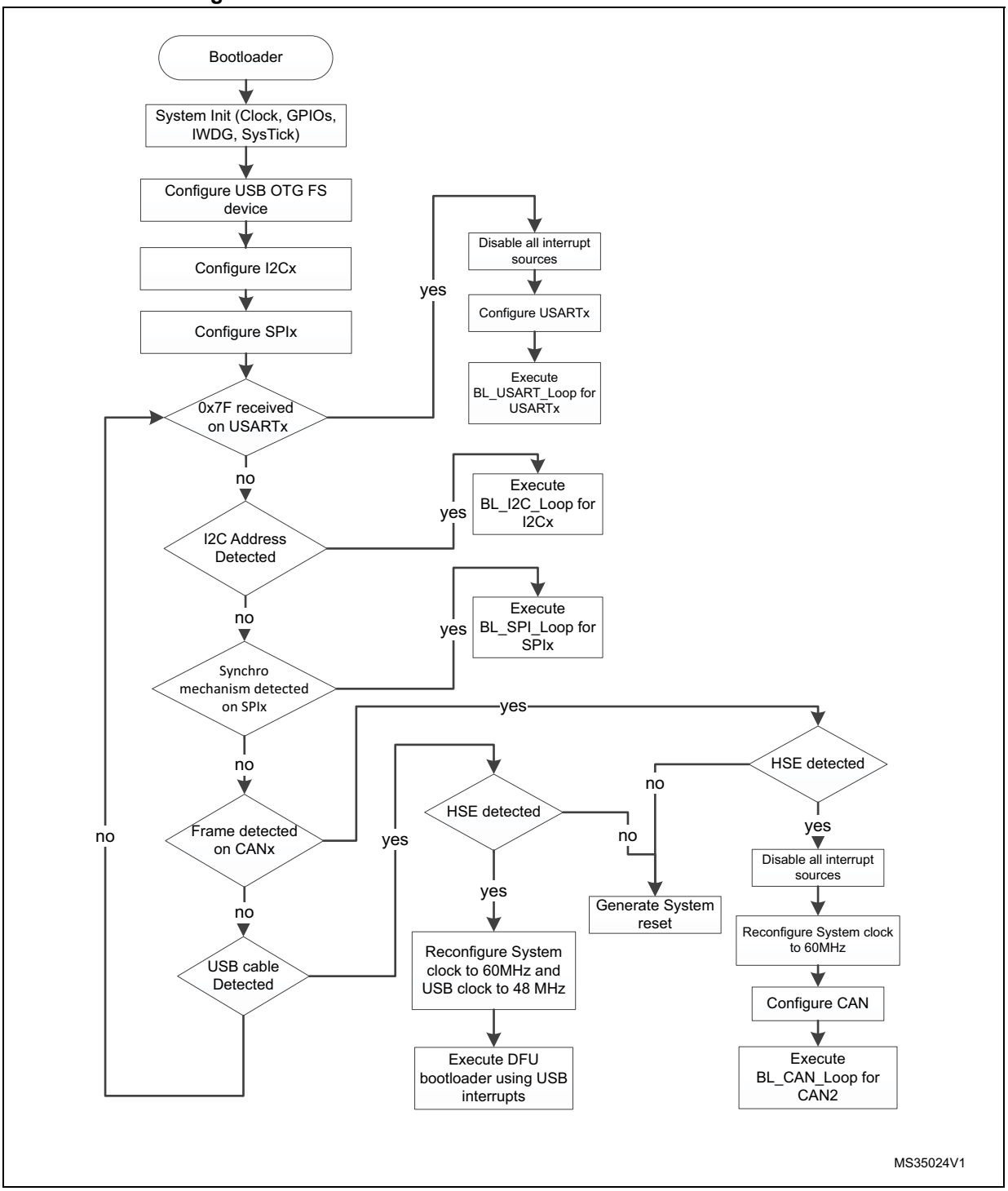
Figure 53 and *Figure 54* show the bootloader selection mechanism.

Figure 53. Dual bank boot implementation for STM32F42xxx/43xxx bootloader V9.x



1. CCM RAM is not considered valid as stack pointer address for the dual bank boot mechanism.

Figure 54. Bootloader V9.x selection for STM32F42xxx/43xxx



41.2.3 Bootloader version

Table 93 lists the STM32F42xxx/43xxx devices bootloader V9.x versions.

Table 93. STM32F42xxx/43xxx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	This bootloader is an updated version of bootloader v7.0. This new version of bootloader supports I2C2, I2C3, SPI1, SPI2, and SPI4 interfaces. The RAM used by this bootloader is increased from 8 Kb to 12 Kb. The ID of this bootloader is 0x90 The connection time is increased.	For the USB DFU interface, in Dual Bank mode, the Erase operation is not functional for the second bank. Return to Single Bank mode, erase desired sector(s) and then reactivate the Dual Bank mode. After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)
V9.1	This bootloader is an updated version of bootloader v9.0. This new version implements the new I2C No-stretch commands (I2C protocol v1.1) and the capability of disabling PcROP when RDP1 is enabled with ReadOutUnprotect command for all protocols(USB, USART, CAN, I2C and SPI). The ID of this bootloader is 0x91	For the CAN interface, the Write Unprotect command is not functional. Use Write Memory command and write directly to the option bytes in order to disable the write protection. For the USB DFU interface, in Dual Bank mode, the Erase operation is not functional for the second bank. Return to Single Bank mode, erase desired sector(s) and then reactivate the Dual Bank mode. After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)

42 STM32F446xx devices

42.1 Bootloader configuration

The STM32F446xx bootloader is activated by applying Pattern 1 (described in *Table 2*). The following table shows the hardware resources used by this bootloader.

Table 94.STM32F446xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART, I2C and SPI bootloader operation.
		HSE enabled	The HSE is used only when the CAN or the DFU (USB FS device) interfaces are selected. In this case the system clock configured to 60 MHz with HSE as clock source. The HSE frequency must be multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFUs. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The voltage range is [1.71 V, 3.6 V]. In this range: - Flash wait states: 3. - System Clock 60 MHz. - Prefetch disabled. - Flash write operation by byte (refer to section bootloader memory management for more information).

Table 94.STM32F446xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART3 (on PB10/PB11)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 (on PC10/PC11)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
CAN2	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. **Note:** CAN1 is clocked during CAN2 bootloader execution because in CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b0111100x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.

Table 94.STM32F446xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b0111100x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b0111100x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PC7 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.

Table 94.STM32F446xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI4	SPI4	Enabled	The SPI4 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode
	SPI4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-down mode
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-down mode.
DFU	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
CAN2 and DFUs	TIM17	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determinated, the system clock is configured to 60 MHz using PLL and HSE.

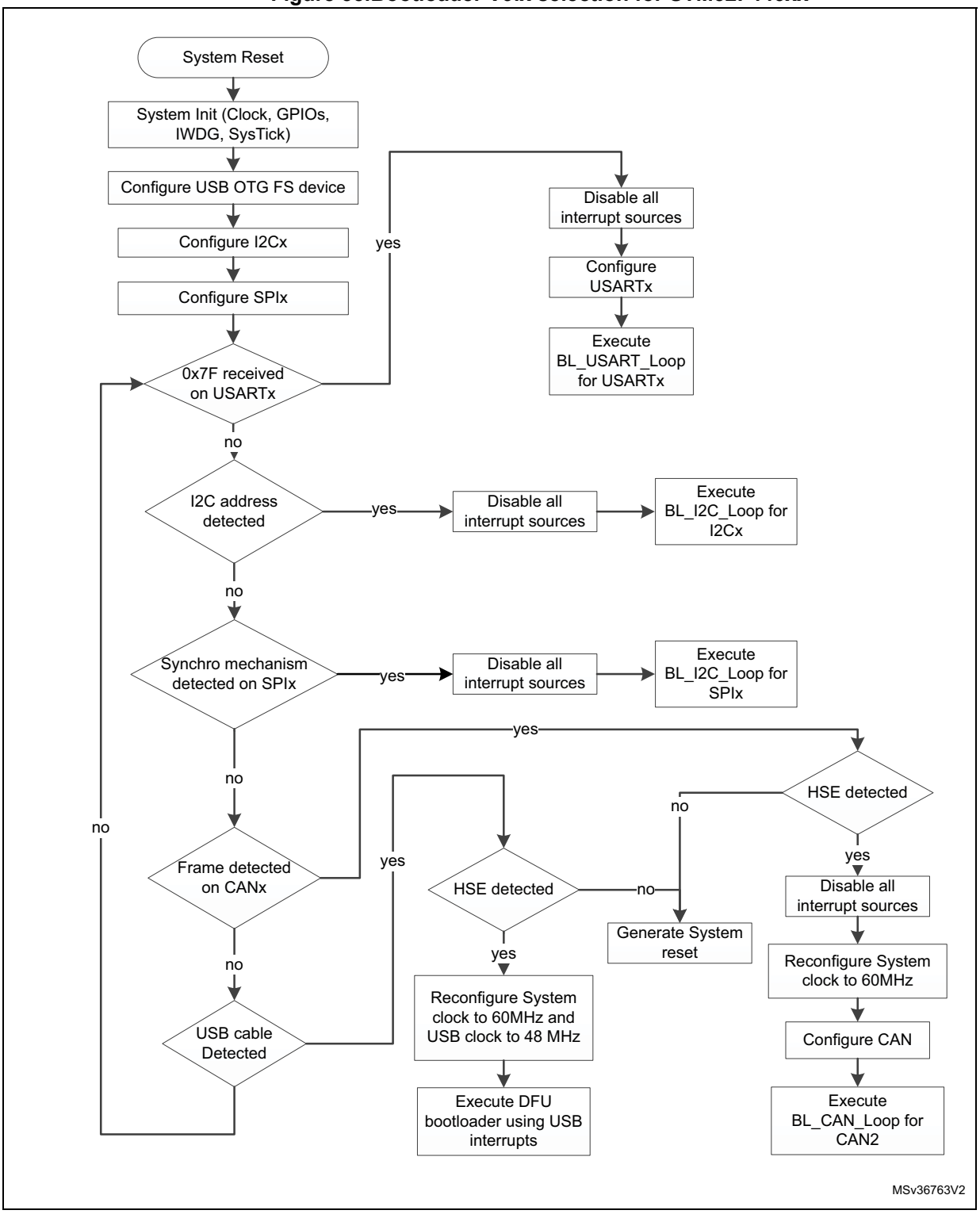
The system clock is derived from the embedded internal high-speed RC for USARTx and I2Cx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

42.2 Bootloader selection

Figure 55 shows the bootloader selection mechanism.

Figure 55.Bootloader V9.x selection for STM32F446xx



42.3 Bootloader version

The following table lists the STM32F446xx devices bootloader V9.x versions:

Table 95. STM32F446xx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	Initial bootloader version	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)

43 STM32F469xx/479xx devices

43.1 Bootloader configuration

The STM32F469xx/479xx bootloader is activated by applying Pattern 5 (described in *Table 2*). *Table 96* shows the hardware resources used by this bootloader.

Table 96. STM32F469xx/479xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USART or SPI or I2C interfaces are selected (once CAN or DFU is selected, the clock source is derived from external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the CAN or the DFU (USB FS device) interfaces are selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFUs. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62 V, 2.1 V]. In this range internal flash write operations are allowed only in byte format (half-word, word, and double-word operations are not allowed). The voltage range can be configured in run time using bootloader commands.

Table 96. STM32F469xx/479xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART3 (on PB10/PB11)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 (on PC10/PC11)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
CAN2	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. **Note:** CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB05 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000100x (x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.

Table 96. STM32F469xx/479xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1000100x (x = 0 for write and x = 1 for read).
	I2C2_SCL pin	Input/output	PF0 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF1 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1000100x (x = 0 for write and x = 1 for read).
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PI3 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PI2 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PI1pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PI0 pin: slave chip select pin used in push-pull, pull-down mode.

Table 96. STM32F469xx/479xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI4	SPI4	Enabled	The SPI4 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode
	SP4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-down mode
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-down mode.
DFU	USB	Enabled	USB OTG FS configured in forced device mode. USB_OTG_FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11 pin: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.

The system clock is derived from the embedded internal high-speed RC for USARTx and I2Cx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 48 MHz) is required for CAN and DFUs execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

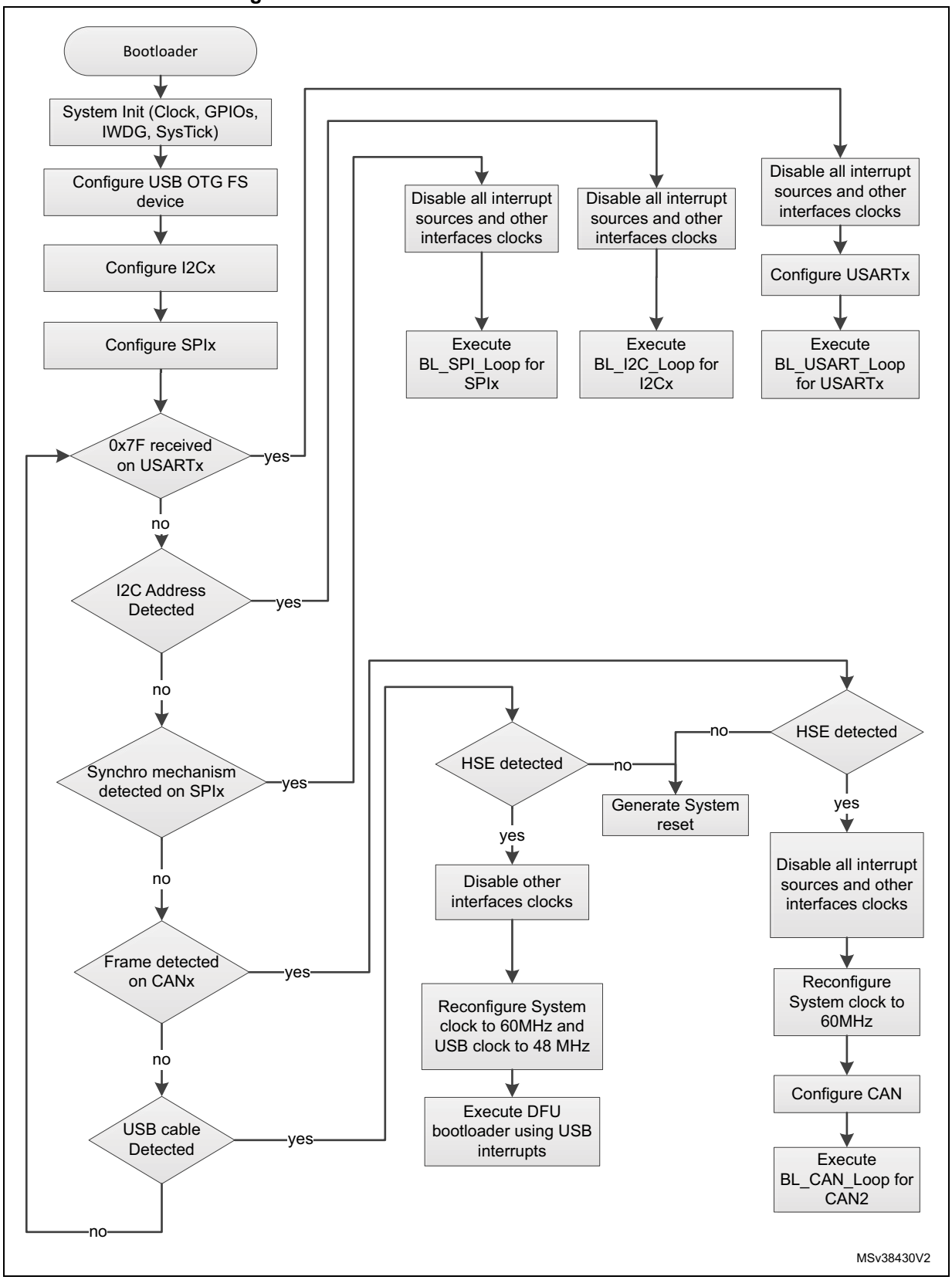
43.2 Bootloader selection

Figure 56 and *Figure 57* show the bootloader selection mechanism.

Figure 56. Dual bank boot implementation for STM32F469xx/479xx Bootloader V9.x



Figure 57.Bootloader V9.x selection for STM32F469xx/479xx



43.3 Bootloader version

Table 97 lists the STM32F469xx/479xx devices V9.x bootloader versions:

Table 97. STM32F469xx/479xx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	Initial bootloader version	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup).

44 STM32F72xxx/73xxx devices

44.1 Bootloader configuration

The STM32F72xxx/73xxx bootloader is activated by applying Pattern 8 (described in *Table 2*). *Table 98* shows the hardware resources used by this bootloader.

Table 98. STM32F72xxx/73xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART and I2C bootloader operation.
		HSE enabled	The HSE is used only when the CAN or the DFU (USB FS device) interfaces are selected. In this case the system clock configured to 60 MHz with HSE as clock source. The HSE frequency must be a multiple of 1 MHz. ranging from 4 to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFUs. Any failure (or removal) of the external clock generates system reset.
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	59 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The voltage range is [1.8V, 3.6V] In this range: - Flash wait states: 3. - System clock frequency 60 MHz. - ART Accelerator enabled. - Flash write operation by byte (refer to bootloader memory management section for more information).

Table 98. STM32F72xxx/73xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART3 (on PB11/PB10)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 (on PC11/PC10)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
CAN1	CAN1	Enabled	Once initialized the CAN1 configuration is: Baudrate 125 kbps, 11-bit identifier.
	CAN1_RX pin	Input	PD0 pin: CAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN1_TX pin	Output	PD1 pin: CAN1 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1001001x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.

Table 98. STM32F72xxx/73xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1001101x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1001001x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PI3 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PI2 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PI1 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PI0 pin: slave chip select pin used in push-pull, pull-down mode.

Table 98. STM32F72xxx/73xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI4	SPI4	Enabled	The SPI4 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode
	SP4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-down mode
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-down mode.
DFU	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11 pin: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.
CAN1 and DFUs	TIM11	Enabled	This timer is used to determine the value of the HSE. Once HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

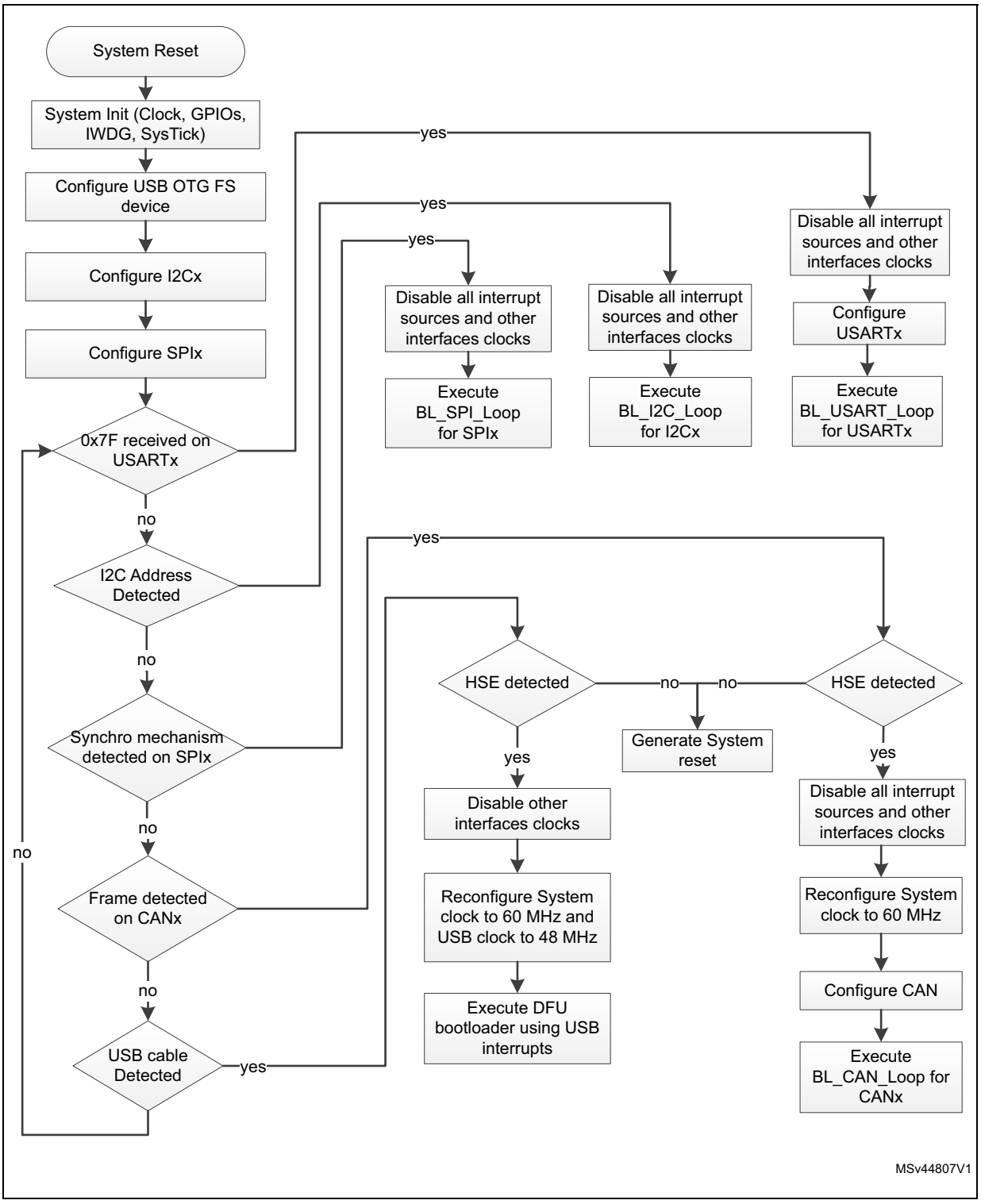
The system clock is derived from the embedded internal high-speed RC for USARTx and I2Cx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

44.2 Bootloader selection

Figure 58 shows the bootloader selection mechanism.

Figure 58. Bootloader V9.x selection for STM32F72xxx/73xxx



44.3 Bootloader version

Table 99 lists the STM32F72xxx/73xxx devices bootloader V9.x versions.

Table 99. STM32F72xxx/73xxx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	Initial bootloader version	At high UART baudrates (115200 bps) connection may fail due to software jitter leading to wrong baudrate calculation. In that case bootloader may respond with a baudrate up to ± 5% different from host baudrate. Workaround: use baudrates lower than 57600 bps if host tolerance to baudrate error is lower than ± 5%

45 STM32F74xxx/75xxx devices

Two bootloader versions are available:

- V7.x supporting USART1, USART3, CAN2, I2C1, I2C2, I2C3, and DFU (USB FS device). This version is embedded in STM32F74xxx/75xxx rev. A devices.
- V9.x supporting USART1, USART3, CAN2, I2C1, I2C2, I2C3, SPI1, SPI2, SPI4, and DFU (USB FS device). This version is embedded in STM32F74xxx/75xxx rev. Z and rev. 1 devices.

Note: When readout protection Level2 is activated, STM32F74xxx/75xxx devices can boot also on system memory and all commands are not accessible except Get, GetID, and GetVersion.

45.1 Bootloader V7.x

45.1.1 Bootloader configuration

The STM32F74xxx/75xxx bootloader is activated by applying Pattern 8 (described in *Table 2*). *Table 100* shows the hardware resources used by this bootloader.

Table 100. STM32F74xxx/75xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART and I2C bootloader operation.
		HSE enabled	The HSE is used only when the CAN or the DFU (USB FS device) interfaces are selected. In this case the system clock configured to 60 MHz with HSE as clock source. The HSE frequency must be multiple of 1 MHz and ranging from 4 to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFUs. Any failure (or removal) of the external clock generates system reset.
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	60 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The voltage range is [1.8V, 3.6V]. In this range: - Flash wait states: 3. - System clock frequency 60 MHz. - ART Accelerator enabled. - Flash write operation by byte (refer to bootloader memory management section for more information).

Table 100. STM32F74xxx/75xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART3 (on PB10/PB11)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 (on PC10/PC11)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
CAN2	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. **Note:** CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address, Target mode – Analog filter ON – Target 7-bit address: 0b1000101x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address, Target mode – Analog filter ON – Target 7-bit address: 0b1000101x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.

Table 100. STM32F74xxx/75xxx configuration in system memory boot mode (continued)

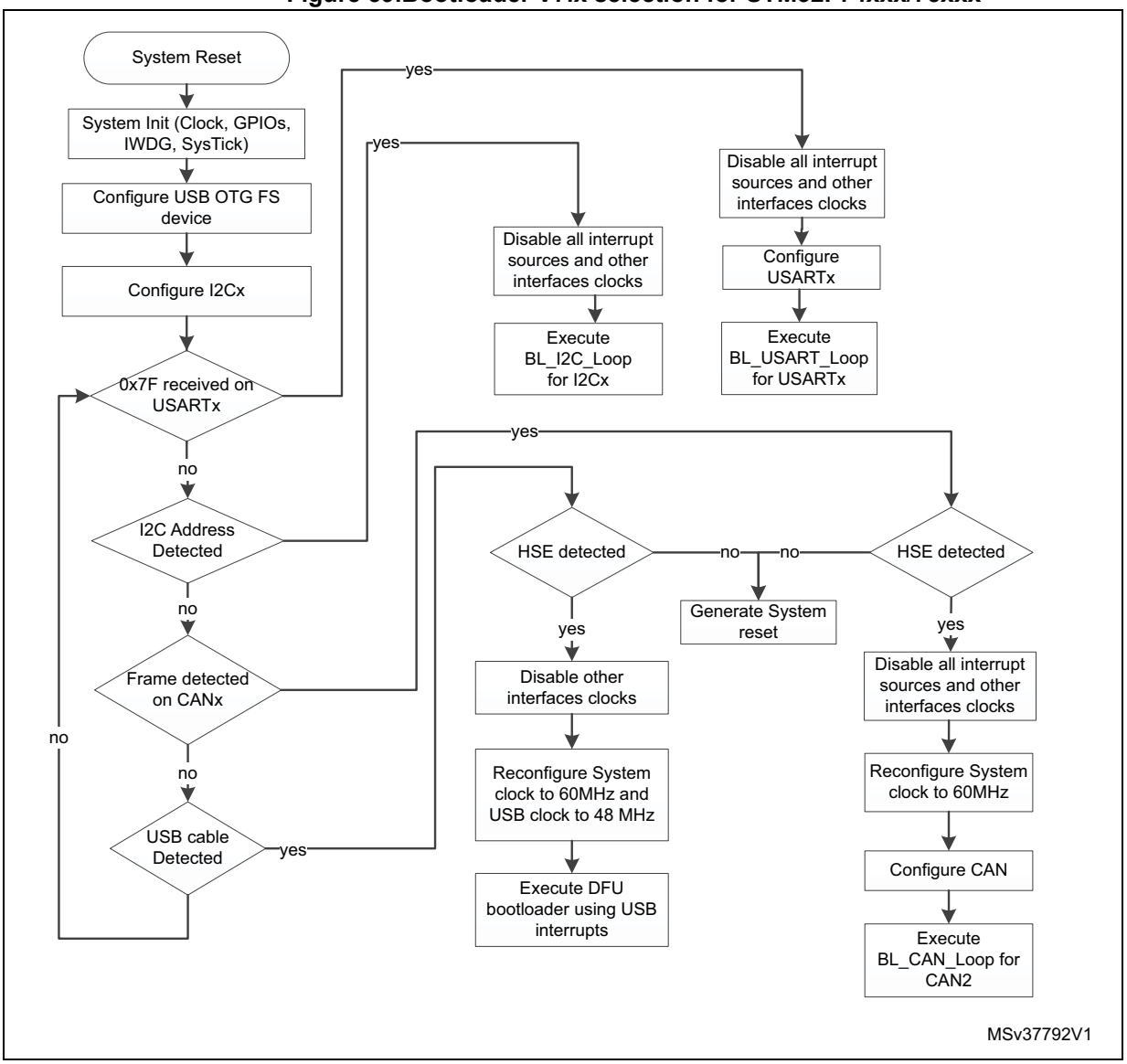
Bootloader	Feature/Peripheral	State	Comment
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode, Analog filter ON – Target 7-bit address: 0b1000101x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.
DFU	USB	Enabled	USB OTG FS configured in forced device mode.
	USB_DM pin	Input/output	PA11 pin: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.
CAN2 and DFUs	TIM11	Enabled	This timer is used to determine the value of the HSE. Once HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

The system clock is derived from the embedded internal high-speed RC for USARTx and I2Cx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

45.1.2 Bootloader selection

Figure 59.Bootloader V7.x selection for STM32F74xxx/75xxx



45.1.3 Bootloader version

Table 101. STM32F74xxx/75xxx bootloader V7.x versions

Version number	Description	Known limitations
V7.0	Initial bootloader version	At high UART baudrates (115200 bps) connection may fail due to software jitter leading to wrong baudrate calculation. In that case bootloader may respond with a baudrate up to ± 5% different from host baudrate. Workaround: use baudrates lower than 57600 bps if host tolerance to baudrate error is lower than ± 5%

45.2 Bootloader V9.x

45.2.1 Bootloader configuration

The STM32F74xxx/75xxx bootloader is activated by applying Pattern 8 (described in *Table 2*). The following table shows the hardware resources used by this bootloader.

Table 102. STM32F74xxx/75xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART, I2C and SPI bootloader operation.
		HSE enabled	The HSE is used only when the CAN or the DFU (USB FS device) interfaces are selected. In this case the system clock configured to 60 MHz with HSE as clock source. The HSE frequency must be multiple of 1 MHz and ranging from 4 to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock generates system reset.
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	60 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The voltage range is 1.8 V, 3.6V. In this range: - Flash wait states: 3. - System clock frequency 60 MHz. - ART Accelerator enabled. - Flash write operation by byte (refer to bootloader memory management section for more information).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.

Table 102. STM32F74xxx/75xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3 (on PB10/PB11)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 (on PC10/PC11)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
CAN2	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. **Note:** CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000101x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000101x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.

Table 102. STM32F74xxx/75xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000101x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PI3 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PI2 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PI1 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PI0 pin: slave chip select pin used in push-pull, pull-down mode.

Table 102. STM32F74xxx/75xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI4	SPI4	Enabled	The SPI4 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode
	SP4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-down mode
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-down mode.
DFU	USB	Enabled	USB OTG FS configured in forced device mode.
	USB_DM pin	Input/output	PA11 pin: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.
CAN2 and DFUs	TIM11	Enabled	This timer is used to determine the value of the HSE. Once HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

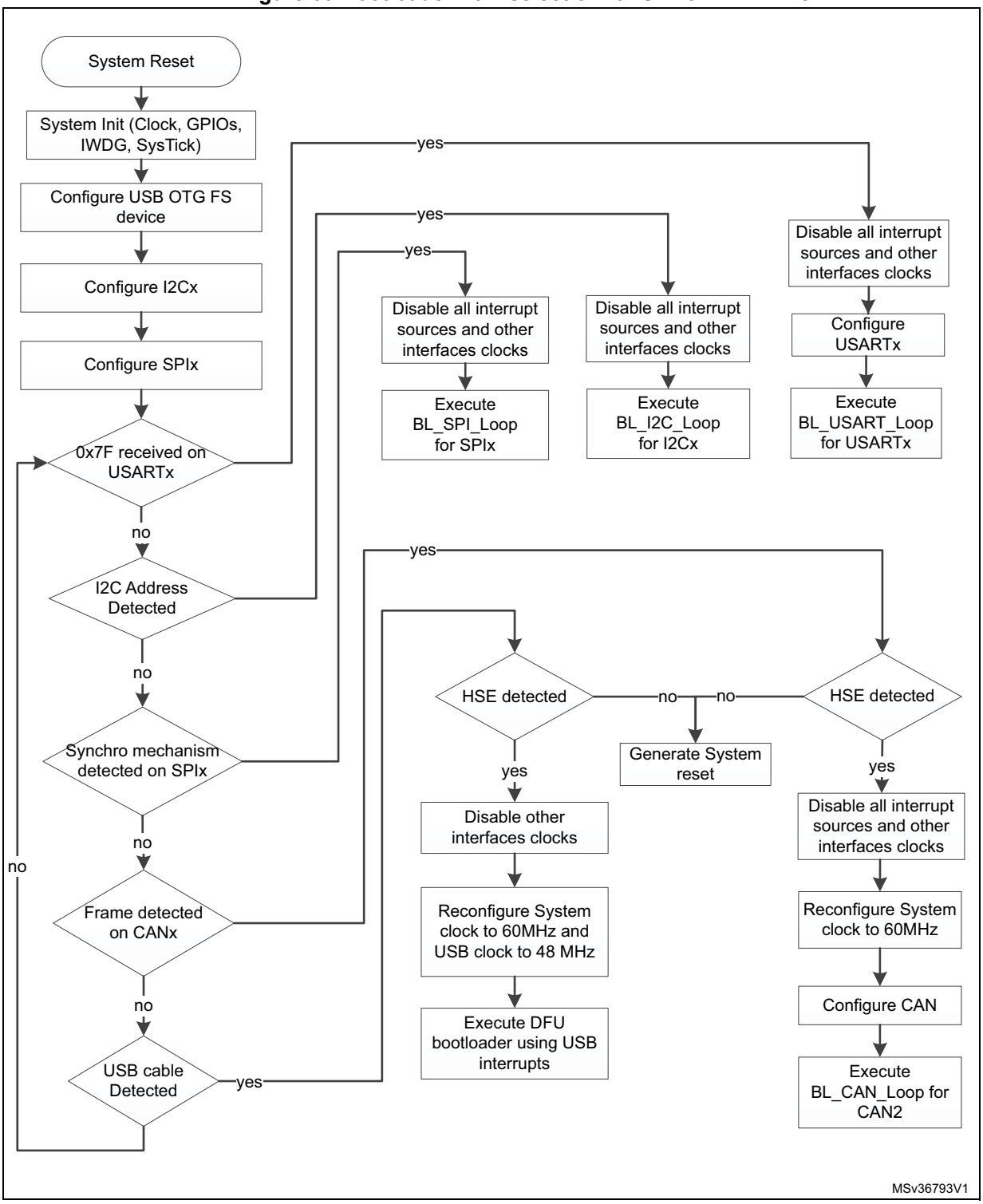
The system clock is derived from the embedded internal high-speed RC for USARTx, I2Cx I2Cx, and SPIx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

45.2.2 Bootloader selection

Figure 60 shows the bootloader selection mechanism.

Figure 60.Bootloader V9.x selection for STM32F74xxx/75xxx



45.2.3 Bootloader version

The following table lists the STM32F74xxx/75xxx bootloader V9.x versions:

Table 103. STM32F74xxx/75xxx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	Initial bootloader version	At high UART baudrates (115200 bps) connection may fail due to software jitter leading to wrong baudrate calculation. In that case bootloader may respond with a baudrate up to ± 5% different from host baudrate. Workaround: use baudrates lower than 57600 bps if host tolerance to baudrate error is lower than ± 5%

46 STM32F76xxx/77xxx devices

46.1 Bootloader configuration

The STM32F76xxx/77xxx bootloader is activated by applying Pattern 9 (described in *Table 2*). The following table shows the hardware resources used by this bootloader.

Table 104. STM32F76xxx/77xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART and I2C bootloader operation.
		HSE enabled	The HSE is used only when the CAN or the DFU (USB FS device) interfaces are selected. In this case the system clock configured to 60 MHz with HSE as clock source. The HSE frequency must be a multiple of 1 MHz, ranging from 4 to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFUs. Any failure (or removal) of the external clock generates system reset.
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	59 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The voltage range is [1.8 V, 3.6 V] In this range: - Flash wait states: 3. - System clock frequency 60 MHz. - ART Accelerator enabled. - Flash write operation by byte (refer to bootloader memory management section for more information).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART3 (on PB11/PB10)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.

Table 104. STM32F76xxx/77xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3 (on PC11/PC10)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
CAN2	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. **Note:** CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1001001x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1001001x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1001001x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.

Table 104. STM32F76xxx/77xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PI3 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PI2 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PI1 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PI0 pin: slave chip select pin used in push-pull, pull-down mode.
SPI4	SPI4	Enabled	The SPI4 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode
	SP4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-down mode
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-down mode.

Table 104. STM32F76xxx/77xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11 pin: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.
CAN2 and DFUs	TIM11	Enabled	This timer is used to determine the value of the HSE. Once HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

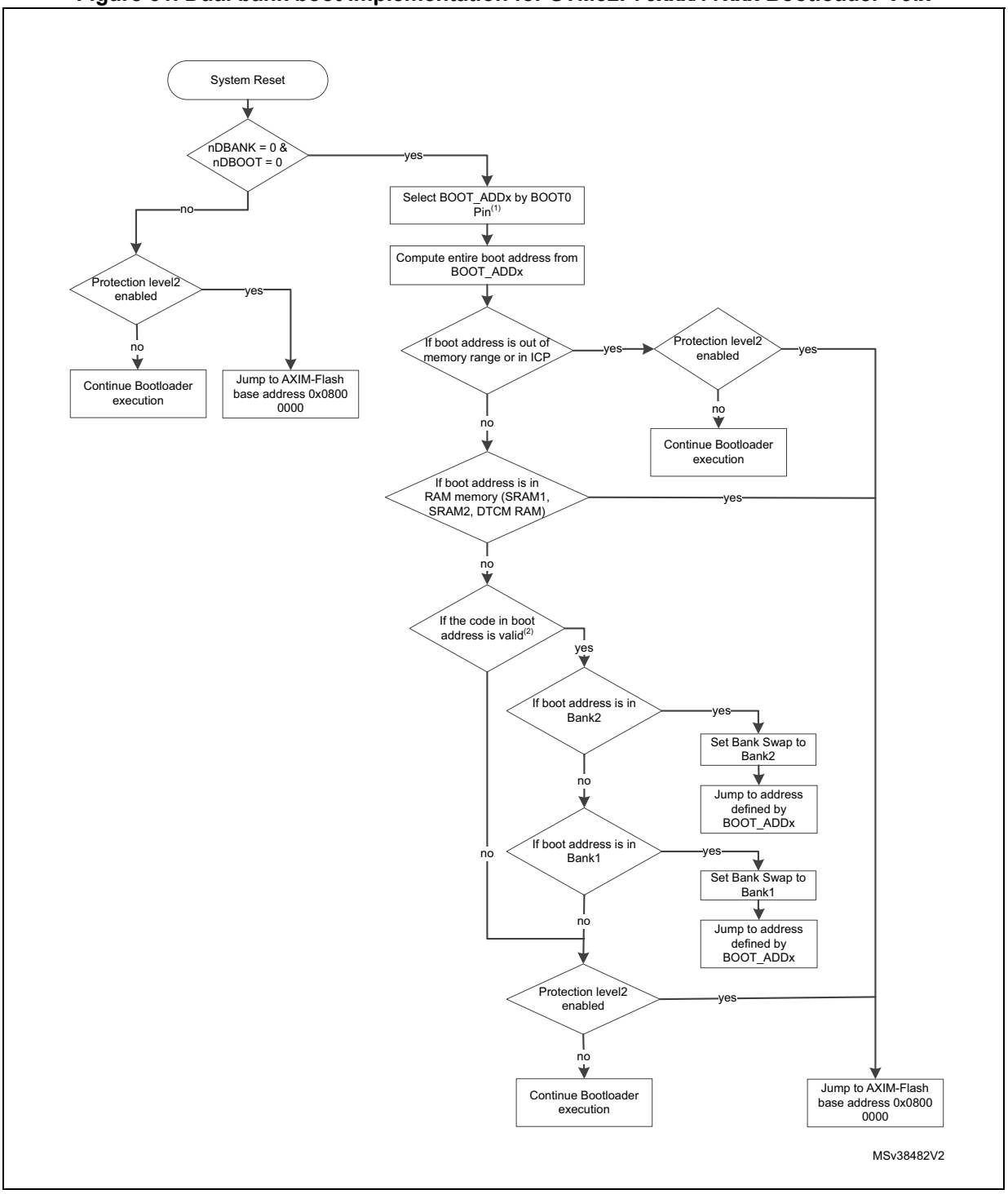
The system clock is derived from the embedded internal high-speed RC for USARTx and I2Cx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

46.2 Bootloader selection

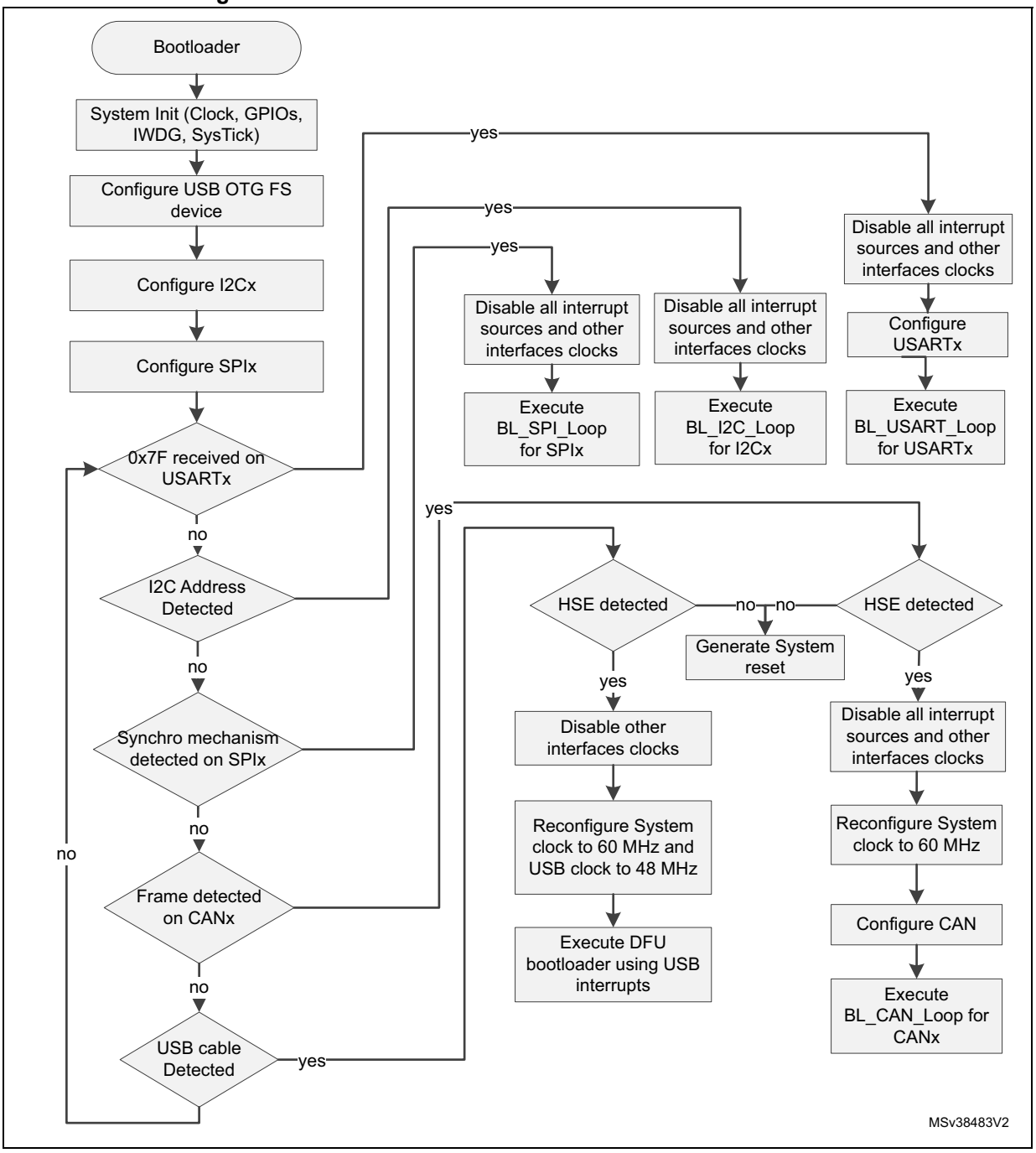
Figure 61 and *Figure 62* show the bootloader selection mechanism.

Figure 61. Dual bank boot implementation for STM32F76xxx/77xxx Bootloader V9.x



1. Only BOOT_ADD0 value is considered whatever the BOOT0 pin state, as described in *Table 105*.
2. ITCM RAM is not considered valid as stack pointer address for the dual bank boot mechanism.

Figure 62. Bootloader V9.x selection for STM32F76xxx/77xxx



46.3 Bootloader version

The following table lists the STM32F76xxx/77xxx devices bootloader V9.x versions.

Table 105. STM32F76xxx/77xxx bootloader V9.x versions

Version number	Description	Known limitations
V9.3	Initial bootloader version	When the flash memory is configured to the dual bank boot mode (nDBANK=nDBOOT=0), whatever the BOOT0 Pin state only BOOT_ADD0 value is considered (when BOOT0 Pin=1, BOOT_ADD0 value is considered not the BOOT_ADD1). Workaround: to manage dual bank boot with BOOT_ADD0 only, refer to AN4826 "*STM32F7 series flash memory dual bank mode*" At high UART baudrates (115200 bps) connection may fail due to software jitter leading to wrong baudrate calculation. In that case bootloader may respond with a baudrate up to ± 5% different from host baudrate. Workaround: use baudrates lower than 57600 bps if host tolerance to baudrate error is lower than ± 5%. Bank2 sector erase issue when using USB interface. Erasing a sector from bank2 with index (i) leads to erase sector (i+4)

47 STM32G03xxx/STM32G04xxx devices

47.1 Bootloader configuration

The STM32G03xxx/G04xxx bootloader is activated by applying Pattern 11 (described in *Table 2*). The following table shows the hardware resources used by this bootloader. Note that STM32G030x do not have BOOT_LOCK(bit), so consider that when using Pattern 11.

Table 106. STM32G03xxx/G04xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz (using PLL clocked by HSI).
	RAM	-	4 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FFF0000
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF1D00
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloader	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1010110x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.

Table 106. STM32G03xxx/G04xxx configuration in system memory boot mode (continued)

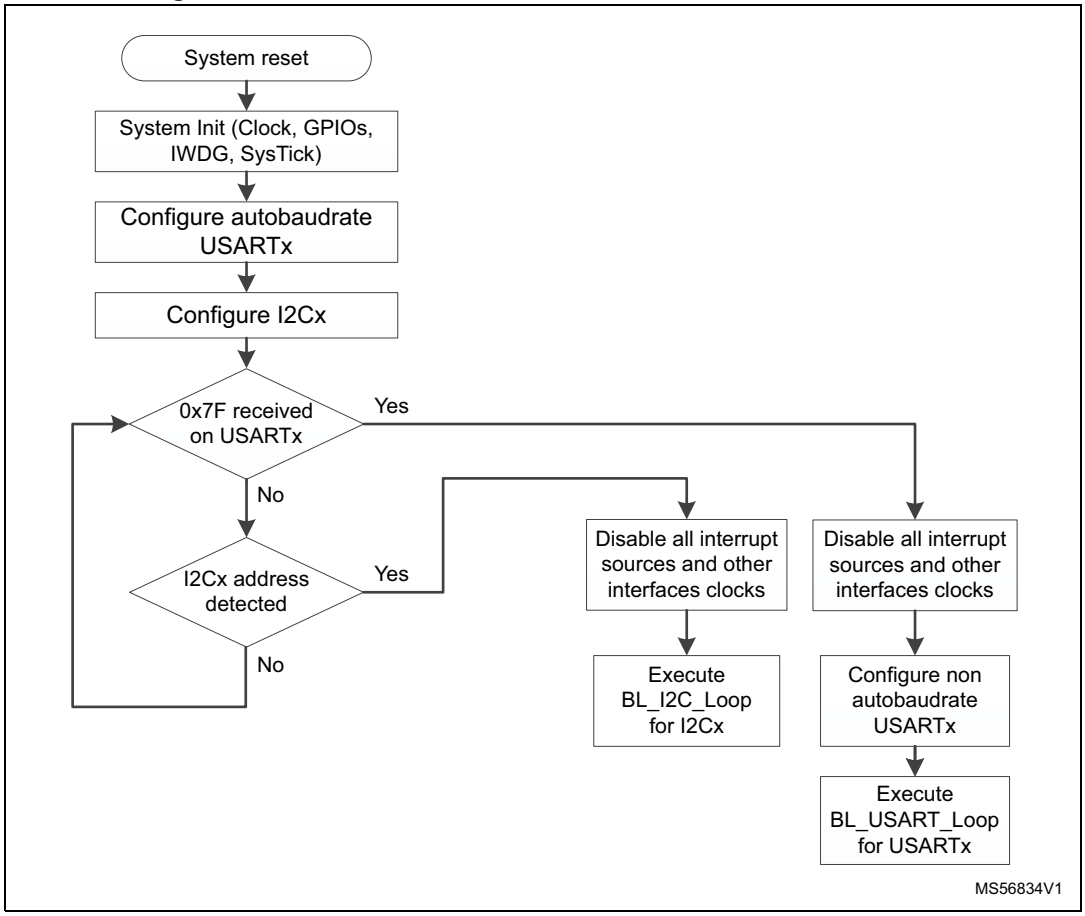
Bootloader	Feature/Peripheral	State	Comment
I2C2	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1010110x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.

Note: On SO8, WLCSP18, TSSOP20, and UFQFN28 packages USART1 PA9/PA10 IOs are remapped on PA11/PA12.

47.2 Bootloader selection

Figure 63 shows the bootloader selection mechanism.

Figure 63. Bootloader V5.x selection for STM32G03xxx/G04xxx



47.3 Bootloader version

Table 107 lists the STM32G03xxx/G04xxx devices bootloader versions.

Table 107. STM32G03xxx/04xxx bootloader versions

Version number	Description	Known limitations
V5.1	Initial bootloader version	– Supports only 48- and 32-pin packages – Issue is seen for both packages, if PA3 stays to low level, system is stuck in the USART2 detection sequence and no other interface is detected.
V5.2	Add support to small packages 8/20 and 28 pins	Issue is seen for all packages (except SO8, no PA3 pin), if PA3 stays to low level, system is stuck in the USART2 detection sequence and no other interface is detected.
V5.3	Fix V5.2 limitations	None
V5.4	– Improve USART2 detection method – Expose ENGI memory area – Enable interrupts by resetting PRIMASK	None

48 STM32G07xxx/08xxx device bootloader

48.1 Bootloader configuration

The STM32G07xxx/G08xxx bootloader is activated by applying Pattern 11 (described in *Table 2*). *Table 108* shows the hardware resources used by this bootloader.

When using Pattern 11, consider that STM32G070xx devices do not have BOOT_LOCK(bit).

Table 108. STM32G07xxx/8xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz (using PLL clocked by HSI).
	RAM	-	12 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF6800
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 108. STM32G07xxx/8xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1010001x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1010001x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode.(1)
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. **Note**: This IO can be tied to GND if the SPI master does not use it.

Table 108. STM32G07xxx/8xxx configuration in system memory boot mode (continued)

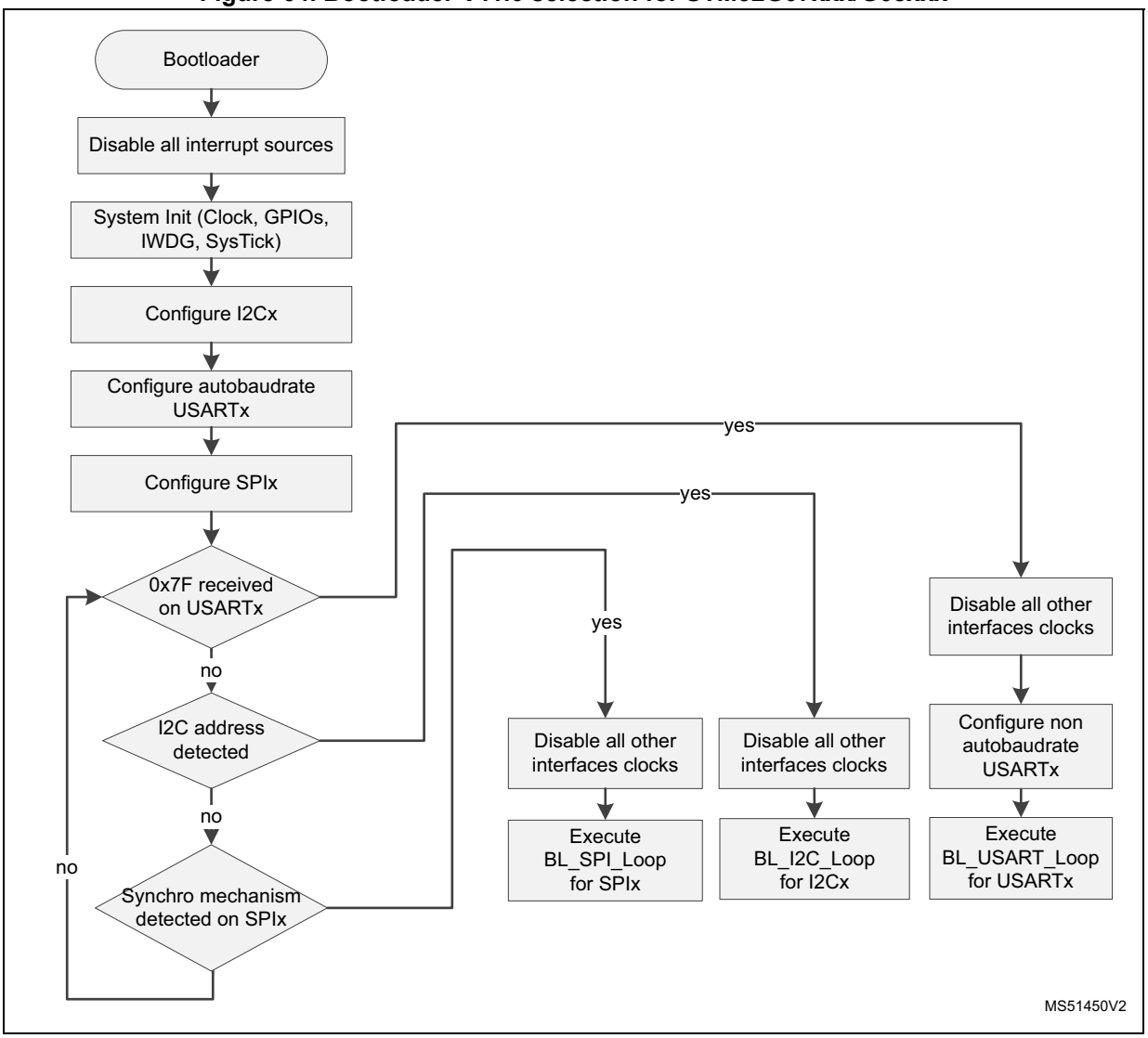
Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode.
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode.(1)
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down. **Note**: This IO can be tied to GND if the SPI master does not use it.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

48.2 Bootloader selection

Figure 64 shows the bootloader selection mechanism.

Figure 64. Bootloader V11.0 selection for STM32G07xxx/G08xxx



48.3 Bootloader version

Table 109 lists the STM32G07xxx/8xxx devices bootloader versions.

Table 109. STM32G07xxx/08xxx bootloader versions

Version number	Description	Known limitations
V11.0	Initial bootloader version	Not supporting packages smaller than LQFP64
V11.1	Supporting all packages	None

Table 109. STM32G07xxx/08xxx bootloader versions (continued)

Version number	Description	Known limitations
V11.2	Added securable memory area feature	– Option byte launch missing when using USART protocol – RCC register RCC_ICSCR is not set to its default value when Go command is used. HSITRIM value is set to a value different from default. – RCC registers are not set to their default value when Go command is used (HSITRIM is not correctly reset). – Enabling SRAM parity check option byte causes bootloader crash if the SRAM is not initialized before enabling this feature.
V11.3	Fixed V11.2 limitations and added SW enhancements	– Empty check flag cleared by bootloader at boot – Compatibility break on boot sequence versus older versions(1) – Erase sectors not working as expected Root cause: Wrong FLITF BUSY bit check leading to not waiting for the erase operation termination. Workaround: Erase only by one sector and wait 40 ms for the erase termination before running the next operation. – I2C stretches the line on the connection causing issues with some HW hosts Root cause: USART3 detection method changed compared to the V11.2: a loop is added when a low edge is detected on the RX pin as the BL SW start baudrate calculations expecting it is the begining of 0x7F byte. When the RX pin PC11 is tied to GND (manually on 64-pin packages or by production on low pin count packages), the USART3 detection loop is done on every Bootloader detection phase, causing a timeout wait when another peripheral is needed. Behavior: When connection to I2C is requested (host sends I2C address to the bootloader), the I2C HW detects the request ,but the BL SW is blocked on the USART3 SW loop, causing the I2C line stretching. Some HW hosts that do not support the stretching fail connecting with bootloader. Workaround: on 64-pin packages, do not put PC11 pin to GND. There is no workaround on low pin count packages, the only solution is to use a HW host supporting the clock stretching.
V11.4	Fixed V11.3 limitations	None

1. See *Section 48.3.1*.

48.3.1 Compatibility break on boot sequence

Some enhancements introduced in V11.3 break the compatibility with the boot sequence of versions V11.2 and V11.1.

The major change is the addition of initialization of hardware peripherals (for the exact list refer to *Section 48.1*) used by the bootloader to their default values (as defined in RM0444).

The main impact is seen in two cases:

1. When jumping to the bootloader from user flash, the first operation is to reset the peripherals to their default values.
2. Usage of the “Empty check” boot mode
   - Empty check flag is raised by HW on a POR or option byte change when the user flash is empty.
   - This detection leads to boot on the bootloader.
   - As per the new boot sequence, the bootloader clears this flag.
   - Using a reset while the user flash is not yet programmed leads to a wrong boot on an empty user flash.

   Avoid resets (except POR or option byte change) while the user flash is not programmed by the bootloader.

49 STM32G0B0xx device bootloader

49.1 Bootloader configuration

The STM32G0B0xx bootloader is activated by applying Pattern 11 (described in *Table 2*). The following table shows the hardware resources used by this bootloader. Note that STM32G0B0xx do not have BOOT_LOCK(bit), so consider that when using Pattern 11.

Table 110. STM32G0B0xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz (using PLL clocked by HSI). If an external clock (HSE) is not present, the system is kept clocked from the HSI
		HSE enabled	The external clock can be used for all bootloader interfaces and must have one of the following values [48, 32, 16, 12, 8] MHz. The PLL is used to generate 48 MHz for USB and system clock.
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	The bootloader firmware is shared on two banks: - 28 Kbytes, starting from address 0x1FFF0000 until 0x1FFF6FFF - Part of the 28 KB (0x1FFF8000 – 0x1FFFEFFF)
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to for the exit securable memory area is 0x1FFF6800
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 110. STM32G0B0xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1011101x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1011101x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode.(1)
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. **Note**: This IO can be tied to GND if the SPI master does not use it.

Table 110. STM32G0B0xx configuration in system memory boot mode (continued)

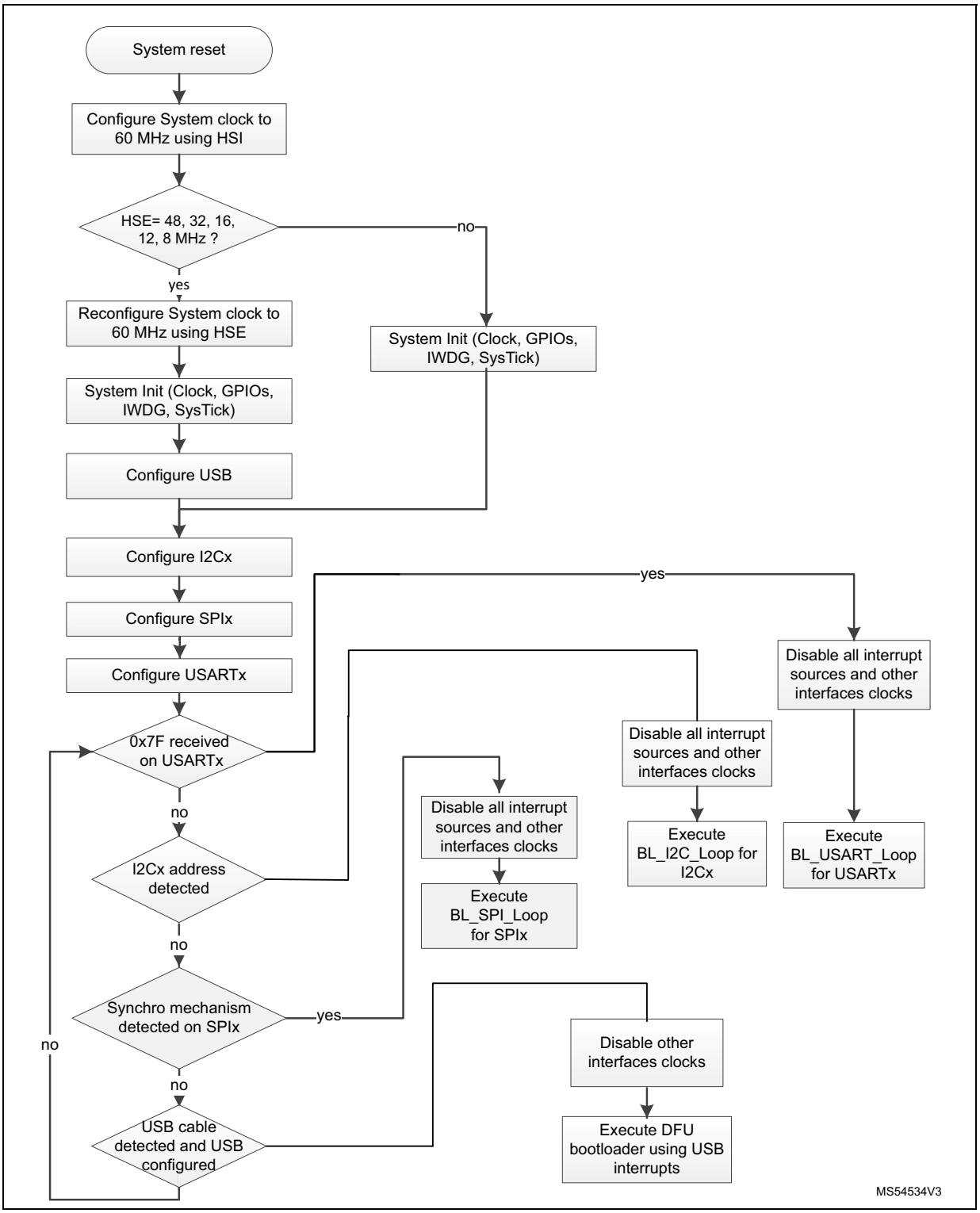
Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode.
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode.(1)
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down. **Note**: This IO can be tied to GND if the SPI master does not use it.
DFU(2)	USB	Enabled	USB FS configured in Forced Device mode. USB FS interrupt vector is enabled and used for USB DFU communications. **Note**: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.‘
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.
2. USB DFU is not available on LQFP32 package.

49.2 Bootloader selection

Figure 65 shows the bootloader selection mechanism.

Figure 65. Bootloader selection for STM32G0B0xx



49.3 Bootloader version

Table 111 lists the STM32G0B0xx devices bootloader versions.

Table 111. STM32G0B0xx bootloader versions

Version number	Description	Known limitations
V13.0	Initial bootloader version	Erase multiple sectors not working on Bank2 – Root cause: wrong BUSY bit check on Bank2 leads to generate FLITF error after one sector erase – Workaround: erase only by one sector when targeting Bank2 Empty check flag cleared by error on the bootloader startup phase – Root cause: on the startup phase the bootloader SW performs a system deinitialization, leading to write the default value on the FLASH_ACR register, which overrides the Empty check bit with 0 – Behavior: when Empty check boot mode is used and the flash memory is empty, the MCU boots on the bootloader but the flag is cleared by the SW. If a reset is triggered, the system tries to boot on the empty flash memory, and crashes. – **Caution**: Avoid using reset on this case. if the system crashes, an option byte change or POR is needed to reboot.

50 STM32G0B1xx/0C1xx device bootloader

50.1 Bootloader configuration

The STM32G0B1xx/0C1xx bootloader is activated by applying Pattern 11 (described in *Table 2*). The following table shows the hardware resources used by this bootloader.

Table 112. STM32G0B1xx/0C1xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz (using PLL clocked by HSI).
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz.
		-	20 MHz derived from the PLLQ is used for FDCAN
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	The bootloader firmware is shared on two banks: - 28 Kbytes, starting from address 0x1FFF0000 until 0x1FFF6FFF - Part of the 28 KB (0x1FFF8000 – 0x1FFFEFFF)
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF6800
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 112. STM32G0B1xx/0C1xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b1011101x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b1011101x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode.(1)
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. **Note**: This IO can be tied to GND if the SPI master does not use it.

Table 112. STM32G0B1xx/0C1xx configuration in system memory boot mode (continued)

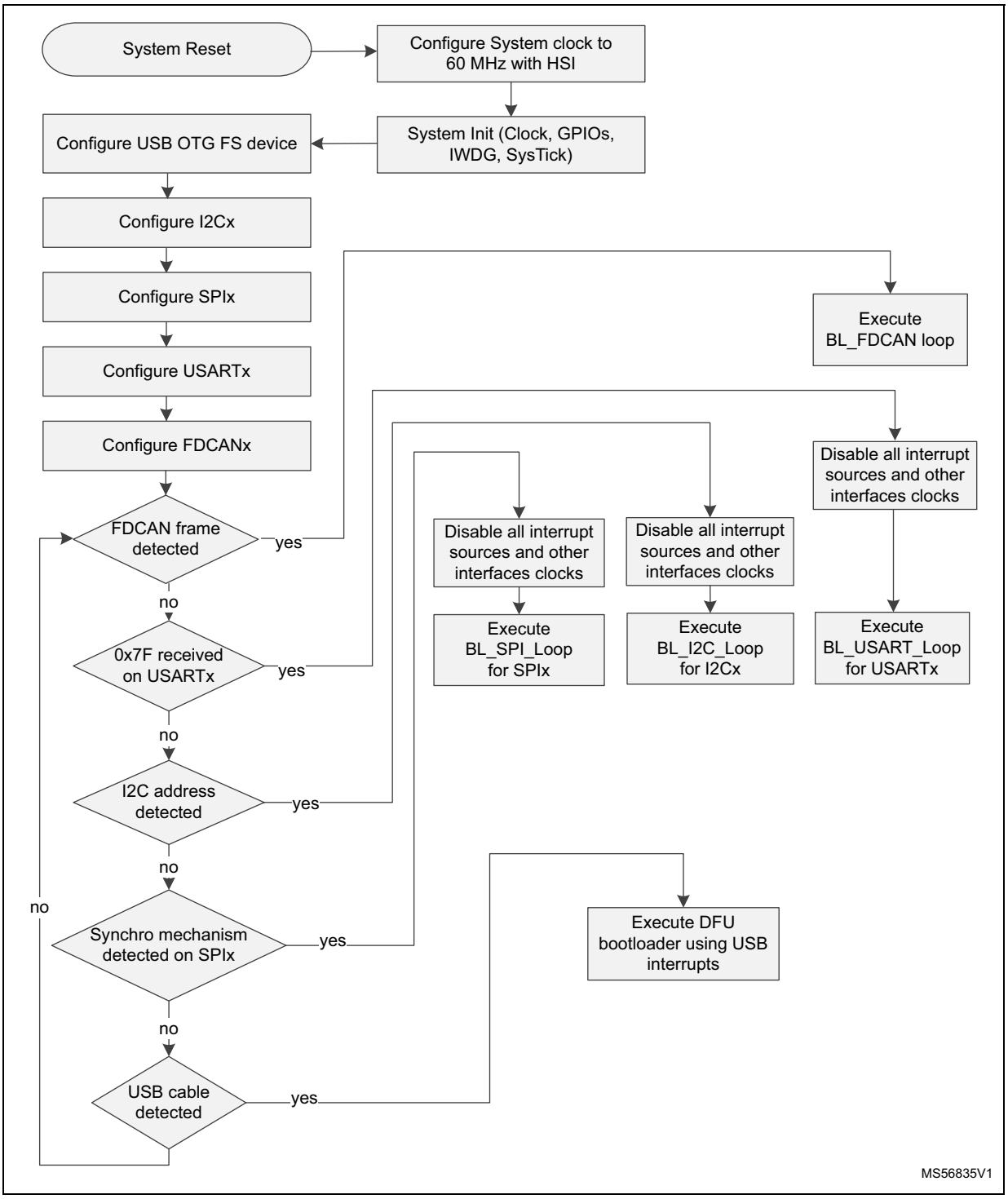
Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode.
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode.(1)
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down. **Note**: This IO can be tied to GND if the SPI master does not use it.
DFU	USB	Enabled	USB FS configured in Forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. **Note**: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.‘
	USB_DM pin	Input/output	PA11: USB DM line. Used in no pull mode.
	USB_DP pin		PA12: USB DP line. Used in no pull mode. No external pull-up resistor is required
FDCAN	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PD0 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	FDCAN1_Tx pin	Output	PD1 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-up mode.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

50.2 Bootloader selection

Figure 66 shows the bootloader selection mechanism.

Figure 66. Bootloader selection for STM32G0B1xx/0C1xx



50.3 Bootloader version

Table 113 lists the STM32G0B1xx/0C1xx devices bootloader versions.

Table 113. STM32G0B1xx/0C1xx bootloader versions

Version number	Description	Known limitations
V9.2	Initial bootloader version	When jumping to an application, the Go command disables the debug access port by writing a wrong value on the FLASH_ACR register (bit DBG_SWEN). Erase multiple sectors not working on Bank2 – Root cause: wrong BUSY bit check on Bank2 leads to generate FLITF error after one sector erase – Workaround: erase only by one sector when targeting Bank2 Empty check flag cleared by error on the bootloader startup phase – Root cause: on the startup phase the bootloader SW performs a system deinitialization, leading to write the default value on the FLASH_ACR register, which overrides the Empty check bit with 0 – Behavior: when Empty check boot mode is used and the flash memory is empty, the MCU boots on the bootloader but the flag is cleared by the SW. If a reset is triggered, the system tries to boot on the empty flash memory, and crashes. – **Caution**: Avoid using reset on this case. if the system crashes, an option byte change or POR is needed to reboot.

51 STM32G05xxx/061xx devices

51.1 Bootloader configuration

The STM32G05xxx/061xx bootloader is activated by applying Pattern 11 (described in *Table 2*). The following table shows the hardware resources used by this bootloader. Note that STM32G050x do not have BOOT_LOCK(bit), so consider that when using Pattern 11.

Table 114. STM32G05xxx/061xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz (using PLL clocked by HSI).
	RAM	-	4 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF6800
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode. PA12 pin: remapped to PA10, as it is not available on WLCSP20, TSOPP20, and UFQFPN28 packages.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode. PA11 pin: remapped to PA9, as it is not available on WLCSP20, TSOPP20, and UFQFPN28 packages.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloader	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USART2s.

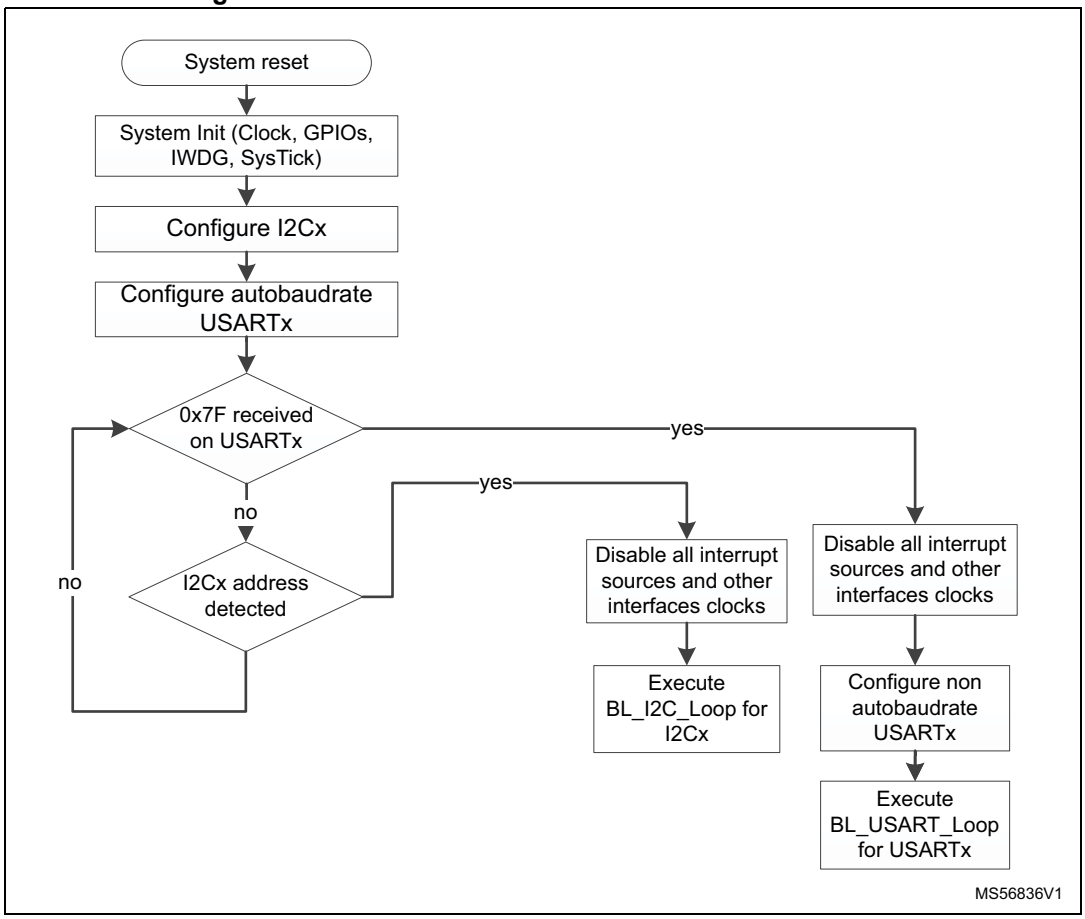
Table 114. STM32G05xxx/061xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1100010x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain pull-up mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1100010x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin		PB11 pin: data line is used in open-drain pull-up mode.

51.2 Bootloader selection

Figure 67 shows the bootloader selection mechanism.

Figure 67. Bootloader selection for STM32G05xxx/061xx



51.3 Bootloader version

Table 115 lists the STM32G05xxx/061xx devices bootloader versions.

Table 115. STM32G05xxx/061xx bootloader versions

Version number	Description	Known limitations
V5.0	Initial bootloader version	USART2 SW jitter issue on detection phase
V5.1	Fix V5.0 limitation	Non-stretch command not working as expected and stretching the line – Root cause: wrong BUSY check leads to not entering BUSY byte generation while waiting for the Non stretch command to complete – Behavior: when running a non-stretch commands instead of receiving a BUSY byte (0x76) while command is running; the BL is stretching the line and no data are sent to the host. This is noticed only on the non-stretch erase command, as it can take few ms, and can cause an issue if the host does not support the line stretching. – Workaround: patch in RAM to use the correct check

52 STM32G431xx/441xx devices

52.1 Bootloader configuration

The STM32G431xx/441xx bootloader is activated by applying Pattern 15 (described in *Table 2*). The following table shows the hardware resources used by this bootloader.

Table 116. STM32G431xx/441xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 72 MHz (using the PLL clocked by HSI)
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to the exit securable memory area @0x1FFF6800
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 116. STM32G431xx/441xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1010100x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PC4 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin		PA8 pin: data line is used in open-drain pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1010100x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC8 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin		PC9 pin: data line is used in open-drain pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode.(1)
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode.
	SPI1_NSS pin		PA4 pin: slave chip select pin used in push-pull, pull-down mode.

Table 116. STM32G431xx/441xx configuration in system memory boot mode (continued)

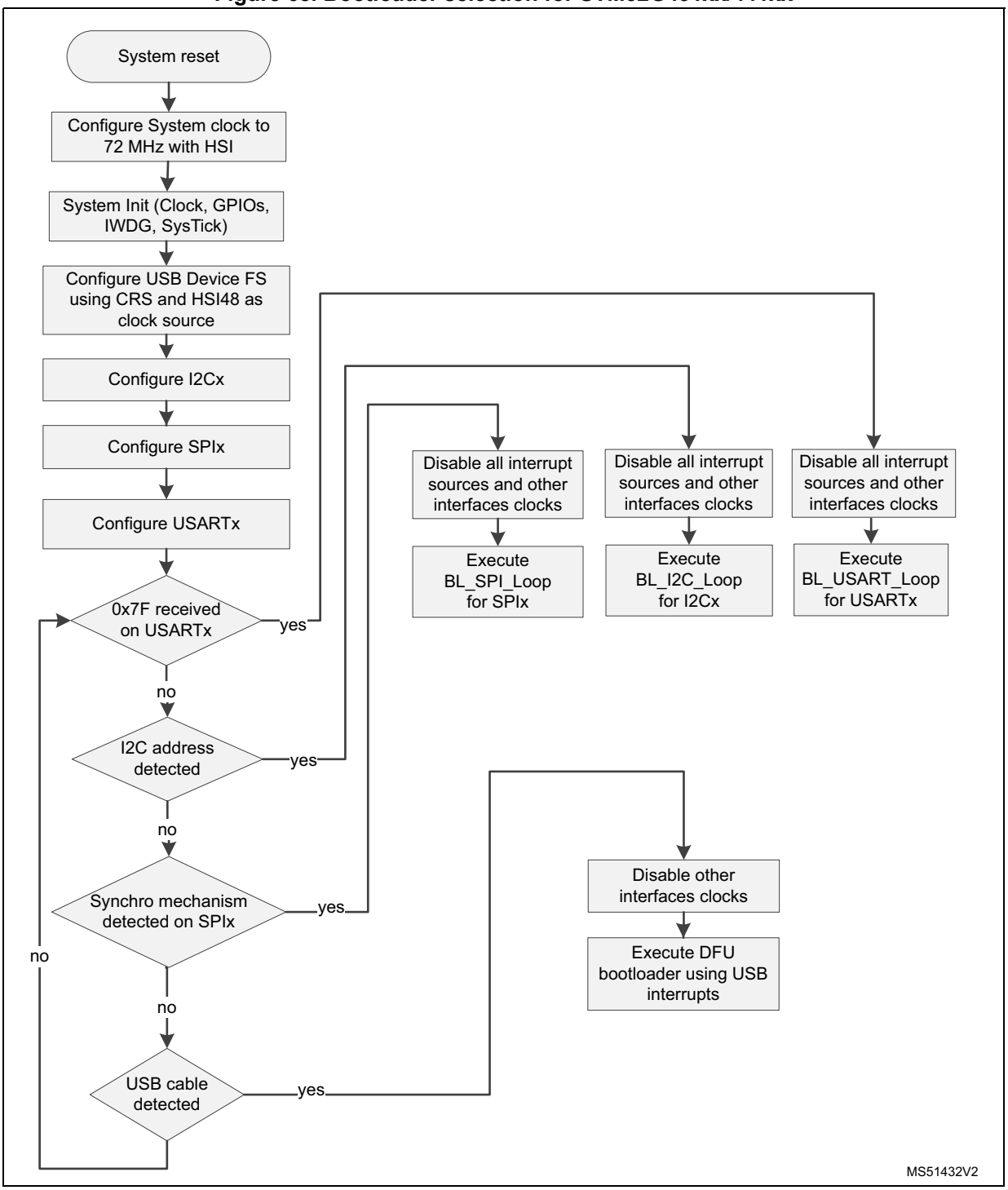
Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode.
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode.(1)
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

52.2 Bootloader selection

The following figure shows the bootloader selection mechanism.

Figure 68. Bootloader selection for STM32G431xx/441xx



52.3 Bootloader version

Table 117. STM32G431xx/441xx bootloader version

Version number	Description	Known limitations
V13.3 (0xD3)	Initial bootloader version	– CCSRAM not supported – ENGI area not exposed
V13.4 (0xD4)	– Fix V13.3 limitations – Add CCSRAM support – Add ENGI support	-

53 STM32G47xxx/48xxx devices

53.1 Bootloader configuration

The STM32G47xxx/48xxx bootloader is activated by applying Pattern 14 (described in *Table 2*). The following table shows the hardware resources used by this bootloader.

Table 118. STM32G47xxx/48xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 72 MHz (using the PLL clocked by HSI)
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
		-	
Securable memory area	-	-	The address to jump to the exit securable memory area @0x1FFF6800
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 118. STM32G47xxx/48xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1010011x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PC4 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PA8 pin: data line is used in open-drain pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1010011x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC8 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain pull-up mode.
I2C4	I2C4	Enabled	The I2C4 configuration is: I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1010011x (x = 0 for write and x = 1 for read)
	I2C4_SCL pin	Input/output	PC6 pin: clock line is used in open-drain pull-up mode.
	I2C4_SDA pin	Input/output	PC7 pin: data line is used in open-drain pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode.(1)
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull no pull-up, pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.

Table 118. STM32G47xxx/48xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, npull-down mode.
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode.(1)
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, n pull-down mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. **Note**: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

53.2 Bootloader selection

The following figures show the bootloader selection mechanism.

Figure 69. Bootloader selection for STM32G47xxx/48xxx

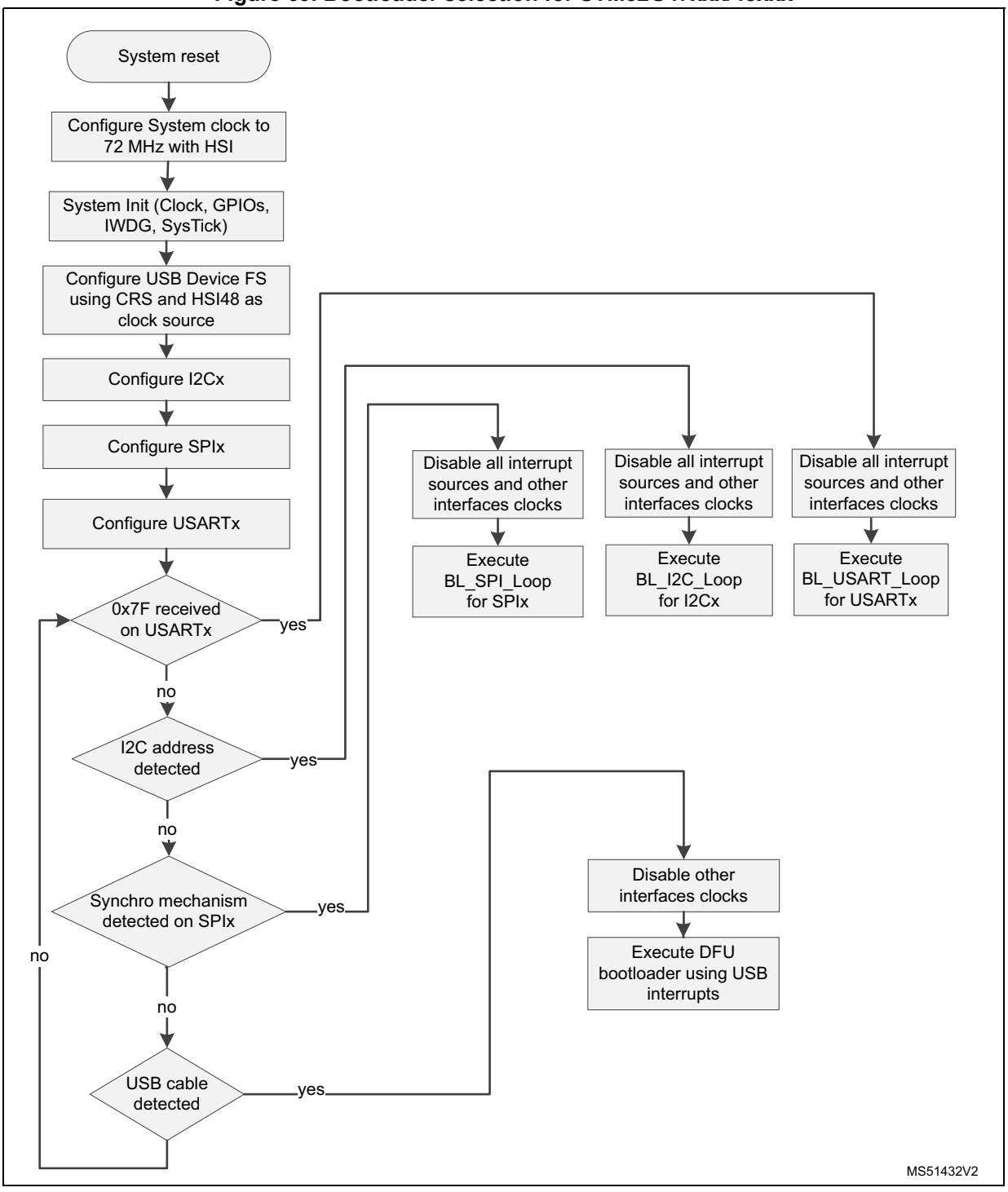
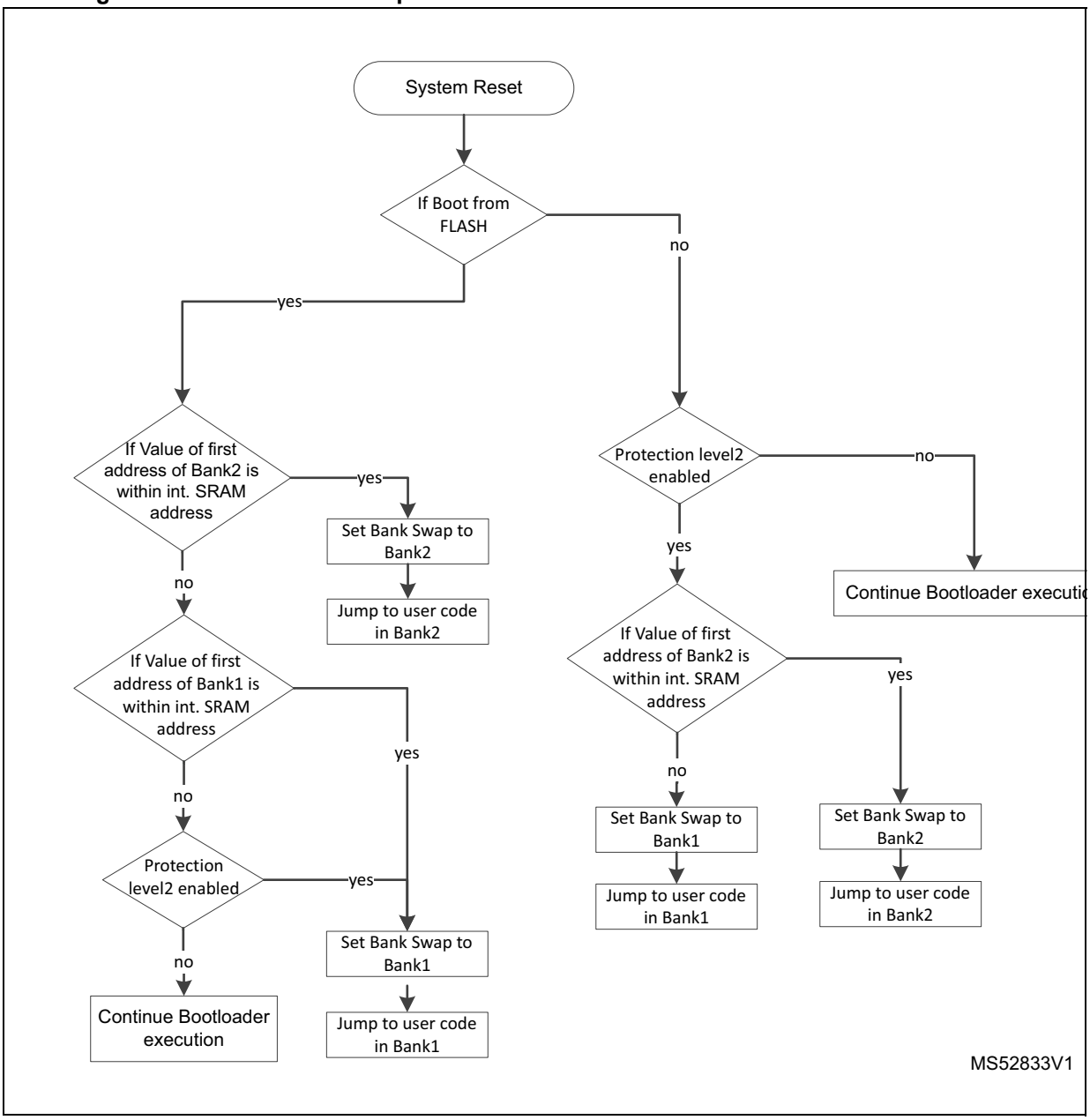


Figure 70. Dual bank boot implementation for STM32G47xxx/48xxx bootloader V13.x



53.3 Bootloader version

Table 119. STM32G47xxx/48xxx bootloader version

Version number	Description	Known limitations
V13.3 (0xD3)	Initial bootloader version	Boot from bank2 is not working

Table 119. STM32G47xxx/48xxx bootloader version (continued)

Version number	Description	Known limitations
V13.4 (0xD4)	Fix V13.3 limitations	CCSRAM/ENGI not supported
V13.5 (0xD5)	– Fix V13.4 limitations – Add CCSRAM/ENGI support	None

54 STM32G491xx/4A1xx devices

54.1 Bootloader configuration

The STM32G491xx/4A1xx bootloader is activated by applying Pattern 15 (described in *Table 2*). The following table shows the hardware resources used by this bootloader.

Table 120. STM32G491xx/4A1xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 72 MHz (using the PLL clocked by HSI)
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to the exit securable memory area @0x1FFF6800
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 120. STM32G491xx/4A1xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1011111x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PC4 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PA8 pin: data line is used in open-drain pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1011111x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC8 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode.(1)
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull no pull-up, pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.

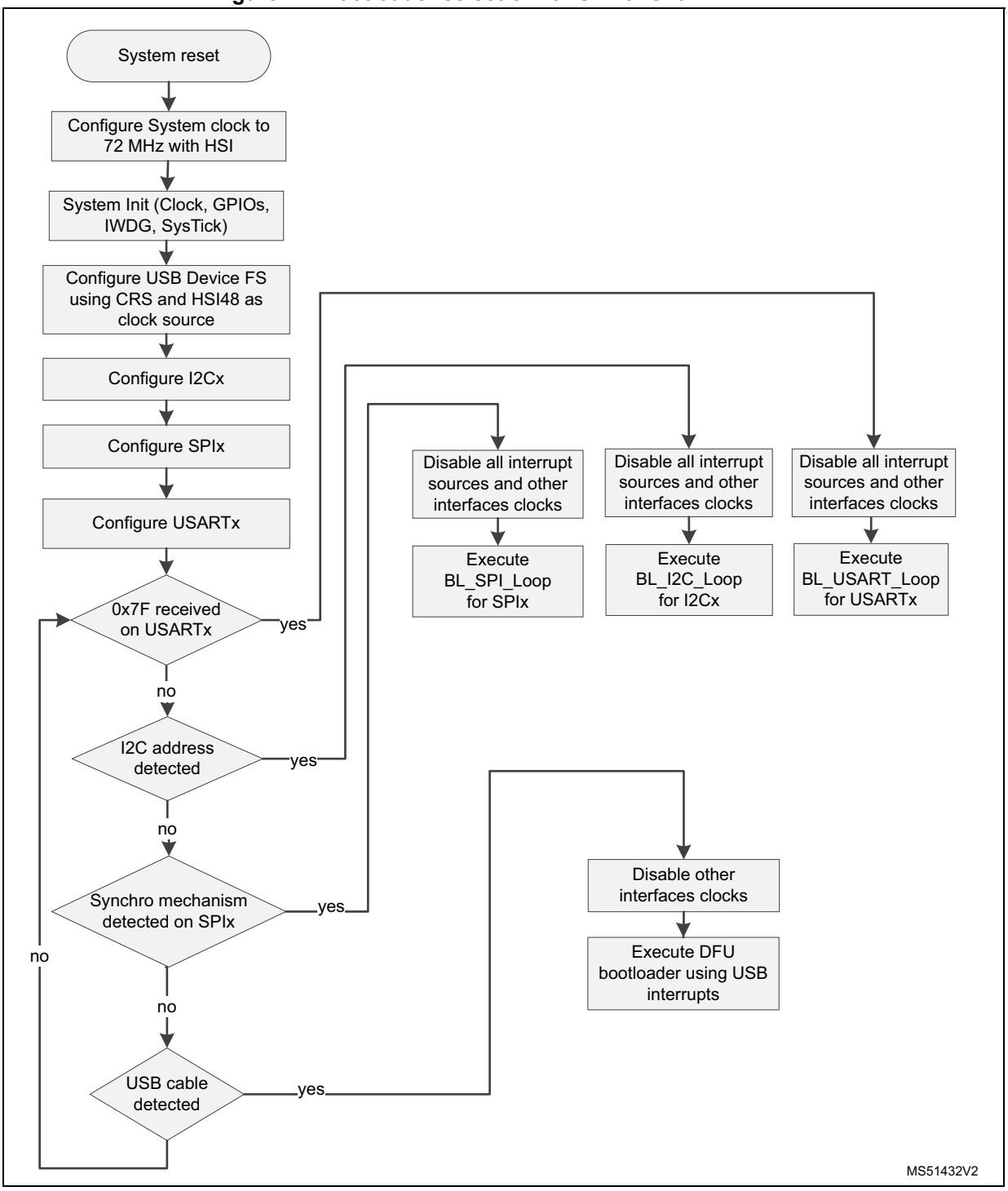
Table 120. STM32G491xx/4A1xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, npull-down mode.
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode.(1)
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, n pull-down mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. **Note**: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization, as soon as bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

54.2 Bootloader selection

Figure 71. Bootloader selection for STM32G491xx/4A1xx



54.3 Bootloader version

Table 121. STM32G491xx/4A1xx bootloader version

Version number	Description	Known limitations
V13.2	Initial bootloader version	None

55 STM32G53xxx/54xxx devices

55.1 Bootloader configuration

The STM32G53xxx/54xxx bootloader is activated by applying Pattern 17 (described in *Table 2*). *Table 122* shows the hardware resources used by this bootloader.

The bootloader follows boot model V3_2 (see *Section 4.10*), so it inherits all its constraints.

Table 122. STM32G53xxx/54xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 200 MHz (using PLL)
		HSE enabled	Enabled only when FDCAN is enabled in the option byte “BL_COM_CFG”. The quartz value is detected using TIM17. Only 12 MHz, 24 MHz, and 48 MHz values are supported as the FDCAN clock source. If no HSE is detected, or if the detected value does not match one of the supported values, HSE is disabled and the FDCAN clock source is HSI. Note that HSI is subject to drift, as mentioned in the product datasheet, and may lead to nonfunctional FDCAN. To avoid this issue, the HSE clock must be used.
	RAM	-	9 Kbytes, starting from address 0x20000C00, are used by the bootloader firmware
	System memory	-	45 Kbytes, starting from address 0x0BFA2C00, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.
UART4	UART4	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	UART4_RX pin	Input	PA1 pin: UART4 in reception mode. Used in alternate push-pull, pull-up mode.
	UART4_TX pin	Output	PA0 pin: UART4 in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.

Table 122. STM32G53xxx/54xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART5	USART5	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART5_RX pin	Input	PC14 pin: USART5 in reception mode. Used in alternate push-pull, pull-down mode.
	USART5_TX pin	Output	PC15 pin: USART5 in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON – Slave 7-bit address: 0b0110010x, x = 0 for write and x = 1 for read
	I2C2_SCL pin	Input/output	PB4 pin: clock line is used in open-drain, pull-up mode.
	I2C2_SDA pin	Input/output	PB3 pin: data line is used in open-drain, pull-up mode.
SPI1	SPI1_MOSI pin	Input	PB2 pin: slave data input line, used in push-pull, no pull mode.
	SPI1_MISO pin	Output	PB1 pin: slave data output line, used in push-pull, no pull mode(1).
	SPI1_SCK pin	Input	PB0 pin: slave clock line, used in push-pull, no pull mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, no pull mode.
SPI2	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull no pull mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, no pull mode(1).
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, no pull mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, no pull mode.

Table 122. STM32G53xxx/54xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
FDCAN	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PA6 pin: FDCAN1 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN1_Tx pin	Output	PA7 pin: FDCAN1 in transmission mode. Used in alternate push-pull, no pull mode.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

55.2 BL_COM_CFG mapping

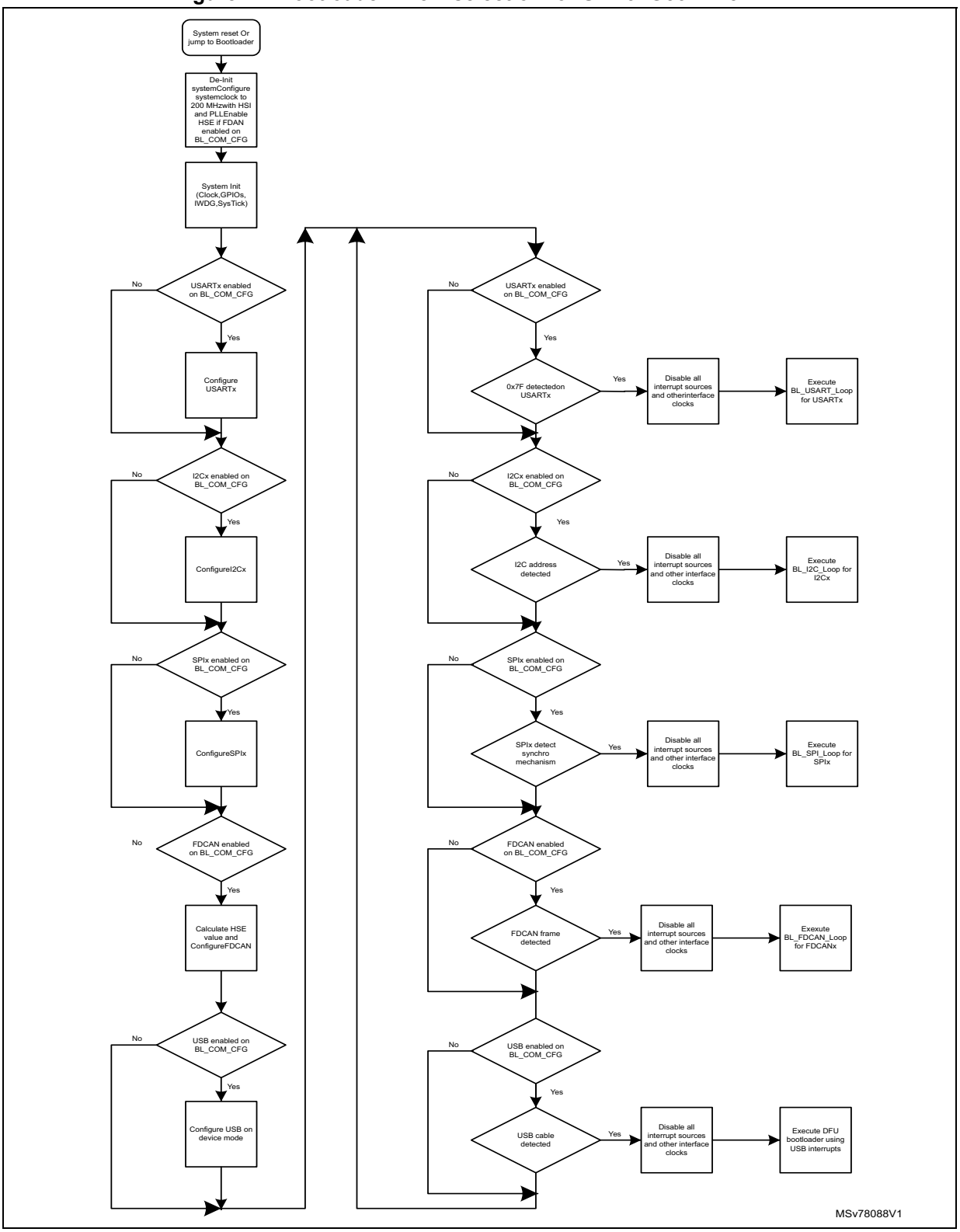
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved				Reserved				USB				FDCAN			
Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	FDCAN 1
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
I3C				SPI				I2C				USART			
Res.	Res.	Res.	Res.	Res.	Res.	SPI2	SPI1	Res.	Res.	Res.	I2C2	Res.	USART 5	UART4	USART 2

Table 123. STM32G53xxx/54xxx special commands

Special commands supported (USART/I2C/SPI/FDCAN) Opcode - 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent (MSB first)**	**Number of data received**	**Data received**	**Number of status data received (2 bytes)**	**Status data received**
Change product state	0x01	0x4	Product state targeted Ex: 0x00000017	0x0	NA	0x1	0x0
Reset	0x02	0x4	0x0	0x0	NA	0x1	0x0
Data provisioning Only when BL is on HDPL = 1	0x83	0x4	RAM address where data to provision is written	– 0x0 if success – 0x4 if fail	– NA if success – Error code on 4 bytes if fail	0x1	0x0

55.3 Bootloader selection

Figure 72. Bootloader V18.x selection for STM32G53xxx/54xxx



55.4 Bootloader version

Table 124. STM32G53xxx/54xxx bootloader version

Version number	Description	Known limitations
V18.0	Initial bootloader version	None

56 STM32G554xx/564xx devices

56.1 Bootloader configuration

The STM32G554xx/564xx bootloader is activated by applying Pattern 17 (described in *Table 2*). *Table 125* shows the hardware resources used by this bootloader.

The bootloader follows boot model V3_2 (see *Section 4.10*), so it inherits all its constraints.

Table 125. STM32G554xx/564xxconfiguration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 200 MHz (using PLL)
		HSI48 enabled	The clock recovery system (CRS) is enabled in the DFU bootloader to allow USB to be clocked by HSI48 at 48 MHz.
		HSE enabled	Enabled only when FDCAN is enabled in the option byte “BL_COM_CFG”. The quartz value is detected using TIM17. Only 12 MHz, 24 MHz, and 48 MHz values are supported as the FDCAN clock source. If no HSE is detected, or if the detected value does not match one of the supported values, HSE is disabled and the FDCAN clock source is HSI. Note that HSI is subject to drift, as mentioned in the product datasheet, and may lead to nonfunctional FDCAN. To avoid this issue, the HSE clock must be used.
	RAM	-	16 Kbytes, starting from address 0x20018000 , are used by the bootloader firmware
	System memory	-	45 Kbytes, starting from address 0x0BFA2C00, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.
UART4	UART4	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	UART4_RX pin	Input	PA1 pin: UART4 in reception mode. Used in alternate push-pull, pull-up mode.
	UART4_TX pin	Output	PA0 pin: UART4 in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.

Table 125. STM32G554xx/564xxconfiguration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART5	USART5	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART5_RX pin	Input	PC14 pin: USART5 in reception mode. Used in alternate push-pull, pull-down mode.
	USART5_TX pin	Output	PC15 pin: USART5 in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON – Slave 7-bit address: 0b0110011x, x = 0 for write and x = 1 for read
	I2C2_SCL pin	Input/output	PB4 pin: clock line is used in open-drain, pull-up mode.
	I2C2_SDA pin	Input/output	PB3 pin: data line is used in open-drain, pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON – Slave 7-bit address: 0b0110011x, x = 0 for write and x = 1 for read
	I2C3_SCL pin	Input/output	PE5 pin: clock line is used in open-drain, pull-up mode.
	I2C3_SDA pin	Input/output	PE4 pin: data line is used in open-drain, pull-up mode.
SPI1	SPI1_MOSI pin	Input	PB2 pin: slave data input line, used in push-pull, no pull mode.
	SPI1_MISO pin	Output	PB1 pin: slave data output line, used in push-pull, no pull mode(1).
	SPI1_SCK pin	Input	PB0 pin: slave clock line, used in push-pull, no pull mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, no pull mode.
SPI2	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull no pull mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, no pull mode(1).
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, no pull mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, no pull mode.

Table 125. STM32G554xx/564xxconfiguration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: not configured by the bootloader software, but assigned to the USB hardware once the block is initialized inside the bootloader.
	USB_DP pin		PA12: not configured by the bootloader software, but assigned to the USB hardware once the block is initialized inside the bootloader.
FDCAN	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PA6 pin: FDCAN1 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN1_Tx pin	Output	PA7 pin: FDCAN1 in transmission mode. Used in alternate push-pull, no pull mode.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

56.2 BL_COM_CFG mapping

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Reserved				Reserved				USB				FDCAN			
Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	Res.	USB	Res.	Res.	Res.	Res.	FDCAN 1
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
I3C				SPI				I2C				USART			
Res.	Res.	Res.	Res.	Res.	Res.	SPI2	SPI1	Res.	Res.	I2C3	I2C2	Res.	USART 5	UART4	USART 2

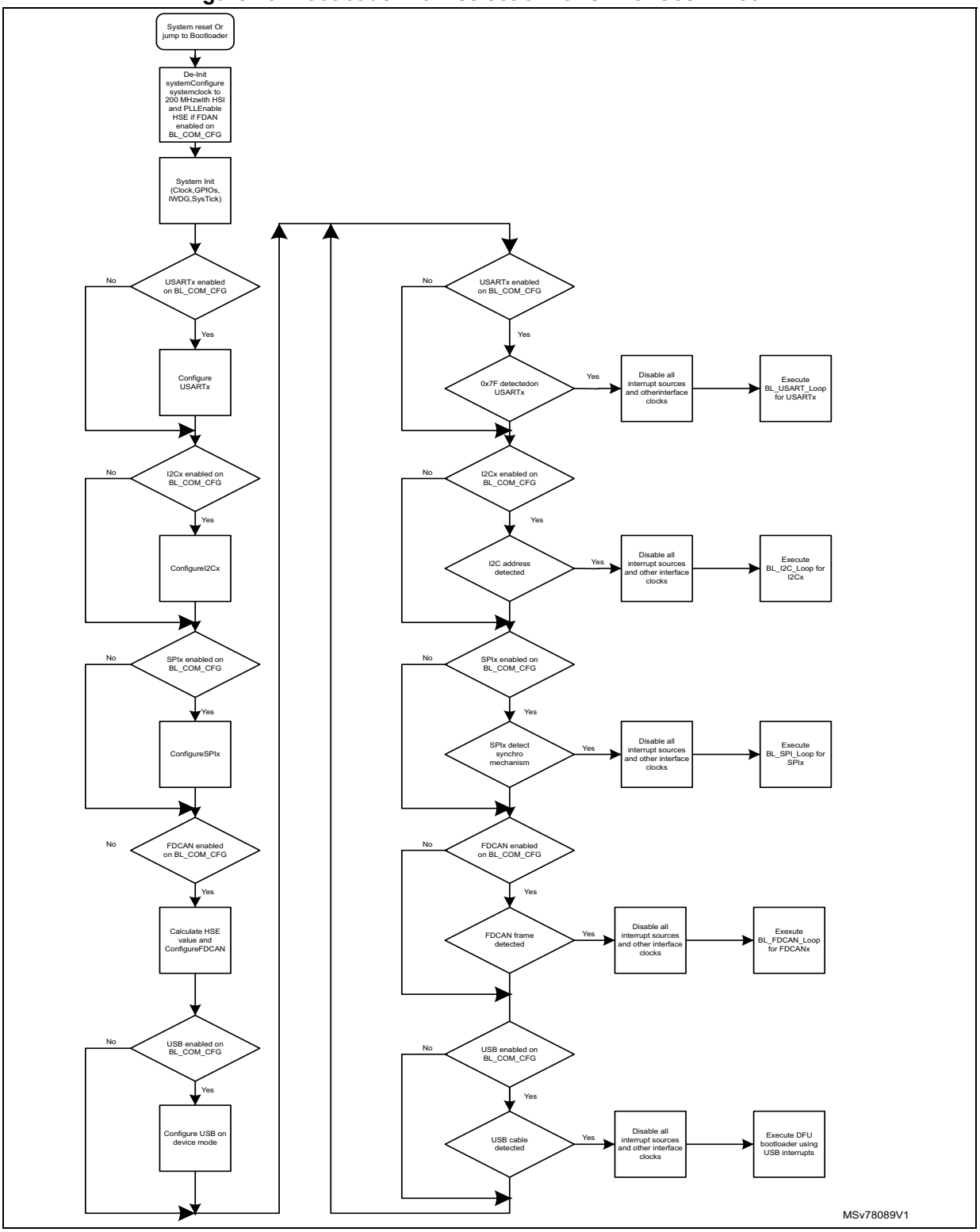
Table 126. STM32G554xx/564xx special commands

Special commands supported (USART/I2C/SPI/FDCAN) Opcode - 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent (MSB first)**	**Number of data received**	**Data received**	**Number of status data received (2 bytes)**	**Status data received**
Change product state	0x01	0x4	Product state targeted Ex: 0x00000017	0x0	NA	0x1	0x0
Reset	0x02	0x4	0x0	0x0	NA	0x1	0x0
Data provisioning Only when BL is on HDPL = 1	0x83	0x4	RAM address where data to provision is written	– 0x0 if success – 0x4 if fail	– NA if success – Error code on 4 bytes if fail	0x1	0x0

Note: USB special commands are slightly different from the other protocols as per the USB protocol specificities:
- *No Opcode is used, Sub-Opcode is used directly*
- *Sub-Opcode is treated in a single byte and not two bytes*
- *Data are sent on USB frame by byte (LSB first). No need to add number of data to transmit*
- *Returned data and status are formatted on the USB native protocol*

56.3 Bootloader selection

Figure 73. Bootloader V9.x selection for STM32G554xx/564xx



56.4 Bootloader version

Table 127. STM32G554xx/564xx bootloader version

Version number	Description	Known limitations
V9.0	Initial bootloader version	None

57 STM32H503xx devices

57.1 Bootloader configuration

The STM32H503xx bootloader is activated by applying Pattern 17 (described in *Table 2*). *Table 128* shows the hardware resources used by this bootloader.

The bootloader follows boot model V3_2 (see *Section 4.10*), so it inherits all its constraints.

Table 128. STM32H503xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 200 MHz (using PLL clocked by the HSI)
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz
		-	20 MHz derived from the PLLQ is used for FDCAN
	RAM	-	16 Kbytes, starting from address 0x24000000, are used by the bootloader firmware
	System memory	-	35 Kbytes, starting from address 0x0BF87000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Set as input until USART1 is detected.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA15 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA5 pin: USART2 in transmission mode. Set as input until USART2 is detected.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PA3 pin: USART3 in reception mode. Used in alternate push-pull, pull-down mode.
	USART3_TX pin	Output	PA4 pin: USART3 in transmission mode. Set as input until USART3 is detected.

Table 128. STM32H503xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2	I2C2	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b1100111x, x = 0 for write and x = 1 for read
	I2C2_SCL pin	Input/output	PB3 pin: clock line is used in open-drain, pull-up mode.
	I2C2_SDA pin	Input/output	PB4 pin: data line is used in open-drain, pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, no pull mode.
	SPI1_MISO pin	Output	PA0 pin: slave data output line, used in push-pull, no pull mode.
	SPI1_SCK pin	Input	PA8 pin: slave clock line, used in push-pull, no pull mode.
	SPI1_NSS pin	Input	PB8 pin: slave chip select pin used in push-pull, no pull mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB1 pin: slave data input line, used in push-pull no pull mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, no pull mode.
	SPI2_SCK pin	Input	PB10 pin: slave clock line, used in push-pull, no pull mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, no pull mode.

Table 128. STM32H503xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data input line, used in push-pull no pull mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, no pull mode.
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, no pull mode.
	SPI3_NSS pin	Input	PD2 pin: slave chip select pin used in push-pull, no pull mode.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. **Note**: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required
FDCAN	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PB5 pin: FDCAN1 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN1_Tx pin	Output	PB15 pin: FDCAN1 in transmission mode. Used in alternate push-pull, no pull mode.

Table 128. STM32H503xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I3C	I3C	Enabled	– Mode: target mode – Aval timing:0x4E – DMA Reg RX: disabled – DMA Req TX: disabled – Status FIFO: disabled – DMA Req status: disabled – DMA Req control: disabled – IBI: enabled – Additional data after IBI ack-ed: 1 byte – IBI configuration: Mandatory Data Byte (MDB) – All IT disabled except RXFNE (Receive FIFO Interrupt) The RXFNE interruption is disabled after SYNC byte detection by the bootloader.
	I3C1_SCL pin	Input/output	PB6 pin: I3C1 in transmission mode. Used in alternate push-pull, no pull mode.
	I3C1_SDA pin		PB7 pin: I3C1 in transmission mode. Used in alternate push-pull, no pull mode.

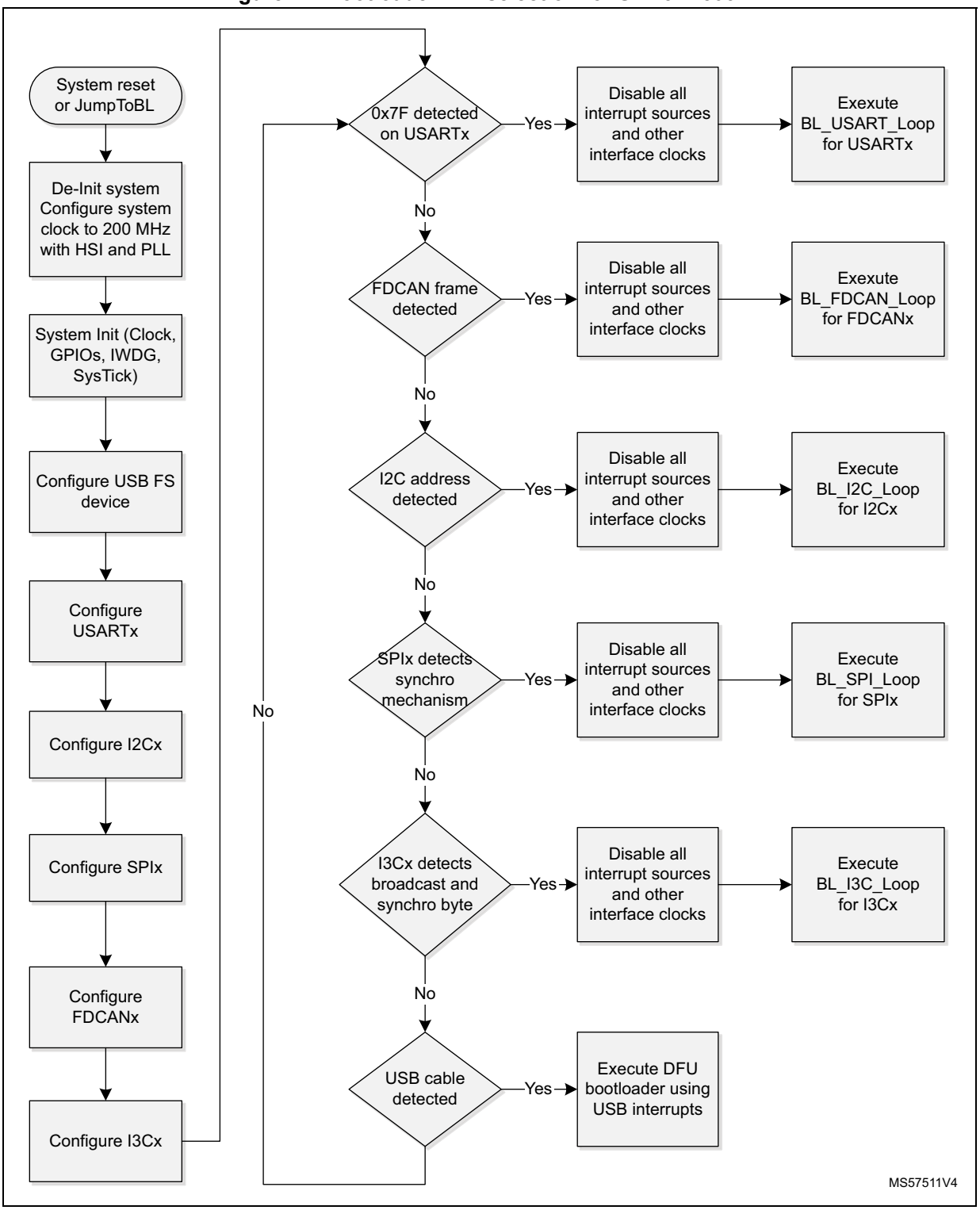
Table 129. STM32H503xx special commands

Special commands supported (USART/I2C/SPI/FDCAN/I3C) Opcode - 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent (MSB first)**	**Number of data received**	**Data received**	**Number of status data received (2 bytes)**	**Status data received**
Change product state	0x01	0x4	Product state targeted Ex: 0x00000017	0x0	NA	0x1	0x0
Reset	0x02	0x4	0x0	0x0	NA	0x1	0x0

Note: USB special commands are slightly different from the other protocols as per the USB protocol specificities:
• No Opcode is used, Sub-Opcode is used directly
• Sub-Opcode is treated in a single byte and not two bytes
• Data are sent on USB frame by byte (LSB first). No need to add number of data to transmit
• Returned data and status are formatted on the USB native protocol

57.2 Bootloader selection

Figure 74. Bootloader V14 selection for STM32H503xx



57.3 Bootloader version

Table 130. STM32H503xx bootloader version

Version number	Description	Known limitations
V14.1	Initial bootloader version	Bootloader crash when jumping to it with (HiDe Protection Level = 3 + product state ≥ Provisioned)
V14.2	– Fix known limitations – Change BL system clock from 160 to 200 MHz	None

58 STM32H523xx/533xx devices

58.1 Bootloader configuration

The STM32H523xx/533xx bootloader is activated by applying Pattern 17 (described in *Table 2*). *Table 131* shows the hardware resources used by this bootloader.

The bootloader follows boot model V3_2 (see *Section 4.10*), so it inherits all its constraints.

Table 131. STM32H523xx/533xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 200 MHz (using PLL clocked by the HSI)
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz
		-	20 MHz derived from the PLLQ is used for FDCAN
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	35 Kbytes, starting from address 0x0BF97000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Set as input until USART1 is detected.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Set as input until USART2 is detected.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PD9 pin: USART3 in reception mode. Used in alternate push-pull, pull-down mode.
	USART3_TX pin	Output	PD8 pin: USART3 in transmission mode. Set as input until USART3 is detected.

Table 131. STM32H523xx/533xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1101110x, x = 0 for write and x = 1 for read
	I2C1_SCL pin	Input/output	PB8 pin: clock line is used in open-drain, pull-up mode.
	I2C1_SDA pin		PB9 pin: data line is used in open-drain, pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1101110x, x = 0 for write and x = 1 for read
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain, pull-up mode.
	I2C3_SDA pin		PC9 pin: used in all packages with more than 39 pins. PB4 pin: used in packages with 39 pins or fewer. The data line is used in open-drain, pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, no pull mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, no pull mode.
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, no pull mode.
	SPI1_NSS pin		PA4 pin: slave chip select pin used in push-pull, no pull mode.

Table 131. STM32H523xx/533xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PC1 pin: slave data input line, used in push-pull, no pull mode in all packages except LQFP48, UFQFN48, and WLCSP39. PB15 pin: Slave data Input line, used in push-pull, no pull mode in LQFP48, UFQFN48, and WLCSP39 packages.
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, no pull mode.
	SPI2_SCK pin	Input	PB10 pin: slave clock line, used in push-pull, no pull mode.
	SPI2_NSS pin		PB12 pin: slave chip select pin used in push-pull, no pull mode.
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data input line, used in push-pull no pull mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, no pull mode.
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, no pull mode.
	SPI3_NSS pin		PA15 pin: slave chip select pin used in push-pull, no pull mode.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode.- No external pull-up resistor is required

Table 131. STM32H523xx/533xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
FDCAN	FDCAN2	Enabled	Once initialized the FDCAN2 configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN2_Rx pin	Input	PB5 pin: FDCAN2 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN2_Tx pin	Output	PB13 pin: FDCAN2 in transmission mode. Used in alternate push-pull, no pull mode.
I3C	I3C1	Enabled	– Mode: target mode – Aval timing:0x4E – DMA Reg RX: disabled – DMA Req TX: disabled – Status FIFO: disabled – DMA Req status: disabled – DMA Req control: disabled – IBI: enabled – Additional data after IBI ack-ed: 1 byte – IBI configuration: Mandatory Data Byte (MDB) – All IT disabled except RXFNE (Receive FIFO Interrupt). The RXFNE interruption is disabled after SYNC byte detection by the bootloader.
	I3C1_SCL pin	Input/output	PB6 pin: I3C1 in transmission mode. Used in alternate push-pull, no pull mode in all packages except LQFP48, UFQFN48, and WLCSP39. PB8 pin: I3C1 in transmission mode. Used in alternate push-pull, no pull mode in LQFP48, UFQFN48 and WLCSP39 packages..
	I3C1_SDA pin		PB7 pin: I3C1 in transmission mode. Used in alternate push-pull, no pull mode.

Table 132. STM32H523xx/533xx special commands

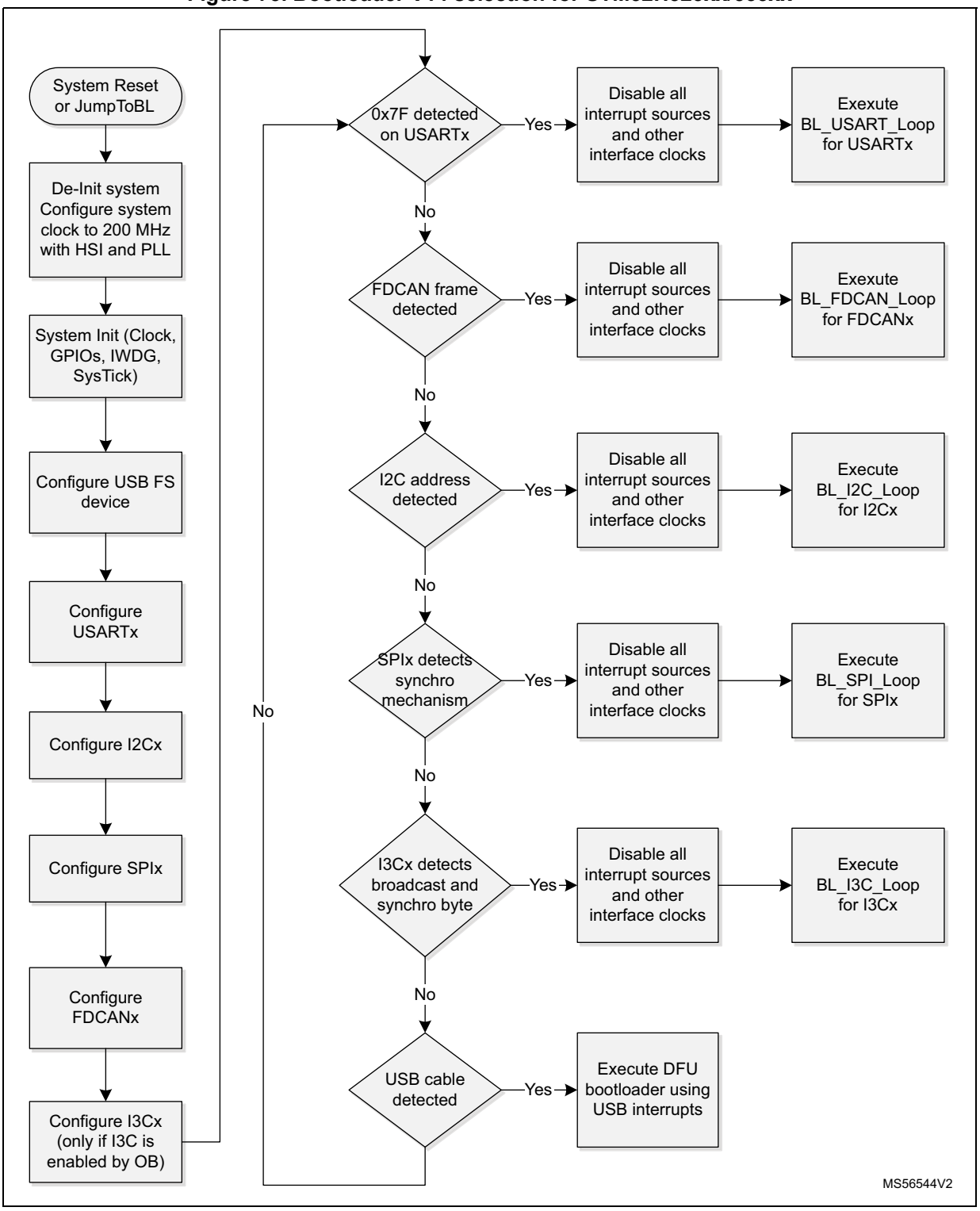
Special commands supported (USART/I2C/SPI/FDCAN/I3C) Opcode - 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent (MSB first)**	**Number of data received**	**Data received**	**Number of status data received (2 bytes)**	**Status data received**
Change product state	0x01	0x4	Product state targeted Ex: 0x00000017	0x0	NA	0x1	0x0
Reset	0x02	0x4	0x0	0x0	NA	0x1	0x0
Data provisioning Only when BL is on HDPL = 1	0x83	0x4	RAM address where data to provision is written	– 0x0 if success – 0x4 if fail	– NA if success – Error code if fail	0x1	0x0

Note: USB special commands are slightly different from the other protocols as per the USB protocol specificities:
- *No Opcode is used, Sub-Opcode is used directly*
- *Sub-Opcode is treated in a single byte and not two bytes*
- *Data are sent on USB frame by byte (LSB first). No need to add number of data to transmit*
- *Returned data and status are formatted on the USB native protocol*

58.2 Bootloader selection

Figure 75 shows the bootloader selection mechanism.

Figure 75. Bootloader V14 selection for STM32H523xx/533xx



58.3 Bootloader version

Table 133. STM32H523xx/533xx bootloader version

Version number	Description	Known limitations
V14.0	Initial bootloader version	– PKG_ID wrongly detected when PKG_ID > 0xF – I2C/I3C not working on BL as wrong pinout applied
V14.2	Fix known limitations	None

59 STM32H543xx/553xx devices

59.1 Bootloader configuration

The STM32H543xx/553xx bootloader is activated by applying Pattern 17 (described in *Table 2*). *Table 131* shows the hardware resources used by this bootloader.

The bootloader follows boot model V3_2 (see *Section 4.10*), so it inherits all its constraints.

Table 134. STM32H543xx/553xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 200 MHz (using PL)
		HSI48 enabled	CRS is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz
		-	20 MHz derived from the PLLQ is used for FDCAN
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	40 Kbytes, starting from address 0x0BFA4000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PD9 pin: USART3 in reception mode. Used in alternate push-pull, pull-down mode.
	USART3_TX pin	Output	PD8 pin: USART3 in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.

Table 134. STM32H543xx/553xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111010x , x = 0 for write and x = 1 for read
	I2C1_SCL pin	Input/output	PB8 pin: clock line is used in open-drain, pull-up mode.
	I2C1_SDA pin		PB9 pin: data line is used in open-drain, pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0111010x, x = 0 for write and x = 1 for read
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain, pull-up mode.
	I2C3_SDA pin		PC9 pin: used in all packages except for LQFP48 and UFQFN48. PB4 pin: used in packages LQFP48 and UFQFN48. The data line is used in open-drain, pull-up mode.
SPI1	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, no pull mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, no pull mode.
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, no pull mode.
	SPI1_NSS pin		PA4 pin: slave chip select pin used in push-pull, no pull mode.
SPI2	SPI2_MOSI pin	Input	PC1 pin: slave data input line, used in push-pull, no pull mode in all packages except LQFP48, UFQFN48. PB15 pin: Slave data Input line, used in push-pull, no pull mode in LQFP48 and UFQFN48 packages.
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, no pull mode.
	SPI2_SCK pin	Input	PB10 pin: slave clock line, used in push-pull, no pull mode.
	SPI2_NSS pin		PB12 pin: slave chip select pin used in push-pull, no pull mode.

Table 134. STM32H543xx/553xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI3	SPI3_MOSI pin	Input	PC12 pin: slave data input line, used in push-pull no pull mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, no pull mode.
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, no pull mode.
	SPI3_NSS pin		PA15 pin: slave chip select pin used in push-pull, no pull mode.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: not configured by the bootloader software, but assigned to the USB hardware once the block is initialized inside the bootloader.
	USB_DP pin		PA12: not configured by the bootloader software, but assigned to the USB hardware once the block is initialized inside the bootloader.
FDCAN	FDCAN2	Enabled	Once initialized the FDCAN2 configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN2_Rx pin	Input	PB5 pin: FDCAN2 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN2_Tx pin	Output	PB13 pin: FDCAN2 in transmission mode. Used in alternate push-pull, no pull mode.

Table 134. STM32H543xx/553xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I3C	I3C1	Enabled	– Mode: target mode – Aval timing:0x62 – DMA Reg RX: disabled – DMA Req TX: disabled – Status FIFO: disabled – DMA Req status: disabled – DMA Req control: disabled – IBI: enabled – Additional data after IBI ack-ed: 1 byte – IBI configuration: Mandatory Data Byte (MDB) – All IT disabled except RXFNE (Receive FIFO Interrupt). The RXFNE interruption is disabled after SYNC byte detection by the bootloader.
	I3C1_SCL pin	Input/output	PB6 pin: I3C1 in transmission mode. Configured in alternate push-pull, pull-up, then switched to no-pull mode.
	I3C1_SDA pin		PB7 pin: I3C1 in transmission mode. Configured in alternate push-pull, pull-up, then switched to no-pull mode.

Table 135. STM32H543xx/553xx special commands

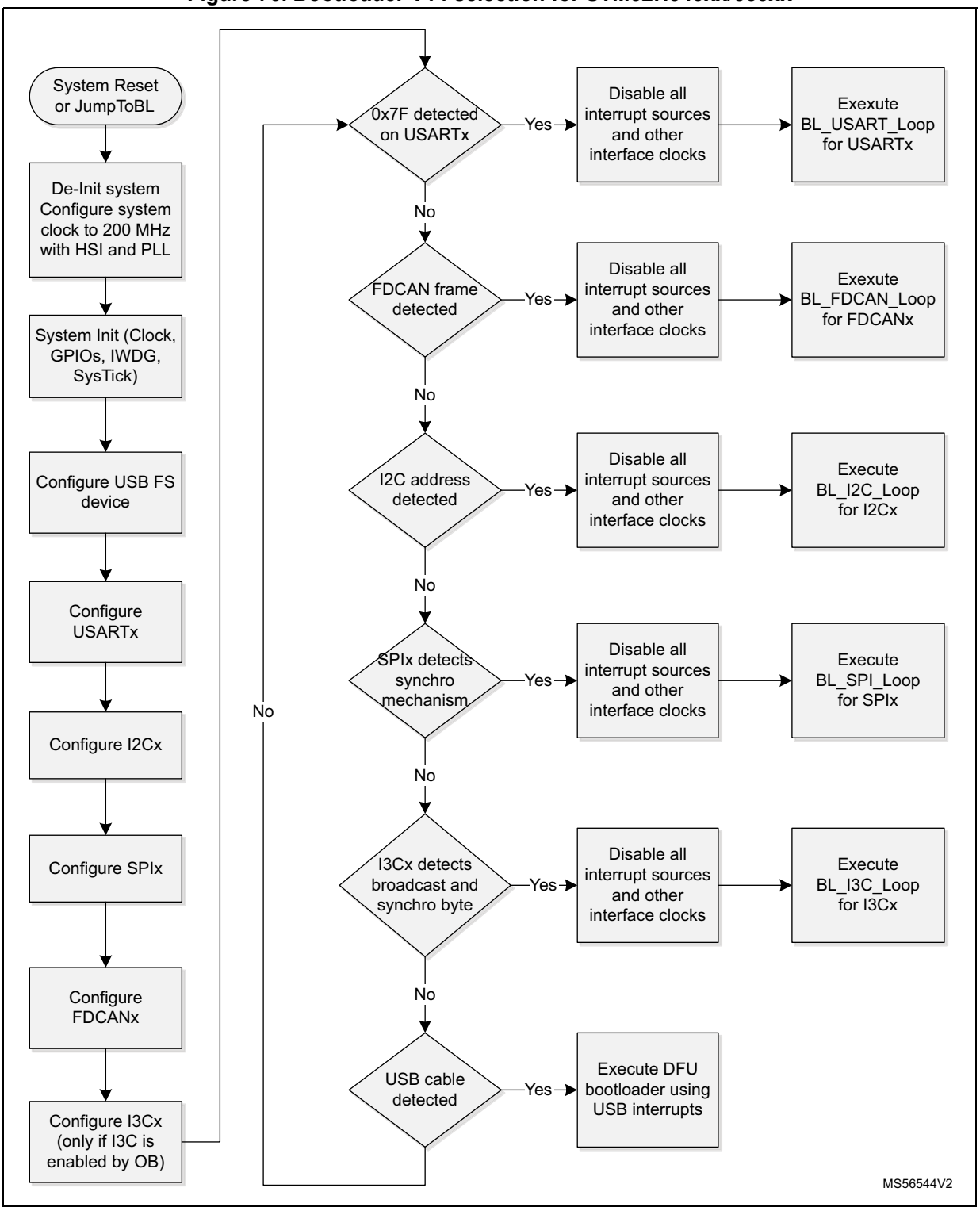
Special commands supported (USART/I2C/SPI/FDCAN/I3C) Opcode - 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent (MSB first)**	**Number of data received**	**Data received**	**Number of status data received (2 bytes)**	**Status data received**
Change product state	0x01	0x4	Product state targeted Ex: 0x00000017	0x0	NA	0x1	0x0
Reset	0x02	0x4	0x0	0x0	NA	0x1	0x0
Data provisioning Only when BL is on HDPL = 1	0x83	0x4	RAM address where data to provision is written	– 0x0 if success – 0x4 if fail	– NA if success – Error code on 4 bytes if fail	0x1	0x0

Note: USB special commands are slightly different from the other protocols as per the USB protocol specificities:
- *No Opcode is used, Sub-Opcode is used directly*
- *Sub-Opcode is treated in a single byte and not two bytes*
- *Data are sent on USB frame by byte (LSB first). No need to add number of data to transmit*
- *Returned data and status are formatted on the USB native protocol*

59.2 Bootloader selection

Figure 76 shows the bootloader selection mechanism.

Figure 76. Bootloader V14 selection for STM32H543xx/553xx



59.3 Bootloader version

Table 136. STM32H543xx/553xx bootloader version

Version number	Description	Known limitations
V14.0	Initial bootloader version	None

60 STM32H562xx/563xx/573xx devices

60.1 Bootloader configuration

The STM32H562xx/563xx/573xx bootloader is activated by applying Pattern 17 (described in *Table 2*). *Table 137* shows the hardware resources used by this bootloader.

The bootloader follows boot model V3_2 (see *Section 4.10*), so it inherits all its constraints.

Table 137. STM32H562xx/563xx/573xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 200 MHz (using PLL clocked by the HSI)
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz
		-	20 MHz derived from the PLLQ is used for FDCAN
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	35 Kbytes, starting from address 0x0BF97000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Set as input until USART1 is detected.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Set as input until USART2 is detected.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PD9 pin: USART3 in reception mode. Used in alternate push-pull, pull-down mode.
	USART3_TX pin	Output	PD8 pin: USART3 in transmission mode. Set as input until USART3 is detected.

Table 137. STM32H562xx/563xx/573xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1100101x, x = 0 for write and x = 1 for read
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain, pull-up mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain, pull-up mode.
I2C4	I2C4	Enabled	The I2C4 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1100101x, x = 0 for write and x = 1 for read
	I2C4_SCL pin	Input/output	PD12 pin: clock line is used in open-drain, pull-up mode.
	I2C4_SDA pin	Input/output	PD13 pin: data line is used in open-drain, pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, no pull mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, no pull mode.
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, no pull mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, no pull mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PC1 pin: slave data input line, used in push, pull no pull mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, no pull mode.
	SPI2_SCK pin	Input	PB10 pin: slave clock line, used in push-pull, no pull mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, no pull mode.

Table 137. STM32H562xx/563xx/573xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data input line, used in push-pull no pull mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, no pull mode.
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, no pull mode.
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, no pull mode.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. **Note**: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required
FDCAN	FDCAN2	Enabled	Once initialized the FDCAN2 configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN2_Rx pin	Input	PB5 pin: FDCAN2 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN2_Tx pin	Output	PB13 pin: FDCAN2 in transmission mode. Used in alternate push-pull, no pull mode.

Table 137. STM32H562xx/563xx/573xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I3C	I3C	Enabled	– Mode: target mode – Aval timing:0x4E – DMA Reg RX: disabled – DMA Req TX: disabled – Status FIFO: disabled – DMA Req status: disabled – DMA Req control: disabled – IBI: enabled – Additional data after IBI ack-ed: 1 byte – IBI configuration: Mandatory Data Byte (MDB) – All IT disabled except RXFNE (Receive FIFO Interrupt) The RXFNE interruption is disabled after SYNC byte detection by the bootloader.
	I3C1_SCL pin	Input/output	PB6 pin: I3C1 in transmission mode. Used in alternate push-pull, no pull mode.
	I3C1_SDA pin		PB7 pin: I3C1 in transmission mode. Used in alternate push-pull, no pull mode.

Table 138. STM32H562xx/563xx/573xx special commands

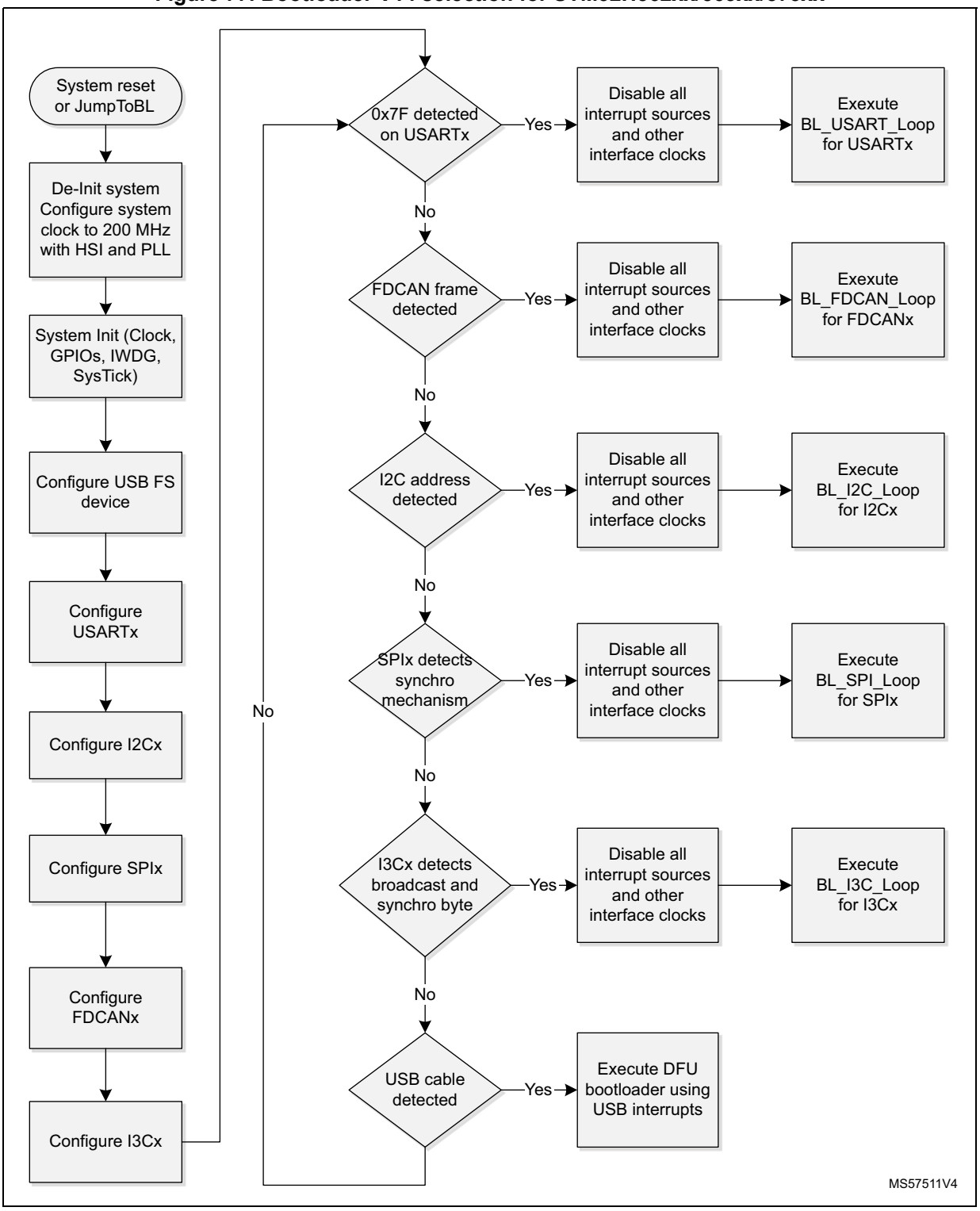
Special commands supported (USART/I2C/SPI/FDCAN/I3C) Opcode - 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent (MSB first)**	**Number of data received**	**Data received**	**Number of status data received (2 bytes)**	**Status data received**
Change product state	0x01	0x4	Product state targeted Ex: 0x00000017	0x0	NA	0x1	0x0
Reset	0x02	0x4	0x0	0x0	NA	0x1	0x0
Data provisioning Only when BL is on HDPL = 1	0x83	0x4	RAM address where data to provision is written	– 0x0 if success – 0x4 if fail	– NA if success – Error code if fail	0x1	0x0

Note: USB special commands are slightly different from the other protocols as per the USB protocol specificities:
- *No Opcode is used, Sub-Opcode is used directly*
- *Sub-Opcode is treated in a single byte and not two bytes*
- *Data are sent on USB frame by byte (LSB first). No need to add number of data to transmit*
- *Returned data and status are formatted on the USB native protocol*

60.2 Bootloader selection

Figure 77 shows the bootloader selection mechanism.

Figure 77. Bootloader V14 selection for STM32H562xx/563xx/573xx



60.3 Bootloader version

Table 139. STM32H562xx/563xx/573xx bootloader version

Version number	Description	Known limitations
V14.5	Fix known limitations – Only on 1 Mbyte devices for revisions other than W. – Populated on all sales types for revision W.	None
V14.4	– Fix known limitations – Change BL system clock from 160 to 200 MHz	EEPROM sector erase not working on 1 Mbyte devices.
V14.3	Initial bootloader version	Bootloader crash when jumping to it with the following condition (TrustZone® enabled + HiDe Protection = 3 + Product state ≥ Provisioned)

A standalone EraseEEPROM function is added on the system memory at address 0x0BF9 F500. When an erase sector is needed:

1. Write at RAM address 0x2000 4000 (LSB to MSB)
   c) Byte0: number of sectors to erase (N)
   d) Byte1 to N (every byte contains the sector number, that is, 0 to 7 for Bank1, 8 to 15 for Bank2)
   e) Example: to erase sector 3, 4, and 13, write 0x0303040D at address 0x20004000.
2. After the erase, go back to the bootloader.
3. To continue using the bootloader, a reconnect is needed.

61 STM32H5Ex/5Fx devices

61.1 Bootloader configuration

The STM32H5Ex/5Fx bootloader is activated by applying Pattern17 (see *Table 2*). *Table 140* shows the hardware resources used by this bootloader.

The bootloader follows boot model V3_2 (see *Section 4.10*), so it inherits all its constraints.

Table 140. STM32H5Ex/5Fx configuration in system memory boot mode

Bootloader	Feature/peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 200 MHz (with PLL).
		HSI48 enabled if USB HS does not exist on the package	Depending on engineering values read at bootloader startup, if USB HS is not enabled, USB FS is used by the bootloader. In this case, the clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI48 at 48 MHz.
		HSE enabled if USB HS exists on the package	Depending on engineering values read at bootloader startup, if USB HS is enabled, USB HS is used by the bootloader. At startup, USB HS is clocked from HSI PLLQ, with a fixed value of 20 MHz. If a USB cable is detected on the USB HS port and enumeration is complete, USB HS stops, and HSE quartz calculation starts based on TIM17. Supported values are 8 MHz, 12 MHz, 16 MHz, 20 MHz, 24 MHz, 26 MHz, 32 MHz, and 48 MHz. If no HSE is detected or the value does not match the supported values, the system issues a reset.
	RAM	-	16 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	40 Kbytes, starting from address 0x0BFAC000 contain the bootloader firmware.
	IWDG	-	The independent watchdog (IWDG) prescaler is configured to its maximum value. It is periodically refreshed to prevent a watchdog reset (in case the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the USART1 configuration is: 8 bits, even parity and 1 Stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.

Table 140. STM32H5Ex/5Fx configuration in system memory boot mode (continued)

Bootloader	Feature/peripheral	State	Comment
USART2	USART2	Enabled	Once initialized the USART2 configuration is: 8 bits, even parity and 1 Stop bit.
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.
USART3	USART3	Enabled	Once initialized the USART2 configuration is: 8 bits, even parity and 1 Stop bit
	USART3_RX pin	Input	PD9 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PD8 pin: USART3 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.
I2C3	I2C3	Enabled	The I2C3 configuration is: - I2C speed: up to 400 kHz - 7-bit address - Target mode - Analog filter ON - Target 7-bit address: 0b1110100x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/Output	PA8 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/Output	PC9 pin: data line is used in open-drain pull-up mode.
I2C4	I2C4	Enabled	The I2C4 configuration is: - I2C speed: up to 400 kHz - 7-bit address - Target mode - Analog filter ON - Target 7-bit address: 0b1110100x (where x = 0 for write and x = 1 for read)
	I2C4_SCL pin	Input/Output	PD12 pin: clock line is used in open-drain pull-up mode.
	I2C4_SDA pin	Input/Output	PD13 pin: data line is used in open-drain pull-up mode.

Table 140. STM32H5Ex/5Fx configuration in system memory boot mode (continued)

Bootloader	Feature/peripheral	State	Comment
I3C	I3C1	Enabled	– Mode: target mode – Aval timing:0x4E – DMA Request RX: disabled – DMA Request TX: disabled – Status FIFO: disabled – DMA Request status: disabled – DMA Request control: disabled – IBI: enabled – Additional data after IBI ack-ed: 1 byte – IBI configuration: mandatory data byte (MDB) – All interrupts are disabled except RXFNE (Receive FIFO Interrupt). The RXFNE interrupt is disabled after SYNC byte is detected by the bootloader.
	I3C1_SCL pin	Input/output	PB6 pin: I3C1 in transmission mode. Configured in alternate push-pull, pull-up, and switched to no pull mode.
	I3C1_SDA pin		PB7 pin: I3C1 in transmission mode. Configured in alternate push-pull, pull-up, and switched to no pull mode.
DFU	USBFS	Enabled only if USB HS is not enabled by the engineering bytes on the package	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USBFS_DM pin	Input/Output	PA11: Not configured by bootloader SW.
	USBFS_DP pin		PA12: Not configured by bootloader SW.
	USBHS	Enabled - if USB HS enabled by the engineering bytes on the package	USB HS configured in forced device mode. USB HS interrupt vector is enabled and used for USB DFU communications.
	USBHS_DM pin	Input/Output	No pins configured for the USB HS.
	USBHS_DP pin		

Table 141. STM32H5Ex/5Fx special commands

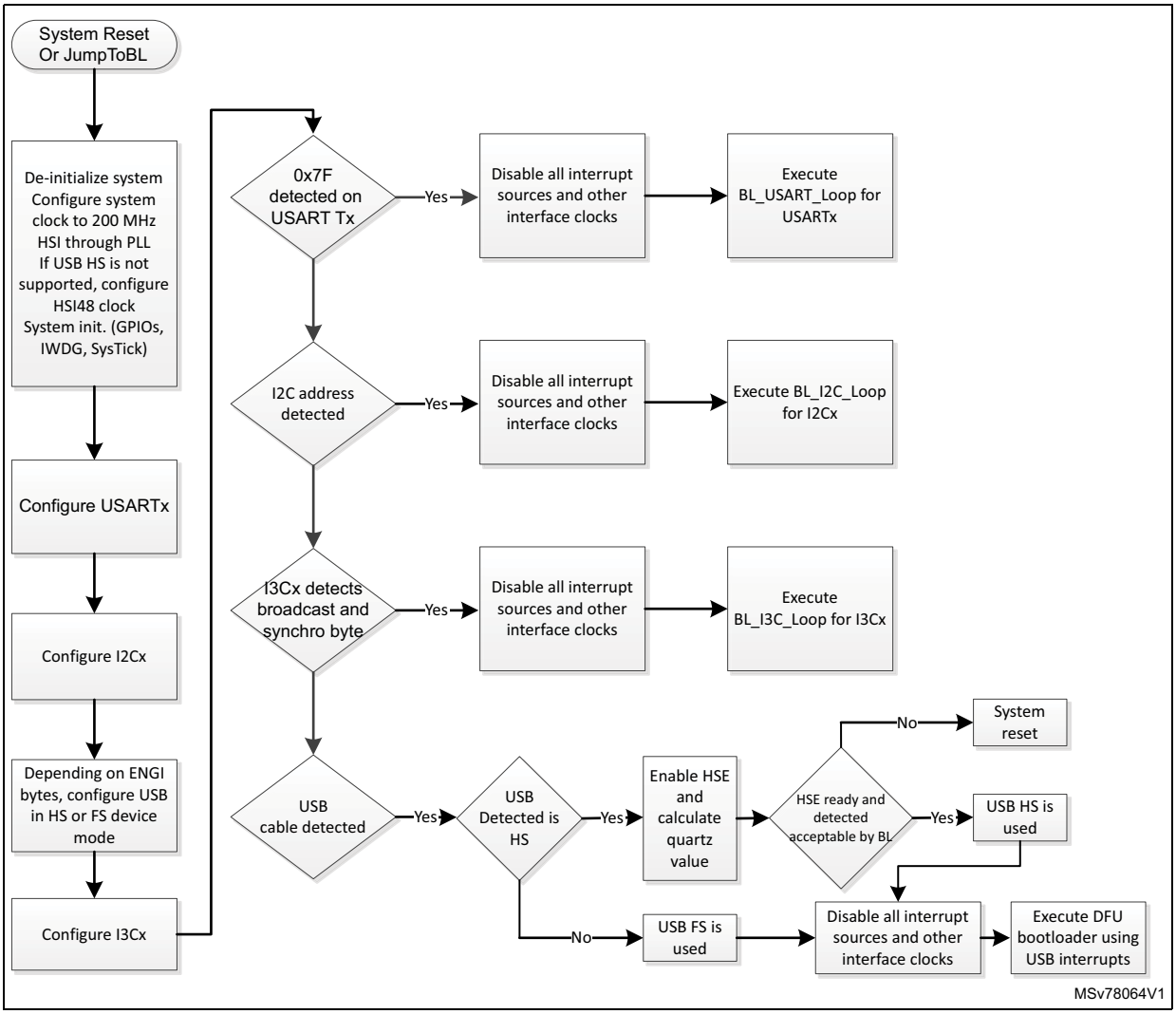
Special commands supported (USART/I2C/I3C) Opcode - 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent (MSB first)**	**Number of data received**	**Data received**	**Number of status data received (2 bytes)**	**Status data received**
Change product state	0x01	0x4	Product state targeted Ex: 0x00000017	0x0	NA	0x1	0x0
Reset	0x02	0x4	0x0	0x0	NA	0x1	0x0
Data provisioning Only when BL is on HDPL = 1	0x83	0x4	RAM address where data to provision is written	– 0x0 if success – 0x4 if fail	– NA if success – Error code on 4 bytes if fail	0x1	0x0

Note: USB special commands differ from other protocols due to USB protocol specificities:
- No opcode is used; the sub-opcode is used directly.
- The sub-opcode is treated as a single byte, not two bytes.
- Data is sent on the USB frame byte by byte; there is no need to specify the number of data bytes to be transmitted.
- Returned data and status are formatted according to the native USB protocol.

61.2 Bootloader selection

Figure 78 shows the bootloader selection mechanism.

Figure 78. Bootloader V15.x selection for STM32H5Ex/5Fx devices



61.3 Bootloader version

Table 142 lists the STM32H5Ex/5Fx devices bootloader versions.

Table 142. STM32H5Ex/5Fx bootloader versions

Bootloader version number	Description	Known limitations
V15.0	Initial bootloader version	None

62 STM32H72xxx/73xxx devices

62.1 Bootloader configuration

The STM32H72xxx/73xxx bootloader is activated by applying Pattern 10 (described in *Table 2*). *Table 143* shows the hardware resources used by this bootloader.

Table 143. STM32H72xxx/73xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 66 MHz (using PLL clocked by the HSI)
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz
		-	20 MHz derived from the PLLQ is used for FDCAN
	RAM	-	16 Kbytes, starting from address 0x24000000, are used by the bootloader firmware
	System memory	-	128 Kbytes, starting from address 0x1FF00000 contain the bootloader firmware. The bootloader start address is 0x1FF09800.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage is set to Voltage Range 3. Bootloader SW is writing to the PWR_CR3 register using 4 bytes, locking this register. Only Power off/on unlocks it. This is fixed on the BL with 0x93 version.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode. Set as input until USART1 is detected on the BL version 0x93.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode. Set as input until USART2 is detected on the BL version 0x93.

Table 143. STM32H72xxx/73xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3 (on PB10/PB11)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in alternate push-pull, pull-down mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-down mode. Set as input until USART3 is detected on the BL version 0x93.
USART3 (on PD8/PD9)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PD9 pin: USART3 in reception mode. Used in alternate push-pull, pull-down mode.
	USART3_TX pin	Output	PD8 pin: USART3 in transmission mode. Used in alternate push-pull, pull-down mode. Set as input until USART3 is detected on the BL version 0x93.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1011100x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB9 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1011100x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin		PF0 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1011100x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin		PC9 pin: data line is used in open-drain no pull mode.

Table 143. STM32H72xxx/73xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, no pull mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, no pull mode.
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, no pull mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, no pull mode.
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data input line, used in push-pull no pull mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, no pull mode.
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, no pull mode.
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, no pull mode.
SPI4	SPI4	Enabled	The SPI4 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode.
	SPI4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-dpwn mode.
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-up mode. Note: This IO can be tied to GND if the SPI master does not use it.

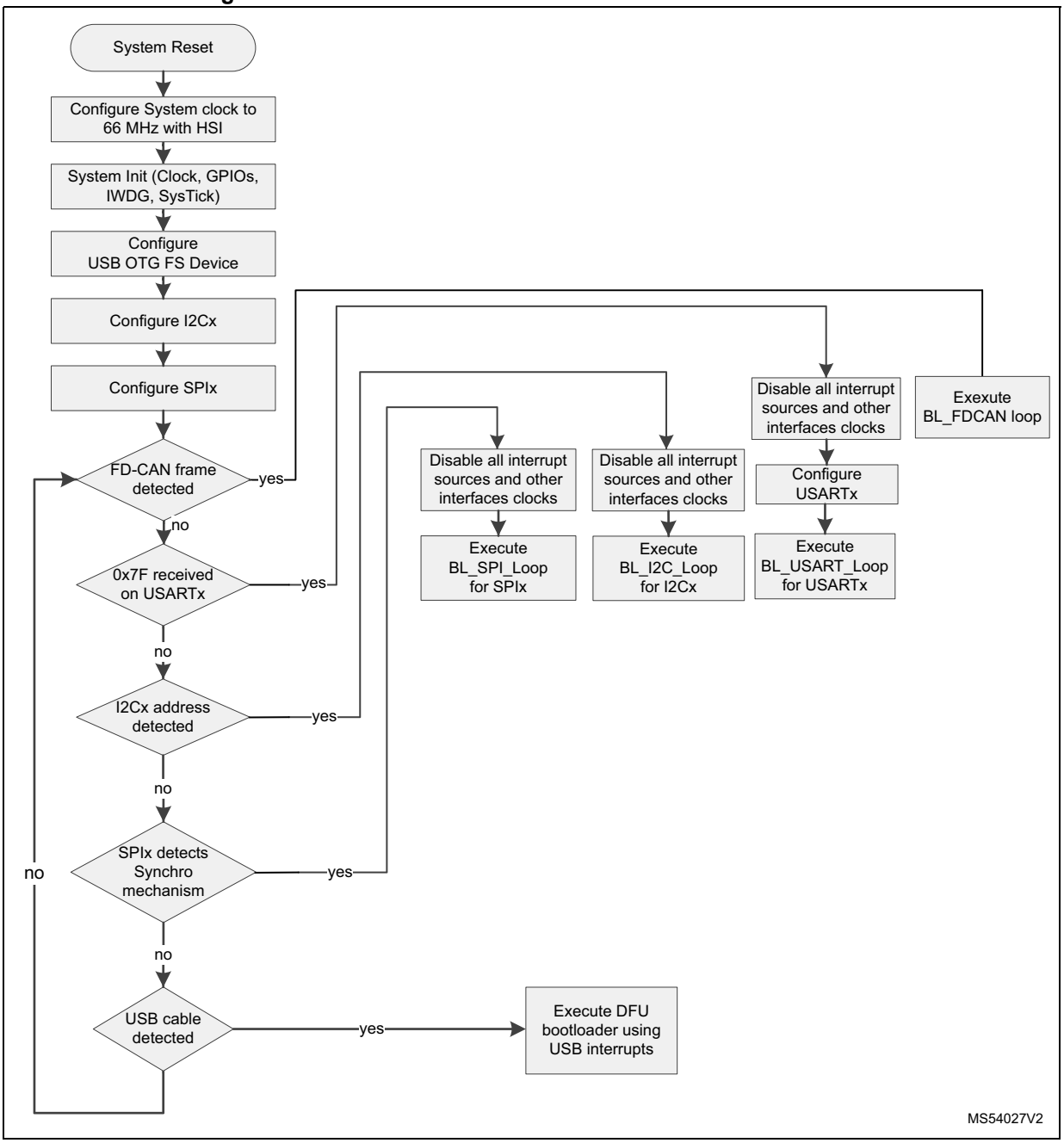
Table 143. STM32H72xxx/73xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
FDCAN (on PH13/PH14)	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: Connection bit rate 250 kbit/s Data bit rate 1000 kbit/s FrameFormat = FDCAN_FRAME_FD_BRS Mode = FDCAN_MODE_NORMAL AutoRetransmission = ENABLE TransmitPause = DISABLE ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PH14 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-down mode.
	FDCAN1_Tx pin	Output	PH13 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-down mode.
FDCAN (on PD1/PD0)	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: Connection bit rate 250 kbit/s Data bit rate 1000 kbit/s FrameFormat = FDCAN_FRAME_FD_BRS Mode = FDCAN_MODE_NORMAL AutoRetransmission = ENABLE TransmitPause = DISABLE ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PD0 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-down mode.
	FDCAN1_Tx pin	Output	PD1 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-down mode.

62.2 Bootloader selection

Figure 79 shows the bootloader selection mechanism.

Figure 79. Bootloader V9.0 selection for STM32H72xxx/73xxx



62.3 Bootloader version

Table 144 lists the STM32H72xxx/73xxx devices bootloader versions.

Table 144. STM32H72xxx/73xxx bootloader version

Version number	Description	Known limitations
V9.1	Initial bootloader version	– TCM_AXI OB cannot be modified using all BL interfaces – String returned describing the memory size when using USB is wrong
V9.2	Fix all issues of previous release	– Crash loop when booting on the BL, setting RDP to Level1, doing a reset or power on/off and the USB cable is plugged. – BL is not working in RDP Level1 when TCM_AXI_SHARED option byte is not “0”. Value of this OB must be set to “0” before going to RDP L1. – Bootloader SW is writing to the PWR_CR3 register using 4 bytes, which is locking this register. Only Power off/on will unlock it.
V9.3	– Fix all issues of previous release. – Modify USART TX from push pull mode in the previous versions to input.	None

63 STM32H74xxx/75xxx devices

63.1 Bootloader configuration

The STM32H74xxx/75xxx bootloader is activated by applying Pattern 10 (described in *Table 2*). *Table 145* shows the hardware resources used by this bootloader.

Table 145. STM32H74xxx/75xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 64 MHz using the HSI. The HSI clock source is used at startup (interface detection phase) and when USART or SPI or I2C interface is selected.
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz
		-	Clock used for the FDCAN is fixed to 20 MHz and is derived from PLLQ
	RAM	-	16 Kbytes, starting from address 0x20000000, and 208 Kbytes (reduced to 20 Kbytes in V9.1 version) starting from address 0x24000000, are used by the bootloader firmware
	System memory	-	122 Kbytes, starting from address 0x1FF00000 contain the bootloader firmware. The bootloader start address is 0x1FF09800.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage is set to Range 3. Bootloader software writes to the PWR_CR3 register using 4 bytes, which locks this register. Only Power off/on unlocks it. This is fixed on the bootloader with 0x91 version.
USART1 (on PA9/PA10)	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode. Set as input until USART1 is detected on the bootloader version 0x91.
USART1 (on PB14/PB15)	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PB15 pin: USART1 in reception mode.Used in input pull-up mode.
	USART1_TX pin	Output	PB14 pin: USART1 in transmission mode. Used in alternate function push pull pull-up mode.

Table 145. STM32H74xxx/75xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, no pull mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode. Set as input until USART3 is detected on the bootloader version 0x91.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode. Set as input until USART3 is detected on the bootloader version 0x91.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b1001110x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b1001110x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b1001110x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.

Table 145. STM32H74xxx/75xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, no pull mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, no pull mode.
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, no pull mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, no pull mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PI3 pin: slave data input line, used in push-pull, no pull mode.
	SPI2_MISO pin	Output	PI2 pin: slave data output line, used in push-pull, no pull mode.
	SPI2_SCK pin	Input	PI1 pin: slave clock line, used in push-pull, no pull mode.
	SPI2_NSS pin	Input	PI0 pin: slave chip select pin used in push-pull, no pull mode.
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data input line, used in push-pull, no pull mode.
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, no pull mode.
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, no pull mode.
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, no pull mode.

Table 145. STM32H74xxx/75xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI4	SPI4	Enabled	The SPI4 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data input line, used in push-pull, no pull mode.
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, no pull mode.
	SPI4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, no pull mode.
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, no pull mode.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
FDCAN	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PH14 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	FDCAN1_Tx pin	Output	PH13 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-up mode.

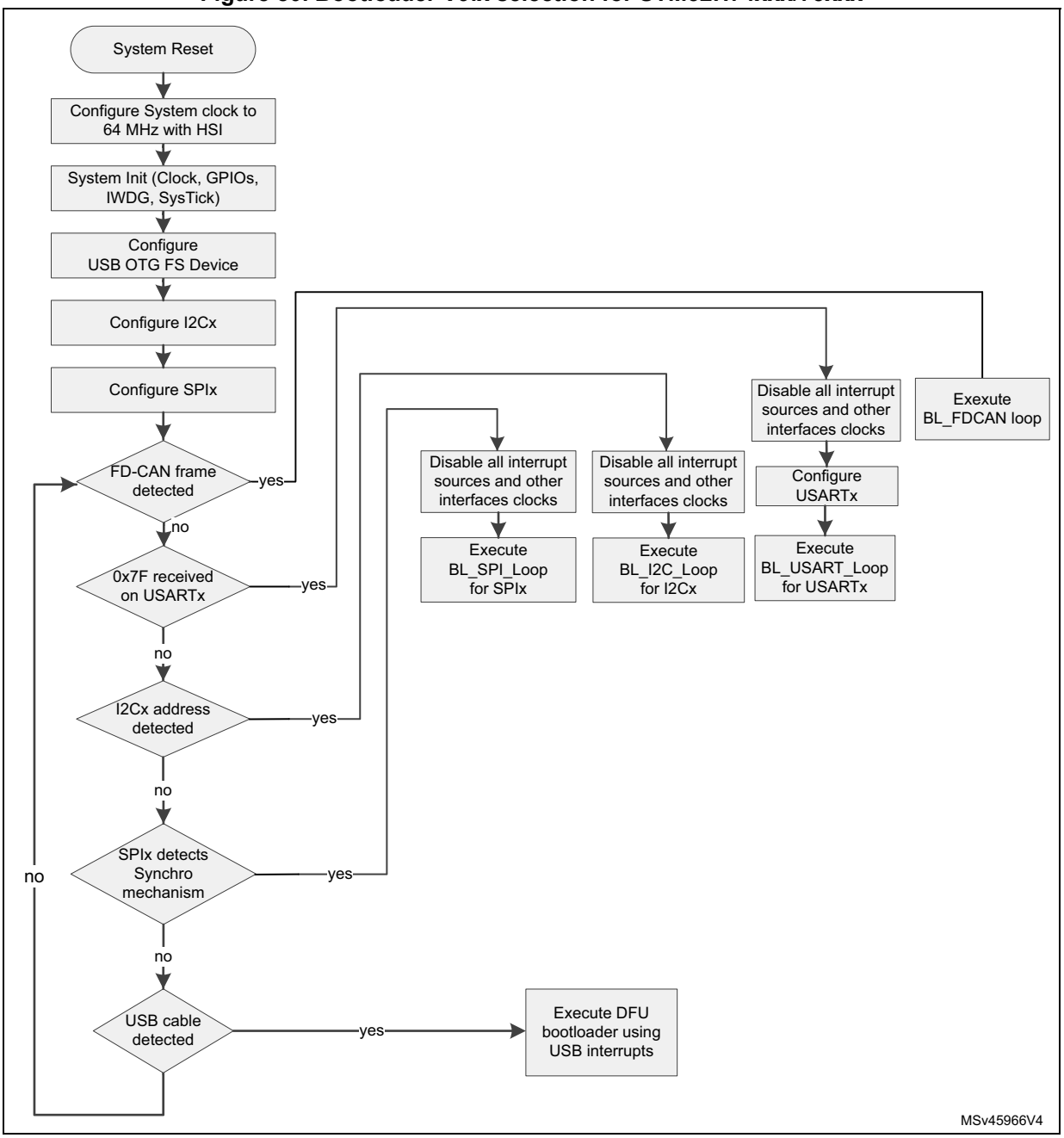
Note: To connect to the bootloader USART1 using PB14/PB15 pins, user must send two synchronization bytes. Baudrate is limited to 115200.

DFU mode does not support USBREGEN mode. If STM32 is powered by an 1.8 V source, it is not possible to use the BL DFU unless 3.3 V is provided

63.2 Bootloader selection

Figure 80 shows the bootloader selection mechanism.

Figure 80. Bootloader V9.x selection for STM32H74xxx/75xxx



63.3 Bootloader version

Table 146 lists the STM32H74xxx/75xxx devices bootloader versions.

Table 146. STM32H74xxx/75xxx bootloader version

Version number	Description	Known limitations
V13.2 (0xD2)	Initial bootloader version	– Go command is not working – USART2 connection is not working – SPI1 connection is not working – Mass erase does not work correctly on I2C (only Bank2 is erased in this command)
V13.3 (0xD3)	– Switch USB clock input from HSE to HSI48 with CRS – Fix known limitations on the V13.2	– Bank erase is not working on USART/SPI and I2C – DFU mass-erase not working
V9.0 (0x90)	– Add support of FDCAN interface – Fix V13.3 limitations – V9.0 is the latest version in production and replaces V13.2 and V13.3	– First ACK not received on Go command when using USART or SPI – On the FDCAN write memory, write of data with length > 63 bytes fails – If PB15 is set to GND, user cannot connect to BL interfaces. Only the USB is able to connect as it uses interrupt for detection. PB15 must not be pulled down if USART1 on PB14/PB15 is not used – Jump issue on some application.Application stack pointer must be lower than (RAM end @ - 16 bytes) to guarantee it is working – Additional reset needed after power off/on to enable connection to the BL interfaces. As a workaround user can add a pull up on PA11 pin.’ – Cannot program the "CM4_BOOT_ADDx" option byte using BL in dual core case – FDCAN Get version command is giving a bad FDCAN protocol version (0x11). It must be 0 x10 (V1.0) – SRAM1/SRAM2/SRAM3 (0x30000000-0x30047FFF) and ITCM memories not accessible by the BL – Number of supported commands is wrong (13 instead of 11)

Table 146. STM32H74xxx/75xxx bootloader version (continued)

Version number	Description	Known limitations
V9.1 (0x91)	Fix V9.0 limitations – Fix the configuration of PWR control register CR3. Bootloader is no more blocking the change of PWR source – Adjust USB, I^2C erase and program timings and fix them – Fix FDCAN version from V1.0 to V1.1 – Fix write issue when using FDCAN – Fix missing PCROP disable in RDP level1 regression – Update option byte support to handle all possible use cases	If PB15 is set to GND, user cannot connect to BL interfaces SRAM1/SRAM2/SRAM3 (0x30000000 to 0x30047FFF) and ITCM memories not accessible by the BL Jump issue on some applications. Application stack pointer must be lower than (RAM end address - 16 bytes) to guarantee it is working Erase on bank2 not working as expected – Root cause: check bad busy value while erasing on bank2. – Behavior: when erase on bank2 is requested, SW exits while the operation is ongoing. Sending a new command invoking the flash memory after the erase can hang the system. – Workaround: worst case erase timing from the product datasheet can be added after the erase command to allow the FLITF to complete the erase. A safer method is to use a RAM patch for the erase command. Same data are output on the USART1_TX PB14 when using USART1 on PA10/PA9. – Root cause: both USART1 TX pins PA9 and PB14 configured as alternate push pull-up and PB15/PB14 pins not disabled when PA10/PA9 set used by the customer. – Behavior: same data are output on USART1 TX pins PA9 and PB14. – **Caution**: take care to what PB14 is connected on your design to not damage it when using USART1 on PA10/PA9. Same data are output on the USART1_TX PA9 when using USART1 on PB15/PB14. – Root cause: both USART1 TX pins PB14 and PA9 configured as alternate push pull-up and PA10/PA9 pins not disabled when PB15/PB14 set used by the customer. – Behavior: same data are output on USART1 TX pins PA9 and PB14. – **Caution**: take care to what PA9 is connected on your design to not damage it when using USART1 on PB15/14.

Table 146. STM32H74xxx/75xxx bootloader version (continued)

Version number	Description	Known limitations
V9.2 (0x92)	Fix V9.1 limitations: – Same data on PA9 when USART1 is used on PB15/PB14. – Same data on PB14 when USART1 is used on PA10/PA9. – Erase on bank2 not working as expected. Enhancements: – Erase timeouts increased	– If PB15 is set to GND, user cannot connect to BL interfaces. – SRAM1/SRAM2/SRAM3 (0x30000000 to 0x30047FFF) and ITCM memories not accessible by the BL. – Jump issue on some applications. Application stack pointer must be lower than (RAM end address - 16 bytes) to guarantee it is working.

64 STM32H7A3xx/7B3xx/7B0xx devices

64.1 Bootloader configuration

The STM32H7A3xx/7B3xx/7B0xx bootloader is activated by applying Pattern 10 (described in *Table 2*). *Table 147* shows the hardware resources used by this bootloader.

Table 147. STM32H7A3xx/7B3xx/7B0xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 64 MHz using the HSI.
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz
		-	Clock used for the FDCAN is fixed to 20 MHz and is derived from PLLQ
	RAM	-	16 Kbytes, starting from address 0x24000000, are used by the bootloader firmware
	System memory	-	128 Kbytes, starting from address 0x1FF00000 contain the bootloader firmware. The bootloader start address is 0x1FF0A000
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Bootloader software writes to PWR_CR3 register using four bytes, which locks it, only Power off/on unlocks it. Fixed on the bootloader with 0x92 versions.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode. Set as input until USART1 is detected on the bootloader version 0x92.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode. Set as input until USART2 is detected on the bootloader version 0x92.

Table 147. STM32H7A3xx/7B3xx/7B0xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3 on (PB10/PB11)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in alternate push-pull, pull-down mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-down mode. Set as input until USART3 is detected on the bootloader version 0x92.
USART3 on (PD8/PD9)	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PD9 pin: USART3 in reception mode. Used in alternate push-pull, pull-down mode.
	USART3_TX pin	Output	PD8 pin: USART3 in transmission mode. Used in alternate push-pull, pull-down mode. Set as input until USART3 is detected on the bootloader version 0x92.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b10101111x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b10101111x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b10101111x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.

Table 147. STM32H7A3xx/7B3xx/7B0xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, no pull-up no pull-down mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, no pull-up no pull-down mode.
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull no pull-up, no pull-up no pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PI3 pin: slave data input line, used in push-pull, no pull mode.
	SPI2_MISO pin	Output	PI2 pin: slave data output line, used in push-pull, no pull mode.
	SPI2_SCK pin	Input	PI1 pin: slave clock line, used in push-pull, no pull mode.
	SPI2_NSS pin	Input	PI0 pin: slave chip select pin used in push-pull, no pull mode.
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data input line, used in push-pull, no pull mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, no pull mode.
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, no pull mode.
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, no pull mode.

Table 147. STM32H7A3xx/7B3xx/7B0xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI4	SPI4	Enabled	The SPI4 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data input line, used in push-pull, no pull up, no pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, no pull up, no pull-down mode.
	SPI4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, no pull up, no pull-down mode.
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, no pull up, no pull-down mode.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.
FDCAN on (PH13/PH14)	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: Connection bit rate 250 kbit/s Data bit rate 1000 kbit/s FrameFormat = FDCAN_FRAME_FD_BRS Mode = FDCAN_MODE_NORMAL AutoRetransmission = ENABLE TransmitPause = DISABLE ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PH14 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-down mode.
	FDCAN1_Tx pin	Output	PH13 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-down mode.

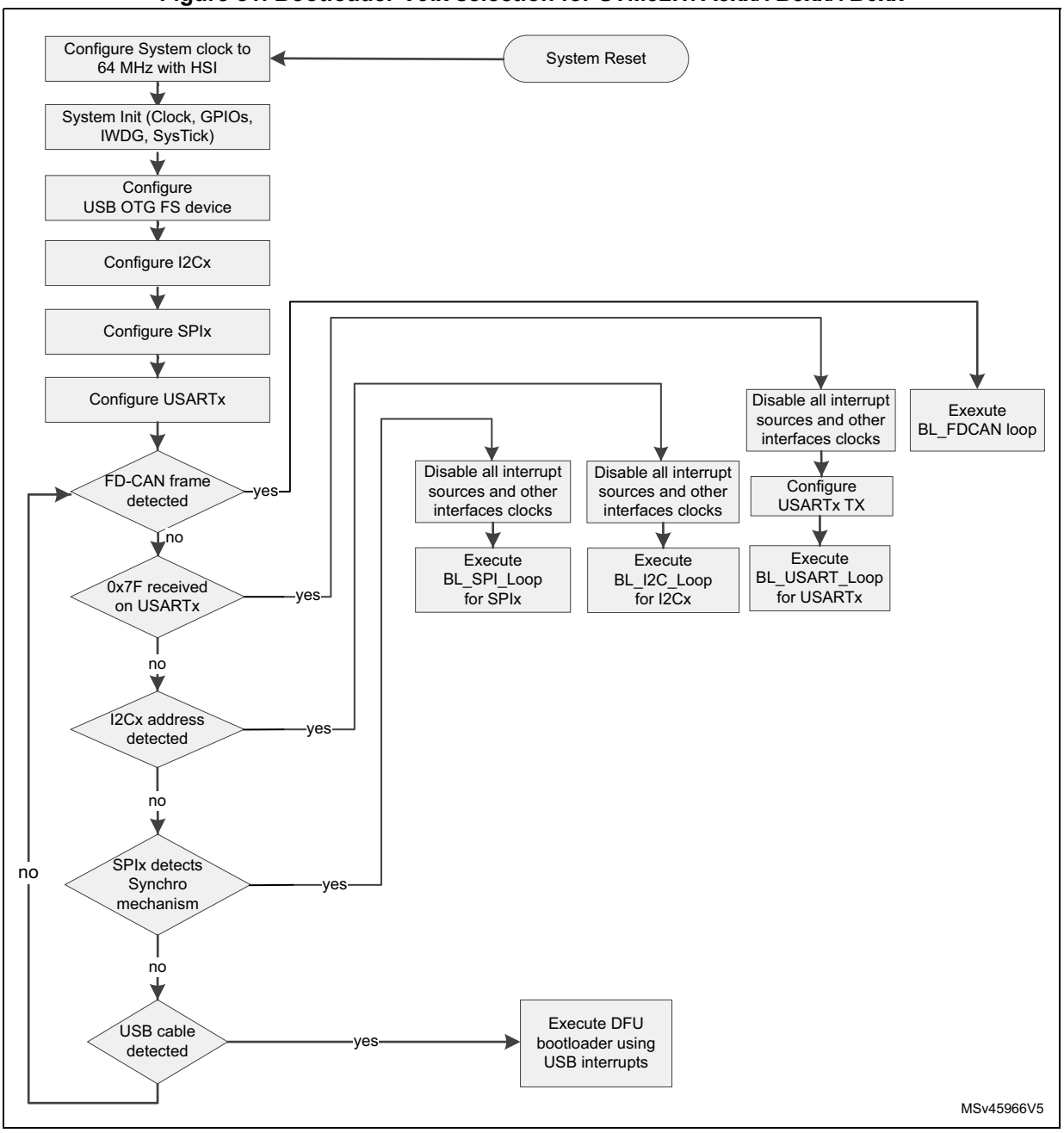
Table 147. STM32H7A3xx/7B3xx/7B0xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
FDCAN on (PD1/PD0)	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: Connection bit rate 250 kbit/s Data bit rate 1000 kbit/s FrameFormat = FDCAN_FRAME_FD_BRS Mode = FDCAN_MODE_NORMAL AutoRetransmission = ENABLE TransmitPause = DISABLE ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PD0 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-down mode.
	FDCAN1_Tx pin	Output	PD1 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-down mode.

64.2 Bootloader selection

Figure 80 shows the bootloader selection mechanism.

Figure 81. Bootloader V9.x selection for STM32H7A3xx/7B3xx/7B0xx



64.3 Bootloader version

Table 148 lists the STM32H7A3xx/7B3xx/7B0xx devices bootloader versions.

Table 148. STM32H7A3xx/7B3xx/7B0xx bootloader version

Version number	Description	Known limitations
V9.0	Initial bootloader version	– String returned describing the flash memory size when using USB is wrong (expected value 256 x 8 KB, but returns 256 x 2 KB) – OTP memory is not supported by the bootloader
V9.1	Fixes all issues of previous release.	– Crash loop when booting on the bootloader, setting RDP to Level1, doing a reset or power on/off and the USB cable is plugged. – Bootloader software is writing to the PWR_CR3 register using four bytes, which is locking this register. Only Power off/on unlocks it
V9.2	– Fix all issues of previous release – Modify USART TX from push pull mode in the previous versions to input.	None

65 STM32H7Rxxx/7Sxxx devices

65.1 Bootloader configuration

The STM32H7Rxxx/7S7xxx bootloader is activated by applying Pattern 17 (described in *Table 2*). *Table 149* shows the hardware resources used by this bootloader.

Table 149. STM32H7Rxxx/7Sxxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 380 MHz using the PLL clocked by HSI
		-	20 MHz derived from the PLLQ is used for FDCAN.
		HSI48 enabled	CRS is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz.
	RAM	-	16 Kbytes, starting from address 0x24020000, are used by the bootloader firmware
	System memory	-	32 Kbytes, starting from address 0x1FF18000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode. Set as input until USART1 is detected on the bootloader version 0x91.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, no pull mode. Used in alternate push-pull, no pull mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, no pull mode. Set as input until USART3 is detected on the bootloader version 0x91.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PD9 pin: USART3 in reception mode. Used in alternate push-pull, no pull mode.
	USART3_TX pin	Output	PD8 pin: USART3 in transmission mode. Set as input until USART3.

Table 149. STM32H7Rxxx/7Sxxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
UART4	UART4	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	UART4_RX pin	Input	PD0 pin: UART4 in reception mode. Used in alternate push-pull, no pull mode.
	UART4_TX pin	Output	PD1 pin: UART4 in transmission mode. Set as input until UART4 is detected.
I2C1[(1)]	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1100001x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB8 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain pull-up mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1100001x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin		PB11 pin: data line is used in open-drain pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1100001x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin		PC9 pin: data line is used in open-drain pull-up mode.

Table 149. STM32H7Rxxx/7Sxxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, no pull mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, no pull mode.
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, no pull mode.
	SPI1_NSS pin		PA4 pin: slave chip select pin used in push-pull, no pull mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, no pull mode.
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, no pull mode.
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, no pull mode.
	SPI2_NSS pin		PB12 pin: slave chip select pin used in push-pull, no pull mode.
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data input line, used in push-pull, no pull mode.
	SPI3_MISO pin	Output	PB4 pin: slave data output line, used in push-pull, no pull mode.
	SPI3_SCK pin	Input	PB3 pin: slave clock line, used in push-pull, no pull mode.
	SPI3_NSS pin		PA15 pin: slave chip select pin used in push-pull, no pull mode.

Table 149. STM32H7Rxxx/7Sxxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PM12: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PM11: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
FDCAN	FDCAN2	Enabled	Once initialized the FDCAN1 configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN2_Rx pin	Input	PB5 pin: FDCAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	FDCAN2_Tx pin	Output	PB1 pin: FDCAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I3C1[(1)]	I3C1	Enabled	– Mode: target mode – Aval timing:0x4E – DMA Reg RX: disabled – DMA Req TX: disabled – Status FIFO: disabled – DMA Req status: disabled – DMA Req control: disabled – IBI: Enabled – Additional data after IBI ACK-ed: 1 byte – IBI configuration: Mandatory Data Byte (MDB) – All IT disabled except RXFNE (Receive FIFO Interrupt). The RXFNE interruption is disabled after SYNC byte detection by the bootloader.
	I3C1_SCL pin	Input/output	PB8 pin: I3C1 in transmission mode. Used in alternate push-pull, no pull mode.
	I3C1_SDA pin		PB7 pin: I3C1 in transmission mode. Used in alternate push-pull, no pull mode.

1. I2C1 and I3C1 are exclusive: only one of them can be used, depending on the option byte FLASH_OBW2SR_I2C_NI3C.

Table 150. STM32H7Rxxx/7Sxxx special commands

Special commands supported (USART/I2C/SPI/FDCAN/USB/I3C) Based on Go/Read commands on virtual addresses			
Function	**Command**	**Virtual address**	**Data received**
Get Security State	Read	0xFF010001	4 bytes security status
Get product state		0xFF010002	
Data Provisioning	Go	0xFF83xxxx (xxxx indicates LSB address of the wrapper on the SRAM: 0x2404xxxx)	N/A
Change Product State		0xFF0100xx (xx indicates new product state value: 17 for provisioning, 72 for closed, and 5C for locked)	
Change Secure OB		0xFF02xxxx (xxxx indicates LSB address of the wrapper on the SRAM: 0x2404xxxx)(1)	

1. According to data written at address 0x2404xxxx, you can select option byte:
   0: secure option byte i-Rot Select
   1: secure option byte Writeprotection
   2: secure option byte writeunprotect
   3: secure option byte HDP.

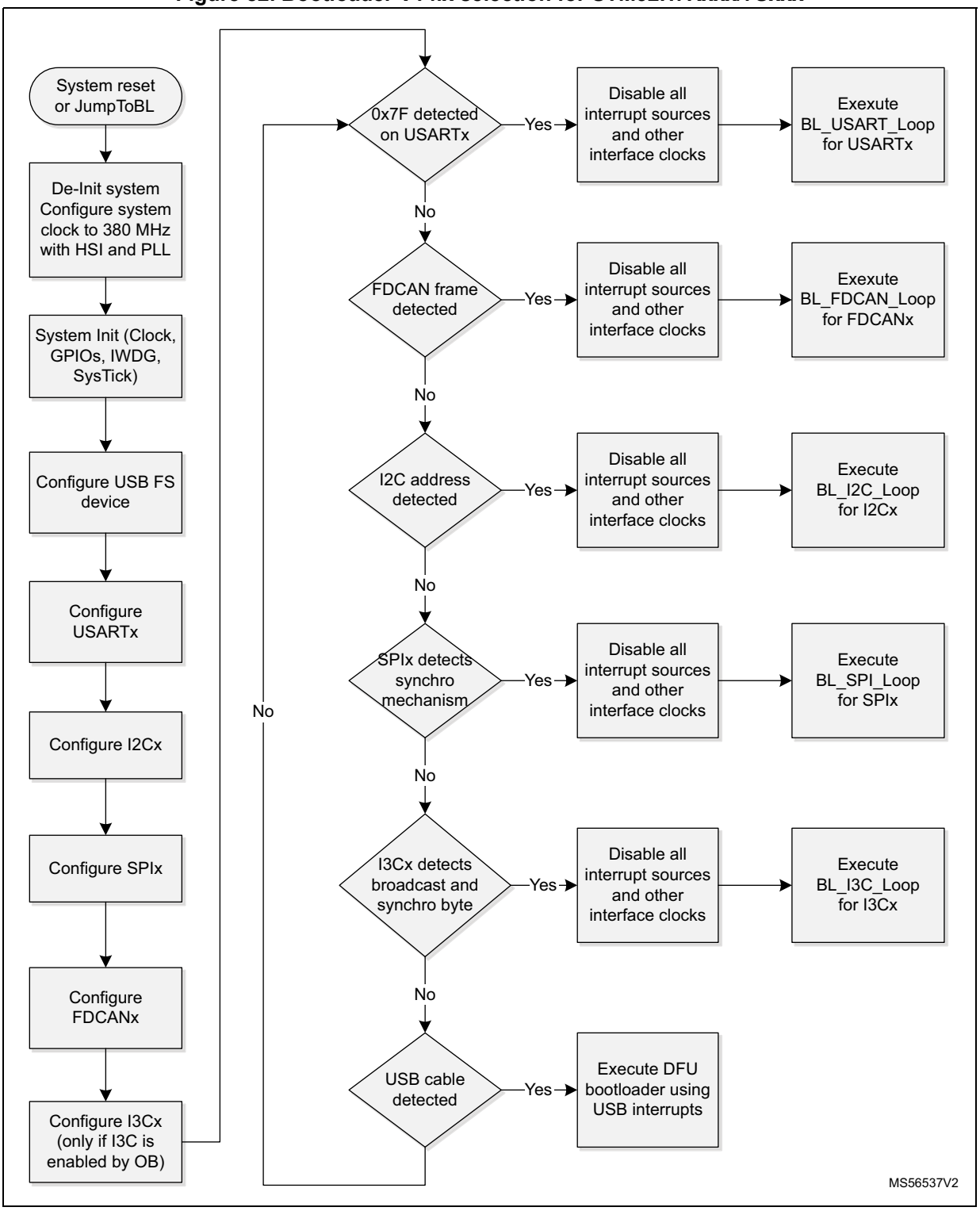
For secure option bytes i-Rot Select, Writeprotection or HDP start and HDP end, the register values will be at address (0x2404xxxx + 0x00000004).

Example: HDP options bytes:
write at 0x24040000 the value 0x00000003
write at 0x24040004 the value 0x00EE0011 (EE: HDPend, 11:HDPstart)
go at 0xFF020000.

65.2 Bootloader selection

Figure 80 shows the bootloader selection mechanism.

Figure 82. Bootloader V14.x selection for STM32H7Rxxx/7Sxxx



65.3 Bootloader version

Table 151 lists the STM32H7Rxxx/7Sxxx devices bootloader versions.

Table 151. STM32H7Rxxx/7Sxxx bootloader version

Version number	Description	Known limitations
V14.3	Initial bootloader version, used only for RevY	None
V14.4	Bootloader compatible with RevB	None
V14.5	Change on security descriptor located on 0x1FF1FD00 (256 bytes) to be aligned with latest SFSP release.	None

65.4 Jump to bootloader

If a user application jumping to the bootloader has the protection clock bits (xSPICKP or FMCCKP) enabled, the bootloader will be stuck/crash on the clock configuration.

The following fields cannot be modified when FMCCKP bit from RCC_CKPROT register is set to 1: PLL1ON, PLL2ON, PLL1QEN, PLL2REN, HSEON, HSION, CSION, FMCEN, FMCLPEN, and FMCRST.

The following fields cannot be modified when xSPICKP bit from RCC_CKPROTR register is set to 1: PLL2ON, PLL2SEN, PLL2TEN, HSEON, HSION, CSION, XSPIxEN, XSPIxLPEN, and XSPIxRST..

Refer to the section describing clock protection on RM0477.

At the startup; the bootloader deinitialises all the peripherals (including the clock), then reconfigures the clock based on PLL1 from HSI. In this case the bootloader is not be able to switch correctly to the needed default clock (crash or hang may be seen, depending on the application clock configuration)

Ensure that the protection clock bits (xSPICKP or FMCCKP) are disabled before jumping to the BL.

66 STM32H7P4xx/P5xx devices

66.1 Bootloader configuration

The STM32H7P4xx/P5xx bootloader is activated by applying Pattern 16 (described in *Table 2*). *Table 152* shows the hardware resources used by this bootloader.

Table 152. STM32H7P4xx/P5xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 360 MHz using the PLL clocked by HSI
		-	60 MHz derived from the PLLQ is used for FDCAN.
		HSI48 enabled	CRS is enabled for the DFU to allow USB to be clocked by HSI48 at 48 MHz.
	RAM	-	17 Kbytes, starting from address 0x2FFD0000, are used by the bootloader firmware
	System memory	-	40 Kbytes, starting from address 0x1FF10000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, no pull mode. Used in alternate push-pull, no pull mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.
UART4	UART4	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	UART4_RX pin	Input	PA1 pin: UART4 in reception mode. Used in alternate push-pull, pull-up mode.
	UART4_TX pin	Output	PA0 pin: UART4 in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.
UART5	UART5	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	UART5_RX pin	Input	PC14 pin: UART5 in reception mode. Used in alternate push-pull, pull-up mode.
	UART5_TX pin	Output	PC15 pin: UART5 in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.

Table 152. STM32H7P4xx/P5xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Slave mode – Analog filter ON – Slave 7-bit address: 0b1111001x, x = 0 for write and x = 1 for read
	I2C1_SCL pin	Input/output	PB5 pin: clock line is used in open-drain, no pull-up mode.
	I2C1_SDA pin		PB6 pin: data line is used in open-drain, no pull-up mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Slave mode – Analog filter ON – Slave 7-bit address: 0b1111001x, x = 0 for write and x = 1 for read
	I2C2_SCL pin	Input/output	PB4 pin: clock line is used in open-drain, no pull-up mode.
	I2C2_SDA pin		PB3 pin: data line is used in open-drain, no pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Slave mode – Analog filter ON – Slave 7-bit address: 0b1111001x, x = 0 for write and x = 1 for read
	I2C3_SCL pin	Input/output	PE5 pin: clock line is used in open-drain, no pull-up mode.
	I2C3_SDA pin		PE4 pin: data line is used in open-drain, no pull-up mode.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11 pin: not configured by the bootloader software, but assigned to the USB hardware once the block is initialized inside the bootloader.
	USB_DP pin		PM12 pin: not configured by the bootloader software, but assigned to the USB hardware once the block is initialized inside the bootloader.

Table 152. STM32H7P4xx/P5xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
FDCAN	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: – Connection bit rate 750 kbit/s – Data bit rate 3000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PA6 pin: FDCAN1 in reception mode. Used in alternate push-pull, no pull-up mode.
	FDCAN1_Tx pin	Output	PA7 pin: FDCAN1in transmission mode. Used in alternate push-pull, no pull-up mode.
I3C1	I3C1	Enabled	– Mode: target mode – Aval timing:0x5D – DMA Reg RX: disabled – DMA Req TX: disabled – Status FIFO: disabled – DMA Req status: disabled – DMA Req control: disabled – IBI: Enabled – Additional data after IBI ACK-ed: 1 byte – IBI configuration: Mandatory Data Byte (MDB) – All IT disabled except RXFNE (Receive FIFO Interrupt). The RXFNE interruption is disabled after SYNC byte detection by the bootloader.
	I3C1_SCL pin	Input/output	PI12 pin: configured in alternate push-pull mode with pull-up, then switched to no pull-up mode. The pin is used in all packages except LQFP64_SMPS. PA15 pin: configured in alternate push-pull mode with pull-up, then switched to no pull-up mode. The pin is used only on the LQFP64_SMPS package.
	I3C1_SDA pin		PB8 pin: configured in alternate push-pull mode with pull-up, then switched to no pull-up mode. The pin is used in all packages except LQFP64_SMPS. PB9 pin: configured in alternate push-pull mode with pull-up, then switched to no pull-up mode. The pin is used only on the LQFP64_SMPS package.

Table 153. STM32H7P4xx/P5xx special commands

Special commands supported (USART/I2C/FDCAN/USB/I3C) Based on Go/Read commands on virtual addresses			
Function	**Command**	**Virtual address**	**Data received**
Get Security State	Read	0xFF010001	4 bytes security status
Get product state		0xFF010002	
Data Provisioning	Go	0xFF83xxxx (xxxx indicates LSB address of the wrapper on the SRAM: 0x2FFExxxx)	N/A
Change Product State		0xFF0100xx (xx indicates new product state value: 17 for provisioning, 72 for closed, and 5C for locked)	
Change Secure OB		0xFF02xxxx (xxxx indicates LSB address of the wrapper on the SRAM: 0x2FFExxxx)(1)	

1. According to data written at address 0x2FFExxxx, you can select option byte:
   1: WPR bank1
   2: secure option byte writeunprotect bank1
   3: secure option byte HDP bank1
   4: WPR bank2
   5: secure option byte writeunprotect bank2
   6: secure option byte HDP bank2
   7:Bootlock

For secure option bytes Bootlock, Writeprotection or HDP start and HDP end, the register values are at address (0x2FFExxxx + 0x00000004).

Example: HDP options bytes in bank1:

write at 0x2FFE0000 the value 0x00000003

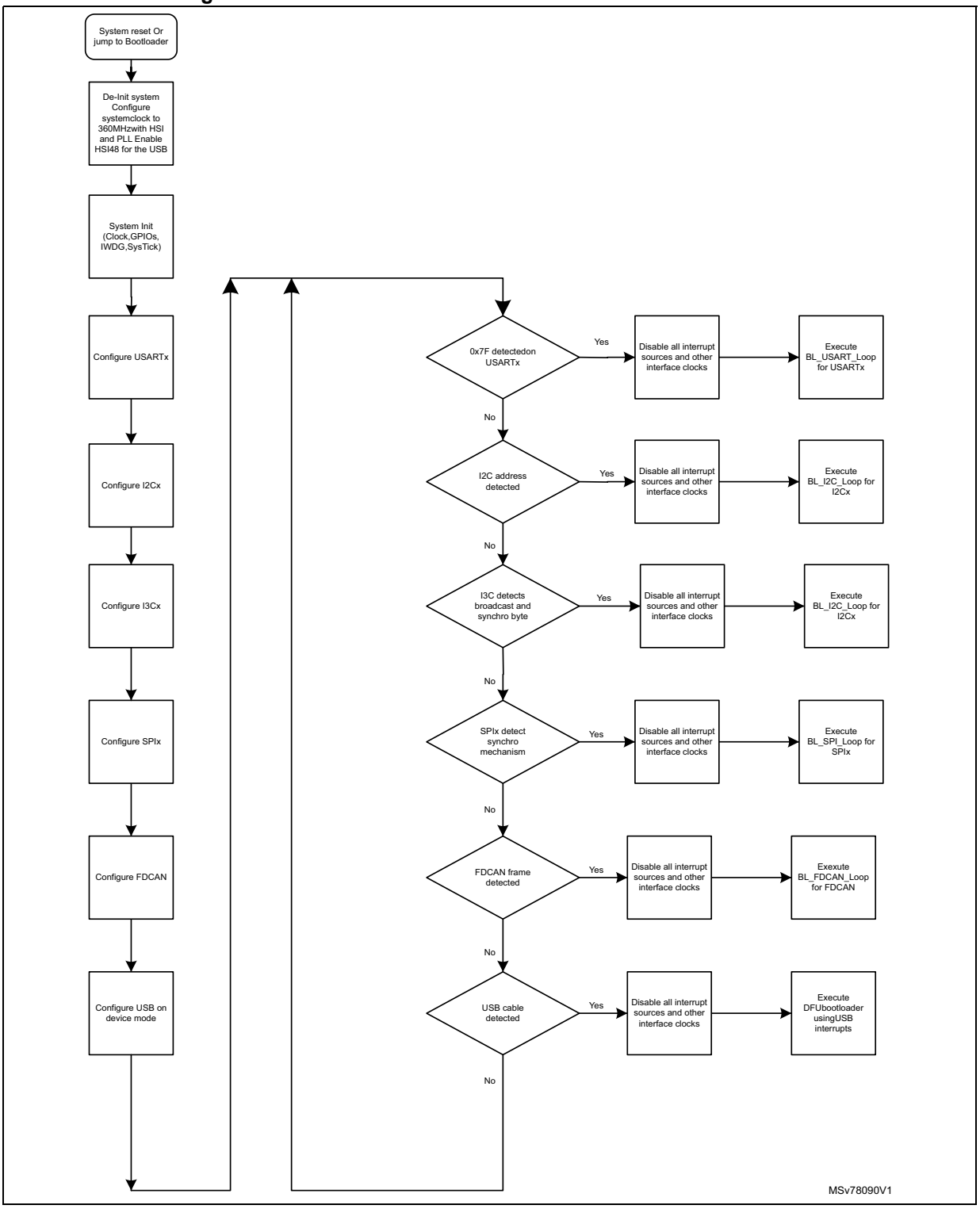
write at 0x2FFE0004 the value 0x00EE0011 (EE: HDPend, 11: HDPstart)

go at 0xFF020000

66.2 Bootloader selection

Figure 83 shows the bootloader selection mechanism.

Figure 83. Bootloader V20.x selection for STM32H7P4xx/P5xx



66.3 Bootloader version

Table 151 lists the STM32H7P4xx/P5xx devices bootloader versions.

Table 154. STM32H7P4xx/P5xx bootloader version

Version number	Description	Known limitations
V20.1	Initial bootloader version	None

67 STM32L01xxx/02xxx devices

67.1 Bootloader configuration

The STM32L01xxx/02xxx bootloader is activated by applying Pattern 6 (described in *Table 2*). *Table 155* shows the hardware resources used by this bootloader.

Table 155. STM32L01xxx/02xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 32 MHz with HSI 16 MHz as clock source.
	RAM	-	2 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	4 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART2 (on PA9/PA10)	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA10 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA9 pin: USART2 in transmission mode. Used in input pull-up
USART2 (on PA2/PA3)	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode.Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input pull-up mode.
USART2	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.

Table 155. STM32L01xxx/02xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1 (for all device packages except TSSOP14)	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. **Note:** This IO can be tied to GND if the SPI master does not use it.
SPI1 (only for devices on TSSOP14 package)	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA14 pin: slave data output line, used in push-pull, pull-down mode. **Note**: This IO is also used as SWCLK for debug interface, as a consequence debugger cannot connect to the device in "on-the-fly" mode when the bootloader is running.
	SPI1_SCK pin	Input	PA13 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. **Note:** NSS pin synchronization is required on bootloader with SPI1 interface for devices on TSSOP14 package.

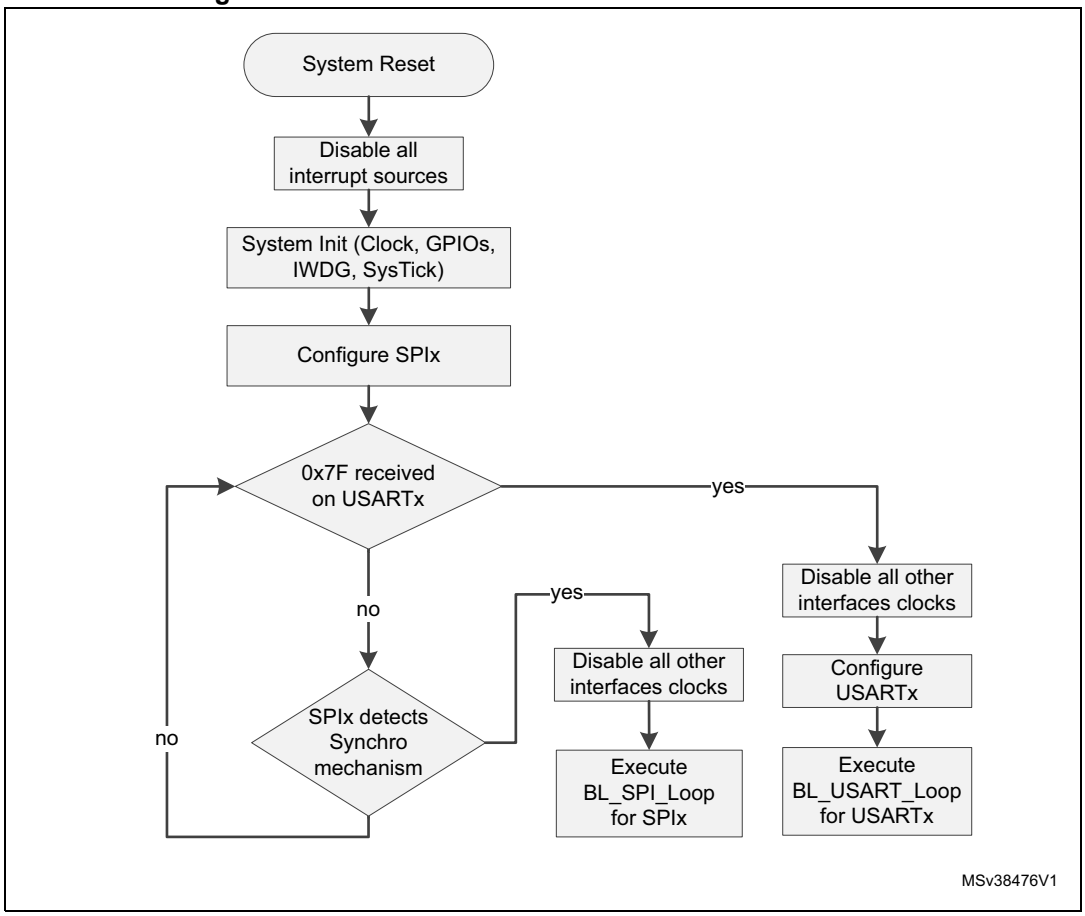
The system clock is derived from the embedded internal high-speed RC for all bootloader interfaces. No external quartz is required for bootloader operations.

Note: Due to empty check mechanism present on this product, it is not possible to jump from user code to system bootloader. Such jump results in a jump back to user flash memory space. But if the first 4 bytes of user flash memory (at 0x0800 0000) are empty at the moment of the jump (i.e. erase first sector before jump or execute code from SRAM while flash is empty), then system bootloader is executed when jumped to.

67.2 Bootloader selection

The *Table 84* shows the bootloader selection mechanism.

Figure 84. Bootloader selection for STM32L01xxx/02xxx



67.3 Bootloader version

The following table lists the STM32L01xxx/02xxx devices bootloader versions.

Table 156. STM32L01xxx/02xxx bootloader versions

Version number	Description	Known limitations
V12.2	Initial bootloader version	Bootloader not functional with SPI1 interface for devices on TSSOP14 package.
V12.3	Adds support of SPI interface for devices in TSSOP14 package.	For the SPI1 interface for devices in TSSOP14, a falling edge on NSS pin is required before staring communication, to properly synchronize the SPI interface. If the NSS pin is grounded (all time from device reset) the SPI communication is not synchronized and bootloader does not work properly with the SPI interface.

68 STM32L031xx/041xx devices

68.1 Bootloader configuration

The STM32L031xx/041xx bootloader is activated by applying Pattern 2 (described in *Table 2*). The following table shows the hardware resources used by this bootloader.

Table 157. STM32L031xx/041xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 32 MHz with HSI 16 MHz as clock source.
	RAM	-	4 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	4 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART2 (on PA9/PA10)	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA10 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA9 pin: USART2 in transmission mode. Used in input pull-up mode.
USART2 (on PA2/PA3)	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode.Used in input pull-up mode.
USART2	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.

Table 157. STM32L031xx/041xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. **Note:** This IO can be tied to GND if the SPI master does not use it.

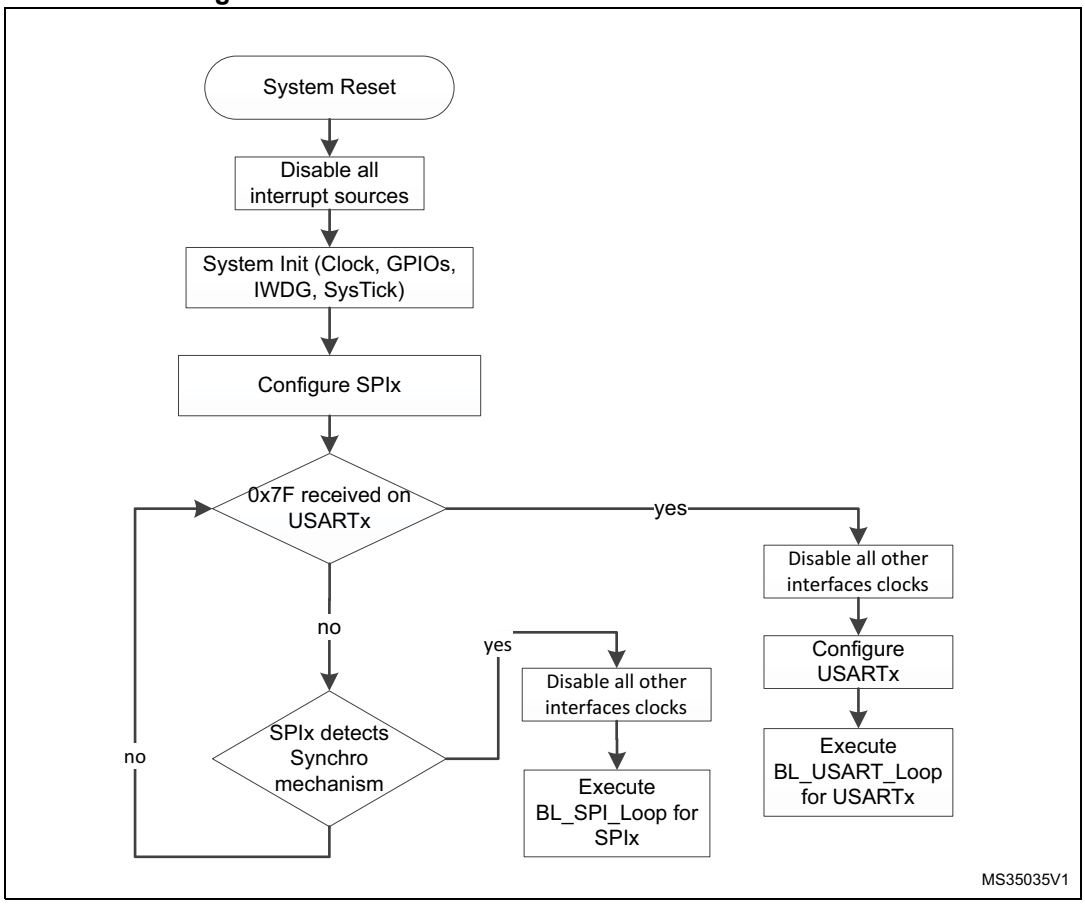
The system clock is derived from the embedded internal high-speed RC for all bootloader interfaces. No external quartz is required for bootloader operations.

The bootloader Read/Write commands do not support SRAM space for this product.

68.2 Bootloader selection

Figure 85 shows the bootloader selection mechanism.

Figure 85. Bootloader selection for STM32L031xx/041xx



68.3 Bootloader version

Table 158 lists the STM32L031xx/041xx devices bootloader versions.

Table 158. STM32L031xx/041xx bootloader versions

Version number	Description	Known limitations
V12.0	Initial bootloader version	None

69 STM32L05xxx/06xxx devices

69.1 Bootloader configuration

The STM32L05xxx/06xxx bootloader is activated by applying Pattern 1 (described in *Table 2*). *Table 159* shows the hardware resources used by this bootloader.

Table 159. STM32L05xxx/06xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 32 MHz with HSI 16 MHz as clock source.
	Power	-	Voltage range is set to Voltage Range 1.
	RAM	-	4 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	4 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.

Table 159. STM32L05xxx/06xxx configuration in system memory boot mode (continued)

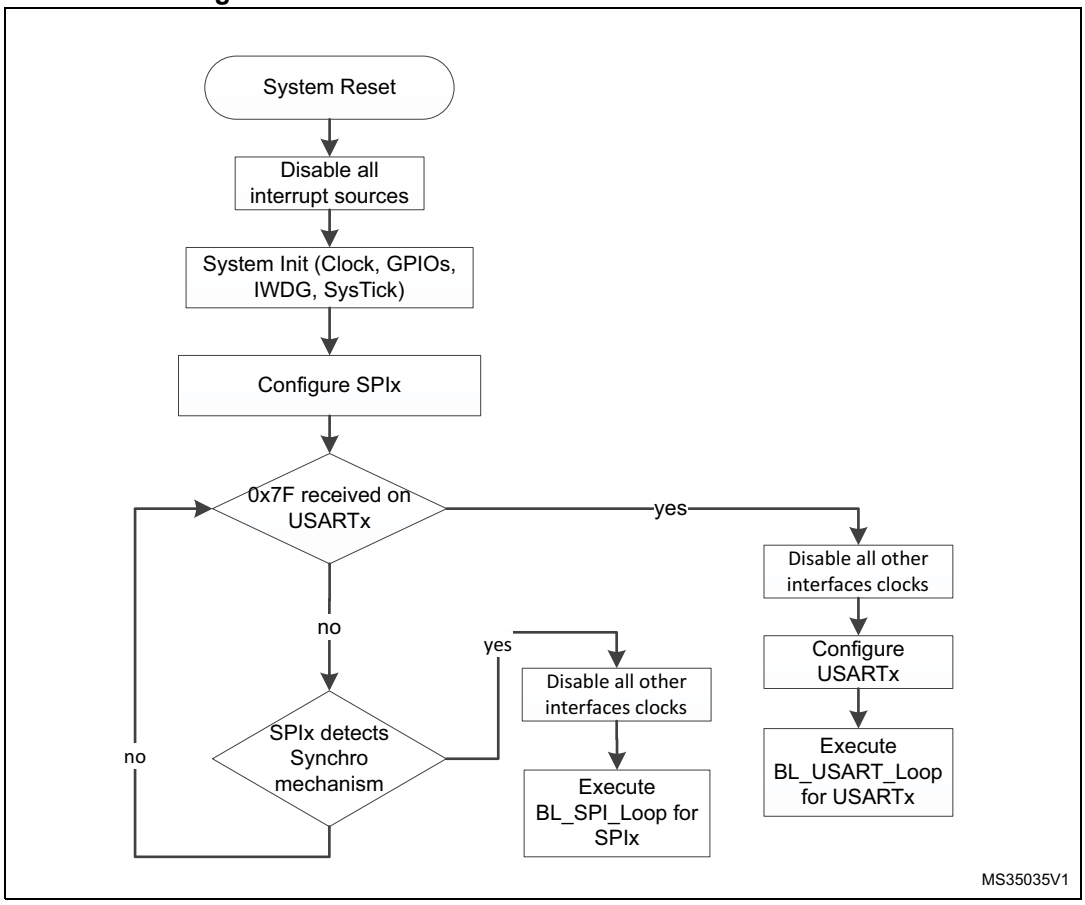
Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.

The system clock is derived from the embedded internal high-speed RC for all bootloader interfaces. No external quartz is required for bootloader operations.

69.2 Bootloader selection

Figure 86 shows the bootloader selection mechanism.

Figure 86. Bootloader selection for STM32L05xxx/06xxx



69.3 Bootloader version

Table 160 lists the STM32L05xxx/06xxx devices bootloader versions:

Table 160. STM32L05xxx/06xxx bootloader versions

Version number	Description	Known limitations
V12.0	Initial bootloader version	PA13 set in alternate push-pull, pull-up mode and PA14 set in alternate pull-up pull-down mode even if not used.

70 STM32L07xxx/08xxx devices

Two bootloader versions are available on STM32L07xxx/08xxx devices:

- V4.x supporting USART1, USART2 USART2, and DFU (USB FS device). This version is embedded in STM32L072xx/73xx and STM32L082xx/83xx devices.
- V11.x supporting USART1, USART2, I2C1, I2C2, SPI1 and SPI2. This version is embedded in other STM32L071xx/081xx devices.

70.1 Bootloader V4.x

70.1.1 Bootloader configuration

The STM32L07xxx/08xxx bootloader is activated by applying Pattern 2 or Pattern 7 when dual bank boot feature is available (described in *Table 2*). *Table 161* shows the hardware resources used by this bootloader.

Table 161. STM32L07xxx/08xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 32 MHz with HSI 16 MHz as clock source.
	RAM	-	4 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	8 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.

Table 161. STM32L07xxx/08xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11 pin: USB FS DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB FS DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.

The system clock is derived from the embedded internal high-speed RC for all bootloader interfaces. No external quartz is required for bootloader operations.

70.1.2 Bootloader selection

Figure 87 and *Figure 88* show the bootloader selection mechanism.

Figure 87. Dual bank boot implementation for STM32L07xxx/08xxx bootloader V4.x

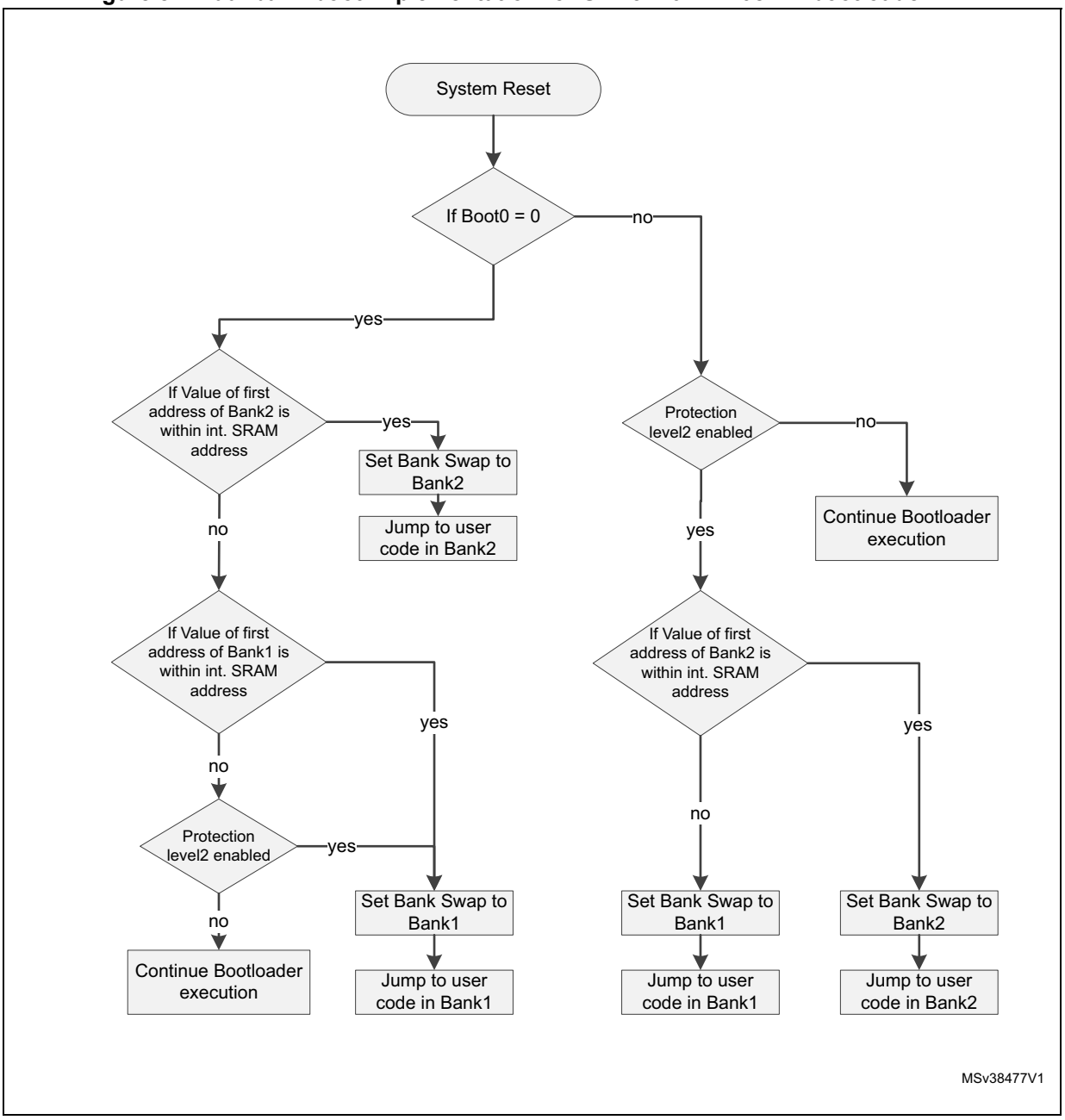
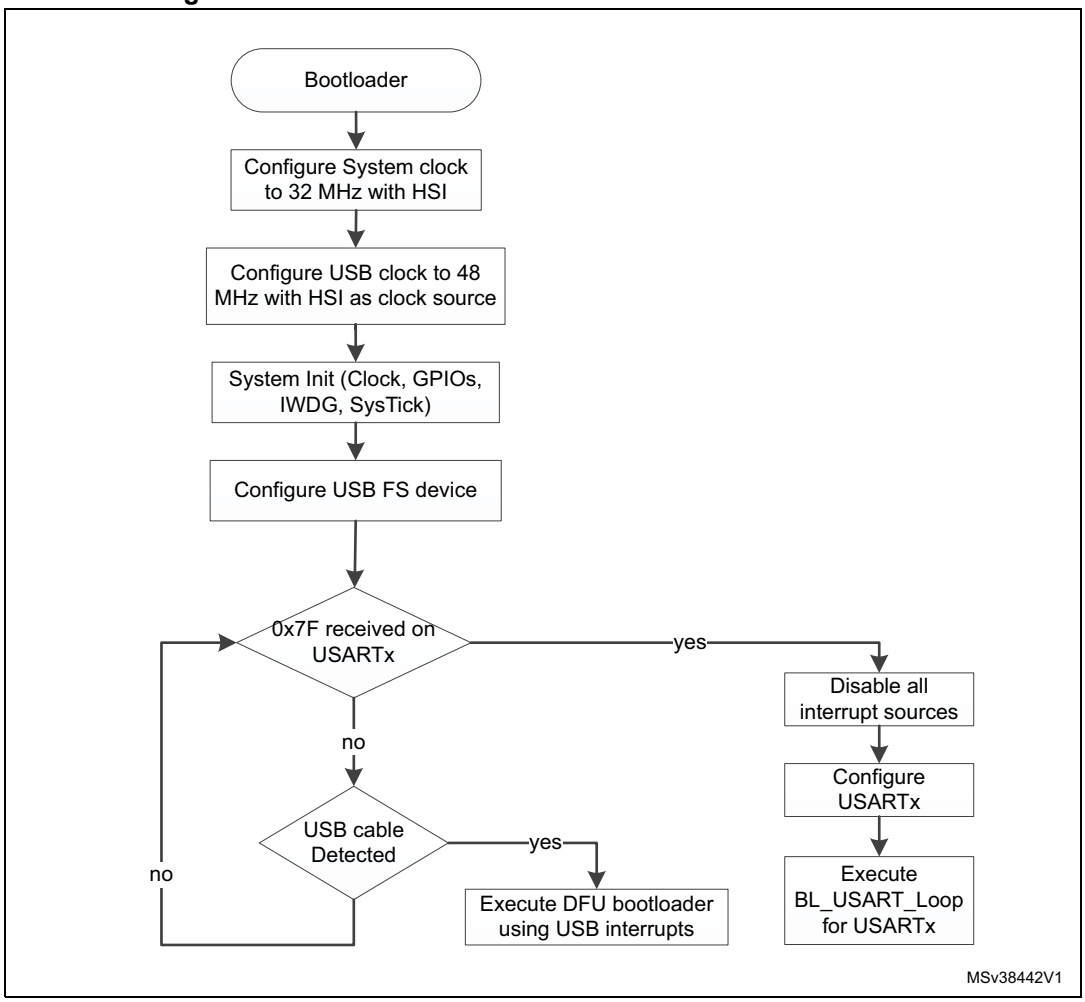


Figure 88. Bootloader V4.x selection for STM32L07xxx/08xxx



70.1.3 Bootloader version

Table 162 lists the STM32L07xxx/08xxx devices bootloader versions.

Table 162. STM32L07xxx/08xxx bootloader versions

Version number	Description	Known limitations
V4.0	Initial bootloader version	PA4, PA5, PA6 and PA7 IOs are configured in pull-down mode despite not used by bootloader
V4.1	This new version implements the Dual Bank Boot feature.	– PA4, PA5, PA6 and PA7 IOs are configured in pull-down mode despite not used by bootloader – The USB bootloader fails on some machines using a high speed controller. The bootloader is detected. but then data transaction fails. Root causes: De-synchronization between USB controller and bootloader SW due to the controller high speed transactions. Controller high speed inter-packet delay seems not sufficient for the bootloader SW (based on interrupt routines) to serve all needed transactions (the delay needed by the BL is nearly 25 µs). Some servicing IT are missed. This results in a communication fail, causing Write command to fail. Workarounds: Add an USB HUB between the host and the MCU. This relaxes transactions inter-packet delay, and allows the BL SW to perform correctly the task. Use USB controller/host that increase inter-packet delay. On new designs, use DFU SW that fix the issue in user flash memory.

70.2 Bootloader V11.x

70.2.1 Bootloader configuration

The STM32L07xxx/08xxx bootloader is activated by applying Pattern 2 or Pattern 7 when dual bank boot feature is available (see in *Table 2*). *Table 163* shows the hardware resources used by this bootloader.

Table 163. STM32L07xxx/08xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 32 MHz with HSI 16 MHz as clock source.
	RAM	-	5 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b1000010x – (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: I2C1 clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: I2C1 data line is used in open-drain no pull mode.

Table 163. STM32L07xxx/08xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b1000010x – (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: I2C2 clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB11 pin: I2C2 data line is used in open-drain no pull mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. **Note**: This IO can be tied to GND if the SPI master does not use it.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. **Note**: This IO can be tied to GND if the SPI master does not use it.

The system clock is derived from the embedded internal high-speed RC for all bootloader interfaces. No external quartz is required for bootloader operations.

70.2.2 Bootloader selection

Figure 89 and *Figure 90* show the bootloader selection mechanism.

Figure 89. Dual bank boot implementation for STM32L07xxx/08xxx bootloader V11.x

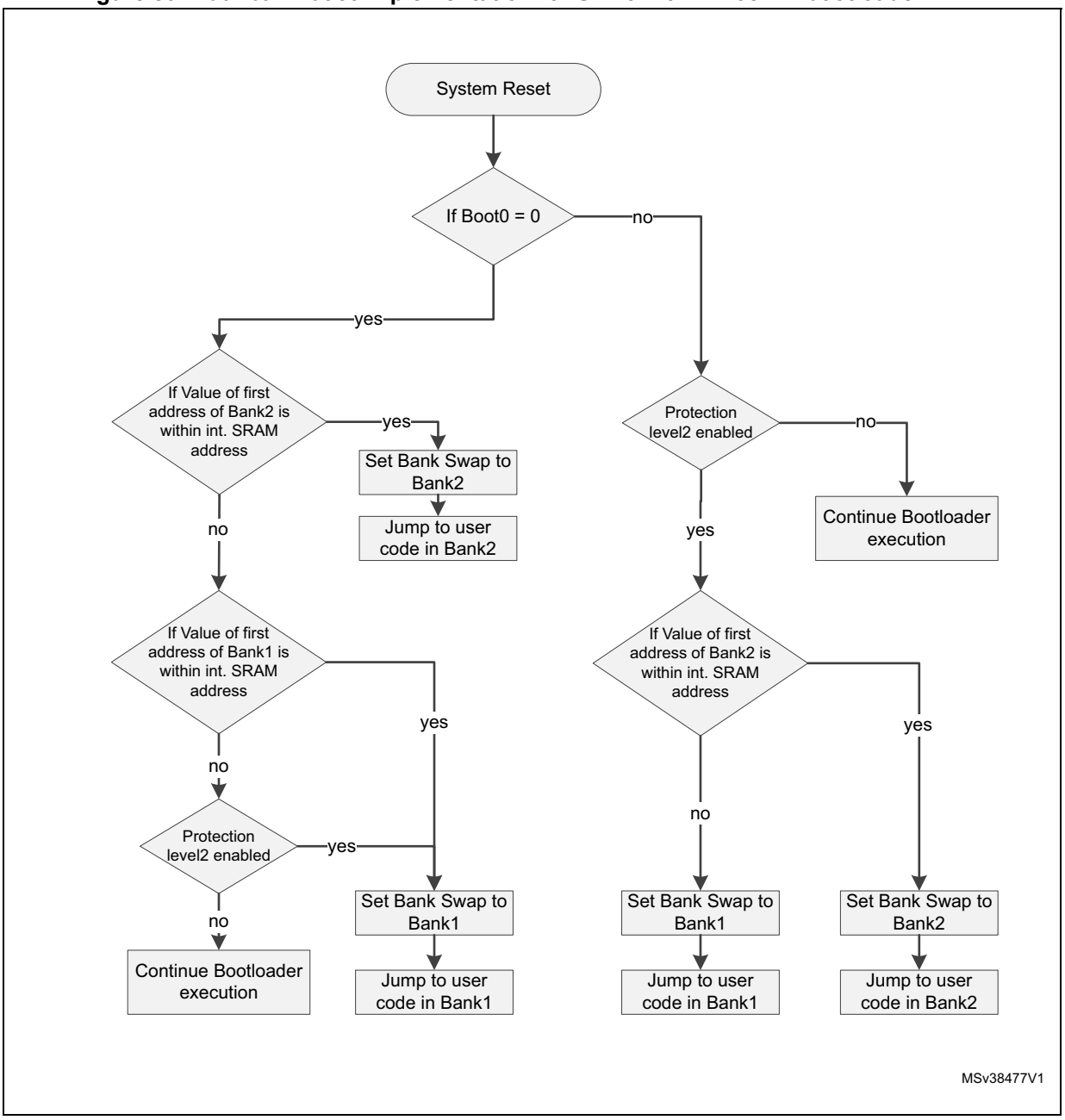
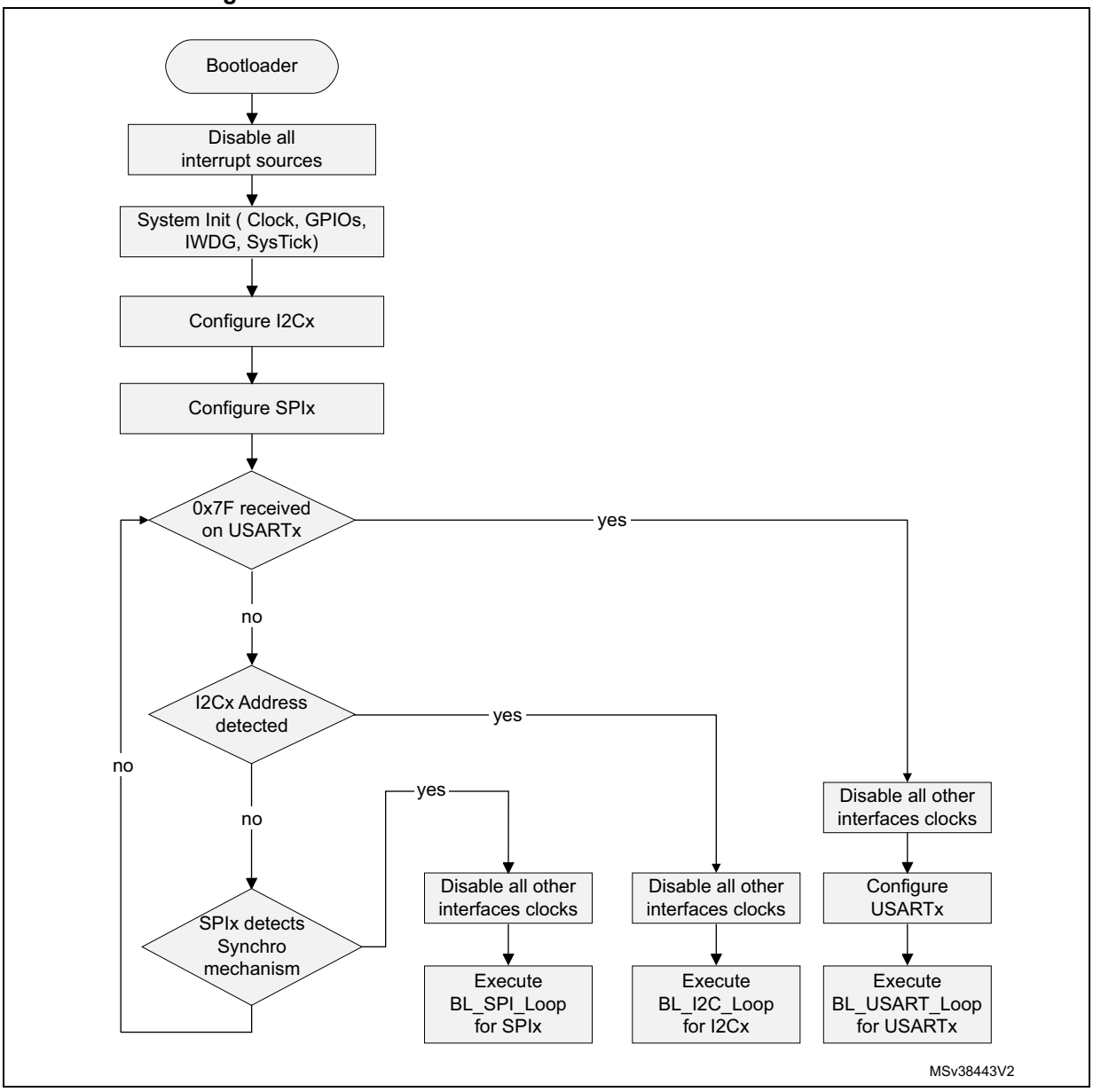


Figure 90. Bootloader V11.x selection for STM32L07xxx/08xxx



70.2.3 Bootloader version

Table 164 lists the STM32L07xxx/08xxx devices bootloader versions:

Table 164. STM32L07xxx/08xxx bootloader V11.x versions

Version number	Description	Known limitations
V11.1	Initial bootloader version	None
V11.2	This new version implements the Dual Bank Boot feature.	None

71 STM32L1xxx6(8/B)A devices

71.1 Bootloader configuration

The STM32L1xxx6(8/B)A bootloader is activated by applying Pattern 1 (described in *Table 2*). *Table 165* shows the hardware resources used by this bootloader.

Table 165. STM32L1xxx6(8/B)A configuration in system memory boot mode

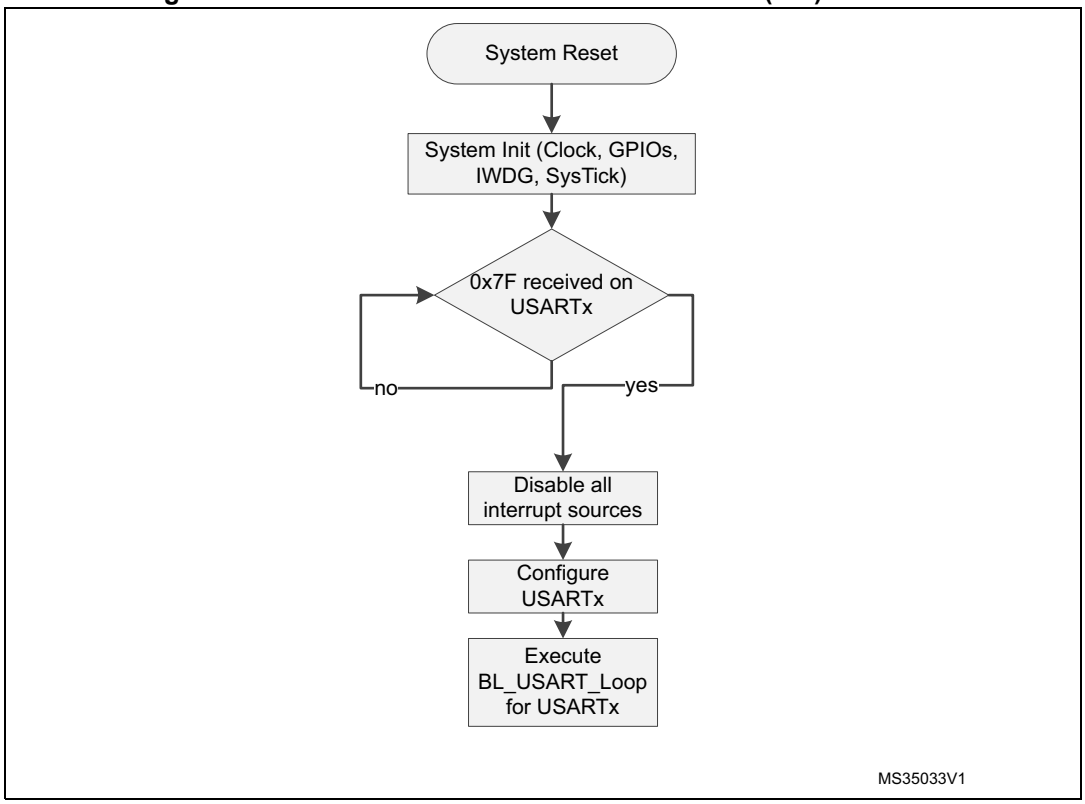
Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 16 MHz.
	RAM	-	2 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	4 Kbytes, starting from address 0x1FF00000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage is set to Voltage Range 1.
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.

The system clock is derived from the embedded internal high-speed RC, no external . No external quartz is required for the bootloader execution.

71.2 Bootloader selection

The figure below shows the bootloader selection mechanism.

Figure 91. Bootloader selection for STM32L1xxx6(8/B)A devices



71.3 Bootloader version

The following table lists the STM32L1xxx6(8/B)A devices bootloader versions:

Table 166. STM32L1xxx6(8/B)A bootloader versions

Version number	Description	Known limitations
V2.0	Initial bootloader version	When a Read Memory or Write Memory command is issued with an unsupported memory address and a correct address checksum (i.e. address 0x6000 0000), the command is aborted by the bootloader device, but the NACK (0x1F) is not sent to the host. As a result, the next two bytes (the number of bytes to be read/written and its checksum) are considered as a new command and its checksum.(1)

1. If the “number of data - 1” (N-1) to be read/written is not equal to a valid command code, the limitation is not perceived from the host, as the command is NACK-ed anyway (as an unsupported new command).

72 STM32L1xxx6(8/B) devices

72.1 Bootloader configuration

The STM32L1xxx6(8/B) bootloader is activated by applying Pattern 1 (described in *Table 2*). The following table shows the hardware resources used by this bootloader.

Table 167. STM32L1xxx6(8/B) configuration in system memory boot mode

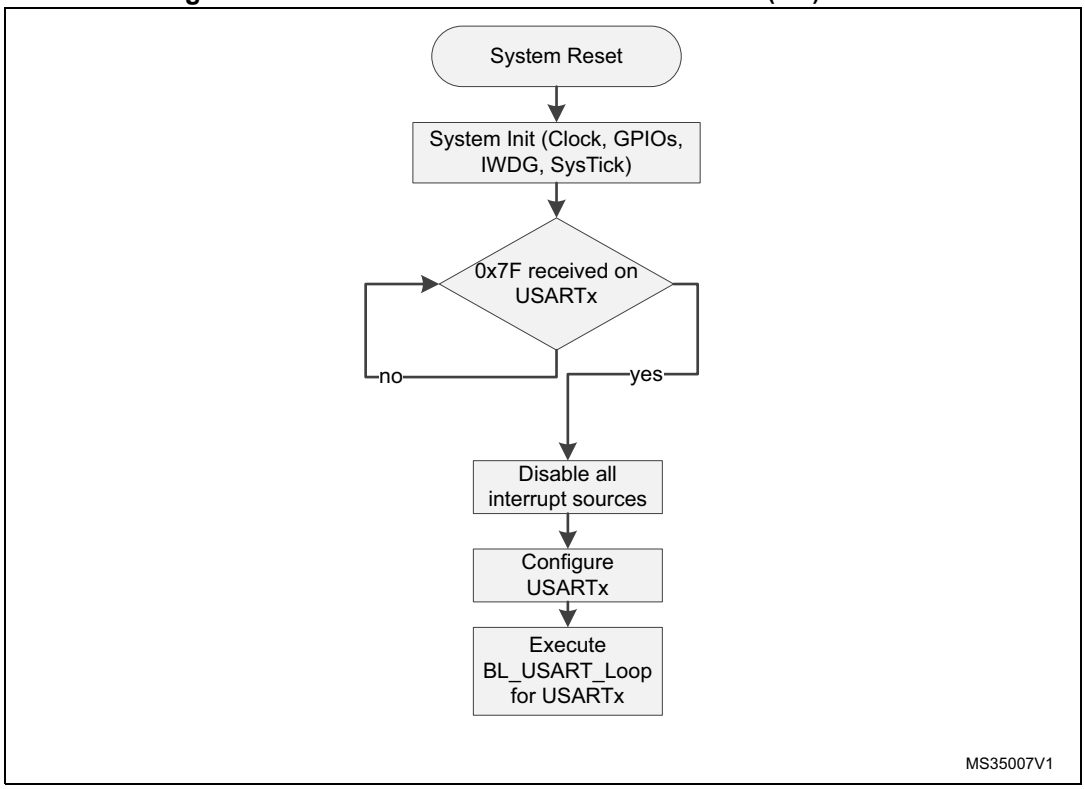
Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 16 MHz.
	RAM	-	2 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	4 Kbytes, starting from address 0x1FF00000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage is set to Voltage Range 1.
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.

The system clock is derived from the embedded internal high-speed RC, no external . No external quartz is required for the bootloader execution.

72.2 Bootloader selection

The figure below shows the bootloader selection mechanism.

Figure 92. Bootloader selection for STM32L1xxx6(8/B) devices



72.3 Bootloader version

The following table lists the STM32L1xxx6(8/B) devices bootloader versions:

Table 168. STM32L1xxx6(8/B) bootloader versions

Version number	Description	Known limitations
V2.0	Initial bootloader version	– When a Read Memory or Write Memory command is issued with an unsupported memory address and a correct address checksum (i.e. address 0x6000 0000), the command is aborted by the bootloader device, but the NACK (0x1F) is not sent to the host. As a result, the next two bytes (the number of bytes to be read/written and its checksum) are considered as a new command and its checksum.(1) – PA13/14/15 is configured in alternate push-pull (PA14 in pull-down) even if not used.

1. If the “number of data - 1” (N-1) to be read/written is not equal to a valid command code, the limitation is not perceived from the host, as the command is NACK-ed anyway (as an unsupported new command).

73 STM32L1xxxC devices

73.1 Bootloader configuration

The STM32L1xxxC bootloader is activated by applying Pattern 1 (described in *Table 2*). The following table shows the hardware resources used by this bootloader.

Table 169. STM32L1xxxC configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 16 MHz using the HSI. This is used only for USARTx and during USB detection for DFU (once the DFU is selected, the clock source is derived from the external crystal).
		HSE enabled	The external clock is mandatory only for the DFU and must be in the following range: [24, 16, 12, 8, 6, 4, 3, 2] MHz. The PLL is used to generate the USB 48 MHz clock and the 32 MHz clock for the system clock.
		-	The CSS interrupt is enabled for the DFU. Any failure (or removal) of the external clock generates a system reset.
	RAM	-	4 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	8 Kbytes, starting from address 0x1FF00000 contains the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog resets (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage is set to Voltage Range 1.
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity and 1 stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 169. STM32L1xxxC configuration in system memory boot mode (continued)

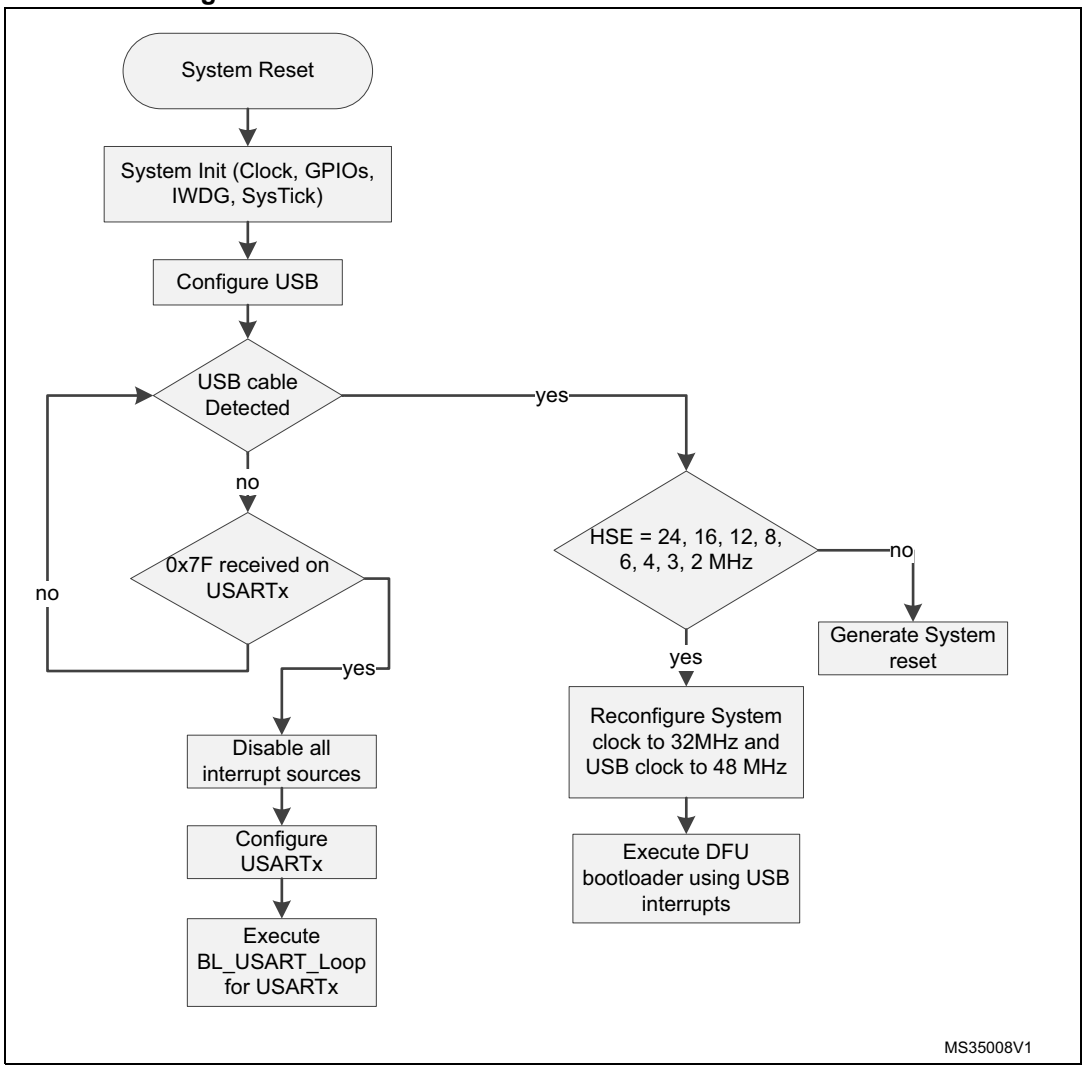
Bootloader	Feature/Peripheral	State	Comment
USART2	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity and 1 stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for the USARTx bootloader.
DFU	USB	Enabled	USB used in FS mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode.

The system clock is derived from the embedded internal high-speed RC for the USARTx bootloader. This internal clock is also used the for DFU, but only for the selection phase. An external clock in the range of [24, 16, 12, 8, 6, 4, 3, 2] MHz is required for the execution of the DFU after the selection phase.

73.2 Bootloader selection

The figure below shows the bootloader selection mechanism.

Figure 93. Bootloader selection for STM32L1xxxC devices



73.3 Bootloader version

Table 170 lists the STM32L1xxxC devices bootloader versions.

Table 170. STM32L1xxxC bootloader versions

Version number	Description	Known limitations
V4.0	Initial bootloader version	– For the USART interface, two consecutive instead of one NACKs are sent when a Read Memory or Write Memory command is sent and the RDP level is active. – PA13/14/15 configured in alternate push-pull, pull (PA14 in pull-down) even if not used. – The USB bootloader fails on some machines using a high speed controller. The bootloader is detected. but then data transaction fails. Root causes: De-synchronization between USB controller and bootloader SW due to the controller high speed transactions. Controller high speed inter-packet delay seems not sufficient for the bootloader SW (based on interrupt routines) to serve all needed transactions (the delay needed by the BL is nearly 25 µs). Some servicing IT are missed. This results in a communication fail, causing Write command to fail. Workarounds: Add an USB HUB between the host and the MCU. This relaxes transactions inter-packet delay, and allows the BL SW to perform correctly the task. Use USB controller/host that increase inter-packet delay. On new designs, use DFU SW that fix the issue in user flash memory.

74 STM32L1xxxD devices

74.1 Bootloader configuration

The STM32L1xxxD bootloader is activated by applying Pattern 4 (described in *Table 2*). The following table shows the hardware resources used by this bootloader.

Table 171. STM32L1xxxD configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 16 MHz using the HSI. This is used only for USARTx and during USB detection for DFU (once the DFU is selected, the clock source is derived from the external crystal).
		HSE enabled	The external clock is mandatory only for DFU and it must be in the following range: [24, 16, 12, 8, 6, 4, 3, 2] MHz. The PLL is used to generate the USB 48 MHz clock and the 32 MHz clock for the system clock.
		-	The CSS interrupt is enabled for the DFU. Any failure (or removal) of the external clock generates a system reset.
	RAM	-	4 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	8 Kbytes, starting from address 0x1FF00000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage is set to voltage range 1.
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 171. STM32L1xxxD configuration in system memory boot mode (continued)

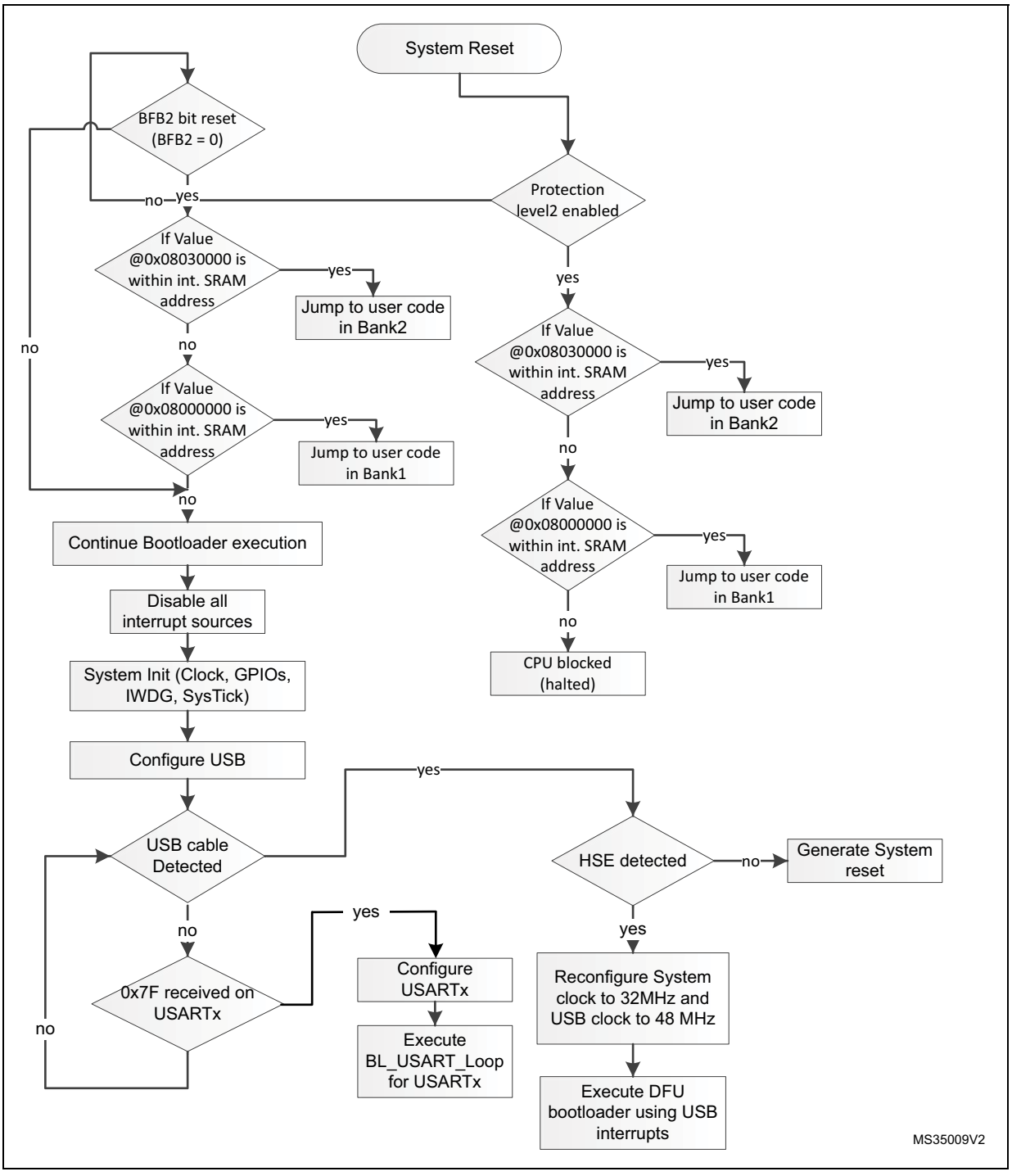
Bootloader	Feature/Peripheral	State	Comment
USART2	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloader.
DFU	USB	Enabled	USB used in FS mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode.

The system clock is derived from the embedded internal high-speed RC for USARTx bootloader. This internal clock is used also for DFU, but only for the selection phase. An external clock in the range of [24, 16, 12, 8, 6, 4, 3, 2] MHz is required for DFU execution after the selection phase.

74.2 Bootloader selection

The figure below shows the bootloader selection mechanism.

Figure 94. Bootloader selection for STM32L1xxxD devices



74.3 Bootloader version

The following table lists the STM32L1xxxD devices bootloader versions:

Table 172. STM32L1xxxD bootloader versions

Version number	Description	Known limitations
V4.1	Initial bootloader version	– In the bootloader code the PA13 (JTMS/SWDIO) I/O output speed is configured to 400 kHz, as a consequence some debugger cannot connect to the device in Serial Wire mode when the bootloader is running. – When the DFU is selected, the RTC is reset and thus all RTC information (such as calendar, alarm) are lost including backup registers. **Note**: When the USART bootloader is selected there is no change on the RTC configuration (including backup registers).
V4.2	Fix V4.1 limitations (available on Rev.Z devices only)	– Stack overflow by 8 bytes when jumping to Bank1/Bank2 if BFB2 = 0 or when Read Protection level is set to 2. Workaround: the user code must force in the startup file the top of stack address before to jump to the main program. This can be done in the “Reset_Handler” routine. – When the Stack of the user code is placed outside the SRAM (at 0x2000 C000) the bootloader cannot jump to that user code, considered invalid. This can happen with compilers that put the stack at a non-physical address at the top of the SRAM (at 0x2000 C000). Workaround: place manually the stack at a physical address.
V4.5	Fix V4.2 limitations. DFU interface robustness enhancements (available on Rev.Y devices only).	– For the USART interface, two consecutive NACKs (instead of one) are sent when a Read Memory or Write Memory command is sent and the RDP level is active. – The USB bootloader fails on some machines using a high speed controller. The bootloader is detected. but then data transaction fails. Root causes: De-synchronization between USB controller and bootloader SW due to the controller high speed transactions. Controller high speed inter-packet delay seems not sufficient for the bootloader SW (based on interrupt routines) to serve all needed transactions (the delay needed by the BL is nearly 25 µs). Some servicing IT are missed. This results in a communication fail, causing Write command to fail. Workarounds: Add an USB HUB between the host and the MCU. This relaxes transactions inter-packet delay, and allows the BL SW to perform correctly the task. Use USB controller/host that increase inter-packet delay. On new designs, use DFU SW that fix the issue in user flash memory.

75 STM32L1xxxE devices

75.1 Bootloader configuration

The STM32L1xxxE bootloader is activated by applying Pattern 4 (described in *Table 2*). The following table shows the hardware resources used by this bootloader.

Table 173. STM32L1xxxE configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 16 MHz using the HSI. This is used only for USARTx and during USB detection for DFU (once the DFU is selected, the clock source is derived from the external crystal).
		HSE enabled	The external clock is mandatory only for DFU and it must be in the following range: [24, 16, 12, 8, 6, 4, 3, 2] MHz. The PLL is used to generate the USB 48 MHz clock and the 32 MHz clock for the system clock.
		-	The CSS interrupt is enabled for the DFU. Any failure (or removal) of the external clock generates system reset.
	RAM	-	4 Kbytes, starting from address 0x20000000, are used by the bootloader firmware.
	System memory	-	8 Kbytes, starting from address 0x1FF00000 contains the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage is set to Voltage Range 1.
USART1	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 173. STM32L1xxxE configuration in system memory boot mode (continued)

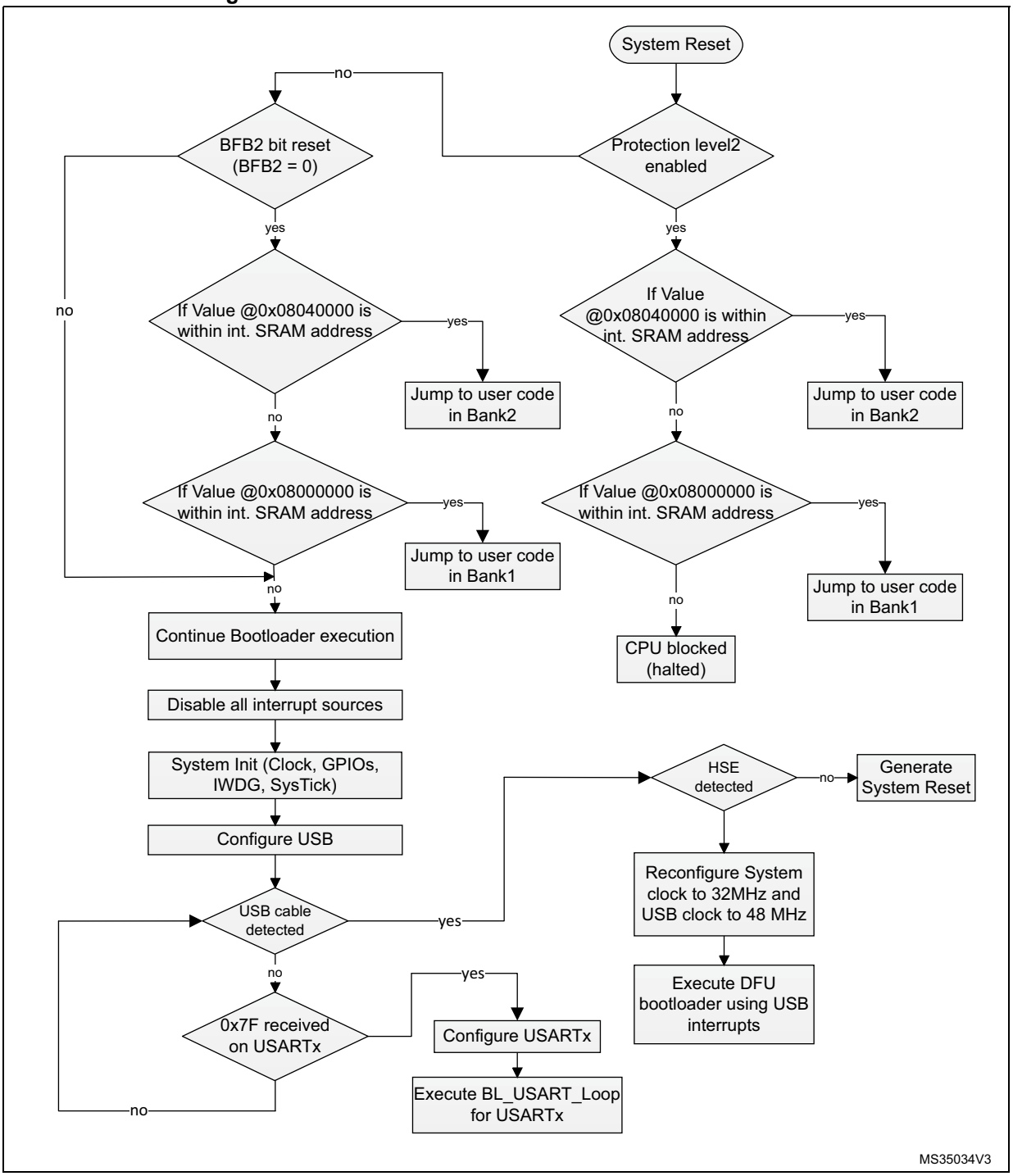
Bootloader	Feature/Peripheral	State	Comment
USART2	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloader.
DFU	USB	Enabled	USB used in FS mode
	USB_DM pin	Input/output	PA11: USB DM line.
	USB_DP pin		PA12: USB DP line.

The system clock is derived from the embedded internal high-speed RC for USARTx bootloader. This internal clock is used also for DFU, but only for the selection phase. An external clock in the range of [24, 16, 12, 8, 6, 4, 3, 2] MHz is required for DFU execution after the selection phase.

75.2 Bootloader selection

The figure below shows the bootloader selection mechanism.

Figure 95. Bootloader selection for STM32L1xxxE devices



75.3 Bootloader version

Table 174 lists the STM32L1xxxE devices bootloader versions:

Table 174. STM32L1xxxE bootloader versions

Version number	Description	Known limitations
V4.0	Initial bootloader version	– For the USART interface, two consecutive NACKs (instead of 1 NACK) are sent when a Read Memory or Write Memory command is sent and the RDP level is active. – PA13/14/15 configured in alternate push-pull, pull (PA14 in pull-down) even if not used. – The USB bootloader fails on some machines using a high speed controller. The bootloader is detected. but then data transaction fails. Root causes: De-synchronization between USB controller and bootloader SW due to the controller high speed transactions. Controller high speed inter-packet delay seems not sufficient for the bootloader SW (based on interrupt routines) to serve all needed transactions (the delay needed by the BL is nearly 25 µs). Some servicing IT are missed. This results in a communication fail, causing Write command to fail. Workarounds: Add an USB HUB between the host and the MCU. This relaxes transactions inter-packet delay, and allows the BL SW to perform correctly the task. Use USB controller/host that increase inter-packet delay. On new designs, use DFU SW that fix the issue in user flash memory.

76 STM32L412xx/422xx devices

76.1 Bootloader configuration

The STM32L412xx/422xx bootloader is activated by applying Pattern 16 (described in *Table 2*). *Table 175* shows the hardware resources used by this bootloader.

Table 175. STM32L412xx/422xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 72 MHz and for USART, I2C, SPI and USB bootloader operation.
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz.
	RAM	-	12 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The DFU cannot be used to communicate with bootloader if the voltage scaling range 2 is selected. Bootloader firmware does not configure voltage scaling range value in PWR_CR1 register.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input pull-up mode
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.

Table 175. STM32L412xx/422xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1010010x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1010010x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON Target 7-bit address: 0b1010010x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain no pull mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode.(1)
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. **Note:** This IO can be tied to GND if the SPI master does not use it.

Table 175. STM32L412xx/422xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode.(1)
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. **Note:** This IO can be tied to GND if the SPI master does not use it.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. **Note**: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required

1. SPI Tx (MISO) is handled by DMA. On the bootloader statup after SPI initialisation as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line will be set to 3.3 V.

Note: If VDDUSB pin is not connected to V_{DD}, SPI flash memory write operations may be corrupted due to voltage issue. For more details, refer to product's datasheet and errata sheet.

76.2 Bootloader selection

The following figures show the bootloader selection mechanism.

Figure 96. Dual bank boot Implementation for STM32L412xx/422xx bootloader V9.x

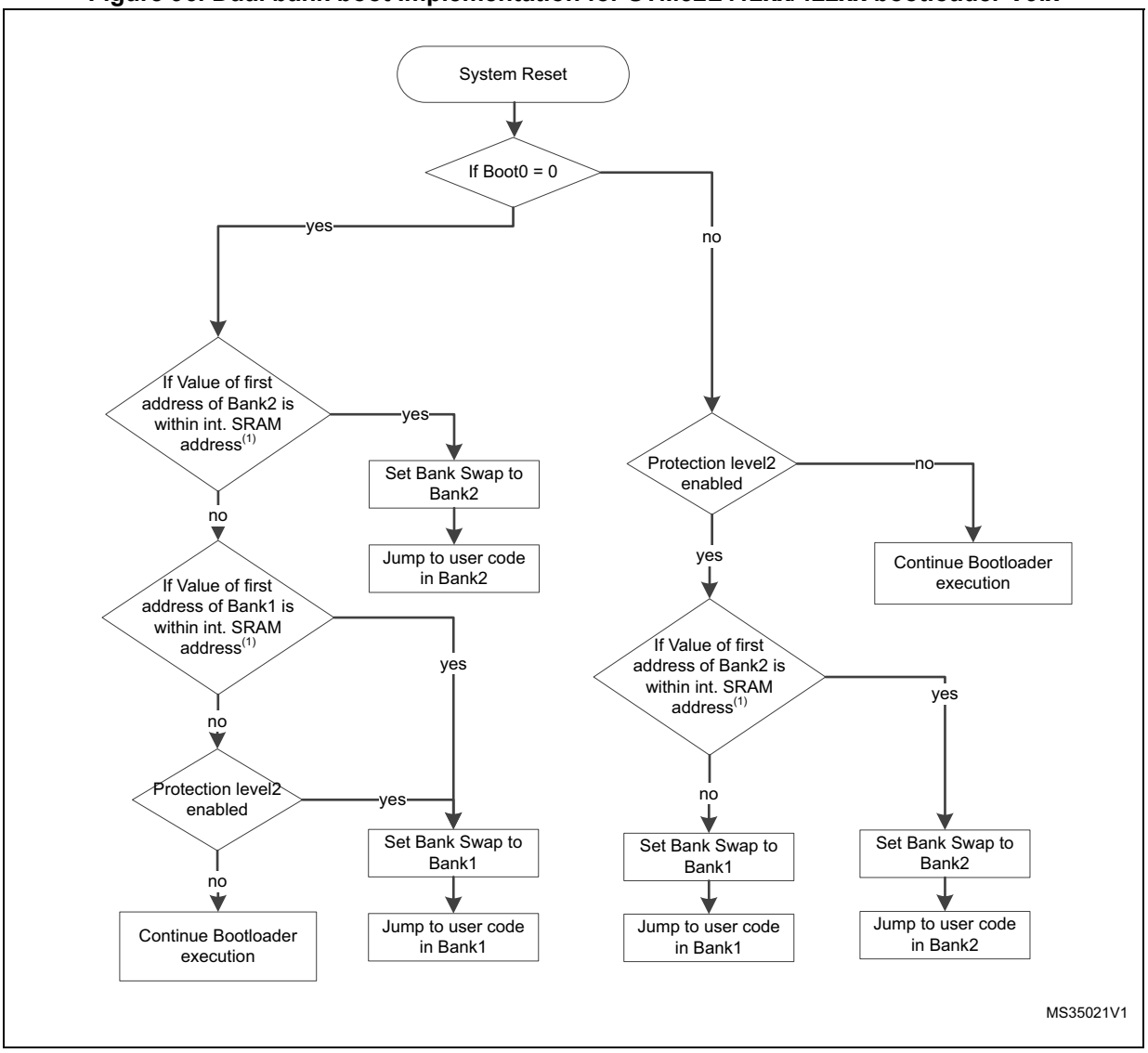
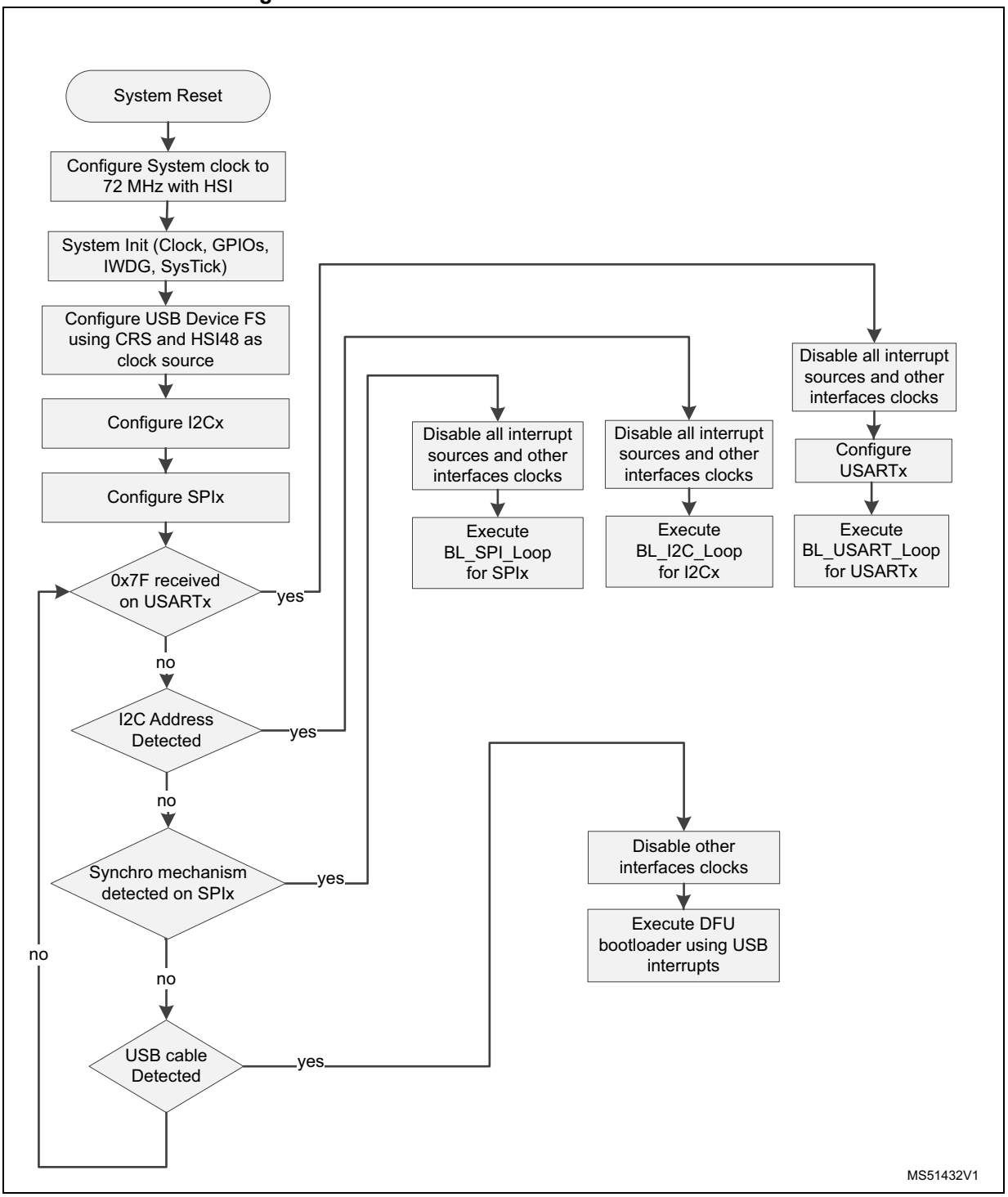


Figure 97.Bootloader V13.x selection for STM32L412xx/422xx



76.3 Bootloader version

Table 176 lists the STM32L412xx/422xx devices bootloader version.

Table 176. STM32L412xx/422xx bootloader versions

Version number	Description	Known limitations
V13.1	Initial bootloader version	– On connection phase, USART responds with two ACK bytes (0x79) instead of one. – PcROP option bytes cannot be written as Bootloader uses Byte access while PcROP must be accessed using half-word access. **Workaround**: load a code snippet in SRAM using Bootloader interface, then jump to it, and that code writes PcROP value.

77 STM32L43xxx/44xxx devices

77.1 Bootloader configuration

The bootloader V9.1 version is updated to fix known limitations relative to USB-DFU interface, and is implemented on devices with version information ID equal to 0x10 (refer to *Table 178* for more details).

The STM32L43xxx/44xxx bootloader is activated by applying Pattern 16 (described in *Table 2*). *Table 177* shows the hardware resources used by this bootloader.

Table 177. STM32L43xxx/44xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART, I2C, SPI and USB bootloader operation.
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz.
		HSE enabled	The HSE is used only when the CAN interface is selected. The HSE must have one of the following values [24,20,18,16,12,9,8,6,4] MHz.
		-	The CSS interrupt is enabled when HSE is enabled. Any failure (or removal) of the external clock generates system reset
	RAM	-	12 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The DFU cannot be used to communicate with bootloader if the voltage scaling range 2 is selected. Bootloader firmware does not configure voltage scaling range value in PWR_CR1 register.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Initialized in input no pull mode, then switched to alternate pull-up after USART detection.

Table 177. STM32L43xxx/44xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Initialized in input no pull mode, then switched to alternate pull-up after USART detection.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b1001000x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b1001000x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b1001000x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain no pull mode.

Table 177. STM32L43xxx/44xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. **Note**: This IO can be tied to GND if the SPI master does not use it.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. **Note:** This IO can be tied to GND if the SPI master does not use it.
CAN1	CAN1	Enabled	Once initialized the CAN1 configuration is: Baudrate 125 kbps, 11 -bit identifier.
	CAN1_RX pin	Input	PB8 pin: CAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN1_TX pin	Output	PB9 pin: CAN1 in transmission mode. Used in alternate push-pull, pull-up mode.
	TIM16	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

Table 177. STM32L43xxx/44xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. **Note**: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required

Note: If VDDUSB pin is not connected to V_{DD}, SPI flash memory write operations may be corrupted due to voltage issue. For more details, refer to product's datasheet and errata sheet.
SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization, as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

77.2 Bootloader selection

The following figures show the bootloader selection mechanism.

Figure 98. Dual bank boot Implementation for STM32L3x2xx/44xxx bootloader V9.x

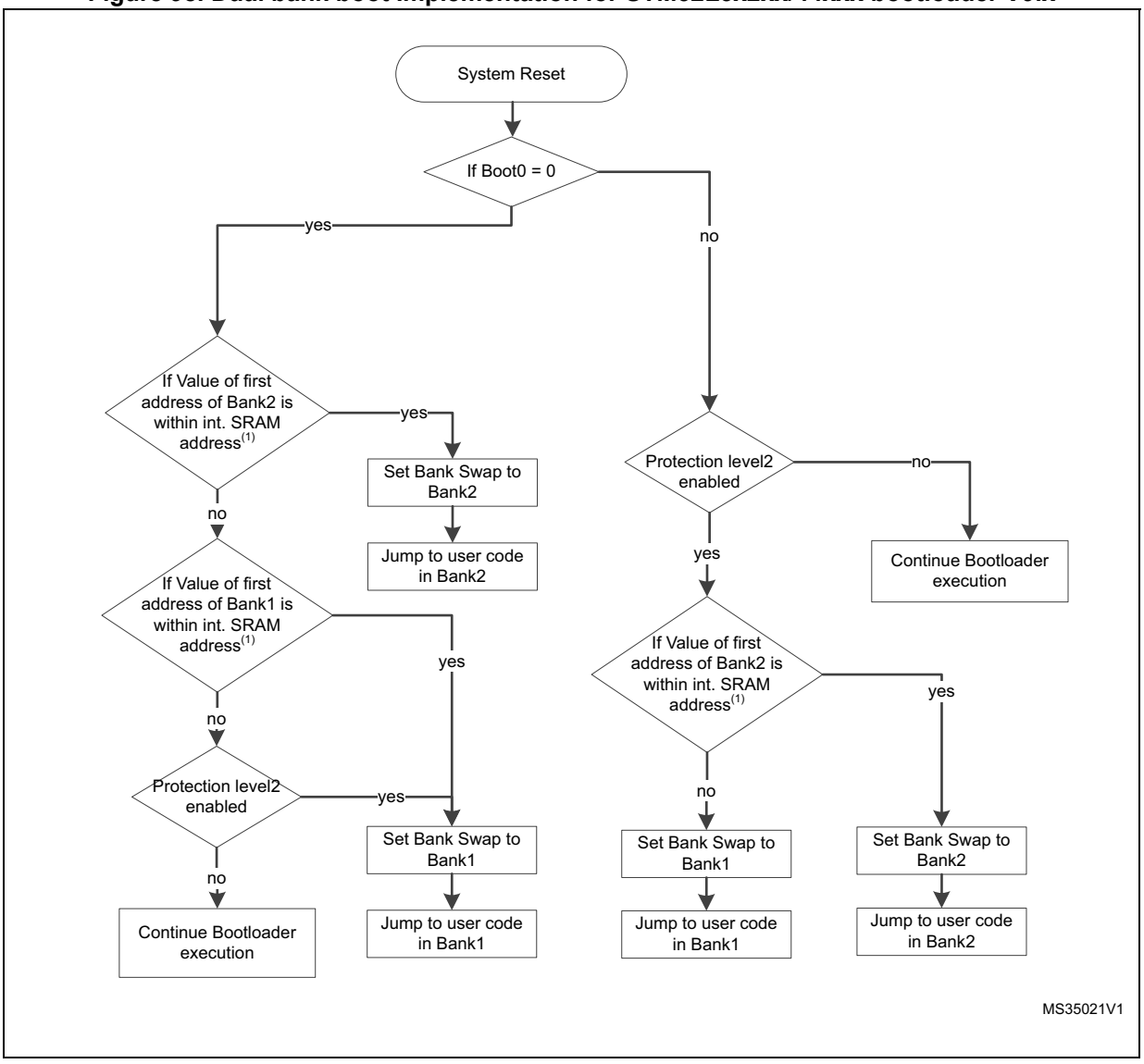
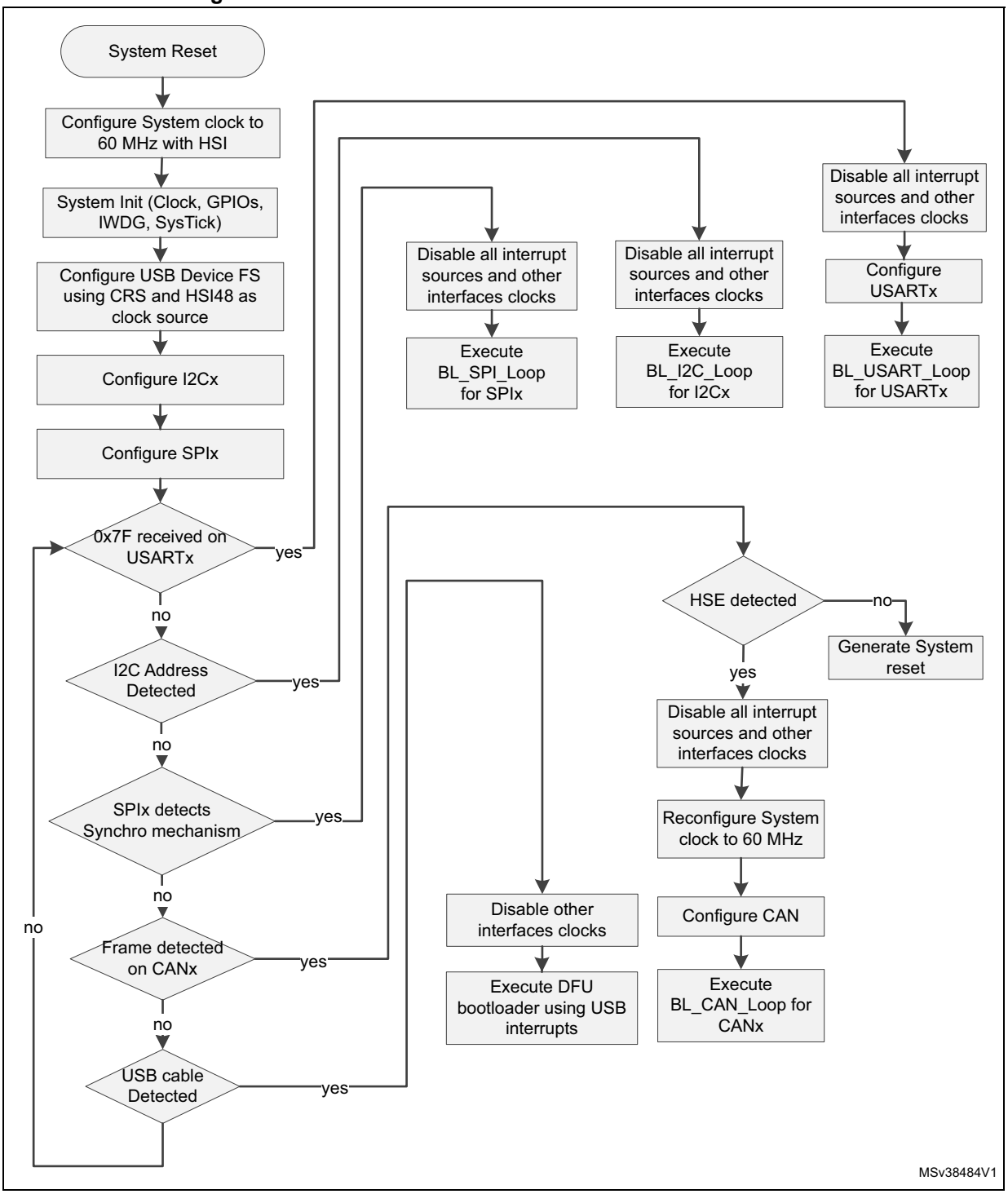


Figure 99. Bootloader V9.x selection for STM32L43xxx/44xxx



77.3 Bootloader version

Table 178 lists the STM32L43xxx/44xxx devices bootloader versions.

Table 178. STM32L43xxx/44xxx bootloader versions

Version number	Description	Known limitations
V9.1	Initial bootloader version	Check the Version Information ID of your STM32L43xxx/44xxx device, which can be read at 0x1FFF6FF2 address. **Version Information ID equal to 0xFF**: – For memory write operations using DFU interface: If the buffer size is larger than 256 bytes and not multiple of 8 bytes, the write memory operation result is corrupted. Workaround: if the file size is larger than 256 bytes, add byte padding to align it on 8-bytes multiple size. – For the USB-DFU interface, the CRS (clock recovery system) is not correctly configured and this may lead to random USB communication errors (depending on temperature and voltage). In most case communication error will manifest by a "Stall" response to setup packets. – On the Go command, system bootloader de-init clears the RTCAPBEN bit in the RCC_APB1ENR register Workaround: manually call __HAL_RCC_RTC_CLK_ENABLE() in the software which sets the RTCAPBEN bit. **Version Information ID equal to 0x10**: None – PcROP option bytes cannot be written as Bootloader uses Byte access while PcROP must be accessed using half-word access. **Workaround**: load a code snippet in SRAM using Bootloader interface then jump to it, and that code writes the PcROP value.

Table 178. STM32L43xxx/44xxx bootloader versions (continued)

Version number	Description	Known limitations
V9.1 (continued)	Initial bootloader version (continued)	– SPI write operation fail Limitation: a. During bootloader SPI write flash memory operation, some random 64-bits (2 double-words) may be left blank at 0xFF. **Root cause**: a. Bootloader uses 64-bits cast write operation which is interrupted by SPI DMA and it leads to double access on same flash memory address and the 64-bits are not written. **Workarounds**: a. WA1: add a delay between sending write command and its ACK request. Its duration must be the duration of the 256-Bytes flash memory write time. b. WA2: read back after write and in case of error start write again. c. WA3: Patch in RAM to write in flash memory that implements write memory without 64-bits cast. WA1 and WA3 are more efficient than WA2 in terms of total programming time. **How critical is the limitation**: a. The limitation leads to a modification in customer SPI host software by adding 3-4 ms delay to each write operation. b. The delay is not waste because it is anyway the flash memory write period of time that host has to wait anyway (so instead of waiting by sending ACK requests, host will wait by delay). c. Limitation has been seen only on SPI and cannot impact USART/I2C/CAN – If the RTC is used by application prior to booting (through a system reset) on system bootloader, it is possible that CAN interface does not work correctly (cannot establish connection) unless a power cycle is performed or RTC is reset by application before booting on System Bootloader

78 STM32L45xxx/46xxx devices

78.1 Bootloader configuration

The STM32L45xxx/46xxx bootloader is activated by applying Pattern 16 (described in *Table 2*). *Table 179* shows the hardware resources used by this bootloader.

Table 179. STM32L45xxx/46xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 72 MHz and for USART, I2C, SPI and USB bootloader operation.
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI48 48 MHz.
		HSE enabled	The system clock frequency is 60 MHz. The HSE is used only when the CAN interface is selected. The HSE must have one of the following values [24,20,18,16,12,9,8,6,4] MHz.
		-	The CSS interrupt is enabled when HSE is enabled. Any failure (or removal) of the external clock generates system reset
	RAM	-	12 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The DFU cannot be used to communicate with bootloader if the voltage scaling range 2 is selected. Bootloader firmware does not configure voltage scaling range value in PWR_CR1 register.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input pull-up mode.

Table 179. STM32L45xxx/46xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b1001010x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b1001010x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz, 7-bit address, Target mode, Analog filter ON – Target 7-bit address: 0b1001010x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain no pull mode.

Table 179. STM32L45xxx/46xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. **Note**: This IO can be tied to GND if the SPI master does not use it.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. **Note**: This IO can be tied to GND if the SPI master does not use it.
CAN1	CAN1	Enabled	Once initialized the CAN1 configuration is: Baudrate 125 kbps, 11 -bit identifier.
	CAN1_RX pin	Input	PB8 pin: CAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN1_TX pin	Output	PB9 pin: CAN1 in transmission mode. Used in alternate push-pull, pull-up mode.
	TIM16	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

Table 179. STM32L45xxx/46xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. **Note:** VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required

Note: If VDDUSB pin is not connected to V_{DD}, SPI flash memory write operations may be corrupted due to voltage issue. For more details, refer to product's datasheet and errata sheet.

78.2 Bootloader selection

The following figures show the bootloader selection mechanism.

Figure 100. Dual bank boot implementation for STM32L45xxx/46xxx bootloader V9.x

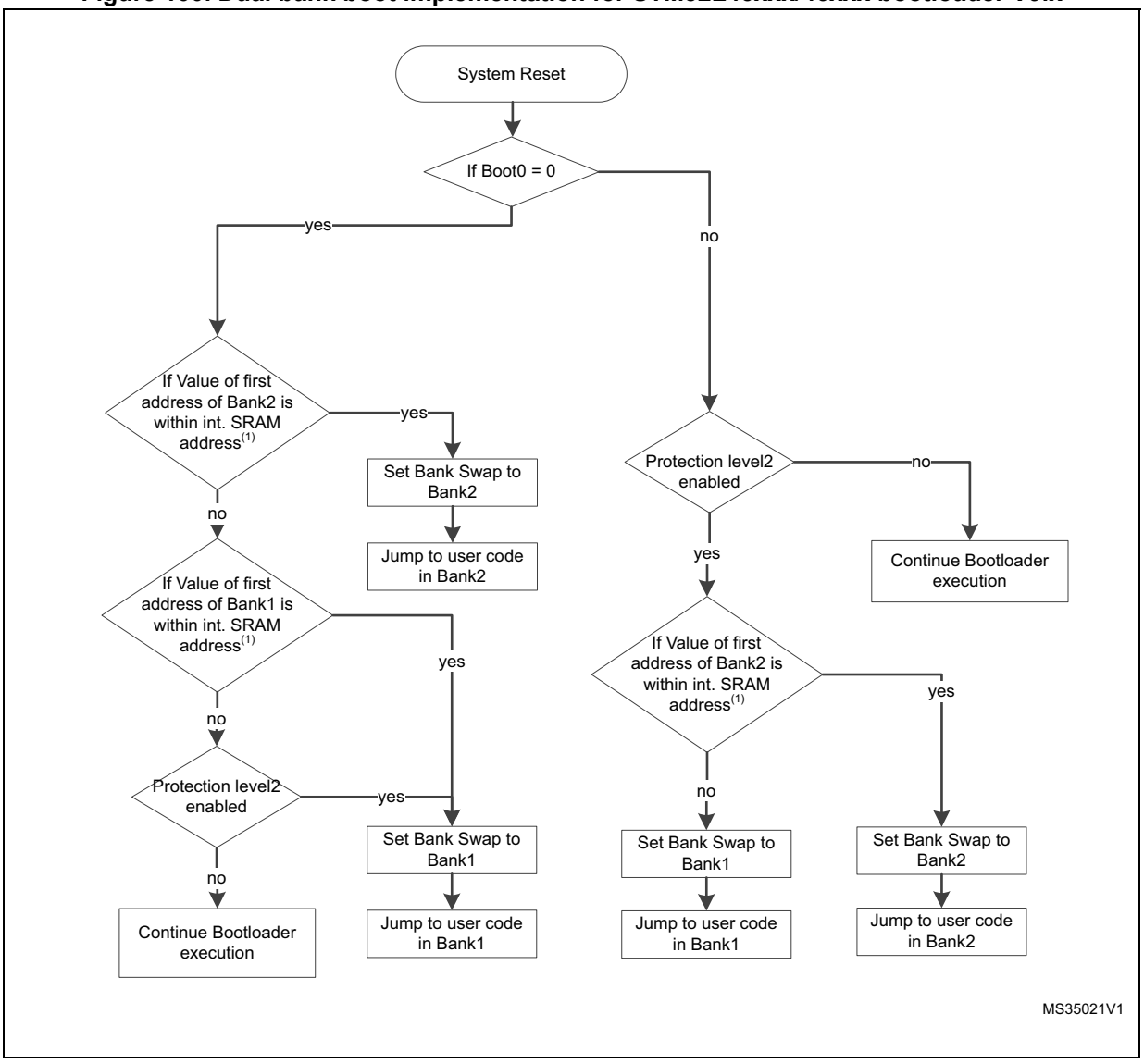
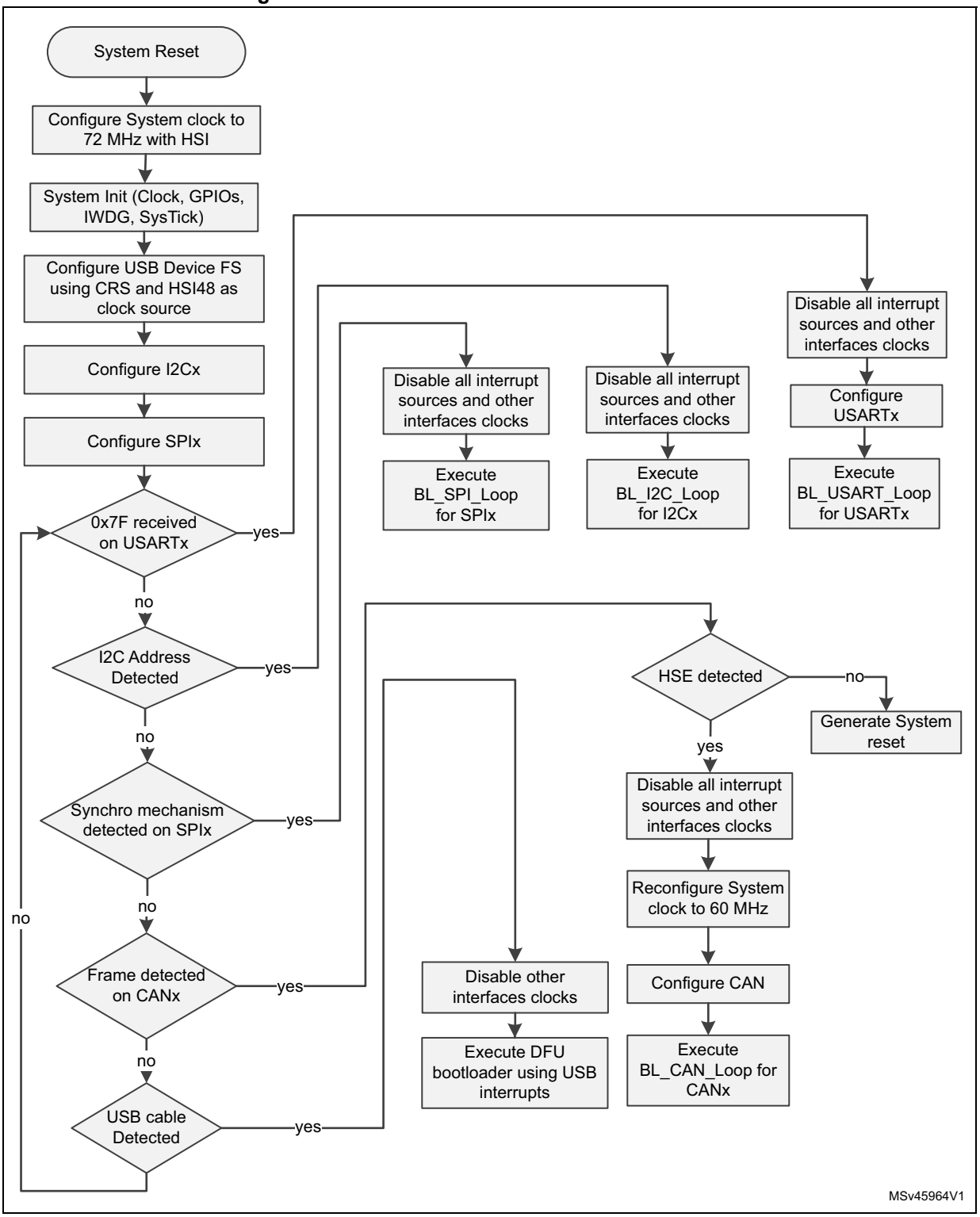


Figure 101.Bootloader V9.x selection for STM32L45xxx/46xxx



78.3 Bootloader version

Table 180 lists the STM32L45xxx/46xxx devices bootloader versions.

Table 180. STM32L45xxx/46xxx bootloader versions

Version number	Description	Known limitations
V9.2	Initial bootloader version	– PcROP option bytes cannot be written as Bootloader uses Byte access while PcROP must be accessed using half-word access. **Workaround**: load a code snippet in SRAM using Bootloader interface then jump to it, and that code writes the PcROP value. – SPI write operation fail limitation: a. During Bootloader SPI write flash memory operation, some random 64-bits (2 double-words) may be left blank at 0xFF. **Root cause**: a. Bootloader uses 64-bits cast write operation which is interrupted by SPI DMA and it leads to double access on same flash memory address and the 64-bits are not written **Workarounds**: a. WA1: add a delay between sending write command and its ACK request. Its duration must be the duration of the 256-Bytes flash memory write time. b. WA2: read back after write and in case of error start write again. c. WA3: Patch in RAM to write in flash memory that implements write memory without 64-bits cast. WA1 and WA3 are more efficient than WA2 in terms of total programming time **How critical is the limitation:** a. The limitation leads to a modification in customer SPI host software by adding 3-4 ms delay to each write operation. b. The delay is not waste because it is anyway the flash memory write period of time that host has to wait anyway (so instead of waiting by sending ACK requests, host will wait by delay). c. Limitation has been seen only on SPI and cannot impact USART/I2C/CAN.

79 STM32L47xxx/48xxx devices

Two bootloader versions are available:

- V10.x supporting USART, I2C and DFU (USB FS device).
  This version is embedded in STM32L47xxx/48xxx rev. 2 and rev. 3 devices.
- V9.x supporting USART, I2C, SPI, CAN and DFU (USB FS device).
  This version is embedded in STM32L47xxx/48xxx rev. 4 devices.

79.1 Bootloader V10.x

79.1.1 Bootloader configuration

The STM32L47xxx/48xxx bootloader is activated by applying Pattern 7 (described in *Table 2*). *Table 181* shows the hardware resources used by this bootloader.

Table 181. STM32L47xxx/48xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 24 MHz and for USART and I2C bootloader operation.
		HSE enabled	The HSE is used only when the USB interface is selected and the LSE is not present. The HSE must have one of the following values: 24, 20, 18, 16, 12,9, 8, 6, and 4 MHz.
		LSE enabled	The LSE is used to trim the MSI which is configured to 48 MHz as USB clock source. The LSE must be equal to 32.768 kHz. If the LSE is not detected, the HSE is used instead if USB is connected.
		MSI enabled	The MSI is configured to 48 MHz and is used as USB clock source. The MSI is used only if LSE is detected, otherwise, HSE is used if USB is connected.
		-	The CSS interrupt is enabled when LSE or HSE is enabled. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The DFU cannot be used to communicate with bootloader if the voltage scaling range 2 is selected. Bootloader firmware does not configure voltage scaling range value in PWR_CR1 register.

Table 181. STM32L47xxx/48xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input pull-up mode.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used i input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000011x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000011x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin		PB11 pin: data line is used in open-drain no pull mode.

Table 181. STM32L47xxx/48xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address is 0b1000011x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin		PC1 pin: data line is used in open-drain no pull mode.
DFU	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
	TIM17	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 24 MHz using PLL and HSE.

For USARTx and I2Cx bootloaders no external clock is required.

USB bootloader (DFU) requires either an LSE (low-speed external clock) or a HSE (high-speed external clock):

- If the LSE is present regardless of the HSE presence, the MSI is configured and trimmed by the LSE to provide an accurate clock equal to 48 MHz, which is the clock source of the USB. The system clock is kept clocked to 24 MHz by the HSI.
- If the HSE is present, the system clock and USB clock are configured, respectively, to 24 MHz and 48 MHz with HSE as clock source.

79.1.2 Bootloader selection

Figure 102 and *Figure 103* show the bootloader selection mechanism.

Figure 102. Dual bank boot implementation for STM32L47xxx/48xxx bootloader V10.x

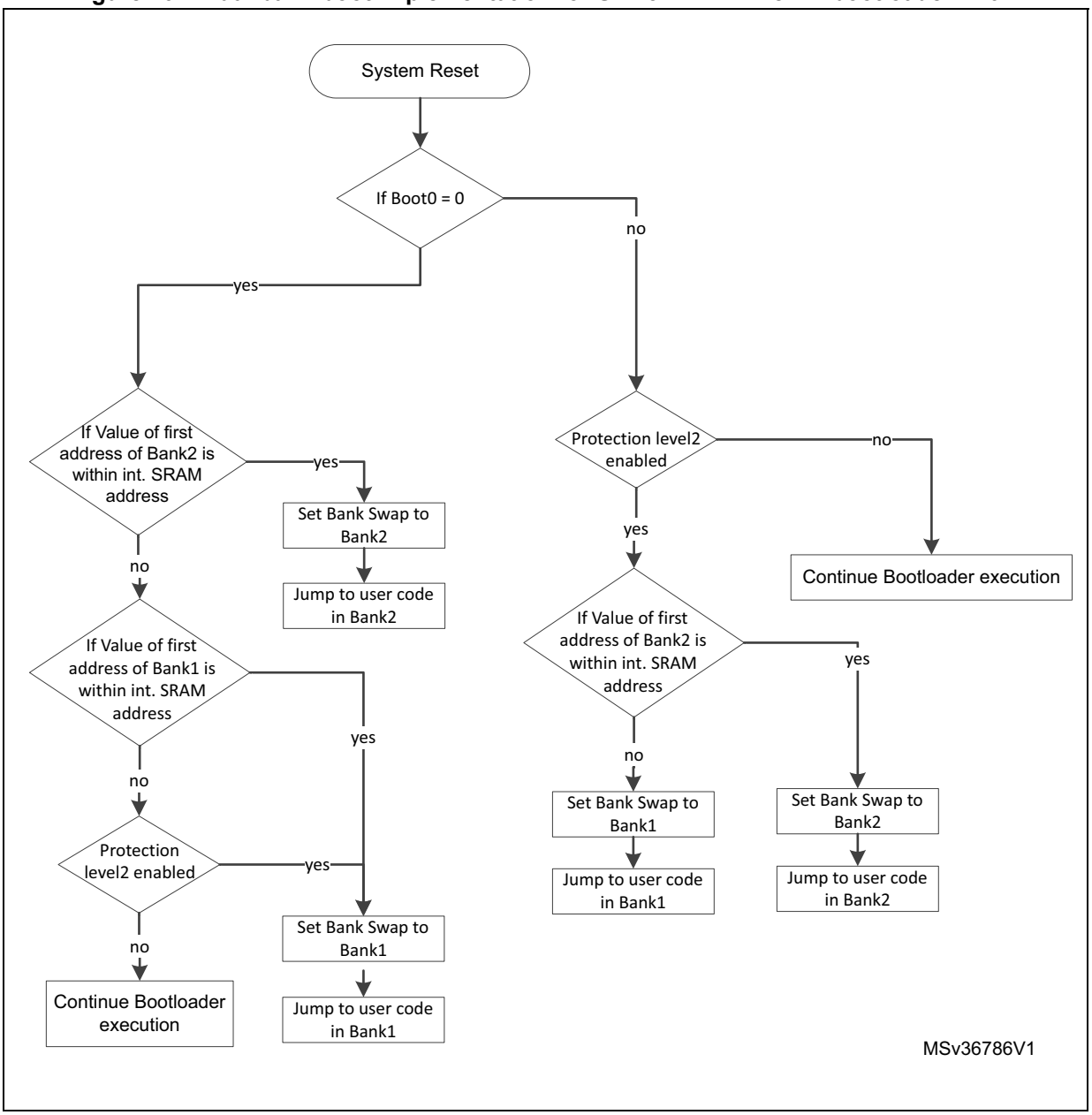
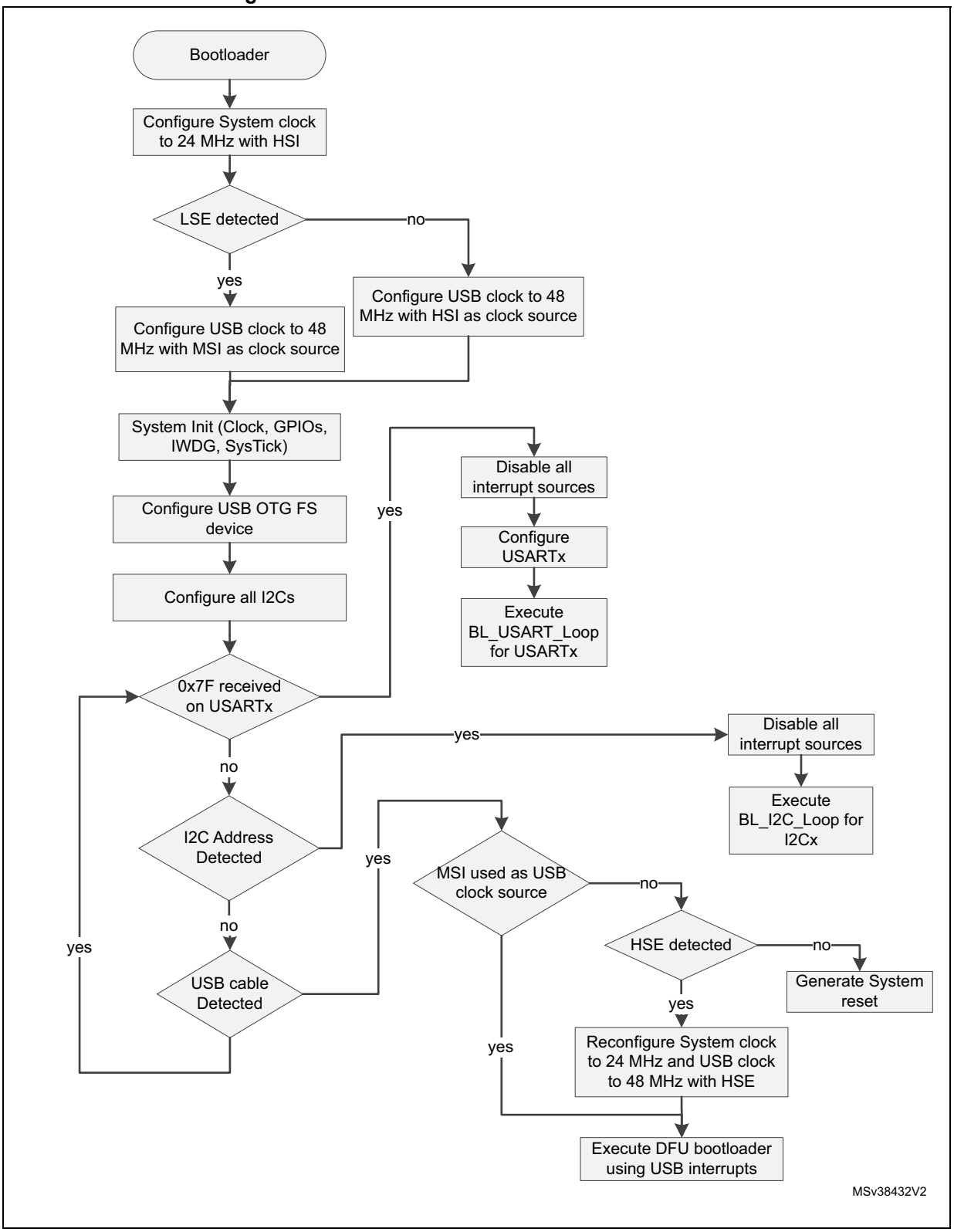


Figure 103.Bootloader V10.x selection for STM32L47xxx/48xxx



79.1.3 Bootloader version

Table 182 lists the STM32L47xxx/48xxx devices bootloader V10.x versions:

Table 182. STM32L47xxx/48xxx bootloader V10.x versions

Version number	Description	Known limitations
V10.1	Initial bootloader version	For memory write operations using DFU interface: If the buffer size is larger than 256 bytes and not multiple of 8 bytes, the write memory operation result is corrupted. Workaround: if the file size is larger than 256 bytes, add byte padding to align it on 8-bytes multiple size. Write in SRAM is corrupted.
V10.2	Fix write in SRAM issue	For memory write operations using DFU interface: If the buffer size is larger than 256 bytes and not multiple of 8 bytes, the write memory operation result is corrupted. Workaround: if the file size is larger than 256 bytes, add byte padding to align it on 8-bytes multiple size.
V10.3	Add support of MSI as USB clock source (MSI is trimmed by LSE). Update dual bank boot feature to support the case when user stack is mapped in SRAM2.	– For memory write operations using DFU interface: If the buffer size is larger than 256 bytes and not multiple of 8 bytes, the write memory operation result is corrupted. Workaround: if the file size is larger than 256 bytes, add byte padding to align it on 8-bytes multiple size. – PcROP option bytes cannot be written as Bootloader uses Byte access while PcROP must be accessed using half-word access. Workaround: load a code snippet in SRAM using the bootloader interface, then jump to it, and that code writes the PcROP value.

79.2 Bootloader V9.x

79.2.1 Bootloader configuration

The STM32L47xxx/48xxx bootloader is activated by applying Pattern 7 (described in *Table 2*). *Table 183* shows the hardware resources used by this bootloader.

Table 183. STM32L47xxx/48xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 72 MHz and for USART and I2C bootloader operation.
		HSE enabled	The HSE is used only when the USB interface is selected and the LSE is not present. The HSE must have one of the following values: 24, 20, 18, 16, 12, 8, 6, 4 MHz. System is clocked at 72 MHz if USB is used or 60 MHz if CAN is used.
		LSE enabled	The LSE is used to trim the MSI which is configured to 48 MHz as USB clock source. The LSE must be equal to 32.768 kHz. If the LSE is not detected, the HSE is used instead if USB is connected.
		MSI enabled	The MSI is configured to 48 MHz and is used as USB clock source. The MSI is used only if LSE is detected, otherwise, HSE is used if USB is connected.
		CSS	The CSS interrupt is enabled when LSE or HSE is enabled. Any failure (or removal) of the external clock generates system reset.
	RAM	-	13 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The DFU cannot be used to communicate with bootloader if the voltage scaling range 2 is selected. Bootloader firmware does not configure voltage scaling range value in PWR_CR1 register.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.

Table 183. STM32L47xxx/48xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input pull-up mode.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode Used in input pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000011x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000011x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin		PB11 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1000011x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin		PC1 pin: data line is used in open-drain no pull mode.

Table 183. STM32L47xxx/48xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode(1)
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin		PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode(1)
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin		PB12 pin: slave chip select pin used in push-pull, pull-down mode.
CAN1	CAN1	Enabled	Once initialized the CAN1 configuration is: Baudrate 125 kbps, 11-bit identifier.
	CAN1_RX pin	Input	PB8 pin: CAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN1_TX pin	Output	PB9 pin: CAN1 in transmission mode. Used in alternate push-pull, pull-up mode.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. **Note**: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11 pin: USB FS DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB FS DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization, as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

If the HSE is present, the system clock and USB clock are configured, respectively, to 72 and 48 MHz with PLL (clocked by HSE) as a clock source.

Note: If VDDUSB pin is not connected to V_{DD}, SPI flash memory write operations may be corrupted due to voltage issue. For more details, refer to product's datasheet and errata sheet.

79.2.2 Bootloader selection

Figure 104 and *Figure 105* show the bootloader selection mechanism.

Figure 104. Dual bank boot implementation for STM32L47xxx/48xxx bootloader V9.x

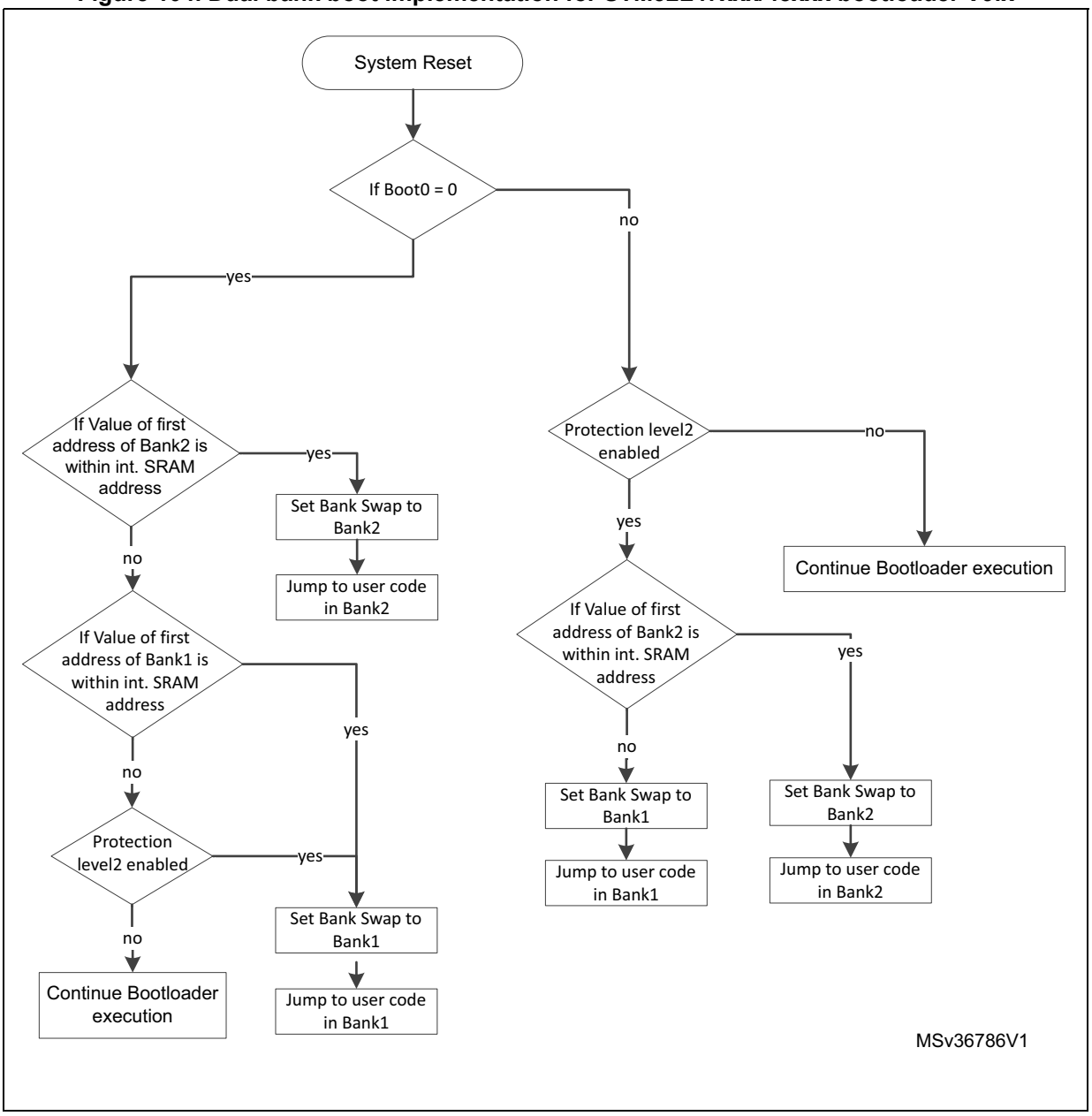
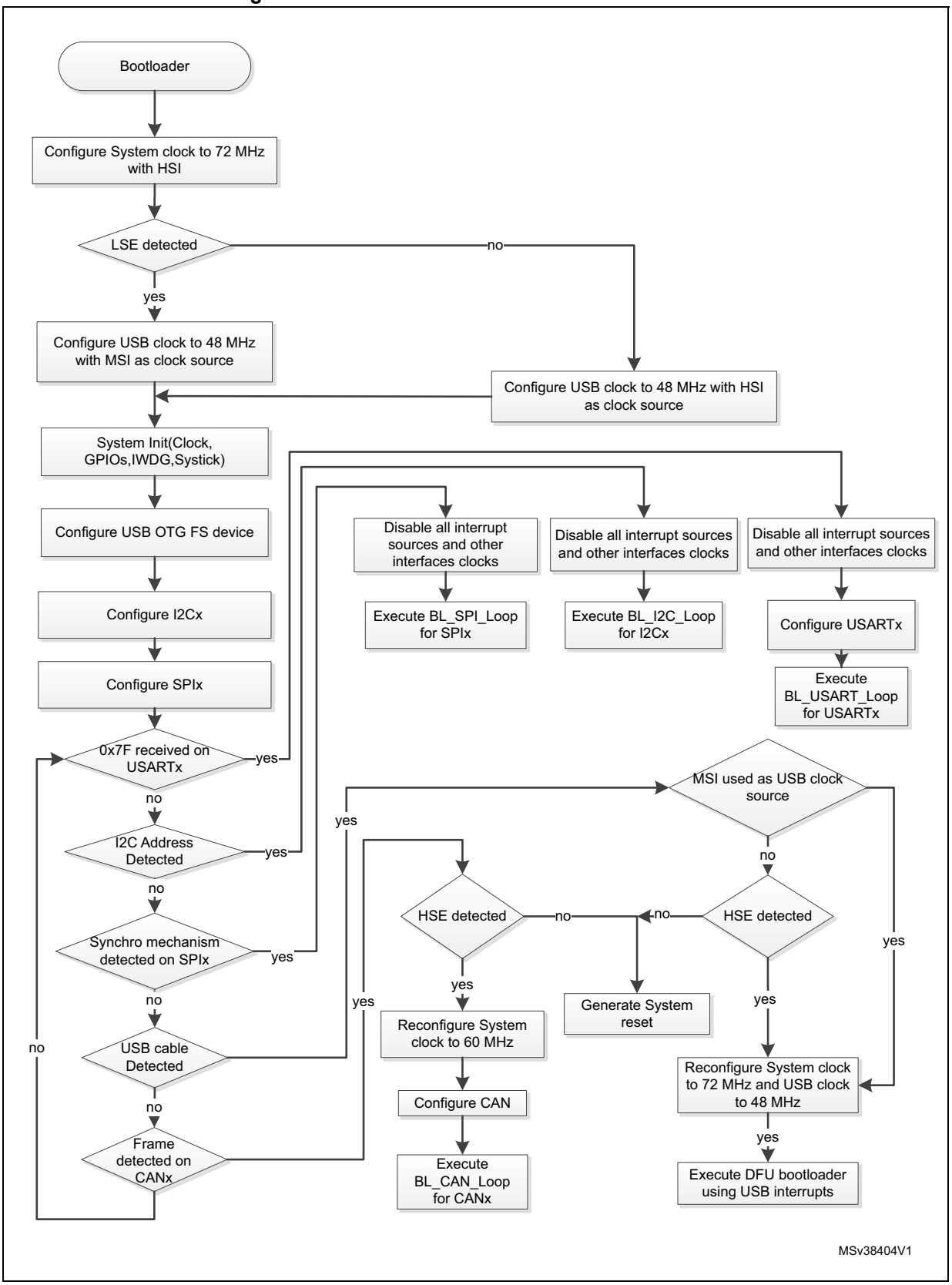


Figure 105.Bootloader V9.x selection for STM32L47xxx/48xxx



79.2.3 Bootloader version

Table 184 lists the STM32L47xxx/48xxx devices bootloader V9.x versions:

Table 184. STM32L47xxx/48xxx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	Initial bootloader version	For memory write operations using DFU interface: If the buffer size is larger than 256 bytes and not multiple of 8 bytes, the write memory operation result is corrupted. Workaround: if the file size is larger than 256 bytes, add byte padding to align it on 8-bytes multiple size. Write in SRAM is corrupted
V9.1	Deprecated version (not used)	None
V9.2	Fix write in SRAM issue	For memory write operations using DFU interface: If the buffer size is larger than 256 bytes and not multiple of 8 bytes, the write memory operation result is corrupted. Workaround: if the file size is larger than 256 bytes, add byte padding to align it on 8-bytes multiple size. PcROP option bytes cannot be written as the bootloader uses byte access while PcROP must be accessed using half-word access. Workaround: load a code snippet in SRAM using Bootloader interface then jump to it, and that code writes the PcROP value. During bootloader SPI write flash memory operation, some random 64 bits (2 double-words) may be left blank at 0xFF. Root cause: the bootloader uses 64-bit cast write operation, interrupted by SPI DMA. This leads to double access on same flash memory address, and the 64 bits are not written. Workarounds: – WA1: add a delay between sending write command and its ACK request. Its duration must be the duration of the 256-byte flash memory write time. – WA2: read back after write, and, in case of error, start write again. – WA3: patch in RAM to write in flash memory that implements write without 64-bit cast. WA1 and WA3 are more efficient than WA2 in terms of total programming time. The limitation leads to a modification in customer SPI host software by adding 3-4 ms delay to each write operation. This time is not lost, because it is anyway the flash memory write time, the host must wait anyway (so instead of waiting by sending ACK requests, host waits by delay). Limitation has been seen only on SPI and cannot impact USART/I2C/CAN/USB.

80 STM32L496xx/4A6xx devices

80.1 Bootloader configuration

The STM32L496xx/4A6xx bootloader is activated by applying Pattern 6 (described in *Table 2*). *Table 185* shows the hardware resources used by this bootloader.

Table 185. STM32L496xx/4A6xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 72 MHz and for USART, I2C and SPI bootloader operation.
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI 48 MHz.
		HSE enabled	The HSE is used only when the CAN interface is selected. The HSE must have one of the following values: 24,20,18,16,12,9,8,6,4 MHz.
		-	The CSS interrupt is enabled when HSE is enabled. Any failure (or removal) of the external clock generates system reset
	RAM	-	12 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The DFU cannot be used to communicate with bootloader if voltage scaling range 2 is selected. Bootloader firmware does not configure voltage scaling range value in PWR_CR1 register.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input no pull mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input no pull mode.

Table 185. STM32L496xx/4A6xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input no pull mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input no pull mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1001100x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1001100x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin		PB11 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1001100x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin		PC1 pin: data line is used in open-drain no pull mode.

Table 185. STM32L496xx/4A6xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. **Note**: This IO can be tied to GND if the SPI master does not use it.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. **Note:** This IO can be tied to GND if the SPI master does not use it.
CAN1	CAN1	Enabled	Once initialized the CAN1 configuration is:Baudrate 125 kbps, 11 -bit identifier.
	CAN1_RX pin	Input	PB8 pin: CAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN1_TX pin	Output	PB9 pin: CAN1 in transmission mode. Used in alternate push-pull, pull-up mode.
	TIM16	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

Table 185. STM32L496xx/4A6xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB OTG FS configured in forced device mode. USB OTG FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required

Note: If VDDUSB pin is not connected to V_{DD}, SPI flash memory write operations may be corrupted due to voltage issue. For more details, refer to product's datasheet and errata sheet.

80.2 Bootloader selection

The figures below show the bootloader selection mechanism.

Figure 106. Dual bank boot Implementation for STM32L496xx/4A6xx bootloader V9.x

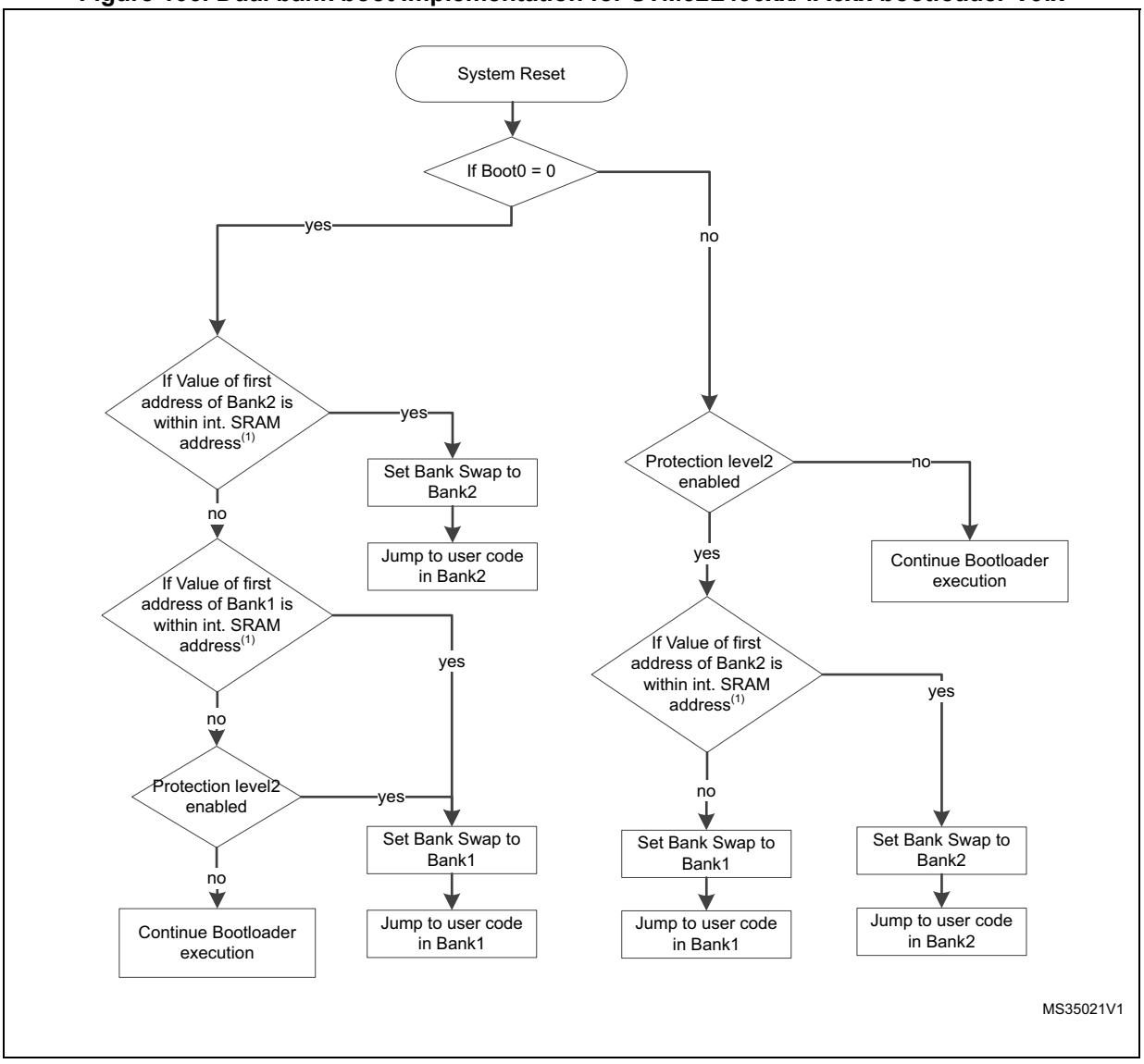
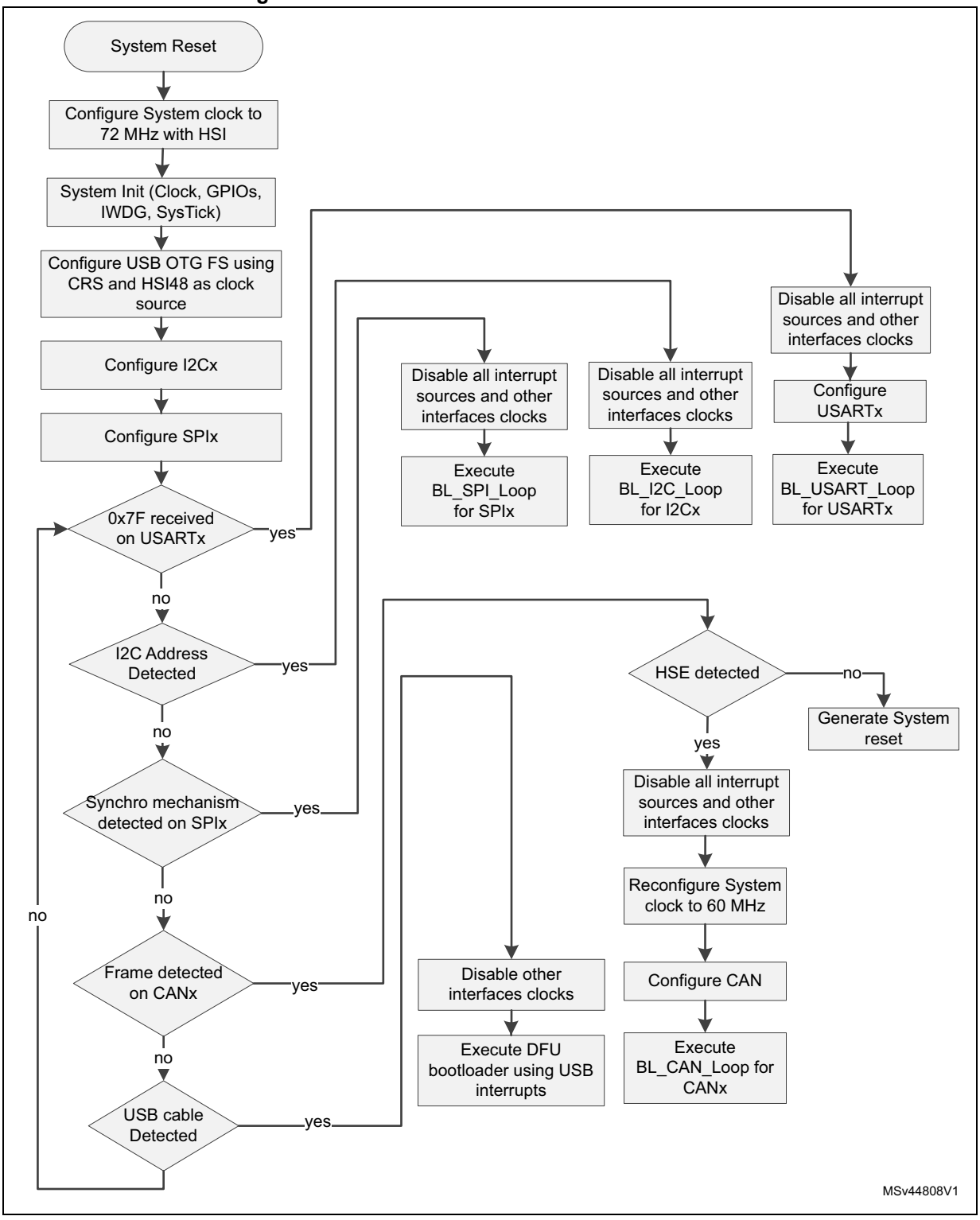


Figure 107.Bootloader V9.x selection for STM32L496xx/4A6xx



80.3 Bootloader version

Table 186 lists the STM32L496xx/4A6xx devices bootloader versions.

Table 186. STM32L496xx/4A6xx bootloader version

Version number	Description	Known limitations
V9.3	Initial bootloader version	– The Bank Erase command is aborted by the bootloader device, and the NACK (0x1F) is sent to the host. Workaround: Perform Bank erase operation through page erase using the Erase command (0x44). – SPI write operation fail **Limitation**: a. During Bootloader SPI write flash memory operation, some random 64-bits (2 double-words) may be left blank at 0xFF. **Root cause**: a. Bootloader uses 64-bits cast write operation which is interrupted by SPI DMA and it leads to double access on same flash memory address and the 64-bits are not written **Workarounds**: a. WA1: add a delay between sending write command and its ACK request. Its duration must be the duration of the 256-Bytes flash memory write time. b. WA2: read back after write and in case of error start write again. c. WA3: Patch in RAM to write in flash memory that implements write memory without 64-bits cast. WA1 and WA3 are more efficient than WA2 in terms of total programming time **How critical is the limitation**: a. The limitation leads to a modification in customer SPI host software by adding 3-4 ms delay to each write operation. b. The delay is not waste because it is anyway the flash memory write period of time that host has to wait anyway (so instead of waiting by sending ACK requests, host will wait by delay). c. Limitation has been seen only on SPI and cannot impact USART/I2C/CAN. – PcROP option bytes cannot be written as Bootloader uses Byte access while PcROP must be accessed using half-word access. **Workaround**: load a code snippet in SRAM using Bootloader interface then jump to it, and that code writes the PcROP value.

81 STM32L4P5xx/4Q5xx devices

81.1 Bootloader configuration

The STM32L4P5xx/4Q5xx bootloader is activated by applying Pattern 7 (described in *Table 2*). *Table 189* shows the hardware resources used by this bootloader.

Table 187. STM32L4P5xx/4Q5xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART, I2C, SPI and USB bootloader operation.
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI 48 MHz.
		HSE enabled	The HSE is used only when the CAN interface is selected. The HSE must have one of the following values 24, 20, 18, 16, 12, 9, 8, 6, 4 MHz.
		-	The CSS interrupt is enabled when HSE is enabled. Any failure (or removal) of the external clock generates system reset
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The DFU cannot be used to communicate with bootloader if the voltage scaling range 2 is selected. Bootloader firmware does not configure voltage scaling range value in PWR_CR1 register.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode

Table 187. STM32L4P5xx/4Q5xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1011011x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1011011x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin		PB11 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1011011x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin		PC1 pin: data line is used in open-drain no pull mode.

Table 187. STM32L4P5xx/4Q5xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. **Note**: This IO can be tied to GND if the SPI master does not use it.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. **Note:** This IO can be tied to GND if the SPI master does not use it.
CAN1	CAN1	Enabled	Once initialized the CAN1 configuration is: Baudrate 125 kbps, 11 -bit identifier.
	CAN1_RX pin	Input	PB8 pin: CAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN1_TX pin	Output	PB9 pin: CAN1 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 187. STM32L4P5xx/4Q5xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. **Note**: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required

81.2 Bootloader selection

Figure 110 and *Figure 111* show the bootloader selection mechanisms.

Figure 108. Dual bank boot implementation for STM32L4P5xx/4Q5xx bootloader V9.x

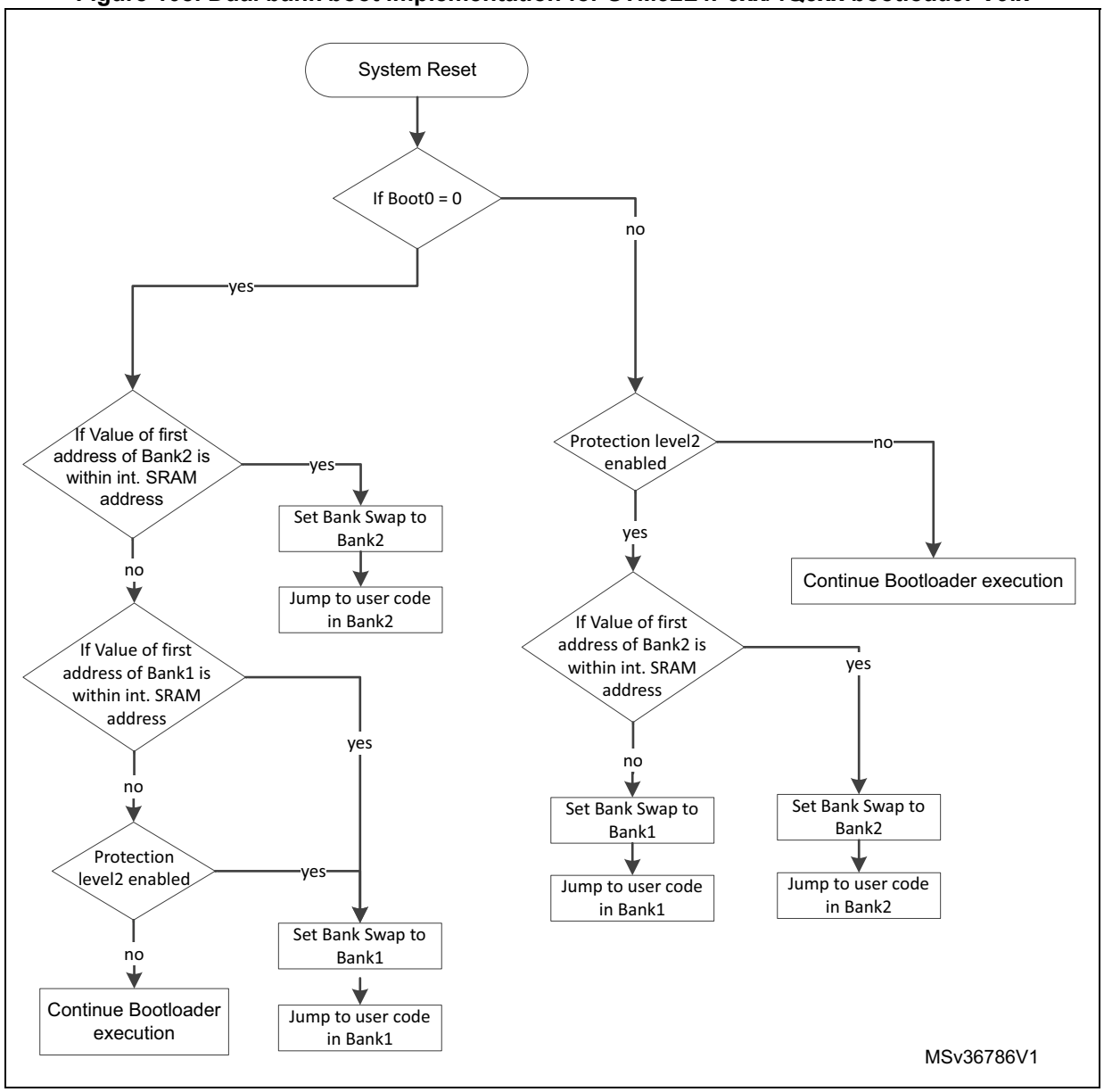
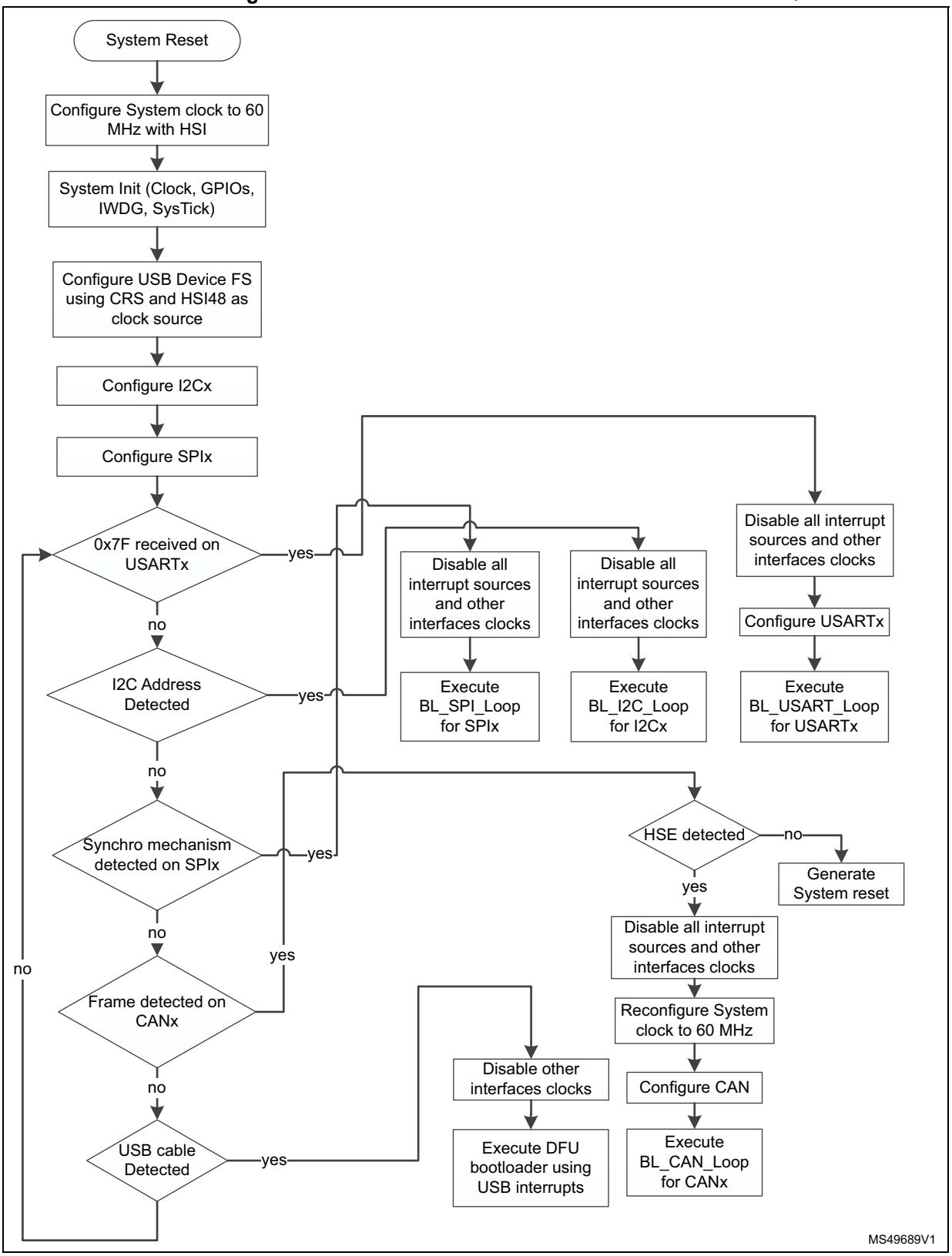


Figure 109.Bootloader V9.x selection for STM32L4P5xx/4Q5xx



81.3 Bootloader version

Table 188 lists the STM32L4P5xx/4Q5xx devices bootloader versions.

Table 188. STM32L4P5xx/4Q5xx bootloader versions

Version number	Description	Known limitations
V9.0	Initial bootloader version on cut 1.0 samples	– PcROP option bytes cannot be written as bootloader uses byte access while PcROP must be accessed using half-word access. **Workaround**: load a code snippet in SRAM using bootloader interface then jump to it, and that code writes PcROP value.

82 STM32L4Rxxx/4Sxxx devices

82.1 Bootloader configuration

The STM32L4Rxx/4Sxx bootloader is activated by applying Pattern 6 (described in *Table 2*). *Table 189* shows the hardware resources used by this bootloader.

Table 189. STM32L4Rxxx/4Sxxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART, I2C, SPI and USB bootloader operation.
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI 48 MHz.
		HSE enabled	The HSE is used only when the CAN interface is selected. The HSE must have one of the following values: 24, 20, 18, 16, 12, 9, 8, 6, 4 MHz.
		-	The CSS interrupt is enabled when HSE is enabled. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	28672 bytes starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The DFU cannot be used to communicate with bootloader if the voltage scaling range 2 is selected. Bootloader firmware does not configure voltage scaling range value in PWR_CR1 register.
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input pull-up mode.

Table 189. STM32L4Rxxx/4Sxxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1010000x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1010000x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain no pull mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1010000x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain no pull mode.

Table 189. STM32L4Rxxx/4Sxxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. **Note**: This IO can be tied to GND if the SPI master does not use it.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. **Note:** This IO can be tied to GND if the SPI master does not use it.
CAN1	CAN1	Enabled	Once initialized the CAN1 configuration is: Baudrate 125 kbps, 11 -bit identifier.
	CAN1_RX pin	Input	PB8 pin: CAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN1_TX pin	Output	PB9 pin: CAN1 in transmission mode. Used in alternate push-pull, pull-up mode.
	TIM16	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

Table 189. STM32L4Rxxx/4Sxxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. **Note**: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line.
	USB_DP pin		PA12: USB DP line No external pull-up resistor is required

82.2 Bootloader selection

Figure 110 and *Figure 111* show the bootloader selection mechanisms.

Figure 110. Dual bank boot implementation for STM32L4Rxxx/STM32L4Sxxx bootloader V9.x

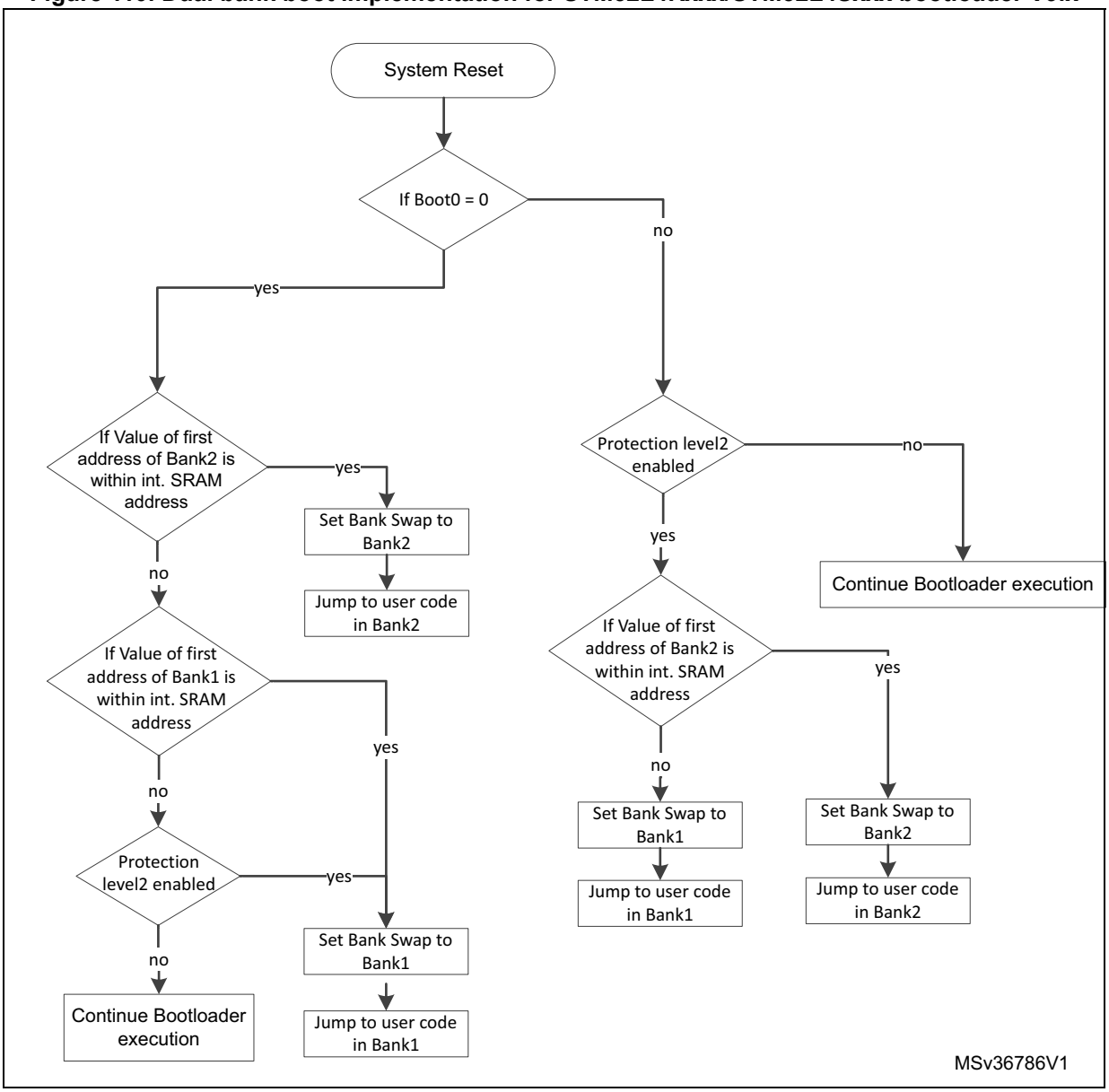
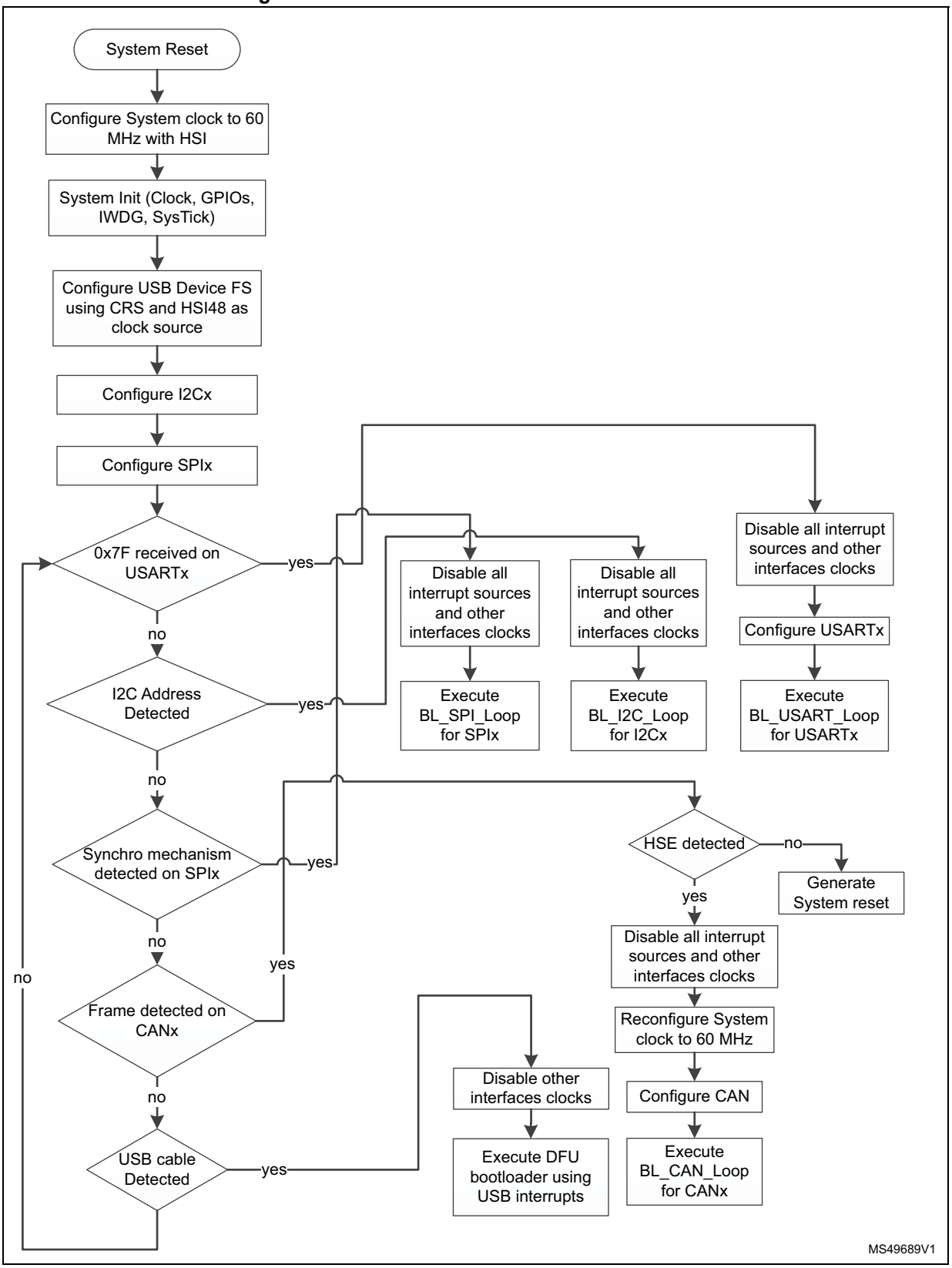


Figure 111.Bootloader V9.x selection for STM32L4Rxx/4Sxx



82.3 Bootloader version

Table 190 lists the STM32L4Rxx/4Sxx devices bootloader versions.

Table 190. STM32L4Rxx/4Sxx bootloader versions

Version number	Description	Known limitations
V9.0	Initial bootloader version on cut 1.0 samples	None

83 STM32L552xx/62xx devices

83.1 Bootloader configuration

The STM32L552xx/62xx bootloader is activated by applying Pattern 12 (described in *Table 2*). *Table 191* shows the hardware resources used by this bootloader.

The bootloader follows boot model V3_1 (see *Section 4.10*), so it inherits all its constraints.

Table 191. STM32L552xx/62xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz (using PLL clocked by HSI).
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI 48 MHz.
		-	20 MHz derived from the PLLQ is used for FDCAN
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	32 Kbytes, starting from address 0x0BF90000.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 191. STM32L552xx/62xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0101100x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain pull-up mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0101100x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin		PB11 pin: data line is used in open-drain pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b0101100x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin		PC1 pin: data line is used in open-drain pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. **Note:** This IO can be tied to GND if the SPI master does not use it.

Table 191. STM32L552xx/62xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. **Note:** This IO can be tied to GND if the SPI master does not use it.
SPI3	SPI3	Enabled	The SPI configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PB5 pin: slave data input line, used in push-pull, pull-down mode
	SPI3_MISO pin	Output	PG10 pin: slave data output line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PG9 pin: slave clock line, used in push-pull, pull-down mode
	SPI3_NSS pin	Input	PG12 pin: slave chip select pin used in push-pull, pull-down mode. **Note:** This IO can be tied to GND if the SPI master does not use it.
FDCAN	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input/	PB9 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	FDCAN1_Tx pin	Output	PB8 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 191. STM32L552xx/62xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. **Note**: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

Table 192. STM32L552xx/62xx special commands

Special commands supported (USART/I2C/SPI/FDCAN) Opcode - 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent**	**Number of data received**	**Data received**	**Number of status data received (2 bytes)**	**Status data received**
TrustZone disable Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x0	0x0	NA	0x1	0x0
Regression from RDP L1 to RDP 0.5 Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x1	0x0	NA	0x1	0x0

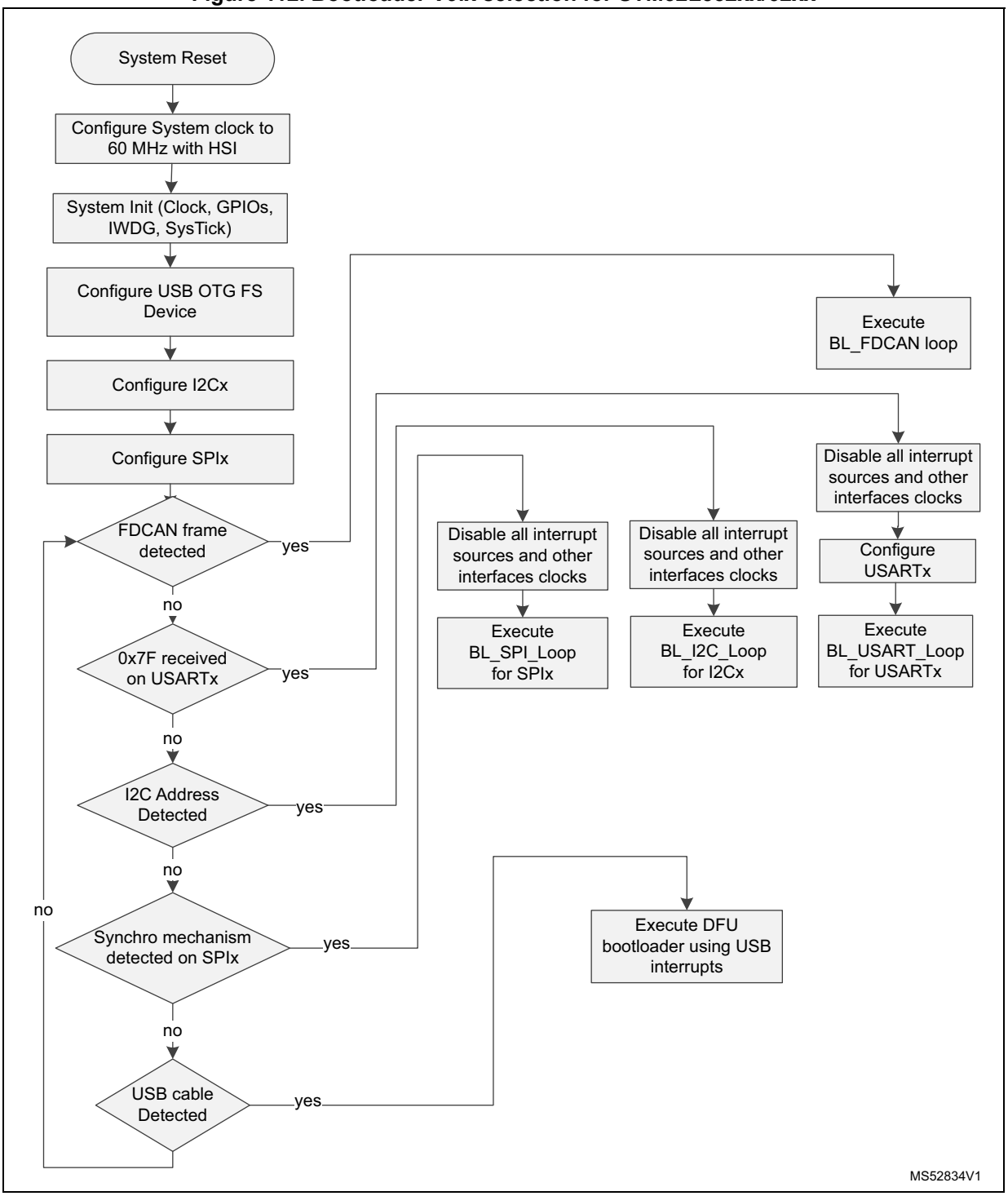
Note: USB special commands are slightly different from the other protocols as per the USB protocol specificities:

- *No Opcode is used, Sub-Opcode is used directly*
- *Sub-Opcode is treated in a single byte and not two bytes*
- *Data are sent on USB frame byte per byte. No need to add number of data to be transmitted*
- *Returned data and status are formatted on the USB native protocol*

83.2 Bootloader selection

Figure 112 shows the bootloader selection mechanism.

Figure 112. Bootloader V9.x selection for STM32L552xx/62xx



83.3 Bootloader version

Table 193 lists the STM32L552xx/62xx devices bootloader versions.

Table 193. STM32L552xx/62xx bootloader versions

Version number	Description	Known limitations
V13.0	Initial bootloader version on cut1.0 samples	– USART3 not working – SPI3 not working – OB launch not working on USB-DFU – No read/write SRAM2 in all protocols – Read Secure Option bytes only implemented on USART/I2C – Regression from TZEN = 1 to TZEN = 0 is done automatically on RDP regression
V9.0	Release supported only in cut2.0 – Fix all issues on previous release – Add FDCAN support – New command added for TZEN disable – Support of sales type 256 KB	– Unable to set TZEN to 1 option byte using all interfaces of the BL No workarounds available – Cannot set RDP level 0.5 nor option bytes in RDP level 0.5 using BL interfaces No workarounds available – Multiple reset seen when enabling HW IWDG option byte in TZEN = 1 No workarounds available – Unable to set secure option bytes setting when TZEN = 1 and RDP level is 0 No workarounds available – Go command on USB is not working – FDCAN erase not working as page number endianness is not aligned with the protocol (device waits for LSB first but host sends MSB first) – WA - Send data MSB first to the BL
V9.1	– Fix all known limitations of previous release – Add enable BOOT_LOCK BL command – Add support of RDP L1 to 0.5 regression	– Option byte programming is not working properly when using FDCAN interface. This makes the change of the Option byte not effective until a power off/power on. – FDCAN erase not working as page number endianness is not aligned with the protocol (device waits for LSB first but host sends MSB first) – WA - Send data MSB first to the BL
V9.2	– Fix all known limitations of previous release – Version for silicon revision Z	FDCAN Readout unprotect command does not send the command ID to the host

Note: When jumping to the BL the cache must be disabled.

84 STM32WB10xx/15xx devices

84.1 Bootloader configuration

The STM32WB10xx/15xx bootloader is activated by applying Pattern 6 (described in *Table 2*). *Table 196* shows the hardware resources used by this bootloader.

Table 194. STM32WB10xx/15xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	MSI enabled	The system clock frequency is 64 MHz (using PLL clocked by MSI).
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1001111x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain no pull mode.

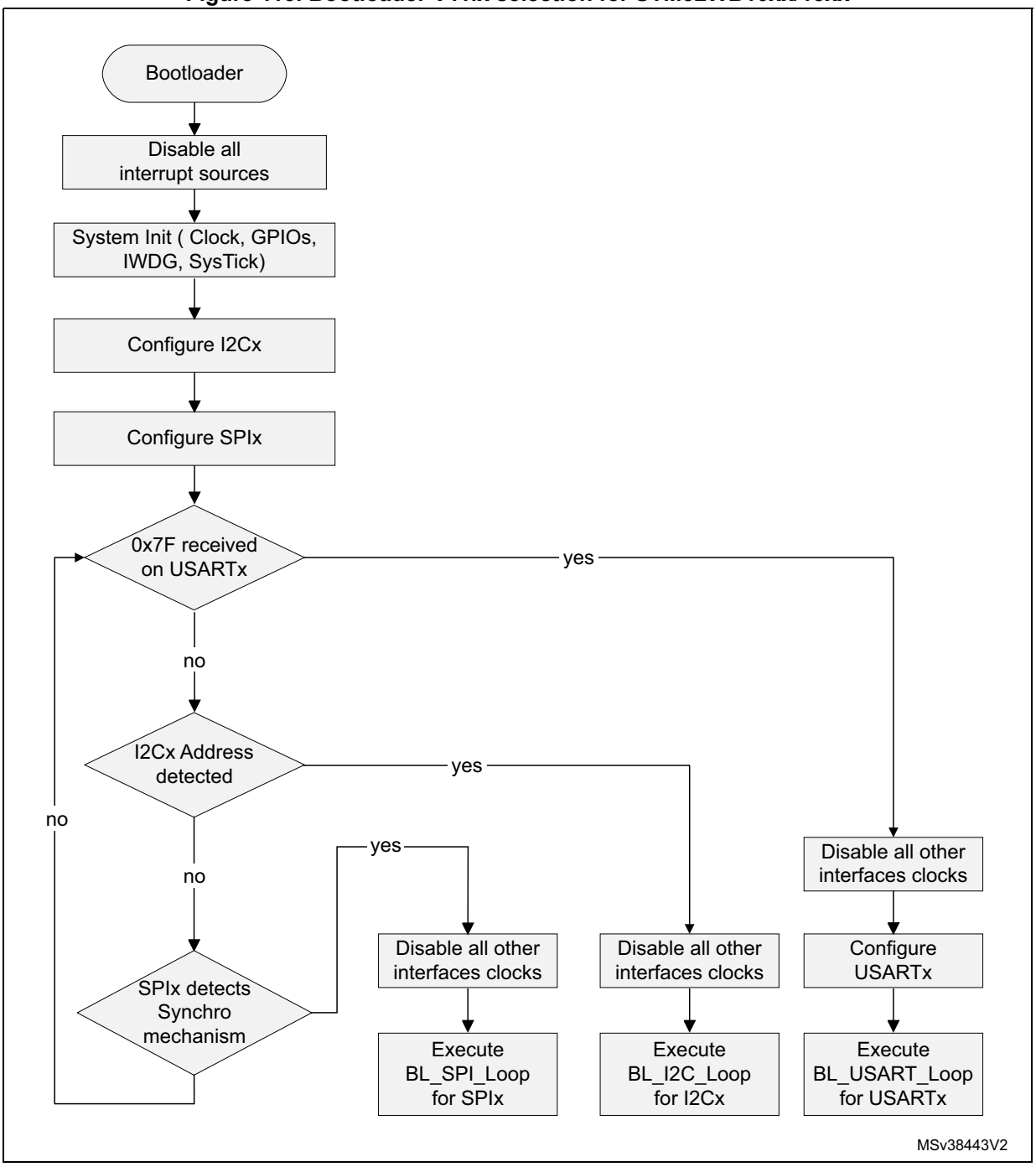
Table 194. STM32WB10xx/15xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.

84.2 Bootloader selection

Figure 113 shows the bootloader selection mechanism.

Figure 113. Bootloader V11.x selection for STM32WB10xx/15xx



84.3 Bootloader version

Table 195. STM32WB10xx/15xx bootloader versions

Version number	Description	Known limitations
V11.1	Initial bootloader version	– I2C Write Protect command (0x73) performs a Read Unprotect instead of disabling write protection. – Workaround: Use No-Stretch Write Unprotect command (0x74) that is performing correctly the write unprotect operation

85 STM32WB30xx/35xx/50xx/55xx devices

85.1 Bootloader configuration

The STM32WB30xx/35xx/50xx/55xx bootloader is activated by applying Pattern 16 (described in *Table 2*). *Table 196* shows the hardware resources used by this bootloader.

Table 196. STM32WB30xx/35xx/50xx/55xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	MSI enabled	The system clock frequency is 64 MHz (using PLL clocked by MSI).
		-	CRS is enabled for the DFU to allow USB to be clocked by HSI 48 MHz.
	RAM	-	20 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1001111x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.

Table 196. STM32WB30xx/35xx/50xx/55xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1001111x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain no pull mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.

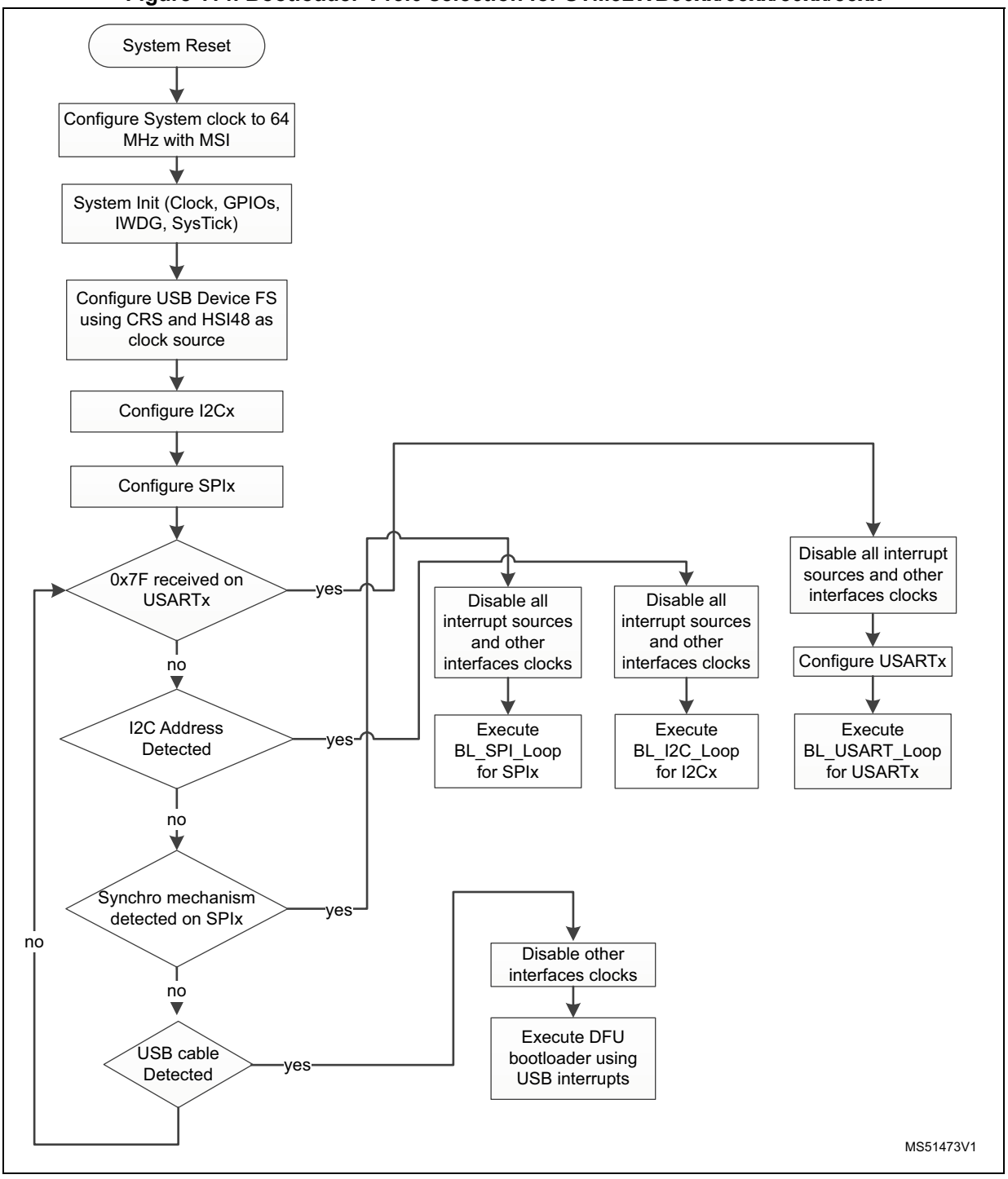
Table 196. STM32WB30xx/35xx/50xx/55xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. **Note:** This IO can be tied to GND if the SPI master does not use it.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. **Note**: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

85.2 Bootloader selection

Figure 114 shows the bootloader selection mechanism.

Figure 114. Bootloader V13.0 selection for STM32WB30xx/35xx/50xx/55xx



85.3 Bootloader version

Table 197. STM32WB30xx/35xx/50xx/55xx bootloader versions

Version number	Description	Known limitations
V13.5	Initial bootloader version	– Readout Unprotect Command is not working properly as at the end of the command an NVIC_SystemReset is done instead of a flash option bytes reload. This makes the change of the RDP level not effective until a power off/on. – I2C Write Protect command (0x73) performs a Read Unprotect instead of disabling write protection. Workaround: Uses No-Stretch Write Unprotect command (0x74) that is performing correctly the write unprotect operation

Note: Instability when performing multiple resets during operations ongoing causing Overrun or FrameError errors on USART Bootloader and not recoverable unless Hardware Reset is performed. Fixed by workaround in FUS V1.0.1 and V1.0.2.

86 STM32WBA5xxx devices

86.1 Bootloader configuration

The STM32WBA5xxx bootloader is activated by applying Pattern12 (described in *Table 2*). *Table 198* shows the hardware resources used by this bootloader.

The bootloader follows boot model V3_1 (see *Section 4.10*), so it inherits all its constraints.

Table 198. STM32WBA5xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz (using PLL clocked by HSI).
	RAM	-	6 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x0BF88000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA8 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PB12 pin: USART1 in transmission mode. Not set until USART1 is detected.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA11 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA12 pin: USART2 in transmission mode. Not set until USART2 is detected.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1100110x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB2 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin		PB1 pin: data line is used in open-drain pull-up mode.

Table 198. STM32WBA5xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1100110x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA6 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin		PA7 pin: data line is used in open-drain pull-up mode.
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PB8 pin: slave data input line, used in push-pull, no pull mode
	SPI3_MISO pin	Output	PB9 pin: slave data output line, used in push-pull, no pull mode
	SPI3_SCK pin	Input	PA0 pin: slave clock line, used in push-pull, no pull mode
	SPI3_NSS pin		PA5 pin: slave chip select pin used in push-pull, no pull mode.

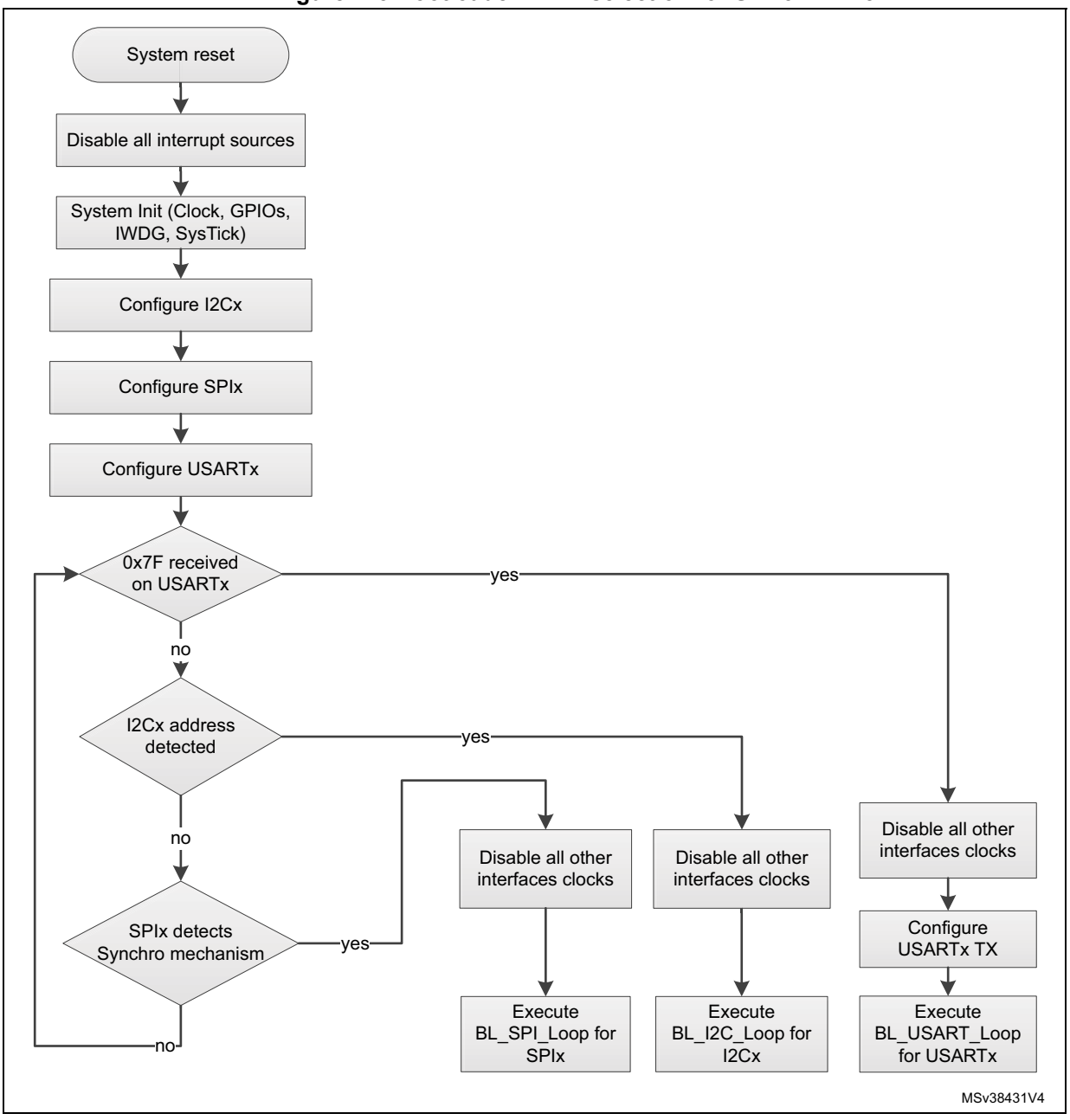
Table 199. STM32WBA5xxx special commands

Special commands supported (USART/I2C/SPI) Opcode - 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent**	**Number of data received**	**Data received**	**Number of status data received (2 bytes)**	**Status data received**
TrustZone disable Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x0	0x0	NA	0x1	0x0
Regression from RDP L1 to RDP 0.5 Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x1	0x0	NA	0x1	0x0
Unlock write protection Must be run when RDP = 1	0x82	0x4	0xYY02[1]	0x0	NA	0x1	0x0

1. 0xYY can have three values (0: WRP area, 1: WRP1A, 2: WRP2A)

86.2 Bootloader selection

Figure 115.Bootloader V11.x selection for STM32WBA5xxx



86.3 Bootloader version

Table 200. STM32WBA5xxx bootloader versions

Version number	Description	Known limitations
V11.0	Initial bootloader version for Rev A samples	None
V11.1	Initial bootloader version for Rev B samples	None

87 STM32WBA2xxx devices

87.1 Bootloader configuration

The STM32WBA2xxx bootloader is activated by applying Pattern12 (see *Table 2*). *Table 201* shows the hardware resources used by this bootloader.

The bootloader follows boot model V3_1 (see *Section 4.10*), so it inherits all its constraints.

Table 201. STM32WBA2xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 48 MHz with PLL.
		HSE enabled	By reading the engineering bytes we can check if the USB FS IP is enabled on the package or not. When USB FS is enabled, the HSE is enabled from the startup. Once HSE is ready, it is considered as the main entry for the PLL and system clock is switched to HSE through PLL. The clock of USB is 48 MHz taken from HSE with PLL.
	RAM	-	12 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	28 Kbytes, starting from address 0x0BF85000, contain the bootloader firmware.
	IWDG	-	The independent watchdog (IWDG) prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (in case the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the USART1 configuration is: 8 bits, even parity and 1 Stop bit.
	USART1_RX pin	Input	PA12 pin: Used in QFN48-SMPS-USB and WLCSP37 packages. PA8 pin: Used in packages QFN32 and QFN48-SMPS. USART1 in reception mode. Used in alternate push-pull, pull-up mode
	USART1_TX pin	Output	PA6 pin: Used in QFN48-SMPS-USB and WLCSP37 packages. PB12 pin: Used in packages QFN32 and QFN48-SMPS. USART1 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.

Table 201. STM32WBA2xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: - I2C speed: up to 400 kHz - 7-bit address - Target mode - Analog filter ON - Target 7-bit address: 0b1111000x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/Output	PA15 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/Output	PB3 pin: data line is used in open-drain pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: - I2C speed: up to 400Khz - 7-bit address - Target mode - Analog filter ON - Target 7-bit address: 0b1111000x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/Output	PB2 pin: used in all packages except QFN32 and QFN48-SMPS. PA6 pin: used in packages QFN32 and QFN48-SMPS. Clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/Output	PA11 pin: used in all packages except QFN32 and QFN48-SMPS. PA7 pin: used in packages QFN32 and QFN48-SMPS. Data line is used in open-drain pull-up mode.

Table 201. STM32WBA2xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI3	SPI3_MOSI pin	Input	PA6 pin: used in all packages except QFN32 and QFN48-SMPS. Slave data Input line, used in push-pull, no pull mode. PB8 pin: used in packages QFN32 and QFN48-SMPS. Slave data Input line, used in push-pull, pull-down mode.
	SPI3_MISO pin(1)	Output	PB4 pin: used in all packages except QFN32 and QFN48-SMPS. PB9 pin: used in packages QFN32 and QFN48-SMPS. Slave data output line, used in push-pull, pull-down mode.
	SPI3_SCK pin	Input	PA8 pin: used in all packages except QFN32 and QFN48-SMPS. PA0 pin: used in packages QFN32 and QFN48-SMPS. Slave clock line, used in push-pull, pull-down mode.
	SPI3_NSS pin	Input	PA5 pin: slave chip select pin used in push-pull, pull-down mode.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/Output	PB9 pin: Not configured by bootloader SW, but reserved by HW to the USB peripheral once enabled by the bootloader SW.
	USB_DP pin		PB8 pin: Not configured by bootloader SW, but reserved by HW to the USB peripheral once enabled by the bootloader SW.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

Table 202. STM32WBA2xxx special commands

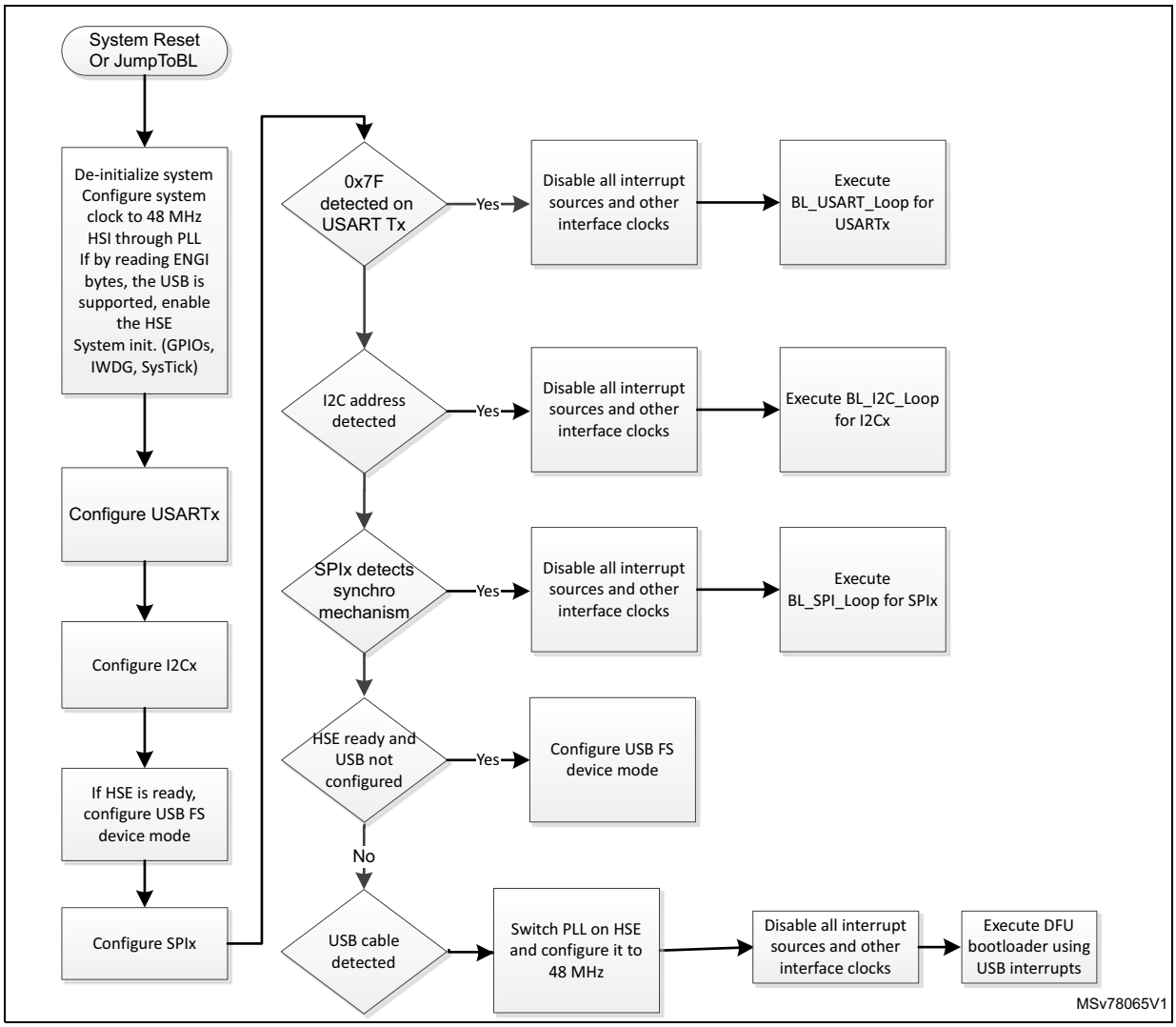
Special commands supported (USART/I2C/SPI) Opcode – 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent**	**Number of data received**	**Data received (2 bytes)**	**Number of status data received (2 bytes)**	**Status data received**
TrustZone disable Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x0	0x0	NA	0x1	0x0
Regression from RDP L1 to RDP 0.5 Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x1	0x0	NA	0x1	0x0
Unlock write protection Must be run when RDP = 1	0x82	0x4	0xYY02 (1)	0x0	NA	0x1	0x0

1. 0xYY can have three values (0: all WRP areas, 1: WRP1A, 2: WRP1B).

Note: USB special commands differ from other protocols due to USB protocol specificities:
- No opcode is used; the sub-opcode is used directly.
- The sub-opcode is treated as a single byte, not two bytes.
- Data is sent on the USB frame byte by byte; there is no need to specify the number of data bytes to be transmitted.
- Returned data and status are formatted according to the native USB protocol.

87.2 Bootloader selection

Figure 116. Bootloader V13.x selection for STM32WBA2xxx



87.3 Bootloader version

Table 203. STM32WBA2xxx bootloader versions

Version number	Description	Known limitations
V13.0	Initial bootloader version	None

88 STM32WBA62xx/63xx/64xx/65xx devices

88.1 Bootloader configuration

The STM32WBA62xx/63xx/64xx/65xx bootloader is activated by applying Pattern12 (described in *Table 2*). *Table 204* shows the hardware resources used by this bootloader.

The bootloader follows boot model V3_1 (see *Section 4.10*), so it inherits all its constraints.

Table 204. STM32WBA62xx/63xx/64xx/65xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz (using HSI through PLL1 source).
		HSE enabled	Enabled only when USB cable detected. HSE must be 32 MHz to have the USB working.
	RAM	-	12 Kbytes, starting from address 0x2000 0000 are used by the bootloader firmwaree
	System memory	-	64 Kbytes, starting from address 0x0BF9 0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA8 pin: USART1 in reception mode. Used in alternate function, pull-up mode.
	USART1_TX pin	Output	PB12 pin: USART1 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA11 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA12 pin: USART2 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1101111x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB2 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin		PB1 pin: data line is used in open-drain no pull mode.

Table 204. STM32WBA62xx/63xx/64xx/65xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1101111x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA6 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin		PA7 pin: data line is used in open-drain no pull mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB14 pin: Slave data Input line, used in alternate function with no pull.
	SPI2_MISO pin(1)	Output	PB0 pin: Slave data output line used in alternate function with no pull.
	SPI2_SCK pin	Input	PA9 pin: Slave clock line, used in alternate function with no pull.
	SPI2_NSS pin		PA10 pin: slave chip select pin used in alternate function with no pull.
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PB8 pin: Slave data Input line, used in alternate function with pull down.
	SPI3_MISO pin	Output	PB9 pin: Slave data output line used in alternate function with no pull.
	SPI3_SCK pin	Input	PA0 pin: Slave clock line, used in alternate function with no pull.
	SPI3_NSS pin		PA5 pin: slave chip select pin used in alternate function with no pull.
DFU	USB	Enabled	USB configured in device mode. USB interrupt vector is enabled and used for DFU communications.
	USB_DM pin	Input/output	PD7: USB DM line. Used in alternate function, no pull mode.
	USB_DP pin		PD6: USB DP line. Used in alternate function, no pull mode. No external pull-up resistor is required.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization, as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

Table 205. STM32WBA62xx/63xx/64xx/65xx special commands

Special commands supported (USART/I2C/SPI) Opcode - 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent**	**Number of data received**	**Data received**	**Number of status data received (2 bytes)**	**Status data received**
TrustZone disable Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x0	0x0	NA	0x1	0x0
Regression from RDP L1 to RDP 0.5 Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x1	0x0	NA	0x1	0x0
Unlock write protection Must be run when RDP = 1	0x82	0x4	0xYY02(1)	0x0	NA	0x1	0x0

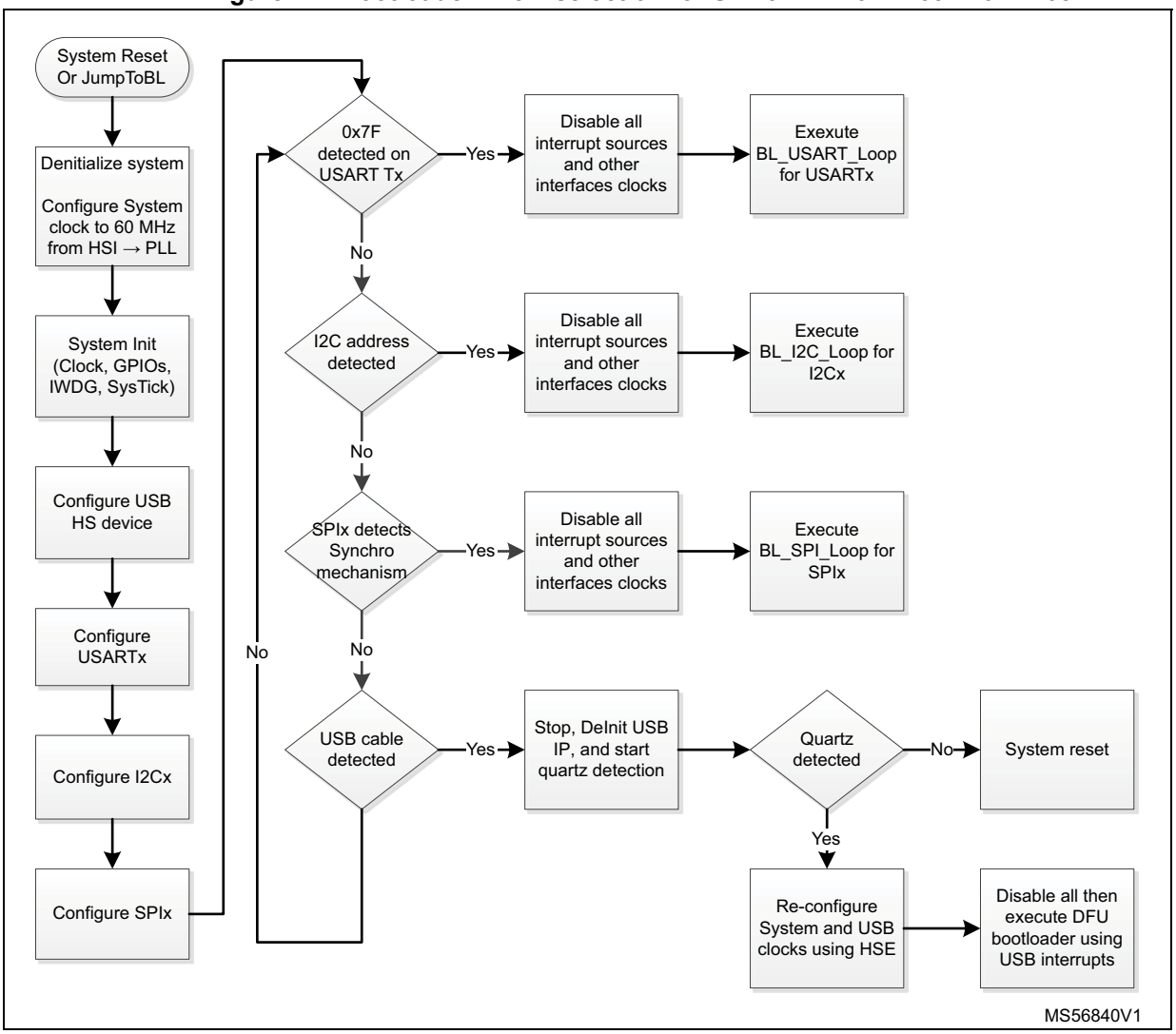
1. 0xYY can have three values (0: WRP area, 1: WRP1A, 2: WRP2A)

Note: USB special commands are slightly different from the other protocols as per the USB protocol specificities:

- *No Opcode is used, Sub-Opcode is used directly*
- *Sub-Opcode is treated in a single byte and not in two bytes*
- *Data are sent on USB frame byte per byte. No need to add the number of data to be transmitted*
- *Returned data and status are formatted on the USB native protocol*

88.2 Bootloader selection

Figure 117.Bootloader V13.2 selection for STM32WBA62xx/63xx/64xx/65xx



88.3 Bootloader version

Table 206. STM32WBA62xx/63xx/64xx/65xx bootloader versions

Version number	Description	Known limitations
V13.2	Initial bootloader version	None

89 STM32WB05xx devices

89.1 Bootloader configuration

The STM32WB05xx bootloader is activated by applying Pattern 18 (described in *Table 2*). *Table 207* shows the hardware resources used by this bootloader.

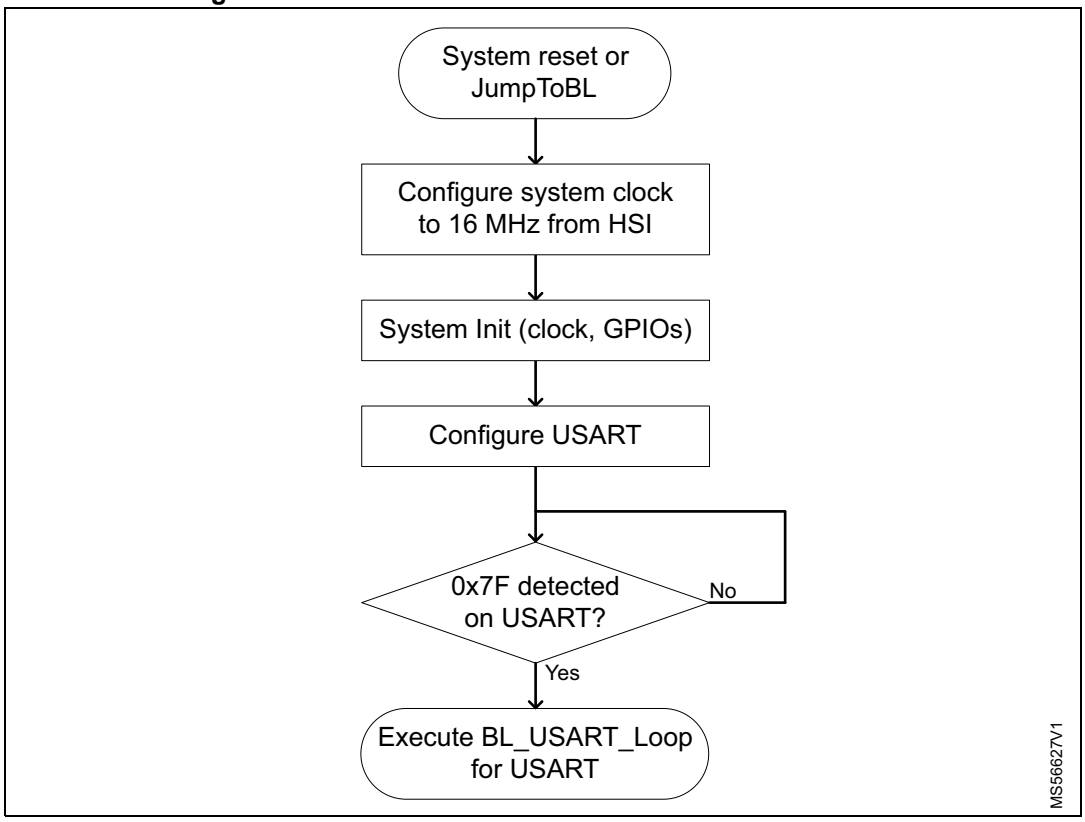
Table 207. STM32WB05xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 16 MHz using HSI
	RAM	-	The last 3 Kbytes of the last bank
	System memory	-	6 Kbytes, starting from address 0x10000000, contain the bootloader firmware
USART	USART	Enabled	Once initialized, the configuration is 8-bit, no parity
	USART_RX pin	Input	PB0 pin: USART in reception mode. Used in alternate push-pull, pull-up mode.
	USART_TX pin	Output	PA1 pin: USART in transmission mode. Not set until USART is detected.

89.2 Bootloader selection

Figure 118 shows the bootloader selection mechanism.

Figure 118. Bootloader V2.x selection for STM32WB05xx



89.3 Bootloader version

Table 208. STM32WB05xx bootloader versions

Version number	Description	Known limitations
V2.0	Final bootloader version	None

90 STM32WB06xx/07xx devices

90.1 Bootloader configuration

The STM32WB06xx/07xx bootloader is activated by applying Pattern 18 (described in *Table 2*). *Table 209* shows the hardware resources used by this bootloader.

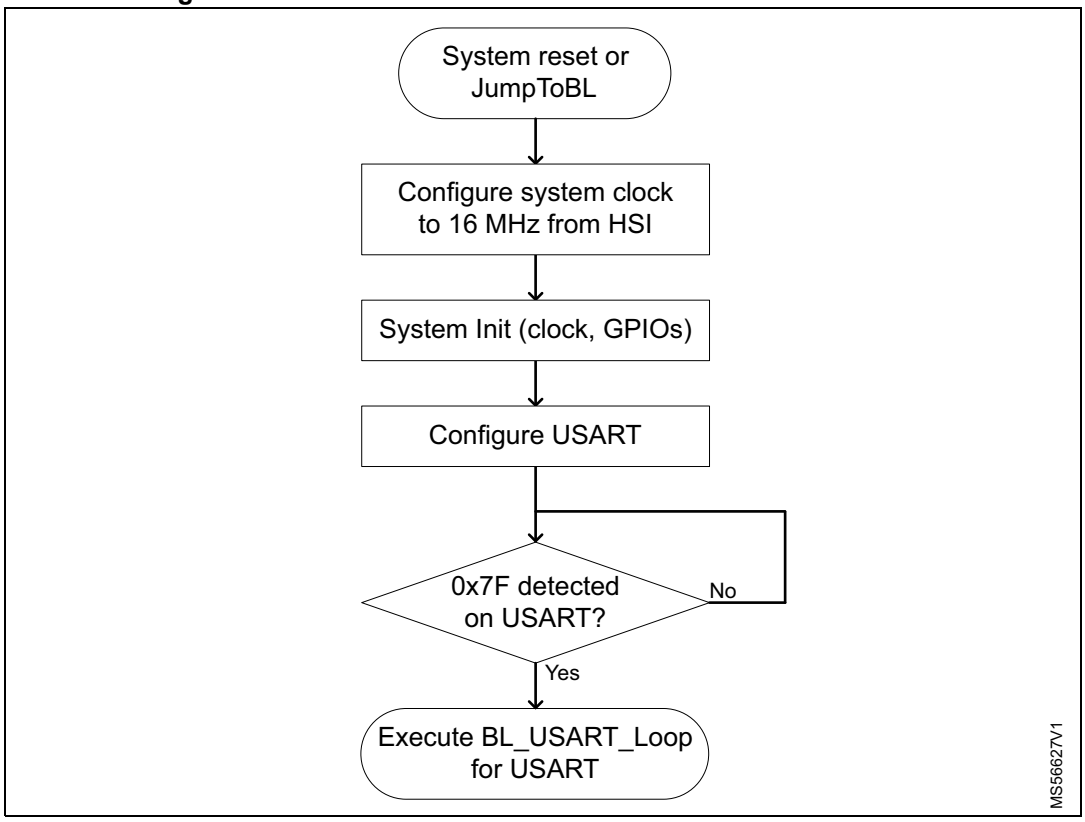
Table 209. STM32WB06xx/07xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 16 MHz using HSI
	RAM	-	The last 3 Kbytes of the last bank
	System memory	-	6 Kbytes, starting from address 0x10000000, contain the bootloader firmware
USART	USART	Enabled	Once initialized, the configuration is 8-bit, no parity
	USART_RX pin	Input	PA8 pin: USART in reception mode. Used in alternate push-pull, pull-up mode.
	USART_TX pin	Output	PA9 pin: USART in transmission mode. Not set until USART is detected.

90.2 Bootloader selection

Figure 119 shows the bootloader selection mechanism.

Figure 119. Bootloader V4.x selection for STM32WB06xx/07xx



90.3 Bootloader version

Table 210. STM32WB06xx/07xx bootloader versions

Version number	Description	Known limitations
V4.0	Final bootloader version	None

91 STM32WB09xx devices

91.1 Bootloader configuration

The STM32WB09xx bootloader is activated by applying Pattern 18 (described in *Table 2*). *Table 211* shows the hardware resources used by this bootloader.

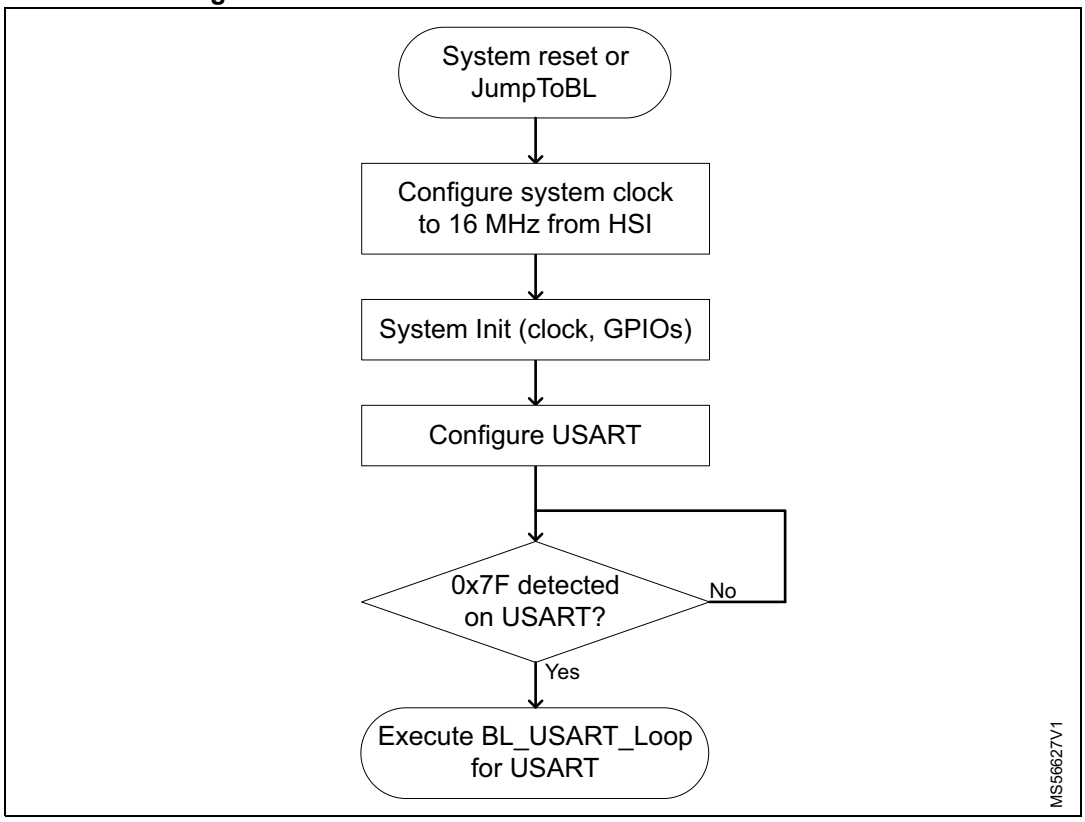
Table 211. STM32WB09xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 16 MHz using HSI
	RAM	-	The last 3 Kbytes of the last bank
	System memory	-	6 Kbytes, starting from address 0x10000000, contain the bootloader firmware
USART	USART	Enabled	Once initialized, the configuration is 8-bit, no parity
	USART_RX pin	Input	PB0 pin: USART in reception mode. Used in alternate push-pull, pull-up mode.
	USART_TX pin	Output	PA1 pin: USART in transmission mode. Not set until USART is detected.

91.2 Bootloader selection

Figure 122 shows the bootloader selection mechanism.

Figure 120. Bootloader V1.x selection for STM32WB09xx



91.3 Bootloader version

Table 212. STM32WB09xx bootloader versions

Version number	Description	Known limitations
V1.0	Final bootloader version	None

92 STM32WL3xxx devices

92.1 Bootloader configuration

The STM32WL3xxx bootloader is activated by applying Pattern 18 (described in *Table 2*). *Table 213* shows the hardware resources used by this bootloader.

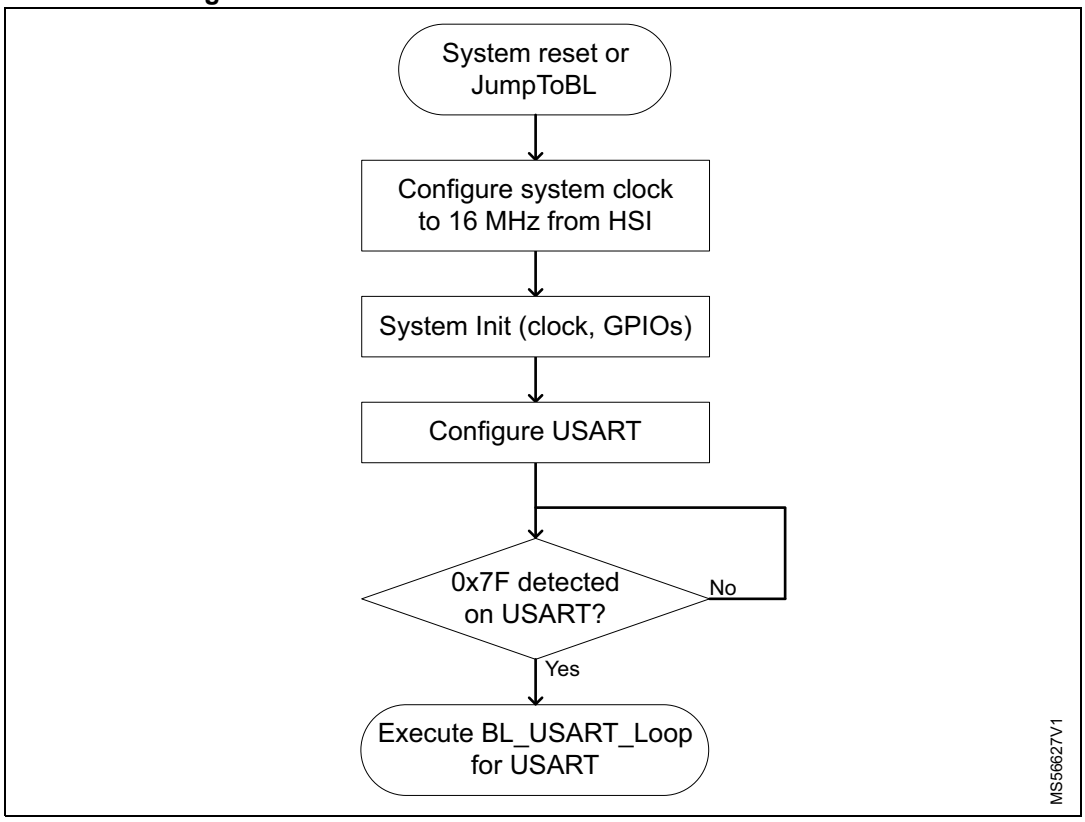
Table 213. STM32WL3xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 16 MHz using HSI
	RAM	-	The last 3 Kbytes of the last bank
	System memory	-	6 Kbytes, starting from address 0x10000000, contain the bootloader firmware
USART	USART	Enabled	Once initialized, the configuration is 8-bit, no parity
	USART_RX pin	Input	For QFN48 package: UART Rx = PA15 For QFN32 package: UART Rx = PB14
	USART_TX pin	Output	UART Tx = PA1

92.2 Bootloader selection

Figure 121 shows the bootloader selection mechanism.

Figure 121. Bootloader V12.x selection for STM32WL3xxx



92.3 Bootloader version

Table 214. STM32WL3xxx bootloader versions

Version number	Description	Known limitations
V4.0	Initial bootloader version	None

93 STM32WLE5xx/55xx devices

93.1 Bootloader configuration

The STM32WLE5xx/55xx bootloader is activated by applying Pattern 13 (described in *Table 2*). *Table 215* shows the hardware resources used by this bootloader.

Table 215. STM32WLE5xx/55xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 48 MHz (using PLL clocked by HSI).
	RAM	-	8 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	16 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.

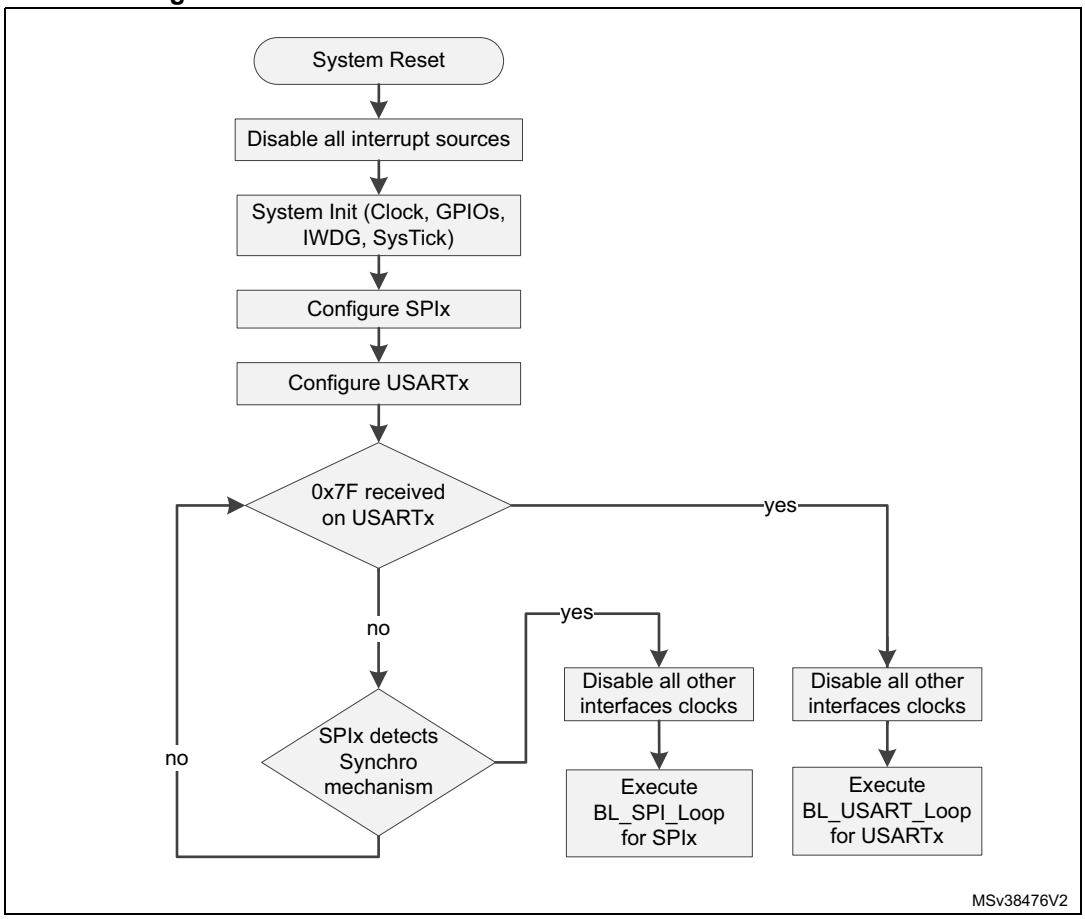
Table 215. STM32WLE5xx/55xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. **Note:** This IO can be tied to GND if the SPI master does not use it.

93.2 Bootloader selection

Figure 122 shows the bootloader selection mechanism.

Figure 122. Bootloader V12.x selection for STM32WLE5xx/55xx



93.3 Bootloader version

Table 216. STM32WLE5xx/55xx bootloader versions

Version number	Description	Known limitations
V12.2	Initial bootloader version on rev. Z samples	BL cannot write/read the following option bytes: – FLASH_SFR (Offset - 0x80) – FLASH_SRRVR (Offset - 0x84)
V12.3	Final bootloader version on rev. Z samples	BL cannot write/read the following option bytes: – FLASH_SFR (Offset - 0x80) – FLASH_SRRVR (Offset - 0x84)
V12.4	Final bootloader version on rev. Y samples	BL cannot write/read the following option bytes: – FLASH_SFR (Offset - 0x80) – FLASH_SRRVR (Offset - 0x84)

94 STM32U031xx devices

94.1 Bootloader configuration

The STM32U031xx bootloader is activated by applying Pattern 11 (described in *Table 2*). *Table 217* shows the hardware resources used by this bootloader.

Table 217. STM32U031xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI16 enabled	The system clock frequency is 24 MHz (using PLL clocked by HSI16).
	RAM	-	5 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	14 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF3500
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART in reception mode. Used in alternate function input, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX. PA11 is remapped to PA9 on the TSSOP20 package.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART in reception mode. Used in alternate function input, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART in reception mode. Used in alternate function input, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.
	EXTI line 11	Input	Used on detection on USART and its IT for baudrate calculation

Table 217. STM32U031xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1101011x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain pull-up mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1101011x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin		PB11 pin: data line is used in open-drain pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1101011x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PB3 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin		PB4 pin: data line is used in open-drain pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in alternate function, pull-down mode
	SPI1_MISO pin(1)	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in alternate function, pull-down mode. PA1 pin is used instead of PA5 on TSSOP20 package. Used on push-pull, pull-up mode
	SPI1_NSS pin		PA4 pin: slave chip select pin used in alternate function, pull-down mode.

Table 217. STM32U031xx configuration in system memory boot mode (continued)

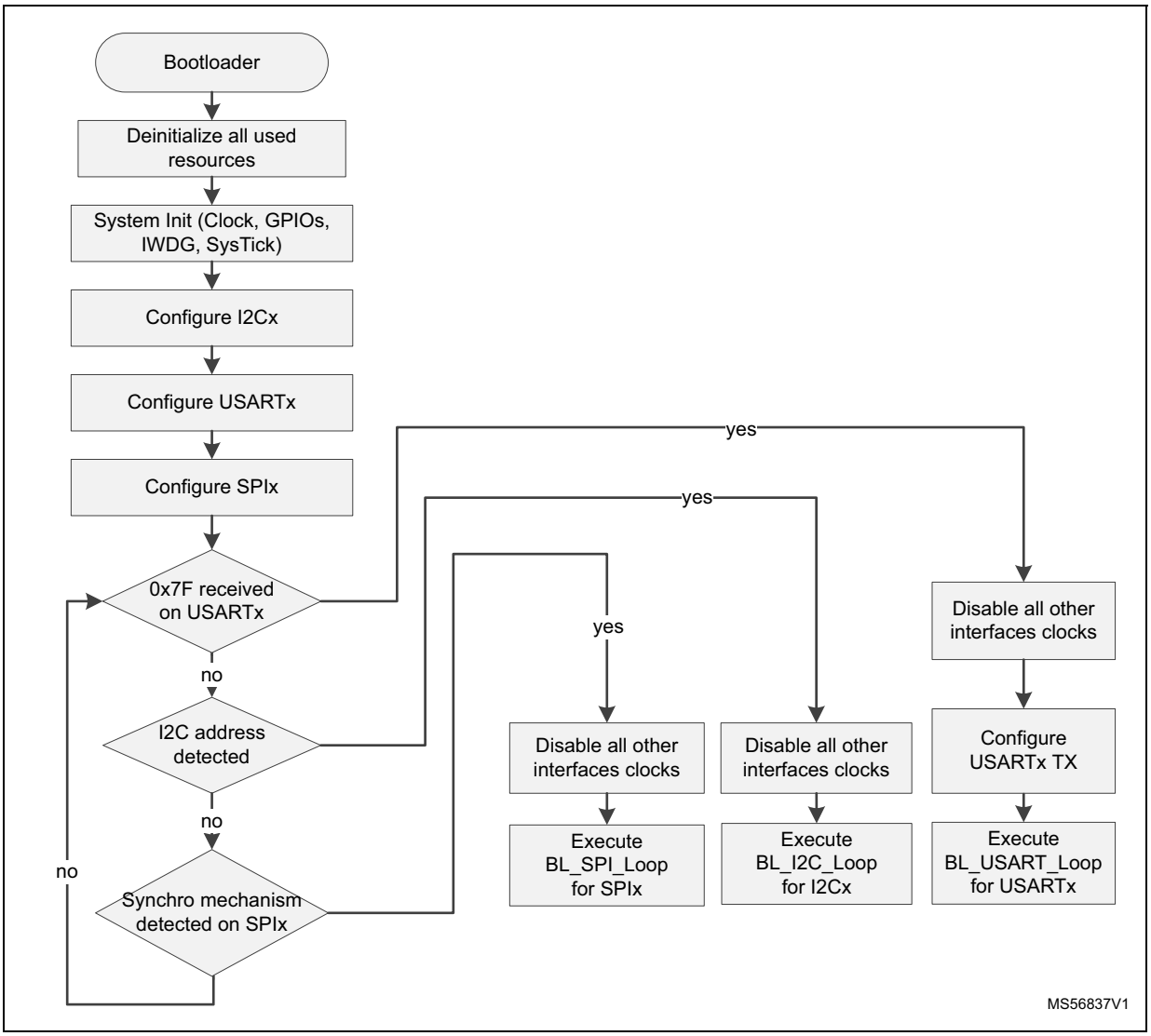
Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in alternate function, no pull mode
	SPI2_MISO pin(1)	Output	PB14 pin: slave data output line, used in push-pull, no pull mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in alternate function, no pull mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in alternate function, no pull mode.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization, as soon as the bit DMATx enable on SPI CR2 register is set to 1, the MISO line is set to 3.3 V.

94.2 Bootloader selection

Figure 123 shows the bootloader selection mechanism.

Figure 123. Bootloader V11.x selection for STM32U031xx



94.3 Bootloader version

Table 218. STM32U031xx bootloader versions

Version number	Description	Known limitations
V11.1	Initial bootloader version	Empty check flag cleared by error on the bootloader startup phase – Root cause: on the startup phase the bootloader SW performs a system deinitialization, leading to write the default value on the FLASH_ACR register, which overrides the Empty check bit with 0 – Behavior: when Empty check boot mode is used and the flash memory is empty, the MCU boots on the bootloader but the flag is cleared by the SW. If a reset is triggered, the system tries to boot on the empty flash memory, and crashes. – **Caution**: Avoid using reset on this case. if the system crashes, an option byte change or POR is needed to reboot.

95 STM32U073xx/83xx devices

95.1 Bootloader configuration

The STM32U073xx/83xx bootloader is activated by applying Pattern 11 (described in *Table 2*). *Table 219* shows the hardware resources used by this bootloader.

Table 219. STM32U073xx/83xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 24 MHz (using PLL clocked by HSI).
		HSI48 enabled	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI48 48 MHz
	RAM	-	8.5 Kbytes, starting from address 0x2000000, are used by the bootloader firmware
	System memory	-	26 Kbytes, starting from address 1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF6000
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART in reception mode. Used in alternate function, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART in reception mode. Used in alternate function, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART in reception mode. Used in alternate function, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART in transmission mode. Kept in reset configuration until 0x7F is detected on USART_RX.
	EXTI line 11	Input	Used on detection on USART and its IT for baudrate calculation

Table 219. STM32U073xx/83xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1101010x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain pull-up mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1101010x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin		PB11 pin: data line is used in open-drain pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1101010x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PB3 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin		PB4 pin: data line is used in open-drain pull-up mode.
SPI1	SPI	Enabled	The SPI configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in alternate function, pull-down mode
	SPI1_MISO pin(1)	Output	PA6 pin: slave data output line, used in push pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in alternate function, pull-down mode
	SPI1_NSS pin		PA4 pin: slave chip select pin used in alternate function, pull-down mode.

Table 219. STM32U073xx/83xx configuration in system memory boot mode (continued)

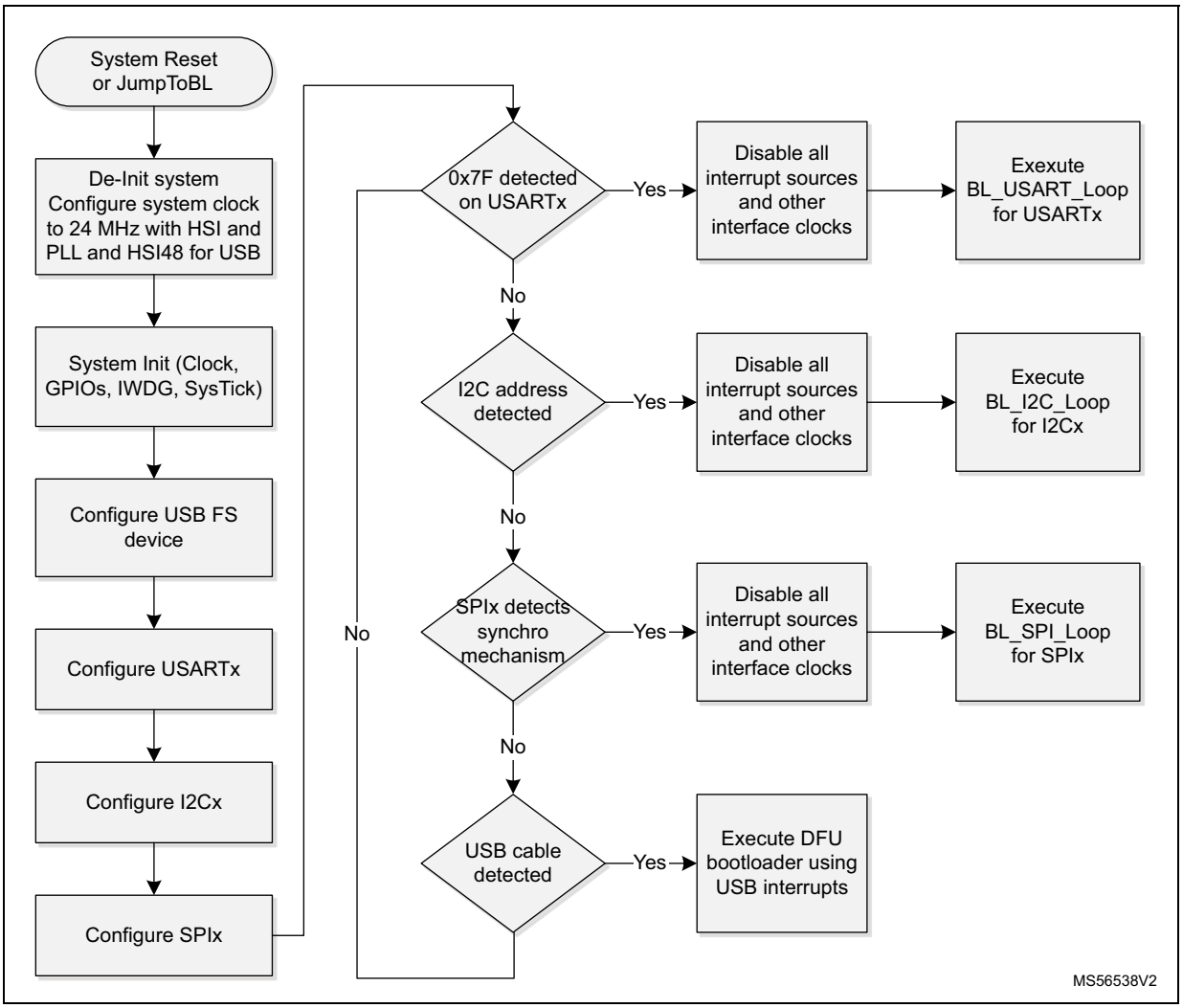
Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI	Enabled	The SPI configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in alternate function, pull-down mode
	SPI2_MISO pin(1)	Output	PB14 pin: slave data output line, used in push-pull, pull mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in alternate function, pull-down mode
	SPI2_NSS pin		PB12 pin: slave chip select pin used in alternate function, pull-down mode.
DFU	USB	Enabled	USB configured in device mode. USB interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in additional function mode, behaving as input until communication starts.
	USB_DP pin		PA12: USB DP line. Used in additional function mode, behaving as input until communication starts.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization, as soon as the bit DMATx enable on SPI CR2 register is set to 1, the MISO line is set to 3.3 V.

95.2 Bootloader selection

Figure 124 shows the bootloader selection mechanism.

Figure 124. Bootloader V13.x selection for STM32U073xx/83xx



95.3 Bootloader version

Table 220. STM32U073xx/83xx bootloader versions

Version number	Description	Known limitations
V13.0	Initial bootloader version	Empty check flag cleared by error on the bootloader startup phase – Root cause: on the startup phase the bootloader SW performs a system deinitialization, leading to write the default value on the FLASH_ACR register, which overrides the Empty check bit with 0 – Behavior: when Empty check boot mode is used and the flash memory is empty, the MCU boots on the bootloader but the flag is cleared by the SW. If a reset is triggered, the system tries to boot on the empty flash memory, and crashes. – **Caution**: Avoid using reset on this case. if the system crashes, an option byte change or POR is needed to reboot.

96 STM32U375xx/85xx devices

96.1 Bootloader configuration

The STM32U375xx/85xx bootloader is activated by applying Pattern 12 (described in *Table 2*). *Table 221* shows the hardware resources used by this bootloader.

The bootloader follows boot model V3_1 (see *Section 4.10*), so it inherits all its constraints.

Table 221. STM32U375xx/85xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	MSI enabled	The system clock frequency is 48 MHz (using MSIS source, that is, MSI divided by 2)).
		-	48 MHz derived from the MSIK (MSI divided by 2) is used for FDCAN
		HSI48	CRS is enabled for the DFU so that USB can be clocked by HSI 48 MHz
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	40 Kbytes, starting from address 0xBF8 F000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate function, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate function, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1101100x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.

Table 221. STM32U375xx/85xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1011010x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1011010x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: Slave data Input line, used in alternate function with pull down. On release v14.2, PG4 pin is used instead of PA7 on WLCSP68-G package. Used on alternate function with pull down.
	SPI1_MISO pin(1)	Output	PA6 pin: Slave data output line used in alternate function with pull down. On release v14.2, PG3 pin is used instead of PA6 on WLCSP68-G package. Used on alternate function with pull down.
	SPI1_SCK pin	Input	PA5 pin: Slave clock line, used in alternate function with pull down. On release v14.2, PG2 pin is used instead of PA5 on WLCSP68-G package. Used on alternate function with pull down.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in alternate function with pull down. On release v14.2, PG5 pin is used instead of PA4 on WLCSP68-G package. Used on alternate function with pull down.

Table 221. STM32U375xx/85xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PD4 pin: Slave data Input line, used in alternate function with pull down.
	SPI2_MISO pin(1)	Output	PD3 pin: Slave data output line used in alternate function with pull down.
	SPI2_SCK pin	Input	PD1 pin: Slave clock line, used in alternate function with pull down.
	SPI2_NSS pin	Input	PD0 pin: slave chip select pin used in alternate function with pull down.
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PB5 pin: Slave data Input line, used in alternate function with pull down.
	SPI3_MISO pin(1)	Output	PB4 pin: Slave data output line used in alternate function with pull down.
	SPI3_SCK pin	Input	PB3 pin: Slave clock line, used in alternate function with pull down.
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in alternate function with pull down.
FDCAN1	FDCAN1	Enabled	Once initialized the configuration is: – Connection bit rate 600 kbit/s – Data bit rate 2400 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input/	PB8 pin: FDCAN1 in reception mode. Used in alternate function, pull-up mode.
	FDCAN1_Tx pin	Output	PB9 pin: FDCAN1 in transmission mode. Used in alternate function, pull-up mode.

Table 221. STM32U375xx/85xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB configured in device mode. USB interrupt vector is enabled and used for DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate function with no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate function with no pull mode. No external pull-up resistor is required.
I3C1	I3C	Enabled	Mode: target mode Aval timing:0x4E DMA Reg RX: disabled DMA Req TX: disabled Status FIFO: disabled DMA Req status: disabled DMA Req control: disabled IBI: enabled Additional data after IBI ack-ed: 1 byte IBI configuration: Mandatory Data Byte (MDB) All IT disabled except RXFNE (Receive FIFO Interrupt) The RXFNE interruption is disabled after SYNC byte detection by the bootloader.
	I3C_SCL pin	Input/Output	PB13 pin: clock line is used in open-drain pull-up mode.
	I3C_SDA pin	Input/Output	PA1 pin: clock line is used in open-drain pull-up mode.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

96.2 SPI1 pinout on WLCSP68-G

The SPI1 pinout on the WLCSP68-G package is different from all the other packages: it uses pins PG5/PG2/PG3/PG4 instead of pins PA4/PA5/PA6/PA7. This makes it possible to use an independent voltage for the SPI1 pins through VDDIO2, to provide them a voltage different from the global MCU voltage (3.3 V).

When using 1.2 V for these pins, the HSLV feature must be enabled on PortG. To protect this feature, which can damage the pins in case of bad usage, some SW option bytes are reserved. Bits 22 and 23 from Flash OPTR registers must be written to 0b11 while enabling IOHSLV feature (refer to RM0487 for OPTR register description).

96.3 Boot model

The bootloader follows boot model V3_1 (see *Section 4.10*), so it inherits all its constraints.

Table 222. STM32U375xx/385xx special commands

Special commands supported (USART/I2C/SPI/FDCAN) Opcode - 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent**	**Number of data received**	**Data received**	**Number of status data received (2 bytes)**	**Status data received**
TrustZone disable Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x0	0x0	NA	0x1	0x0
Regression from RDP L1 to RDP 0.5 Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x1	0x0	NA	0x1	0x0
Unlock write protection Must be run when RDP = 1	0x82	0x4	0xYY02(1)	0x0	NA	0x1	0x0

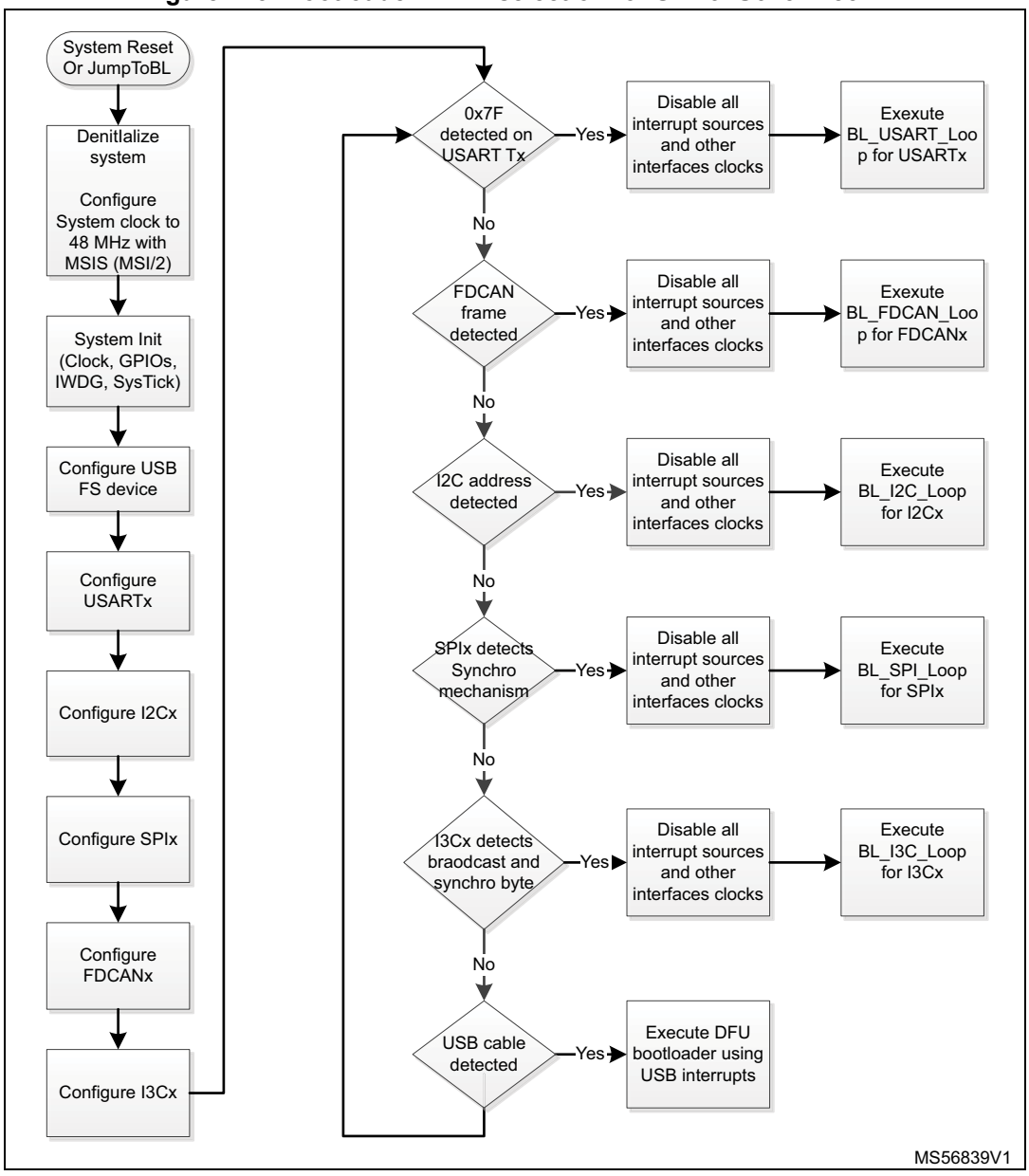
1. 0xYY can have five values (0: WRP area, 1: WRP1A, 2: WRP2A, 3: WRP1B, 4: WRP2B)

Note: USB special commands are slightly different from the other protocols as per the USB protocol specificities:

- *No Opcode is used, Sub-Opcode is used directly*
- *Sub-Opcode is treated in a single byte and not two bytes*
- *Data are sent on USB frame byte per byte. No need to add number of data to be transmitted*
- *Returned data and status are formatted on the USB native protocol*

96.4 Bootloader selection

Figure 125. Bootloader V14.2 selection for STM32U375xx/85xx



96.5 Bootloader version

Table 223. STM32U375xx/85xx bootloader versions

Version number	Description	Known limitations
V14.1	Initial bootloader version	– Erasing multiple flash memory pages at the same time is not working, only the first page is erased – FDCAN: cannot erase more than 32 flash memory sectors on the same time
V14.2	– Correct known limitations – Switch SPI1 support on PortG when using WLCSP68-G package instead of PortA – Add SW OB support to Enable HSLV for PortG SPI1 pins	– FDCAN: cannot erase more than 32 flash memory sectors on the same time

97 STM32U3B5xx/3C5xx devices

97.1 Bootloader configuration

The STM32U3B5xx/3C5xx bootloader is activated by applying Pattern12 (see *Table 2*). *Table 224* shows the hardware resources used by this bootloader.

The bootloader follows boot model V3_1 (see *Section 4.10*), so it inherits all its constraints.

Table 224. STM32U3B5xx/3C5xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	MSI enabled	The system clock frequency is 48 MHz (using MSIS source, that is, MSI divided by 2).
			48 MHz derived from the MSIK (MSI divided by 2) is used for FDCAN.
		HSI48 enabled	CRS is enabled for the DFU so that USB can be clocked by HSI 48 MHz.
	RAM	-	16 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System Memory	-	40 Kbytes starting from address 0x0BF8F000, contain the bootloader firmware.
	IWDG	-	The independent watchdog (IWDG) prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (in case the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the USART1 configuration is: 8 bits, even parity and 1 Stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.
USART3	USART3	Enabled	Once initialized, the USART3 configuration is: 8 bits, even parity and 1 Stop bit.
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Kept in reset configuration until 0x7F detected on USART_RX.

Table 224. STM32U3B5xx/3C5xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: - I2C speed: up to 400 kHz - 7-bit address - Target mode - Analog filter ON - Target 7-bit address: 0b1110011x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/Output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/Output	PB7 pin: data line is used in open-drain pull-up mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: - I2C speed: up to 400 kHz - 7-bit address - Target mode - Analog filter ON - Target 7-bit address: 0b1110011x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/Output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/Output	PB11 pin: data line is used in open-drain pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: - I2C speed: up to 400 kHz - 7-bit address - Target mode - Analog filter ON - Target 7-bit address: 0b1110011x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/Output	PC0 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/Output	PC1 pin: data line is used in open-drain pull-up mode.

Table 224. STM32U3B5xx/3C5xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: Slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin(1)	Output	PA6 pin: Slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: Slave clock line, used in push-pull, pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PD4 pin: Slave data Input line, used in push-pull, pull-down mode.
	SPI2_MISO pin(1)	Output	PD3 pin: Slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PD1 pin: Slave clock line, used in push-pull, pull-down mode.
	SPI2_NSS pin	Input	PD0 pin: slave chip select pin used in push-pull, pull-down mode.
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PB5 pin: Slave data Input line, used in push-pull, pull-down mode.
	SPI3_MISO pin(1)	Output	PB4 pin: Slave data output line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PB3 pin: Slave clock line, used in push-pull, pull-down mode.
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, pull-down mode.

Table 224. STM32U3B5xx/3C5xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
FDCAN	FDCAN1	Enabled	Once initialized, the FDCAN1 configuration is: – Connection bit rate 600 kbit/s – Data bit rate 2400 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PB8 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	FDCAN1_Tx pin	Output	PB9 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-up mode.
I3C	I3C1	Enabled	– Mode: target mode – Aval timing:0x4E – DMA Reg RX: disabled – DMA Req TX: disabled – Status FIFO: disabled – DMA Req status: disabled – DMA Req control: disabled – IBI: enabled – Additional data after IBI ack-ed: 1 byte – IBI configuration: Mandatory Data Byte (MDB) – All IT disabled except RXFNE (Receive FIFO Interrupt). The RXFNE interruption is disabled after SYNC byte detection by the bootloader.
	I3C1_SCL pin	Input/Output	PB13 pin: I3C1 in transmission mode. Configured in alternate push-pull, pull-up then switched to no pull mode.
	I3C1_SDA pin		PA1 pin: I3C1 in transmission mode. Configured in alternate push-pull, pull-up then switched to no pull mode.
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/Output	PA11 pin: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

Table 225. STM32U3B5xx/3C5xx special commands

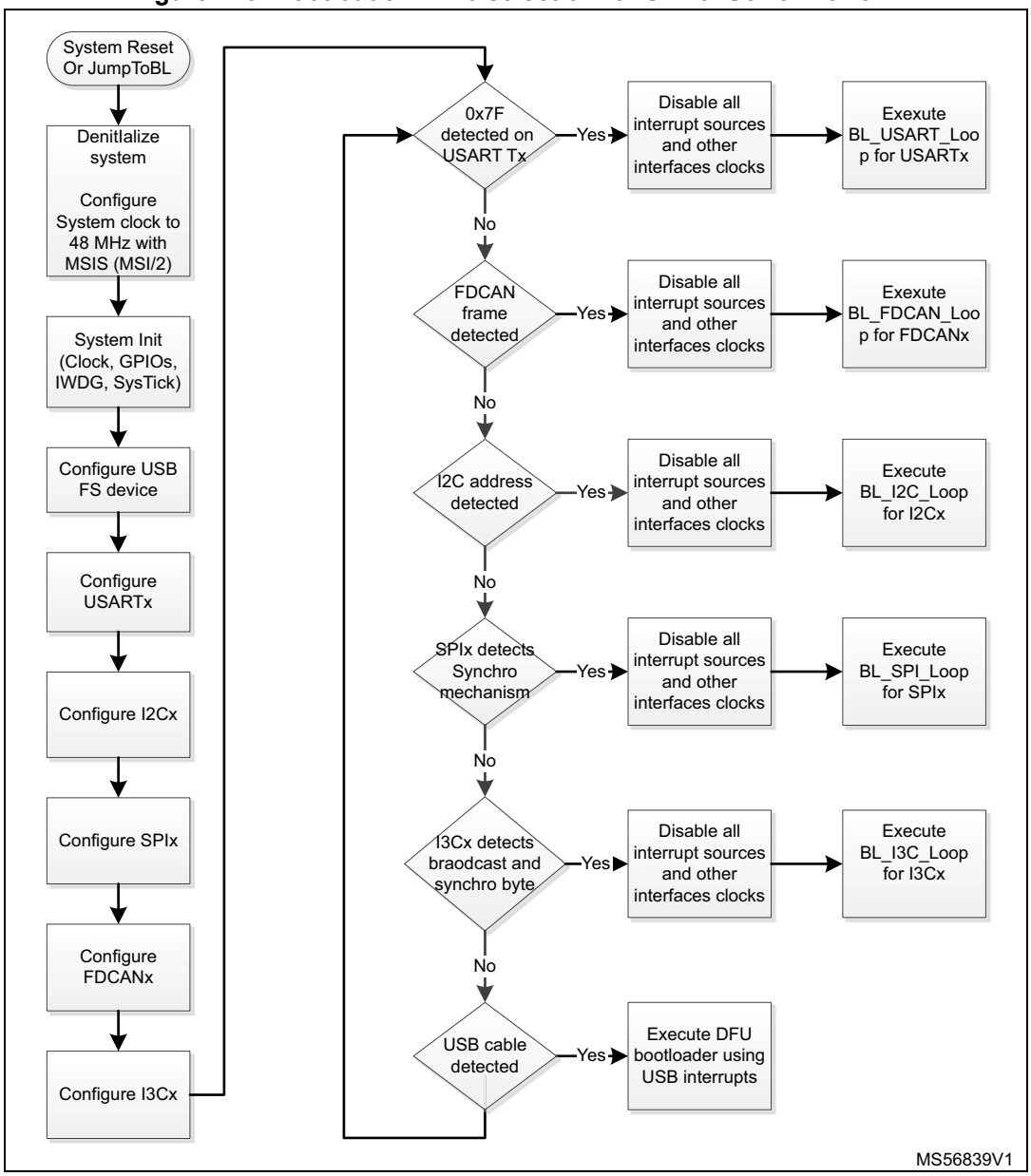
Special commands supported (USART/I2C/I3C/SPI/FDCAN) Opcode – 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent**	**Number of data received**	**Data received (2 bytes)**	**Number of status data received (2 bytes)**	**Status data received**
TrustZone disable Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x0	0x0	NA	0x1	0x0
Regression from RDP L1 to RDP 0.5 Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x1	0x0	NA	0x1	0x0
Unlock write protection Must be run when RDP = 1	0x82	0x4	0xYY02 (1)	0x0	NA	0x1	0x0

1. 0xYY can have five values (0: all WRP areas, 1: WRP1A, 2: WRP1B, 3: WRP2A, 4: WRP2B).

Note: USB special commands differ from other protocols due to USB protocol specificities:
- No opcode is used; the sub-opcode is used directly.
- The sub-opcode is treated as a single byte, not two bytes.
- Data is sent on the USB frame byte by byte; there is no need to specify the number of data bytes to be transmitted.
- Returned data and status are formatted according to the native USB protocol.

97.2 Bootloader selection

Figure 126. Bootloader V14.0 selection for STM32U3B5xx/3C5xx



97.3 Bootloader version

Table 226. STM32U3B5xx/3C5xx bootloader versions

Version number	Description	Known limitations
V14.0	Initial bootloader version	None

98 STM32U535xx/545xx devices

98.1 Bootloader configuration

The STM32U535xx/545xx bootloader is activated by applying Pattern 12 (described in *Table 2*). *Table 227* shows the hardware resources used by this bootloader.

The bootloader follows boot model V3_1 (see *Section 4.10*), so it inherits all its constraints.

Table 227. STM32U535xx/545xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz (using PLL clocked by HSI).
		HSI48 enabled	CRS is enabled for the DFU so that USB can be clocked by HSI 48 MHz.
		-	20 MHz derived from the PLLQ is used for FDCAN
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	64 Kbytes, starting from address 0x0BF90000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Set as input until USART1 is detected.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Set as input until USART1 is detected.
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1011010x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.

Table 227. STM32U535xx/545xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1011010x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1011010x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, no pull mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, no pull mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, no pull mode.

Table 227. STM32U535xx/545xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, no pull mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, no pull mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, no pull mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, no pull mode
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PB5 pin: slave data input line, used in push-pull, no pull mode
	SPI3_MISO pin	Output	PG10 pin: slave data input line, used in push-pull, no pull mode
	SPI3_SCK pin	Input	PG9 pin: slave data output line, used in push-pull, no pull mode
	SPI3_NSS pin	Input	PG12 pin: slave chip select pin used in push-pull, no pull mode.
FDCAN	FDCAN1	Enabled	Once initialized the configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input/	PB8 pin: FDCAN1 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN1_Tx pin	Output	PB9 pin: FDCAN1 in transmission mode. Used in alternate push-pull, no pull mode.

Table 227. STM32U535xx/545xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

Table 228. STM32U535xx/545xx special commands

Special commands supported (USART/I2C/SPI/FDCAN) Opcode - 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent**	**Number of data received**	**Data received**	**Number of status data received (2 bytes)**	**Status data received**
TrustZone disable Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x0	0x0	NA	0x1	0x0
Regression from RDP L1 to RDP 0.5 Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x1	0x0	NA	0x1	0x0
Unlock write protection Must be run when RDP = 1	0x82	0x4	0xYY02[1]	0x0	NA	0x1	0x0

1. 0xYY can have five values (0: WRP area, 1: WRP1A, 2: WRP2A, 3: WRP1B, 4: WRP2B)

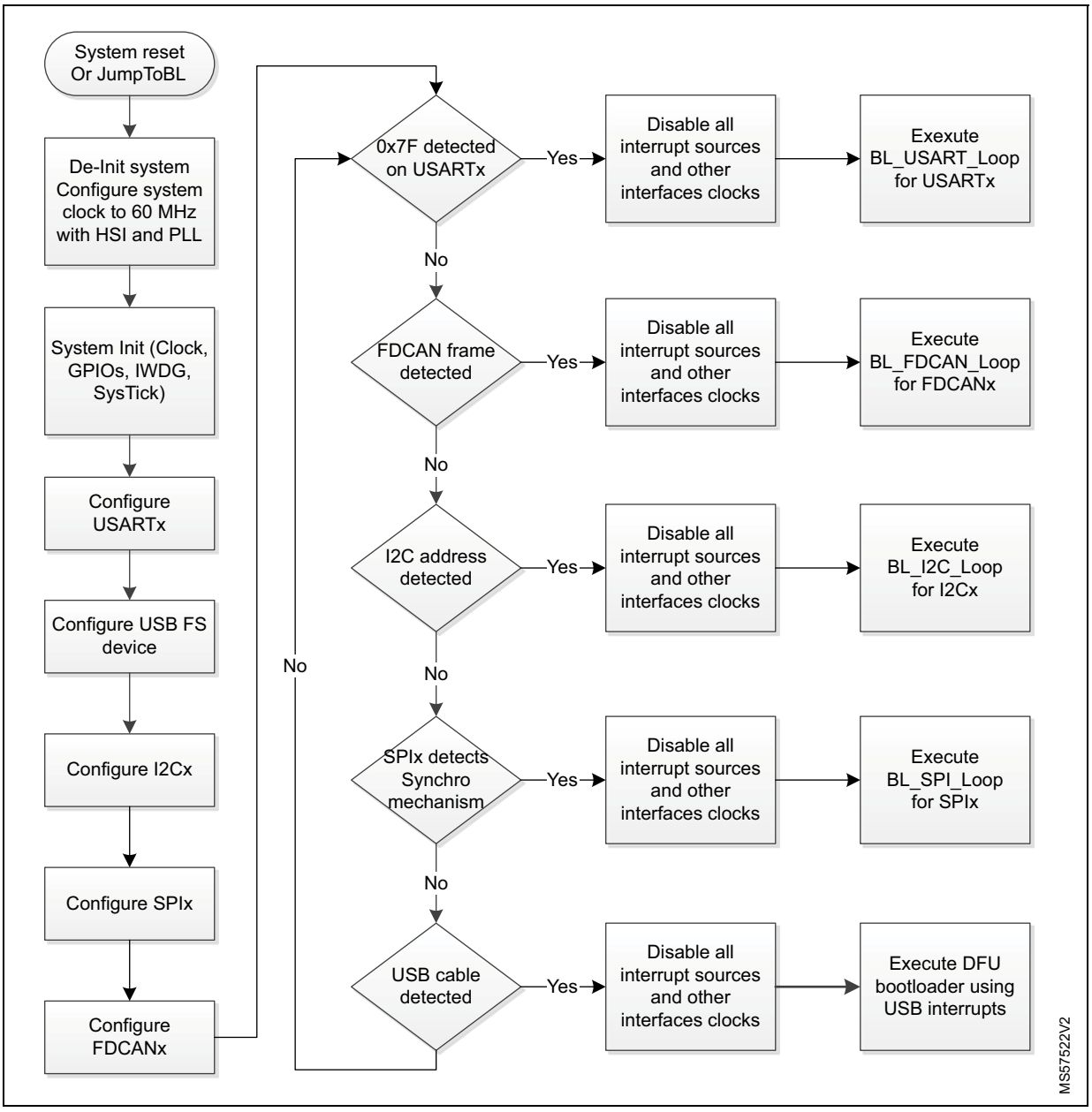
Note: USB special commands are slightly different from the other protocols as per the USB protocol specificities:

- *No Opcode is used, Sub-Opcode is used directly*
- *Sub-Opcode is treated in a single byte and not two bytes*
- *Data are sent on USB frame byte per byte. No need to add number of data to be transmitted*
- *Returned data and status are formatted on the USB native protocol*

98.2 Bootloader selection

Figure 127 shows the bootloader selection mechanism.

Figure 127. Bootloader V9.x selection for STM32U535xx/545xx



98.3 Bootloader version

Table 229. STM32U535xx/545xx bootloader versions

Version number	Description	Known limitations
V9.1	Initial bootloader version	FDCAN Readout unprotect command does not send the command ID to the host

99 STM32U575xx/85xx devices

99.1 Bootloader configuration

The STM32U575xx/85xx bootloader is activated by applying Pattern 12 (described in *Table 2*). *Table 230* shows the hardware resources used by this bootloader.

The bootloader follows boot model V3_1 (see *Section 4.10*), so it inherits all its constraints.

Table 230. STM32U575xx/85xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz (using PLL clocked by HSI).
		HSI48 enabled	CRS is enabled for the DFU so that USB can be clocked by HSI 48 MHz.
		-	20 MHz derived from the PLLQ is used for FDCAN
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	64 Kbytes, starting from address 0x0BF90000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART3	USART3	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 230. STM32U575xx/85xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1011010x (x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1011010x (x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1011010x (x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain pull-up mode.
SPI1	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.

Table 230. STM32U575xx/85xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.
SPI3	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PB5 pin: slave data input line, used in push-pull, pull-down mode
	SPI3_MISO pin	Output	PG10 pin: slave data input line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PG9 pin: slave data output line, used in push-pull, pull-down mode
	SPI3_NSS pin	Input	PG12 pin: slave chip select pin used in push-pull, pull-down mode.
FDCAN	FDCAN1	Enabled	Once initialized the configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input/	PB8 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	FDCAN1_Tx pin	Output	PB9 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 230. STM32U575xx/85xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. **Note**: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

Table 231. STM32U575xx/585xx special commands

Special commands supported (USART/I2C/SPI/FDCAN) Opcode - 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent**	**Number of data received**	**Data received**	**Number of status data received (2 bytes)**	**Status data received**
TrustZone disable Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x0	0x0	NA	0x1	0x0
Regression from RDP L1 to RDP 0.5 Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x1	0x0	NA	0x1	0x0
Unlock write protection Must be run when RDP = 1	0x82	0x4	0xYY02(1)	0x0	NA	0x1	0x0

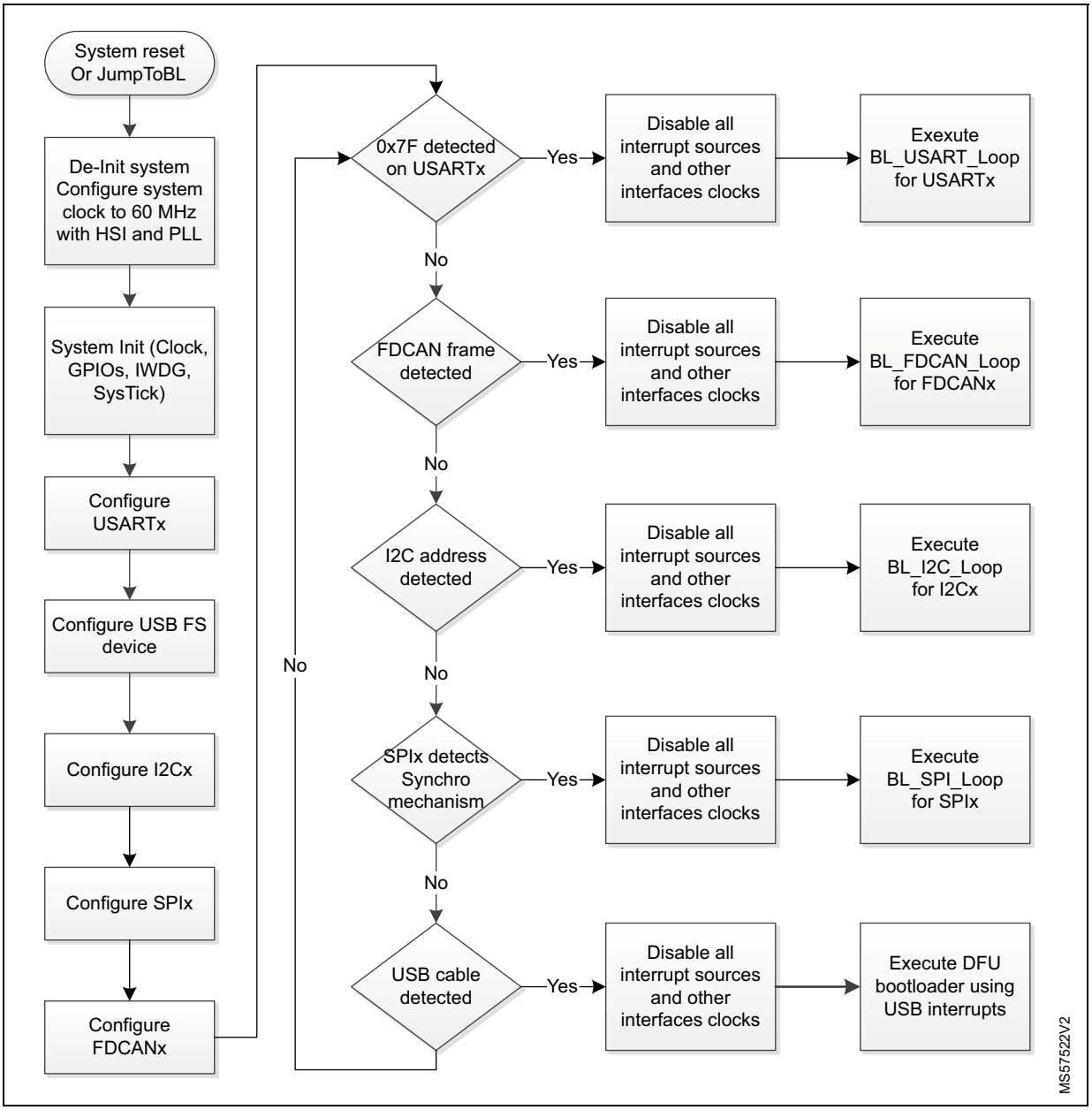
1. 0xYY can have five values (0: WRP area, 1: WRP1A, 2: WRP2A, 3: WRP1B, 4: WRP2B)

Note: USB special commands are slightly different from the other protocols as per the USB protocol specificities:

- *No Opcode is used, Sub-Opcode is used directly*
- *Sub-Opcode is treated in a single byte, not on two bytes*
- *Data are sent on USB frame byte per byte. No need to add number of data to be transmitted*
- *Returned data and status are formatted on the USB native protocol*

99.2 Bootloader selection

Figure 128. Bootloader V9.x selection for STM32U575xx/85xx



99.3 Bootloader version

Table 232. STM32U575xx/85xx bootloader versions

Version number	Description	Known limitations
V9.2	Initial bootloader version	– FDCAN Readout unprotect command does not send the command ID to the host – Not possible to change RDP level and secure option bytes at the same time
V9.3	– Fix known limitations – Add support for writing OEM1 and OEM2 keys separately from other option bytes – Add support for reading FLASH NSSR register, to allow user check if OEM keys have been changed or not using the bootloader	– FDCAN Readout unprotect command does not send the command ID to the host

100 STM32U595xx/99xx/A5xx/A9xx devices

100.1 Bootloader configuration

The STM32U595xx/99xx/A5xx/A9xx bootloader is activated by applying Pattern 12 (described in *Table 2*). *Table 233* shows the hardware resources used by this bootloader.

The bootloader follows boot model V3_1 (see *Section 4.10*), so it inherits all its constraints.

Table 233. STM32U595xx/99xx/A5xx/A9xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz (using PLL clocked by HSI).
		-	20 MHz derived from the PLLQ is used for FDCAN
		HSE enabled	When USB cable is detected, SW tries to detect if a quartz is plugged in the board to configure the USBPHY clock. Supported quartz: 8, 12, 16, 20, 24, 26, and 32 MHz If no quartz is detected a system reset is triggered.
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	64 Kbytes, starting from address 0x0BF90000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Set as input until USART1 is detected.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Set as input until USART1 is detected.
USART3	USART3	Enabled	Once initialized the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Set as input until USART1 is detected.

Table 233. STM32U595xx/99xx/A5xx/A9xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1100000x (x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1100000x (x = 0 for write and x = 1 for read).
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1100000x (x = 0 for write and x = 1 for read).
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain pull-up mode.
SPI1	SPI	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, no pull mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, no pull mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, no pull mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, no pull mode.

Table 233. STM32U595xx/99xx/A5xx/A9xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, no pull mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, no pull mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, no pull mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, no pull mode.
SPI3	SPI	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PB5 pin: slave data input line, used in push-pull, no pull mode
	SPI3_MISO pin	Output	PG10 pin: slave data input line, used in push-pull, no pull mode
	SPI3_SCK pin	Input	PG9 pin: slave data output line, used in push-pull, no pull mode
	SPI3_NSS pin	Input	PG12 pin: slave chip select pin used in push-pull, no pull mode.
DFU	USB	Enabled	USB HS configured in forced device mode. USB HS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

Table 233. STM32U595xx/99xx/A5xx/A9xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
FDCAN	FDCAN1	Enabled	Once initialized the configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input/	PB8 pin: FDCAN1 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN1_Tx pin	Output	PB9 pin: FDCAN1 in transmission mode. Used in alternate push-pull, no pull mode.

Table 234. STM32U595xx/99xx/A5xx/A9xx special commands

Special commands supported (USART/I2C/SPI/FDCAN) Opcode - 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent**	**Number of data received**	**Data received**	**Number of status data received (2 bytes)**	**Status data received**
TrustZone disable Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x0	0x0	NA	0x1	0x0
Regression from RDP L1 to RDP 0.5 Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x1	0x0	NA	0x1	0x0
Unlock write protection Must be run when RDP = 1	0x82	0x4	0xYY02(1)	0x0	NA	0x1	0x0

1. 0xYY can have five values (0: WRP area, 1: WRP1A, 2: WRP2A, 3: WRP1B, 4: WRP2B)

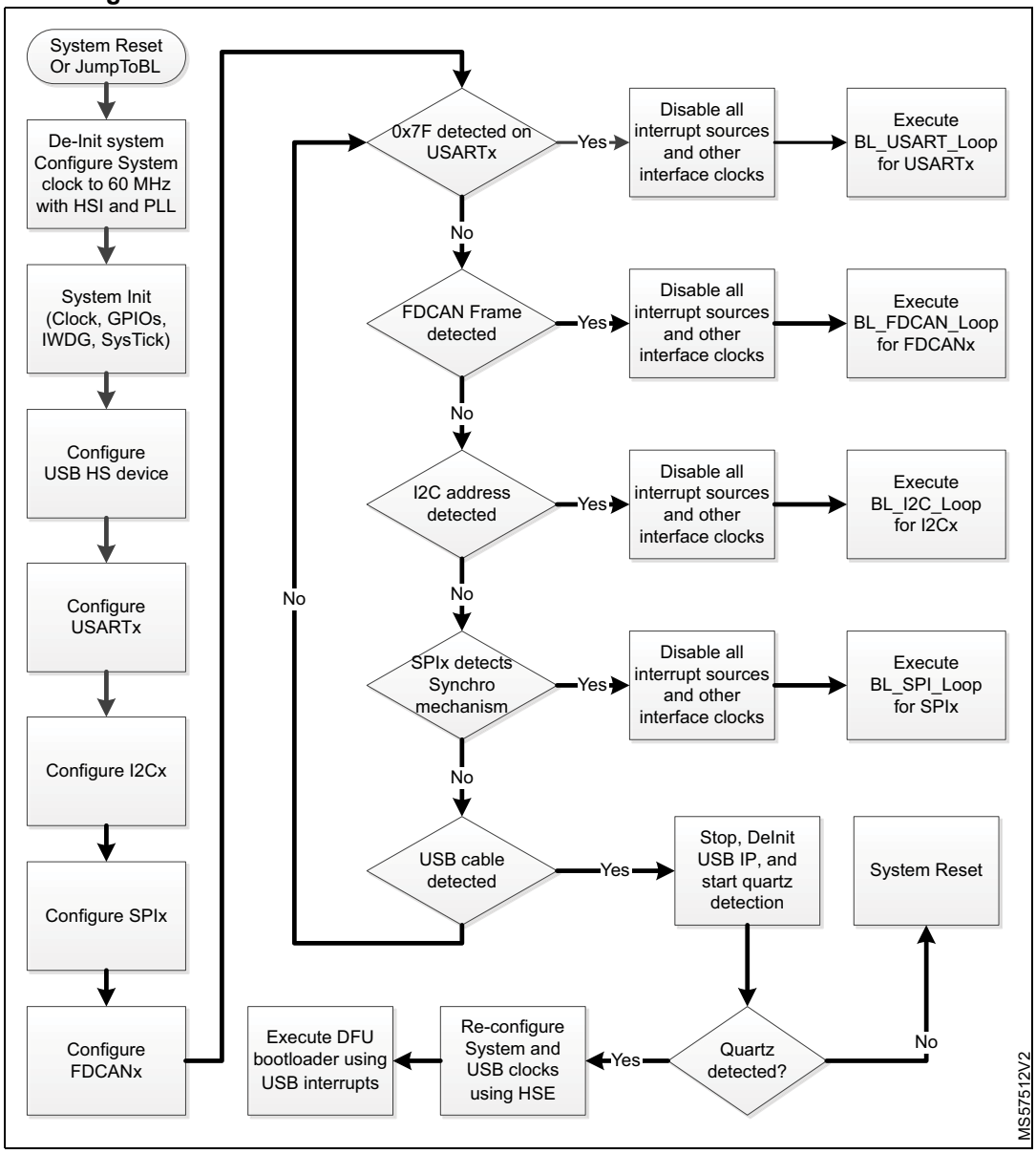
Note: USB special commands are slightly different from the other protocols as per the USB protocol specificities:

- *No Opcode is used, Sub-Opcode is used directly*
- *Sub-Opcode is treated in a single byte and not two bytes*
- *Data are sent on USB frame byte per byte. No need to add number of data to be transmitted*
- *Returned data and status are formatted on the USB native protocol*

100.2 Bootloader selection

Figure 129 shows the bootloader selection mechanism.

Figure 129. Bootloader V9.x selection for STM32U595xx/99xx/A5xx/A9xx



100.3 Bootloader version

Table 235. STM32U595xx/99xx/A5xx/A9xx bootloader versions

Version number	Description	Known limitations
V9.2	Initial bootloader version	– FDCAN Readout unprotect command does not send the command ID to the host. – The jump from the bootloader fails randomly. In the bootloader software, a bad start-of-frame (SOF) condition is detected during the jump, which prevents the jump.

101 STM32U5F7xx/F9xx/G7xx/G9xx devices

101.1 Bootloader configuration

The STM32U5F7xx/F9xx/G7xx/G9xx bootloader is activated by applying Pattern 12 (described in *Table 2*). *Table 236* shows the hardware resources used by this bootloader.

Table 236. STM32U5F7xx/F9xx/G7xx/G9xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all	RCC	HSI enabled	The system clock frequency is 60 MHz (using PLL clocked by HSI).
		-	20 MHz derived from the PLLQ is used for FDCAN
		HSE enabled	When USB cable is detected, SW tries to detect if a quartz is plugged in the board to configure the USBPHY clock. Supported quartz: 8, 12, 16, 20, 24, 26, and 32 MHz If no quartz is detected, a system reset is triggered.
	RAM	-	16 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	64 Kbytes, starting from address 0x0BF90000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1	USART1	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Set as input until USART1 is detected.
USART2	USART2	Enabled	Once initialized, the configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Set as input until USART1 is detected.
USART3	USART3	Enabled	Once initialized the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Set as input until USART1 is detected.

Table 236. STM32U5F7xx/F9xx/G7xx/G9xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
I2C1	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1101001x (x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin		PB7 pin: data line is used in open-drain pull-up mode.
I2C2	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1101001x (x = 0 for write and x = 1 for read).
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin		PB11 pin: data line is used in open-drain pull-up mode.
I2C3	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz – 7-bit address – Target mode – Analog filter ON – Target 7-bit address: 0b1101001x (x = 0 for write and x = 1 for read).
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin		PC1 pin: data line is used in open-drain pull-up mode.
SPI1	SPI	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data input line, used in push-pull, no pull mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, no pull mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, no pull mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, no pull mode.

Table 236. STM32U5F7xx/F9xx/G7xx/G9xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
SPI2	SPI	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data input line, used in push-pull, no pull mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, no pull mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, no pull mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, no pull mode.
SPI3	SPI	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PB5 pin: slave data input line, used in push-pull, no pull mode
	SPI3_MISO pin	Output	PG10 pin: slave data input line, used in push-pull, no pull mode
	SPI3_SCK pin	Input	PG9 pin: slave data output line, used in push-pull, no pull mode
	SPI3_NSS pin	Input	PG12 pin: slave chip select pin used in push-pull, no pull mode.
DFU	USB	Enabled	USB HS configured in forced device mode. USB HS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

Table 236. STM32U5F7xx/F9xx/G7xx/G9xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
FDCAN	FDCAN1	Enabled	Once initialized the configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input/	PB8 pin: FDCAN1 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN1_Tx pin	Output	PB9 pin: FDCAN1 in transmission mode. Used in alternate push-pull, no pull mode.

Table 237. STM32U5F7xx/F9xx/G7xx/G9xx special commands

Special commands supported (USART/I2C/SPI/FDCAN) Opcode - 0x50							
Function	**Sub-Opcode (2 bytes)**	**Number of data sent (2 bytes)**	**Data sent**	**Number of data received**	**Data received**	**Number of status data received (2 bytes)**	**Status data received**
TrustZone disable Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x0	0x0	NA	0x1	0x0
Regression from RDP L1 to RDP 0.5 Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x1	0x0	NA	0x1	0x0
Unlock write protection Must be run when RDP = 1	0x82	0x4	0xYY02[1]	0x0	NA	0x1	0x0

1. 0xYY can have five values (0: WRP area, 1: WRP1A, 2: WRP2A, 3: WRP1B, 4: WRP2B)

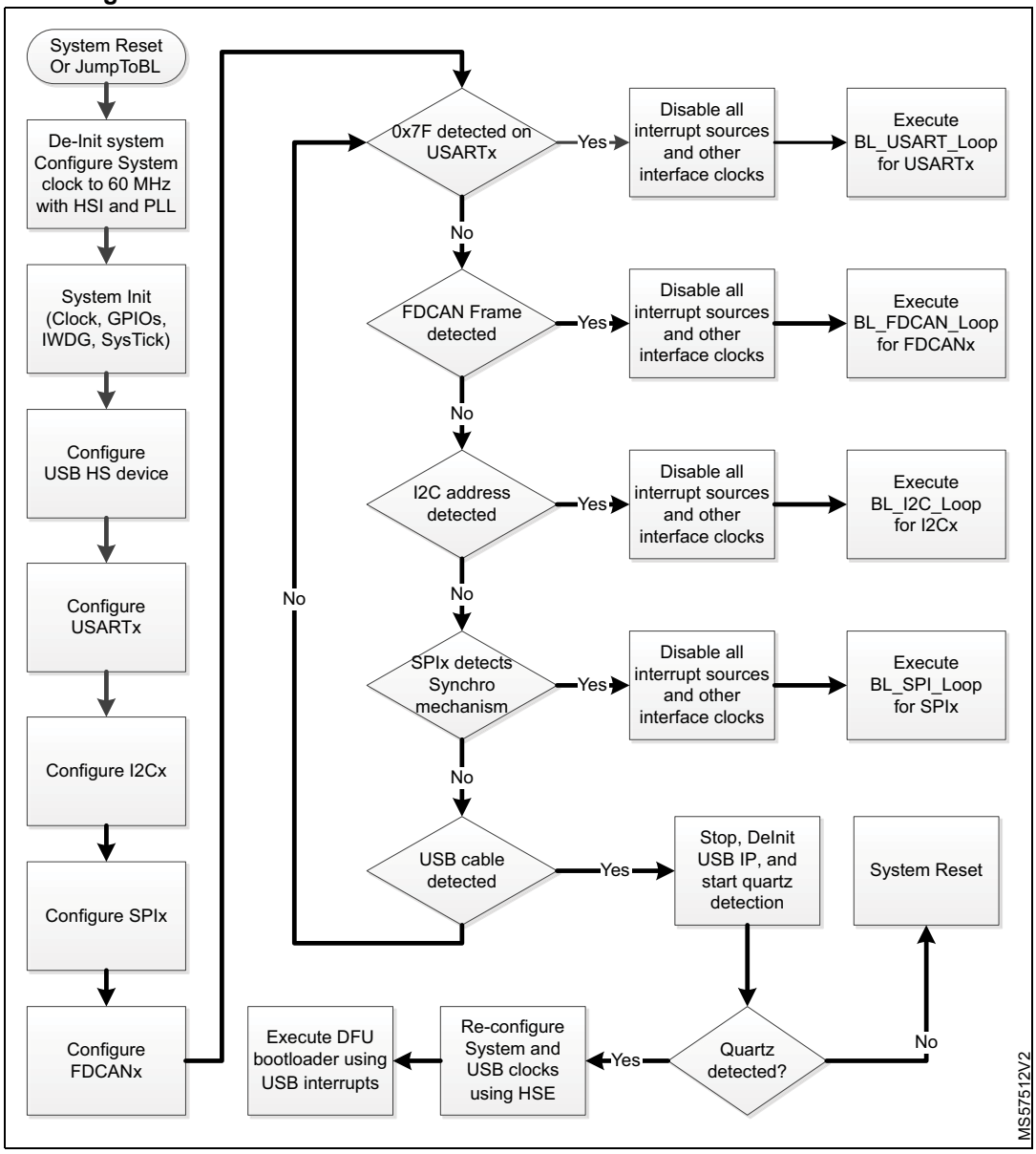
Note: USB special commands are slightly different from the other protocols as per the USB protocol specificities:

- *No Opcode is used, Sub-Opcode is used directly*
- *Sub-Opcode is treated in a single byte and not two bytes*
- *Data are sent on USB frame byte per byte. No need to add number of data to be transmitted*
- *Returned data and status are formatted on the USB native protocol*

101.2 Bootloader selection

Figure 129 shows the bootloader selection mechanism.

Figure 130. Bootloader V9.x selection for STM32U5F7xx/F9xx/G7xx/G9xx



101.3 Bootloader version

Table 238. STM32U5F7xx/F9xx/G7xx/G9xx bootloader versions

Version number	Description	Known limitations
V9.0	Initial bootloader version	– FDCAN Readout unprotect command does not send the command ID to the host. – The jump from the bootloader fails randomly. In the bootloader software, a bad start-of-frame (SOF) condition is detected during the jump, which prevents the jump.

102 Device-dependent bootloader parameters

The bootloader protocol command set and sequences for each serial peripheral are the same for all STM32 devices. Some parameters depend on device and bootloader version:

- PID (Product ID)
- Valid RAM addresses (RAM area used during bootloader execution is not accessible) accepted by the bootloader when the Read Memory, Go and Write Memory commands are requested.
- System memory area.

Table 239 shows the values of these parameters for each STM32 device.

Table 239. Bootloader device-dependent parameters

STM32 series	Device	PID	BL ID	RAM	System memory
C0	STM32C011xx	0x443	0x51	0x20000E00 - 0x200017FF	0x1FFF0000 - 0x1FFF17FF
	STM32C031xx	0x453	0x52	0x20000E00 - 0x20002FFF	
	STM32C051xx	0x44C	0xB0	0x20001400 - 0x20002FFF	0x1FFF0000 - 0x1FFF2FFF
	STM32C071xx	0x493	0xD1	0x20002300 - 0x20005FFF	0x1FFF0000 - 0x1FFF6FFF
	STM32C091xx/92xx	0x44D	0x121	0x20002400 - 0x200077FF	0x1FFF0000 - 0x1FFF3FFF
C5	STM32C55xxx/562xx	0x44E	0x101	0x20003C40 - 0x2001FFFF	0x0BF80080 - 0x0BF885FF
	STM32C53xxx/542xx	0x44F	0x100	0x20003C00 - 0x2000FFFF	0x0BF80080 - 0x0BF885FF
	STM32C5A3xx/59xxx	0x45A	0x100	0x20003C00 - 0x2003FFFF	0x0BF80080 - 0x0BF885FF

Table 239. Bootloader device-dependent parameters (continued)

STM32 series	Device		PID	BL ID	RAM	System memory
F0	STM32F05xxx and STM32F030x8		0x440	0x21	0x20000800 - 0x20001FFF	0x1FFFEC00 - 0x1FFFF7FF
	STM32F03xx4/6		0x444	0x10	0x20000800 - 0x20000FFF	
	STM32F030xC		0x442	0x52	0x20001800 - 0x20007FFF	0x1FFFD800 - 0x1FFFF7FF
	STM32F04xxx		0x445	0xA1	NA	0x1FFFC400 - 0x1FFFF7FF
	STM32F070x6		0x445	0xA2	NA	0x1FFFC400 - 0x1FFFF7FF
	STM32F070xB		0x448	0xA2	NA	0x1FFFC800 - 0x1FFFF7FF
	STM32F071xx/072xx		0x448	0xA1	0x20001800 - 0x20003FFF	0x1FFFC800 - 0x1FFFF7FF
	STM32F09xxx		0x442	0x50	NA	0x1FFFD800 - 0x1FFFF7FF
F1	STM32F10xxx	Low-density	0x412	NA	0x20000200 - 0x200027FF	0x1FFFF000 - 0x1FFFF7FF
		Medium-density	0x410	NA	0x20000200 - 0x20004FFF	
		High-density	0x414	NA	0x20000200 - 0x2000FFFF	
		Medium-density value line	0x420	0x10	0x20000200 - 0x20001FFF	
		High-density value line	0x428	0x10	0x20000200 - 0x20007FFF	
	STM32F105xx/107xx		0x418	NA	0x20001000 - 0x2000FFFF	0x1FFFB000 - 0x1FFFF7FF
	STM32F10xxx XL-density		0x430	0x21	0x20000800 - 0x20017FFF	0x1FFFE000 - 0x1FFFF7FF
F2	STM32F2xxxx		0x411	0x20	0x20002000 - 0x2001FFFF	0x1FFF0000 - 0x1FFF77FF
				0x33		

Table 239. Bootloader device-dependent parameters (continued)

STM32 series	Device	PID	BL ID	RAM	System memory
F3	STM32F373xx	0x432	0x41	0x20001400 - 0x20007FFF	0x1FFFD800 - 0x1FFFF7FF
	STM32F378xx		0x50	0x20001000 - 0x20007FFF	
	STM32F302xB(C)/303xB(C)	0x422	0x41	0x20001400 - 0x20009FFF	
	STM32F358xx		0x50		
	STM32F301xx/302x4(6/8)	0x439	0x40	0x20001800 - 0x20003FFF	
	STM32F318xx		0x50		
	STM32F303x4(6/8)/334xx/328xx	0x438	0x50	0x20001800 - 0x20002FFF	
	STM32F302xD(E)/303xD(E)	0x446	0x40	0x20001800 - 0x2000FFFF	
	STM32F398xx	0x446	0x50	0x20001800 - 0x2000FFFF	
F4	STM32F40xxx/41xxx	0x413	0x31	0x20002000 - 0x2001FFFF	0x1FFF0000 - 0x1FFF77FF
			0x91	0x20003000 - 0x2001FFFF	
	STM32F42xxx/43xxx	0x419	0x70	0x20003000 - 0x2002FFFF	
			0x91		
	STM32F401xB(C)	0x423	0xD1	0x20003000 - 0x2000FFFF	
	STM32F401xD(E)	0x433	0xD1	0x20003000 - 0x20017FFF	
	STM32F410xx	0x458	0xB1	0x20003000 - 0x20007FFF	
	STM32F411xx	0x431	0xD0	0x20003000 - 0x2001FFFF	
	STM32F412xx	0x441	0x90	0x20003000 - 0x2003FFFF	
	STM32F446xx	0x421	0x90	0x20003000 - 0x2001FFFF	
	STM32F469xx/479xx	0x434	0x90	0x20003000 - 0x2005FFFF	
	STM32F413xx/423xx	0x463	0x90	0x20003000 - 0x2004FFFF	

Table 239. Bootloader device-dependent parameters (continued)

STM32 series	Device	PID	BL ID	RAM	System memory
F7	STM32F72xxx/73xxx	0x452	0x90	0x20004000 - 0x2003FFFF	0x1FF00000 - 0x1FF0EDBF
	STM32F74xxx/75xxx	0x449	0x70	0x20004000 - 0x2004FFFF	0x1FF00000 - 0x1FF0EDBF
			0x90	0x20004000 - 0x2004FFFF	0x1FF00000 - 0x1FF0EDBF
	STM32F76xxx/77xxx	0x451	0x93	0x20004000 - 0x2007FFFF	0x1FF00000 - 0x1FF0EDBF
G0	STM32G03xxx/04xxx	0x466	0x54	0x20001000 - 0x20001FFF	0x1FFF0000 - 0x1FFF1FFF
	STM32G05xxx/061xx	0x456	0x51	0x20001000 - 0x20002000	0x1FFF0000 - 0x1FFF1FFF
	STM32G07xxx/08xxx	0x460	0xB4	0x20002700 - 0x20009000	0x1FFF0000 - 0x1FFF6FFF
	STM32G0B0xx	0x467	0xD0	0x20004000 - 0x20020000	0x1FFF0000 - 0x1FFF6FFF 0x1FFF8000 - 0x1FFFEFFF
	STM32G0B1xx/0C1xx	0x467	0x92	0x20004000 - 0x20020000	0x1FFF0000 - 0x1FFF6FFF 0x1FFF8000 - 0x1FFFEFFF
G4	STM32G431xx/441xx	0x468	0xD4	0x20004000 – 0x20005800	0x1FFF0000 - 0x1FFF7000
	STM32G47xxx/48xxx	0x469	0xD5	0x20004000 – 0x20018000	0x1FFF0000 - 0x1FFF7000
	STM32G491xx/A1xx	0x479	0xD2	0x20004000 - 0x2001C000	0x1FFF0000 - 0x1FFF7000
G5	STM32G53xxx/54xxx	0x44B	0x120	0x20000C00 - 0x20002FFF	0x0BFA2C00 - 0x0BFADAFF
	STM32G554xx/564xx	0x44A	0x90	0x20018000 - 0x2001BFFF	0x0BFA2C00 - 0x0BFADAFF
H5	STM32H503xx	0x474	0xE1	0x20004000 - 0x20007FFF	0x0BF87000 - 0x0BF8FFFF
	STM32H562xx/563xx/573xx	0x484	0xE5	0x20000000 - 0x2009FFFF	0x0BF97000 - 0x0BF9FFFF
	STM32H523xx/533xx	0x478	0xE2	0x20004000 - 0x20043FFF	0x0BF97000 - 0x0BF9FFFF
	STM32H543xx/553xx	0x47C	0xE0	0x20004000 - 0x2004BFFF	0x0BFA4000 - 0x0BFADFFF
	STM32H5Ex/5Fx	0x47A	0xF0	0x20004000 - 0x2017FFFF	0x0BFAC000 - 0x0BFB7FFF

Table 239. Bootloader device-dependent parameters (continued)

STM32 series	Device	PID	BL ID	RAM	System memory
H7	STM32H72xxx/73xxx	0x483	0x93	0x20004100 - 0x2001FFFF 0x24004000 - 0x2404FFFF	0x1FF00000 - 0x1FF1E7FF
	STM32H74xxx/75xxx	0x450	0x92	0x20004100 - 0x2001FFFF 0x24005000 - 0x2407FFFF	0x1FF00000 - 0x1FF1E7FF
	STM32H7A3xx/7B3xx/7B0xx	0x480	0x92	0x20004100 - 0x2001FFFF 0x24034000 - 0x2407FFFF	0x1FF00000 - 0x1FF13FFF
	STM32H7Rxxx/7Sxxx	0x485	0xE3	0x24000000 - 0x2401FFFF 0x24024000 - 0x24071FFF 0x20000000 - 0x2002FFFF 0x00000000 - 0x0002FFFF(1)	0x1FF18000 - 0x1FF1FFFF
	STM32H7P4xx/P5xx	0x47B	0x141	0x2FFD0000 - 0x2FFD4BFF	0x1FF10000 - 0x1FF19FFF
L0	STM32L01xxx/02xxx	0x457	0xC3	NA	0x1FF00000 - 0x1FF00FFF
	STM32L031xx/041xx	0x425	0xC0	0x20001000 - 0x20001FFF	0x1FF00000 - 0x1FF00FFF
	STM32L05xxx/06xxx	0x417	0xC0	0x20001000 - 0x20001FFF	0x1FF00000 - 0x1FF00FFF
	STM32L07xxx/08xxx	0x447	0x41	0x20001000 - 0x20004FFF	0x1FF00000 - 0x1FF01FFF
			0xB2	0x20001400 - 0x20004FFF	
L1	STM32L1xxx6(8/B)	0x416	0x20	0x20000800 - 0x20003FFF	0x1FF00000 - 0x1FF01FFF
	STM32L1xxx6(8/B)A	0x429	0x20	0x20001000 - 0x20007FFF	
	STM32L1xxxC	0x427	0x40		
	STM32L1xxxD	0x436	0x45	0x20001000 - 0x2000BFFF	
	STM32L1xxxE	0x437	0x40	0x20001000 - 0x20013FFF	

Table 239. Bootloader device-dependent parameters (continued)

STM32 series	Device	PID	BL ID	RAM	System memory
L4	STM32L412xx/422xx	0x464	0xD1	0x20002100 - 0x20008000	0x1FFF 0000 - 0x1FFF6FFF
	STM32L43xxx/44xxx	0x435	0x91	0x20003100 - 0x2000BFFF	0x1FFF 0000 - 0x1FFF6FFF
	STM32L45xxx/46xxx	0x462	0x92	0x20003100 - 0x2001FFFF	0x1FFF 0000 - 0x1FFF6FFF
	STM32L47xxx/48xxx	0x415	0xA3	0x20003000 - 0x20017FFF	0x1FFF 0000 - 0x1FFF6FFF
			0x92	0x20003100 - 0x20017FFF	
	STM32L496xx/4A6xx	0x461	0x93	0x20003100 - 0x2003FFFF	0x1FFF 0000 - 0x1FFF6FFF
	STM32L4Rxx/4Sxx	0x470	0x95	0x20003200 - 0x2009FFFF	0x1FFF 0000 - 0x1FFF6FFF
	STM32L4P5xx/Q5xx	0x471	0x90	0x20004000 - 0x2004FFFF	0x1FFF 0000 - 0x1FFF6FFF
L5	STM32L552xx/562xx	0x472	0x92	0x20004000 - 0x2003FFFF	0x0BF9 0000 - 0x0BF9 7FFF
U0	STM32U031xx	0x459	0xB0	0x20001500 – 0x20002FFF	0x1FFF 0000 – 0x1FFF 37FF
	STM32U073xx/83xx	0x489	0xD0	0x20002170 – 0x20009FFF	0x1FFF 0000 – 0x1FFF 67FF
U3	STM32U375xx/385xx	0x454	0xE2	0x20004000 - 0x2003FFFF	0x0BF8 F000 - 0x0BF9 FFFF
	STM32U3B5xx/3C5xx	0x42A	0xE0	0x20004000 - 0x2009FFFF	0x0BF8F000 - 0x0BF9FFFF
U5	STM32U535xx/545xx	0x455	0x91	0x20004000 - 0x2023FFFF	0x0BF90000 - 0x0BF9FFFF
	STM32U575xx/585xx	0x482	0x92	0x20004000 - 0x200BFFFF	0x0BF90000 - 0x0BF9FFFF
	STM32U595xx/599xx/5A9xx	0x481	0x92	0x20004000 - 0x2026FFFF	0x0BF90000 - 0x0BF9FFFF
	STM32U5F7xx/5F9xx/5G7xx/5G9xx	0x476	0x90	0x20004000 - 0x202EFFFF	0x0BF90000 - 0x0BF9FFFF
WB	STM32WB10xx/15xx	0x494	0xB1	0x20005000 - 0x20040000	0x1FFF 0000 - 0x1FFF7000
	STM32WB30xx/35xx/50xx/WB55xx	0x495	0xD5	0x20004000 - 0x2000BFFF	0x1FFF 0000 - 0x1FFF7000

Table 239. Bootloader device-dependent parameters (continued)

STM32 series	Device	PID	BL ID	RAM	System memory
WBA	STM32WBA2xxx	0x4B2	0xD0	0x20003000 - 0x20017FFF	0x0BF85000 - 0x0BF8CDFF
	STM32WBA5xxx	0x492	0xB0 (rev A) 0xB1 (rev B)	0x2000 1800 - 0x2000 1FFF	0x0BF8 8000 - 0x0BF8 FFFF
	STM32WBA62xx/63xx/64xx/65xx	0x4B0	0xD2	0x2000 3000 - 0x2007 FFFF	0x0BF9 0000 - 0x0BF9 FFFF
WL	STM32WLE5xx/WL55xx	0x497	0xC4	0x2000 2000 - 0x2000 FFFF	0x1FFF 0000 - 0x1FFF3FFF

1. Addresses are listed with the max values, but depending on option bytes, the end values can change.

103 Bootloader timings

This section details the timings of the bootloader firmware to use for correct synchronization between the host and the STM32 device.

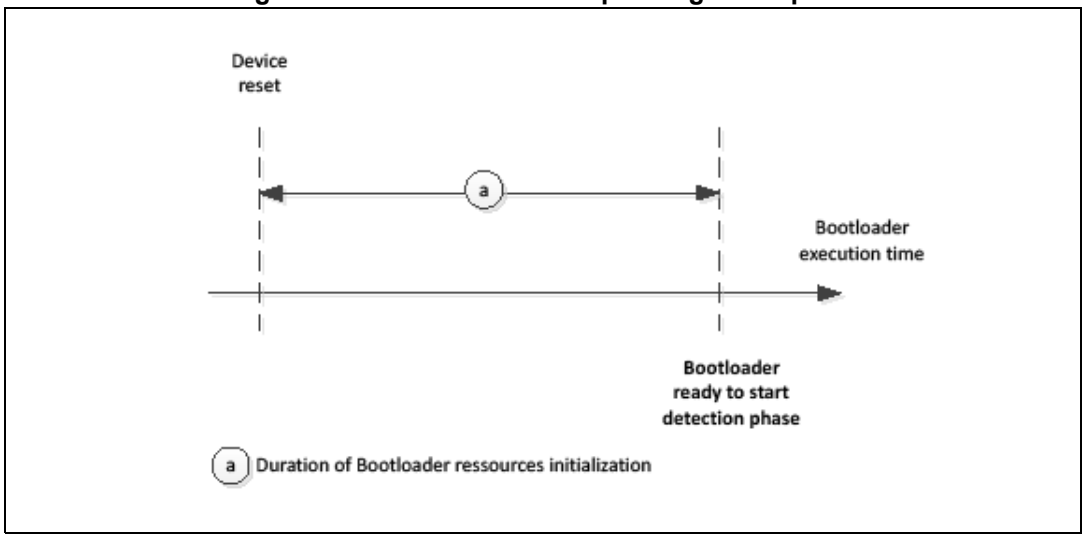
Two types of timings are described, namely STM32 device bootloader resources initialization duration, and communication interface selection duration.

After these timings the bootloader is ready to receive and execute host commands.

103.1 Bootloader startup timing

After bootloader reset, the host must wait until the STM32 bootloader is ready to start detection phase with a specific interface communication. This time corresponds to bootloader startup timing, during which resources used by bootloader are initialized.

Figure 131. Bootloader startup timing description



Depending on the bootloader model, the startup timing calculation differs from one product to another (see *Section 4.10* for more details). The following table details only the startup timings.

Table 240. Bootloader startup timings (ms)

Device	Minimum startup	HSE timeout
STM32C011xx	2.1	NA
STM32C031xx	2.1	NA
STM32C051xx	2.262	NA
STM32C071xx	2.358	NA
STM32C091xx/92xx	1.527	NA
STM32C5A3xx/59xxx	4.8	12
STM32C55xxx/562xx	4.8	12

Table 240. Bootloader startup timings (ms) (continued)

Device		Minimum startup	HSE timeout
STM32C53xxx/542xx		4.8	12
STM32F03xx4/6		1.612	NA
STM32F05xxx and STM32F030x8 devices		1.612	NA
STM32F04xxx		0.058	NA
STM32F071xx/072xx		0.058	NA
STM32F070x6	HSE connected	3	200
	HSE not connected	230	
STM32F070xB	HSE connected	6	200
	HSE not connected	230	
STM32F09xxx		2	NA
STM32F030xC		2	NA
STM32F10xxx		1.227	NA
STM32F105xx/107xx	PA9 pin low	1.396	NA
	PA9 pin high	524.376	
STM32F10xxx XL-density		1.227	NA
STM32F2xxxx	V2.x	134	NA
	V3.x	84.59	0.790
STM32F301xx/302x4(6/8)	HSE connected	45	560.5
	HSE not connected	560.8	
STM32F302xB(C)/303xB(C)	HSE connected	43.4	2.236
	HSE not connected	2.36	
STM32F302xD(E)/303xD	HSE connected	7.53	NA
	HSE not connected	146.71	NA
STM32F303x4(6/8)/334xx/328xx		0.155	NA
STM32F318xx		0.182	NA
STM32F358xx		1.542	NA
STM32F373xx	HSE connected	43.4	2.236
	HSE not connected	2.36	
STM32F378xx		1.542	NA
STM32F398xx		1.72	NA
STM32F40xxx/41xxx	V3.x	84.59	0.790
	V9.x	74	96
STM32F401xB(C)		74.5	85
STM32F401xD(E)		74.5	85
STM32F410xx		0.614	NA

Table 240. Bootloader startup timings (ms) (continued)

Device		Minimum startup	HSE timeout
STM32F411xx		74.5	85
STM32F412xx		0.614	180
STM32F413xx/423xx		0.642	165
STM32F429xx/439xx	V7.x	82	97
	V9.x	74	97
STM32F446xx		73.61	96
STM32F469xx/479xx		73.68	230
STM32F72xxx/73xxx		17.93	50
STM32F74xxx/75xxx		16.63	50
STM32G03xxx/04xxx		0.390	NA
STM32G07xxx/08xxx		0.390	NA
STM32G0Bxxx/Cxxx		0.390	NA
STM32G05xxx/061xx		0.390	NA
STM32G4xxxx		0.390	NA
STM32G53xxx/54xxx		1.8	NA
STM32G554xx/564xx		1.8	NA
STM32H503xx		1.5	NA
STM32H523xx/533xx		2.7	NA
STM32H543xx/553xx		1.8	NA
STM32H562xx/563xx/573xx		1.8	NA
STM32H5Ex/5Fx		11.7	200
STM32H72xxx/73xxx		53.975	NA
STM32H74xxx/75xxx		53.975	2
STM32H7A3xx/7B3xx/7B0xx		545	NA
STM32H7P4xx/P5xx		5.02	NA
STM32L01xxx/02xxx		0.63	NA
STM32L031xx/041xx		0.62	NA
STM32L05xxx/06xxx		0.22	NA
STM32L07xxx/08xxx	V4.x	0.61	NA
	V11.x	0.71	NA
STM32L1xxx6(8/B)A		0.542	NA
STM32L1xxx6(8/B)		0.542	NA
STM32L1xxxC		0.708	80
STM32L1xxxD		0.708	80
STM32L1xxxE		0.708	200

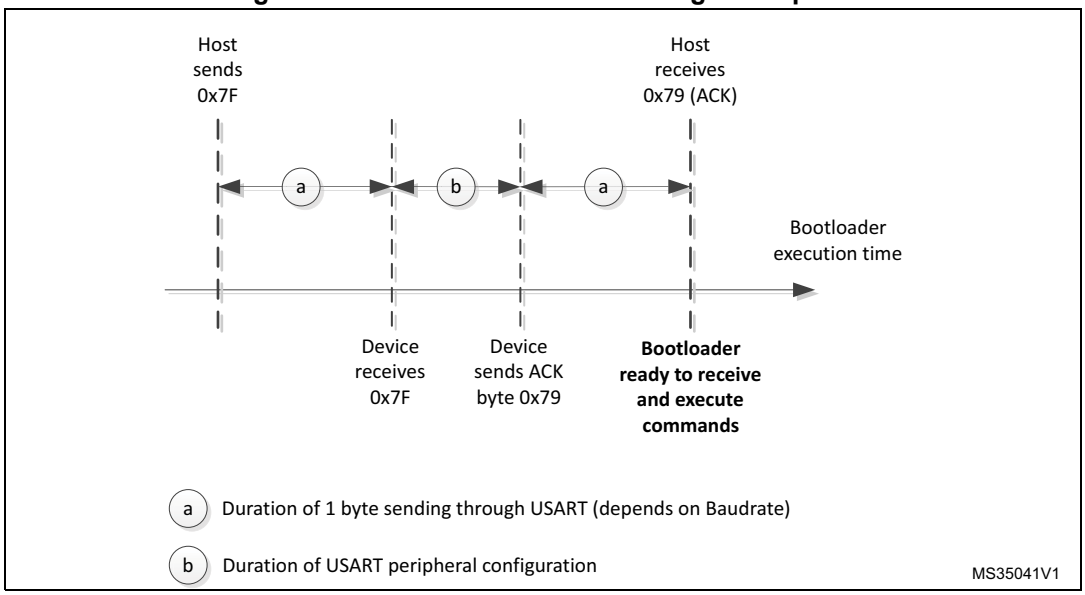
Table 240. Bootloader startup timings (ms) (continued)

Device			Minimum startup	HSE timeout
STM32L43xxx/44xxx			0.86	100
STM32L45xxx/46xxx			0.86	NA
STM32L47xxx/48xxx	V10.x	LSE connected	55	100
		LSE not connected	2560	
	V9.x	LSE connected	55.40	100
		LSE not connected	2560.5	
STM32L412xx/422xx			0.86	NA
STM32L496xx/4A6xx			76.93	100
STM32L4P5xx /Q5xx			9.891	NA
STM32L4Rxx/4Sxx			10.12	NA
STM32L552xx/562xx			0.390	NA
STM32U031xx			4.534	NA
STM32U073xx/ STM32U083xx			5.626	NA
STM32U375xx/385xx			4.418	NA
STM32U3B5xx/3C5xx			4.5	NA
STM32U535xx/545xx			0.390	NA
STM32U575xx/585xx			0.390	NA
STM32U595xx/599xx/5A5xx/5A9xx			0.390	NA
STM32U5F7xx/5F9xx/5G7xx/5G9xx			0.390	NA
STM32WB10xx/15xx/30xx/35xx/50xx/55xx			0.390	NA
STM32WBA2xxx			2.3	NA
STM32WBA52xx			0.390	NA
STM32WBA62xx/63xx/64xx/65xx			2,73	NA
STM32WLE5xx/WL55xx			0.390	NA

103.2 USART connection timing

USART connection timing is the time that the host must wait for between sending the synchronization data (0x7F) and receiving the first acknowledge response (0x79).

Figure 132. USART connection timing description



1. Receiving characters different from 0x7F (or line glitches) causes bootloader to start communication using a wrong baudrate. Bootloader measures the signal length between rising edge of the first bit to the falling edge of the last bit to deduce the baudrate value
2. Bootloader does not realign the calculated baudrate to standard baudrate values (i.e. 1200, 9600, 115200).

Note: The PA9 pin (USB_VBUS) on STM32F105xx/107xx devices is used to detect the USB host connection. The initialization of USB peripheral is performed only if PA9 is high at detection phase, which means that a host is connected to the port and delivering 5 V on the USB bus. When PA9 level is high at detection phase, more time is required to initialize and shutdown the USB peripheral. To minimize bootloader detection time when PA9 pin is not used, keep PA9 low during USART detection phase, from the moment the device is reset, until a device ACK is sent.

Table 241. USART bootloader minimum timings (ms)

Device	One USART byte sending	USART configuration	USART connection
STM32C011xx	0.138	0.043	0.182
STM32C031xx	0.112	0.028	0.168
STM32C051xx	0.1	0.033	0.23
STM32C071xx	0.1	0.104	0.182
STM32C091xx/92xx	0.1	0.102	0.383
STM32C5A3xx/59xxx	0.013188	0.02045	0.013188
STM32C55xxx/562xx	0.010076	0.08032	0.010076
STM32C53xxx/542xx	0.012761	0.018122	0.015346
STM32F03xx4/6	0.078125	0.0064	0.16265
STM32F05xxx and STM32F030x8 devices	0.078125	0.0095	0.16575
STM32F04xxx	0.078125	0.007	0.16325

Table 241. USART bootloader minimum timings (ms) (continued)

Device		One USART byte sending	USART configuration	USART connection
STM32F071xx/072xx		0.078125	0.007	0.16325
STM32F070x6		0.078125	0.014	0.17
STM32F070xB		0.078125	0.08	0.23
STM32F09xxx		0.078125	0.07	0.22
STM32F030xC		0.078125	0.07	0.22
STM32F10xxx		0.078125	0.002	0.15825
STM32F105xx/107xx	PA9 pin low	0.078125	0.007	0.16325
	PA9 pin High		105	105.15625
STM32F10xxx XL-density		0.078125	0.006	0.16225
STM32F2xxxx	V2.x	0.078125	0.009	0.16525
	V3.x			
STM32F301xx/302x4(6/8)	HSE connected	0.078125	0.002	0.15825
	HSE not connected			
STM32F302xB(C)/303xB(C)	HSE connected	0.078125	0.002	0.15825
	HSE not connected			
STM32F302xD(E)/303xD		0.078125	0.002	0.15885
STM32F303x4(6/8)/334xx/328xx		0.078125	0.002	0.15825
STM32F318xx		0.078125	0.002	0.15825
STM32F358xx		0.15625	0.001	0.3135
STM32F373xx	HSE connected	0.078125	0.002	0.15825
	HSE not connected			
STM32F378xx		0.15625	0.001	0.3135
STM32F398xx		0.078125	0.002	0.15885
STM32F40xxx/41xxx	V3.x	0.078125	0.009	0.16525
	V9.x		0.0035	0.15975
STM32F401xB(C)		0.078125	0.00326	0.15951
STM32F401xD(E)		0.078125	0.00326	0.15951
STM32F410xx		0.078125	0.002	0.158
STM32F411xx		0.078125	0.00326	0.15951
STM32F412xx		0.078125	0.002	0.158
STM32F413xx/423xx		0.078125	0.002	0.158
STM32F429xx/439xx	V7.x	0.078125	0.007	0.16325
	V9.x		0.00326	0.15951
STM32F446xx		0.078125	0.004	0.16

Table 241. USART bootloader minimum timings (ms) (continued)

Device		One USART byte sending	USART configuration	USART connection
STM32F469xx/479xx		0.078125	0.003	0.159
STM32F72xxx/73xxx		0.078125	0.070	0.22
STM32F74xxx/75xxx		0.078125	0.065	0.22
STM32G03xxx/04xxx		0.078125	0.01	0.11
STM32G07xxx/08xxx		0.078125	0.01	0.11
STM32G0Bxxx/Cxxx		0.078125	0.01	0.11
STM32G05xxx/061xx		0.078125	0.01	0.11
STM32G4xxxx		0.078125	0.003	0.159
STM32G53xxx/54xxx		0.078125	0.003	0.159
STM32G554xx/564xx		0.078125	0.003	0.159
STM32H503xx		0.048	0.05	0.101
STM32H543xx/553xx		0.047	0.06	0.100
STM32H562xx/563xx/573xx		0.047	0.06	0.100
STM32H5Ex/5Fx		0.012784	0.003048	0.012784
STM32H72xxx/73xxx		0.078125	0.072	0.22825
STM32H74xxx/75xxx		0.078125	0.072	0.22825
STM32H7A3xx/7B3xx/7B0xx		0.078125	0.072	0.22825
STM32H7P4xx/P5xx		0.091	0.010	0.193
STM32L01xxx/02xxx		0.078125	0.016	0.17
STM32L031xx/041xx		0.078125	0.018	0.174
STM32L05xxx/06xxx		0.078125	0.018	0.17425
STM32L07xxx/08xxx	V4.x	0.078125	0.017	0.173
	V11.x	0.078125	0.017	0.158
STM32L1xxx6(8/B)A		0.078125	0.008	0.16425
STM32L1xxx6(8/B)		0.078125	0.008	0.16425
STM32L1xxxC		0.078125	0.008	0.16425
STM32L1xxxD		0.078125	0.008	0.16425
STM32L1xxxE		0.078125	0.008	0.16425
STM32L412xx/422xx		0.078125	0.005	0.2
STM32L43xxx/44xxx		0.078125	0.003	0.159
STM32L45xxx/46xxx		0.078125	0.07	0.22
STM32L47xxx/48xxx	V10.x	0.078125	0.003	0.159
	V9.x	0.078125	0.003	0.159
STM32L496xx/4A6xx		0.078125	0.003	0.159

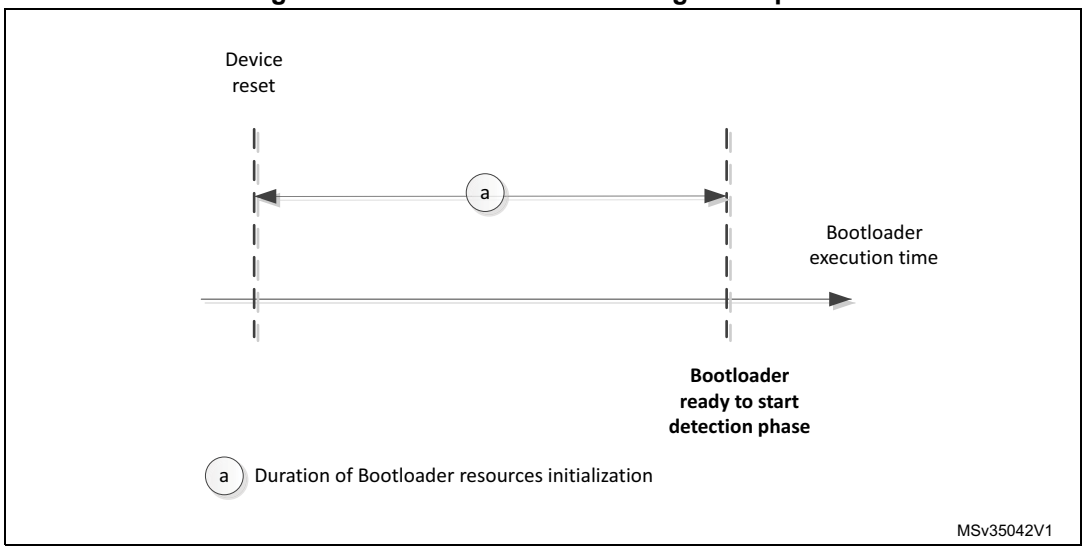
Table 241. USART bootloader minimum timings (ms) (continued)

Device	One USART byte sending	USART configuration	USART connection
STM32L4Rxx/4Sxx	0.0062	0.0235	0.0307
STM32L4P5xx/4Q5xx	0.0062	0.0235	0.0307
STM32L552xx/562xx	0.078125	0.01	0.11
STM32U031xx	0.012	0.050	0.062
STM32U073xx/STM32U083xx	0.014	0.049	0.077
STM32U031xx	0.012	0.050	0.062
STM32U3B5xx/3C5xx	0.0128125	0.00624	0.0128125
STM32U535xx/545xx	0.078125	0.001	NA
STM32U575xx/585xx	0.078125	0.001	NA
STM32U595xx/599xx/5A5xx/5A9xx	0.078125	0.001	NA
STM32U5F7xx/5F9xx/5G7xx/5G9xx	0.078125	0.001	NA
STM32WB10xx/15xx/30xx/35xx/50xx/55xx	0.078125	0.003	0.159
STM32WBA2xxx	0.078125	0.001	0.110
STM32WBA52xx	0.078125	0.001	NA
STM32WBA62xx/63xx/64xx/65xx	0.102	0.004	0.106
STM32WLE5xx/WL55xx	0.078125	0.001	0.110

103.3 USB connection timing

This is the time that the host must wait for between plugging the USB cable and establishing a correct connection with the device. It includes enumeration and DFU components configuration. The USB connection depends upon the host.

Figure 133. USB connection timing description



Note: For STM32F105xx/107xx devices, if the external HSE crystal frequency is different from 25 MHz (14.7456 or 8 MHz), the device performs several unsuccessful enumerations (with connect/disconnect sequences) before establishing a correct connection with the host. This is due to the HSE detection mechanism based on Start-of-frrame (SOF) detection.

Table 242. USB bootloader minimum timings (ms)

Device		USB connection
STM32C071xx		552
STM32C5A3xx/59xxx		140
STM32C55xxx/562xx		140
STM32C53xxx/542xx		140
STM32F04xxx		350
STM32F070x6		TBD
STM32F070xB		320
STM32F105xx/107xx	HSE = 25 MHz	460
	HSE = 14.7465 MHz	4500
	HSE = 8 MHz	13700
STM32F2xxxx		270
STM32F301xx/302x4(6/8)		300
STM32F302xB(C)/303xB(C)		300
STM32F302xD(E)/303xD		100
STM32F373xx		300
STM32F40xxx/41xxx	V3.x	270
	V9.x	250
STM32F401xB(C)		250
STM32F401xD(E)		250
STM32F411xx		250
STM32F412xx		380
STM32F413xx/423xx		350
STM32F429xx/439xx	V7.x	250
	V9.x	
STM32F446xx		200
STM32F469xx/479xx		270
STM32F72xxx/73xxx		320
STM32F74xxx/75xxx		230
STM32G0B1xx/C1xx		300
STM32G4xxxx		300
STM32G554xx/564xx		220

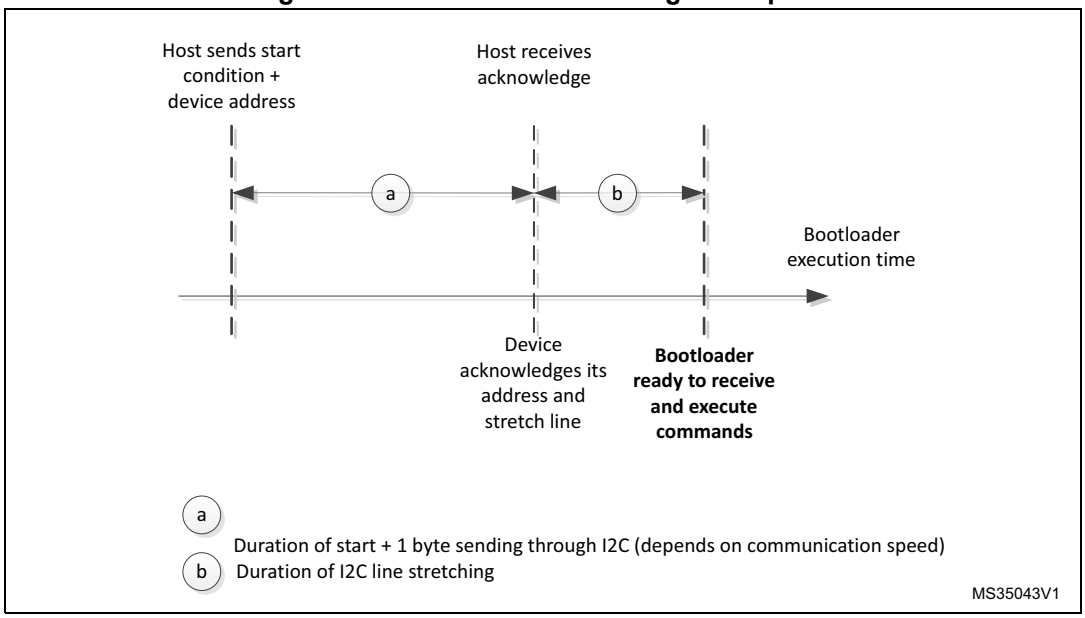
Table 242. USB bootloader minimum timings (ms) (continued)

Device		USB connection
STM32H503xx		251
STM32H543xx/553xx		245
STM32H562xx/63xx/73xx		245
STM32H5Ex/5Fx		217
STM32H72xxx/73xxx		53.9764
STM32H74xxx/75xxx		53.9764
STM32H7A3xx/7B3xx/7B0xx		53.9764
STM32H7P4xx/P5xx		5.02
STM32L07xxx/08xxx		140
STM32L1xxxC		849
STM32L1xxxD		849
STM32L412xx/422xx		820
STM32L43xxx/44xxx		820
STM32L45xxx/46xxx		330
STM32L47xxx/48xxx	V10.x	300
	V9.x	
STM32L496xx/4A6xx		430
STM32L4P5xx/4Q5xx		322
STM32L4Rxx/4Sxx		322
STM32L552xx/L562xx		300
STM32U031xx		NA
STM32U073xx/ STM32U083xx		241
STM32U375xx/385xx		210
STM32U3B5xx/3C5xx		210
STM32U535xx/545xx		300
STM32U575xx/585xx		300
STM32U595xx/599xx/5A5xx/5A9xx		300
STM32U5F7xx/5F9xx/5G7xx/5G9xx		300
STM32WB30xx/35xx/50xx/55xx		300
STM32WBA2xxx		180
STM32WBA62xx/63xx/64xx/65xx		69

103.4 I2C connection timing

I2C connection timing is the time that the host must wait for between sending I2C device address and sending command code. This timing includes I2C line stretching duration.

Figure 134. I2C connection timing description



Note: For I2C communication, a timeout mechanism is implemented and must be respected to execute bootloader commands correctly. This timeout is implemented between two I2C frames in the same command (example: for Write memory command, a timeout is inserted between command sending frame and address memory sending frame). The same timeout period is inserted between two successive data receptions or transmissions in the same I2C frame. If the timeout period elapses, a system reset is generated to avoid bootloader crash.

In Erase memory and Read-out unprotect commands, consider the duration of the operation when implementing the host side. After sending the code of pages to erase, the host must wait until the bootloader device performs page erasing to complete the remaining steps of erase command.

Table 243. I2C bootloader minimum timings (ms)

Device	Start condition + one I2C byte sending	I2C line stretching	I2C connection	I2C timeout
STM32C011xx	0.254	0.004	0.060	2000
STM32C031xx	0.028	0.003	0.031	2000
STM32C051xx	0.031	0.019	0.050	2200
STM32C071xx	0.028	0.017	0.046	2000
STM32C091xx/92xx	0.031	0.018	0.049	2000
STM32F030xC	0.0225	0.0025	0.0250	1000
STM32F04xxx	0.0225	0.0025	0.0250	1000
STM32F070x6	0.0225	0.0025	0.0245	1000
STM32F070xB	0.0225	0.0025	0.0245	1000
STM32F071xx/072xx	0.0225	0.0025	0.0250	1000
STM32F09xxx	0.0225	0.0025	0.0245	1000

Table 243. I2C bootloader minimum timings (ms) (continued)

Device		Start condition + one I2C byte sending	I2C line stretching	I2C connection	I2C timeout
STM32F303x4(6/8)/334xx/328xx		0.0225	0.0027	0.0252	1000
STM32F318xx		0.0225	0.0027	0.0252	1000
STM32F358xx		0.0225	0.0055	0.0280	10
STM32F378xx		0.0225	0.0055	0.0280	10
STM32F398xx		0.0225	0.0020	0.0245	1500
STM32F40xxx/41xxx		0.0225	0.0022	0.0247	1000
STM32F401xB(C)		0.0225	0.0022	0.0247	1000
STM32F401xD(E)		0.0225	0.0022	0.0247	1000
STM32F410xx		0.0225	0.0020	0.0245	1000
STM32F411xx		0.0225	0.0022	0.0247	1000
STM32F412xx		0.0225	0.0020	0.0245	1000
STM32F413xx/423xx		0.0225	0.0020	0.0245	1000
STM32F42xxx/43xxx	V7.x	0.0225	0.0033	0.0258	1000
	V9.x	0.0225	0.0022	0.0247	1000
STM32F446xx		0.0225	0.0020	0.0245	1000
STM32F469xx/479xx		0.0225	0.0020	0.0245	1000
STM32F72xxx/73xxx		0.0225	0.0020	0.0245	1000
STM32F74xxx/75xxx		0.0225	0.0020	0.0245	500
STM32G03xxx/04xxx		0.0225	0.0020	0.0245	1000
STM32G07xxx/08xxx		0.0225	0.0020	0.0245	1000
STM32G0Bxx/Cxx		0.0225	0.0020	0.0245	1000
STM32G05xxx/061xx		0.0225	0.0020	0.0245	1000
STM32G4xxxx		0.0225	0.0020	0.0245	1000
STM32G53xxx/54xxx		0.0048	0.00005	0.003428	1000
STM32G554xx/564xx		0.0048	0.00005	0.003428	1000
STM32H503xx		0.038	0.03	0.041	1000
STM32H543xx/553xx		0.0048	0.000005	0.003428	1000
STM32H562xx/63xx/73xx		0.039	0.02	0.041	1000
STM32H5Ex/5Fx		0.0048	0.000005	0.003428	1000
STM32H72xxx/73xxx		0.0225	0.05	0.0745	1000
STM32H74xxx/75xxx		0.0225	0.05	0.0725	1000
STM32H7A3xx/7B3xx/7B0xx		0.0225	0.05	0.0745	1000
STM32H7P4xx/P5xx		0.035	0.006774	0.0270	1000

Table 243. I2C bootloader minimum timings (ms) (continued)

Device		Start condition + one I2C byte sending	I2C line stretching	I2C connection	I2C timeout
STM32L07xxx/08xxx		0.0225	0.0020	0.0245	1000
STM32L412xx/422xx		0.0225	0.0020	0.o245	1000
STM32L43xxx/44xxx		0.0225	0.0020	0.0245	1000
STM32L45xxx/46xxx		0.0225	0.0020	0.0245	1000
STM32L47xxx/48xxx	V10.x	0.0225	0.0020	0.0245	1000
	V9.x	0.0225	0.0020	0.0245	1000
STM32L496xx/4A6xx		0.0225	0.0020	0.0245	1000
STM32L4P5xx/4Q5xx		0.0109	0.0020	0.0642	1000
STM32L4Rxx/4Sxx		0.0109	0.0020	0.0642	1000
STM32L552xx/L562xx		0.0225	0.0020	0.0245	1000
STM32U031xx		0.035	0.019	0.106	1000
STM32U073xx/ STM32U083xx		0.016	0.019	0.024	1000
STM32U375xx/385xx		0.021	0.018	0.092	1000
STM32U3B5xx/3C5xx		0.0.026	0.0168	0.10288	1000
STM32U535xx/545xx		0.0225	0.0020	0.0245	1000
STM32U575xx/585xx		0.0225	0.0020	0.0245	1000
STM32U595xx/599xx/5A5xx/5A9xx		0.0225	0.0020	0.0245	1000
STM32U5F7xx/5F9xx/5G7xx/5G9xx		0.0225	0.0020	0.0245	1000
STM32WB10xx/15xx/30xx/35xx/50xx/55xx		0.0225	0.0020	0.0245	1000
STM32WBA2xxx		0.003	0.019	0.539	1000
STM32WBA52xx		0.0225	0.0020	0.0245	1000
STM32WBA62xx/63xx/64xx/65xx		0.003	0.019	0.539	1000

103.5 SPI connection timing

SPI connection timing is the time that the host must wait for between sending the synchronization data (0xA5) and receiving the first acknowledge response (0x79).

Figure 135. SPI connection timing description

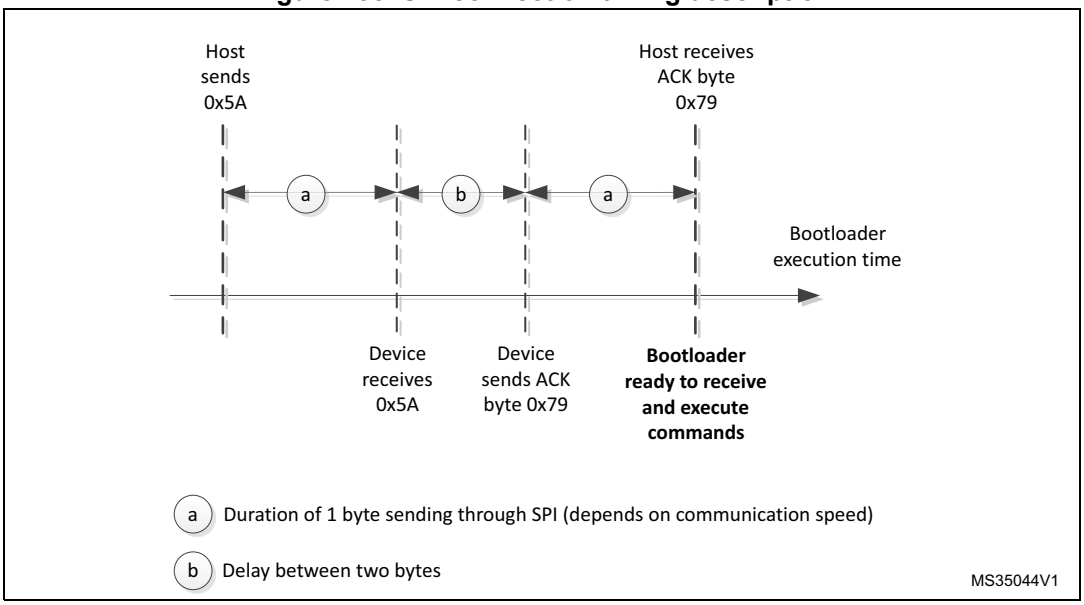


Table 244. SPI bootloader minimum timings (ms) for STM32 devices

Device	One SPI byte sending	Delay between two bytes	SPI connection
All products	0.001	0.008	0.01

Appendix A Example of *ExitSecureMemory v1.0* function

```
/**
******************************************************************************
****
* @file    main.c
******************************************************************************
****
*/

/* Includes ------------------------------------------------------------------
---*/
#include "main.h"

/* Private function prototypes -----------------------------------------------
---*/
static void ConfigClock(void);

void JUMP_WITHOUT_PARAM(uint32_t jump_address);
void JUMP_WITH_PARAM(uint32_t jump_address, uint32_t magic, uint32_t
applicationVectorAddress);

/* Private functions ---------------------------------------------------------
---*/

/**
* @brief  Main program
* @param  None
* @retval None
*/
int main(void)
{
  ConfigClock();

  uint32_t application_address                    = 0x08000800;
  uint32_t exit_secure_memory_address   = 0x1FFF1E00;
  uint32_t magic_number                             = 0x08192A3C;
  uint32_t exit_with_magic_number           = 0x0;

  if (exit_with_magic_number)
  {
    JUMP_WITH_PARAM(exit_secure_memory_address, magic_number,
application_address);
  }
  else
  {
```

```
    JUMP_WITHOUT_PARAM(exit_secure_memory_address);
  }
}

/**
* @brief  ConfigClock
* @param  None
* @retval None
*/
static void ConfigClock(void)
{
  /* Will be developped as per the template of the needed project */
}

/**
* @brief  JUMP_WITHOUT_PARAM
* @param  jump_address
* @retval None
*/
void JUMP_WITHOUT_PARAM(uint32_t jump_address)
{
  asm ("LDR R1, [R0]");     // jump_address
  asm ("LDR R2, [R0,#4]");
  asm ("MOV SP, R1");
  asm ("BX  R2");
}

/**
* @brief  JUMP_WITH_PARAM
* @param  jump_address, magic, applicationVectorAddress
* @retval None
*/
void JUMP_WITH_PARAM(uint32_t jump_address, uint32_t magic, uint32_t
applicationVectorAddress))
{
  asm ("MOV R3, R0");       // jump_address
  asm ("LDR R0, [R3]");
  asm ("MOV SP, R0");
  asm ("LDR R0, [R3,#4]");
  asm ("BX R0");
}

/************************ (C) COPYRIGHT STMicroelectronics *****END OF
FILE****/
```

Appendix B Example of *ExitSecureMemory v1.1* function

```
/**

******************************************************************************
  * @file    main.c

******************************************************************************
  */

/* Includes ------------------------------------------------------------------*/
#include "main.h"

/* Private function prototypes -----------------------------------------------*/
static void ConfigClock(void);
static void Jump_Without_Param(uint32_t exit_secure_address, uint32_t
dummy1, uint32_t dummy2, uint8_t mpu_region_number);
static void Jump_With_Param(uint32_t exit_secure_address, uint32_t magic,
uint32_t application_address, uint8_t mpu_region_number);

/* Private functions ---------------------------------------------------------*/

/**
  * @brief  Main program.
  * @retval None.
  */
int main(void)
{
  ConfigClock();

  uint32_t application_address  = 0x08008000;
  uint32_t exit_secure_address  = 0x1FFF6000;
  uint8_t mpu_region_number     = 0x04;
  uint32_t magic_number         = 0x08192A3C;
  uint32_t with_magic_number    = 0x0;

  if (with_magic_number)
  {
   Jump_With_Param(exit_sticky_address, magic_number, application_address,
mpu_region_number);
  }
```

```
  else
  {
    Jump_Without_Param(exit_sticky_address, 0x0, 0x0, mpu_region_number);
  }
}

/**
  * @brief  Configure system clocks.
  * @retval None.
  */
static void ConfigClock(void)
{
  /* Will be developped as per the template of the needed project */
}

/**
  * @brief  Jump to secure exit memory without magic number and user
address.
  * @param  exit_secure_address Address of exit secure memory.
  * @param  dummy1 Not used.
  * @param  dummy2 Not used.
  * @param  mpu_region_number MPU region to enable.
  * @retval None.
  */
static void Jump_Without_Param(uint32_t exit_secure_address, uint32_t
dummy1, uint32_t dummy2, uint8_t mpu_region_number)
{
  /**
    * R0 = exit_secure_address  --> Exit secure memory stack pointer
    * R1 = dummy1               --> Dummy data
    * R2 = dummy2               --> Dummy data
    * R3 = mpu_region_number    --> MPU region number
    *
   * NOTE: Assume R1 and R2 registers are useless so can be moified, but R3
is used for MPU region number and must not be changed
    */
  asm ("LDR R1, [R0]");     // Load stack pointer (content of address
pointed by R0) in R1
  asm ("LDR R2, [R0,#4]");  // Load jump address (content of address pointed
by R4 + 4) in R2
  asm ("MOV SP, R1");      // Change stack pointer register with value from
R1
  asm ("BX  R2");           // Jump to address pointed by R2
}

/**
```

```
  * @brief  Jump to secure exit memory with parameters.
  * @param  exit_secure_address Address of exit secure memory.
  * @param  magic Magic number value.
  * @param  application_address Application address.
  * @param  mpu_region_number MPU region to enable.
  * @retval None
*/
static void Jump_With_Param(uint32_t exit_secure_address, uint32_t magic,
uint32_t application_address, uint8_t mpu_region_number)
{
  /**
    * R0 = exit_secure_address  --> Exit secure memory stack pointer
    * R1 = magic                --> Magic number
    * R2 = application_address  --> User application start address
    * R3 = mpu_region_number    --> MPU region number
    *
    * NOTE: R1, R2 and R3 registers must not be changed in below code
    */
  asm ("MOV R4, R0");       // Backup R0 in R4
  asm ("LDR R0, [R4]");     // Load stack pointer (content of address
pointed by R4) in R0
  asm ("MOV SP, R0");      // Change stack pointer register with value from
R0
  asm ("LDR R0, [R4,#4]"); // Load jump address (content of address pointed
by R4 + 4) in R0
  asm ("BX R0");            // Jump to address pointed by R0
```

Appendix C ExitSecureMemory v2.0 function

```
EXITHDPLIB_PFUNC->JumpHDPLvl2((uint32_t)NextVectorTableAddr, 1U);
EXITHDPLIB_PFUNC->JumpHDPLvl3((uint32_t)NextVectorTableAddr, 1U);
Example of an implementation on STM32C5xx

/* EXITHDPLIB system Flash region definition constants
*****************************/
#define EXITHDPLIB_SYS_FLASH_PFUNC_START   (0x0BF883E0UL)
#define EXITHDPLIB_ERROR                   (0xF5F5F5F5UL)

/*!< EXITHDPLIB pointer function structure address definition */
#define EXITHDPLIB_PFUNC_BASE EXITHDPLIB_SYS_FLASH_PFUNC_START
#define EXITHDPLIB_PFUNC      ((EXITHDPLIB_pFunc_TypeDef
*)EXITHDPLIB_PFUNC_BASE)

/**
  * @brief  Prototype of EXITHDPLIB JumpHDPLvl2/3 Functions.
  * @detail This function close the requested hdp area passed in input
  *         parameter and jump to the reset handler present within the
  *         Vector table. The function does not return on successful
execution.
  * @param  VectorTableAddr: Address of the next vector table to apply.
  * @param  MPUIndex: MPU region index to enable before jumping.
  * @retval EXITHDPLIB_ERROR on error, otherwise does not return.
  */
typedef uint32_t (*EXITHDPLIB_JumpHDP_TypeDef)(uint32_t VectorTableAddr,
uint32_t MPUIndex);

/**
  * @brief  EXITHDPLIB header structure
  */
typedef struct
{
  uint8_t  Magic[8] ;                       /*!< Address offset: 0x00 */
  uint32_t Version;                         /*!< Address offset: 0x08 */
  EXITHDPLIB_JumpHDP_TypeDef JumpHDPLvl2;   /*!< Address offset: 0x0C */
  EXITHDPLIB_JumpHDP_TypeDef JumpHDPLvl3;   /*!< Address offset: 0x10 */
} EXITHDPLIB_pFunc_TypeDef;
```

104 Revision history

Table 245. Document revision history

Date	Revision	Changes
21-Feb-2019	36	Updated *Table 1: Applicable products*, *Section 3: Glossary*, *Table 3: Embedded bootloaders*, *Table 239: Bootloader device-dependent parameters*, *Table 240: Bootloader startup timings (ms)*, *Table 241: USART bootloader minimum timings (ms)*, *Table 242: USB bootloader minimum timings (ms)*, *Table 243: I2C bootloader minimum timings (ms)*. Added *Section 85: STM32WB30xx/35xx/50xx/55xx devices*
06-May-2019	37	Updated *Table 1: Applicable products*, *Section 3: Glossary*, *Table 239: Bootloader device-dependent parameters*, *Table 240: Bootloader startup timings (ms)*, *Table 241: USART bootloader minimum timings (ms)*, *Table 242: USB bootloader minimum timings (ms)*, *Table 243: I2C bootloader minimum timings (ms)*. Added *Section 52: STM32G431xx/441xx devices*, *Section 53: STM32G47xxx/48xxx devices*.
08-Jul-2019	38	Updated: – *Table 1: Applicable products*, *Table 2: Bootloader activation patterns*, *Table 3: Embedded bootloaders*, *Table 88: STM32F413xx/423xx configuration in system memory boot mode*, *Table 145: STM32H74xxx/75xxx configuration in system memory boot mode*, *Table 146: STM32H74xxx/75xxx bootloader version*, *Table 157: STM32L031xx/041xx configuration in system memory boot mode*, *Table 178: STM32L43xxx/44xxx bootloader versions*, *Table 179: STM32L45xxx/46xxx configuration in system memory boot mode*, *Table 186: STM32L496xx/4A6xx bootloader version*, *Table 197: STM32WB30xx/35xx/50xx/55xx bootloader versions*, *Table 239: Bootloader device-dependent parameters*, *Table 240: Bootloader startup timings (ms)*, *Table 241: USART bootloader minimum timings (ms)*, *Table 242: USB bootloader minimum timings (ms)*, *Table 243: I2C bootloader minimum timings (ms)* – *Section 3: Glossary*, *Section 4.1: Bootloader activation*, *Section 47.1: Bootloader configuration*, *Section 52.1: Bootloader configuration* – *Figure 80: Bootloader V9.x selection for STM32H74xxx/75xxx*, *Figure 110: Dual bank boot implementation for STM32L4Rxxx/STM32L4Sxxx bootloader V9.x* Added *Note:* in *Section 4.2*, *Note:* in *Section 21.3*, *Note:* in *Section 63.1*, *Note:* in *Section 67.1*, *Section 47: STM32G03xxx/STM32G04xxx devices*
16-Sep-2019	39	Updated: – *Table 1: Applicable products*, *Table 2: Bootloader activation patterns*, *Table 3: Embedded bootloaders*, *Table 107: STM32G03xxx/04xxx bootloader versions*, *Table 176: STM32L412xx/422xx bootloader versions*, *Table 178: STM32L43xxx/44xxx bootloader versions*, *Table 180: STM32L45xxx/46xxx bootloader versions*, *Table 182: STM32L47xxx/48xxx bootloader V10.x versions*, *Table 184: STM32L47xxx/48xxx bootloader V9.x versions*, *Table 186: STM32L496xx/4A6xx bootloader version*, *Table 188: STM32L4P5xx/4Q5xx bootloader versions*, *Table 239: Bootloader device-dependent parameters*, *Table 240: Bootloader startup timings (ms)*, *Table 241: USART bootloader minimum timings (ms)*, *Table 242: USB bootloader minimum timings (ms)*, *Table 243: I2C bootloader minimum timings (ms)* – *Section 3: Glossary*, *Section 4.2: Bootloader identification* Added *Figure 70: Dual bank boot implementation for STM32G47xxx/48xxx bootloader V13.x*, *Section 83: STM32L552xx/62xx devices*, note in *Section 85.3: Bootloader version*

Table 245. Document revision history (continued)

Date	Revision	Changes
03-Oct-2019	40	Updated *Table 3: Embedded bootloaders*, *Table 193: STM32L552xx/62xx bootloader versions*, *Table 197: STM32WB30xx/35xx/50xx/55xx bootloader versions*
25-Oct-2019	41	Updated: – *Table 99: STM32F72xxx/73xxx bootloader V9.x versions*, *Table 101: STM32F74xxx/75xxx bootloader V7.x versions*, *Table 103: STM32F74xxx/75xxx bootloader V9.x versions*, *Table 105: STM32F76xxx/77xxx bootloader V9.x versions*, *Table 106: STM32G03xxx/G04xxx configuration in system memory boot mode*, *Table 146: STM32H74xxx/75xxx bootloader version*, *Table 188: STM32L4P5xx/4Q5xx bootloader versions*, *Table 191: STM32L552xx/62xx configuration in system memory boot mode*, *Table 240: Bootloader startup timings (ms)*, *Table 241: USART bootloader minimum timings (ms)*, *Table 243: I2C bootloader minimum timings (ms)* – *Section 24: STM32F2xxxx devices*
05-Dec-2019	42	Updated: – *Table 1: Applicable products*, *Table 2: Bootloader activation patterns*, *Table 3: Embedded bootloaders*, *Table 239: Bootloader device-dependent parameters*, *Table 240: Bootloader startup timings (ms)*, *Table 241: USART bootloader minimum timings (ms)*, *Table 242: USB bootloader minimum timings (ms)*, *Table 243: I2C bootloader minimum timings (ms)* – *Section 3: Glossary* Added: *Section 64: STM32H7A3xx/7B3xx/7B0xx devices*, *Section 81: STM32L4P5xx/4Q5xx devices*, *Section 93: STM32WLE5xx/55xx devices*

Table 245. Document revision history (continued)

Date	Revision	Changes
04-Jun-2020	43	Updated: – *Table 1: Applicable products*, *Table 2: Bootloader activation patterns*, *Table 3: Embedded bootloaders*, *Table 116: STM32G431xx/441xx configuration in system memory boot mode*, *Table 118: STM32G47xxx/48xxx configuration in system memory boot mode*, *Table 119: STM32G47xxx/48xxx bootloader version*, *Table 146: STM32H74xxx/75xxx bootloader version*, *Table 148: STM32H7A3xx/7B3xx/7B0xx bootloader version*, *Table 188: STM32L4P5xx/4Q5xx bootloader versions*, *Table 191: STM32L552xx/62xx configuration in system memory boot mode*, *Table 193: STM32L552xx/62xx bootloader versions*, *Table 196: STM32WB30xx/35xx/50xx/55xx configuration in system memory boot mode*, *Table 239: Bootloader device-dependent parameters* – *Section 3: Glossary*, *Section 45: STM32F74xxx/75xxx devices*, *Section 47.1: Bootloader configuration*, *Section 48.1: Bootloader configuration*, *Section 52.1: Bootloader configuration*, *Section 53.1: Bootloader configuration*, *Section 63.1: Bootloader configuration* Added: – *Section 4.5: Bootloader UART baudrate detection*, *Section 4.6: Programming constraints*, *Section 4.7: ExitSecureMemory feature* – *Note:* in: *Section 34.1.1: Bootloader configuration*, *Section 34.2.1: Bootloader configuration*, *Section 35.1: Bootloader configuration*, *Section 36.1: Bootloader configuration*, *Section 38.1: Bootloader configuration*, *Section 39.1: Bootloader configuration*, *Section 40.1: Bootloader configuration*, *Section 41.1.1: Bootloader configuration*, *Section 41.2.1: Bootloader configurationSection 42.1: Bootloader configuration*, *Section 43.1: Bootloader configuration*, *Section 44.1: Bootloader configuration*, *Section 45.1.1: Bootloader configuration*, *Section 45.2.1: Bootloader configuration*, *Section 46.1: Bootloader configuration* – *Figure 98: Dual bank boot Implementation for STM32L3x2xx/44xxx bootloader V9.x*, *Figure 100: Dual bank boot implementation for STM32L45xxx/46xxx bootloader V9.x*, *Figure 106: Dual bank boot Implementation for STM32L496xx/4A6xx bootloader V9.x* – *Appendix A: Example of ExitSecureMemory v1.0 function* Deleted Figure 48. Access to securable memory area from the bootloader for STM32G03xxx/G04xxx, Figure 50. Access to securable memory area from the bootloader for STM32G07xxx/G08xxx, Figure 52. Access to securable memory area, Figure 54. Access to securable memory area
29-Jul-2020	44	Introduced STM32H72xxx/73xxx devices, hence added *Section 62: STM32H72xxx/73xxx devices* and its subsections. Updated *Section 3: Glossary*, note in *Section 47.1: Bootloader configuration* and *Section 85.1: Bootloader configuration*. Updated *Table 1: Applicable products*, *Table 2: Bootloader activation patterns*, *Table 3: Embedded bootloaders*, *Table 8: ExitSecureMemory entry address*, *Table 118: STM32G47xxx/48xxx configuration in system memory boot mode*, *Table 148: STM32H7A3xx/7B3xx/7B0xx bootloader version*, *Table 169: STM32L1xxxC configuration in system memory boot mode*, *Table 171: STM32L1xxxD configuration in system memory boot mode*, *Table 173: STM32L1xxxE configuration in system memory boot mode*, *Table 191: STM32L552xx/62xx configuration in system memory boot mode*, *Table 239: Bootloader device-dependent parameters*, *Table 240: Bootloader startup timings (ms)*, *Table 241: USART bootloader minimum timings (ms)*, *Table 242: USB bootloader minimum timings (ms)* and *Table 243: I2C bootloader minimum timings (ms)*. Updated *Figure 80: Bootloader V9.x selection for STM32H74xxx/75xxx*. Minor text edits across the whole document.

Table 245. Document revision history (continued)

Date	Revision	Changes
06-Nov-2020	45	Introduced STM32WB30xx, STM32WB35xx, STM32WI55xx in *Table 1: Applicable products*, *Table 3: Embedded bootloaders* and in *Section 3: Glossary* Updated: – *Table 82: STM32F410xx configuration in system memory boot mode*, *Table 88: STM32F413xx/423xx configuration in system memory boot mode*, *Table 94: STM32F446xx configuration in system memory boot mode*, *Table 96: STM32F469xx/479xx configuration in system memory boot mode*, *Table 98: STM32F72xxx/73xxx configuration in system memory boot mode*, *Table 102: STM32F74xxx/75xxx configuration in system memory boot mode*, *Table 104: STM32F76xxx/77xxx configuration in system memory boot mode*, *Table 108: STM32G07xxx/8xxx configuration in system memory boot mode*, *Table 116: STM32G431xx/441xx configuration in system memory boot mode*, *Table 117: STM32G431xx/441xx bootloader version*, *Table 118: STM32G47xxx/48xxx configuration in system memory boot mode*, *Table 145: STM32H74xxx/75xxx configuration in system memory boot mode*, *Table 146: STM32H74xxx/75xxx bootloader version*, *Table 147: STM32H7A3xx/7B3xx/7B0xx configuration in system memory boot mode*, *Table 148: STM32H7A3xx/7B3xx/7B0xx bootloader version*, *Table 155: STM32L01xxx/02xxx configuration in system memory boot mode*, *Table 157: STM32L031xx/041xx configuration in system memory boot mode*, *Table 162: STM32L07xxx/08xxx bootloader versions*, *Table 163: STM32L07xxx/08xxx configuration in system memory boot mode*, *Table 175: STM32L412xx/422xx configuration in system memory boot mode*, *Table 187: STM32L4P5xx/4Q5xx configuration in system memory boot mode*, *Table 189: STM32L4Rxxx/4Sxxx configuration in system memory boot mode*, *Table 191: STM32L552xx/62xx configuration in system memory boot mode*, *Table 196: STM32WB30xx/35xx/50xx/55xx configuration in system memory boot mode*, *Table 215: STM32WLE5xx/55xx configuration in system memory boot mode*, *Table 216: STM32WLE5xx/55xx bootloader versions*, *Table 239: Bootloader device-dependent parameters*, *Table 240: Bootloader startup timings (ms)*, *Table 241: USART bootloader minimum timings (ms)* – title of *Table 85: STM32WB30xx/35xx/50xx/55xx devices*, *Table 196: STM32WB30xx/35xx/50xx/55xx configuration in system memory boot mode*, *Table 93: STM32WLE5xx/55xx devices*, *Table 215: STM32WLE5xx/55xx configuration in system memory boot mode*, *Table 122: Bootloader V12.x selection for STM32WLE5xx/55xx*, *Table 216: STM32WLE5xx/55xx bootloader versions*
02-Dec-2020	46	Upadated: – *Table 3: Embedded bootloaders*, *Table 106: STM32G03xxx/G04xxx configuration in system memory boot mode*, *Table 118: STM32G47xxx/48xxx configuration in system memory boot mode*, *Table 178: STM32L43xxx/44xxx bootloader versions*, *Table 180: STM32L45xxx/46xxx bootloader versions* Added following notes: – *Note: on page 407*, *Note: on page 414*, *Note: on page 422*, *Note: on page 435*, *Note: on page 441*

Table 245. Document revision history (continued)

Date	Revision	Changes
16-Feb-2021	47	Updated: – *Table 1: Applicable products*, *Table 3: Embedded bootloaders*, *Table 8: ExitSecureMemory entry address*, *Table 105: STM32F76xxx/77xxx bootloader V9.x versions*, *Table 118: STM32G47xxx/48xxx configuration in system memory boot mode*, *Table 175: STM32L412xx/422xx configuration in system memory boot mode*, *Table 177: STM32L43xxx/44xxx configuration in system memory boot mode*, *Table 179: STM32L45xxx/46xxx configuration in system memory boot mode*, *Table 183: STM32L47xxx/48xxx configuration in system memory boot mode*, *Table 185: STM32L496xx/4A6xx configuration in system memory boot mode*, *Table 187: STM32L4P5xx/4Q5xx configuration in system memory boot mode*, *Table 189: STM32L4Rxxx/4Sxxx configuration in system memory boot mode*, *Table 191: STM32L552xx/62xx configuration in system memory boot mode*, *Table 196: STM32WB30xx/35xx/50xx/55xx configuration in system memory boot mode*, *Table 239: Bootloader device-dependent parameters*, *Table 240: Bootloader startup timings (ms)*, *Table 241: USART bootloader minimum timings (ms)*, *Table 242: USB bootloader minimum timings (ms)*, *Table 243: I2C bootloader minimum timings (ms)* – *Section 3: Glossary* Added *Section 49: STM32G0B0xx device bootloader* and *Section 50: STM32G0B1xx/0C1xx device bootloader*
01-Apr-2021	48	Updated: – *Table 1: Applicable products*, *Table 3: Embedded bootloaders*, *Table 8: ExitSecureMemory entry address*, *Table 239: Bootloader device-dependent parameters*, *Table 240: Bootloader startup timings (ms)*, *Table 241: USART bootloader minimum timings (ms)*, *Table 243: I2C bootloader minimum timings (ms)* Added *Section 51: STM32G05xxx/061xx devices* and *Section 54: STM32G491xx/4A1xx devices*
06-Jul-2021	49	Updated: – *Section 3: Glossary*, *Section 34.2.1: Bootloader configuration* – *Table 3*, *Table 30*,from *Table 32* to *Table 37*, from *Table 40* to *Table 45*, *Table 46*, *Table 48*, *Table 50*, *Table 54*, *Table 56*, *Table 58*, *Table 60*, *Table 62*, *Table 64*, *Table 66*, *Table 68*, *Table 70*, *Table 72*, *Table 74*, *Table 76*, *Table 77*, *Table 78*, *Table 80*, *Table 82*, *Table 84*, *Table 86*, *Table 88*, *Table 90*, *Table 92*, *Table 94*, *Table 96*, *Table 98*, *Table 100*, *Table 102*, *Table 104*, *Table 106*, *Table 108*, *Table 110*, *Table 112*, *Table 114*, *Table 116*, *Table 118*, *Table 119*, *Table 120*, *Table 143*, *Table 145*, *Table 147*, *Table 147*, *Table 155*, *Table 157*, *Table 159*, *Table 160*, *Table 161*, *Table 163*, *Table 165*, *Table 167*, *Table 168*, *Table 169*, *Table 170*, *Table 171*, *Table 173*, *Table 174*, *Table 175*, *Table 177*, *Table 179*, *Table 181*, *Table 183*, *Table 185*, *Table 187*, *Table 189*, *Table 191*, *Table 196*, *Table 215*, *Table 239* Added *Table 192: STM32L552xx/62xx special commands* and *Section 84: STM32WB10xx/15xx devices*
23-Sep-2021	50	Updated: – *Section 3: Glossary*, *Section 49.1: Bootloader configuration*, *Section 50.1: Bootloader configuration*, – *Table 1*, *Table 2*, *Table 3*, *Table 109*, *Table 144*, *Table 146*, *Table 148*, *Table 178*, *Table 195*, *Table 197*, *Table 239*, *Table 240*, *Table 241*, *Table 242*, *Table 243* Added *Section 99: STM32U575xx/85xx devices*

Table 245. Document revision history (continued)

Date	Revision	Changes
20-Oct-2021	51	Updated: – *Table 3*, *Table 77*,*Table 109*, *Table 144*,*Table 239* – *Section 34.2.1: Bootloader configuration*
04-Feb-2022	52	Updated: – *Section 3: Glossary*, *Section 4.1: Bootloader activation*, – *Table 1*, *Table 2*, *Table 3*, *Table 7*, *Table 109*, *Table 146*, *Table 239* – *Figure 65* Added *Section 5: STM32C011xx devices* and *Section 6: STM32C031xx devices*
01-Mar-2022	53	Updated: – *Table 3*, *Table 143*, *Table 144*, *Table 239*. – *Section 4.1: Bootloader activation*, , *Section 47.1: Bootloader configuration*, *Section 48.1: Bootloader configuration*, *Section 49.1: Bootloader configuration*, *Section 51.1: Bootloader configuration*
20-Apr-2022	54	Updated: – *Table 3*, *Table 143*, *Table 147*, *Table 148*, *Table 239*
22-Jun-2022	55	Updated: – *Table 3*, *Table 145*, *Table 144*, *Table 239*
14-Dec-2022	56	Added *Section 4.8: IWDG usage*, *Section 78: STM32WBA52xx devices* Updated: – *Table 1*, *Table 2*, *Table 3*, *Table 7*, *Table 146*, *Table 147*, *Table 216*, *Table 239*, *Table 240*, *Table 241*, *Table 243* – *Section 3: Glossary*, *Section 4.1: Bootloader activation* – added note 1 in *Table 108*, *Table 110*, *Table 112*, *Table 116*, *Table 118*, *Table 120*, *Table 175*
21-Feb-2023	57	Updated: – *Table 1: Applicable products*, *Table 2: Bootloader activation patterns*, *Table 3: Embedded bootloaders*, *Table 7: Flash memory alignment constraints*, *Table 239: Bootloader device-dependent parameters*, *Table 240: Bootloader startup timings (ms)*, *Table 241: USART bootloader minimum timings (ms)*, *Table 242: USB bootloader minimum timings (ms)*, *Table 243: I2C bootloader minimum timings (ms)* – *Section 3: Glossary*, *Section 4.2: Bootloader identification* Added *Section 57: STM32H503xx devices*, *Section 60: STM32H562xx/563xx/573xx devices*, *Section 100: STM32U595xx/99xx/A5xx/A9xx devices*
04-Apr-2023	58	Updated: – *Table 1: Applicable products*, *Table 3: Embedded bootloaders*, *Table 239: Bootloader device-dependent parameters*, *Table 240: Bootloader startup timings (ms)*, *Table 241: USART bootloader minimum timings (ms)*, *Table 242: USB bootloader minimum timings (ms)*, *Table 243: I2C bootloader minimum timings (ms)* – *Section 3: Glossary* Added *Section 98: STM32U535xx/545xx devices*
21-Jun-2023	59	Updated *Table 3: Embedded bootloaders*, *Table 109: STM32G07xxx/08xxx bootloader versions*, and *Table 239: Bootloader device-dependent parameters*. Minor text edits across the whole document.

Table 245. Document revision history (continued)

Date	Revision	Changes
25-Oct-2023	60	Updated *Section 2: Related documents*, note in *Section 4.1: Bootloader activation*, *Section 60.3: Bootloader version*, and *Section 76.1: Bootloader configuration*. Updated *Table 2: Bootloader activation patterns*, *Table 3: Embedded bootloaders*, *Table 79: STM32F401xB(C) bootloader versions*, *Table 112: STM32G0B1xx/0C1xx configuration in system memory boot mode*, *Table 128: STM32H503xx configuration in system memory boot mode*, *Table 137: STM32H562xx/563xx/573xx configuration in system memory boot mode*, *Table 139: STM32H562xx/563xx/573xx bootloader version*, *Table 143: STM32H72xxx/73xxx configuration in system memory boot mode*, *Table 145: STM32H74xxx/75xxx configuration in system memory boot mode*, *Table 147: STM32H7A3xx/7B3xx/7B0xx configuration in system memory boot mode*, *Table 191: STM32L552xx/62xx configuration in system memory boot mode*, *Table 193: STM32L552xx/62xx bootloader versions*, *Table 227: STM32U535xx/545xx configuration in system memory boot mode*, *Table 227: STM32U535xx/545xx configuration in system memory boot mode*, *Table 229: STM32U535xx/545xx bootloader versions*, *Table 232: STM32U575xx/85xx bootloader versions*, *Table 233: STM32U595xx/99xx/A5xx/A9xx configuration in system memory boot mode*, *Table 235: STM32U595xx/99xx/A5xx/A9xx bootloader versions*, and *Table 240: Bootloader startup timings (ms)*. Updated *Figure 74: Bootloader V14 selection for STM32H503xx*, *Figure 77: Bootloader V14 selection for STM32H562xx/563xx/573xx*, *Figure 127: Bootloader V9.x selection for STM32U535xx/545xx*, *Figure 128: Bootloader V9.x selection for STM32U575xx/85xx*, and *Figure 129: Bootloader V9.x selection for STM32U595xx/99xx/A5xx/A9xx*. Minor text edits across the whole document.
11-Jan-2024	61	Added STM32U5F7xx, STM32U5F9xx, STM32U5G7xx, and STM32U5G9xx devices. Updated *Table 1: Applicable products*, *Table 3: Embedded bootloaders*, and tables *239* to *243*. Updated *Section 3: Glossary*. Added *Section 101: STM32U5F7xx/F9xx/G7xx/G9xx devices* and its subsections. Minor text edits across the whole document.

Table 245. Document revision history (continued)

Date	Revision	Changes
06-Mar-2024	62	Updated *Table 1: Applicable products*, *Table 3: Embedded bootloaders*, *Table 7: Flash memory alignment constraints*, *Table 8: ExitSecureMemory entry address*, *Table 46: STM32F10xxx configuration in system memory boot mode*, *Table 112: STM32G0B1xx/0C1xx configuration in system memory boot mode*, *Table 128: STM32H503xx configuration in system memory boot mode*, *Table 130: STM32H503xx bootloader version*, *Table 137: STM32H562xx/563xx/573xx configuration in system memory boot mode*, *Table 143: STM32H72xxx/73xxx configuration in system memory boot mode*, *Table 145: STM32H74xxx/75xxx configuration in system memory boot mode*, *Table 146: STM32H74xxx/75xxx bootloader version*, *Table 147: STM32H7A3xx/7B3xx/7B0xx configuration in system memory boot mode*, *Table 183: STM32L47xxx/48xxx configuration in system memory boot mode*, and *Table 239: Bootloader device-dependent parameters*. Updated *Section 3: Glossary*, *Section 4.1: Bootloader activation*, *Section 77.1: Bootloader configuration*, and *Section 78.1: Bootloader configuration*. Added *Section 4.7.1: ExitSecureMemory v1.0*, *Section 4.7.2: ExitSecureMemory v1.1*, *Section 58: STM32H523xx/533xx devices*, *Section 65: STM32H7Rxxx/7Sxxx devices*, *Section 86: STM32WBA5xxx devices*, *Section 94: STM32U031xx devices*, *Section 95: STM32U073xx/83xx devices*, and their subsections. Added *Appendix B: Example of ExitSecureMemory v1.1 function*. Updated *Figure 6: ExitSecureMemory (v1.0 or v1.1) function usage*, *Figure 7: Access to securable memory (v1.0 or V1.1) area from the bootloader*, *Figure 74: Bootloader V14 selection for STM32H503xx*, and *Figure 77: Bootloader V14 selection for STM32H562xx/563xx/573xx*. Minor text edits across the whole document.
13-May-2024	63	Added STM32H562xx devices and STM32WB0 series, hence updated *Table 1: Applicable products*, *Table 3: Embedded bootloaders*, *Table 7: Flash memory alignment constraints*, and tables *240* to *244*. Updated *Section 3: Glossary* and note in *Section 77.1: Bootloader configuration*. Added *Section 89: STM32WB05xx devices*, *Section 90: STM32WB06xx/07xx devices*, *Section 91: STM32WB09xx devices*, and their subsections. Updated *Figure 55: Bootloader V9.x selection for STM32F446xx* and *Figure 115: Bootloader V11.x selection for STM32WBA5xxx*. Updated *Table 2: Bootloader activation patterns*, *Table 113: STM32G0B1xx/0C1xx bootloader versions*, *Table 143: STM32H72xxx/73xxx configuration in system memory boot mode*, *Table 145: STM32H74xxx/75xxx configuration in system memory boot mode*, *Table 227: STM32U535xx/545xx configuration in system memory boot mode*, and *Table 230: STM32U575xx/85xx configuration in system memory boot mode*. Minor text edits across the whole document.

Table 245. Document revision history (continued)

Date	Revision	Changes
18-Sep-2024	64	Added STM32C071xx and STM32H7B0xx devices, hence updated *Table 1: Applicable products*, *Table 3: Embedded bootloaders*, and tables *239* to *244*. Updated *Section 3: Glossary*, *Section 4.2: Bootloader identification*, *Section 57.1: Bootloader configuration*, *Section 58.1: Bootloader configuration*, *Section 60.1: Bootloader configuration*, *Section 64: STM32H7A3xx/7B3xx/7B0xx devices*, *Section 83.1: Bootloader configuration*, *Section 78.1: Bootloader configuration*, *Section 86.1: Bootloader configuration*, *Section 98.1: Bootloader configuration*, *Section 99.1: Bootloader configuration*, and *Section 100.1: Bootloader configuration*. Added *Section 4.9: Bootloader models*, *Section 4.10: Boot constraints on BL*, *Section 7: STM32C051xx devices*, and *Section 48.3.1: Compatibility break on boot sequence*. Updated *Table 8: ExitSecureMemory entry address*, *Table 109: STM32G07xxx/08xxx bootloader versions*, *Table 182: STM32L47xxx/48xxx bootloader V10.x versions*, and *Table 183: STM32L47xxx/48xxx configuration in system memory boot mode*.
14-Feb-2025	65	Added STM32C051/91/92xx, STM32U375/385xx, and STM32WBA62/63/64/65xx devices. Updated *Table 1: Applicable products*, *Table 3: Embedded bootloaders*, tables *6* to *11*, *Table 15: STM32C051xx configuration in system memory boot mode*, *Table 111: STM32G0B0xx bootloader versions*, *Table 113: STM32G0B1xx/0C1xx bootloader versions*, *Table 115: STM32G05xxx/061xx bootloader versions*, *Table 117: STM32G431xx/441xx bootloader version*, *Table 131: STM32H523xx/533xx configuration in system memory boot mode*, *Table 137: STM32H562xx/563xx/573xx configuration in system memory boot mode*, *Table 146: STM32H74xxx/75xxx bootloader version*, *Table 149: STM32H7Rxxx/7Sxxx configuration in system memory boot mode*, *Table 184: STM32L47xxx/48xxx bootloader V9.x versions*, *Table 198: STM32WBA5xxx configuration in system memory boot mode*, tables *217* to *221*, *Table 233: STM32U595xx/99xx/A5xx/A9xx configuration in system memory boot mode*, and tables *239* to *244*. Added footnote to *Table 110: STM32G0B0xx configuration in system memory boot mode*. Updated *Section 3: Glossary*, *Section 4.2: Bootloader identification*, *Section 4.3: Hardware connection requirements*, *Section 94.1: Bootloader configuration*, and *Section 95.1: Bootloader configuration*. Replaced master/slave with controller target when referring to I2C. Added *Section 7: STM32C051xx devices*, *Section 9: STM32C091xx/92xx devices*, *Section 65.4: Jump to bootloader*, *Section 88: STM32WBA62xx/63xx/64xx/65xx devices*, *Section 96: STM32U375xx/85xx devices*, and their subsections. Updated *Figure 4: SPI connection*, figures *13* to *15*, *63* to *69*, *71* to *77*, *81* and *82*, *Figure 115: Bootloader V11.x selection for STM32WBA5xxx*,and figures *122* to *124*. Minor text edits across the whole document.
10-Apr-2025	66	Updated *Table 3: Embedded bootloaders*, *Table 109: STM32G07xxx/08xxx bootloader versions*, *Table 146: STM32H74xxx/75xxx bootloader version*, and *Table 239: Bootloader device-dependent parameters*.

Table 245. Document revision history (continued)

Date	Revision	Changes
01-Jul-2025	67	Updated document title. Added STM32WBA50xx and STM32WL3xxx devices. Updated *Table 1: Applicable products*, *Table 2: Bootloader activation patterns*, *Table 3: Embedded bootloaders*, *Table 7: Flash memory alignment constraints*, *Table 18: STM32C071xx bootloader versions*, *Table 107: STM32G03xxx/04xxx bootloader versions*, *Table 117: STM32G431xx/441xx bootloader version*, *Table 198: STM32WBA5xxx configuration in system memory boot mode*, *Table 200: STM32WBA5xxx bootloader versions*, *Table 239: Bootloader device-dependent parameters*, and *Table 240: Bootloader startup timings (ms)*. Updated *Section 3: Glossary*, *Section 4.1: Bootloader activation*, *Section 4.3: Hardware connection requirements*, note in *Section 16.1: Bootloader configuration*, *Section 86: STM32WBA5xxx devices*, and *Section 103.1: Bootloader startup timing*. Removed former *Section 78: STM32WBA52xx devices*. Added *Section 92: STM32WL3xxx devices* and its subsections.
04-Aug-2025	68	Updated *Table 13: STM32C031xx configuration in system memory boot mode*, *Table 17: STM32C071xx configuration in system memory boot mode*, *Table 37: STM32F04xxx bootloader versions*, *Table 39: STM32F070x6 bootloader versions*, *Table 41: STM32F070xB bootloader versions*, *Table 43: STM32F071xx/072xx bootloader versions*, *Table 57: STM32F301xx/302x4(6/8) bootloader versions*, *Table 59: STM32F302xB(C)/303xB(C) bootloader versions*, *Table 61: STM32F302xD(E)/303xD(E) bootloader versions*, *Table 69: STM32F373xx bootloader versions*, *Table 162: STM32L07xxx/08xxx bootloader versions*, *Table 170: STM32L1xxxC bootloader versions*, *Table 172: STM32L1xxxD bootloader versions*, and *Table 174: STM32L1xxxE bootloader versions*.
18-Nov-2025	69	Updated *Table 3: Embedded bootloaders*, *Table 19: STM32C091xx/92xx configuration in system memory boot mode*, *Table 114: STM32G05xxx/061xx configuration in system memory boot mode*, *Table 151: STM32H7Rxxx/7Sxxx bootloader version*, and *Table 232: STM32U575xx/85xx bootloader versions*. Updated *Figure 15: Bootloader V11.0 selection for STM32C051xx devices*. Minor text edits across the whole document.
23-Feb-2026	70	Updated the entire document to add STM32C5xx, STM32H5Ex/5Fx, STM32U3B5xx/3C5xx, and STM32WBA2xxx devices.
02-Nov-2026	71	Updated the entire document to add STM32H543xxx/553xxx, STM32G5 series, and STM32H7P4xx/P5xx devices.

IMPORTANT NOTICE – READ CAREFULLY

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice.

In the event of any conflict between the provisions of this document and the provisions of any contractual arrangement in force between the purchasers and ST, the provisions of such contractual arrangement shall prevail.

The purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgment.

The purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of the purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

If the purchasers identify an ST product that meets their functional and performance requirements but that is not designated for the purchasers' market segment, the purchasers shall contact ST for more information.

ST and the ST logo are trademarks of ST. For additional information about ST trademarks, refer to www.st.com/trademarks. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2026 STMicroelectronics – All rights reserved